



IBM Field Engineering Maintenance Diagrams

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2025 Processing Unit

Preface

The IBM System/360 Model 25 FEMDM is intended as a quick-recall document for use in the field. The manual consists of the following sections.

1. Diagnostic Technique Diagrams
These diagrams give a generalized approach to troubleshooting problems on the System/360 Model 25.
3. Data Flow Diagrams
These diagrams show the system data flow and identify the major components of the system.
4. Functional Units Diagrams
The functional units diagrams are positive logic diagrams of the CPU, Integrated Units, File, and Channel circuits. These diagrams show logical operation of circuits without regard to signal level, although actual ALD line names are used.
5. Operational Diagrams
The operational diagrams describe some of the basic operations performed by the System/360 Model 25 and its integrated attachments.

Immediately following the table of contents is a reference list of lights, switches, and latches used in the System/360 Model 25.

References to the System/360 Model 25 FEMDM are made from the following manuals.

System/360 Model 25 Processing Unit FETOM,
Form Y24-3527.

System/360 Model 25 Processing Unit Integrated 2540 Attachment FETOM, Form Y24-3532.

System/360 Model 25 Processing Unit Integrated 1403 Attachment FETOM, Form Y24-3533.

System/360 Model 25 Processing Unit Integrated 2311 Attachment FETOM, Form Y24-3534.

System/360 Model 25 Processing Unit Channel FETOM,
Form Y24-3531.

System/360 Model 25 Processing Unit FE Maintenance Manual, Form Y24-3528.

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Significant changes or additions to the specifications contained in this publication are continually being made. Any such changes will be reported in subsequent revisions or FE Supplements.

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Set IC Interlock	4-2	4B	1403 PRINTER		
Shift Cycle	4-75	7B	80-240 Latch	4-205	4D
Soft Stop	4-2	9B	Block 2 Homes	4-209	5D
Stop Latch	4-75	5E	Block Check	4-211	5B
Storage Addr Check	4-10 P1	6E	Block Resync	4-203	8E
Storage Data Check	4-10 P1	6C	Carriage Busy	4-213	8E
Storage Wrap	4-25	7E	Channel 9	4-212	9E
Store Control	4-27 P5	3B	Channel 12	4-212	9E
Store Local Storage	4-6	5D	Clock Control	4-203	7B
Store Local Storage Intlk	4-6	4D	Coil Protect Check	4-211	9C
System Mask Reg	4-50	8A-8C	Device-End	4-201	6D
System Reset	4-1	5A	Diagnostic Decode 2	4-202	7D
System Reset Interlock	4-1	4B			

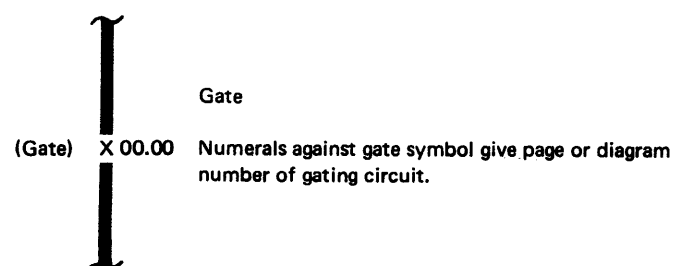
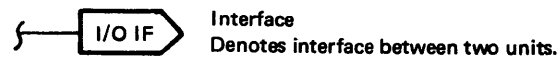
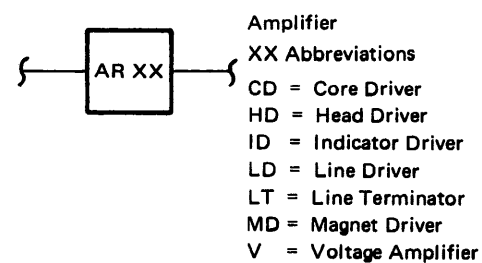
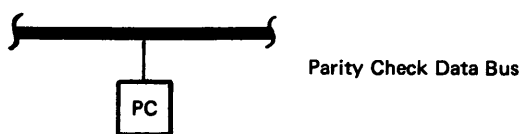
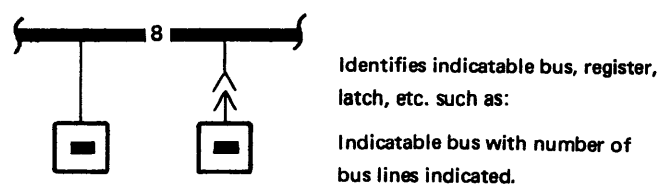
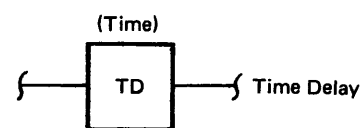
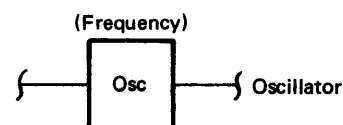
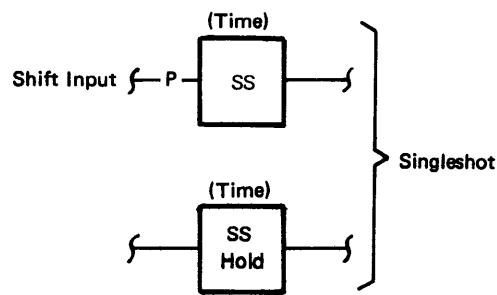
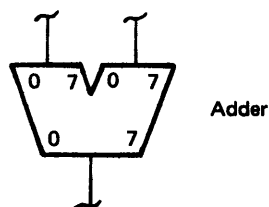
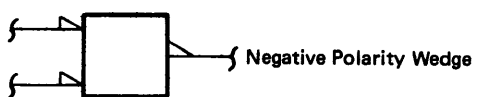
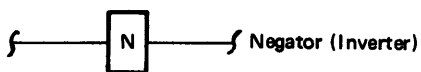
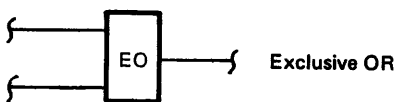
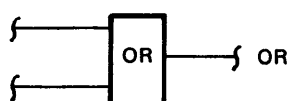
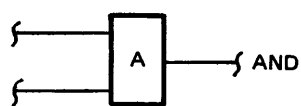
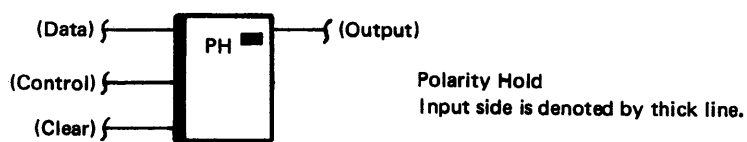
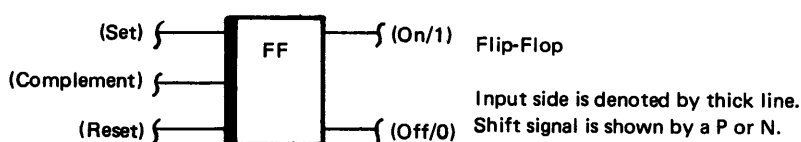
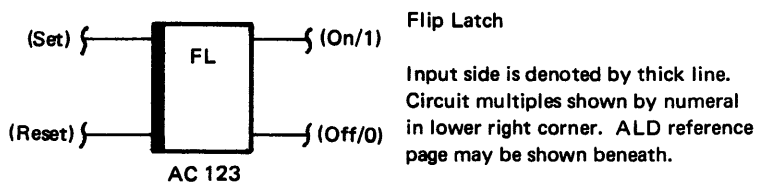
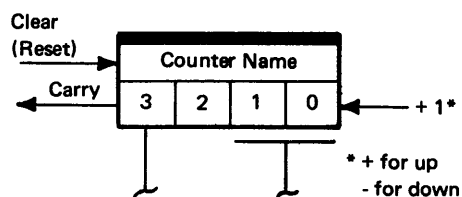
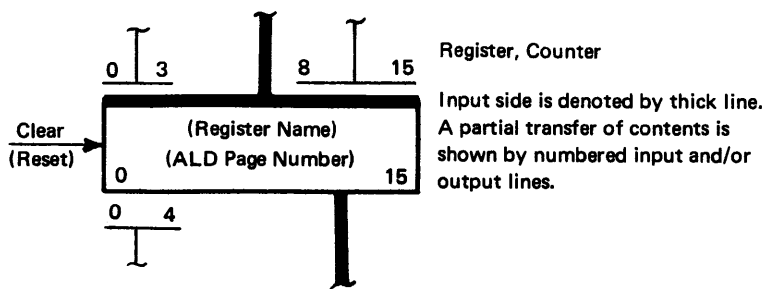
1403 PRINTER (Continued)

Diagnostic Decode 3	4-202	7D	Field Ring	4-305	8B
Diagnostic Decode 4	4-202	7E	File 0-3 Select	4-351	4A
Diagnostic PSS Pulse	4-204	4B	File Bus Out 0-7	4-349	8A
Diagnostic Write	4-209	5D	File Request.	4-337	7C
End of Forms	4-213	4A	First Field	4-339	3C
Forms Check	4-213	4B	First Share	4-337	7D
Hammer Check	4-211	8D	Flag Bit 0	4-339	8C
Hammer Driver Latches	4-210	9B	Flag Bit 6	4-339	8D
Home Gate	4-204	9C	Flag Bit 7	4-339	8E
Initial Ready.	4-201	8B	Flag Byte	4-339	4D
Last Scan	4-209	5D	GMWM	4-353	8E
MCS Emitter	4-204	4E	Gate Addr 0-3 Diag	4-355	3A
PCC End Latch	4-206	8D	Gate Addr 4-6 Diag	4-355	7A
PCC Latches	4-205	9B-9E	Gated Atten. File 0-3	4-351	3D
PLB.Data Reg Latches	4-208	4C	Go Latch.	4-335	4B
PLB Parity Check.	4-211	8E	Head Compare.	4-315	8E
PLBAR Latches	4-207	5B	Head Condition	4-331	4C
Print Attention	4-201	9A	High Compare	4-327	8A
Print Busy.	4-201	5D	Home Address Field	4-305	8B
Print Control	4-203	4B	Index Passed	4-331	4D
Print Gate	4-201	4D	Interrupt Latch	4-335	4B
Print Ready	4-201	7B	Inter Record Gap Zone A	4-305	5A
Print Request	4-202	6B	Key Field	4-305	8C
Print Scan	4-203	5B	Key Length Reg	4-311	5B
Printer in Sync	4-204	6E	Key-Op	4-319	3C
PSS A-Latch.	4-204	3C	Last Byte Gate	4-315	8C
PSS B-Latch.	4-204	4C	Low Compare	4-327	8B
PSS C-Latch.	4-204	6C	Last End-Op	4-335	8E
PSS Gate	4-204	7C	Miss A M	4-339	4B
Read Control	4-207	5C	Mode Error	4-353	8B
Ready Request Hold.	4-202	3A	Mode Latch	4-353	3D
Remember Last Home	4-209	3D	Multi Track-Op	4-319	3A
Remember No PLC	4-209	3B	NTO-Op	4-341	4C
Request Queued	4-202	5B	No Record Found	4-331	HE
Restore Latch	4-213	4E	Op-Register	4-319	3A
Diagnostic Request Gate	4-202	4D	Phase-A Reset	4-301	3B
Single Cycle	4-203	4C	Phase-A Set	4-301	3A
Single Cycle Print.	4-201	4B	Post Record Zone 4.	4-305	5E
Skip Latch	4-213	7C	Pre Record Zone 1	4-305	5C
Slow Brush Latches	4-212	4A	Prog Controlled Int	4-335	4D
Slow Speed Latch	4-212	8A	Read Buffer Reg.	4-325	8D
Space Latch	4-213	4D	Read Clock	4-301	3C
Start Key	4-201	4A	Read Data	4-301	3D
Sync Check	4-206	6E	Read Delay Control	4-301	4E
Write Control	4-207	5E	Read Gate	4-303	4D
			Read Op	4-319	3D
			Read Phase	4-301	4D
			Read Word Mark	4-353	3E
FILE			Recalibrate Time Out	4-349	3E
0 Count 1	4-333	4A	Record Zone 2.	4-305	5D
0 Count 2	4-333	4B	Scan Gate	4-327	4C
0 Count Control	4-333	4C	SLI Bit	4-321	3C
20/21 Gap Count.	4-311	3A	Search Addr Mark	4-333	4E
20/21 Latch	4-311	6A	Search Equal Op.	4-319	3B
20/21 Reset	4-311	5A	Search Hi Op	4-319	4B
Addr Mark 1.	4-333	7D	Second Share	4-337	7E
Addr Mark 2.	4-333	7D	Selected End of Cyl	4-351	8A
Addr Mark 3.	4-333	7E	Selected File Ready.	4-351	8A
Bit Ring	4-303	6B	Selected Index	4-351	8B
Bit Ring Inhibit	4-303	4B	Selected On-Line	4-351	8B
CCW Count 0	4-314	4A	Selected Seek Incomp	4-351	8C
CCW Flag Reg.	4-321	3A	Selected Status Holds	4-351	8A
Chain End	4-341	4A	Selected Unsafe	4-351	8C
Clock	4-301	8D	Serialized Data Tr	4-325	8B
Clock Thru K + D	4-307	8B	Serializer Reg	4-325	8D
Cold Start	4-335	4A	Set Control Tag	4-349	4C
Command Chain	4-321	3A	Set Cylinder Tag	4-349	4B
Compare Gate	4-327	4A	Set Difference Tag	4-349	4A
Compare Gate Diag	4-355	7D	Set Head Tag	4-349	4B
Compare Data Trig	4-323	8C	Share Req Hold	4-337	9C
Compare Inhibit	4-327	5C	Share Request	4-337	8B
Condition Track Overrun	4-331	8A	Short Search	4-315	4C
Conditioned Index Gate	4-331	4A	Skewed Data	4-333	5A
Count Field	4-305	8B	Skip Data	4-321	3C
Count-Op	4-319	4C	Space Latch	4-353	8B
Counter Byte 000	4-313	8A	Standard Index	4-331	4B
CUB Latch	4-335	4E	Standard Read Data	4-323	7C
Cyclic Code Error	4-327	8C	Status Modifier	4-327	6E
Cyclic Code Shift Reg	4-327	8D	Sync Detect Gate	4-333	8A
Cyclic Code Zone 3	4-305	5E	Tag Register	4-349	4A
DL Equal Zero	4-315	5D	Track Cond Check.	4-339	8B
Data Chain.	4-321	3A	Track Overrun	4-331	8C
Data Check	4-331	8C	Trap Gate	4-335	7A
Data Check In Count.	4-331	8D	Trap Latch	4-335	8C
Data Field	4-305	8D	Variable Gap Ctr	4-311	5B
Data Length Reg. High	4-313	5E	Variable Gap Zone B	4-305	5B
Data Length Reg Low	4-311	5D	Word Mark	4-353	4C
Data-Op	4-319	4D	Write Addr Mark Time	4-301	7A
Data Overrun	4-331	8E	Write Buffer Reg	4-323	8B
Delayed CCW Equal 0	4-315	4B	Write Clock Gate	4-303	8D
Delta Data Chain	4-321	4E	Write Gate	4-307	4C
Deserializer Reg	4-323	8B	Write-Op	4-319	4E
Diagnostic Mode	4-355	4E	Write Pad	4-353	5B
Erase Gate	4-307	4D	Write Phase A	4-301	4A
Erase Gate Hold.	4-307	5D	Wrong Length Record.	4-315	8B
Erase to Index.	4-307	8E	Zone Ring	4-305	5A
Field Length Ctr High.	4-313	5E	Zone Ring Gate	4-305	3E
Field Length Ctr Low	4-313	5C			

CHANNEL		
Address-Out	4-401	5C
Buffered Device.	4-403	5D
Burst Latch	4-403	5C
Channel Diagnostic	4-403	5E
Channel Identification	4-403	5B
Channel Parity Check.	4-413	5C
Command-Out.	4-401	5D
Data Chain Request	4-403	5A
Initial Selection	4-401	5E
Operational-Out.	4-401	5H
Select-Out	4-401	5E
Service-Out.	4-401	5A
Suppress-Out Control.	4-403	5G

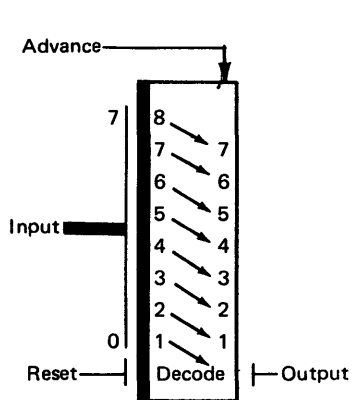
LEGEND

1. LOGIC DIAGRAMS



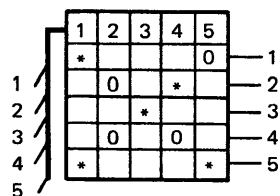
LEGEND

1. LOGIC DIAGRAMS



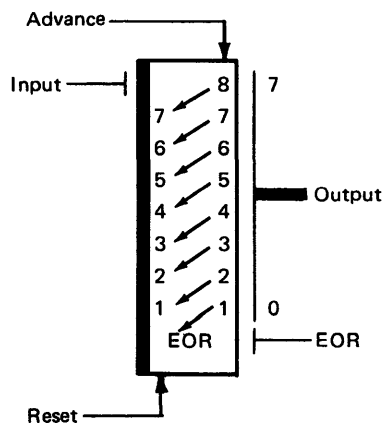
Shift Registers

The Shift Registers are commonly used to serialize and deserialize data information. Input side is denoted by the thick line. A partial transfer of contents is shown by numbered input/output lines.

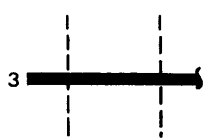


Multiple Line Input/Output Block

* Indicates active level
0 Indicates inactive level

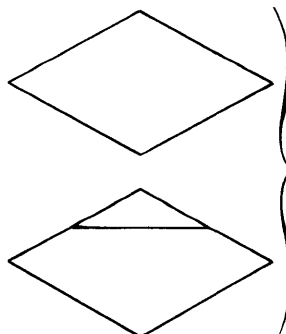


2. TIMING CHARTS



Active State

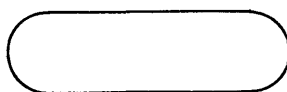
Numerals at beginning and end of the bar identify the signal(s) (also on the same chart) that activate and deactivate this line. "(Not)" with the number indicates that lack of the signal conditions the line



Decision

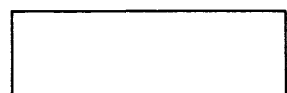
Indicates a point in a flowchart where a branch to alternate paths is possible. The upper portion of a divided block specifies where a detailed flowchart is located.

3. FLOWCHARTS



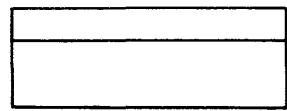
Terminal

Indicates beginning or end of event.



Process

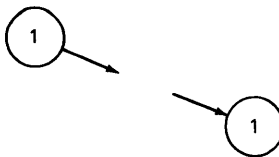
Indicates a major function or event. The upper portion of a divided block specifies where a detailed flowchart of the process is located.



Annotation

Gives descriptive comment or explanatory note.

4. GENERAL



On-Page Connector

Indicates connection between two parts of the same diagram. Arrow leaving symbol points (line-of-sight) to correspondingly-numbered symbol.



On-Page Connector

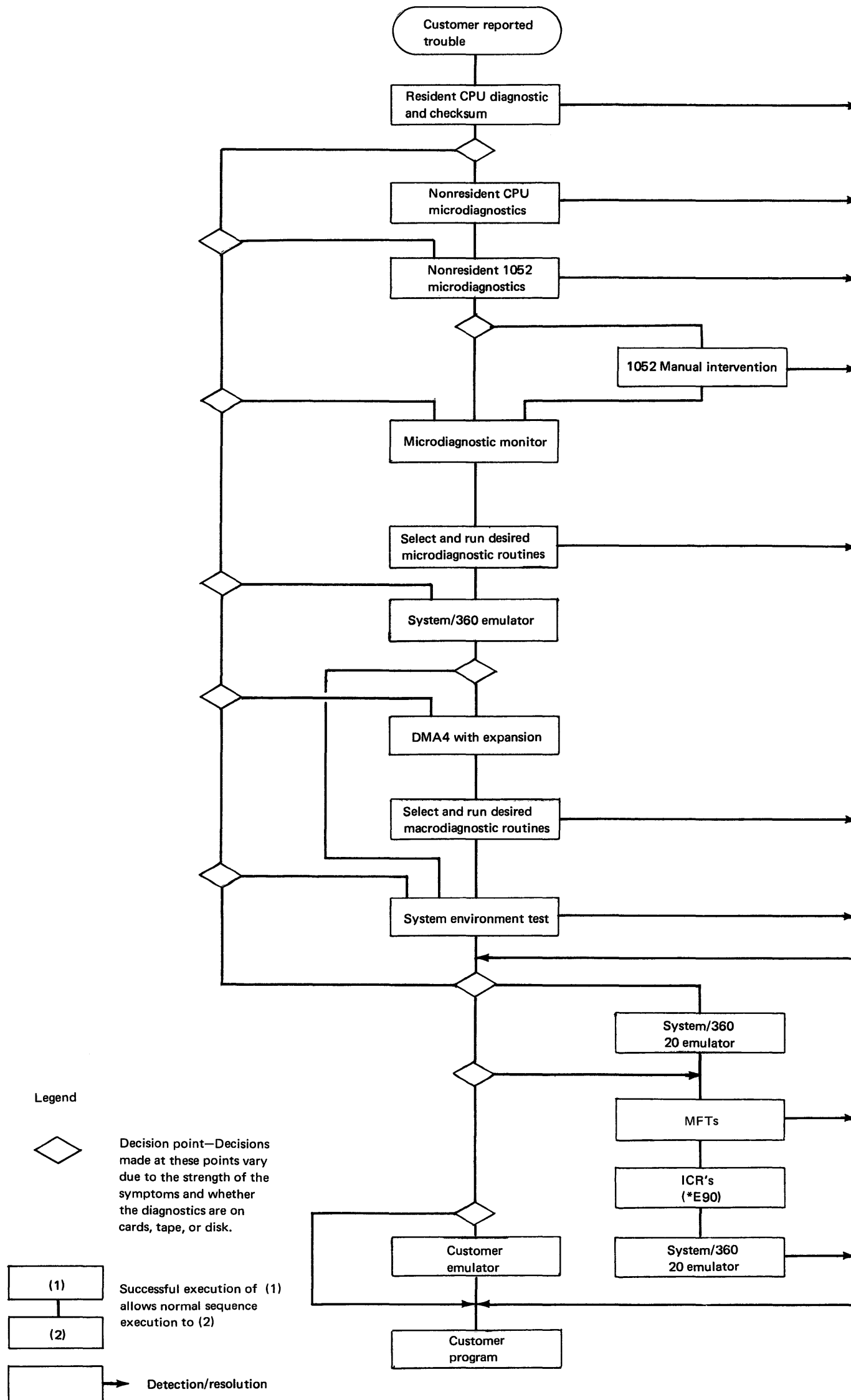
Indicates connection between two parts of the same diagram. Alphameric grid coordinate of complementary connector shown beneath.



Off-Page Connector

Indicates connection between diagrams located on separate pages. Location of correspondingly-lettered symbol shown adjacent.

Diag 1-2



General Diagnostic Strategy Diagrams

These diagrams describe the elements of the System/360 Model 25 basic maintenance strategy and how these elements should be most effectively used by FE. A majority of failures are expected to respond to this diagnostic package, which features comprehensive high-resolution card-fault-locating microdiagnostics.

The above diagram presents a general overview of the diagnostics and is not intended to be complete in itself.

Descriptive text sections of the following diagrams are written to the minimum detail level necessary for understanding and executing the maintenance strategy. For example, the microdiagnostic descriptions are at a summary detail level. The detailed microdiagnostic description consists of the Microprogram Automation System (MAS) list and comments.

For all categories of microdiagnostics, card replacement based on card-fault-location information is the primary approach to fault correction.

Card-fault-location information is provided for all microdiagnostic routines except those that are I/O unit oriented. Tests run under the microdiagnostic monitor use the 1052 to print card-fault-location error messages. Card-fault-location for the nonmonitor microdiagnostics are contained in the MAS listing. For all categories of microdiagnostics, the MAS listing for these routines is provided for additional failure analysis assistance.

Additional resident maintenance facilities are provided as part of every emulator microprogram to assist in failure analysis. These are :

1. FE trap (64 bytes starting at CS address 280)
2. Machine-check trap and 1052 logout
3. 1052 alter/display.

Diagram 1-1. Using the Diagnostic Program Package (Part 1 of 9)

The minor additional circuitry required for 1400-mode operation of 2311 and 2540 devices is tested using the microdiagnostics for these attachment features. Consequently, no special 1400 compatibility diagnostic or function tests are provided with this feature.

Similarly, the System/360 Model 20 Mode feature is implemented almost entirely by microprograms. Therefore special diagnostics are required only when a 2560 MFCM is included with this feature.

Diagnostic coverage for this feature configuration System/360 Model 20 Mode with 2560 MFCM is:

1. Microdiagnostics to test the 2560 attachment logic in the CPU.
2. 2020 Machine Function Tests (macrodiagnostics) executed in the System/360 Model 20 Mode to exercise and diagnose the 2560.
3. Impulse Check Routines (coreload *E90) for measuring the timing impulses from the 2560 and comparing them against a tolerance table.

The diagnostic strategy diagrams are the vehicle used to describe the general approach for executing the diagnostic package. The summary strategy diagram on this page provides a general conceptual perspective of the diagnostic strategy. The detailed strategy diagrams are not intended to cover all failure circumstances nor will they for a specific problem define which diagnostic execution path is most effective. For example, if the failure symptoms point strongly to a tape unit problem, then the microdiagnostics should be bypassed and DMA4 plus the tape macrodiagnostic sections should be loaded and executed.

The 2025 diagnostic program package and diagnostic strategy diagrams do not preclude the FE using common sense and his ability to recognize and interpret customer or machine indicated failure symptoms. The diagnostic package is most effective when its execution is based on the above ingredients.

Note: Where alternate input devices are available, the complete Diagnostic Program Package (DPP) should be kept in appropriate form to use these devices for Control Storage Load (CSL).

The recommended order for using the alternate CSL capability is :

- (a) disk
- (b) tape
- (c) cards

The general diagnostic strategy is based on comprehensive, high-resolution card-fault-locating microdiagnostic programs. These maintenance facilities are sectionalized into the following categories.

RESIDENT MICRODIAGNOSTICS

- The resident CPU microdiagnostic (BDIA) is initiated automatically by system reset CSL, or IPL to test the basic CPU logic necessary for a control storage load operation.
- The checksum routine is always initiated following the resident CPU microdiagnostic to ensure that control-storage contents are correct for all emulator core loads.
- When the card reader is the only input device, the microdiagnostic tests the attachment circuitry and the I/O read function necessary to load control storage from the card reader.
- The channel microdiagnostic is provided on systems having neither Integrated 2311 Attachment nor Integrated 2540 Card Read Punch. It tests the circuitry necessary for the channel to be functional.

The resident CPU microdiagnostic routines test the CPU circuits necessary for a control storage load (CSL) operation. No I/O device or attachment circuitry is checked.

For all operating modes (System/360 or other emulator), the resident CPU microdiagnostic is loaded into fixed locations of control storage beginning at address 0240 (system reset trap address).

Generally, errors are indicated either by a stop word, a stop loop, or a branch-test stop. If the CPU stops because of a stop word, the clock is stopped. The clock-off light on the CPU console is turned on. The M-register contents are displayed (the M-register contains the address of the next control word).

A stop loop is a single-word loop. The clock runs, but the microprogram does not progress. This type of error indication is identified when the system light is on, the manual light and clock-off light are off. The branch test stop method of error detection is used to indicate that a branch was executed incorrectly. This diagnostic function uses special hardware (DR-register bit 7) to detect the failure to branch correctly. The console indication is the same as for a stop word (system light off and manual light on) with the additional indication of the DR-register bit 7 remaining on. Similar to the stop word, the clock is stopped and the M-register contents are displayed (address of next control word).

These stop indications, together with a list of possible failing-card locations, provide a comprehensive diagnostic tool. This microdiagnostic is entered automatically when the:

1. system reset key is released,
2. CSL bootstrap and control-storage loading routines are completed, or
3. load key (IPL) is released.

These routines include a branching test, an ALU function test, a mode-register test, a storage word test, an LS X-line addressing test, an LS set/reset test, a dynamic condition register set/reset test, an ALU error-detection and A/B-register error-detection facilities.

The checksum routine is always initiated upon completion of the resident CPU diagnostic. This routine performs an exclusive OR function of the contents of control storage (with the exception of EC information located at 0002 through 000C and the 64-byte CE trap area starting at location 0280 hex). A special checksum number, created by the microprogram and included with every CSL, causes the exclusive OR function result to be zero. Executing the checksum routine ensures that the control store load was complete and correct, and that the control storage contents have remained complete and correct. This provides protection against a missing CSL card, an inadvertent change to some control storage data, or a machine failure that prevents proper control store loading. A CSL check indicator on the console panel is turned on when a checksum error occurs.

A message confirming the EC level of the core load is printed on the console printer (see example on Diag 1-1 Part 7) when the program is executed as part of the resident microdiagnostic program initiated at the completion of a CSL.

If the CPU is in CE mode (CE key is inserted), a correction factor is automatically entered into control storage. This correction factor permits future execution of the checksum routine without error. This correction factor remains until the next control store load. Upon completion of the checksum routine the system-reset routine is entered and executed.

On systems where the card reader is the only input device, a resident diagnostic is used to test the card reader circuits needed to CSL. The diagnostic uses the portion of control storage usually apportioned for file microprograms.

If used for the Integrated 2540, this microdiagnostic tests the circuits used for manual operation, for card-feed path handling, and reader status and checking circuits.

If used for a card reader attached to the channel, this microdiagnostic tests much of the logic necessary for a CSL operation from a card reader attached through the channel.

For systems having neither 2311 Attachment or Integrated 2540, a resident microdiagnostic is provided to test the channel circuitry. Due to these restrictions, only a low percentage of the systems will have this resident program.

Nonresident, Nonmonitor-Oriented Microdiagnostics

- *100
The nonresident CPU microdiagnostic is intended to provide extensive coverage and high failing-card resolution for the basic CPU logic. It provides expanded detection and failing-card resolution as compared to the resident CPU microdiagnostic. It also contains the resident microdiagnostics for the 2540 and the channel.
- *110
The nonresident 1052 microdiagnostic comprises two parts: the attachment-circuitry routines, and the device exercising routines. This microdiagnostic ensures that the 1052 is capable of performing the I/O functions required by the microdiagnostic monitor.
- *130
The nonresident memory microdiagnostic is designed for use if a CPU has two storage modules under the failure conditions described in the following.

The nonresident CPU microdiagnostic routines provide a complete, high-resolution test of basic CPU logic hardware. The routines are normally executed as the second logical step (after BDIA and checksum routines) of the primary diagnostic strategy. They can also be executed before and after any EC activity to verify CPU operation.

All systems will be shipped with the *100 residing in control storage. Once the basic CPU has been tested, the CSL device (Integrated 2540 or any reader attached to the channel) may be tested by using the resident diagnostic.

The nonresident CPU microdiagnostic can be loaded from cards, tape, or disk, using the CSL procedure for the appropriate input device. The routines are then executed automatically in a given sequence. If these tests are already loaded, the system-reset key initiates execution of the routines in the correct sequence. The system stops after the last test.

These routines should be loaded and executed (although this is not significant) before attempting to run the 1052 diagnostics or any of the tests executed under the microdiagnostic monitor. The nonresident CPU microdiagnostic is executed at computer speed and gives maximum assurance that the basic CPU data paths are error free.

Any errors encountered (such as a stop word or a branch-test stop) are indicated on the system control panel. If an error is detected, the CE checks the fault-location list of possible failing-card locations for this error indication. Some of the functions tested are:

- Access and branch facilities
- Basic ALU
- Arithmetic modifier

Diagnostic register
Status register set and reset
Local storage Y-axis line-address decode and read/write controls
Local storage controls and cycle-control (storage word)
Local storage X-axis line-address decode and set/reset
Local storage addressing and data storage
System mask register
ALU-check circuits
Comprehensive arithmetic facilities
Storage word
Priority Control
Trap priority.

The 1052 microdiagnostic program is a standalone program designed to test the console printer and attachment circuits. An error causes a microprogram stop. Error messages are contained following the stop-word location in the microprogram listings. If the CE performs the suggested repair procedure and the same error occurs again, the scope loop facility allows a tight loop on the error. Logic page references are included in the second error-stop error messages. This test is usually placed in the card reader hopper with the nonresident nonmonitor-controlled CPU microdiagnostic. It is then normally executed as the next test after the CPU microdiagnostic has been completed without error. The nonresident 1052 microdiagnostic can also be loaded separately and run separately from the CPU nonresident microdiagnostic. This is useful for verifying correct operation after making mechanical adjustments in the console printer.

The first part of the test is concerned with the attachment and control circuitry, because confidence in the control circuit must be established before the mechanical units can be checked. Some of the functions tested are:

TU- and TT-registers (basic operation and status storage)
System reset
Basic interface control
Upper case and lower case character decode circuits
Space, carrier return, and end of line, when applicable

The following message is printed on the 1052 when the first part of the test is completed.

```
1==1 0123456789 WRITE. FOR 12.5 INCH
PLATEN DEPRESS START KEY. FOR 13 1/8
PLATEN AND EOL TEST DEP REQ THEN START
KEY-1234567
```

```
ROUTINES TYA1, TYA2, TYDB, TYDC, HAVE
BEEN COMPLETED WITHOUT AN ERROR.
```

```
TO RUN ROUTINES TYDD AND TYDE WHICH WILL
REQUIRE MANUAL INTERVENTION DEPRESS
START THEN THE REQUEST KEY, AND FOLLOW
INSTRUCTIONS AT EACH STOP WORD. STOP
WORD ADDRESS IS ADDRESS IN CONSOLE
LIGHTS MINUS 2.
```

```
*** NOTE ***TO BYPASS MANUAL ROUTINES
DEPRESS THE LOAD KEY. THIS
WILL CSL MICRO MONITOR IF AVAILABLE.
```

With confidence established in the control circuitry, the second part of the microdiagnostic is started. This part includes manual intervention routines, and checks for correct printing from the keyboard as well as the set and reset of the various external facilities. Also included are facilities for adjusting singleshots, for continuous printing of a selected character, and for unlocking the keyboard to allow characters to be typed. The latter function facilitates mechanical adjustments. During this second part of the test, instructions in the MAS listing provide direction to the CE.

The nonresident memory microdiagnostic is provided for systems with two storage modules to isolate hardware failures within a module. It is intended for use when a memory failure is occurring in only one of the modules. The microdiagnostic isolates SLT failures to a failing card and array failures to the defective section of the array.

The microdiagnostic loads various bit patterns into the failing storage module, reads the data back out and retains the addresses of failing locations. The failing addresses are then analyzed and a decision is made as to the card location of the failing component. The card location is then indicated via a 1052 printout. If a card location can not be determined, a message is printed describing the problem causing the failure.

Loading of this microdiagnostic is restricted to the Integrated 2540 or a channel reader. Output messages are printed on the 1052 Printer. A special set of bootstrap cards is required for loading *130; these are provided with the system.

Nonresident, Monitor-Oriented Microdiagnostics

The descriptions in the following sections are used to test for, and diagnose, failures associated with the various input/output attachment features (except 1052) the I/O channel, and certain CPU features. The microdiagnostic monitor (*1C0) provides the capability for loading microdiagnostic sections,

printing messages required by the sections and the monitor, handling all interrupts, handling all traps, looping of a section, and looping of a routine within a section.

The low-half of control storage (addresses 0000 to 1FFE) is reserved for the monitor. The section to be executed is loaded into the high-half of control storage (addresses 2000 to 3FFE).

The micromonitor should be configured for the individual system by adding a maximum of two cards to the monitor deck immediately preceding the end card. For detailed information, refer to routine WW8A in the micromonitor (*1C0) microlisting.

(1) CPU FEATURES (*200)

The CPU features microdiagnostic operates under monitor control to provide a comprehensive check of hardware and logic peculiar to Storage Protection and/or Interval Timer; optional features on the 2025.

The first part of the section is comprised of routines designed to provide resolution for Storage Protection. Some of the functions performed are:

Setting and resetting of the associated registers (Q, FQ, GQ, HQ).

Verification that the data paths between the registers and CPU are operational.

Writing and reading capabilities of the 64-byte monolithic local storage memory. This routine also permits scoping of local storage timings.

Parity checking of the monolithic stack and verification of the parity checking circuitry.

Interaction test of the monolithic stack.

A check of each tag and key position by first setting 00 and then FF in each position.

Capability to detect key and tag mismatch or a bad parity tag in file mode.

The second part of the CPU features section is designed to check logic and hardware (T register triggers and latches, etc.) associated with the Interval Timer. Error and fault locating messages are printed on the 1052 under monitor control for both parts of the CPU feature microdiagnostic.

(2) INTEGRATED 2311 ATTACHMENT MICRODIAGNOSTIC (*300, *310, *320)

This microdiagnostic program operates in the microdiagnostic monitor environment to exercise and test the Integrated 2311 Attachment circuits.

Initially, the diagnostic mode is turned on in the attachment circuitry.

The purpose of this is to prevent any activity in the 2311 itself, and then to allow the attachment circuitry to be tested without the 2311. This permits a thorough evaluation of the attachment circuits without manipulating any actual data on the 2311. A failure in any basic test causes a branch to the error check and message subroutine which provides the general housekeeping needed (within the Integrated 2311 attachment microdiagnostics), such as control of the looping facilities, routing the program to the proper error messages, and interface with the microdiagnostic monitor. The microdiagnostic monitor contains the necessary CPU general housekeeping routines, as well as the console printer-keyboard subroutine so the error messages can be printed.

The basic function tests progress from the simpler hardware functions to more complex overall functions. The test sequence is as follows:

- A general hardware reset test for some of the attachment circuits.
- Op-register and op-register decode.
- Bit ring advance via write phase A and read clock simulation. Both checked for write clock gate and read gate.
- Exercise the compare logic, cyclic code register and associated circuits and read buffer and write buffer shift circuits. Sync detect character and sync detect along with bit ring inhibit is checked.
- A read home address and R0 operation are simulated.
- Flag bits 6 and 7 and track condition are checked.
- A write home address command, write R0 command, a write-count, key and data command are simulated. The write count key data command simulates through write address mark time because after this point the operation is the same as the write R0 command.
- The 1400 circuits are tested if the option is on the file control. See the micromonitor sense switches for definition of Integrated 2311 1400 hardware.
- The data check, data check in count, and track overrun are checked.
- A search equal home address operation is simulated.
- Wrong length record and CCW count 0 circuits are checked.
- Some of the file trap gate, trap conditions, clock through key and data, data overrun, and head compare are checked.
- A search equal count command is simulated.

A routine is provided to aid in adjusting some of the file control singleshots. Routine 06 (X06A) of *300 contains instructions for the adjustment procedure. This routine is normally not run unless the appropriate section sense switch is on. The singleshots that can be adjusted via this routine are:

1. Head condition
2. 400 ns index and delta 400 ns index
3. Control tag
4. Upper and lower 16 ms singleshots for recalibrate timeout.

**(3) INTEGRATED 1403 ATTACHMENT MICRODIAGNOSTIC
(*400, *410, *420)**

The printer attachment microdiagnostic exercises and tests the 1403 attachment and control circuits. The test is designed to check the hardware logic used for printing and performing carriage operations. Mechanical functions are also exercised.

The microdiagnostic program consists of three groups of routines:

The first two groups include the dynamic, non-printing, fault-locating tests. The CE transfers the current limit switch (a CE aid) so printing is suspended. This prevents the possibility of print magnet coil damage due to an existing defect. These groups check all the basic attachment and control circuits such as status generation, timing circuits, buffer and buffer control, PCC and subscan control, and checking circuits.

The third group of routines is executed for a more rigorous exercising of the mechanical and electronic units. In these routines, printing and carriage operations are allowed to occur to exercise all printer functions. This group includes carriage exercising routines and a print routine.

The error message scheme for these routines consists of basic error information printed via the 1052, with reference to the microlisting for more extensive fault locating and troubleshooting messages. In some cases, oscilloscope sync point information is included in the error messages to facilitate trouble analysis with an oscilloscope.

**(4) INTEGRATED 2540 CARD READ PUNCH MICRODIAGNOSTIC
(*500, *510)**

The 2540 microdiagnostic operates under control of the microdiagnostic monitor to perform comprehensive tests of logic circuitry for the Integrated 2540 attachment as well as much of the device circuitry. The first part of the test (*500) includes various dynamic routines designed to exercise and test control and attachment circuits at computer speed. This allows a rapid checkout of the majority of reader-punch circuits. Some of the functions tested are:

Basic data flow and branch registers (RS, DS, RPS, RPD1, RPD2, RP1, and RP2)

Circuitry for manual operations and card feed path handling

Status and error-checking circuits

Basic data handling ability of attachment (includes shift and address registers for all cycles for both reading and punching).

The second part of the test (*510) includes routines that exercise the mechanical functions as well as the attachment and control circuits. This part of the test identifies brush failures by row and column. Punch feed read is also exercised. Also, card punch data-oriented problems are detected and identified.

(5) SYSTEM/360 CHANNEL MICRODIAGNOSTIC (*600)

This microdiagnostic program is executed in the monitor environment to test the System/360 channel. These routines are designed to test the channel circuitry to ensure that it can generate and respond to all standard I/O interface signals. Failures cause a branch to the microdiagnostic monitor for error message printout and looping facilities:

The first routine tests that all channel registers (GD, GS, GI and GT) can be reset correctly. The microlisting describes the correct reset of these latches, and includes a summary of the register position functions. Also tested are the channel diagnostic latch for correct set and reset, the CPU-to-external line for correct function, and the channel mode circuit for correct operation.

The second routine checks the bus-out and bus-in lines (all bits), and the tags-in lines (request-in, operational-in, status-in, service-in, select-in, and address-in).

The third routine checks the tags-out latches for correct set and reset. This includes the operational-out, the select-out, the service-out, the command-out, and the address-out latches. This routine simulates failure conditions that could erroneously raise a tags-out line to determine correct circuit operation.

The fourth routine checks for correct operation of the service-in and status-in circuits. The microdiagnostic program checks that these lines fall in correct response to the service-out and command-out lines being raised. In addition, the correct operation of the channel 1 interrupt latch is determined.

The fifth routine checks the suppress-out data chain, channel ID, and buffered-device latches for correct operation. Direct set and reset responses are checked, as well as the function of these latches in response to other circuit functions.

The sixth routine checks the burst latch, the initial selection latch, and the low and high priority trap circuits. Correct trap requests are simulated and the circuit responses checked. An incorrect trap request causes a branch to the monitor so an error message can be printed.

The seventh routine checks for correct function of the channel parity circuits.

Additional routines are provided to facilitate diagnosing interface and I/O device failures. These include:

a) Check Sel-Out wrap around to Sel-In.

- b) ADDRESS response test
- c) TEST I/O, complete initial selection of all possible device addresses.
- d) Single cycle routine - command to a particular address and looping capabilities

**(6) INTEGRATED COMMUNICATIONS ATTACHMENT
MICRODIAGNOSTICS (*700, *710, *720, *730)**

*700 This microdiagnostic operates under control of the microdiagnostic monitor to test extensively the ICA base hardware. The test performs microprogram trapping, line adapter addressing, and extensive checkout of the CPU to ICA interface.

*710 This microdiagnostic operates under control of the microdiagnostic monitor to test the start/stop EIA and telegraph line adapters. The test performs an extensive checkout of line adapter addressing and trapping. Transmit and receive trapping and clocking are checked on all adapters.

*720 This microdiagnostic operates under control of the microdiagnostic monitor to test the binary synchronous line adapter. Some of the functions tested are the 1- and 3-second time delays, TRCR ring controls, transmit and receive, A-serdes and B-serdes register advancing, SYN character encode and decode, and SYN character count insert.

*730 This microdiagnostic operates under control of the microdiagnostic monitor to test the automatic calling feature. The diagnostic checks to determine that the external autocall unit has power on. If it has power on, an extensive checkout of the base ICA to autocall feature interface is performed.

The ICA microdiagnostics require a line adapter definition table that is stored in program storage location starting at 25C0. The format of the LDT table is explained in detail in routine ZA01, which is contained in coreloads *700, *710, *720, and *730.

(7) INTEGRATED 2560 MICRODIAGNOSTIC (*800, *810, *820)

This microdiagnostic is provided with the Model 20 Mode feature when a 2560 MFCM is included in the configuration. It is executed under monitor control and tests the 2560 attachment logic in the 2025 without exercising the 2560.

The first part of the test, *800 and *810, includes various dynamic routines that exercise the attachment circuits at computer speed. The routines use print latches, diagnostic hardware, and an internal diagnostic configuration to allow a rapid checkout of the majority of the attachment circuits.

Some of the functions tested are feed CB lines, motor ready, data buffer read controls, and data buffer punch controls. Read compare is checked by forcing read checks.

Other tests check the data buffer by exercising various punchbit combinations with external bus-out bits. Punch compare is tested by forcing read checks.

Feed cell inputs are checked by exercising punch feed select lines. Secondary select controls, feed cell dark latches, punch push controls, feed check latches, and attachment controls are also tested.

If the print feature is installed, the print control circuitry is tested. The print feature tests are bypassed automatically if the feature is not installed.

Singleshot adjustment routines, motor ready time delay testing, and manual intervention routines are included in *820.

Generally, the four sections should be executed sequentially although the capability exists under monitor for separate execution.

(8) INTEGRATED 2560 ICR MICRODIAGNOSTICS (*E90)

This is a nonmonitor microdiagnostic that provides 2560 tests corresponding to the following System/360 Model 20 ICR tests:

- Speed calibration
- Feed CB's and feed clutch
- Magnet control and feed CB flip latches - primary
- Magnet control and feed CB flip latches - secondary
- Primary feed (print and non-print)
- Secondary feed (print and non-print)
- Feed flip latches (print and non-print feature)
- Punch pusher - primary
- Punch pusher - secondary
- Punch and print CB's (modified for geneva drive machines)
- Feed check diagnostic - Note 1

The above routines check for proper operation of the 2560 by measuring timing impulses and comparing them against a tolerance table. Test results are printed out on the 1403 printer with provisions for printing out on the 1052 printer keyboard when the 1403 is not available.

Note 1: This is macro test ICR125 run under *E90 diagnostic coreload. It includes the cycle delay feature.

CARD-FAULT LOCATION

All of the microdiagnostic programs are designed to find a failing card by cross-referencing an address to a listing of suspect card locations. This listing is provided as a separate document for resident and nonresident nonmonitor-controlled programs. For monitor-controlled microdiagnostics, the suspect card location or locations are printed on the 1052 console printer for each error. However, the integrity of the card-fault-location information can be assured only if:

1. All microdiagnostics are executed in the sequence shown in the Diagnostic Strategy Diagrams
2. All parts of multiple part programs are executed in sequential order (example for 1403 Printer; *400 must be executed, followed by *410 and then *420).
3. The first error encountered is corrected before proceeding to subsequent routines or sections of the microdiagnostics.

As an assurance against inadvertent failures caused during a repair, it is considered good CE practice to re-execute all parts of multiple-part programs before the system is returned to the customer.

MICRODIAGNOSTIC PROGRAM AND HARDWARE CONCURRENCY

The resolution and fault-locating capabilities of the microdiagnostic programs can be assured only when they are concurrent to the system hardware. Therefore, it is considered good CE practice to verify the EC level of each program before execution.

ALD logic pages AA000 through AAnn provide the cross-reference information for each program and the associated system hardware. Refer the EC level of each program to these charts for each of the Diagnostic Program Package modes as follows:

1) Cards

EC level is punched in columns 36-41 of the first card of each section.

2) Tape or Disk

Nonmonitor-controlled sections (*100, *110, *1C0).

EC level (last four digits in hex form) is stored in control-storage location OECO.

Monitor-controlled sections.

EC level (last four digits in decimal form) is printed on the console printer as part of the operator message when each section is loaded (refer to Diag 1-1 P3 for example).

LOADING AND USING THE DIAGNOSTIC PROGRAM PACKAGE

Set the console switches ABCD as follows (switches A and B must be set the same):

Switches AB = CC CSL from channel
Switches AB = EE CSL from Integrated 2540
Switches AB = FF CSL from Integrated 2311
Switches AB = DD CSL from Integrated 2560
Switches CD = actual unit address (when using a device on the channel (AB=CC) for file (AB=FF))

a. DPP (Diagnostic Program Package) on cards

1. Place the microdiagnostic program decks in the reader in the following sequence:

Note: For bootstrap listing, refer to Vol. 1 of ALD's.

Bootstrap
Nonresident CPU
1052 Nonresident
Micro Monitor
Micro Monitor Sections

2. Use the Diagnostic Strategy Diagrams and execute the microdiagnostic programs in the sequence indicated; setup and execution instructions are provided on the diagrams.

Note: Once the monitor has been loaded, the 1052 prints system configuration information. When this printout is complete, set switches ABCD to 0000 and press the CPU Load button. This initiates loading the next section. When the next section is loaded, the card reader stops. Press SYSTEM RESET and START to execute the section. If the section executes without error, the console printer prints T and, if monitor sense switch 5 is on, the next section loads automatically. Refer to the procedure for using Monitor Sense Switches (Diag 1-1 P5). The next section can be loaded at any time by pressing STOP, setting switches ABCD to 0000, and pressing the CPU load key.

All microdiagnostic card decks have a core load index number punched in columns 73-76. The sequence number within the deck is punched in columns 77-80.

It is possible to load the entire microdiagnostic package sequentially. Refer to the Diagnostic Strategy Diagrams for specific instructions on how to perform a sequential microdiagnostic load and run.

When executing microdiagnostic program sections under monitor, it may be desirable to remove sections already executed and stacked in the 2540 or 2560, and to load additional sections. This can be implemented by setting console switches ABCD to FFFF and pressing the

console load key. Then follow the instructions printed on the console printer.

Note: The same message will print when the reader is out of cards and the load key is pressed with console switches ABCD set to 0000.

b. DPP on Magnetic Tape

1. File protect the DPP tape and mount on tape drive.
2. Set CPU Console switches CD to tape drive address.
3. Press CSL key to load the CPU Non-Resident Microprogram. Follow the test sequence in the strategy diagrams at the successful completion of the CPU nonresident microprogram, press START to load the 1052 microprogram.
4. At the successful completion of the 1052 NONRESIDENT MICROPROGRAM, press the load key to load the Monitor.
5. The following options are now available.
 - (a) Execute all sections in sequence as shown below:

*200 - CPU Features (Storage Protect & Interval Timer)
*300 - 2311 Part 1
*310 - 2311 Part 2
*320 - 2311 Part 3
*400 - 1403 Part 1
*410 - 1403 Part 2
*420 - 1403 Part 3
*500 - 2540 Part 1
*510 - 2540 Part 2
*600 - Channel
*800 - 2560 Part 1
*810 - 2560 Part 2
*820 - 2560 Part 3

Set the CPU console switches ABCD to 0000. Press CPU load key. The first program will load and this message will be S(XXXX) where XXXX is the program number; 0200 STOR PROT DIAG

Press START to execute the program. (At the successful execution of the program, the console printer will print a T and the next program will load automatically if monitor sense switch 5 is on.)

The preceding sequence is repeated through all programs.

- (b) Execute selected programs in (a). Set the CPU console switches ABCD to 0XXX, where XXX is the number of the program; 300, 310, 400, 500 and 600. Press the CPU load key. The program will load and the message as in (a) above will be printed. Press the start key to execute the program.

Note: Read backward operations are not possible with 7-track tape, therefore rewind to the load point. Set switches ABCD to 0100 and rewind tape. Press start key to execute the program.

- (c) Load System/360 Emulator
Set the CPU console switches ABCD to 0E60. Press the CPU load key; then load the customer program.
- (d) Load System/360 Model 20 Emulator
Set the CPU console switches ABCD to 0E20. Press the CPU load key; then load the customer program.

c. DPP on the 2311 Disk File

1. Mount the disk pack on the 2311 disk drive.
2. Set CPU console switches CD to the 2311 disk drive address.
3. Repeat instructions 3 through 5 under DPP on Magnetic Tape.

Monitor Sense Switches

To set any of the monitor sense switches (excepting 8 or 9, see note 1), place the CPU into process mode and press the alter/display key. Enter SC X,X,X, X,X,X,.....on the 1052 printer Keyboard, where X is the representative character on the keyboard to cause setting of the corresponding sense switch. The keys identifying the sense switches may be pressed in any order. Press the EOB key on the 1052 at the end of the SC message entry. Press the start key on the CPU to get out of alter/display function.

To reset any of the microdiagnostic monitor sense switches, place the CPU into process mode and press the alter/display key. Enter RC X,X,X,X,on the 1052 printer Keyboard, where each X represents the corresponding sense switch. The keys identifying the sense switches may be pressed in any order. Press the EOB key on the 1052 at the end of the RC message entry. Press the start key on the CPU to get out of the alter/display function.

Following is a summary of the microdiagnostic monitor sense switch positions and their meanings. All switches are off following a monitor load, monitor initialize function, or if reset by a reset instruction. Pressing SYSTEM RESET, or loading a new section does not affect the setting of the monitor sense switches. The monitor sense switches are located at control storage address 03BE.

Monitor Sense Switch No.	State	Meaning
0	Off	Normal mode
	On	Suppress all messages
1	Off	Normal mode
	On	Print only error messages
2	Off	Halt on error
	On	Continue after error
3	Off	Normal mode
	On	Print only section 1D, routine number, and BAL address
4	Off	Print full error message
	On	Print only * on error message
5 (See Note 1)	Off	Manual Mode All routines are initiated. Monitor halts after loading each section. Monitor halts after executing each section. (If start button is pressed, section is executed again.) Sections halt after issuing setup instructions (See Note 1).
	On	Dynamic Mode Sections are loaded and executed sequentially under monitor control. Tests requiring manual intervention (*420 - routine 70, *510 - all routines, *600 - routine 11) are not run. Sections do not halt after issuing setup instructions (See Note 1).
7	Off	Normal Mode
	On	80-80 card to tape from card reader used to load monitor to tape address XX (hex) specified in auxiliary storage 008D. Set switches ABCD to FFFF, press LOAD and the 1052 prints a message to load the card reader.
8 } 9 }	Off	Normal mode
	On	Loop section
6,A,B,C,D,E,F	Off	Normal mode
	On	Loop routine
		Not used

Note 1: The setup necessary is as follows: Interval Timer Test: Toggle switch on. Printer tests: CE carriage tape on, T-casting closed, no forms check, 6-line neutral, and current limit switch in limit position.

Note 2: Monitor Sense Switches 8 or 9 should not be set on by using alter/display or erroneous looping can result. These switches must be set as described under the following headings:
Section Sense Switches
Select and Loop a Routine

Section Sense Switches

The section sense switches do not have fixed meanings, but instead the meanings are defined according to section need. If these switches require manual setup, the console printer will print the sense switch definition for this section.

To set any of the section sense switches, place the CPU in process mode and press the alter/display key. Enter SS X,X,X,X,.....on the 1052, where X is the representative character on the keyboard to cause setting the corresponding sense switch. Press the EOB key on the 1052 at the end of the SS message entry. Press START on the CPU to get out of the alter/display function.

To reset any of the section sense switches, place the CPU in process mode and press the alter/display key. Enter RS X,X,X,X,.....on the 1052 printer Keyboard where X is the representative character on the keyboard to cause setting the corresponding sense switch. Press the EOB key on the 1052 at the end of the RS message entry. Press CPU start key to get out of alter/display function.

Alter/Display Function

The alter/display function works the same as that on the System/360 Emulator. Press start key once to get out of the alter/display mode when finished.

System Reset-Start

Once a microdiagnostic section is loaded, press the system reset key and then the start key on the CPU console to initiate execution of the section from its starting point.

Select and Loop a Routine

This method of initiating the loop routine function sets microdiagnostic monitor sense switch 9 on automatically, and also allows selection of the routine to be looped. Dial 01XX into the CPU ABCD switches, where XX is the routine number to be looped. Press SET IC and the message "Looping Routine XX" will be printed on the 1052. Press START on the CPU to start the looping function.

To exit a loop routine, press STOP on the CPU. To progress to subsequent routines, reset monitor sense switch 9 as previously described. To select another routine looping, dial another routine number and press SET IC and START as before.

Select and Loop a Section

The capability is provided under monitor, to loop a selected section of the microdiagnostic programs (*300, *310, *320, *400, *410, *420, *500, *600) by setting monitor sense switch 8 on as follows:

1. Set console switches ABCD to 01FF (after the section has been loaded, with monitor sense switch 5 off, or after an error stop).
 2. Press SET IC.
- To exit from a looping section, press the stop key and set monitor sense switch 8 off.

Initialize Microdiagnostic Monitor Function

To initialize the microdiagnostic monitor, press the alter/display key and type an "I" on the 1052. This restores all microdiagnostic monitor sense switches to the normal state (all off).

Microdiagnostic Monitor Message Codes

The messages printed by the 1052 are identified by a code that prints to the left of the message. These are defined as follows:

- * = Section error message
- \$ = Monitor operator message (for your information)
- / = Operator procedural error
- or < = Unanticipated trap

When the microdiagnostic monitor has been loaded, the 1052 prints out an operator message that identifies the features present on this particular system. The 1052 prints a list of features and identifies with a 'Y' those features included with this system, and with an 'N' those features not included with the system. Following are sample messages printed by the 1052.

```

$ MONITOR SYSTEM FEAT EVALUATION
*-MONITOR ASSUMPTION

2581 4 MEM-48K
2582 Y STGPROT
2583 Y TIMER
2584*Y 60 CYCLE
2590 Y NTV 2540
2591*Y PFR
2592*N 51 COL
2593*N 1400
2595 Y NTV 2311
2596*N 1400
259A Y NTV 1403
259B*2 MOD 2
259C*N MCS
25A4 Y CHNL
25A9 Y NTV 2560
25AE Y NTV COMM

TO ALTER SYSTEM CONFIG MODIFY
ASSOCIATED FLAG BYTES IN PROG STOR.
REFER TO WW8A IN MAS LISTING FOR
INSTRUCTIONS
NTV COMM CONFIG INFORMATION IS
CONTAINED IN PROG STOR BEGINNING AT
25C0

Message at completion of microdiagnostic
Monitor CSL with system configuration not defined by input card.

```

\$ MOD 25 SYSTEM CONFIGURATION

2581 3 MEM-32K
 2582 Y STGPROT
 2583 Y TIMER
 2584 Y GO CYCLE
 2590 Y NTV 2540
 2591 Y PFR
 2592 N 51 COL
 2593 N 1400
 2595 Y NTV 2311
 2596 N 1400
 259A Y NTV 1403
 259B 2 MOD 2
 259C N MCS
 25A4 Y CHNL
 25A9 Y NTV 2560
 25AE Y NTV COMM

TO ALTER SYSTEM CONFIG MODIFY ASSOCIATED
 FLAG BYTES IN PROG STOR. REFER TO WW8A IN MAS
 LISTING FOR INSTRUCTIONS
 NTV COMM CONFIG INFORMATION IS CONTAINED
 IN PROG STOR BEGINNING AT 2500

Message at completion of microdiagnostic.
 Monitor CSL with system configuration defined by input card.

S 0600 CHANNEL DIAG

Operator message at start of each section.

S
 0200 20 25F8
 TURN INTERVAL TIMER SWITCH TO ON AND DEPRESS
 START BUTTON. WHEN DIAGNOSTIC IS COMPLETE TURN
 INTERVAL TIMER SWITCH TO OFF. THIS IS A ONE
 TIME MESSAGE.
 T

/ DO NOT HIT START-ROUTINE NOT IN SECTION

/ INV A,B SWITCHES

\$ TO LOOP ROUTINE 03 PRESS CPU START

\$ TO LOOP ROUTINE 05 PRESS CPU START

\$ TO LOOP SECTION PRESS CPU START

\$ TO LOAD NEW SECTION FROM NATIVE 2540,
 DO NPRO AND MAKE READY WITH ADDITIONAL
 SECTION(S).

General operator messages.

Section and routine
 number.

(Refer to microlisting)

Failing address

* 0600 03 2C9C

AE1G4	3016
AD1H2	4070
AE1J6	0006
AE1L2	1835

Last four digits of card
 part number.
 If 7xxx refer to ALD
 card plug chart for
 card part number

Gate, panel and card socket
 of suspect card/cards.

Message for failure under Monitor.

Valid CSL and check sum

8229 0E60 4C14 0000

Check sum value in
 control storage
 (cs 0002 for E060)

Emulator(360) core load

E C level of core load

Invalid CSL and check sum

(Indicator on CPU turned on)

8229 0E60 0C14 0000
 8229 0E60 0C14 4000

Second line
 prints only if
 C. E. key is on.

Result of Exclusive OR
 function.

Creating the Diagnostic Program Package

The entire DPP is shipped in card form for all System/360 Model 25 systems. However, execution of the DPP can be enhanced by using the disk file or magnetic tape capability where the system configuration permits. These mediums not only simplify loading of microdiagnostic programs and the System/360 emulator but also expand their effectiveness by providing an alternate means of CSL.

During installation of the system, the card decks should be transcribed to disk or tape (obtained locally) as follows:

a. Disk DPP

Use FOFE (Revision level 3) to convert the DPP card file to the CE Disk Pack (Both MACROS and MICROS). Refer to FOFE Users Guide.

Note 1: If the CE disk pack to be used was built with a previous level of FOFE, it must be rebuilt completely.

Note 2: The diagnostic microcode chains from the file bootstrap to *100 to *110 to the micromonitor. All four must be on the CE pack.

Note 3: If it is necessary to put two emulators (or diagnostics) on the CE disk pack having the same I.D. (i.e., *E60), this can be accomplished by changing columns 75 and 76 of the first card of one of the decks to another hex value (i.e., *E61).

Note 4: Do not include *130 (Memory Diagnostic) or *E90 (2560 ICRs) in either the Disk DPP or the Tape DPP.

Note 5: Prior to building a DPP on a disk pack, program FFF0 must be run against that disk pack.

b. Magnetic Tape DPP

Either DEBE (if available) or the 80-80 card to tape function of the micromonitor (*1C0) should be used to create the DPP tape from the card decks. The System/360 Model 25 macrodiagnostics can be placed on another tape by the standard procedure used for generating a diagnostic tape.

Example: FOFF as defined in FOFF description in the maintenance diagnostic programs manual for tapes, Vol. 01.

The procedure for using DEBE is as follows.

1. Mount reel of tape (obtain locally) and make drive ready.
2. Load the decks in the card reader in the following sequence.

DEBE or *1C0
Channel Bootstrap Card
*100 CPU Nonresident
*110 - 1052 Nonresident
*1C0 - Diagnostic Monitor
*200 - Storage Protect
*300 - 2311 Part 1
*310 - 2311 Part 2
*320 - 2311 Part 3
*400 - 1403 Part 1
*410 - 1403 Part 2
*420 - 1403 Part 3
*500 - 2540 Part 1
*510 - 2540 Part 2
*600 - Channel
*800 - 2560 Part 1
*810 - 2560 Part 2
*820 - 2560 Part 3
Channel Bootstrap Card
*E60 - System/360
Channel Bootstrap Card
*E20 - System/360 Model 20

3. Make reader ready; press END OF FILE
4. Select reader address on CPU console.
5. Press CPU load key.

The reader will stop about midway through DEBE. At this point press the interrupt key to complete loading DEBE.

6. The console printer will then print this message:

ENT PROG ID - XX

Enter CT EOB from console printer keyboard.

7. This message will then be printed:

ENT ADDR OF OUTPT TAPE - MMAAA

Enter tape drive address EOB
Example 00181

8. At completion of card to tape operation, identify the reel of magnetic tape as the DPP.

The procedure for using the 80-80 card to tape function of the micromonitor is as follows.

1. CSL the micromonitor (*1C0)
2. Set monitor sense switch 7 and store the tape address in auxiliary storage 008D.

Example: (Tape Address = 80)

- a) Press the alter/display key.
- b) Enter from the 1052, SC7 EOB.
- c) Enter from the 1052, AA 008D 80 EOB.

3. Set FFFF in the console switches and press CPU load key.
4. A message will be printed on the console printer describing the action to be taken.

\$ TO LOAD NEW SECTION FROM NATIVE 2540.

Example: DO NPRO AND MAKE READY WITH ADDITIONAL SECTION(S). EOF ON.

5. NPRO the reader used initially to load the micromonitor.
6. Load the decks in the card reader. The sequence of cards is the same as described in step 2 under the DEBE procedure with the exception of the DEBE deck.
7. Make reader ready; press END OF FILE.
8. Column 36 through 80 of the first card of each microprogram deck will be printed on the console printer as that card is written on tape. This printout can be retained as a record of the contents of the tape.

Example: 128500 DIAG---BASIC CPU OECO*1000-01

9. When the card-to-tape operation is complete, the same message as in step 4 will be printed on the console printer.
10. Identify the reel of magnetic tape as the DPP.

Note: If an I/O error is encountered with DEBE or the 80-80 card to tape micromonitor function, the error will be indicated via a 1052 console printout. The respective procedure for generating the DPP tape must be restarted at its beginning.

Macrodiagnostics

The following macrodiagnostics are included in the System/360 Model 25 field maintenance package. Descriptions and listings are provided in volume 40 of the logic binders. Those released previously and in common use on other systems are indicated by an asterisk (*). Descriptions are not provided for diagnostics released previously.

MONITOR

- *1. DMA4 - 3020
- *2. Message Editor - 310A
3. Expansion section - E10B

This allows DMA4 to adjust itself and become more flexible if core storage is available. The areas of increased capabilities are:

- a. The number of UDT entries is expanded from 28 to 100.
- b. A typewriter input language compatible with DMA8 has been incorporated.
- c. System configuration can be set up by English language statements in TXT cards.
- d. UDT table can be set up via DMA4 or DMA8 UDT cards.
- e. Diagnostic information is available via console printer.

The expansion section adjusts itself with DMA4 according to the following rules:

- a. The expansion section is aborted if the proper level of DMA4 is not loaded.
- b. Typewriter input is activated only on systems having DM input device identified as a 90.
- c. The expansion routines are placed in 3000 - 3FFF on 16K systems not having the DM editor (310A) loaded.
- d. On 16K systems having the editor loaded, an option is given to the user to maintain the editor and abort the expansion section or vice versa.
- e. The expansion section and tables will be located in 4000 to 4FFF (thus preserving the DM editor if it is loaded) on systems greater than 16K. New diagnostic sections have been released for the integrated attached I/O device. These sections require unique UDT entries:

1043 Printer	8F
2311 File	67
2540 Reader/Punch	8B

The program listing for DMA4 expansion provides explanation of the status messages, instructions to operator, etc., that are pertinent to the section.

***EXTERNAL INTERRUPT/DIRECT CONTROL - 34E1**

2311 Microdiagnostics

- C675 File Function
- C676 File Function
- C677 File Function
- C678 File Function
- C679 File Function
- C67A File Function
- C67B File Scan
- C67C 2311 Diagnostic Test
- C67D 2311 Diagnostic Test

SYSTEM/360 MODEL 20 MODE (2560)

The following System/360 Model 20 MFT macrodiagnostics are available for execution in the System/360 Model 20 Mode to ascertain proper operation of the 2560 MFCM.

- MFT 2041 Ripple Read
- MFT 2042 Ripple Punch
- MFT 2043 Ripple Card Print
- MFT 2045 Ripple Read (Column binary)
- MFT 2061 Stacker Select
- MFT 2062 Print Head Select
- MFT 2072 I/O Short Program
- MFT 2073 Read Error Last Card
- MFT 2080 Speed Test
- MFT 2090 Read Adjustment

The following MFT test decks consist of data cards for use with the MFT tests indicated:

- MFT 2031 Ripple Data Cards (for MFT 2041)
- MFT 2032 Column Binary Data Cards (for MFT 2045)
- MFT 2033 Read Error Last Card Data Cards (for MFT 2073)
- MFT 2034 Read Adjustment Data Cards (for MFT 2090).

ICR 125 test deck is designed to run under *E90 microdiagnostic coreload.

**MFT2072 should be used only for 2560 problems. The least number of commands that will bring on a failure should be generated. A unique sequence of commands may be generated to simulate the I/O program conditions that are causing machine failure. Other devices (1403, 2501, 1442, etc.) may be operated simultaneously with the 2560, if needed, to develop the failure.

SYSTEM ENVIRONMENT TEST

The SYST-M30-B system environment test is used by the customer engineer to exercise and test the system. This program is designed to allow the customer engineer to operate the System/360 Model 25 in a manner similar to worst case customer operation. The vigorous random internal and I/O exercising done by the program assures that intermittent, timing sensitive, or program-oriented troubles will be detected. The results of this test are logged internally and are printed out automatically at frequent break points as well as being available at any time they are requested.

The I/O units that this test can exercise are 2540, 1403, 1442N1, 1443, 1050, 2400 series tape units, and 2311 files.

INTEGRATED COMMUNICATIONS ATTACHMENT

Physical Wrap Test

To run the macrodiagnostic physical wrap tests (C4F1, C4F2, C4F3, C4F4) a wrap connector (P/N 2543186) must be utilized.

This connector is to be installed on the I/O Gate (01E) in the location of the lines to be tested prior to loading the macrodiagnostics. Each connector has the capability to wrap two pairs of lines or just a single pair depending on the system configuration.

Note of Caution: This wrap connector *cannot* be used with a terminal control Type I telegraph board.

Macrodiagnostics

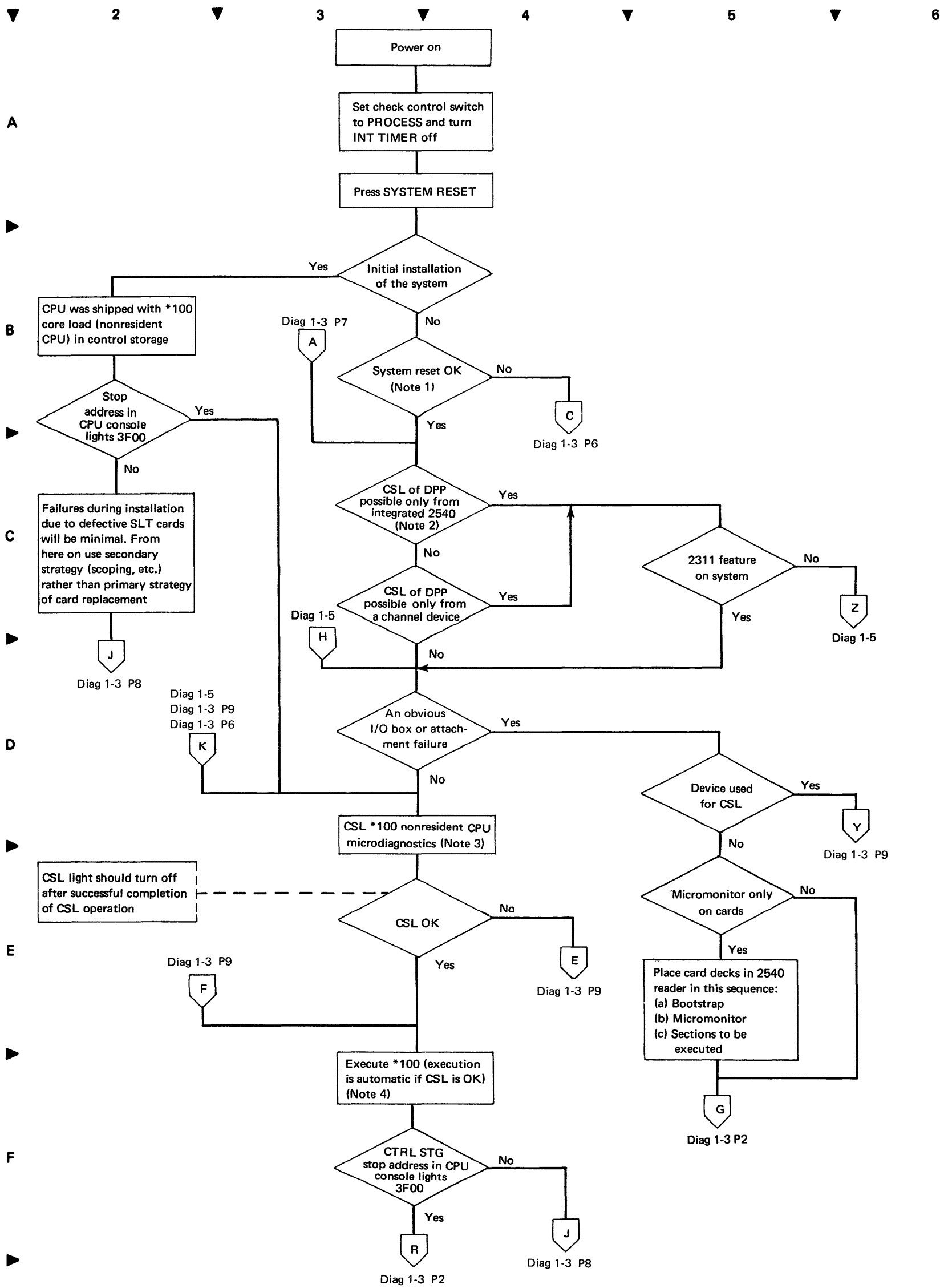
ID Number

- CBB0 Binary Synchronous Function
- CBB1 Binary Synchronous Function
- CBB2 Binary Synchronous Function
- CBB3 Binary Synchronous Function
- CBB4 Binary Synchronous Function
- CBB5 Binary Synchronous Function
- CBB6 Binary Synchronous Function
- CBB7 Binary Synchronous Function
- CBB8 Binary Synchronous Function
- CBB9 Binary Synchronous Function
- CBBA Binary Synchronous Function
- CBBB Binary Synchronous Function
- CBBC Binary Synchronous Multipoint Function

ED60 Binary Synchronous diagnostics can request test message from central BTAM control.

- CBE1 IBM 1 Line Adapter Test
- CBE2 IBM 1 Line Adapter Test
- CBE3 IBM 1 Line Adapter Test
- CBE4 IBM 1 Line Adapter Test
- CBE5 IBM 2 Line Adapter Test
- CBE6 IBM 2 Line Adapter Test
- CBE7 IBM 2 Line Adapter Test
- CBE8 TLG1 Line Adapter Test
- CBE9 TLG1 Line Adapter Test
- CBEA TTY Line Adapter Test
- CBEE Autodial Test

- C4EE Multicom Configurator
- C4EF Multicom 16K
- C4F0 Multicom 32K
- C4F1 IBM 1 Physical Wrap
- C4F2 IBM 2 Physical Wrap
- C4F3 TLG Physical Wrap
- C4F4 TTY Physical Wrap
- C4F5 1050 Terminal Exerciser
- C4F6 2740 Terminal Exerciser
- C4F7 1060 Terminal Exerciser
- C4F8 1030 Terminal Exerciser
- C4F9 TLG Terminal Exerciser
- C4FA TTY Terminal Exerciser
- C4FB 2780 Terminal Exerciser
- C4FC IBM 1 Autowrap
- C4FD IBM 2 Autowrap
- C4FE TLG Autowrap
- C4FF TTY Autowrap



Notes:

- (1) An OK system reset is indicated by all of the following.
- (a) No check lights
 - (b) Manual light off then on
 - (c) System light on then off
 - (d) CPU console lights for byte 0 is 00000000 and parity bit is off.
 - (e) No checksum error.

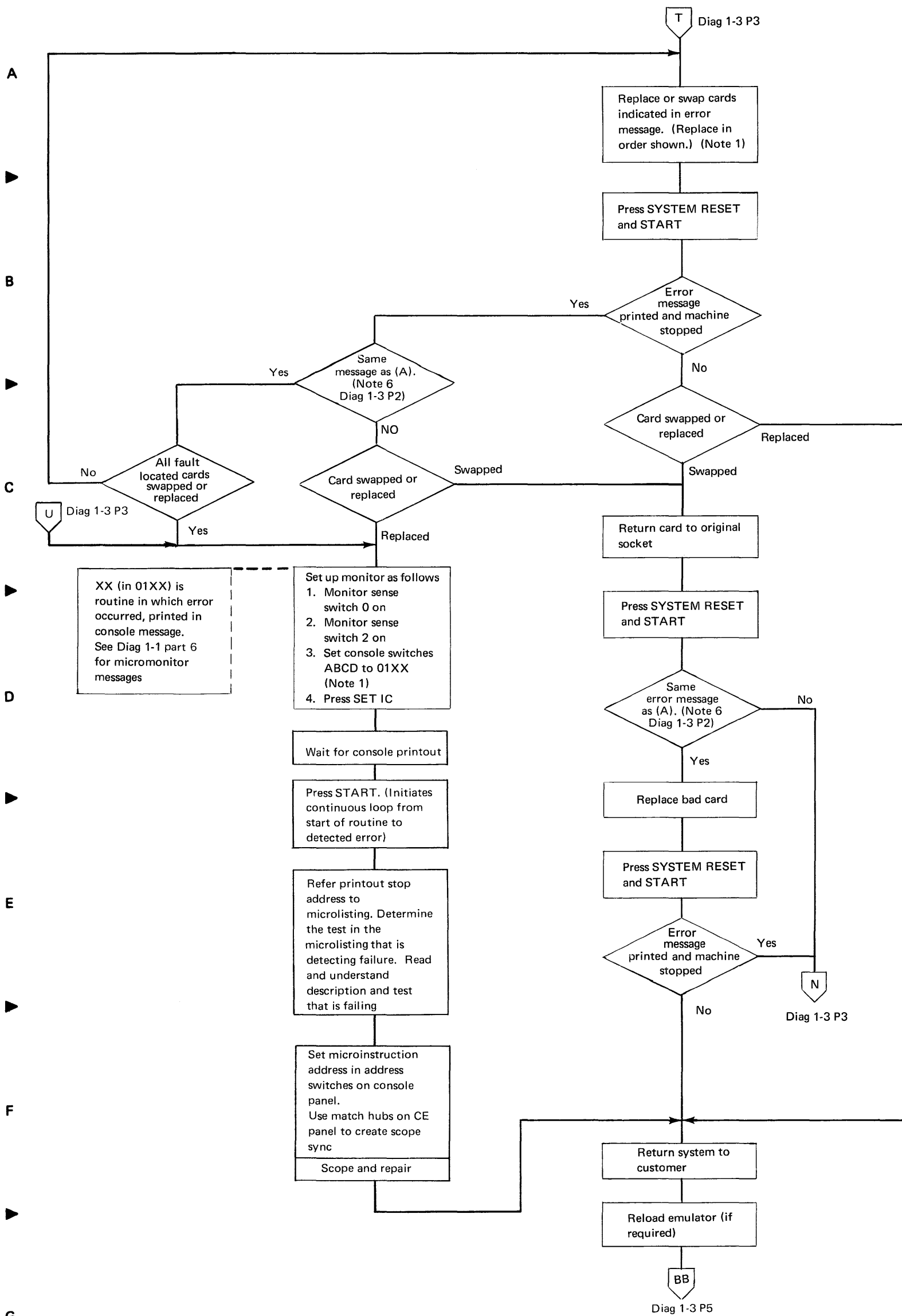
- (2) DPP (Diagnostic Program Package)
Where alternate input devices are available, the complete diagnostic program package should be kept in appropriate form to use these devices for CSL.
The recommended order for using the alternate CSL capability is:
- (a) Disk
 - (b) Tape
 - (c) Card

- (3) For CSL of nonresident microdiagnostics from cards, place decks in hopper of reader at this point, in sequence indicated:
- (a) Bootstrap
 - (b) Nonresident CPU
 - (c) 1052
 - (d) Micromonitor
 - (e) Section(s) to be executed.

- (4) *100 can be looped by setting console switches A,B to 00 and pressing SYSTEM RESET.

Diagram 1-3. Diagnosis Techniques Diagrams (Part 1 of 10)

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6



- Notes:
- (1) Use these guidelines with the card fault list:
- (a) If number of suspect cards is 12 or less, replace all cards in order shown.
 - (b) If number of suspect cards is more than 12, replace the first 12 in order shown, then go to secondary strategy.

A

B

C

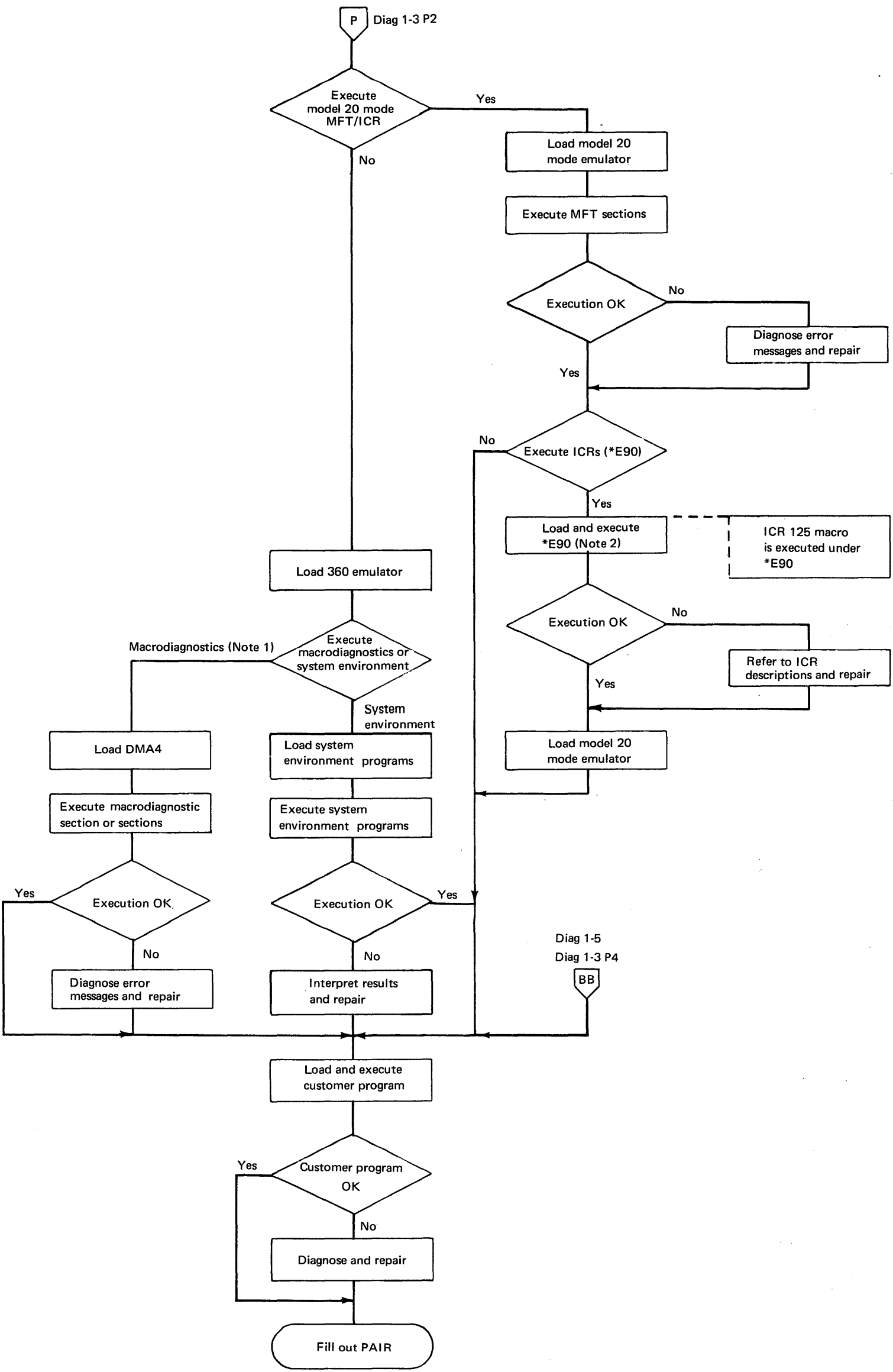
D

E

F

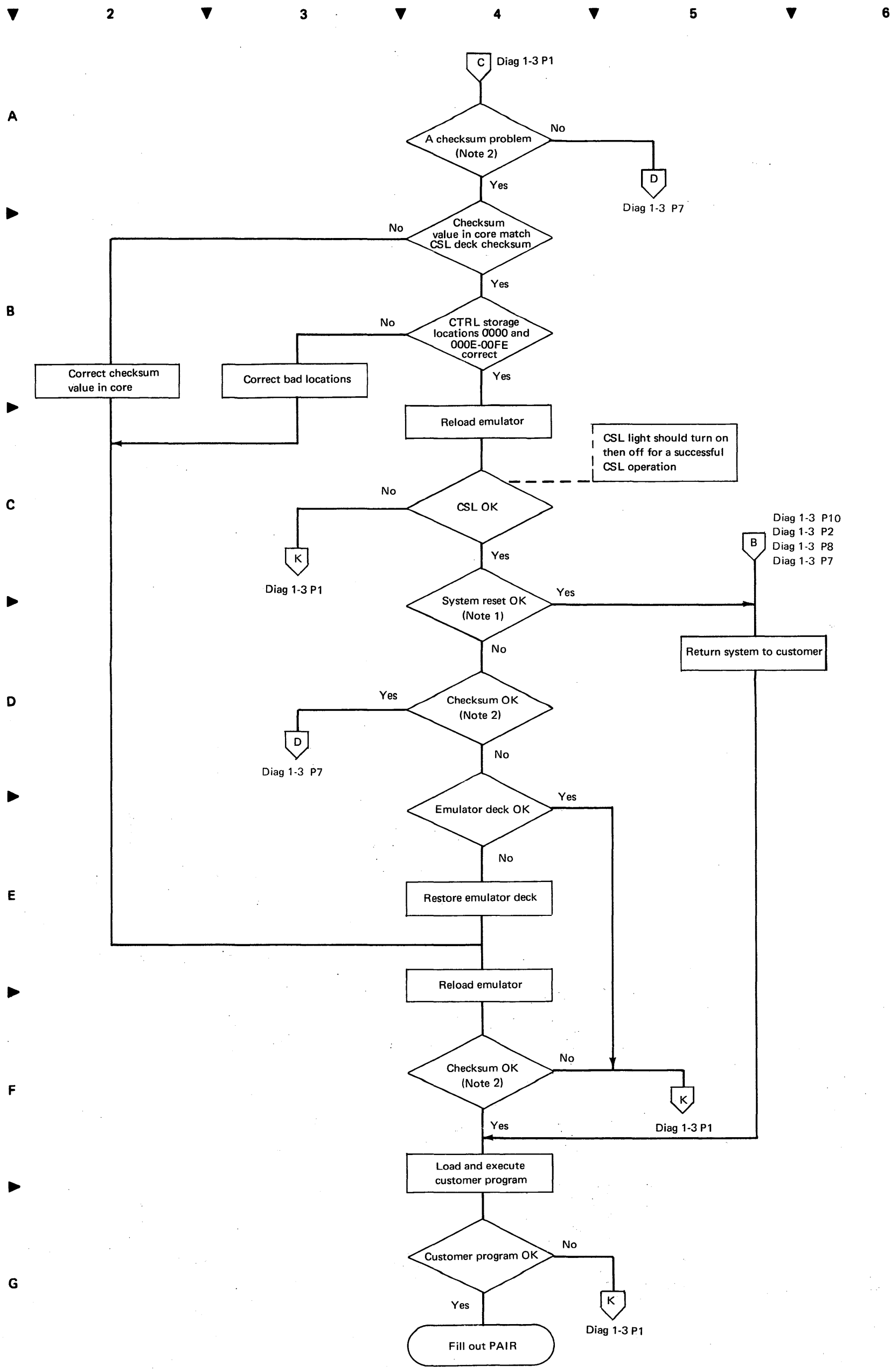
G

H

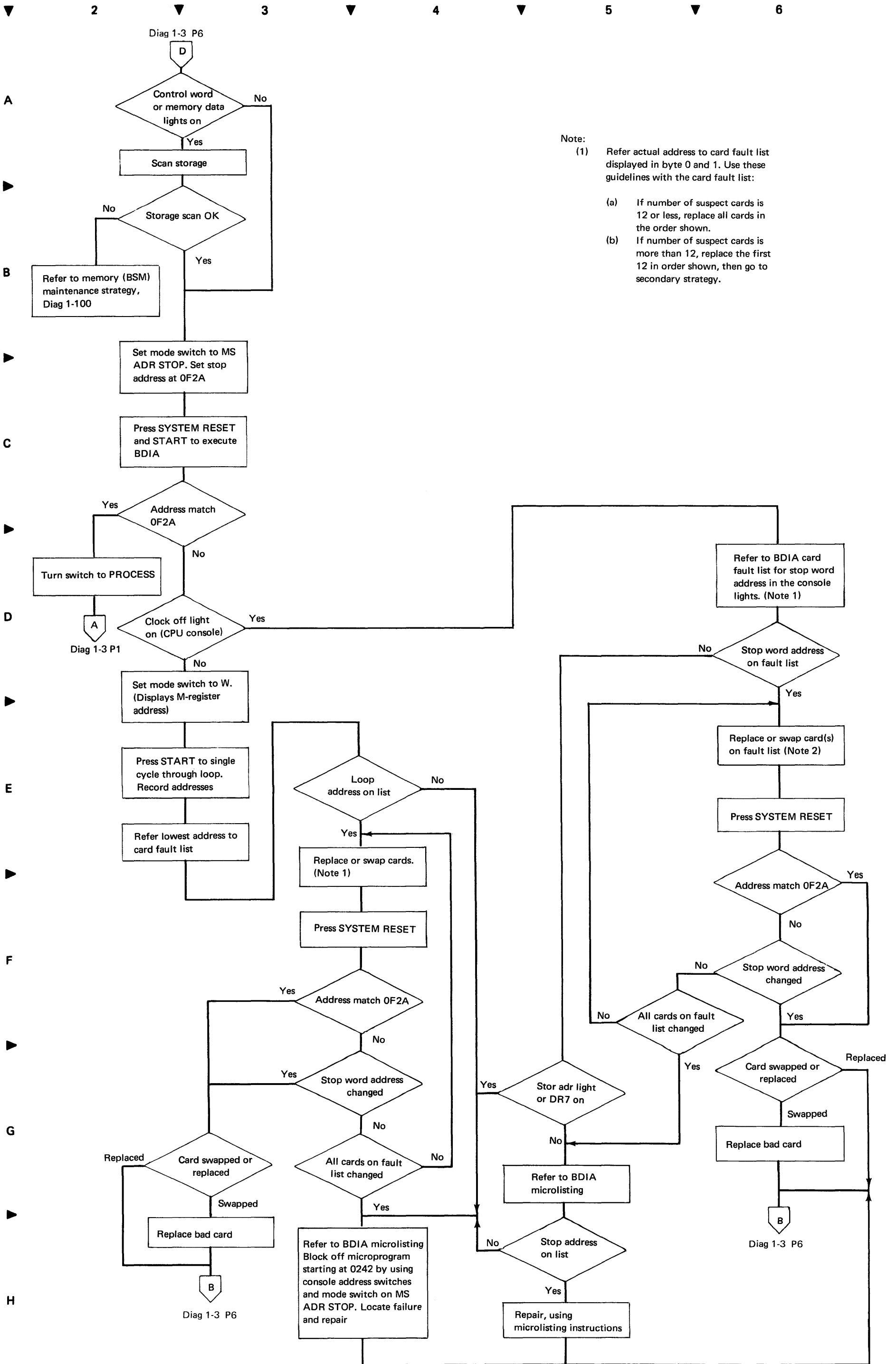


Notes:
 (1) Macrodiagnostic programs are provided only for 2311 and channel attached I/O devices under 360 emulator.
 (2) Microlisting for routine NAAB provides instructions for executing *E90

● Diagram 1-3. Diagnosis Techniques Diagrams (Part 5 of 10)

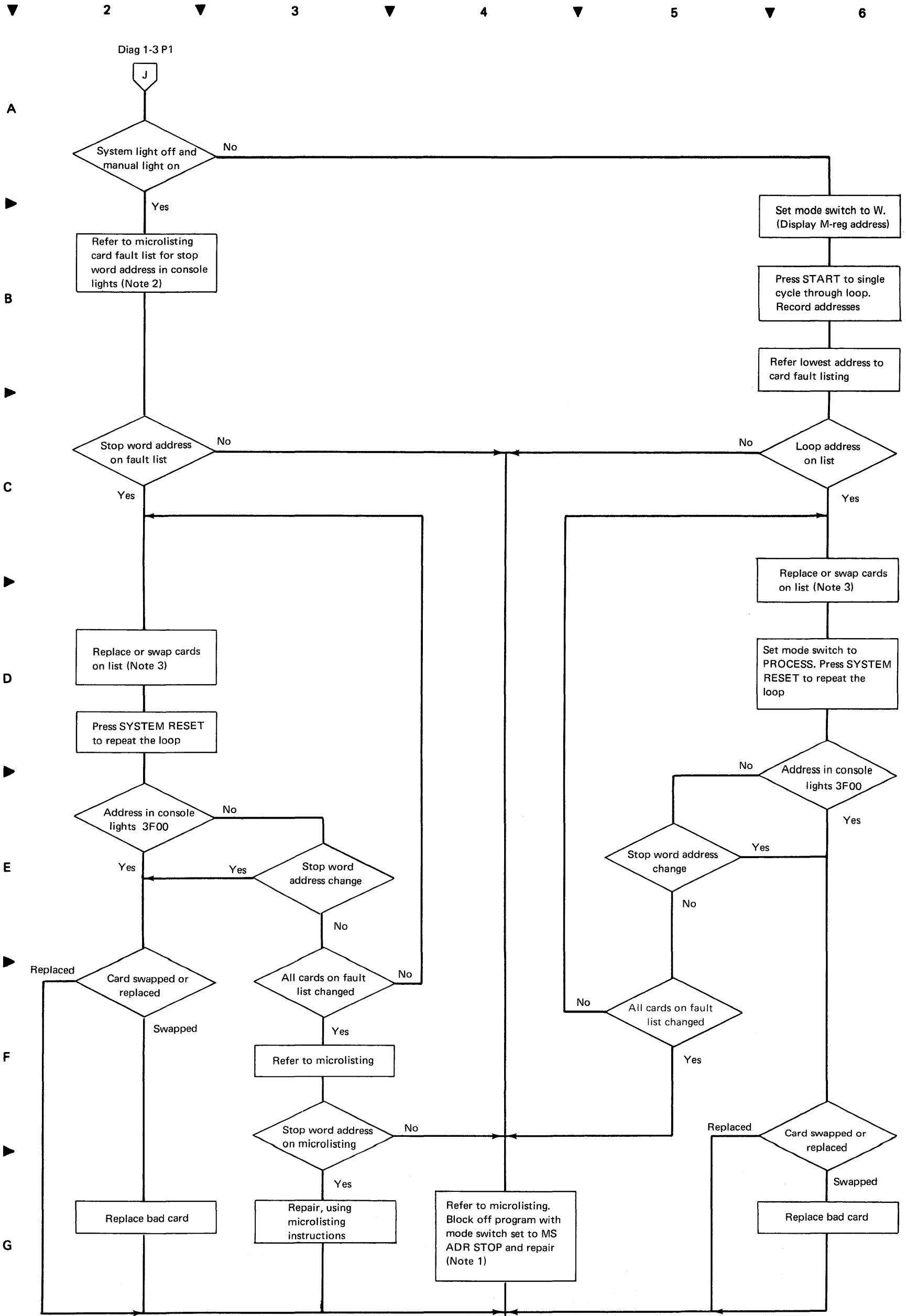


- Notes:
- (1) An OK system reset is indicated by all of the following.
 - (a) No check lights
 - (b) Manual light off then on
 - (c) System light on then off
 - (d) Byte 0 in console lights is 00000000 with parity bit off.
 - (e) No checksum error.
 - (2) A bad checksum is indicated as follows.
 - CE key off - Stop with console checksum light on
 - CE key on - Two line printout on console printer. (Refer to example on Diagram 1-1 P7.)

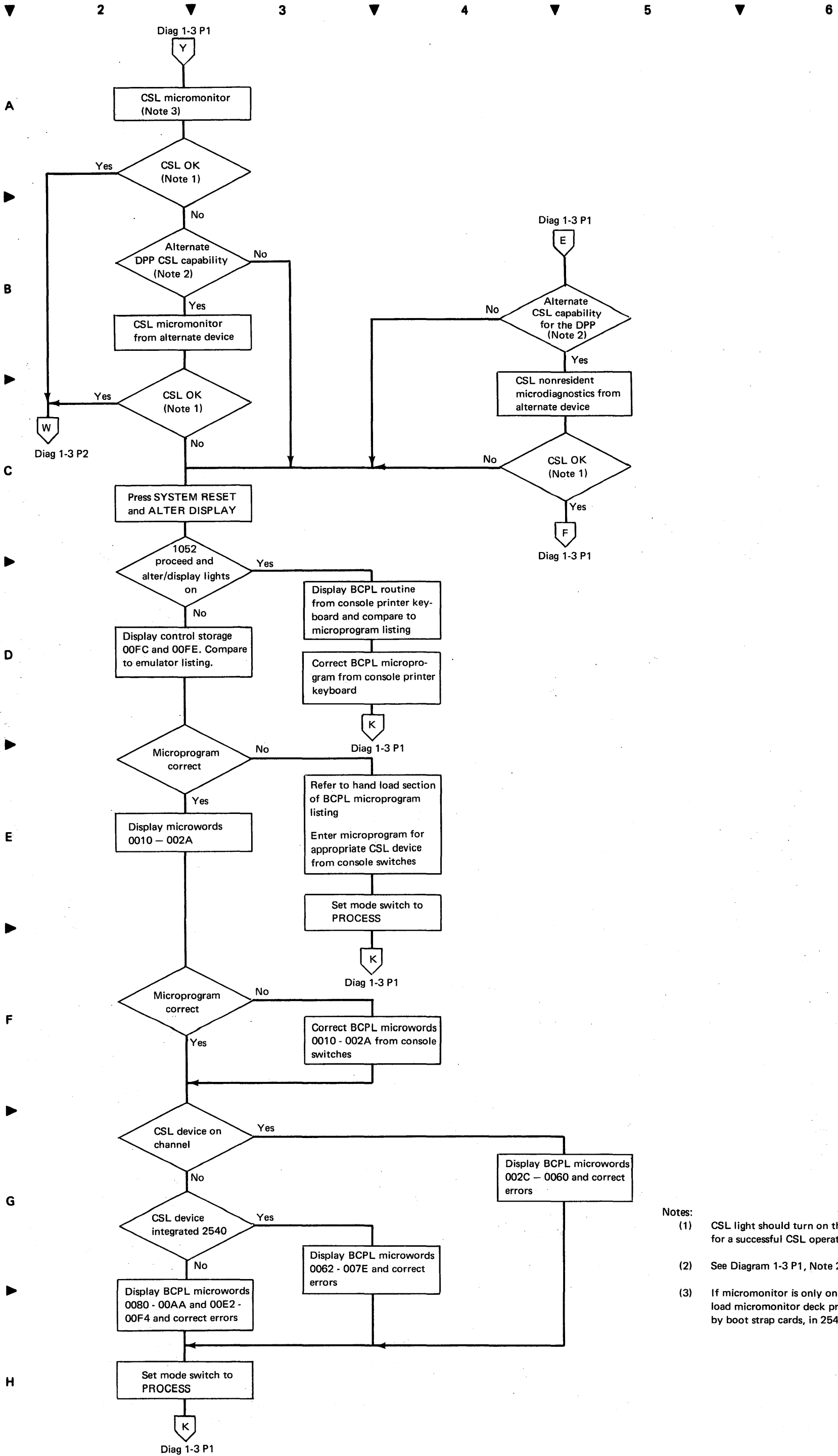


Note:
(1) Refer actual address to card fault list displayed in byte 0 and 1. Use these guidelines with the card fault list:
(a) If number of suspect cards is 12 or less, replace all cards in the order shown.
(b) If number of suspect cards is more than 12, replace the first 12 in order shown, then go to secondary strategy.

● Diagram 1-3. Diagnosis Techniques Diagrams (Part 7 of 10)

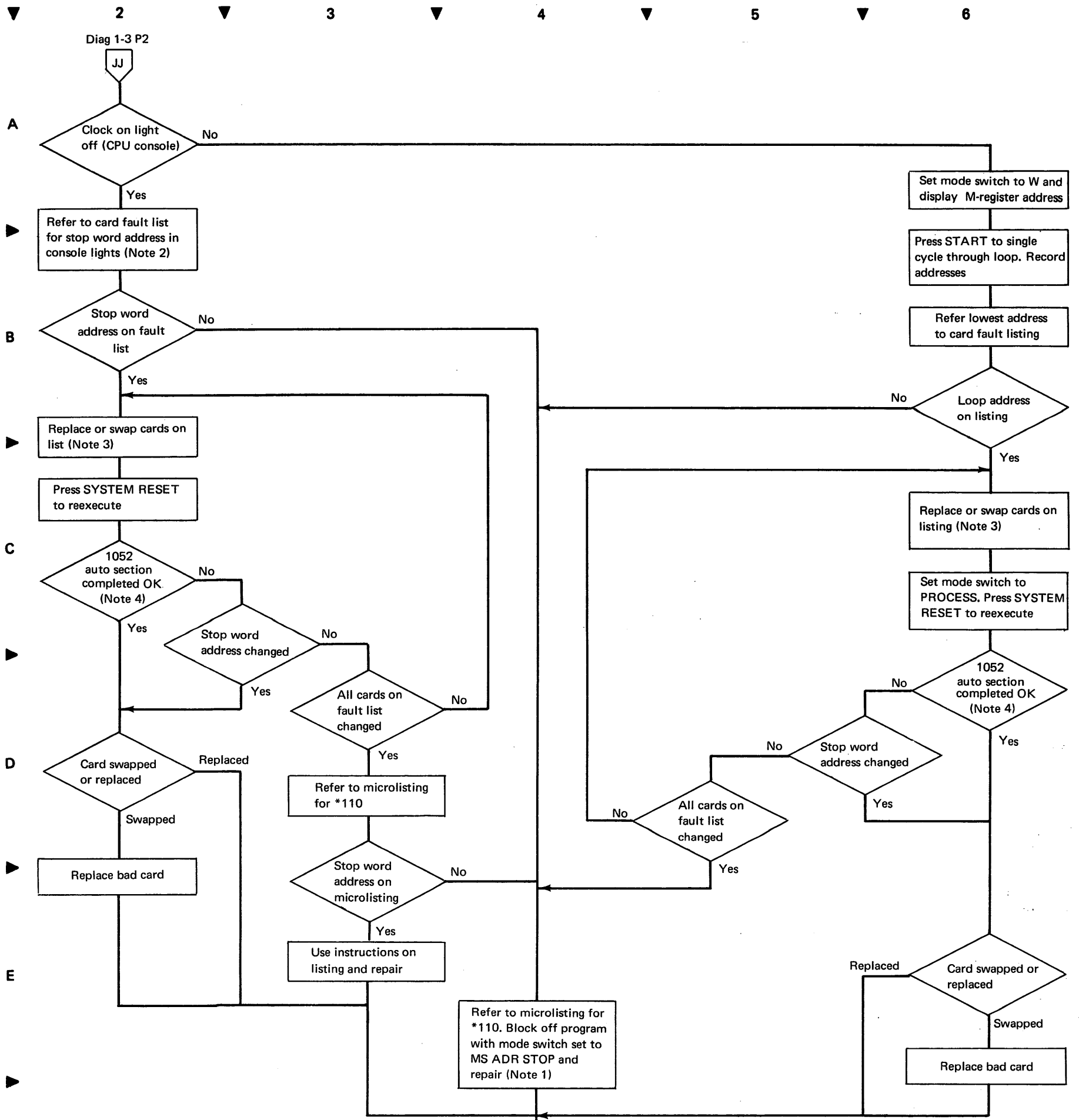


- Note: (1) Set check control switch to DISABLE to clear a loop for scoping. Press START.
 (2) Refer to Diag 1-3 P7. Note 1.
 (3) Use these guidelines with the card fault list:
 (a) If number of suspect cards is 12 or less, replace all cards in the order shown.
 (b) If number of suspect cards is more than 12 replace the first 12 in order shown, then go to secondary strategy.



- Notes:
- (1) CSL light should turn on then off for a successful CSL operation.
 - (2) See Diagram 1-3 P1, Note 2.
 - (3) If micromonitor is only on cards, load micromonitor deck preceded by boot strap cards, in 2540 reader.

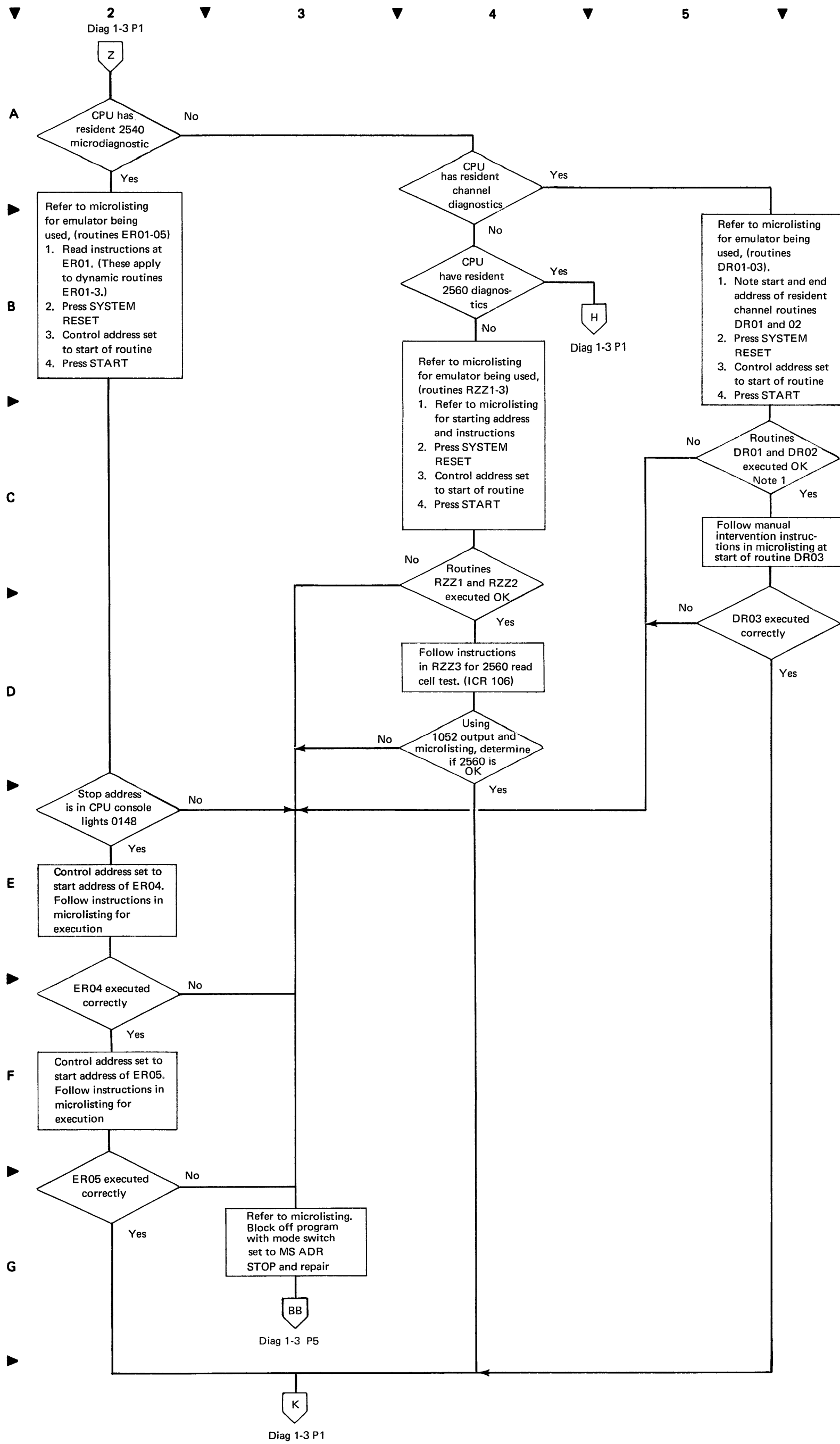
● Diagram 1-3. Diagnosis Techniques Diagrams (Part 9 of 10)



Notes:

- (1) Set check control switch to DISABLE to create a loop for scoping. Press START
- (2) Refer to Diagram 1-3 P7, Note 1
- (3) Use these guidelines with the card fault list:
 - (a) If number of suspect cards is 12 or less, replace all cards in the order shown.
 - (b) If number of suspect cards is more than 12, replace the first 12 in order shown, then go to secondary strategy.
- (4) Refer to Diagram 1-3 P2, Note 5.

Diag 1-3 P6



H Notes:
(1) DR01 and DR02 execute automatically; DR03 requires manual intervention. If DR01 and DR02 execute correctly, the CPU will stop at the point manual intervention is required in DR03; follow the instructions in the DR03 microlisting.

● Diagram 1-5. Resident 2540, 2560 Channel Microdiagnostics

Memory Diagnostic Technique Diagrams

The following diagnostic strategy diagrams should be used when troubleshooting a memory failure. Used with the operator's console, these diagrams provide a comprehensive diagnostic tool for locating and correcting memory failures.

A

Use *130 Memory Microdiagnostic on systems with two memory modules (more than 16K of program storage) when the failure is occurring in only one of the modules. The microlisting for *130 provides the necessary instructions for setup and execution of this microdiagnostic.

▶

B

▶

C

▶

D

▶

E

▶

F

▶

G

▶

H

A

SCAN STORAGE

1. Mode switch to single cycle position
2. Diagnostic control switch to scan stor
3. Mode switch to process
4. Check control switch to stop (unless specified otherwise)
5. System reset
6. Start

B

LOAD PROG STORAGE

1. Mode switch to single cycle position
2. ABCD switches to data to be stored [$X_1 X_2 X_2 X_2$ (Hex)]
3. Diagnostic control switch to load prgm stor
4. Mode switch to process
5. Check control switch to stop (unless specified otherwise)
6. System reset
7. Start

B

SINGLE ADDRESS SCAN (At Address 0000)

1. Mode switch to single cycle position
2. Diagnostic control switch to single adr ms
3. Mode switch to process
4. Check control switch to stop (unless specified otherwise)
5. Set switches ABCD to address to be scanned
6. System reset
7. Control address set and start

C

LOAD STORAGE (Control storage addresses 0000-00FE are accessed but contents remain unchanged)

1. Mode switch to single cycle position
2. ABCD switches to data to be stored
3. Diagnostic control switch to load stor
4. Mode switch to process
5. Check control switch to stop (unless specified otherwise)
6. System reset
7. Start

Memory Diagnostic Technique Console Scan Procedure

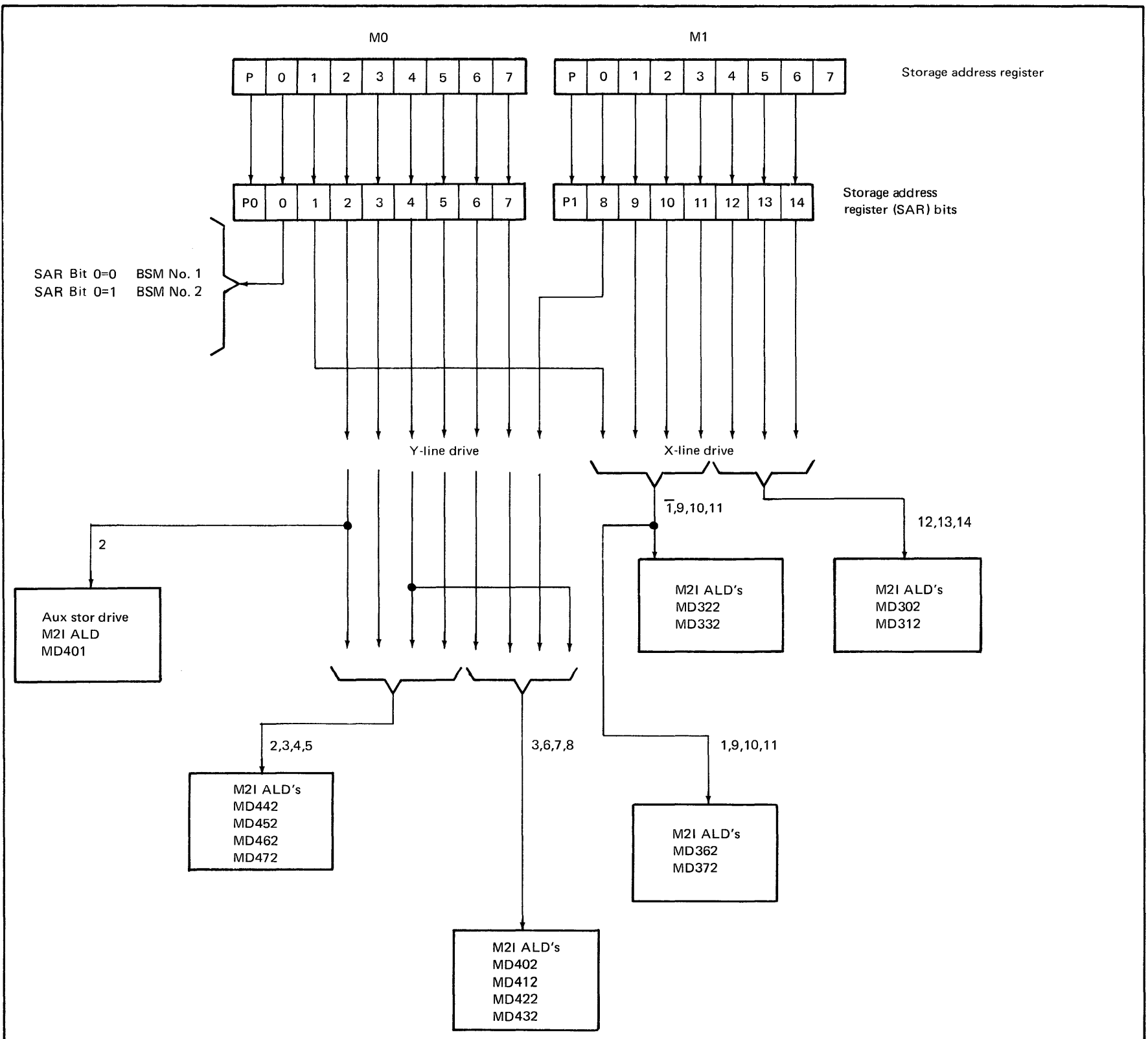
D

E

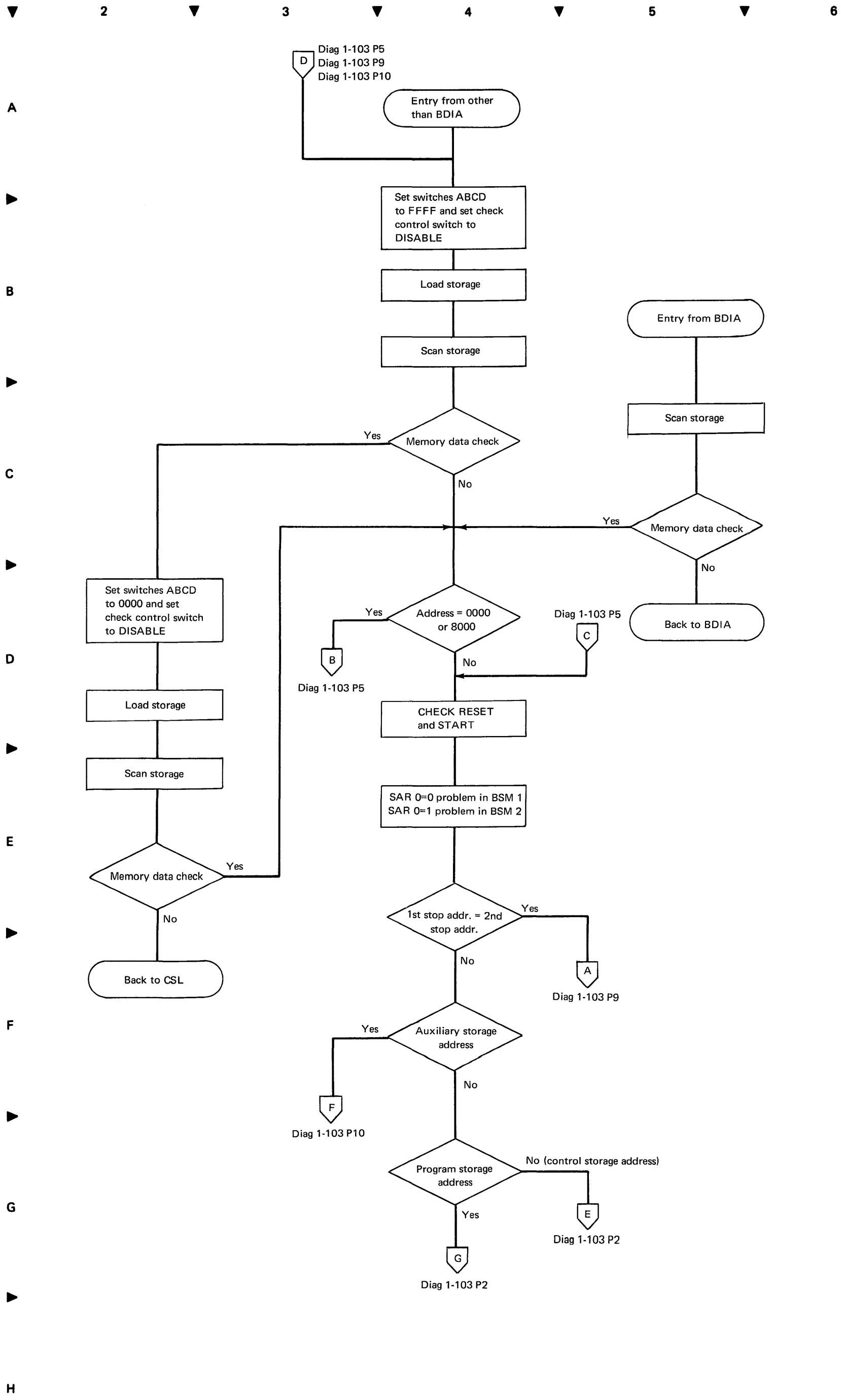
F

G

H



● Diagram 1-101. X-Line, Y-Line Decode Source and Memory Diagnostic Technique Console Scan Procedure



● Diagram 1-103. Memory Diagnostic Technique Diagrams (Part 1 of 10)

A

B

C

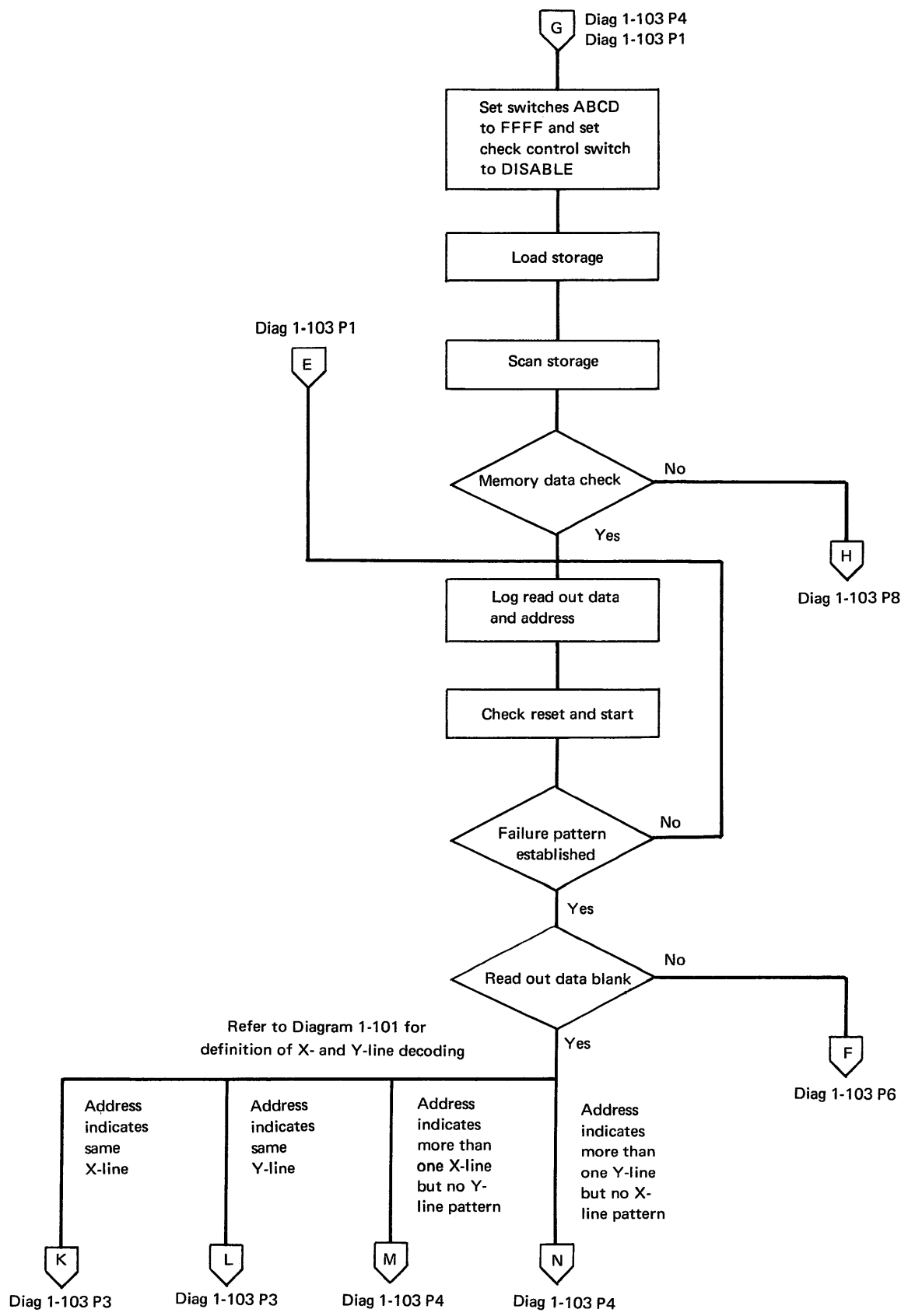
D

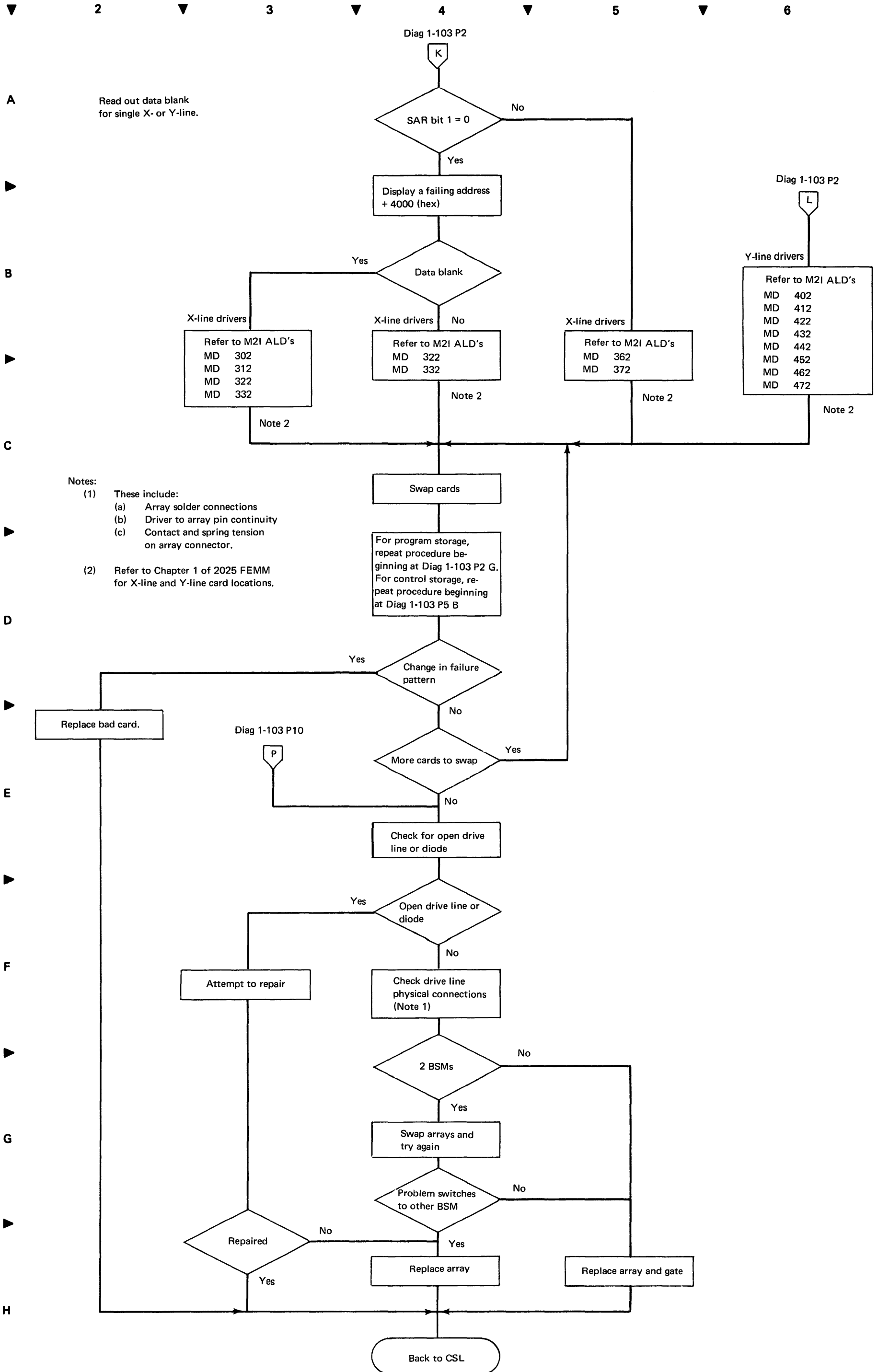
E

F

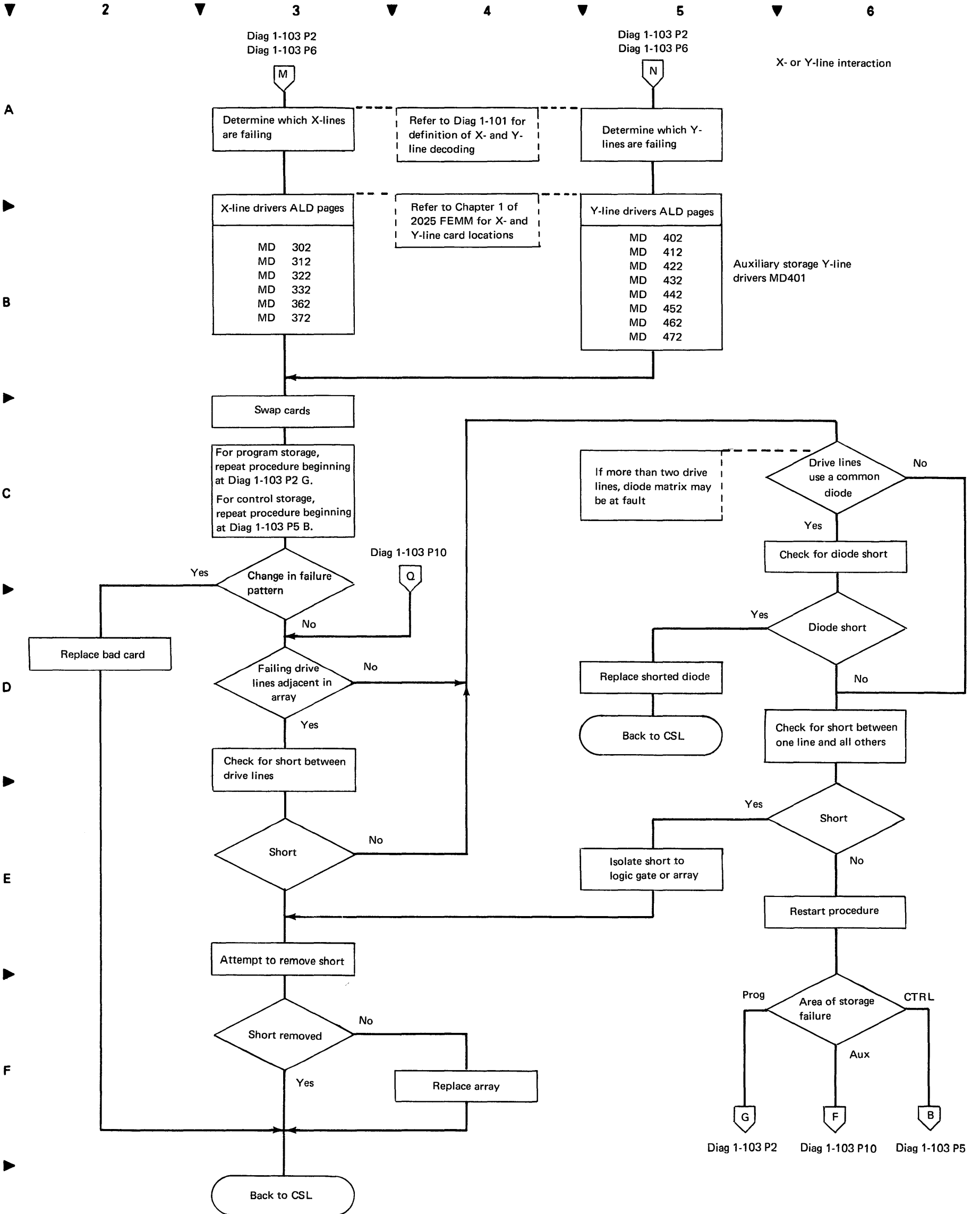
G

H

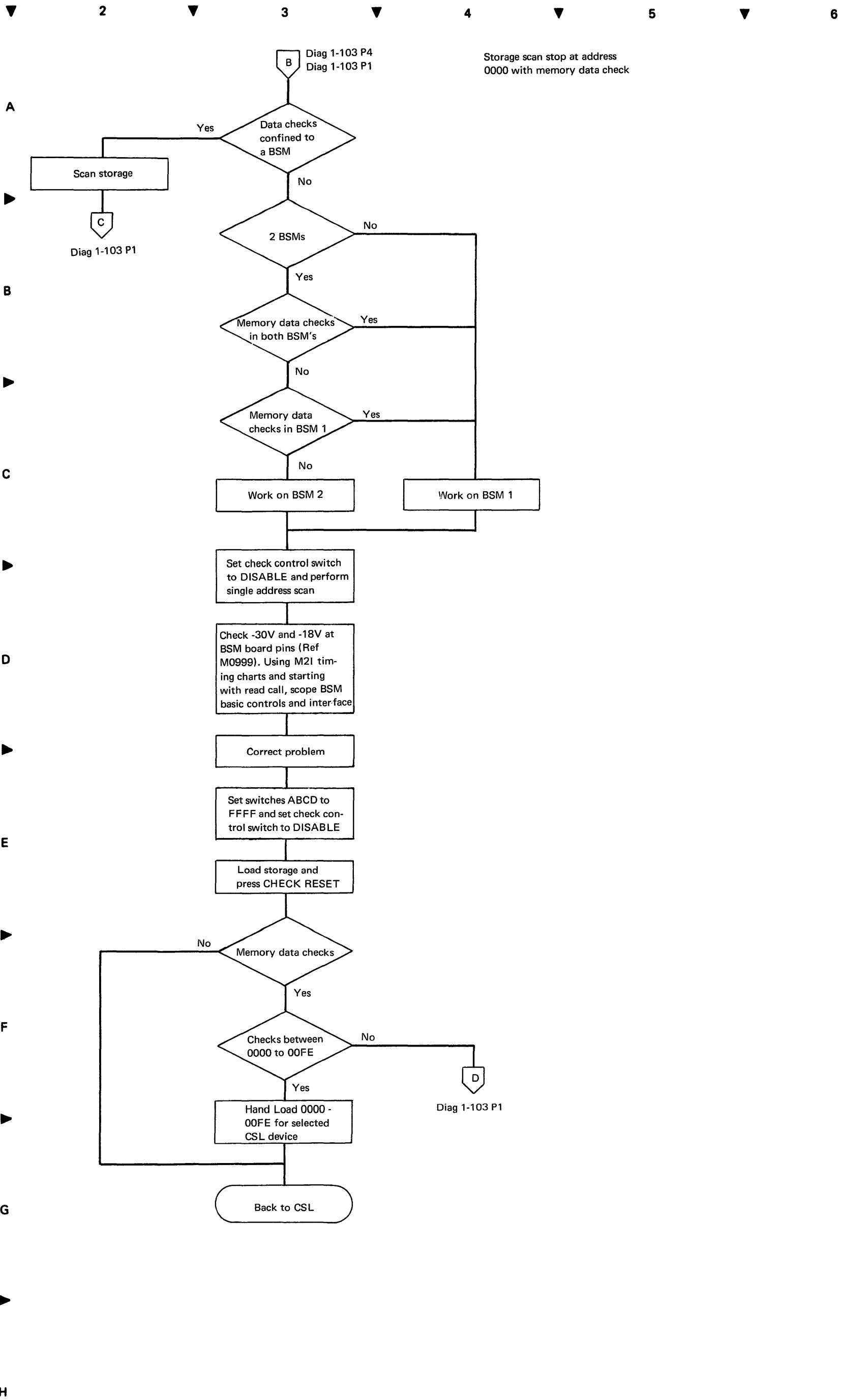


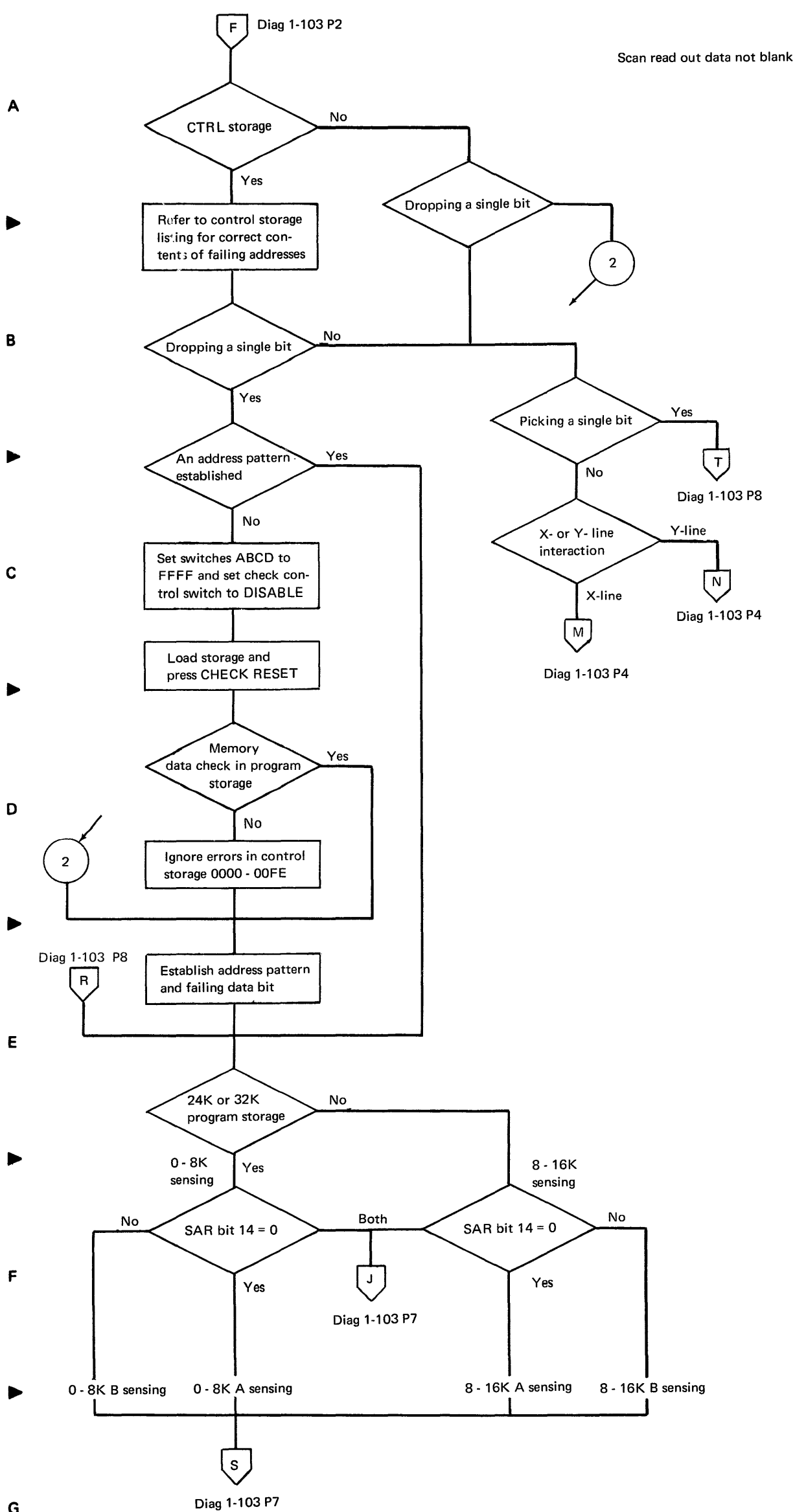


● Diagram 1-103. Memory Diagnostic Technique Diagrams (Part 3 of 10)



● Diagram 1-103. Memory Diagnostic Technique Diagrams (Part 4 of 10)





Notes:

(1) Do not swap out of the 8K block of storage.

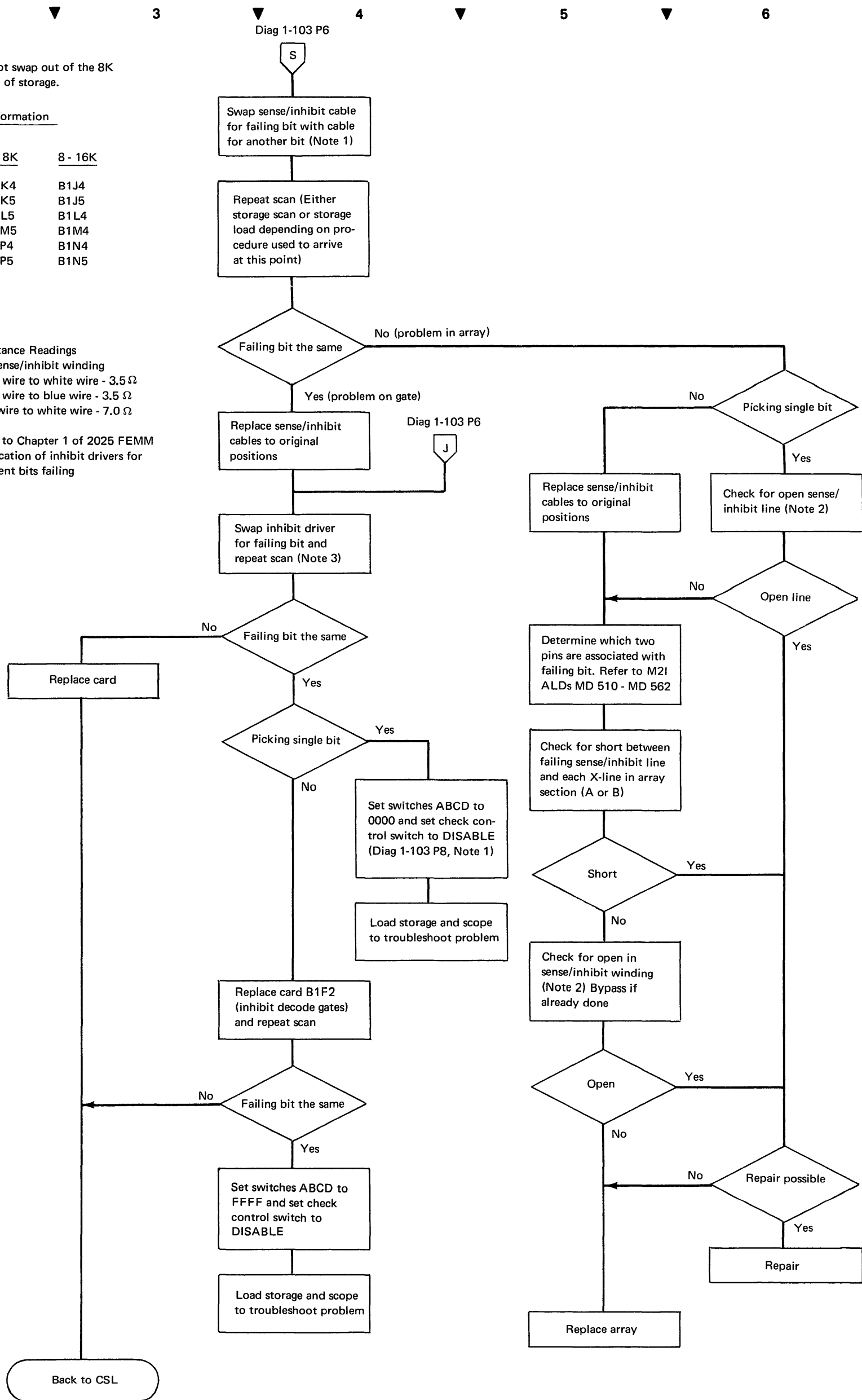
Cable information

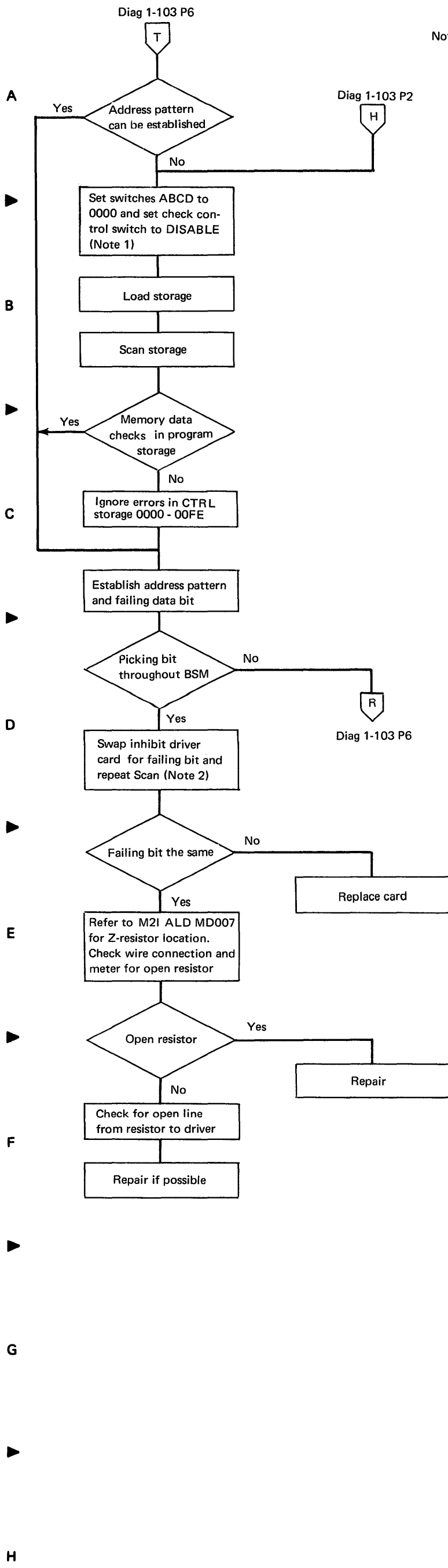
Date bits	0 - 8K	8 - 16K
0,1,2	B1K4	B1J4
3,4,5	B1K5	B1J5
6,7,P0	B1L5	B1L4
8,9,10	B1M5	B1M4
11,12,13	B1P4	B1N4
14,15,P1	B1P5	B1N5

(2) Resistance Readings

For sense/inhibit winding
Black wire to white wire - 3.5 Ω
Black wire to blue wire - 3.5 Ω
Blue wire to white wire - 7.0 Ω

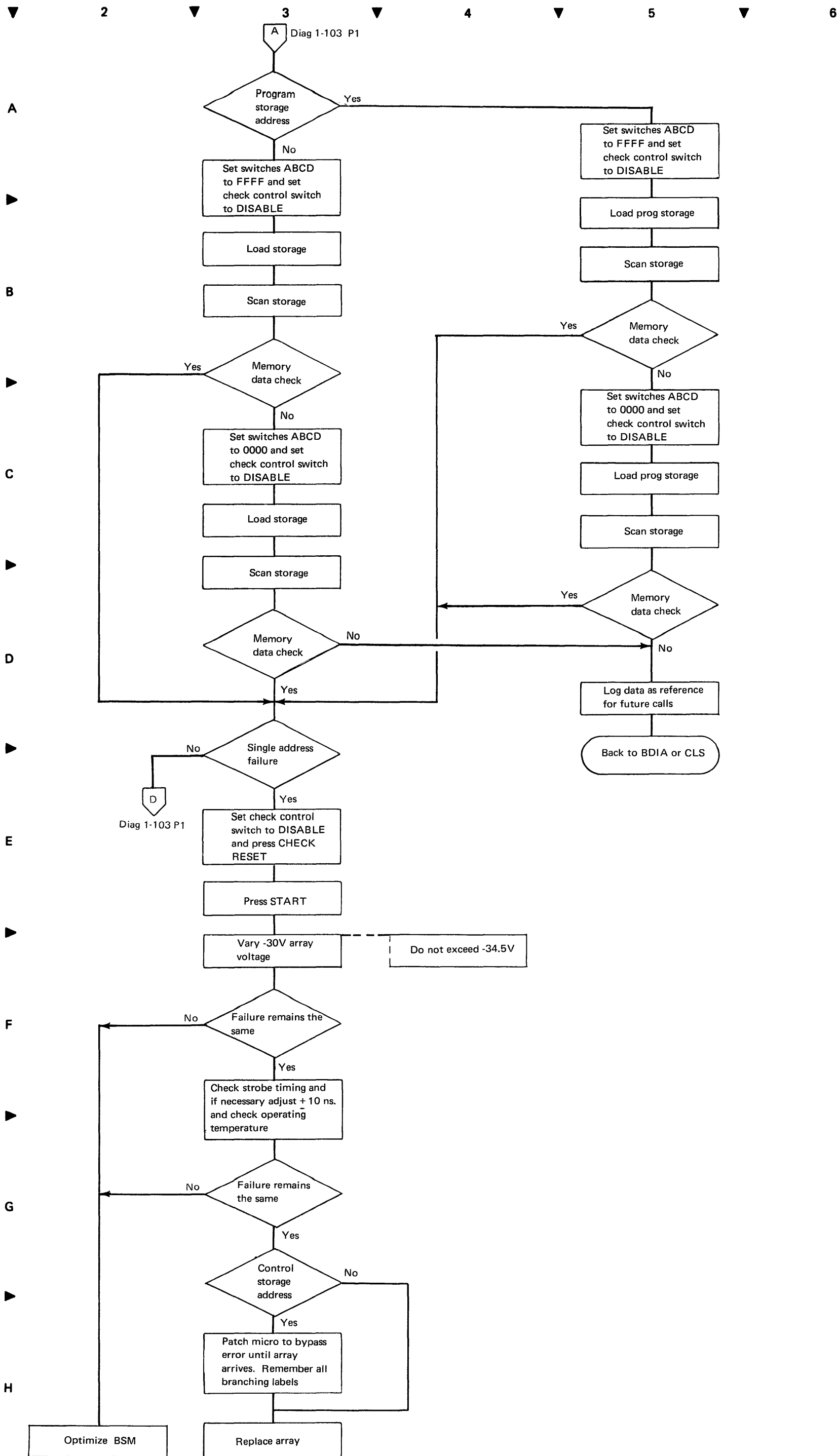
(3) Refer to Chapter 1 of 2025 FEMM for location of inhibit drivers for different bits failing



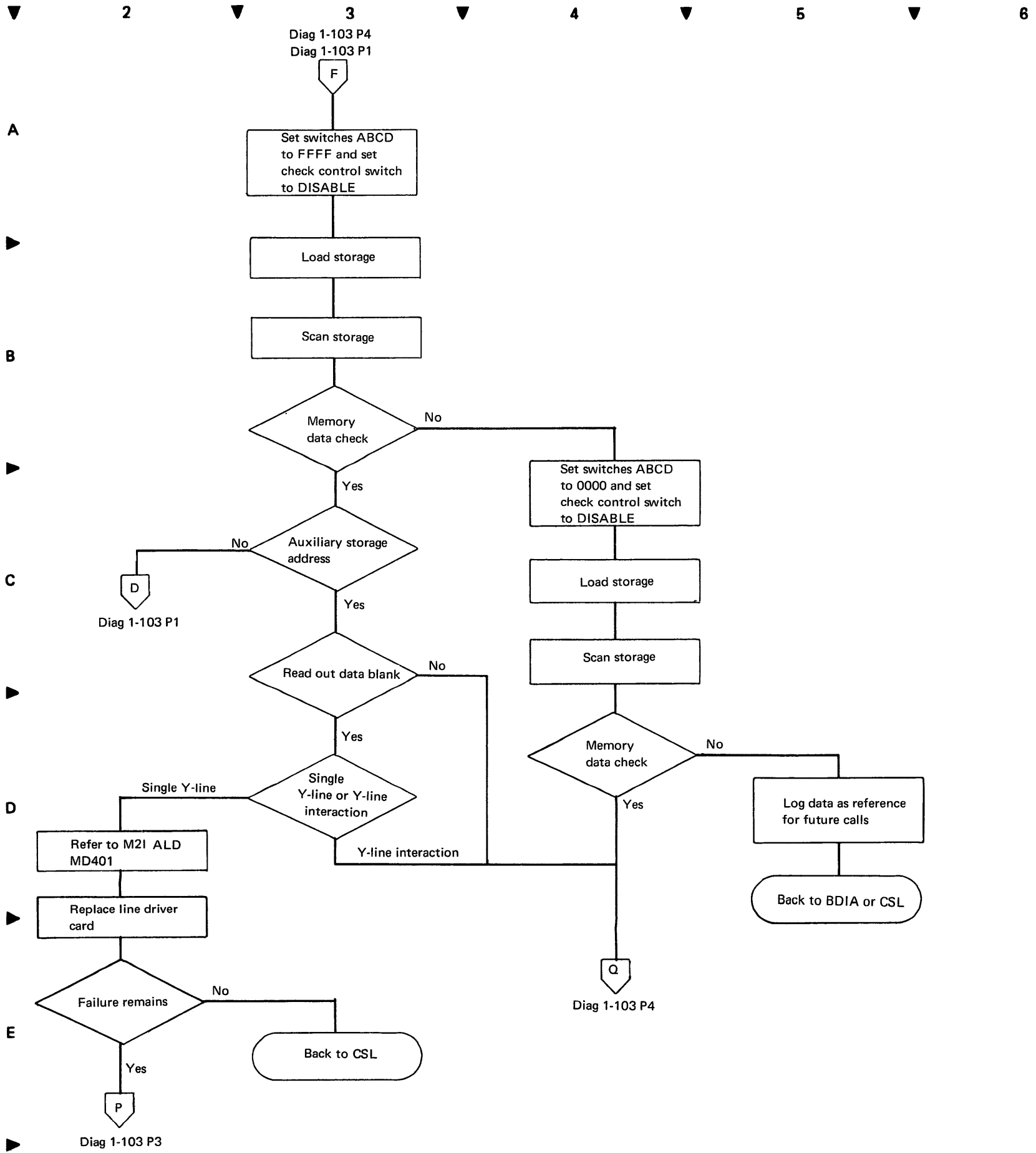


Notes:
(1) If P0 or P1 are being picked, set switches ABCD to 0101
(2) Refer to Chapter 1 of 2025 FEMM for location of inhibit drivers for different bits failing

PICKING A SINGLE BIT



● Diagram 1-103. Memory Diagnostic Technique Diagrams (Part 9 of 10)



Power System Diagnostic Technique

A



B



C



D



E



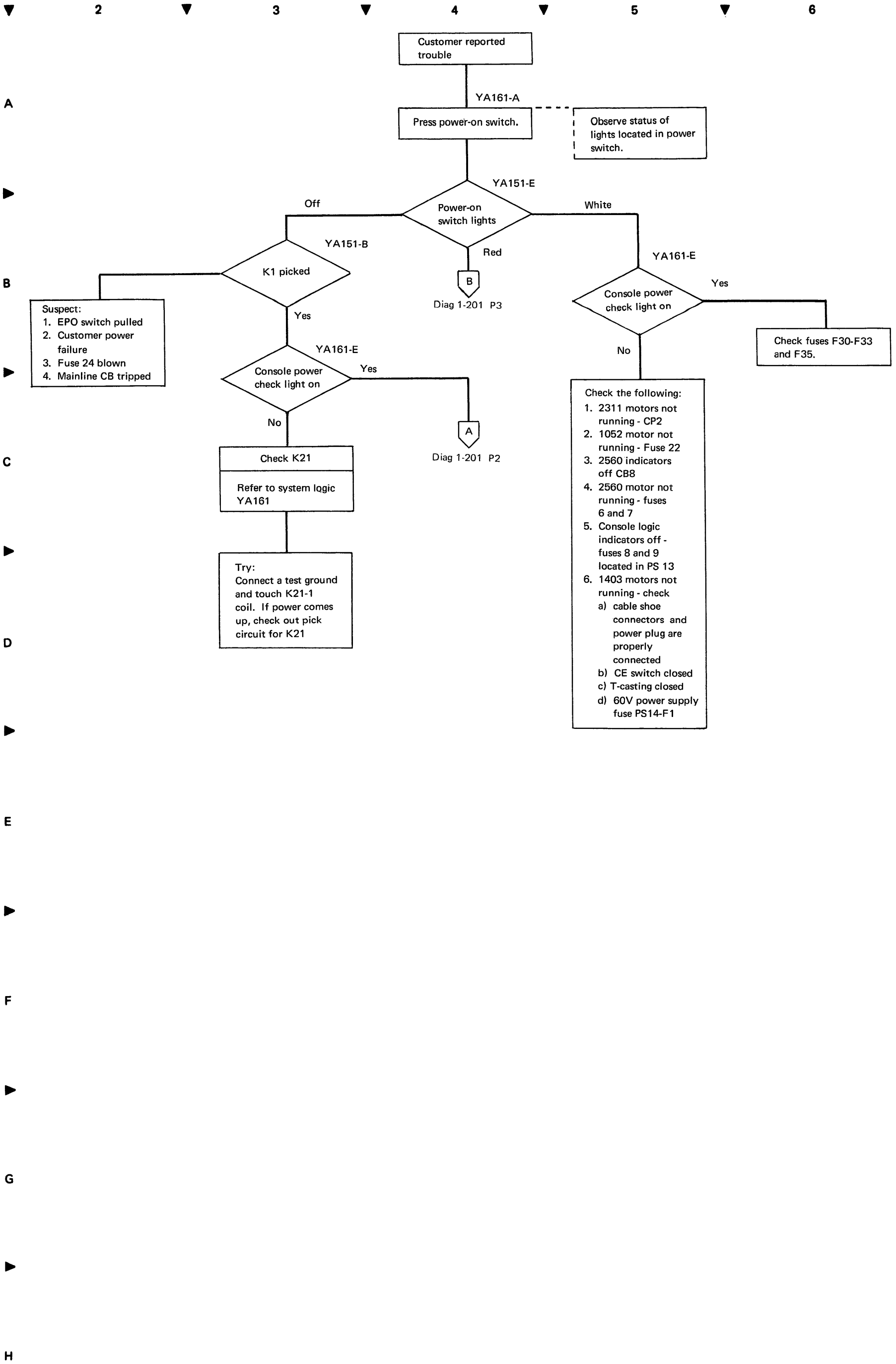
F



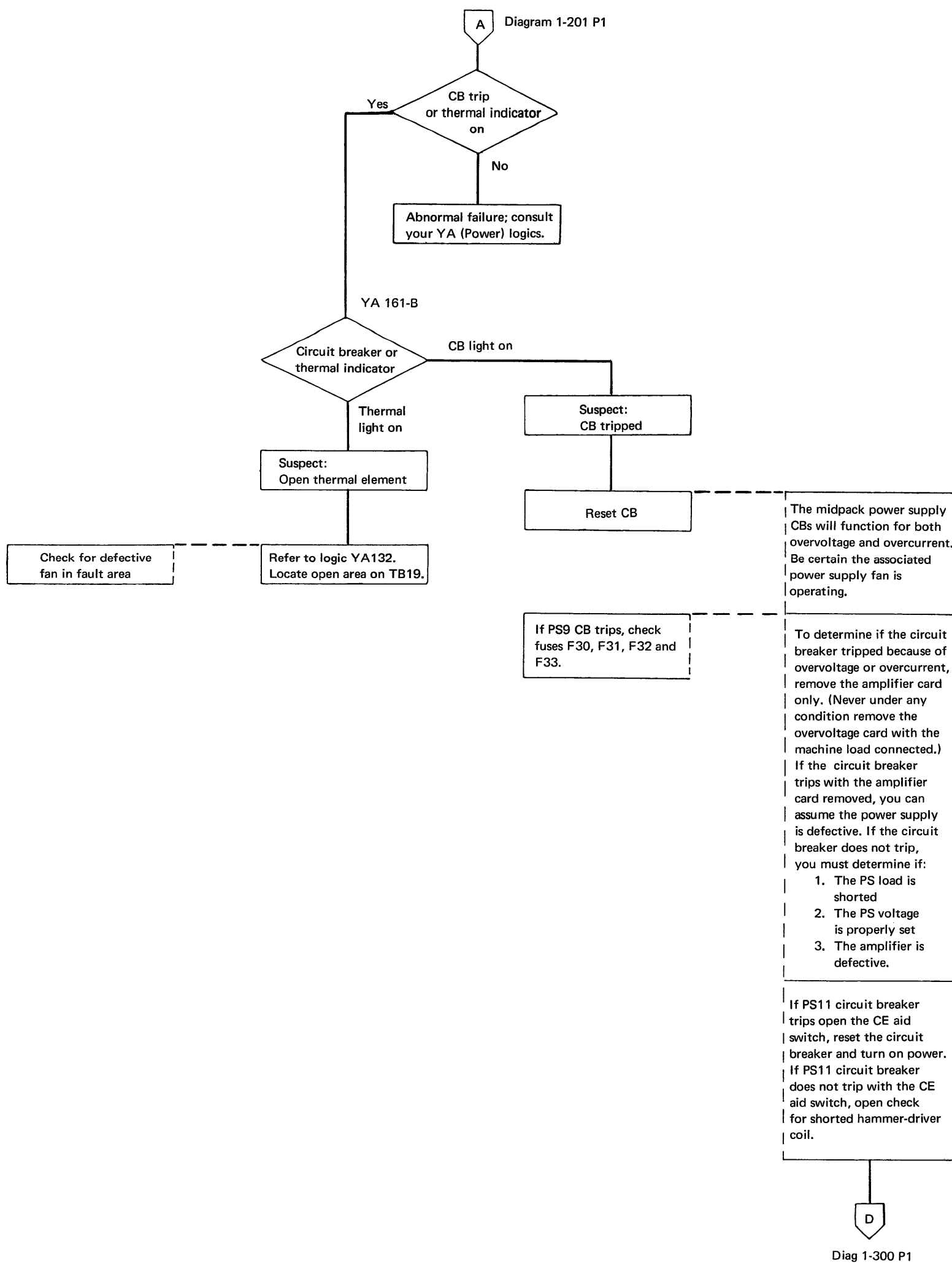
G

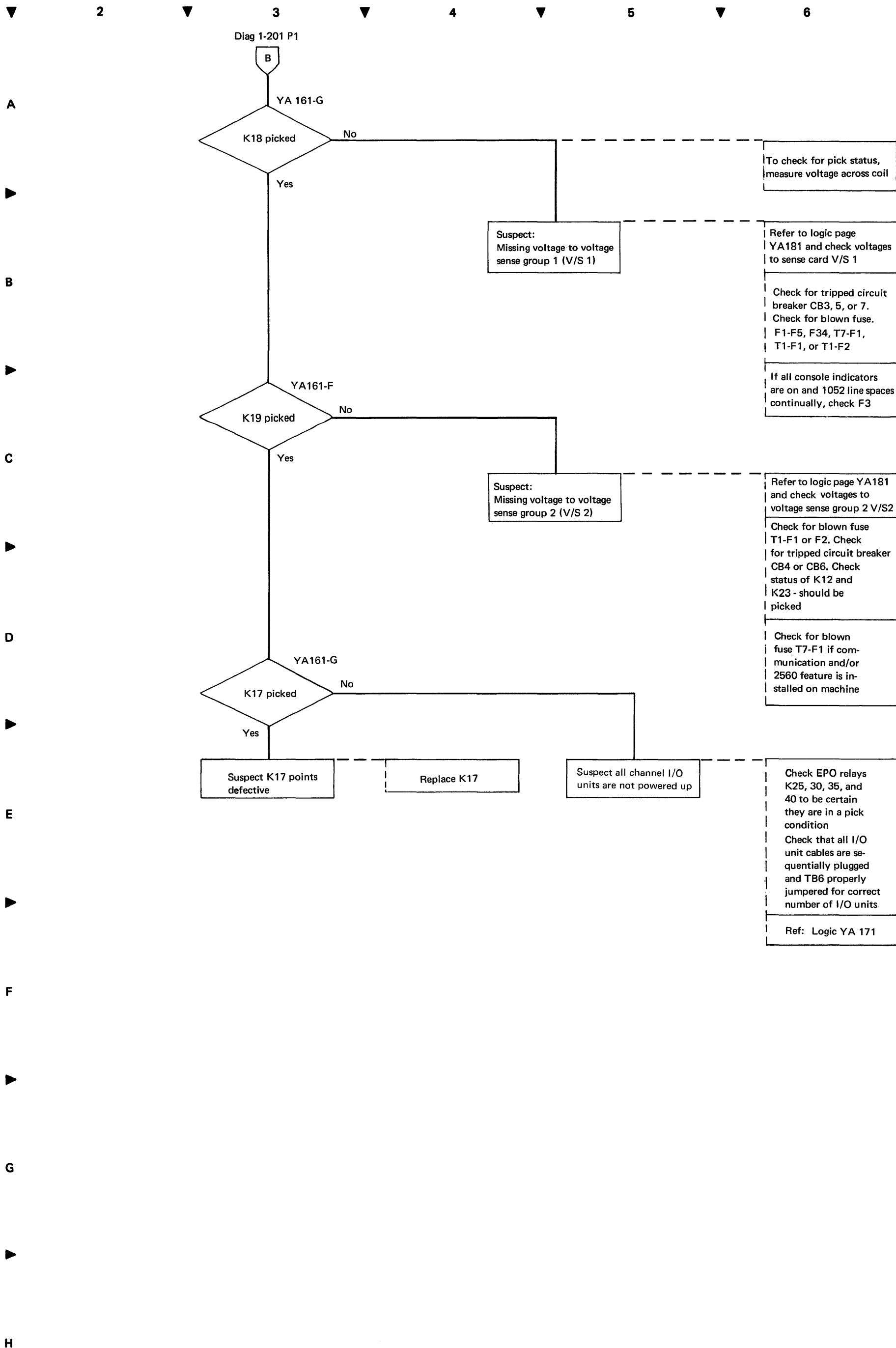


H



● Diagram 1-201. Power System Failure Analysis (Part 1 of 3)





● Diagram 1-201. Power System Failure Analysis (Part 3 of 3)

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6

A print check with print ready off can indicate a coil protect check. If the chain motor is not running, this is an indication of a coil protect check because this error would drop the +60V.

A

Caution
A bad hammer driver card that is always on may have been due to a shorted hammer coil. Swapping cards may result in damaging additional hammer driver cards. The problem causing position should be positively identified and checked for a shorted coil before full current printing is attempted.

B

C

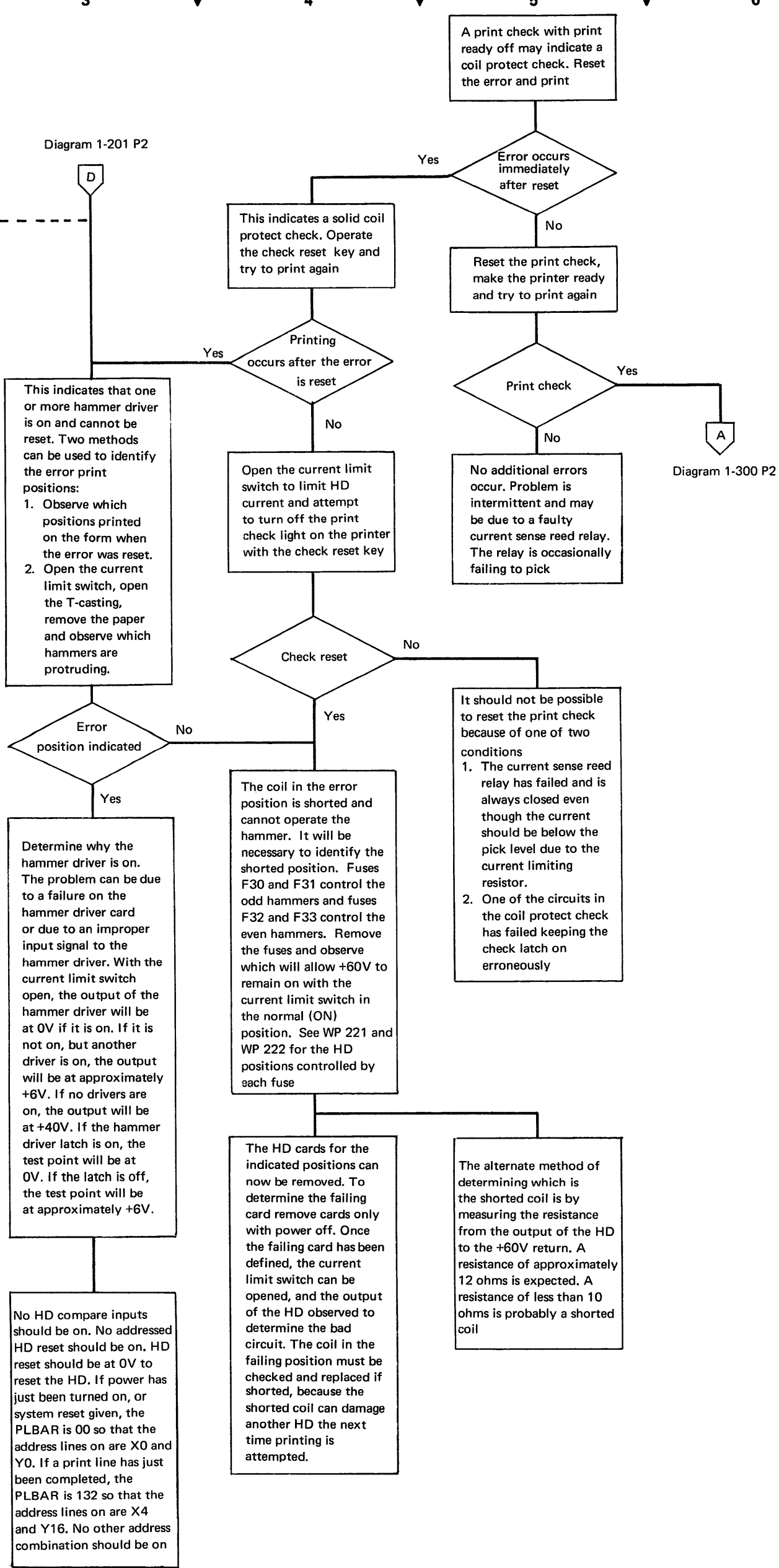
D

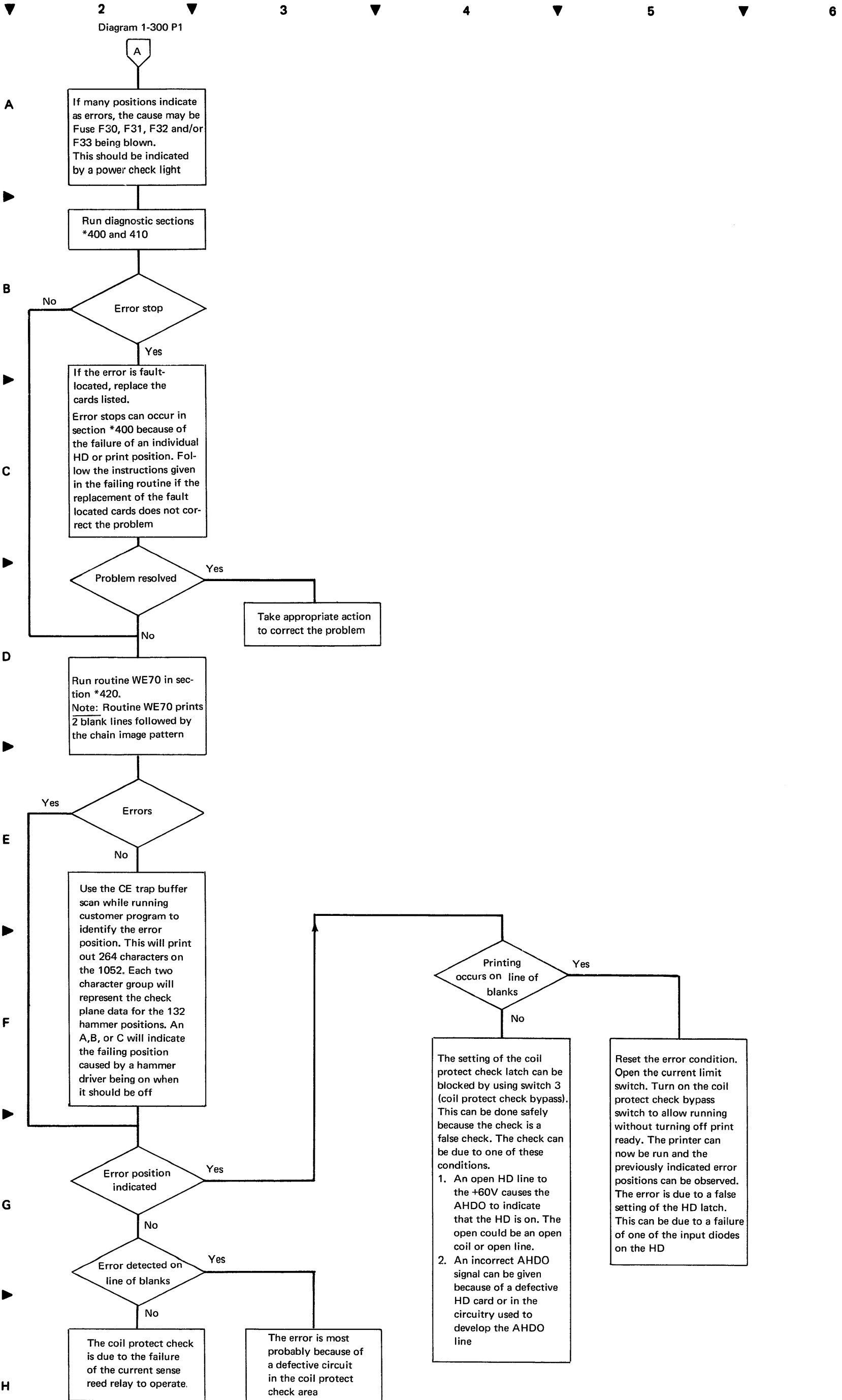
E

F

G

H





● Diagram 1-300. Coil Protect Diagnostic Technique (Part 2 of 2)

Diagram 4-26. Core Storage Driver

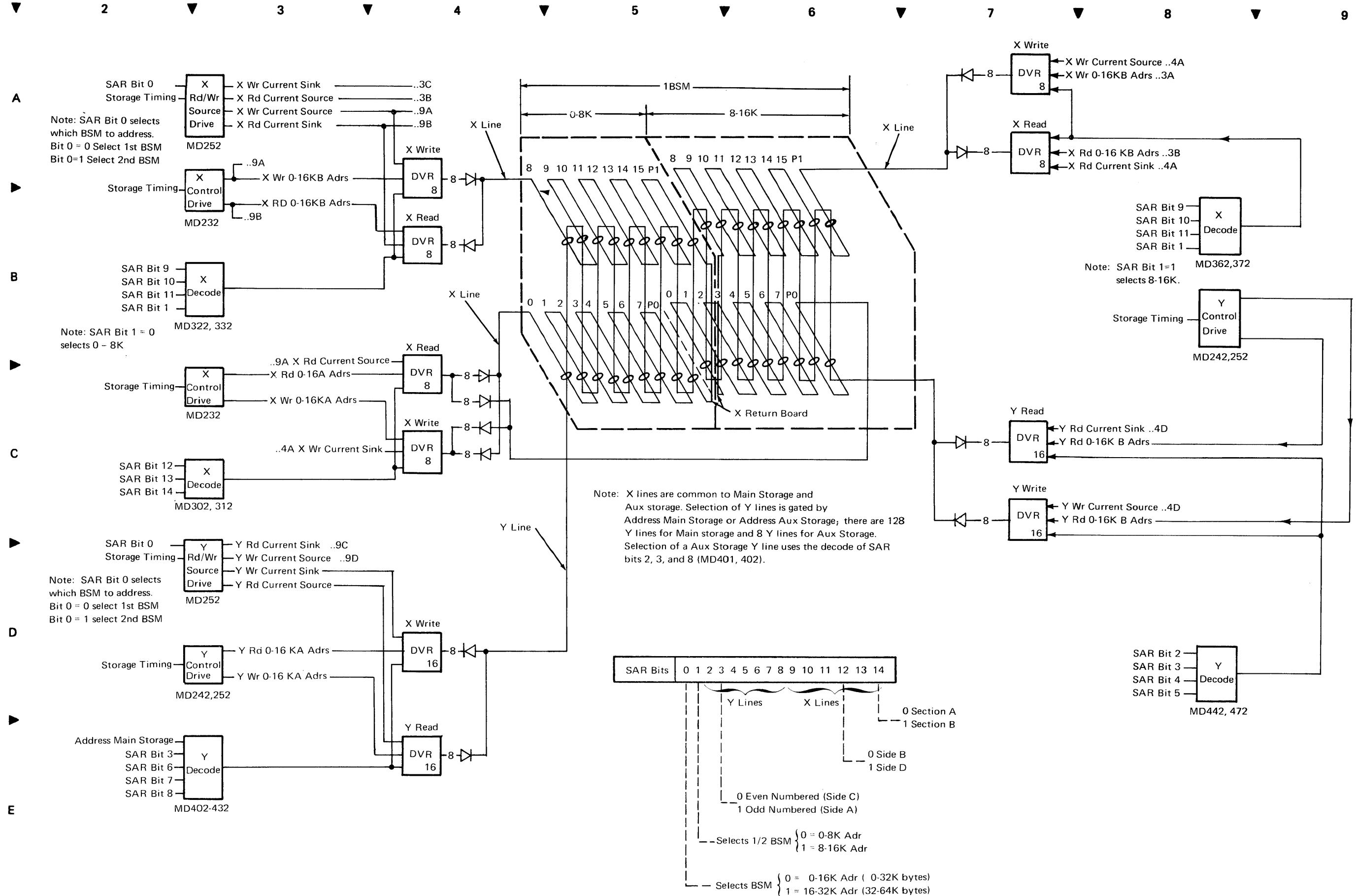


Diagram 3-1. 2025 System Data Flow

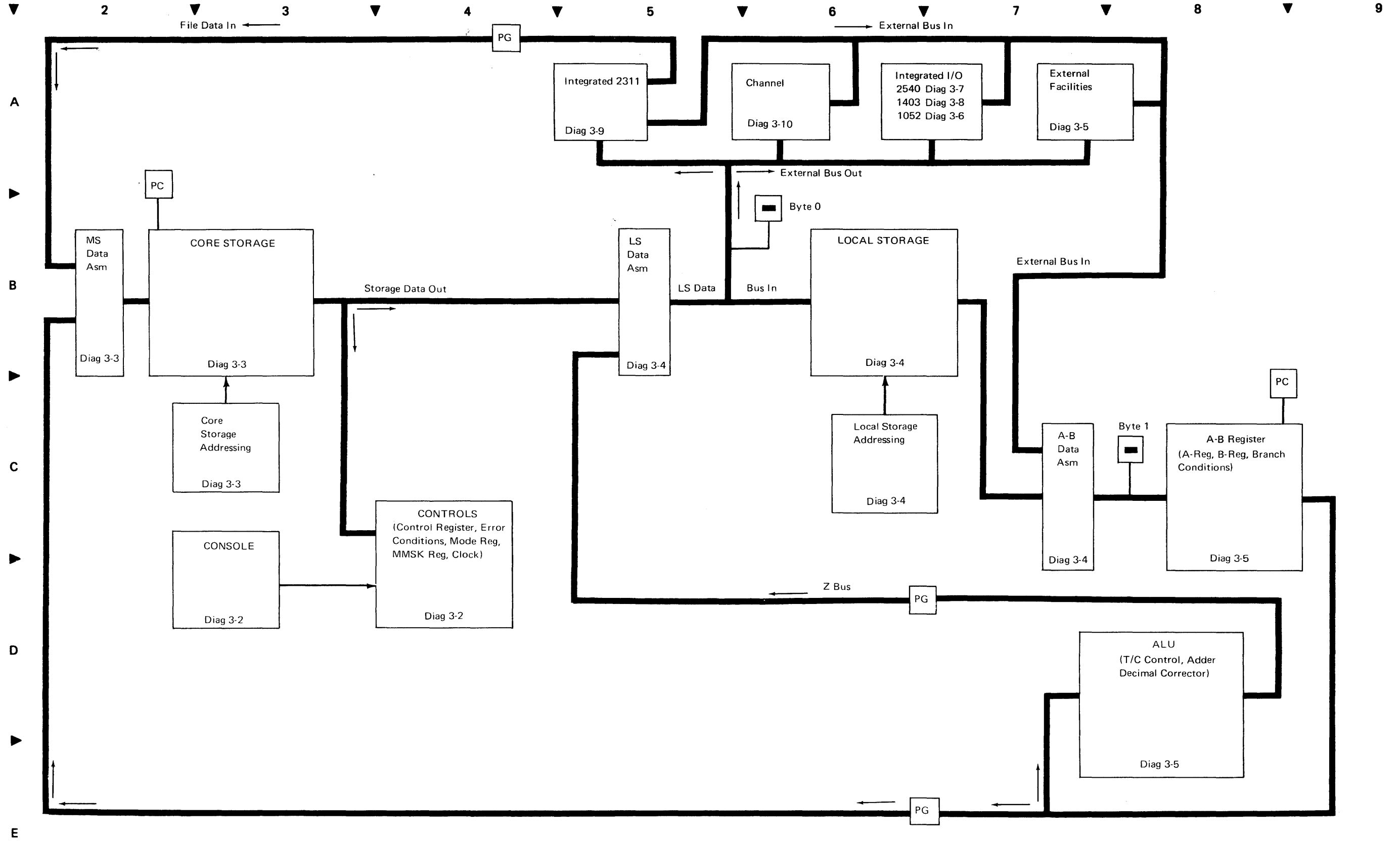


Diagram 3-2. Control Circuits Data Flow

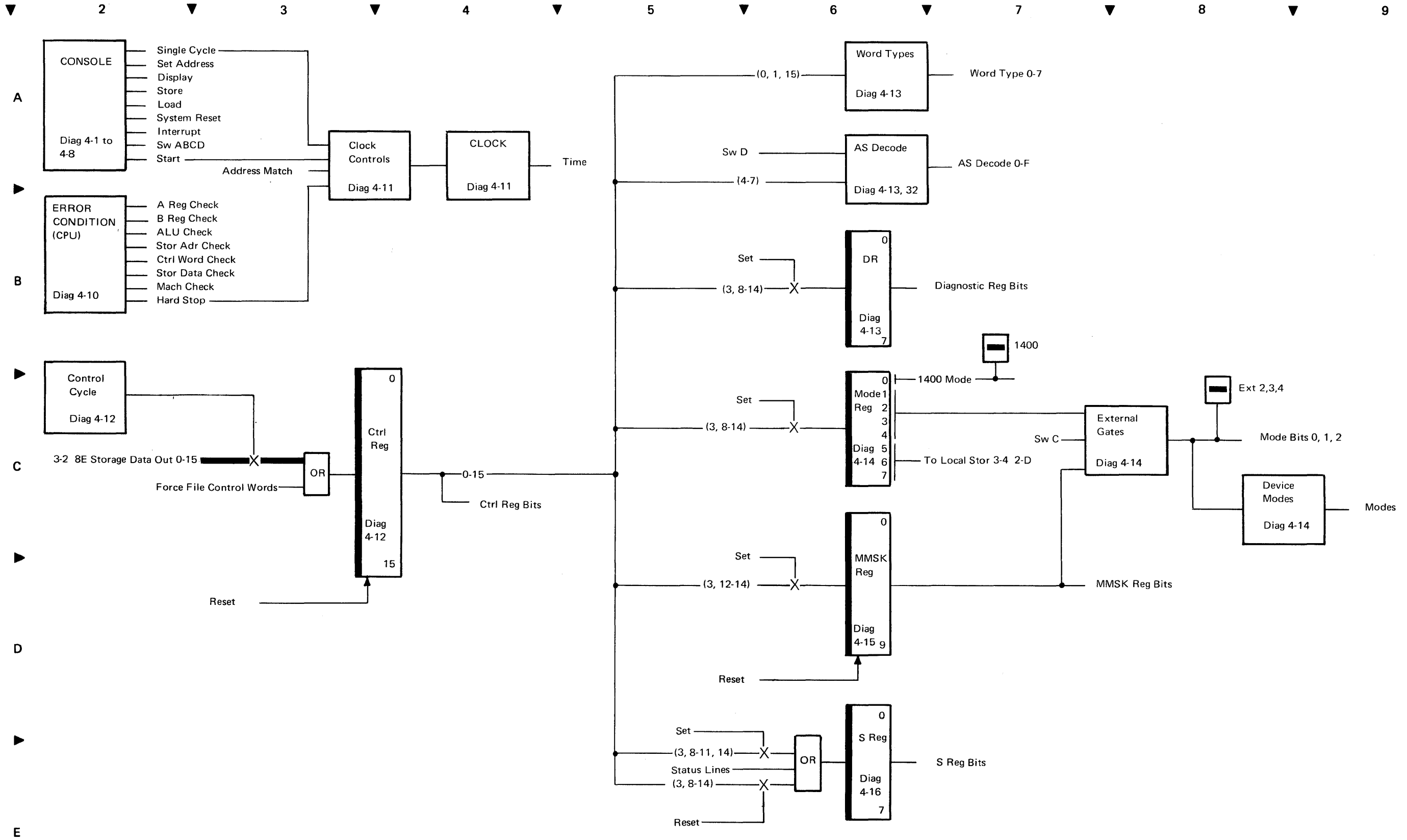


Diagram 3-3. Core Storage and Addressing Data Flow

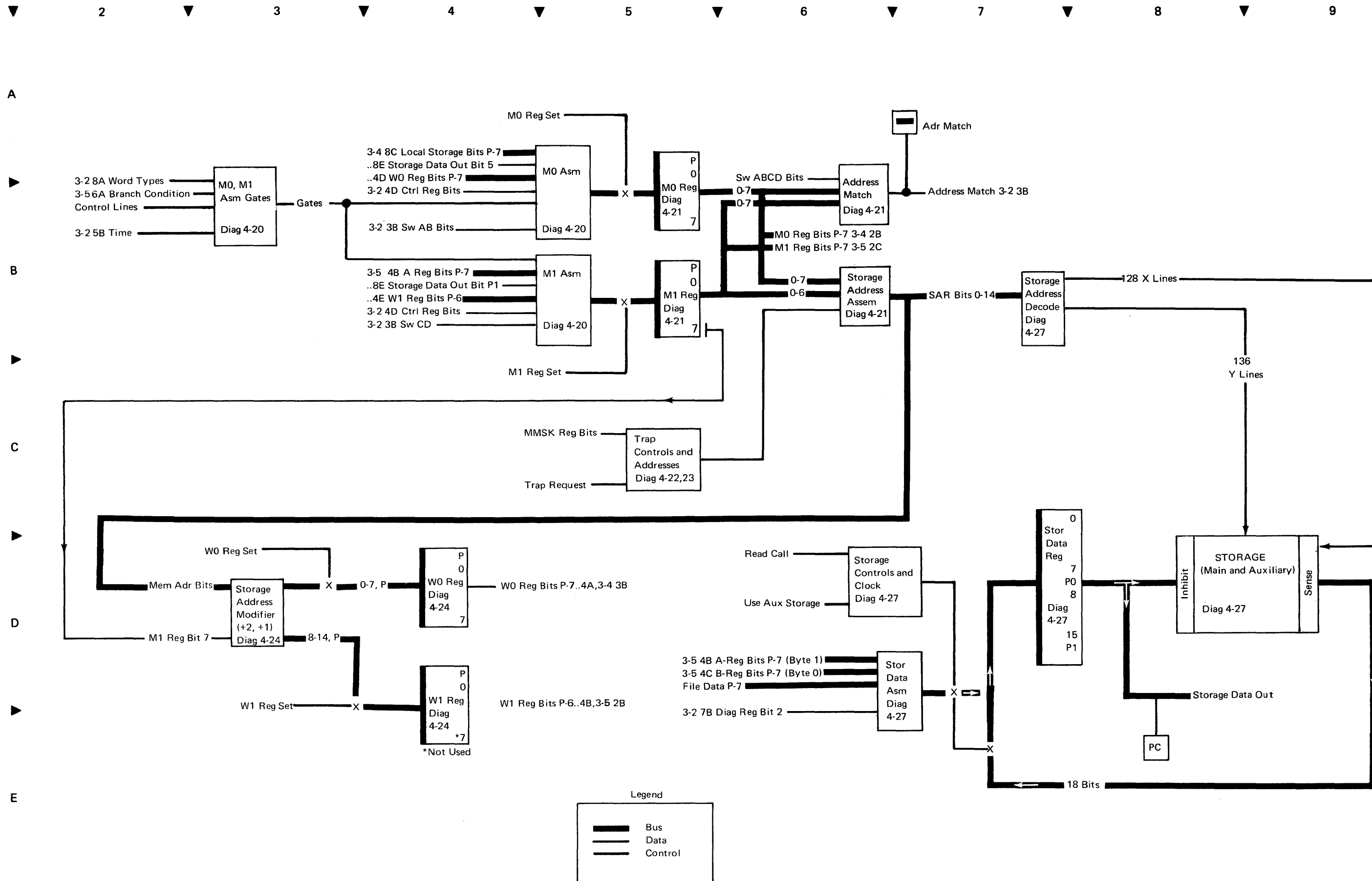
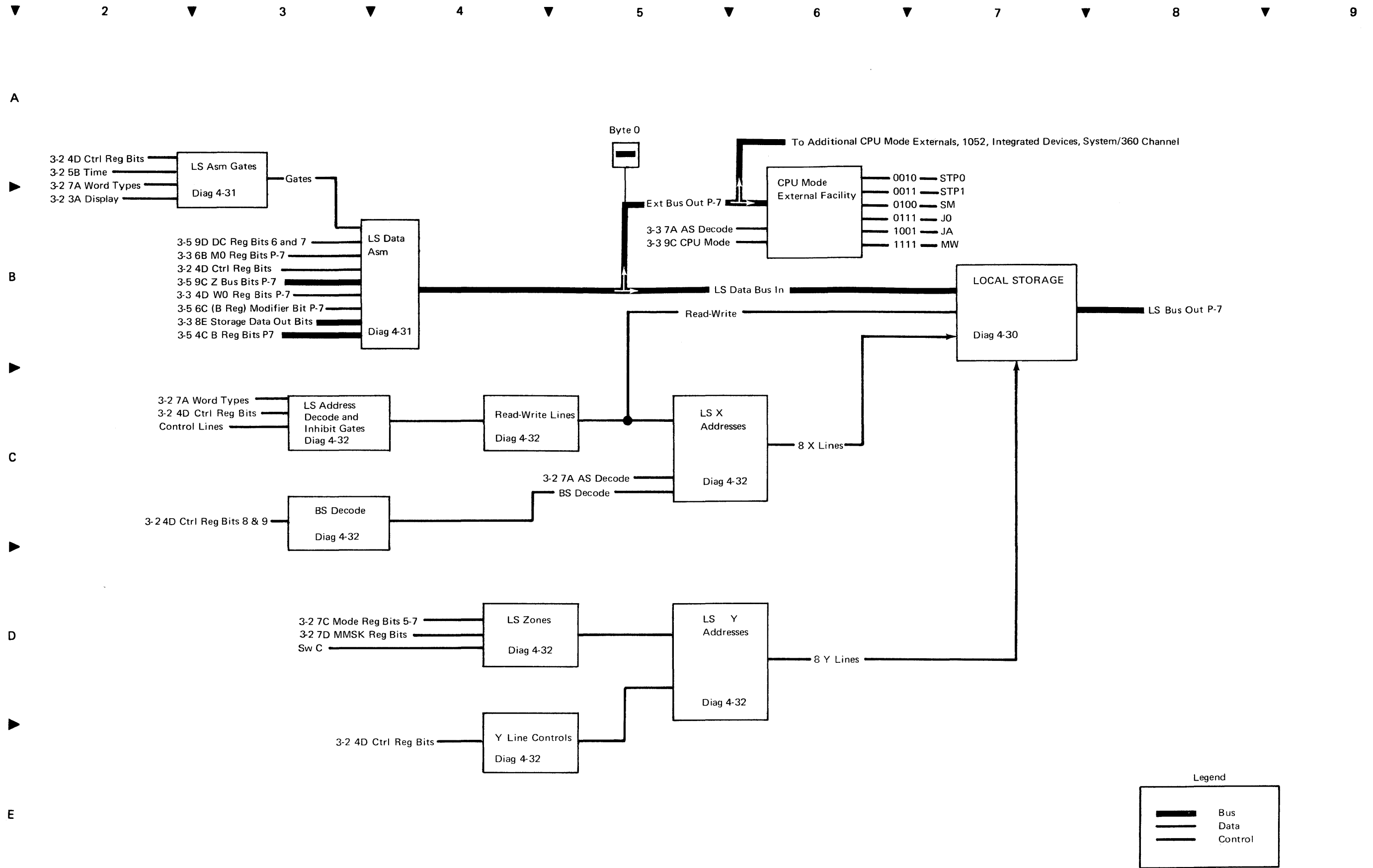


Diagram 3-4. Local Storage Data Flow



A

B

C

D

E

2

3

4

5

6

7

8

9

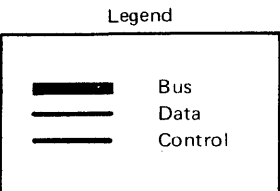


Diagram 3-5. A B Register, ALU, Ext Facility In Data Flow

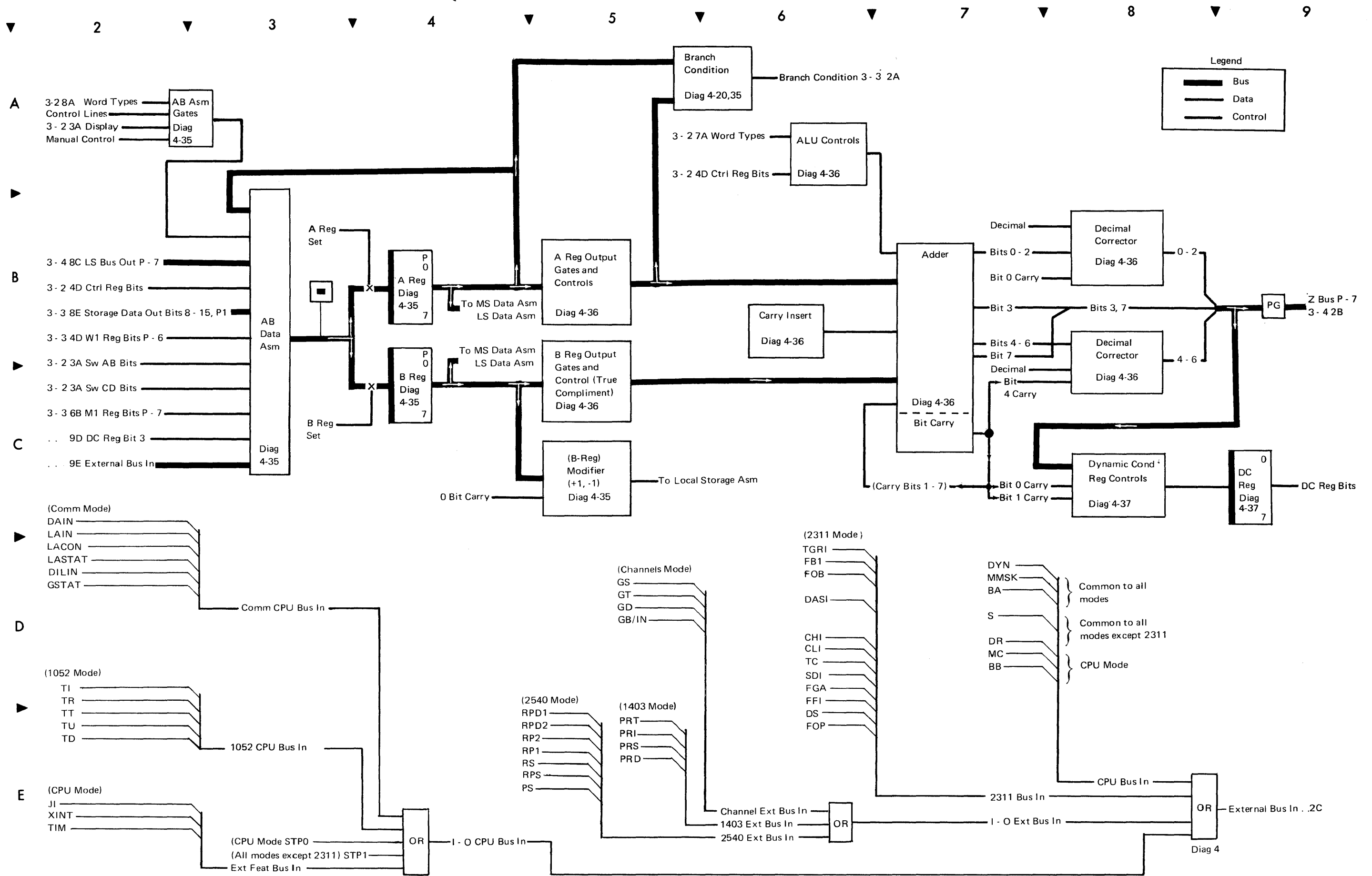


Diagram 3-6. Console Printer-Keyboard Data Flow

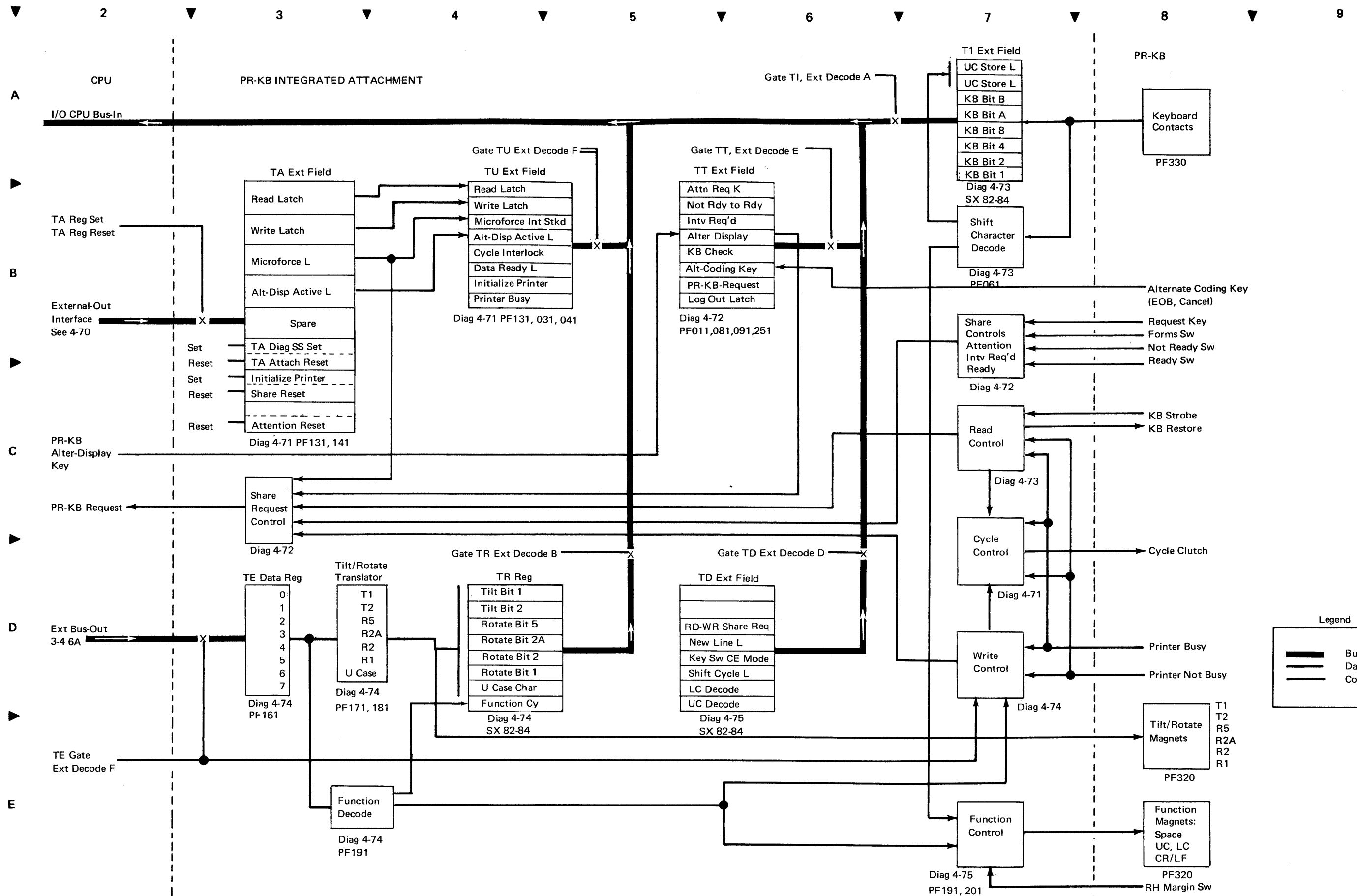


Diagram 3-7. Reader Punch Unit Data Flow

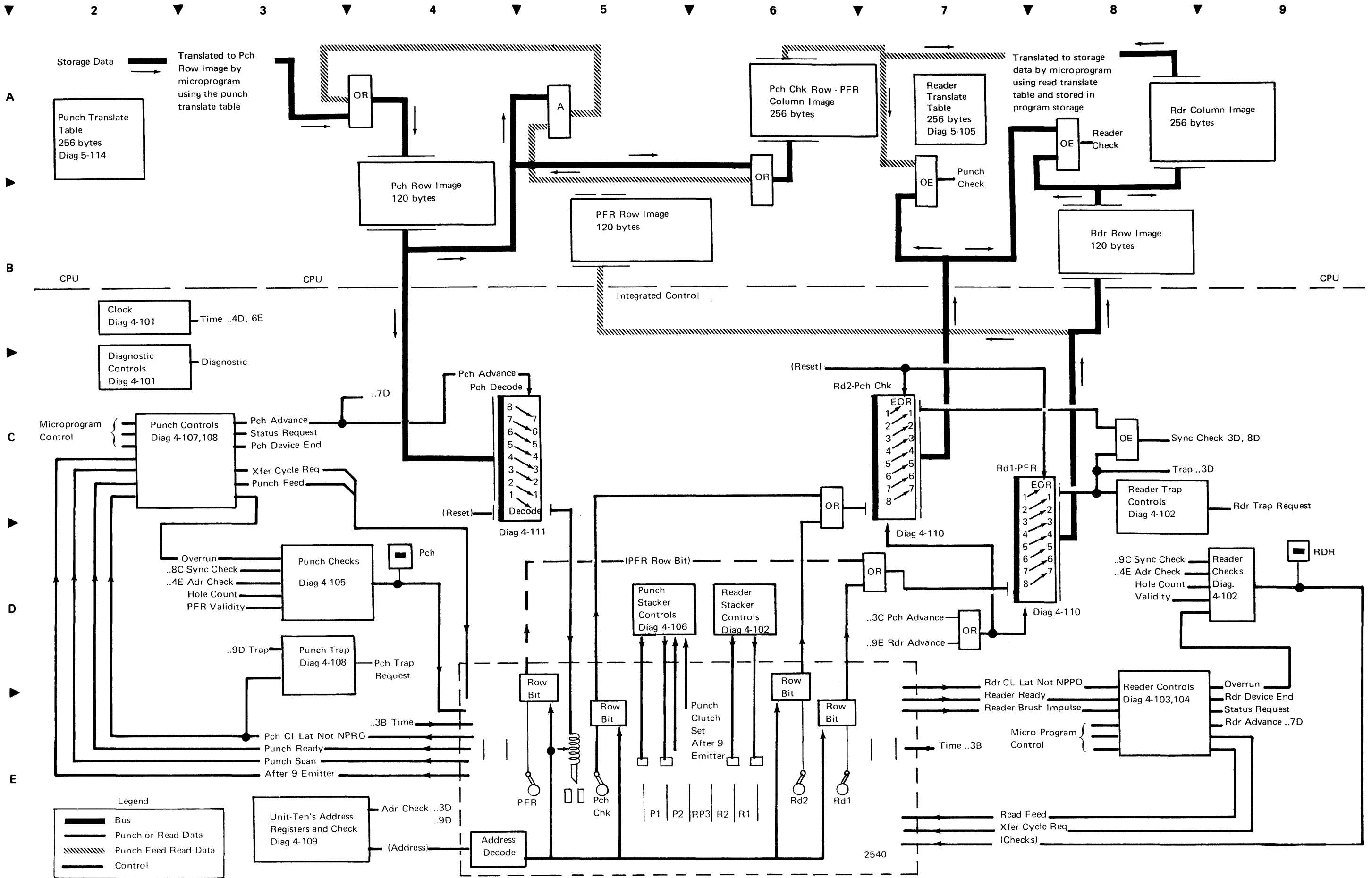
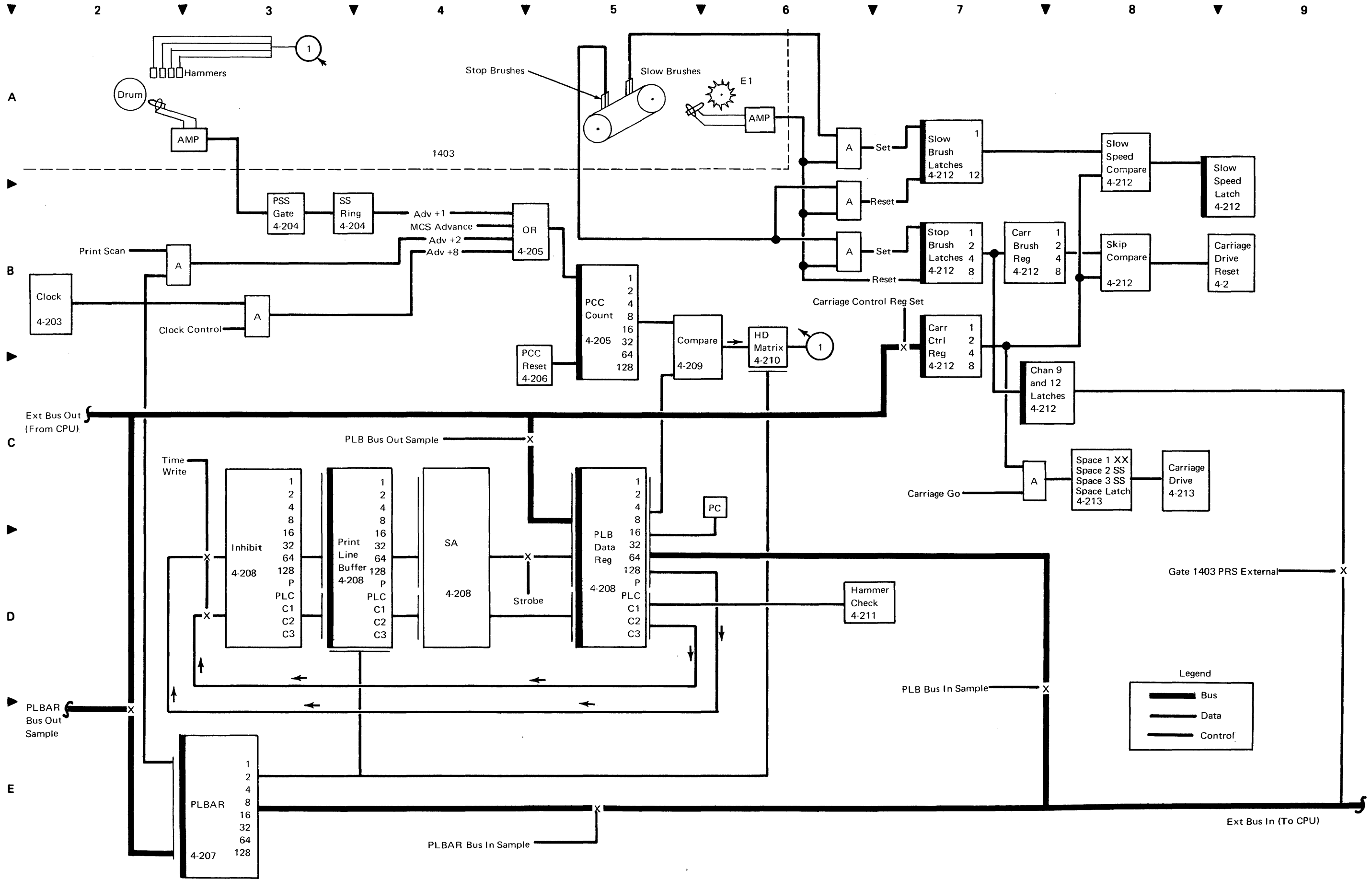


Diagram 3-8. Printer Data Flow



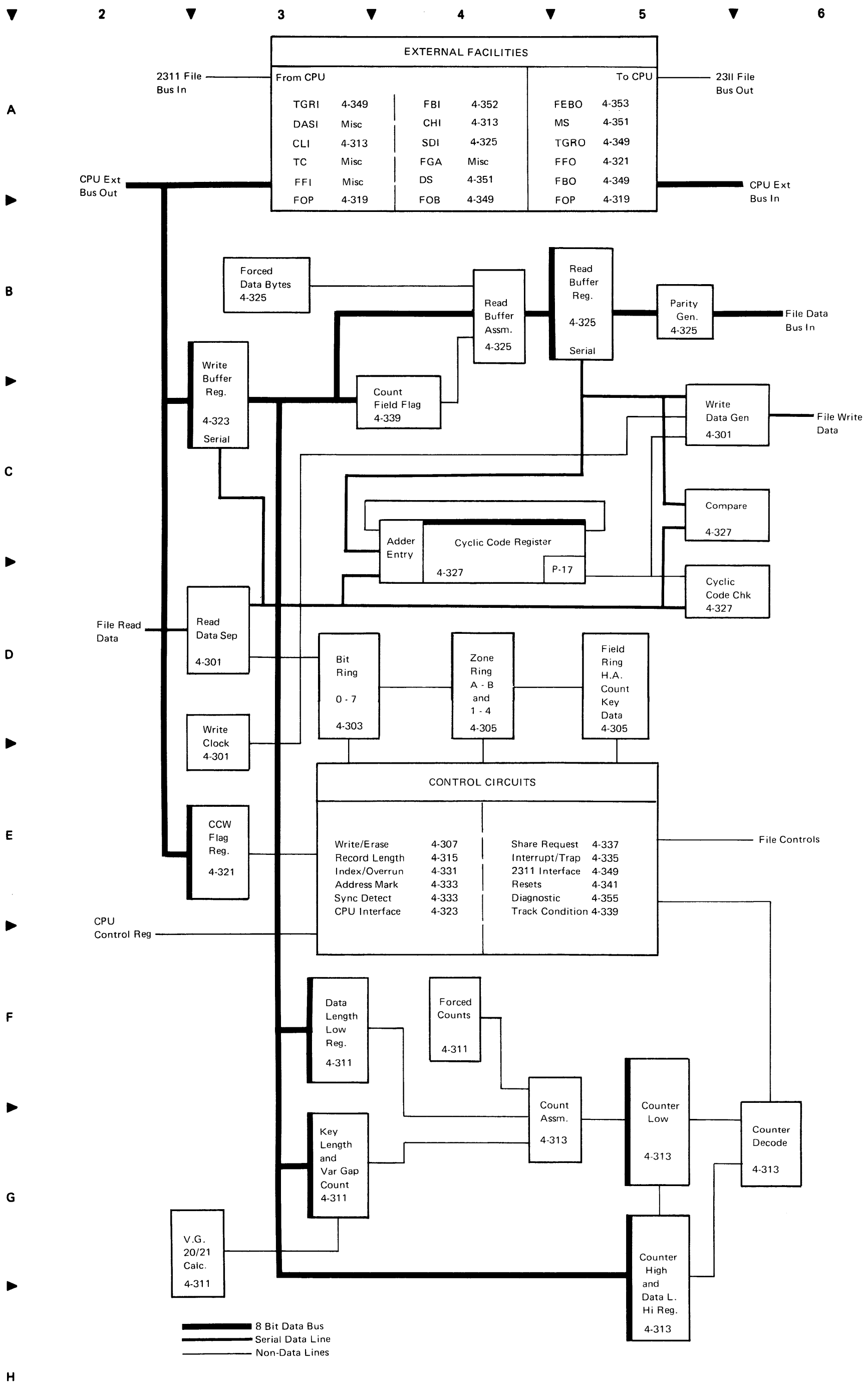


Diagram 3-9. File Control Data Flow

Diagram 3-10. Gating of External Facilities in Channel Operation

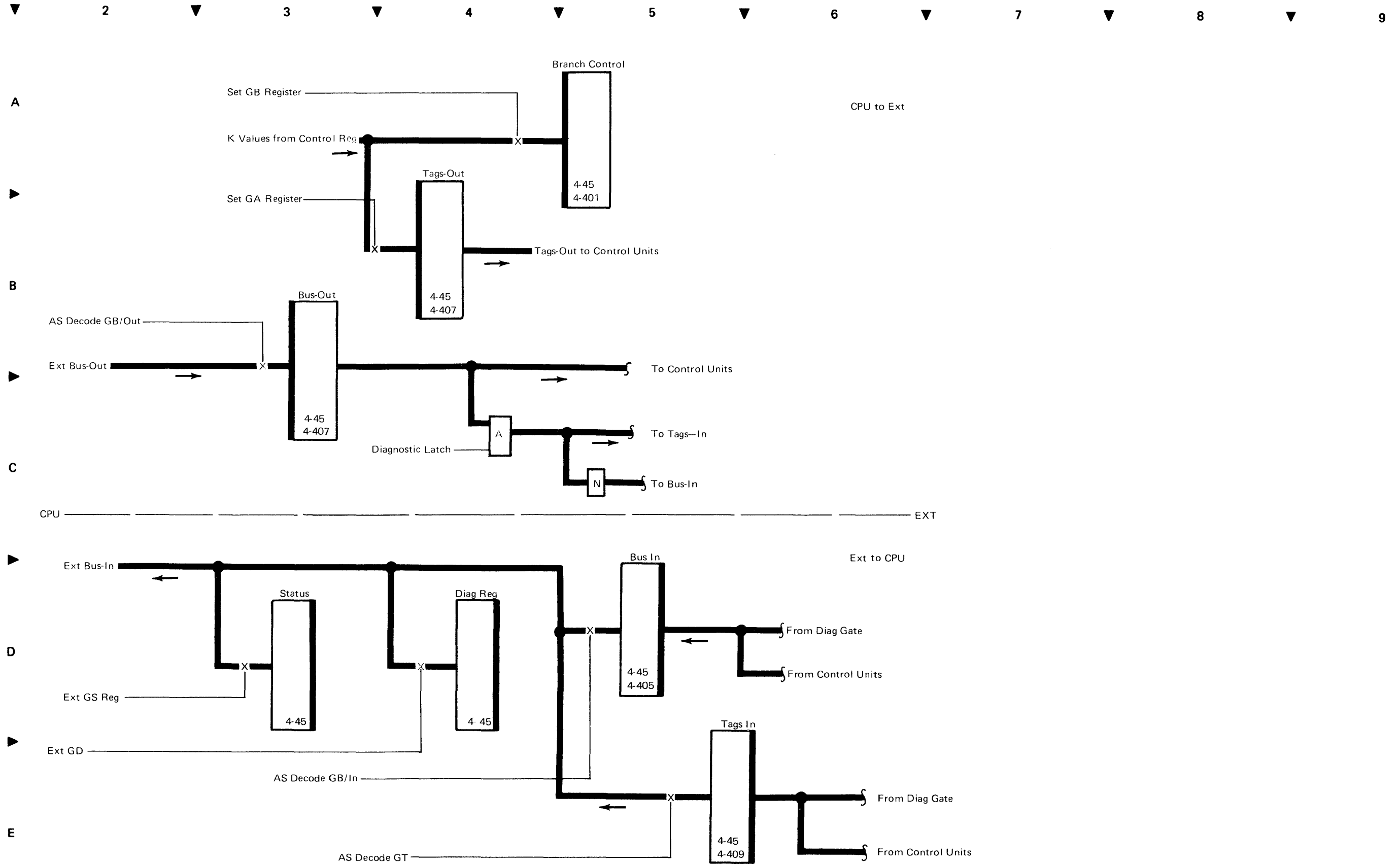


Diagram 3-11. Communications Start/Stop Data Flow

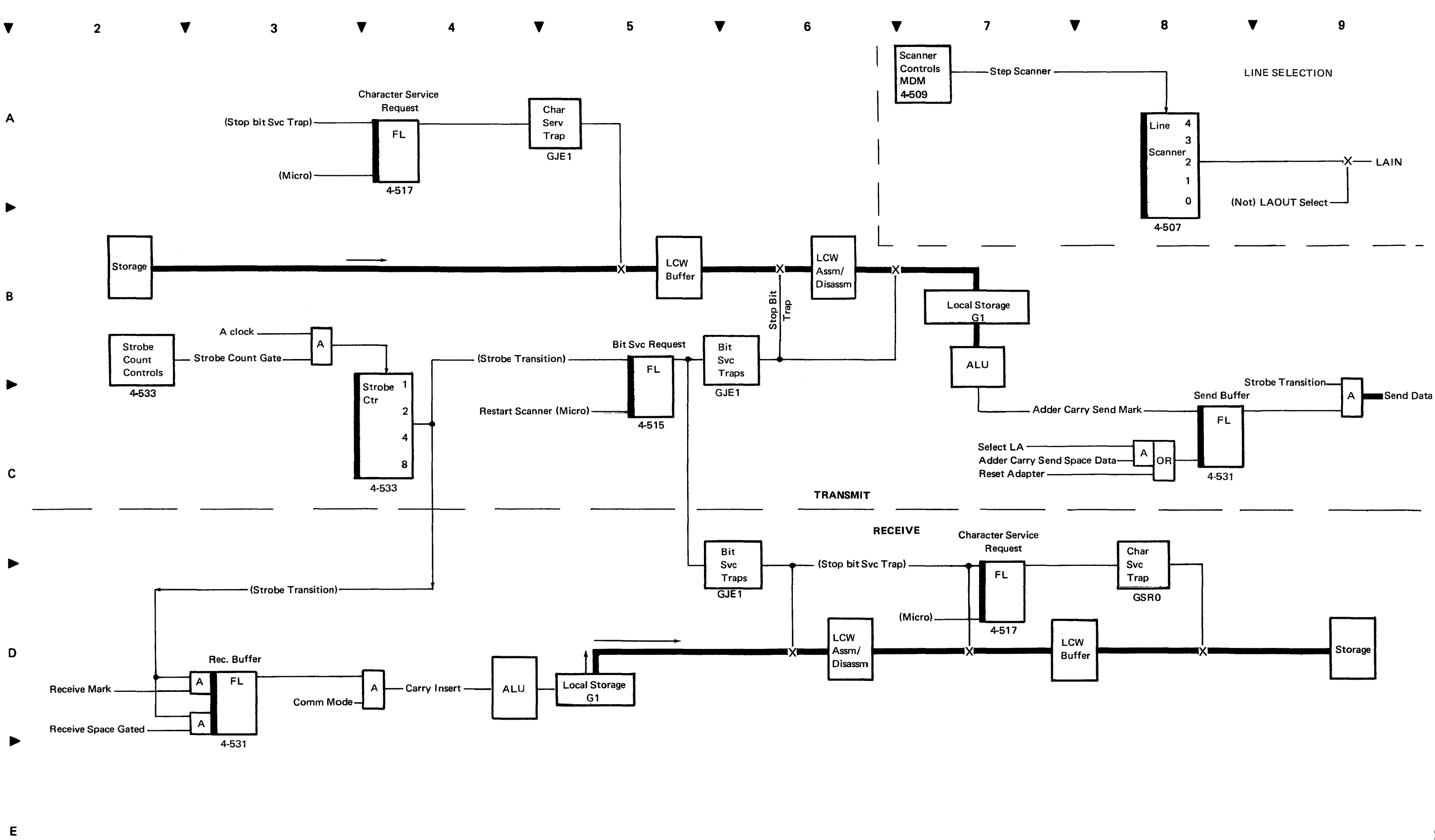


Diagram 3-12. Communications Synchronous Data Flow

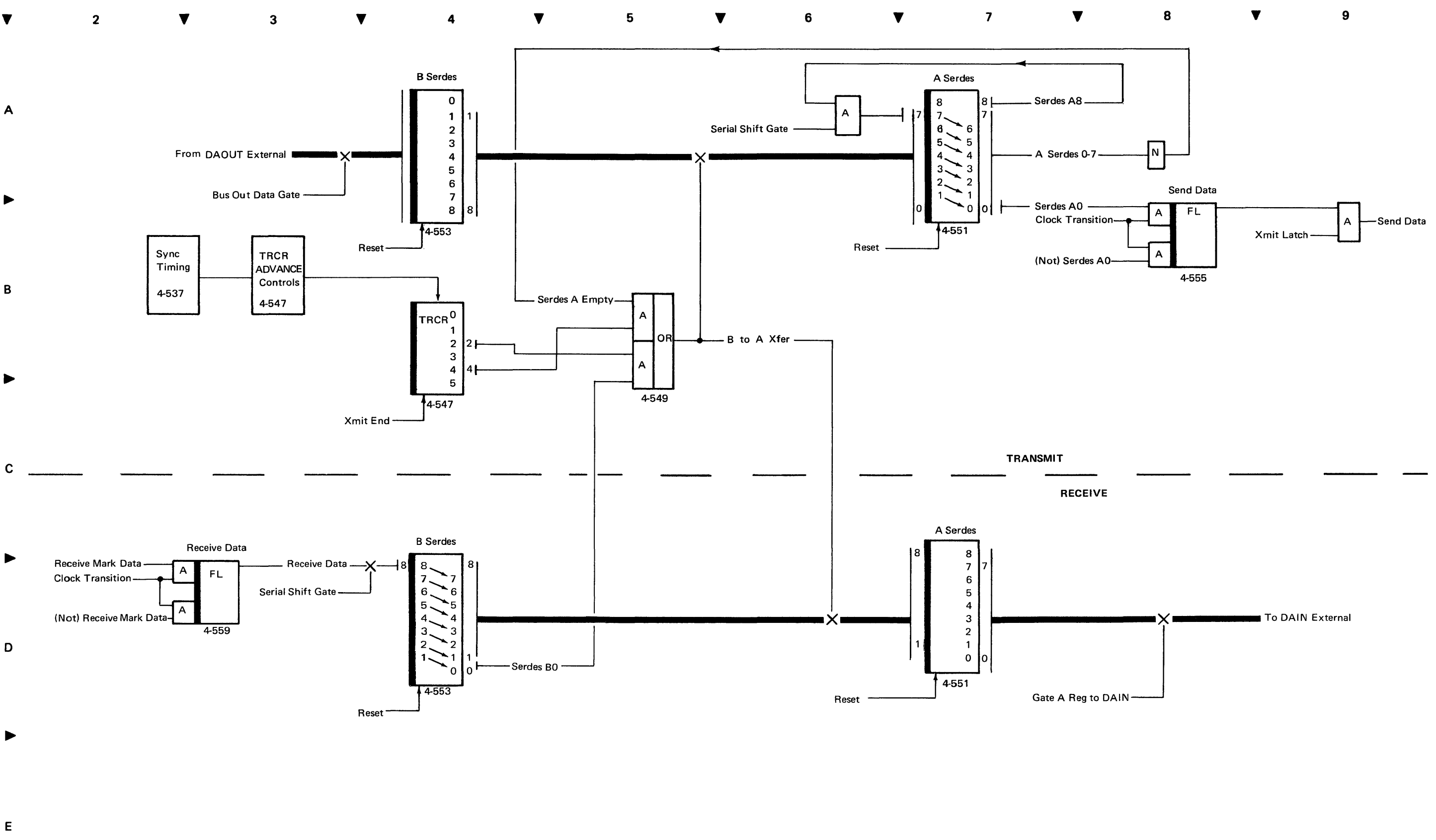


Diagram 4-1. Manual Switches (System Reset, Load, CSL, Start)

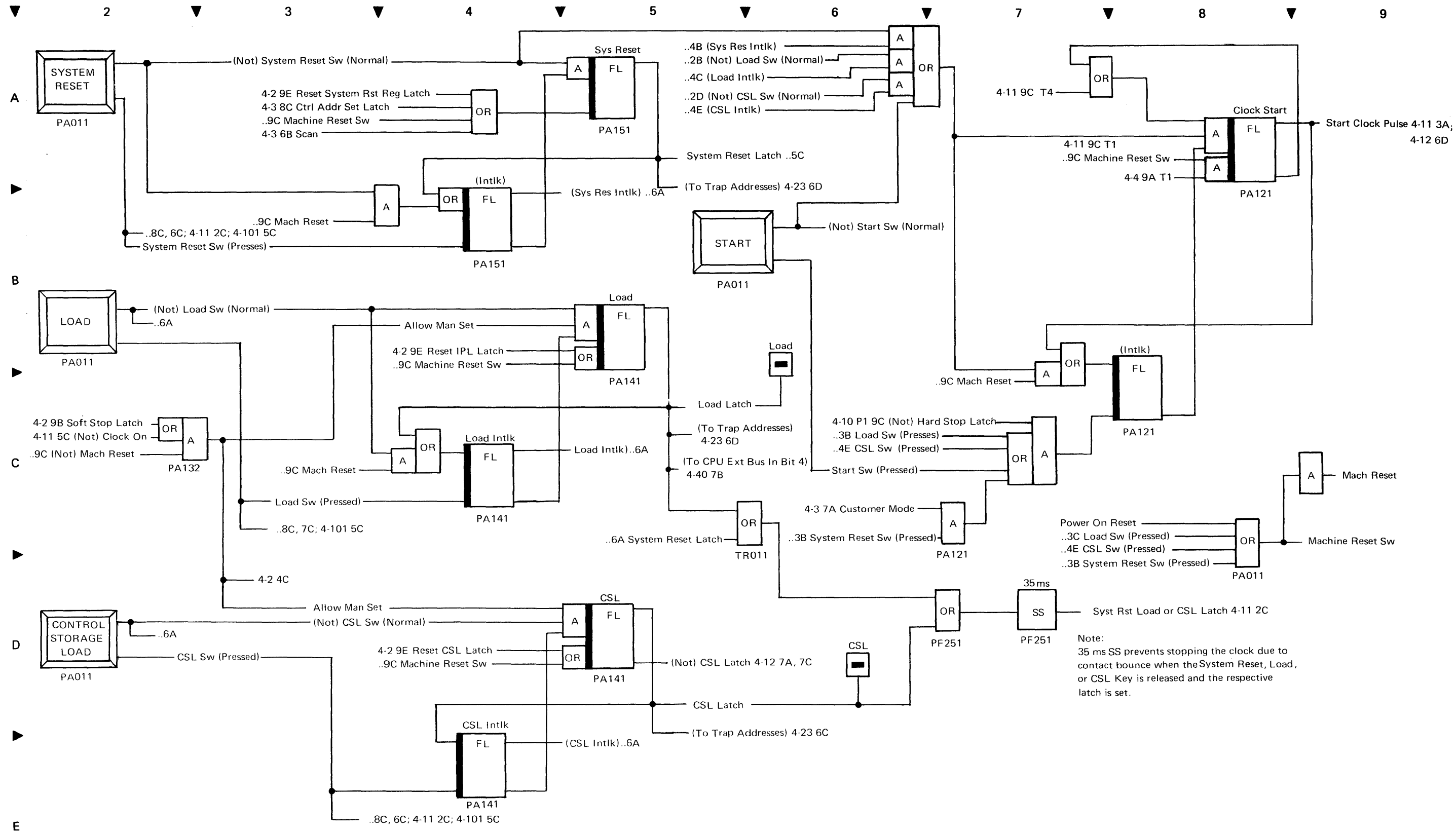


Diagram 4-2. Manual Switches Lamp Test, Set IC, Interrupt, Stop

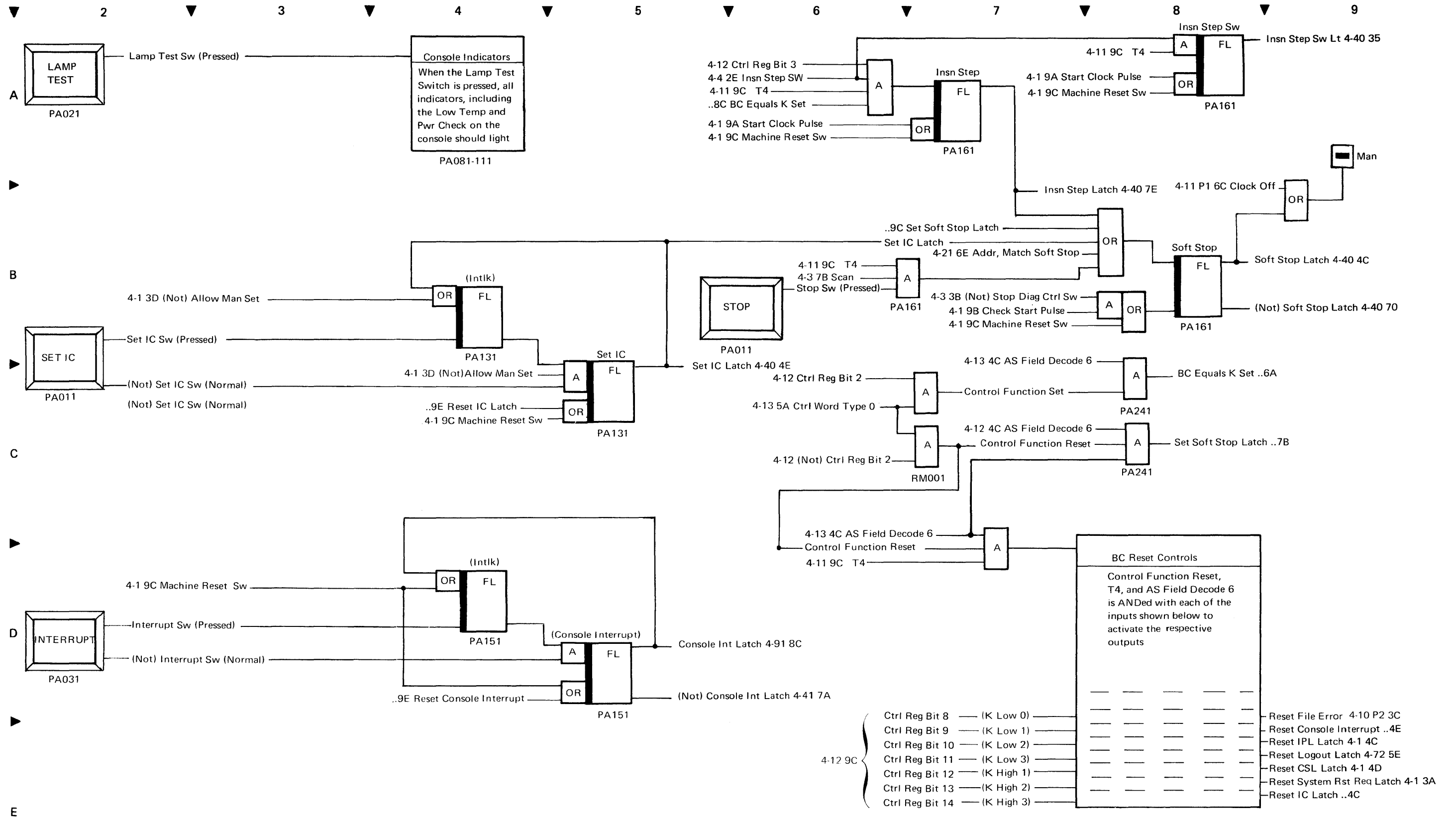


Diagram 4-3. Manual Switches (Check Control, Diagnostic Control, Ctrl Adr Set, A B C D)

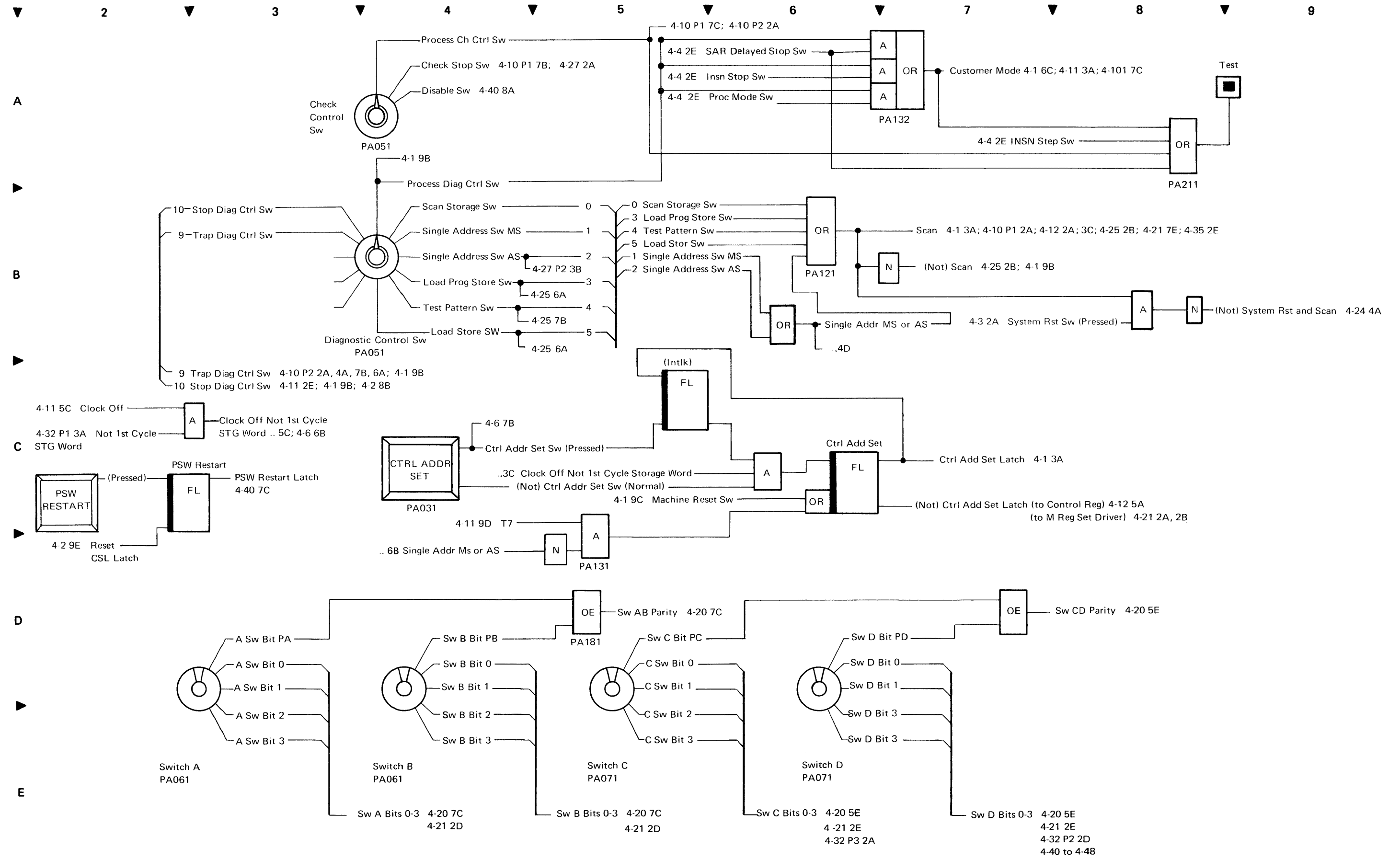


Diagram 4-4. Manual Switches (Display)

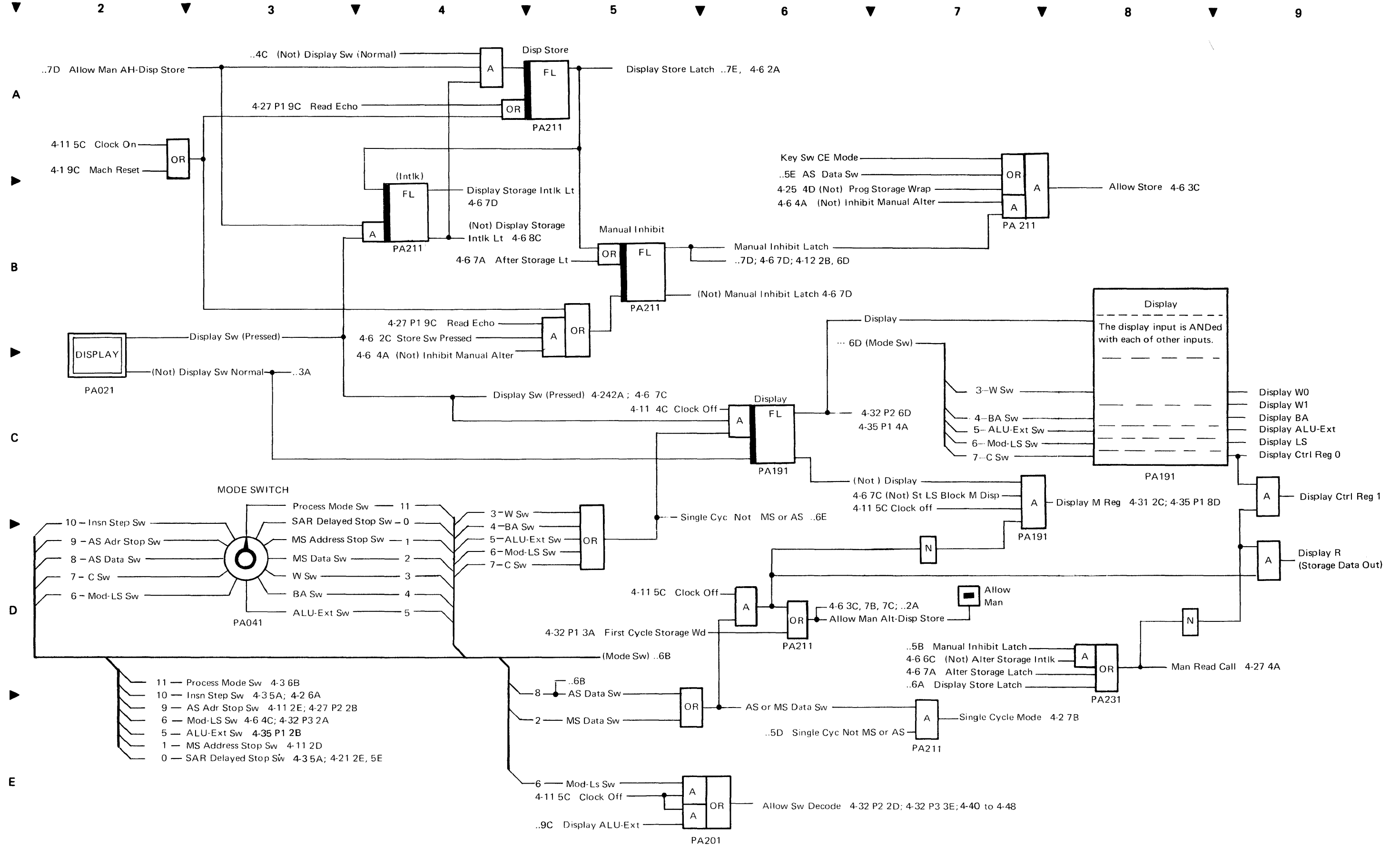
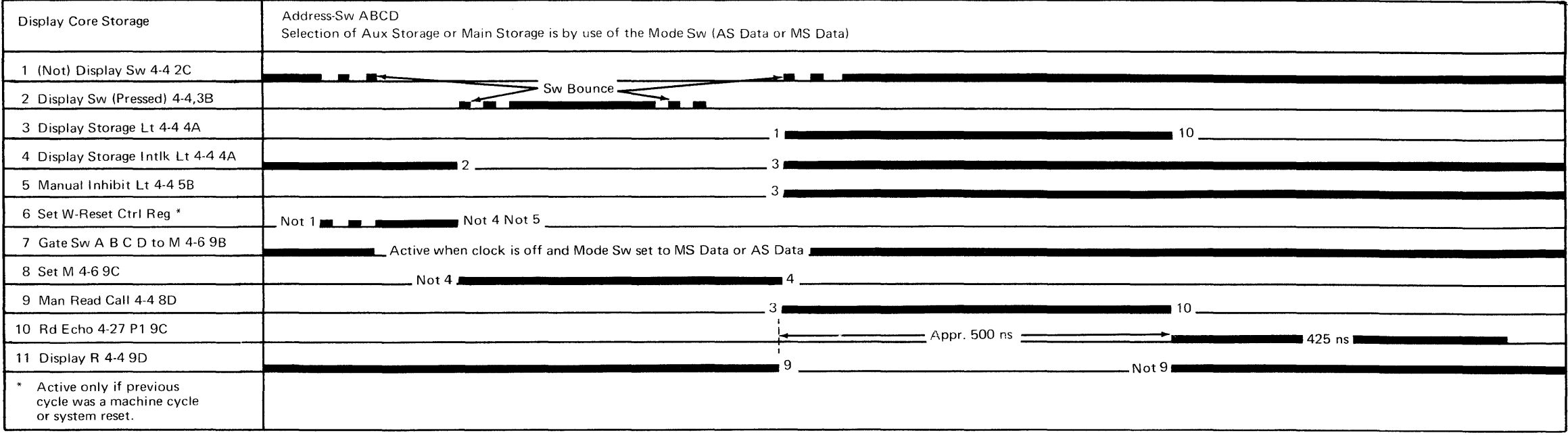


Diagram 4-5. Timing Chart (Display Core Storage)

2 3 4 5 6 7 8 9

A



B

C

D

E

F

Diagram 4-6. Manual Switch (Store)

A
B
C
D
E

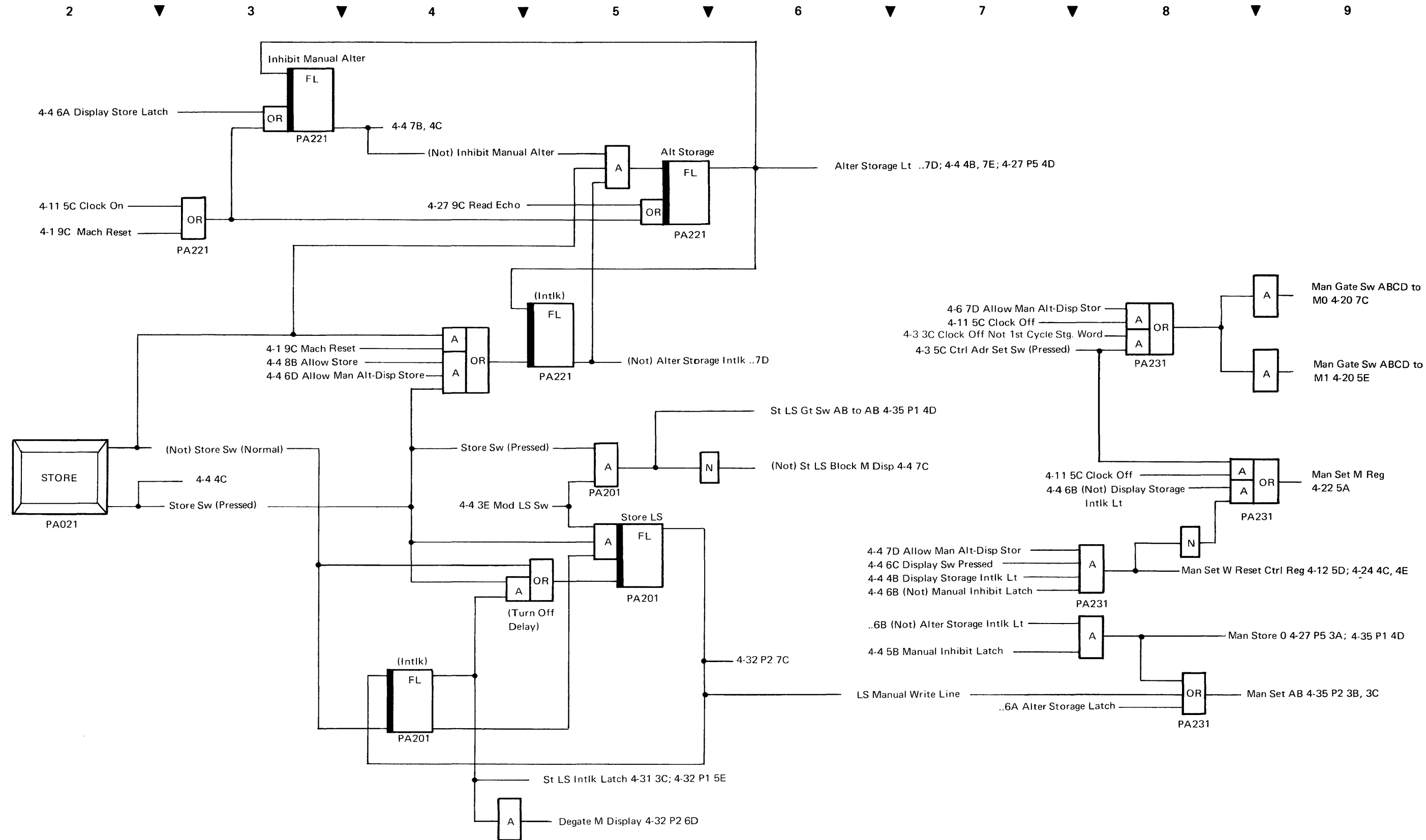


Diagram 4-7. Timing Chart (Store Local Storage, Alter Core Storage)

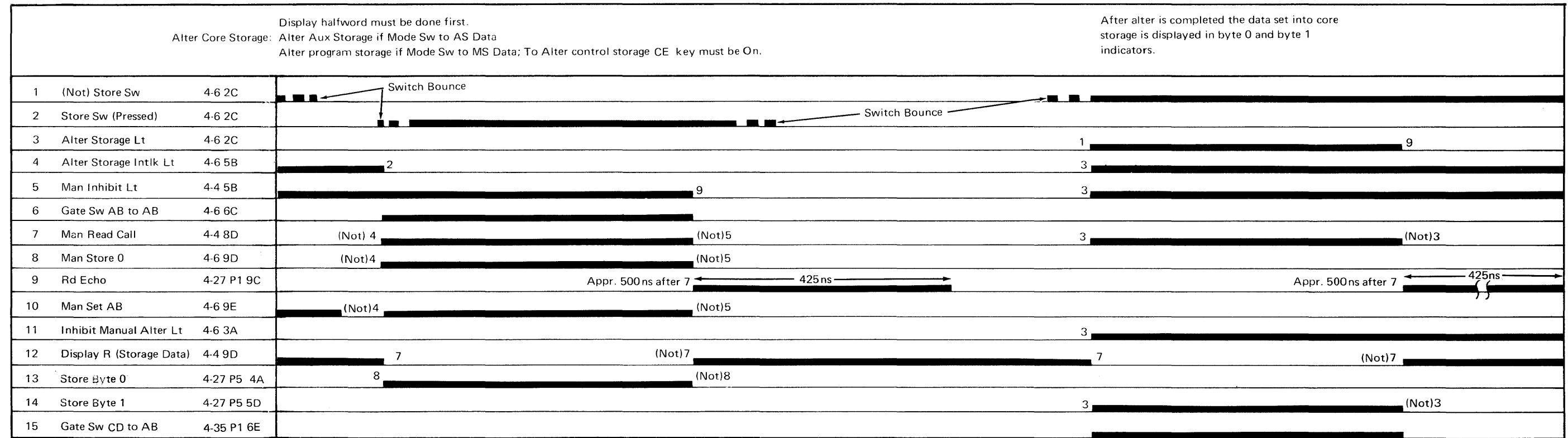
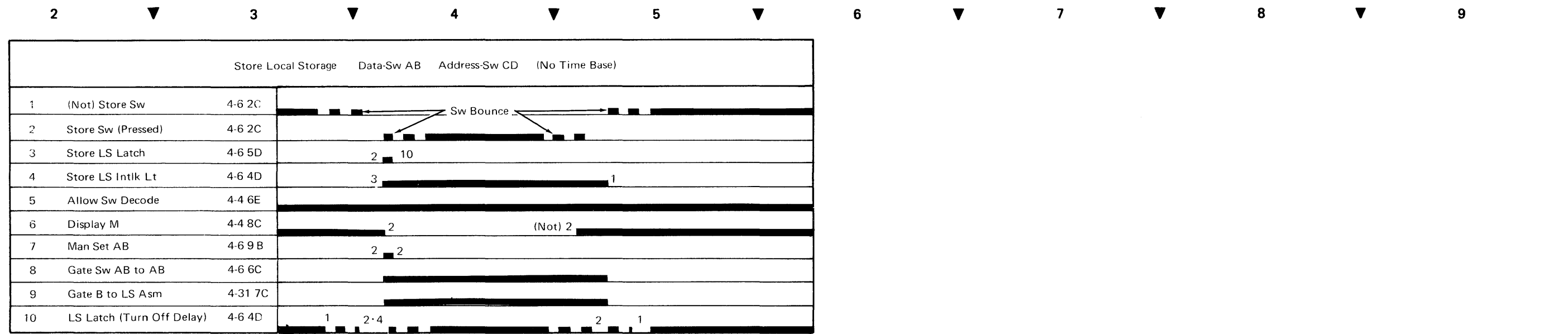


Diagram 4-10. Error Latches (Part 1 of 3)

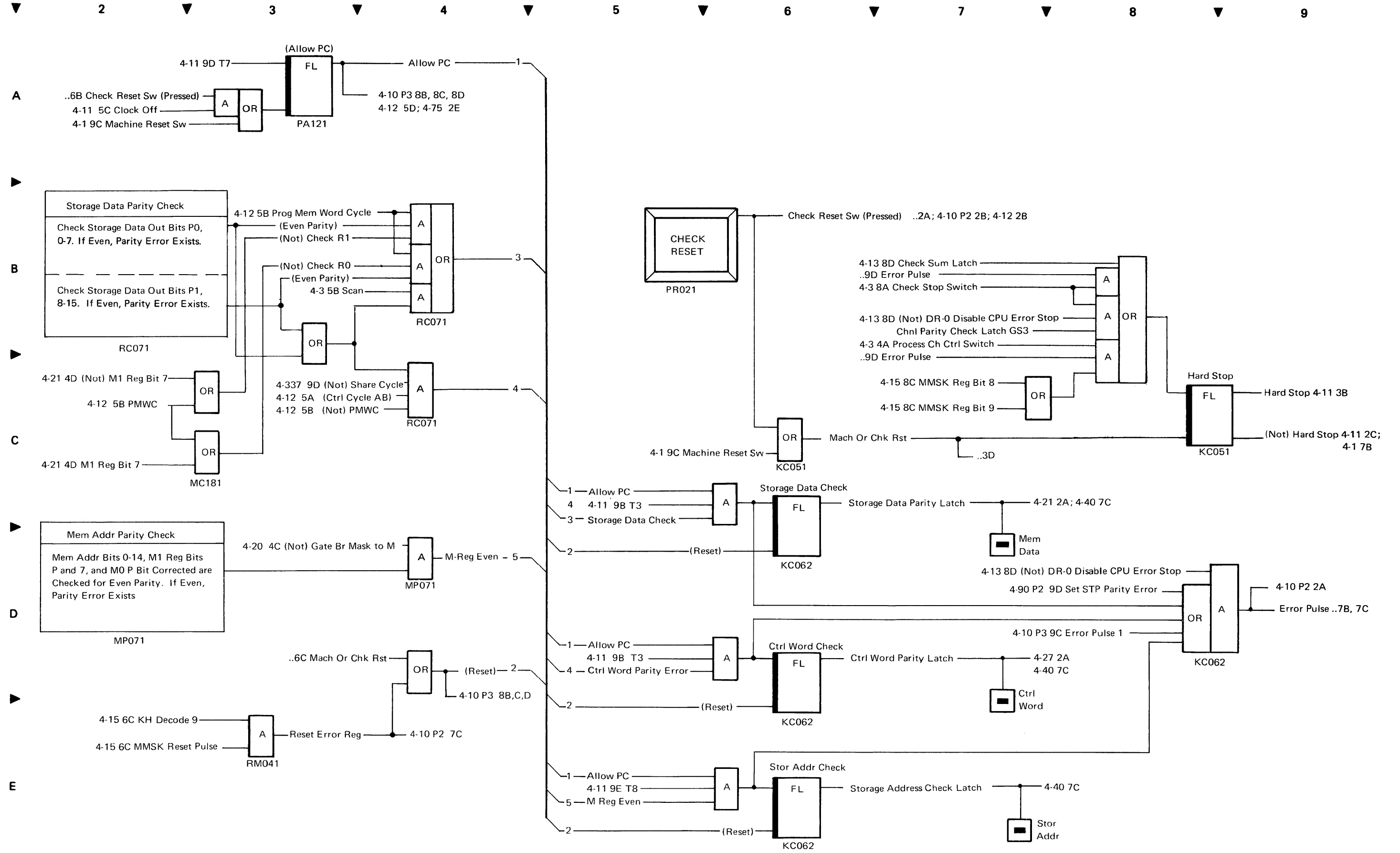
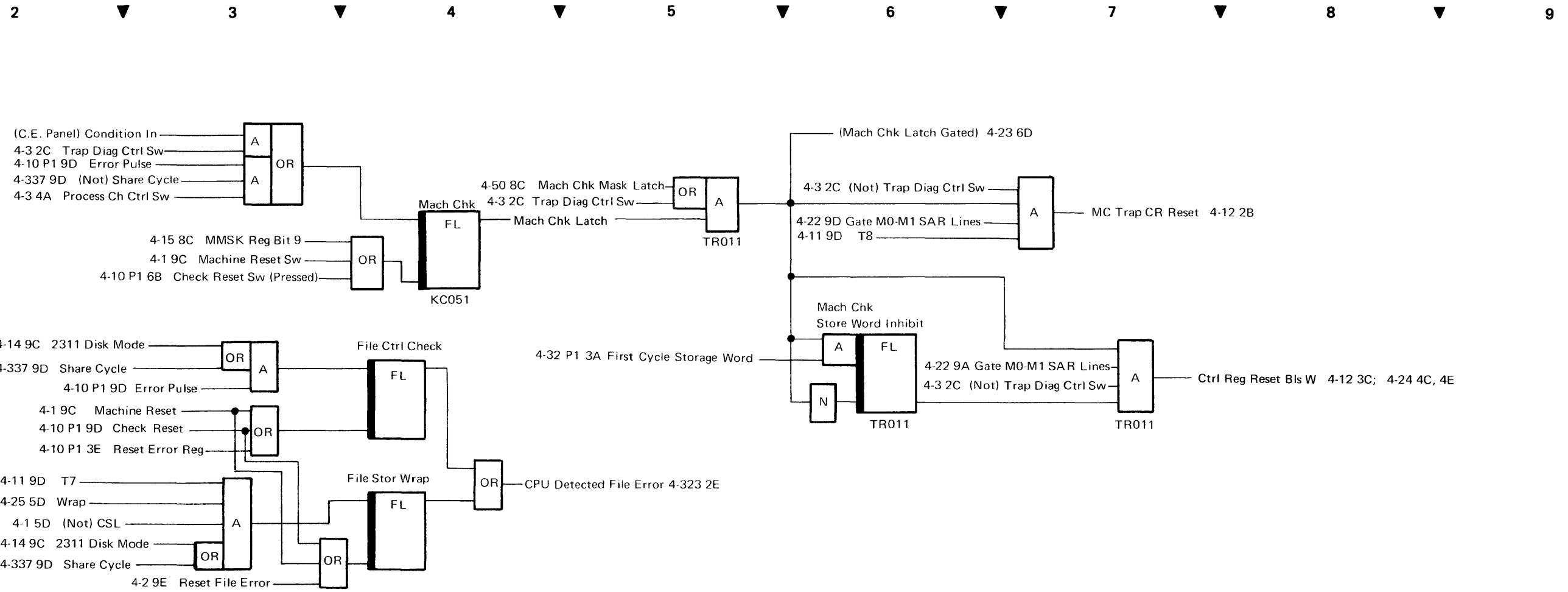


Diagram 4-10. Error Latches (Part 2 of 3)



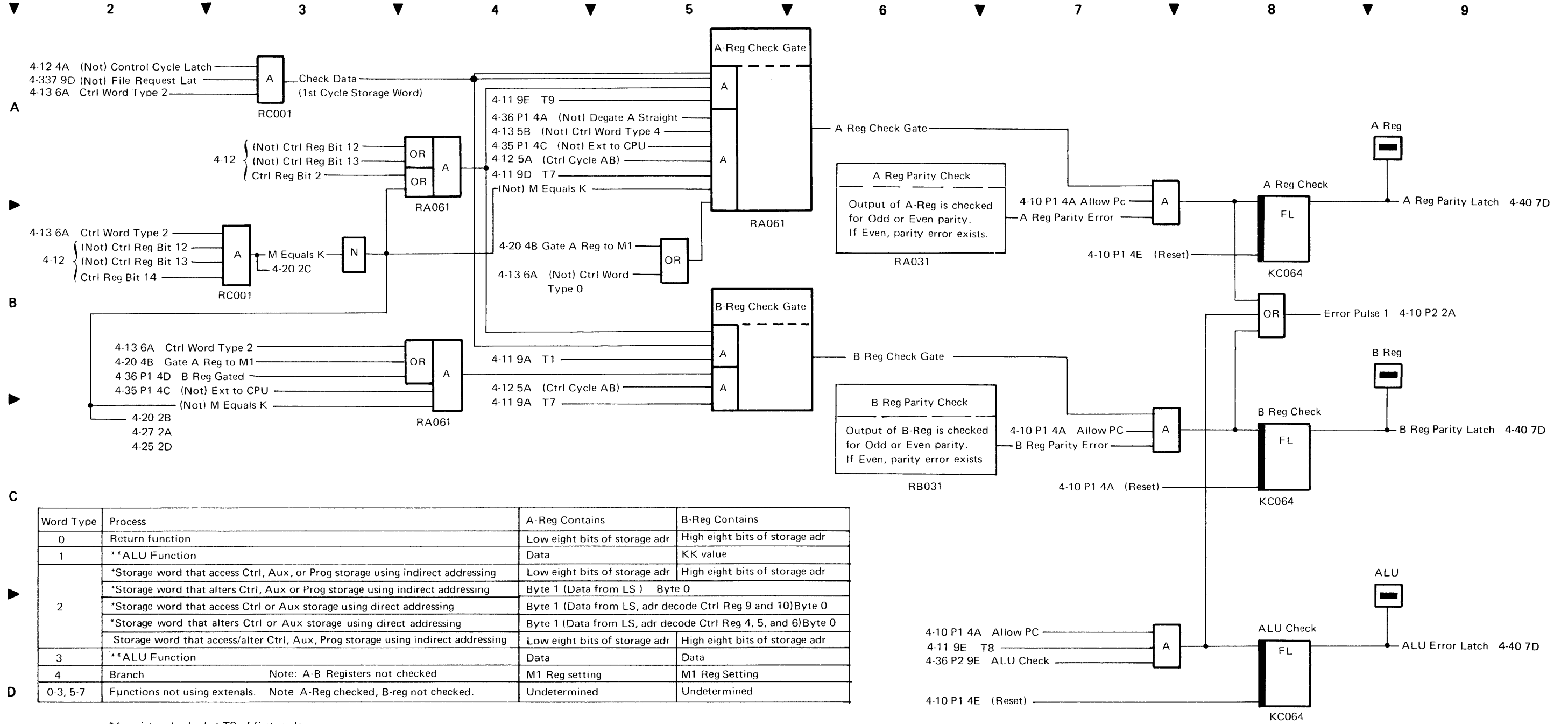
	During Storage Word (Word Type 2)			During Word Types 0, 1, 3-7		
	T0	T0	T0	T0	T0	T0
Mach Chk Trap with Trap Diag Ctrl Sw Off	1 st Cycle Stor Wd	2 nd Cycle Stor Wd	1 st Wd of Trap	Ctrl Word X	* No Operation	1 st Wd of Trap
1 Mach Chk Latch 4-10 4A	[Signal Pulse]			[Signal Pulse]		
2 Mch Chk Stor Word Inh Lt 4-10 6B	[Signal Pulse]			[Signal Pulse]		
3 Gate M0-M1 to SAR Lines 4-22 9A	[Signal Pulse]			[Signal Pulse]		
4 Ctrl Cycle Lt 4-12 4A	[Signal Pulse]			[Signal Pulse]		
5 MC Trap CR Reset 4-10 7A	[Signal Pulse]			[Signal Pulse]		
6 Ctrl Reg Reset Bls W 4-10 8B	[Signal Pulse]			[Signal Pulse]		
7 Ctrl Reg Reset 4-12 6D	[Signal Pulse]			[Signal Pulse]		
8 Mach Chk Mask Latch 4-50 8D	[Signal Pulse]			[Signal Pulse]		

Note 1: Reset does not occur when the Trap Diag Ctrl Sw is on.

Note 2: Second cycle of storage word normally blocks set C-register and set W-register.

* No operation occurs during this cycle; cycle is required to save the address + 2 where the error occurred. Ctrl reg is reset at T0 of the no operation cycle and is not set.

Diagram 4-10. Error Latches (Part 3 of 3)



Word Type	Process	A-Reg Contains	B-Reg Contains
0	Return function	Low eight bits of storage adr	High eight bits of storage adr
1	**ALU Function	Data	KK value
2	*Storage word that access Ctrl, Aux, or Prog storage using indirect addressing	Low eight bits of storage adr	High eight bits of storage adr
	*Storage word that alters Ctrl, Aux or Prog storage using indirect addressing	Byte 1 (Data from LS)	Byte 0
	*Storage word that access Ctrl or Aux storage using direct addressing	Byte 1 (Data from LS, adr decode Ctrl Reg 9 and 10)	Byte 0
	*Storage word that alters Ctrl or Aux storage using direct addressing	Byte 1 (Data from LS, adr decode Ctrl Reg 4, 5, and 6)	Byte 0
	Storage word that access/alter Ctrl, Aux, Prog storage using indirect addressing	Low eight bits of storage adr	High eight bits of storage adr
3	**ALU Function	Data	Data
4	Branch Note: A-B Registers not checked	M1 Reg setting	M1 Reg Setting
D	0-3, 5-7 Functions not using externals. Note: A-Reg checked, B-reg not checked.	Undetermined	Undetermined

*A-register checked at T9 of first cycle.
B-register checked at T1 of second cycle.

**A-register and/or B-register checked if gated.

Diagram 4-11. Clock Logic (Part 1 of 2)

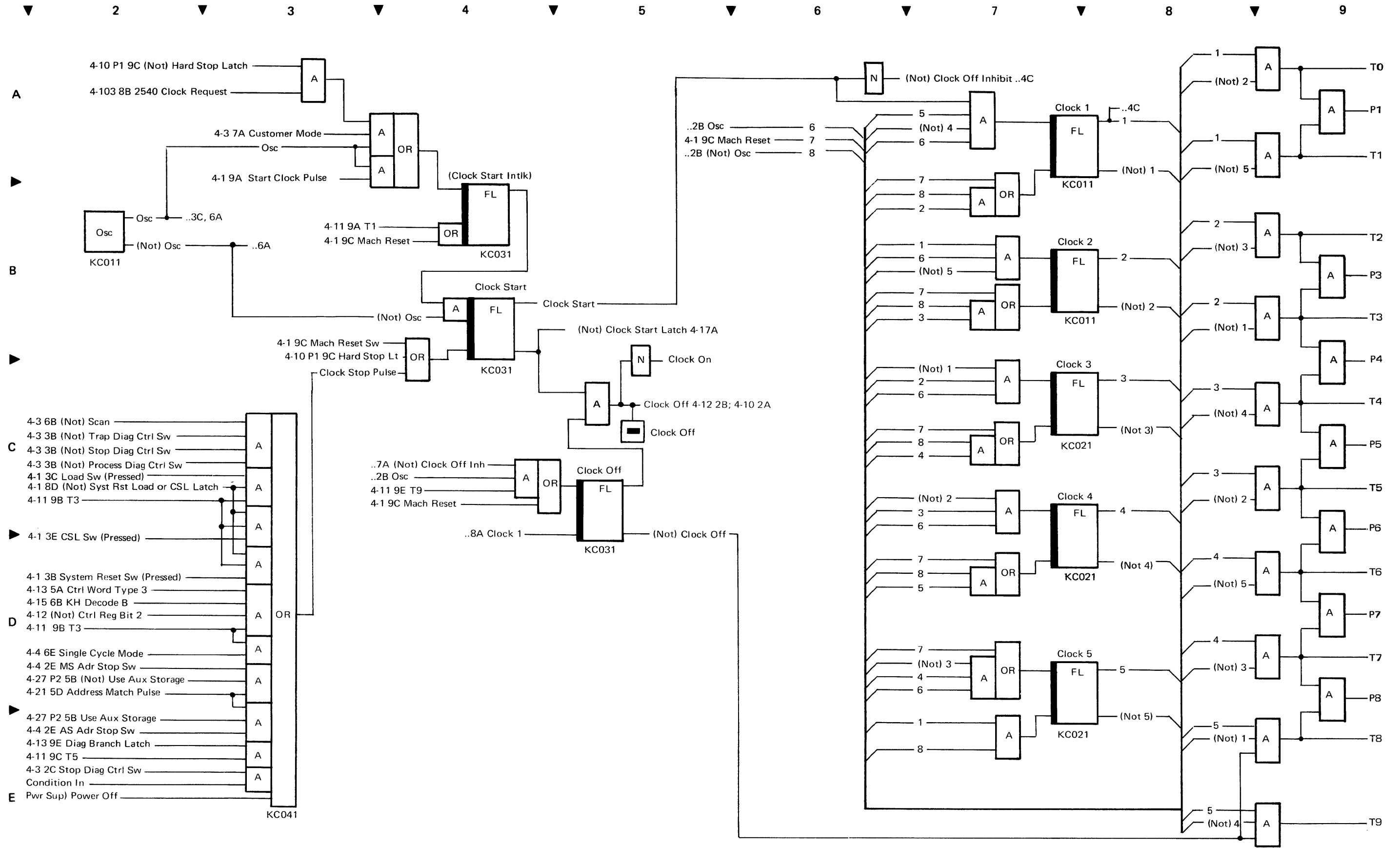
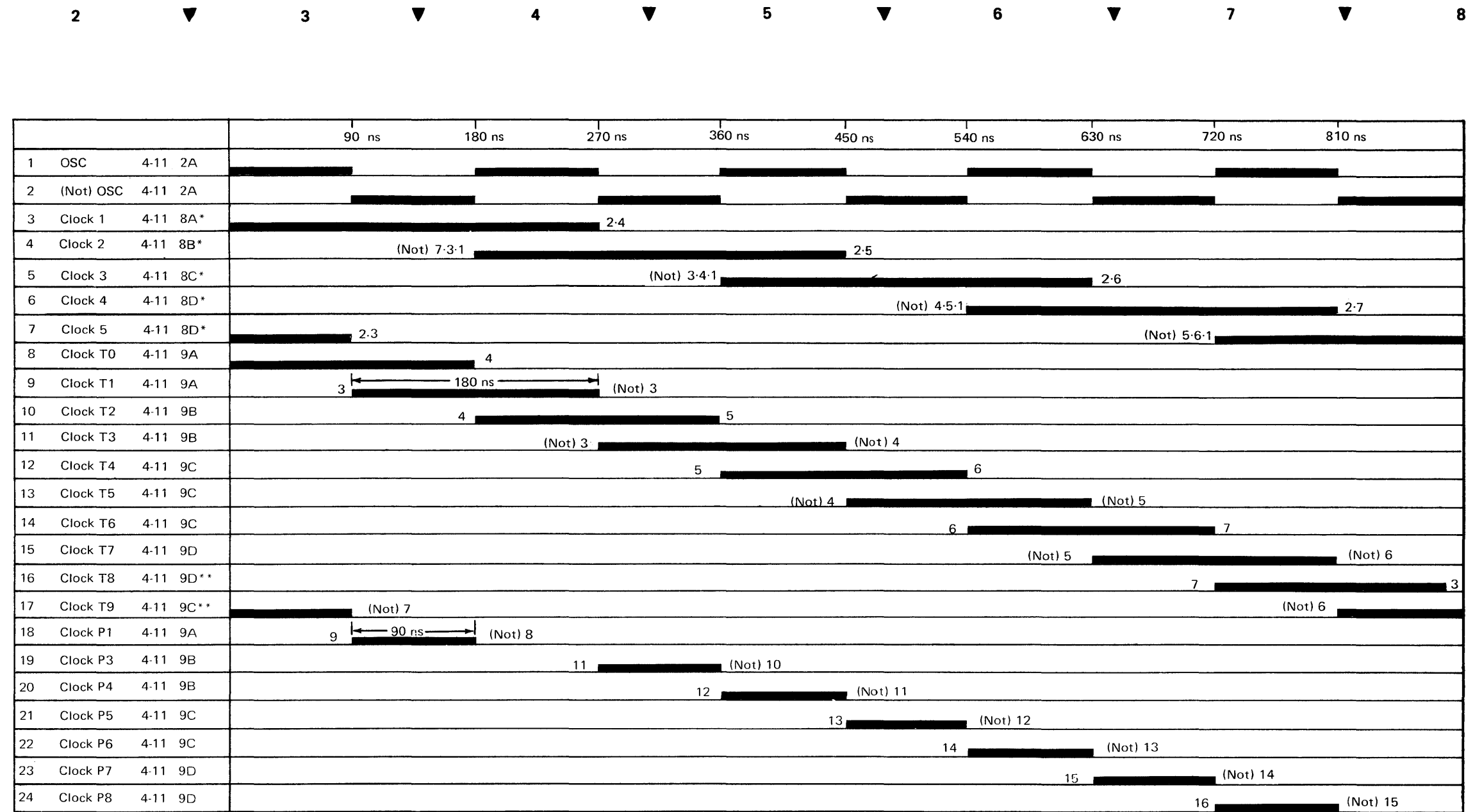


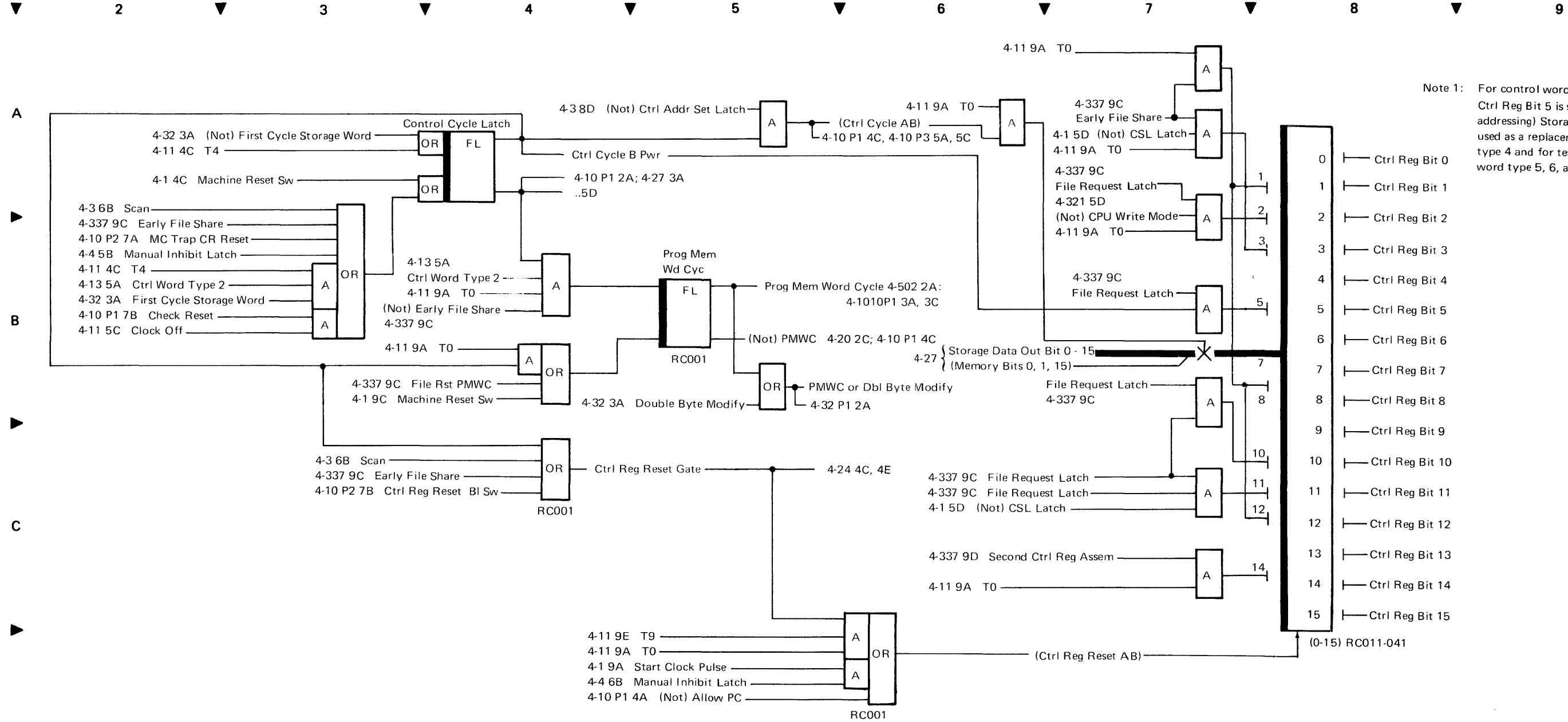
Diagram 4-11. Clock Timing (Part 2 of 2)



*Machine reset turns Clock 1, 2, 3, and 4 off and turns Clock 5 on.

**When clock is off these lines are blocked.

Diagram 4-12. Control Register



Note 1: For control word types 4, 5, 6, and 7 Ctrl Reg Bit 5 is set to a 1 (limits register addressing) Storage Data Out Bit 5 is used as a replacement bit for word type 4 and for testing A-Reg gates on word type 5, 6, and 7.

Control Register	T0		
	Control Cycle (Non Branch)	Storage Word (Read or Store)	Control Cycle (Non Branch)
1 First Cycle Storage Word		█	
2 Control Cycle Latch	█	█	█
3 Prog Mem Wd Cyc Lt		█	
4 Ctrl Reg Reset	█		█
5 Ctrl Reg Set	█		█
6 Set W	█		█
7 Set M	█ From W	█ From LS	█ From W
8 Ctrl Reg	█	█	█

D

E

Diagram 4-13. Ctrl Word Decode, AS Field Decode, Diagnostic Register

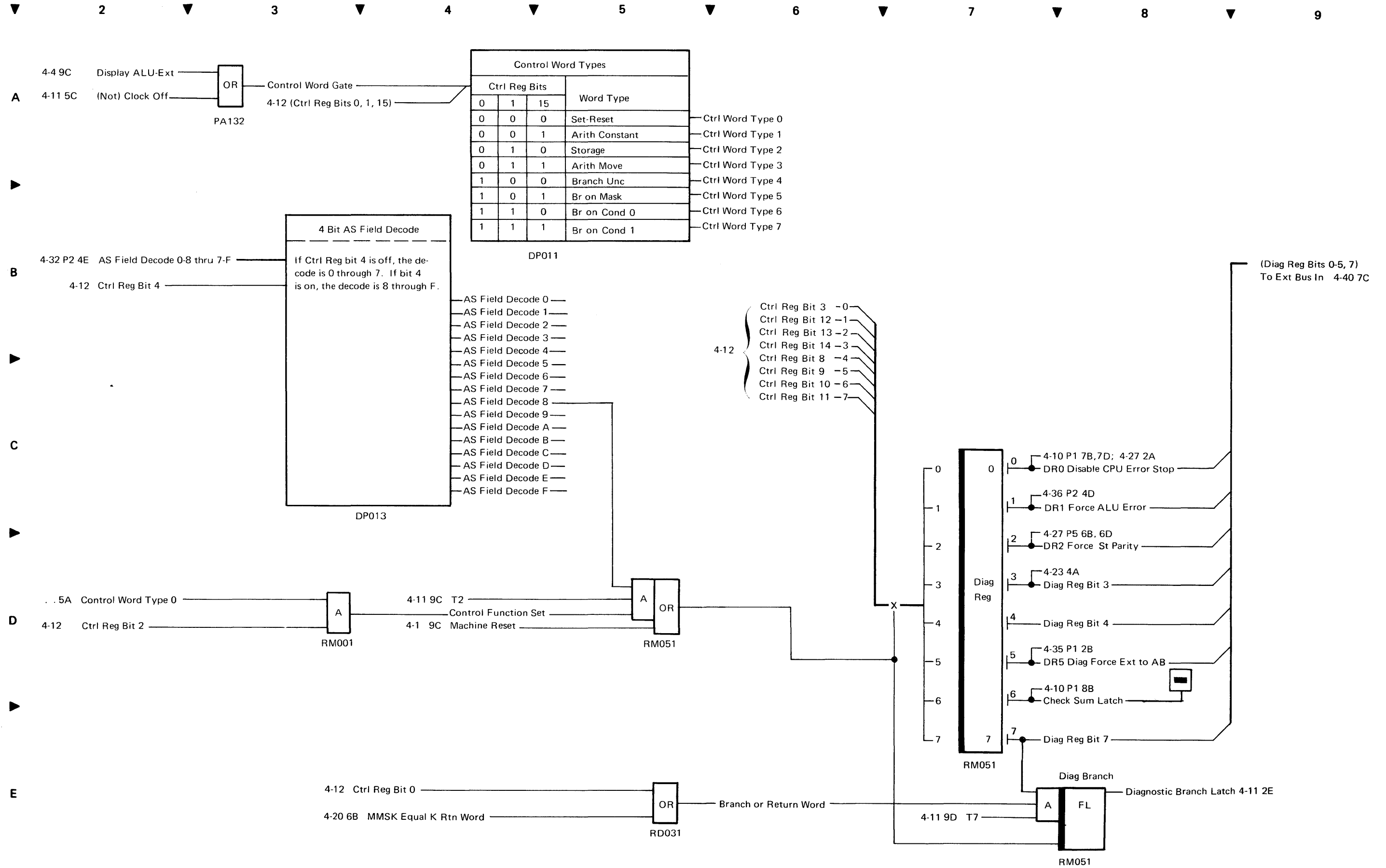


Diagram 4-14. Mode Register and Mode Decode

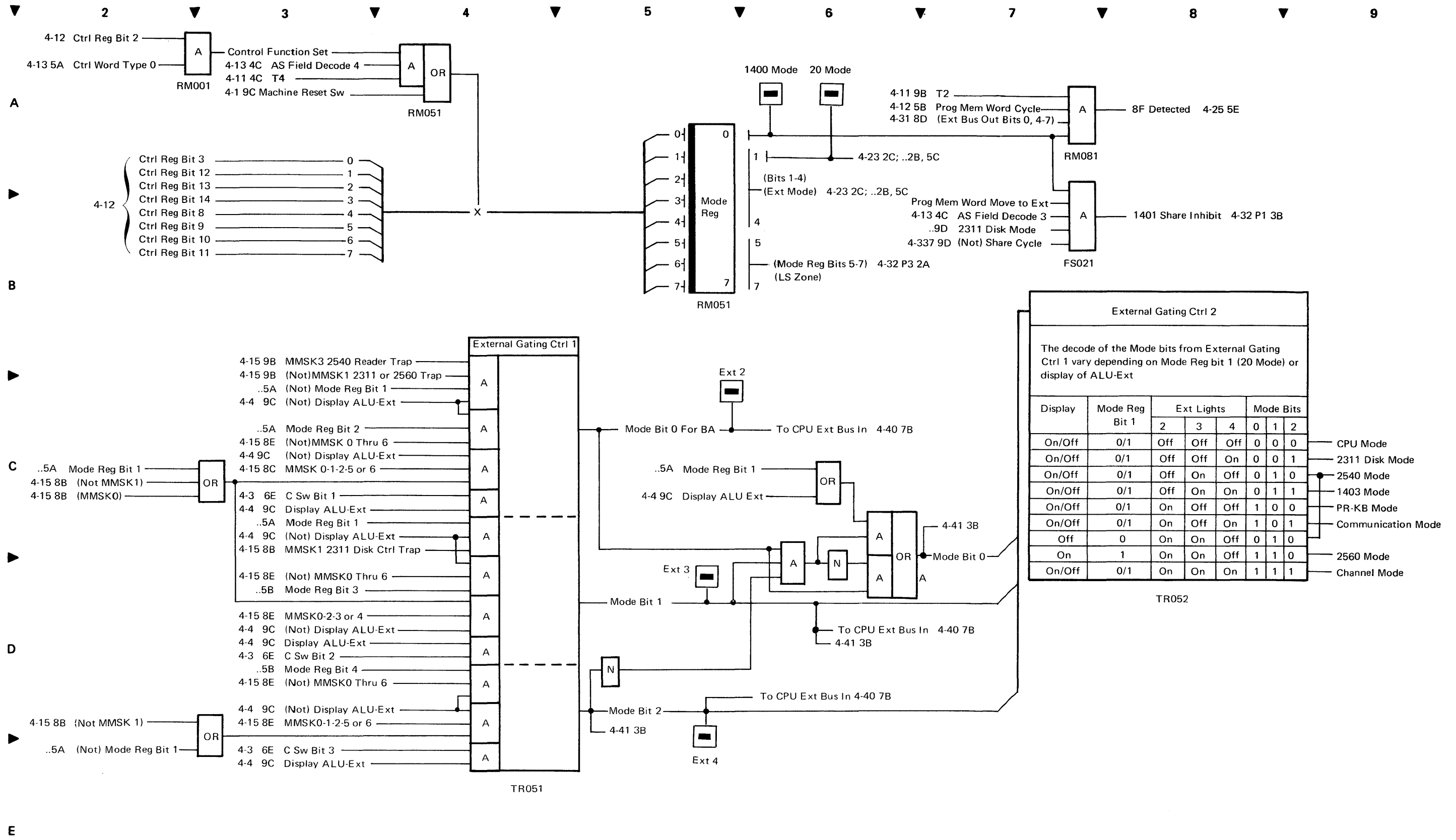
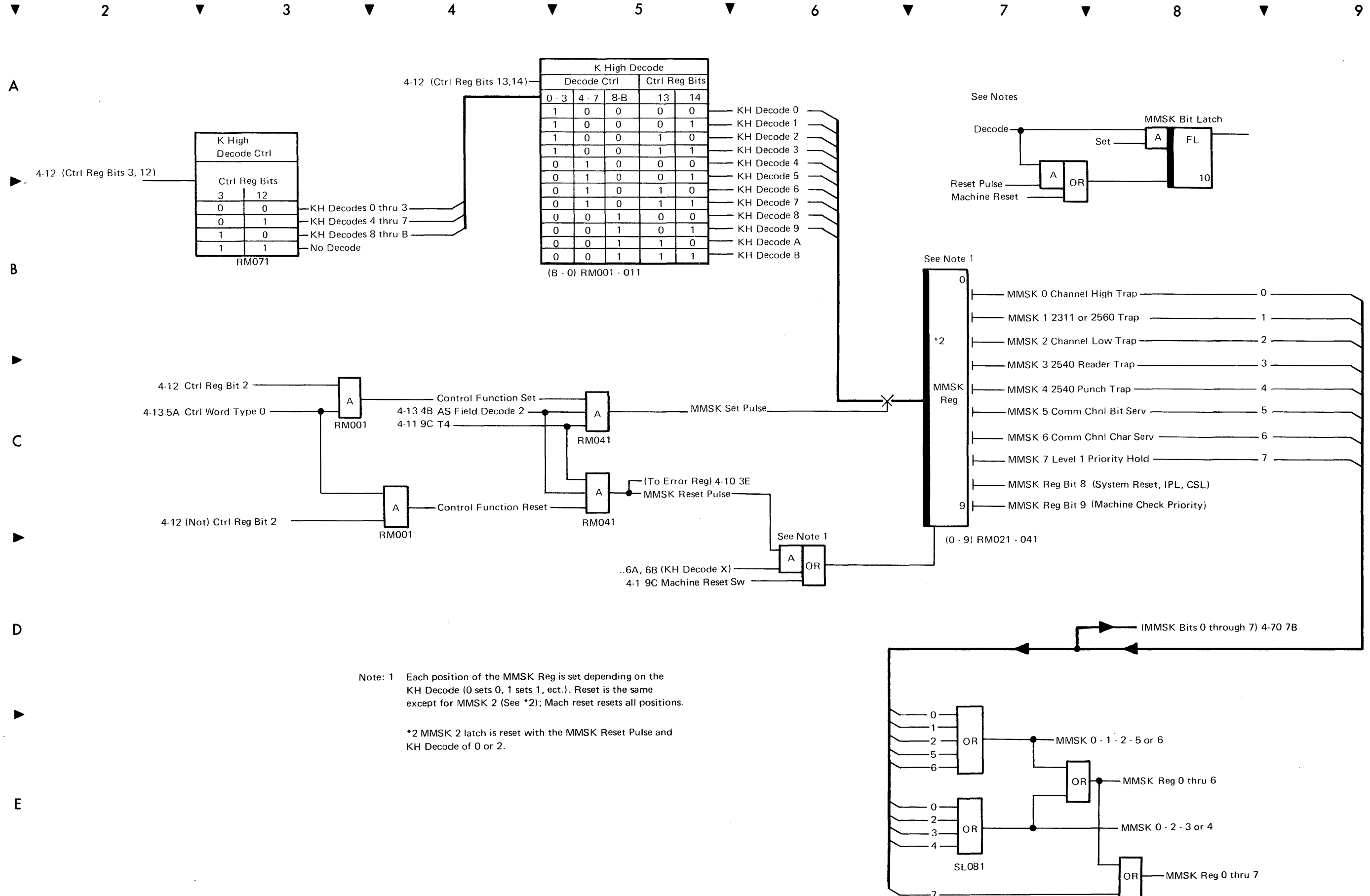


Diagram 4-15. MMSK Register



Note: 1 Each position of the MMSK Reg is set depending on the KH Decode (0 sets 0, 1 sets 1, ect.). Reset is the same except for MMSK 2 (See *2); Mach reset resets all positions.

*2 MMSK 2 latch is reset with the MMSK Reset Pulse and KH Decode of 0 or 2.

Diagram 4-16. S Register

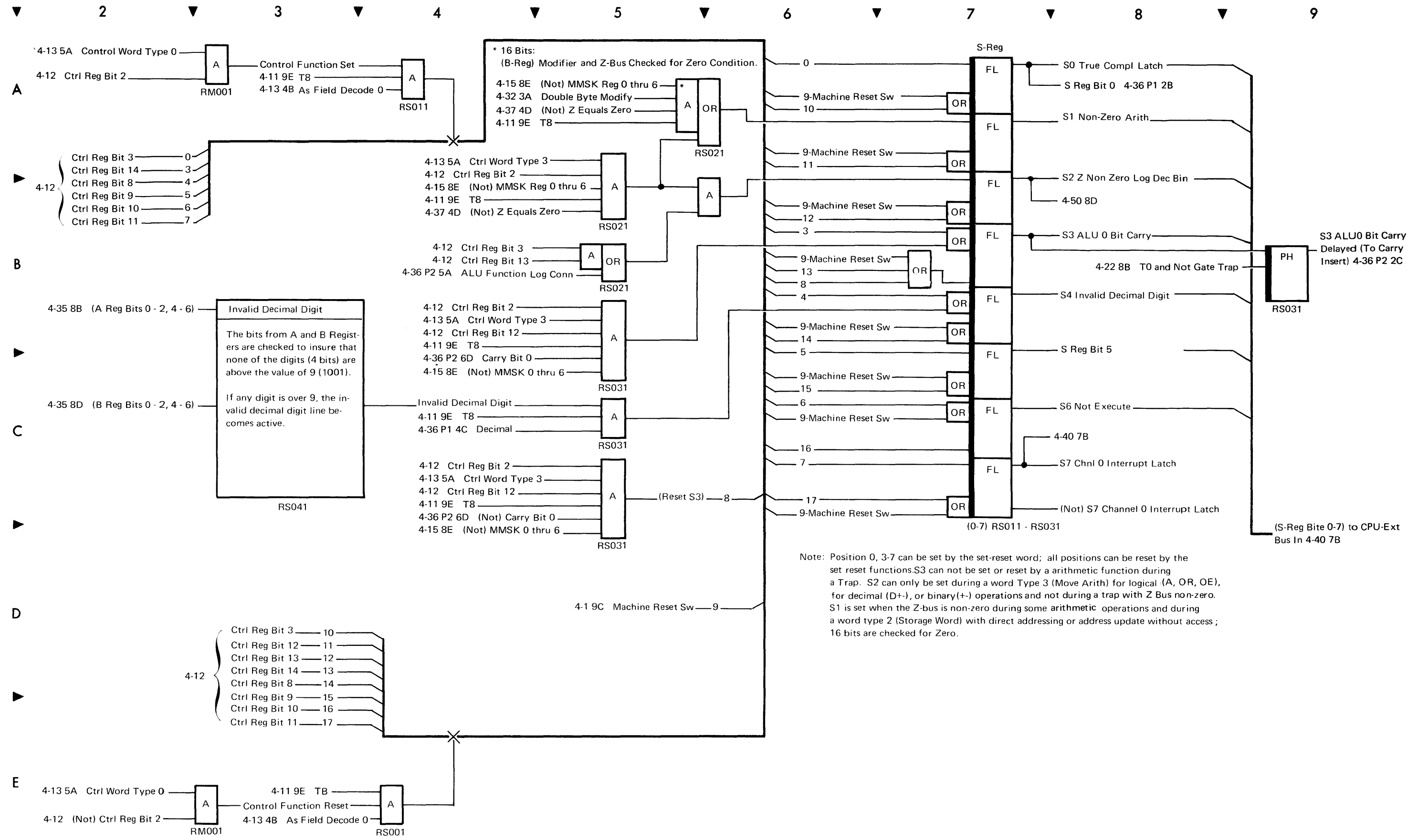


Diagram 4-20. M Registers, Gates and Assembler

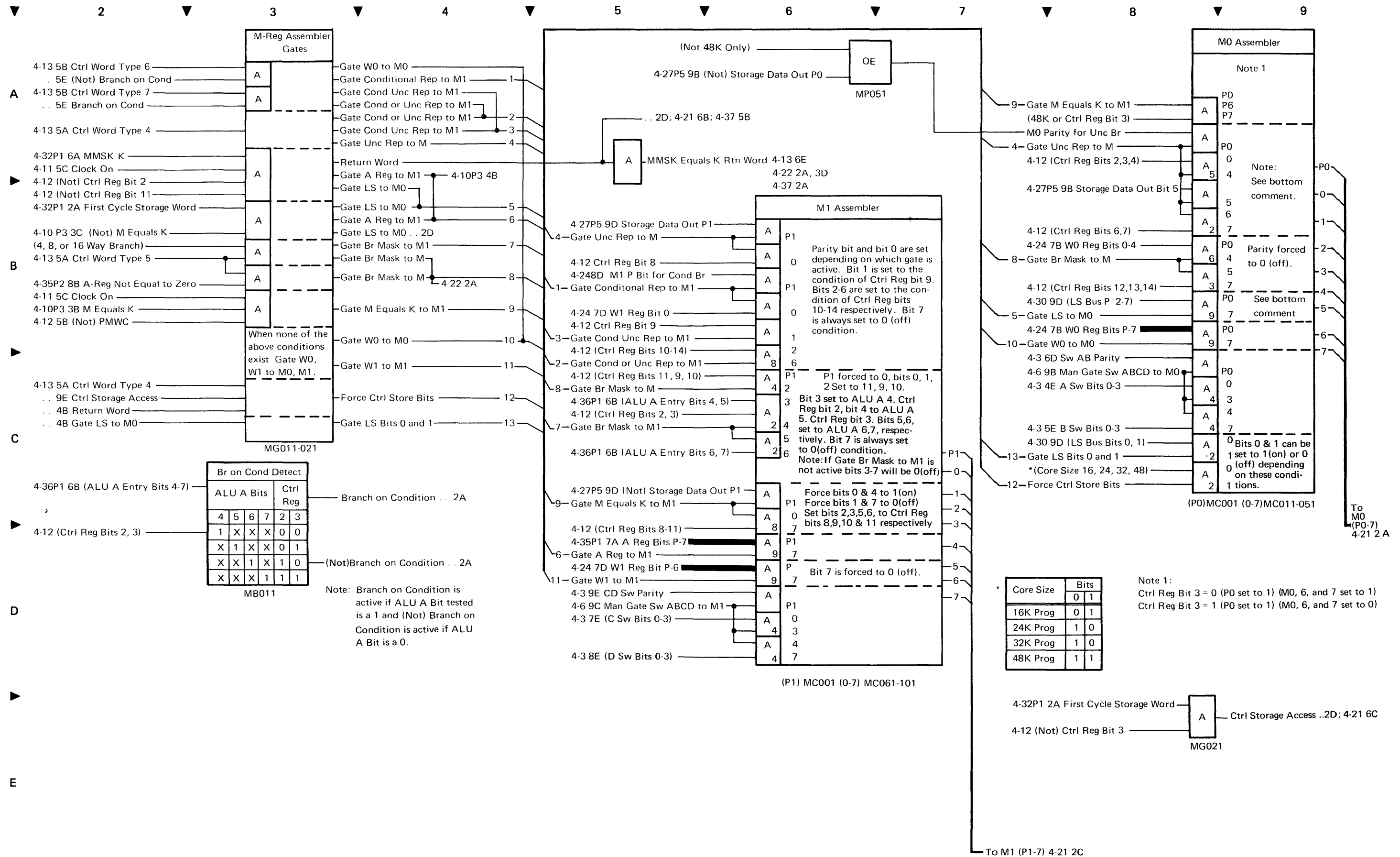
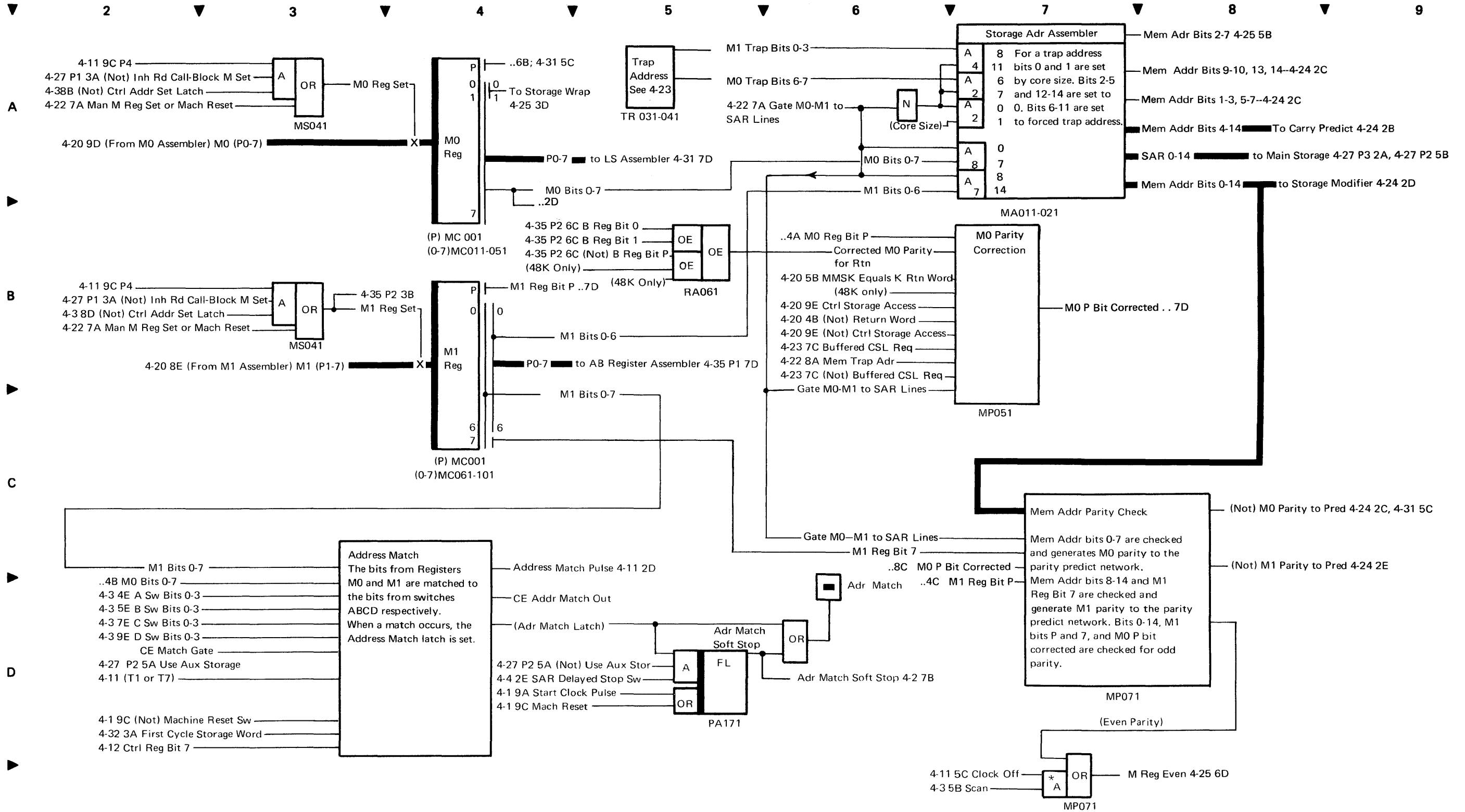


Diagram 4-21. M Registers, Address Match, SAR Lines



*Used to reset the store control latch (4-27 Part 5) when the clock is stopped in a scan operation.

Diagram 4-22. Trap Controls

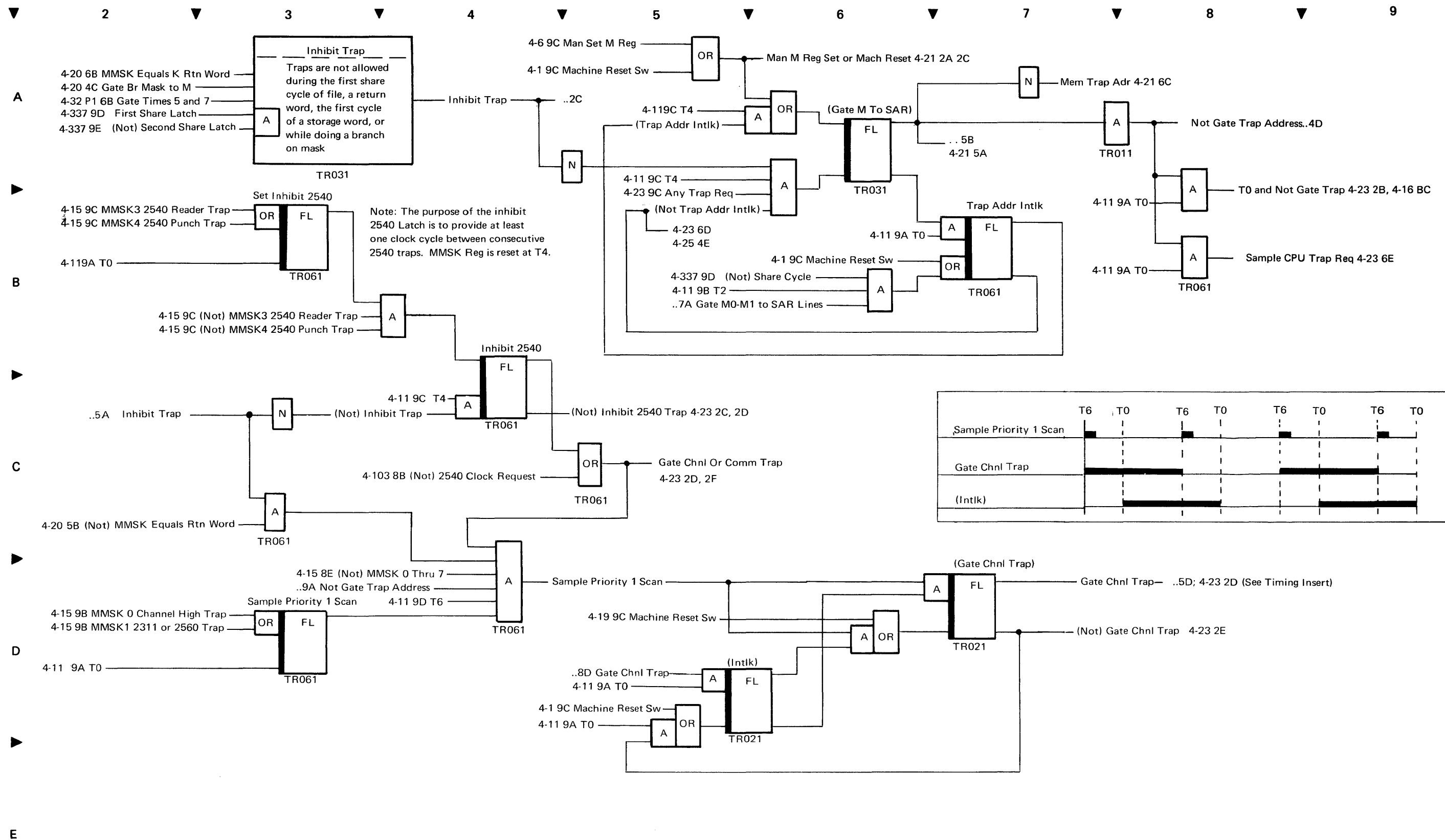


Diagram 4-23. Trap Addresses

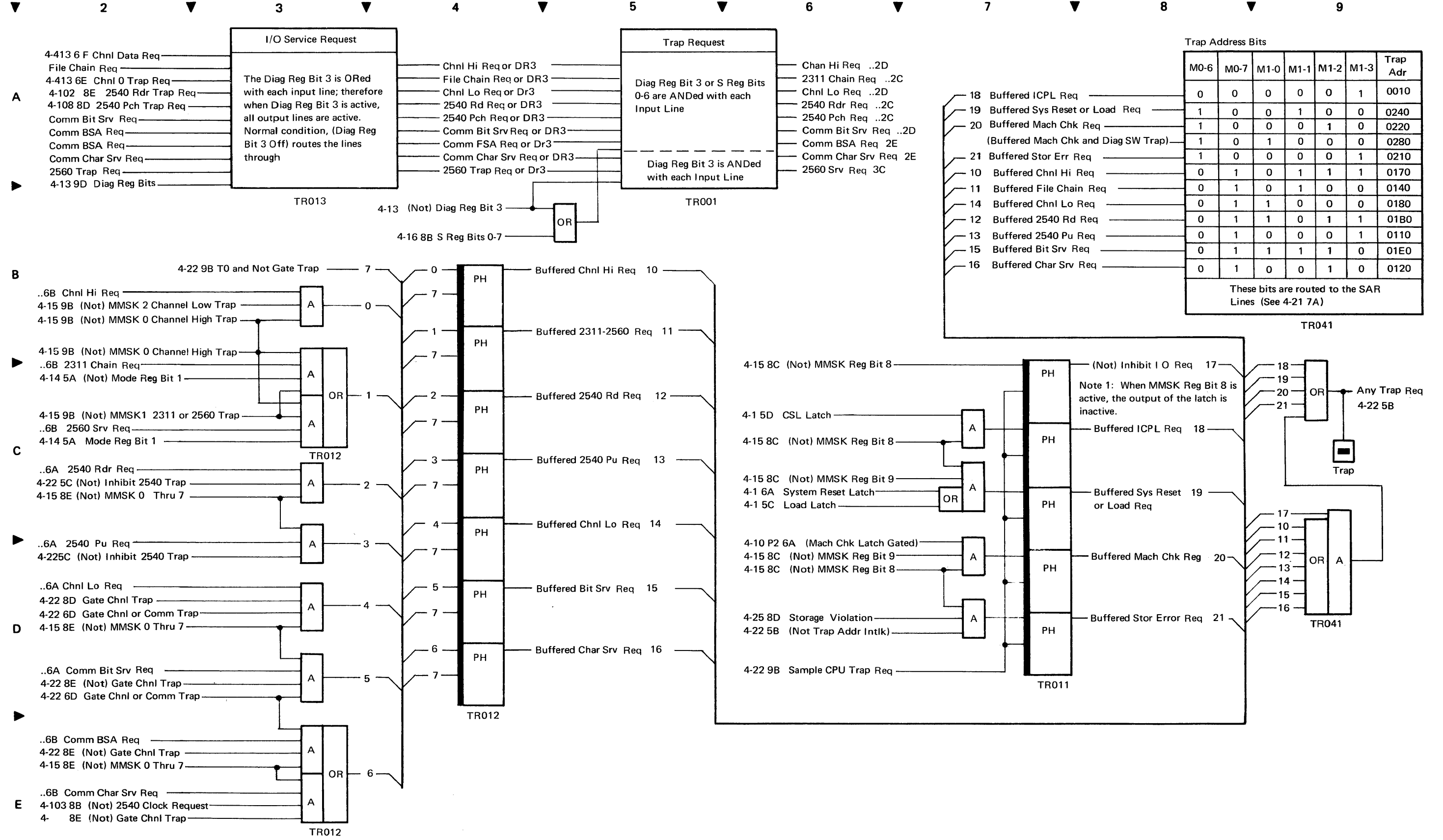
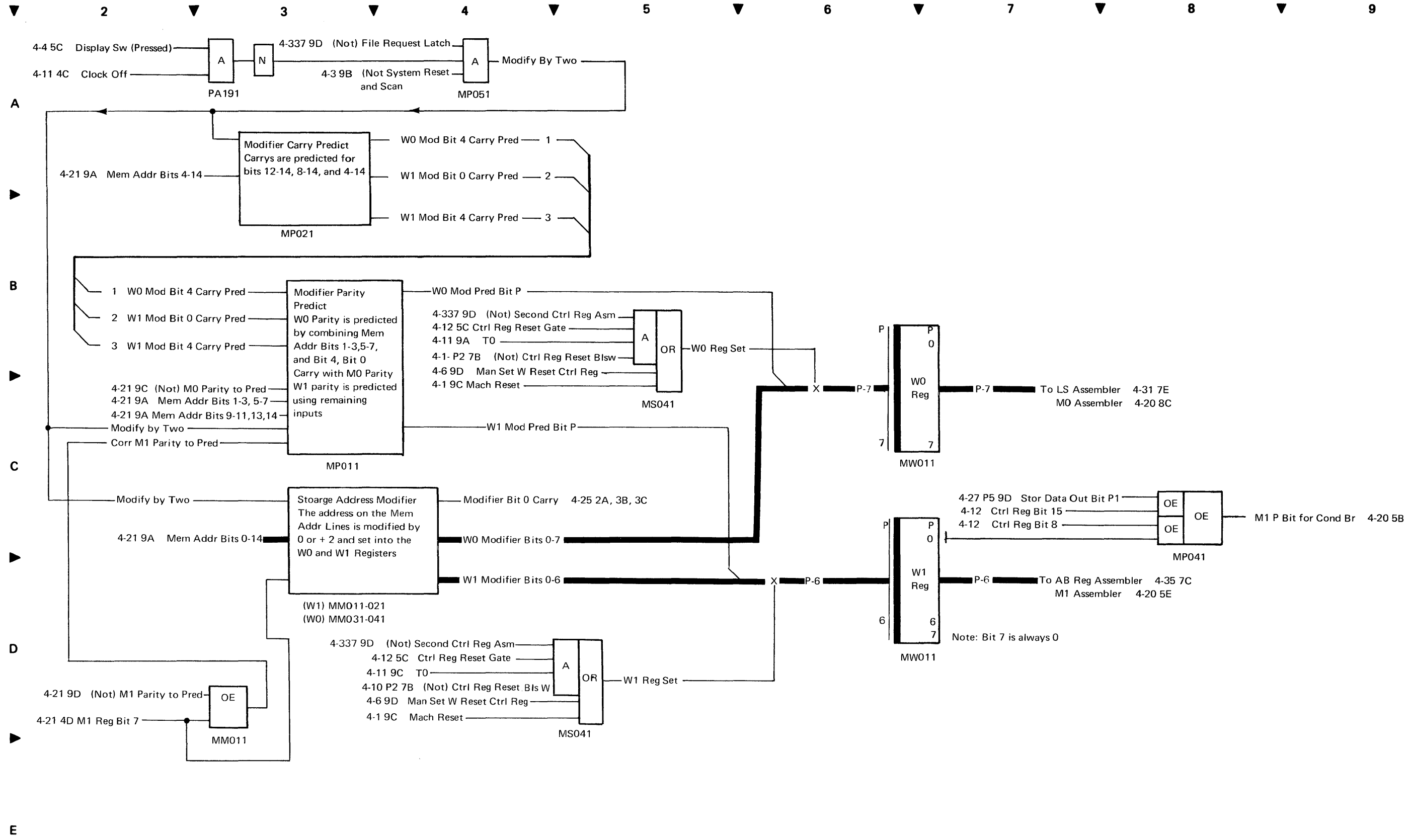


Diagram 4-24. Storage Address Modifier, W0, W1 Register



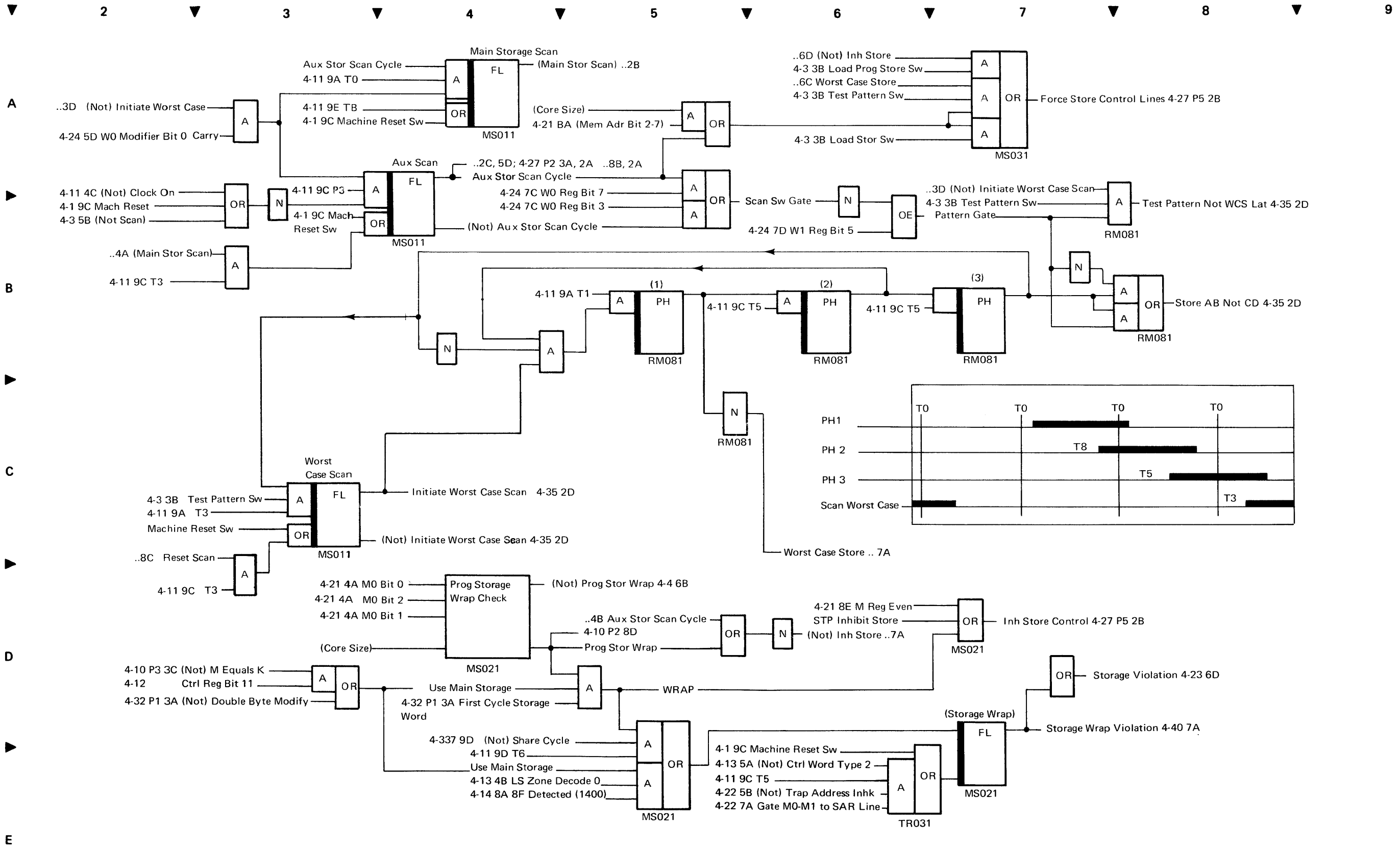
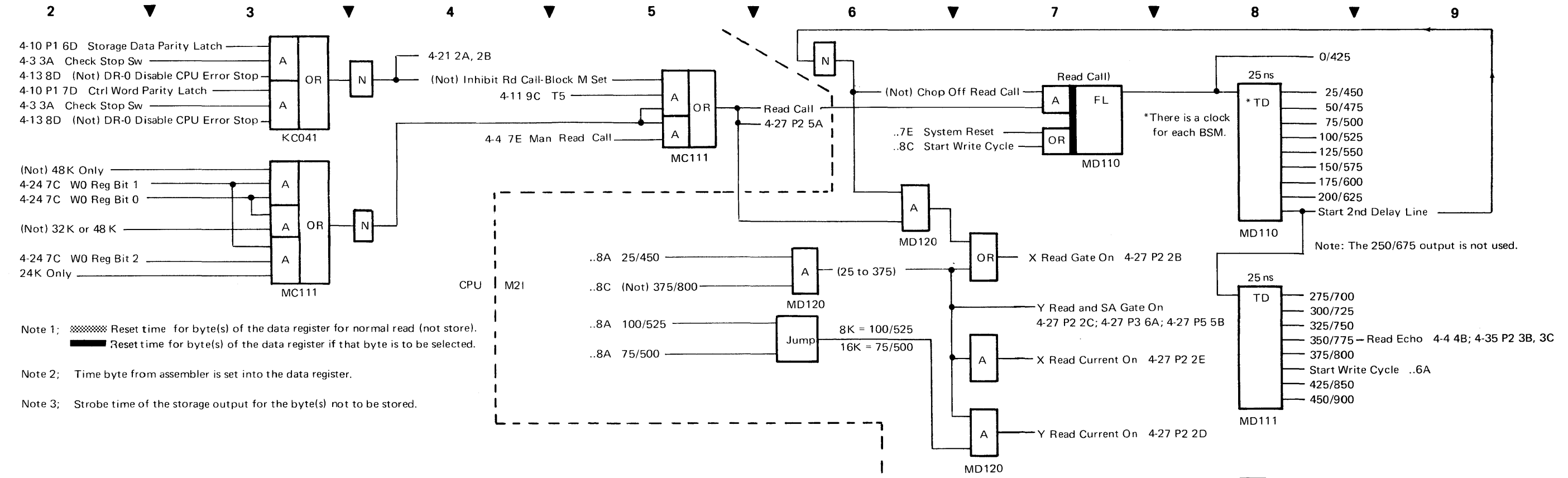


Diagram 4-27. Main and Aux Storage (Clock) (Part 1 of 5)



Note 1: Reset time for byte(s) of the data register for normal read (not store).
 Reset time for byte(s) of the data register if that byte is to be selected.

Note 2: Time byte from assembler is set into the data register.

Note 3: Strobe time of the storage output for the byte(s) not to be stored.

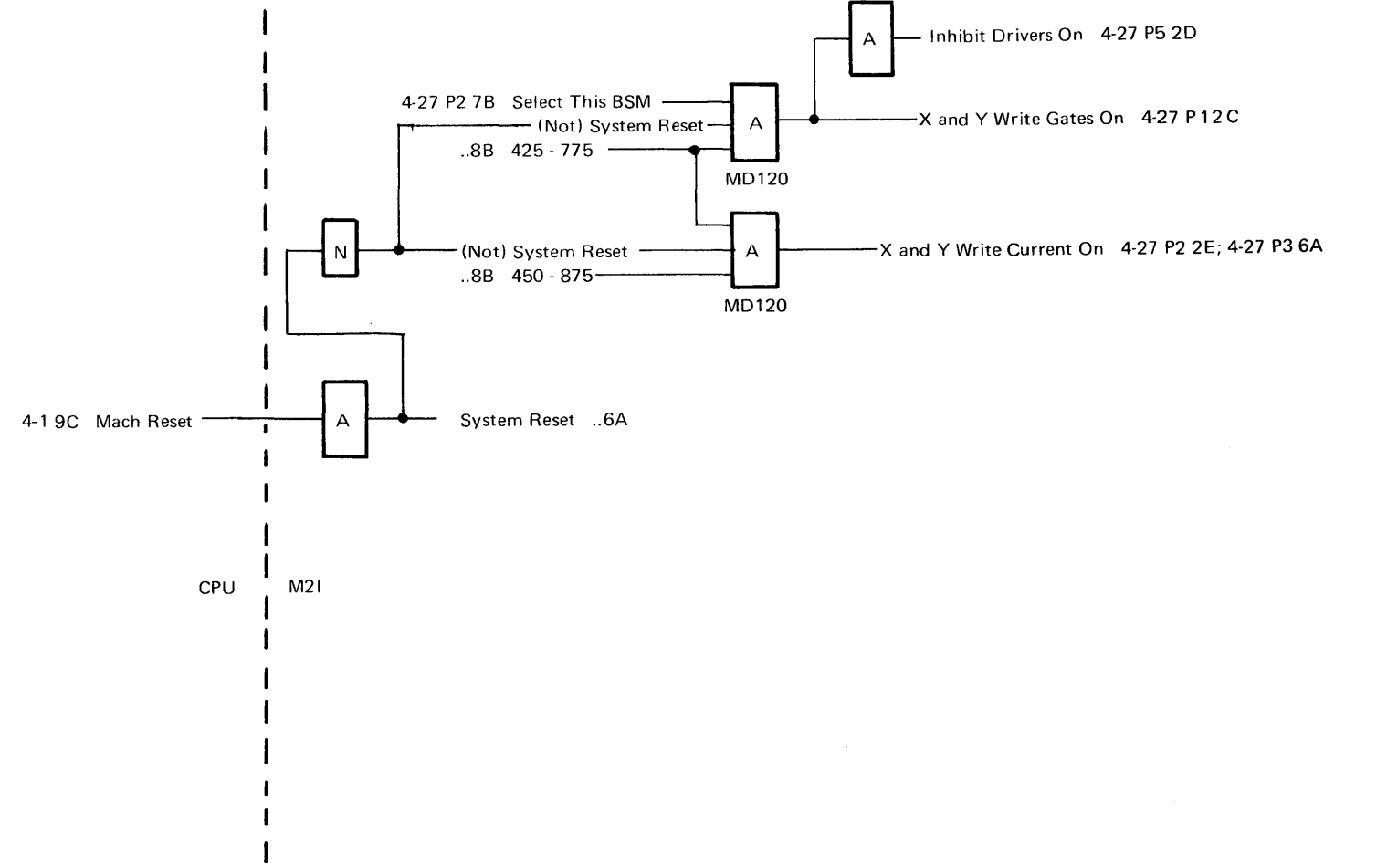
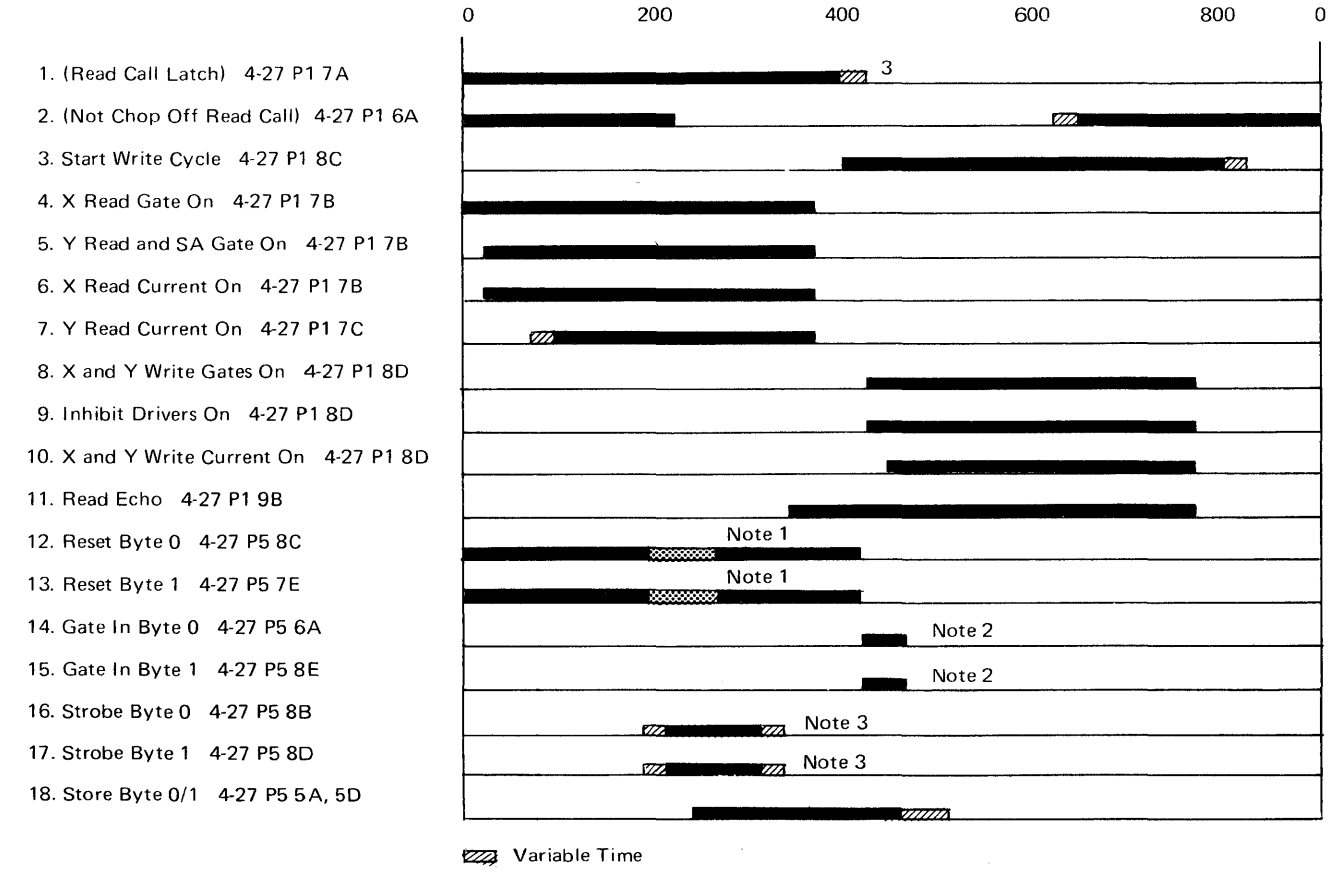


Diagram 4-27. Main and Aux Storage (X Decode) (Part 2 of 5)

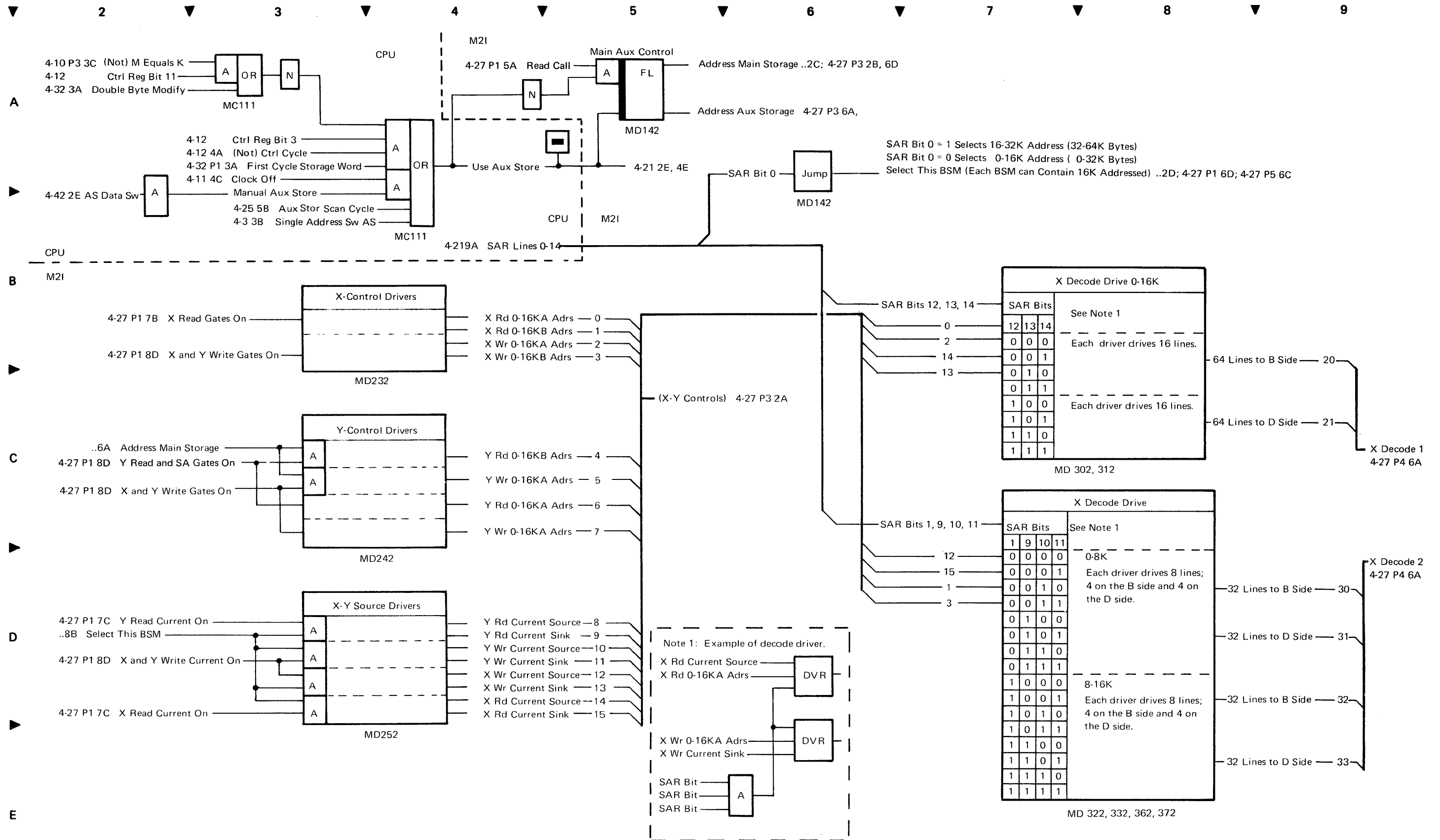


Diagram 4-27. Main and Aux Storage (Y Decode) (Part 3 of 5)

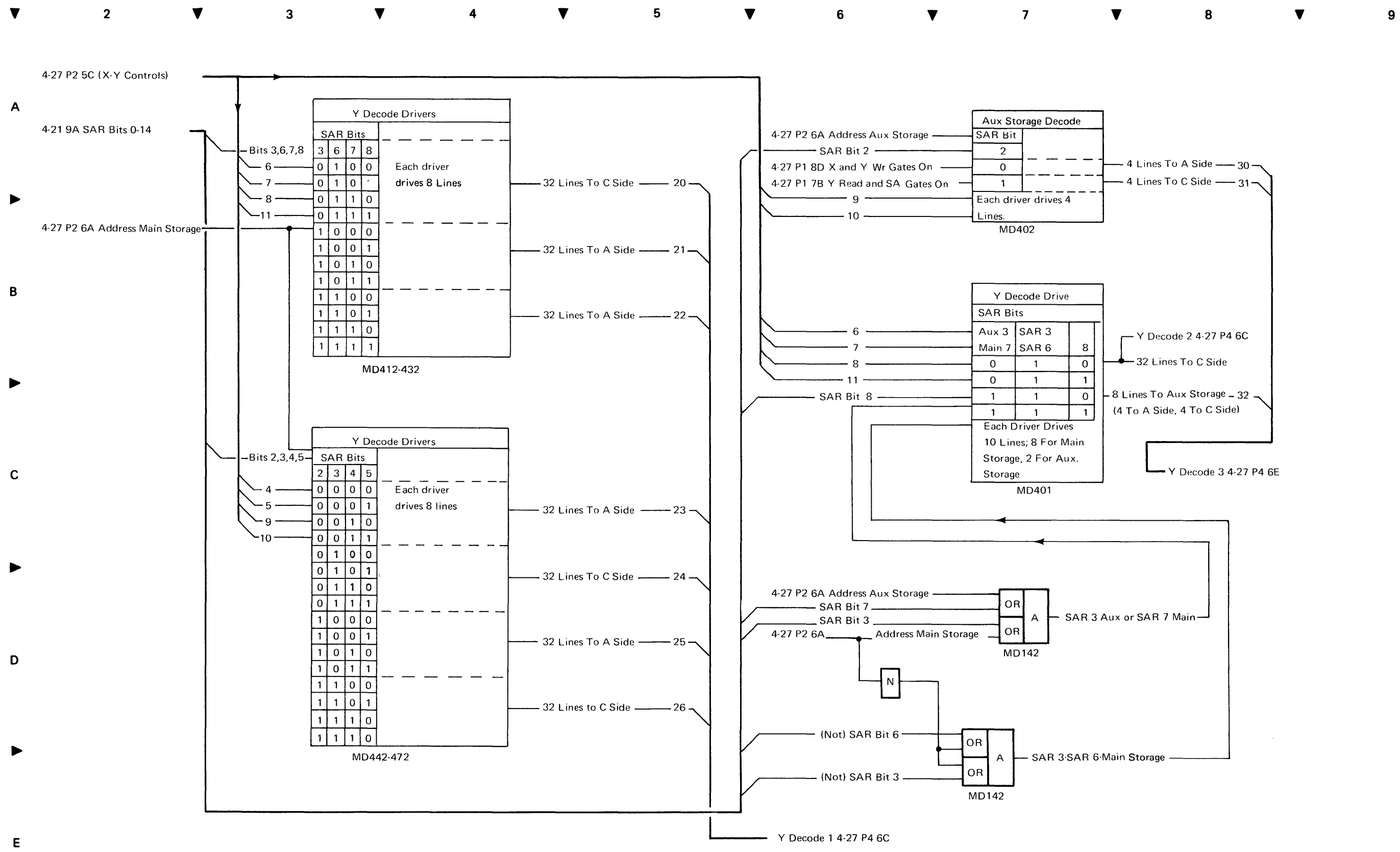
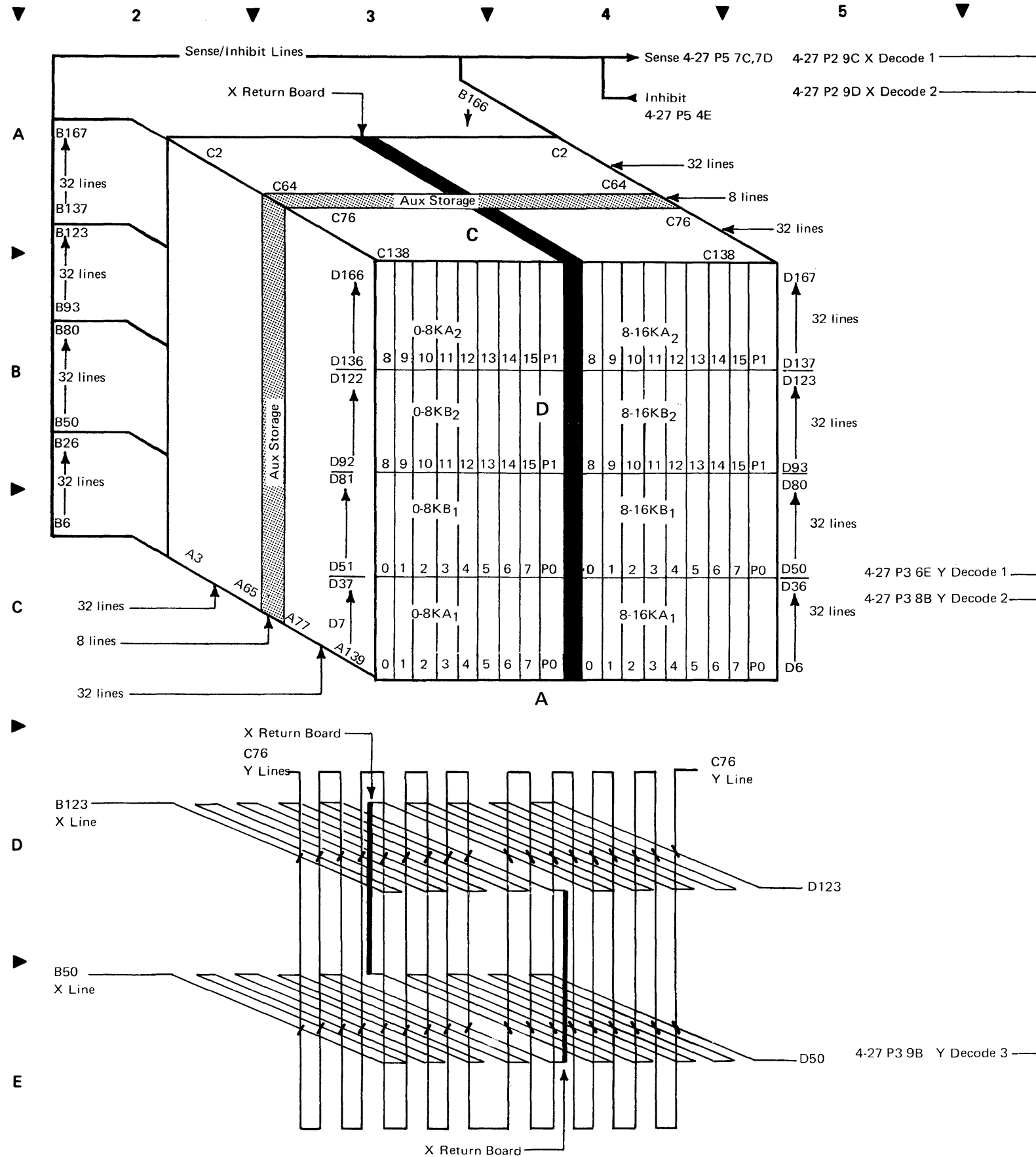


Diagram 4-27. Main and Aux Storage (Core) (Part 4 of 5)



Main And Aux. Storage					X Lines Decode Pin Entry and Exit							
SAR Bits					SAR Bit 12 13 14							
1	9	10	11		000	001	010	011	100	101	110	111
0	0	0	0		6-167	50-123	8-165	52-121	7-166	51-122	9-164	53-120
0	0	0	1		10-163	54-119	12-161	56-117	11-162	55-118	13-160	57-116
0	0	1	0		14-159	58-115	16-157	60-113	15-158	59-114	17-156	61-112
0	0	1	1		18-155	62-111	20-153	64-109	19-154	63-110	21-152	65-108
0	1	0	0		22-151	66-107	24-149	68-105	23-150	67-106	25-148	69-104
0	1	0	1		26-147	70-103	28-145	72-101	27-146	71-102	29-144	73-100
0	1	1	0		30-143	74-99	32-141	76-97	31-142	75-98	34-140	77-96
0	1	1	1		34-139	78-95	36-137	80-93	35-138	79-94	37-136	81-92
1	0	0	0		7-166	51-122	9-164	53-120	6-167	50-123	8-165	52-121
1	0	0	1		11-162	55-118	13-160	57-116	10-163	54-119	12-161	56-117
1	0	1	0		15-158	59-114	17-156	61-112	14-159	58-115	16-157	60-113
1	0	1	1		19-154	63-110	21-152	65-108	18-155	62-111	20-153	64-109
1	1	0	0		23-150	67-106	25-148	69-104	22-151	66-107	24-149	68-105
1	1	0	1		27-146	71-102	29-144	73-100	26-147	70-103	28-145	72-101
1	1	1	0		31-142	75-98	34-140	77-96	30-143	74-99	32-141	76-97
1	1	1	1		35-138	79-94	37-136	81-92	34-139	78-95	36-137	80-93
					Side B				Side D			

Main Storage					Y Lines Decode Pin Entry and Exit								
SAR Bits					SAR Bits 6, 7, 8								
2	3	4	5		000	001	010	011	100	101	110	111	Side
0	0	0	0		2	34	76	108	4	36	78	110	C
0	0	0	1		6	38	80	112	8	40	82	114	
0	0	1	0		10	42	84	116	12	44	86	118	
0	0	1	1		14	46	88	120	16	48	90	122	
0	1	0	0		3	35	77	109	5	37	79	111	A
0	1	0	1		7	39	81	113	9	41	83	115	
0	1	1	0		11	43	85	117	13	45	87	119	
0	1	1	1		15	47	89	121	17	49	91	123	
1	0	0	0		18	50	92	124	20	52	94	126	C
1	0	0	1		22	54	96	128	24	56	98	130	
1	0	1	0		26	58	100	132	28	60	102	134	
1	0	1	1		30	62	104	136	32	64	106	138	
1	1	0	0		19	51	93	125	21	53	95	127	A
1	1	0	1		23	55	97	129	25	57	99	131	
1	1	1	0		27	59	101	133	29	61	103	135	
1	1	1	1		31	63	105	137	33	65	107	139	

Aux Storage Y Lines Decode Pin Entry and Exit					
SAR Bit	SAR Bit 3,8				Side
2	00	01	10	11	
0	66	68	72	74	C
1	67	69	73	75	A

Note: Shown on this page is the layout for one 16K half word BSM. 8K of addresses (16K bytes) for program storage require 1 BSM; any thing greater up to 48K (bytes) require a second BSM which has the same layout.

Diagram 4-27. Main and Aux Storage (Stor Data Reg) (Part 5 of 5)

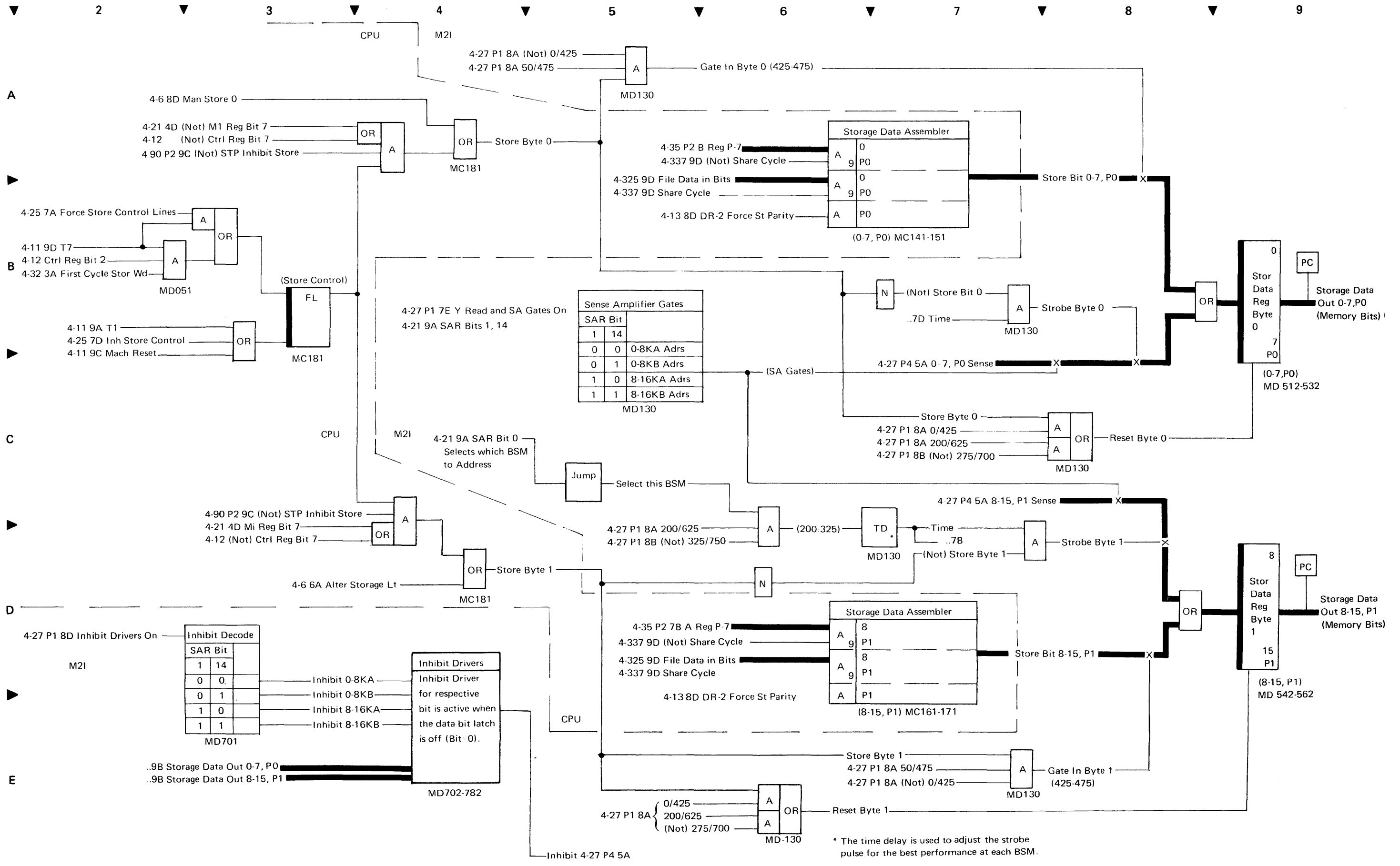


Diagram 4-30. Local Storage

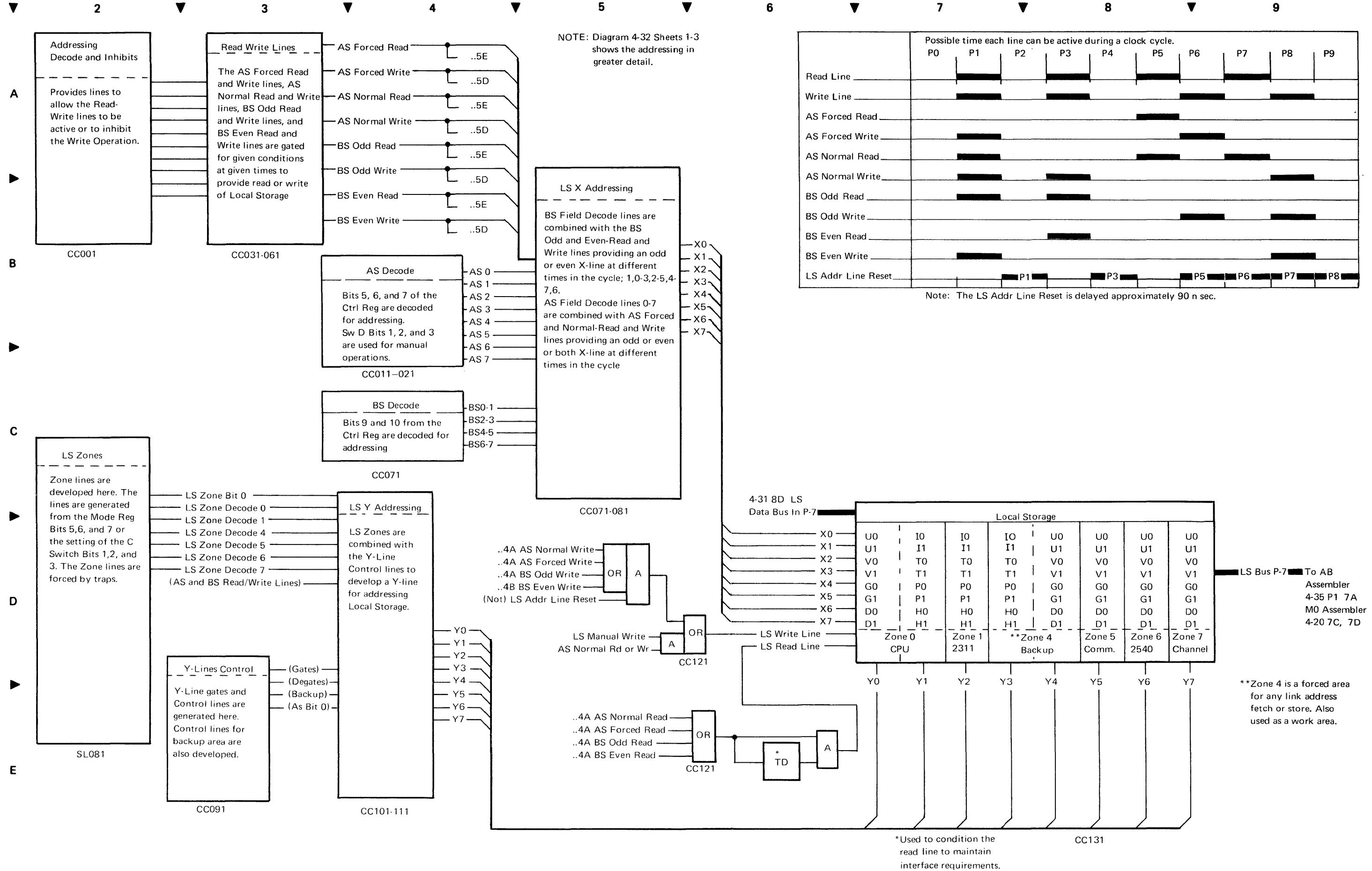


Diagram 4-31. LS Data Assembler

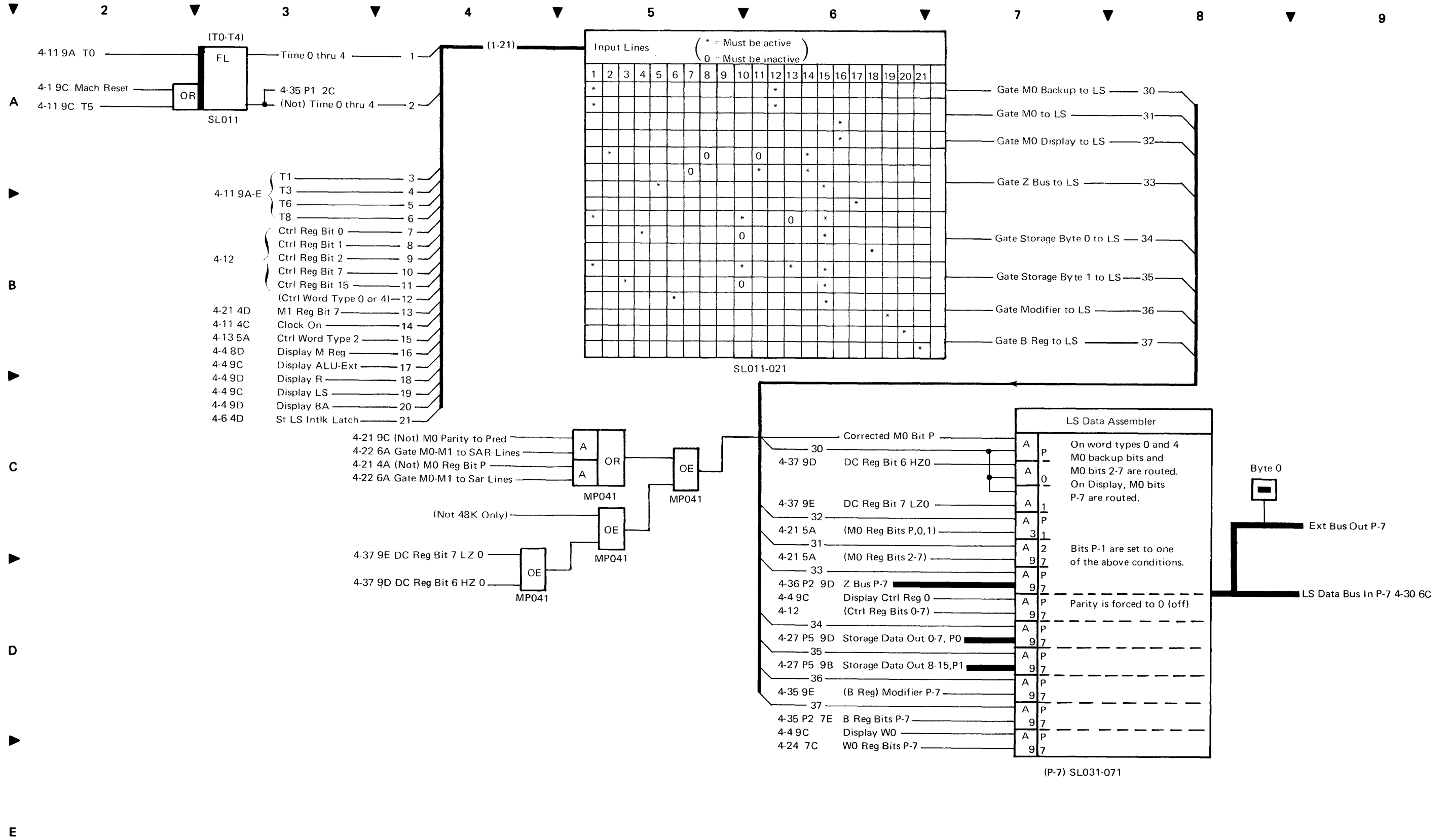


Diagram 4-32. LS Addressing (Part 1 of 3)

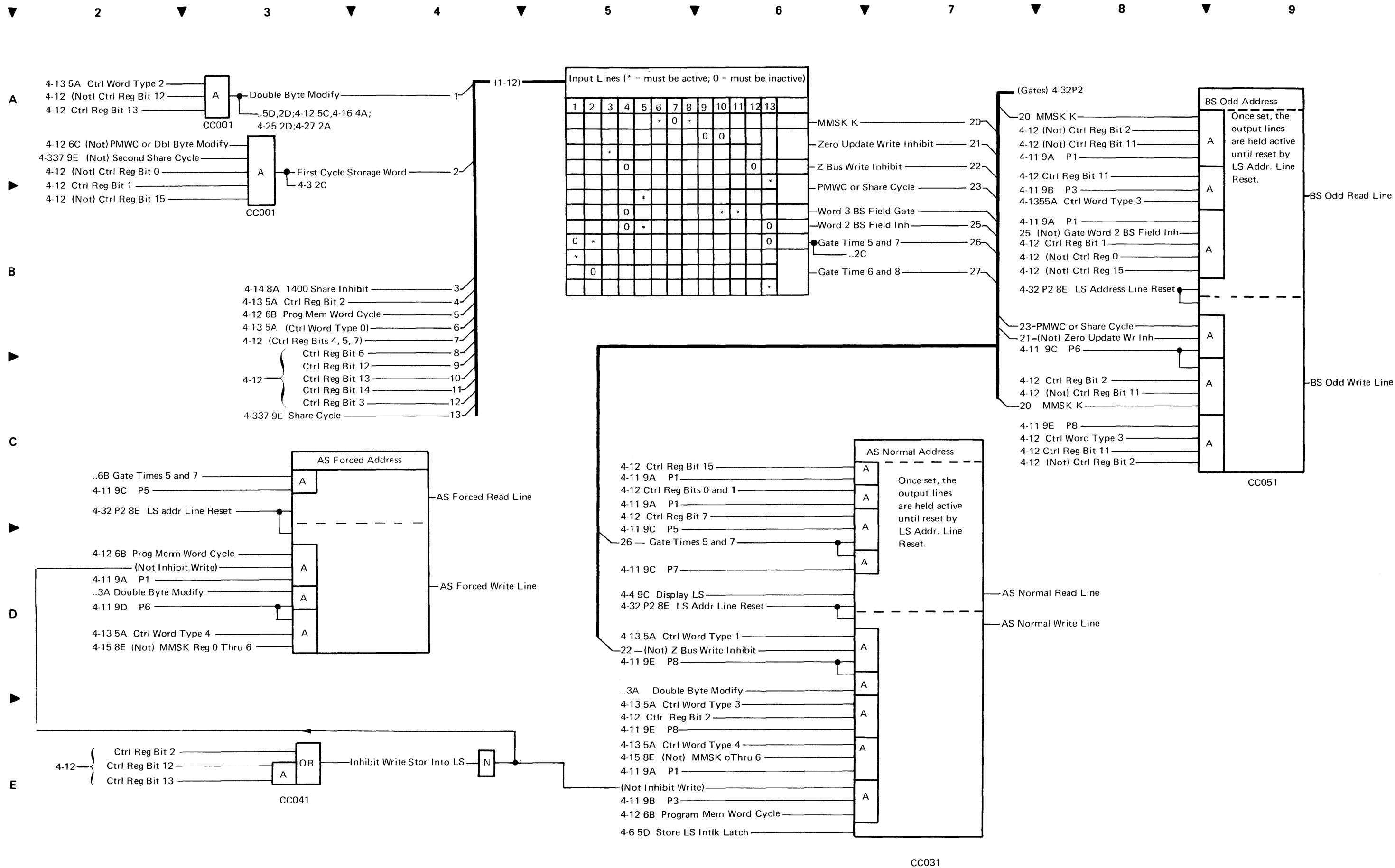


Diagram 4-32. LS Addressing (Part 2 of 3)

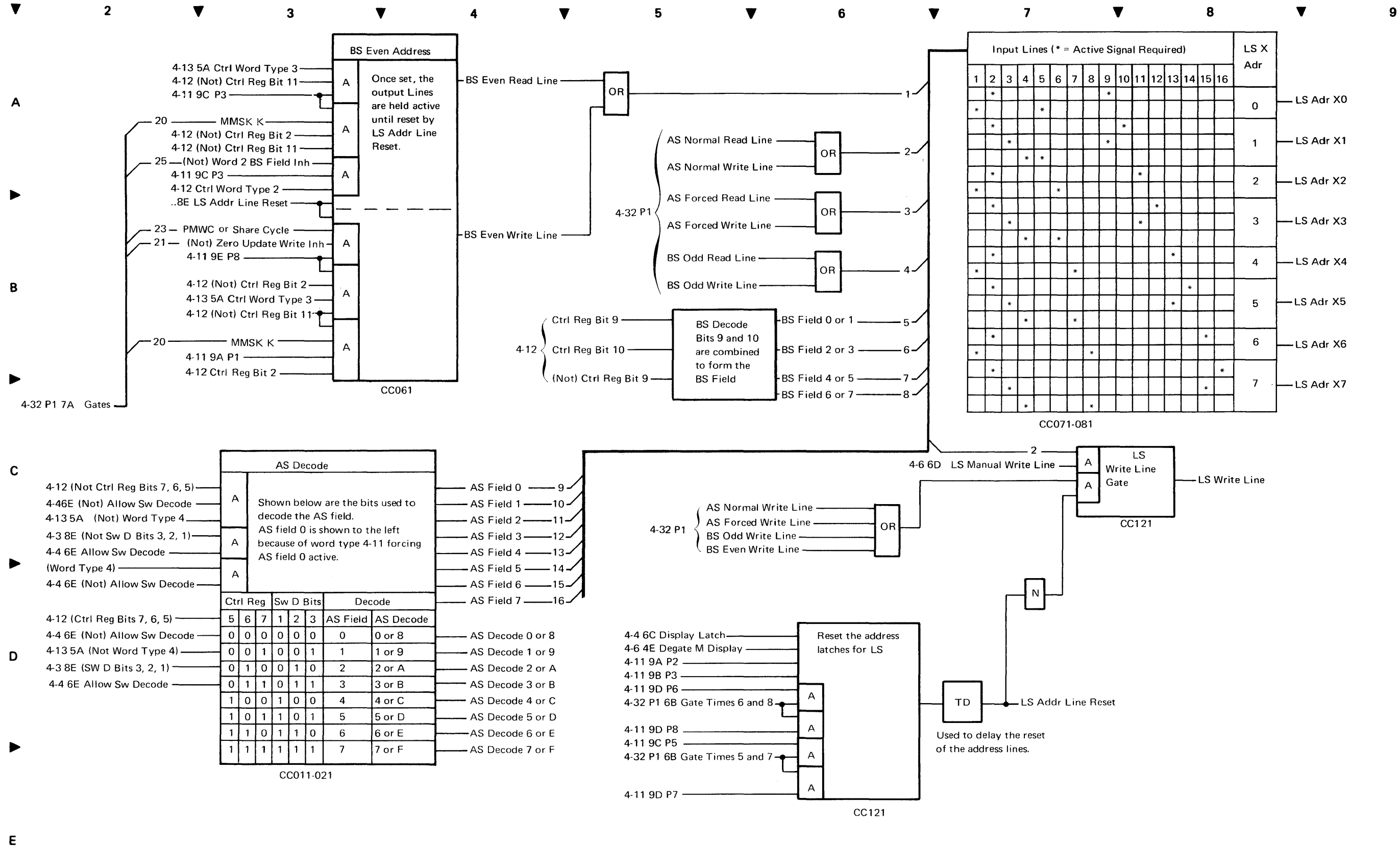


Diagram 4-32. LS Addressing (Part 3 of 3)

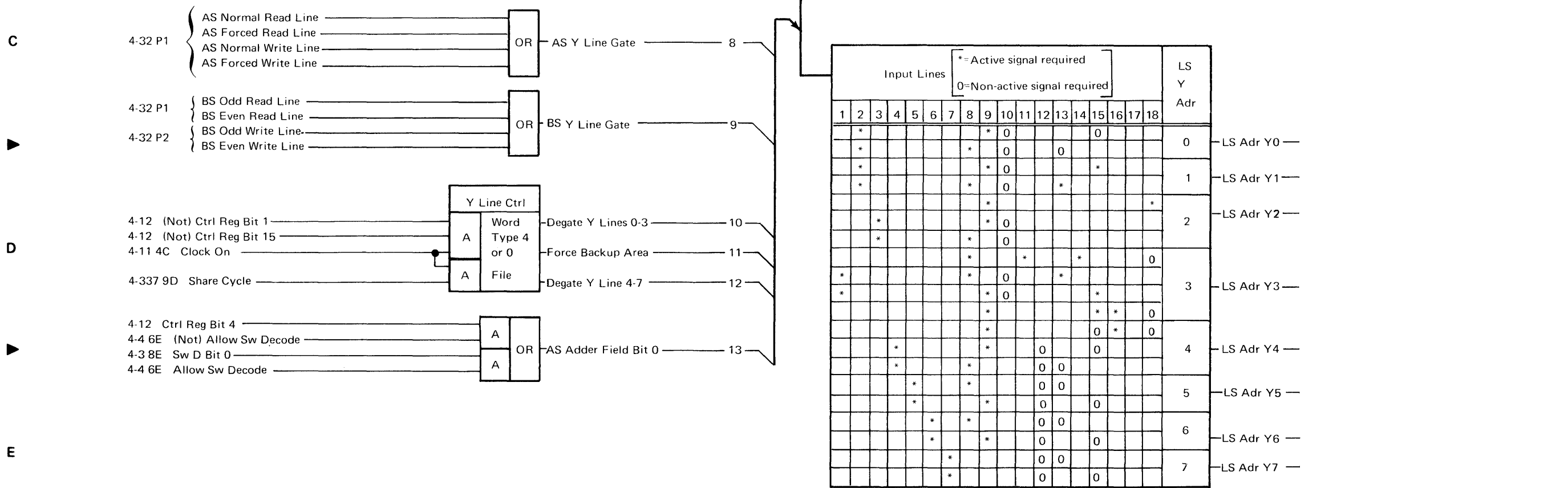
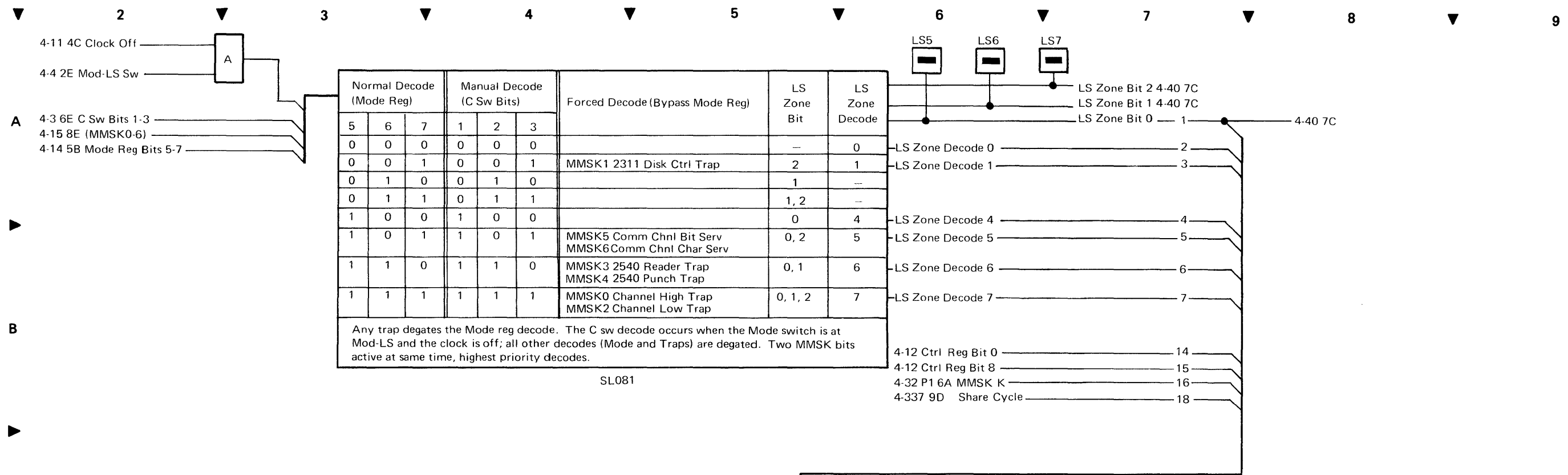


Diagram 4-35. A-B Assembler, Registers, and Modifier (Part 1 of 2)

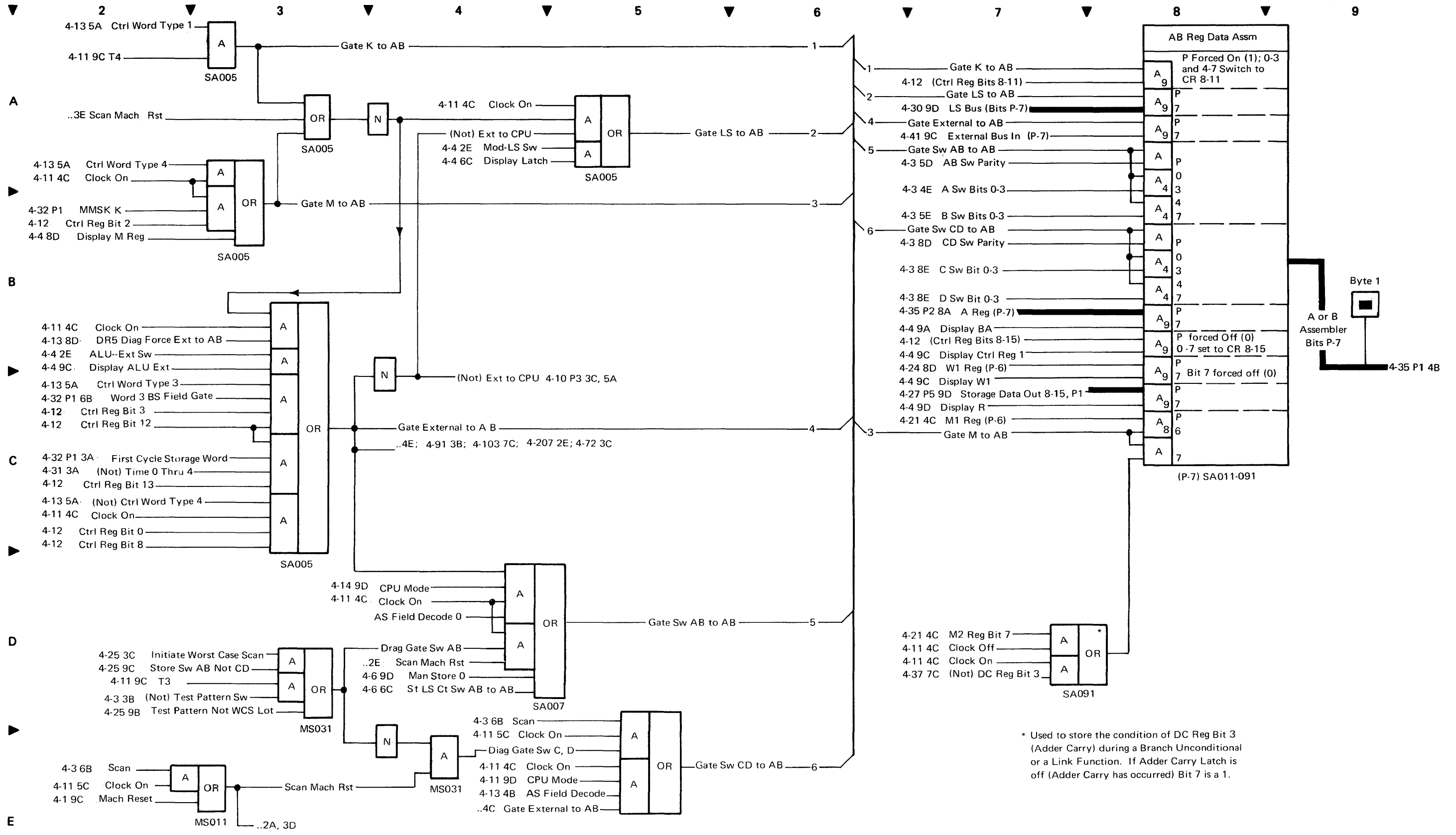


Diagram 4-35. A-B Assembler, Registers, and Modifier (Part 2 of 2)

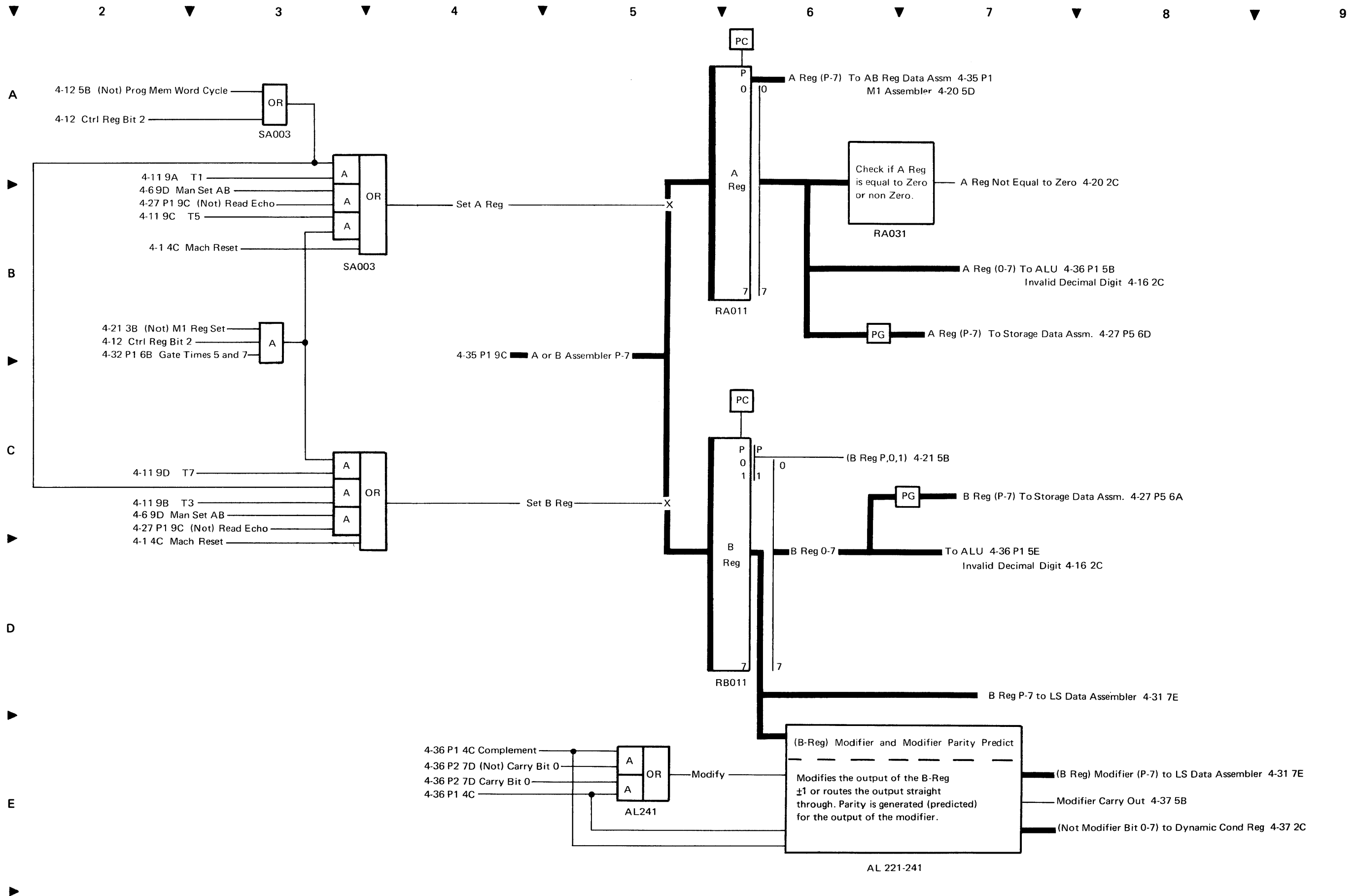


Diagram 4-36. ALU (Part 1 of 2)

A
B
C
D
E

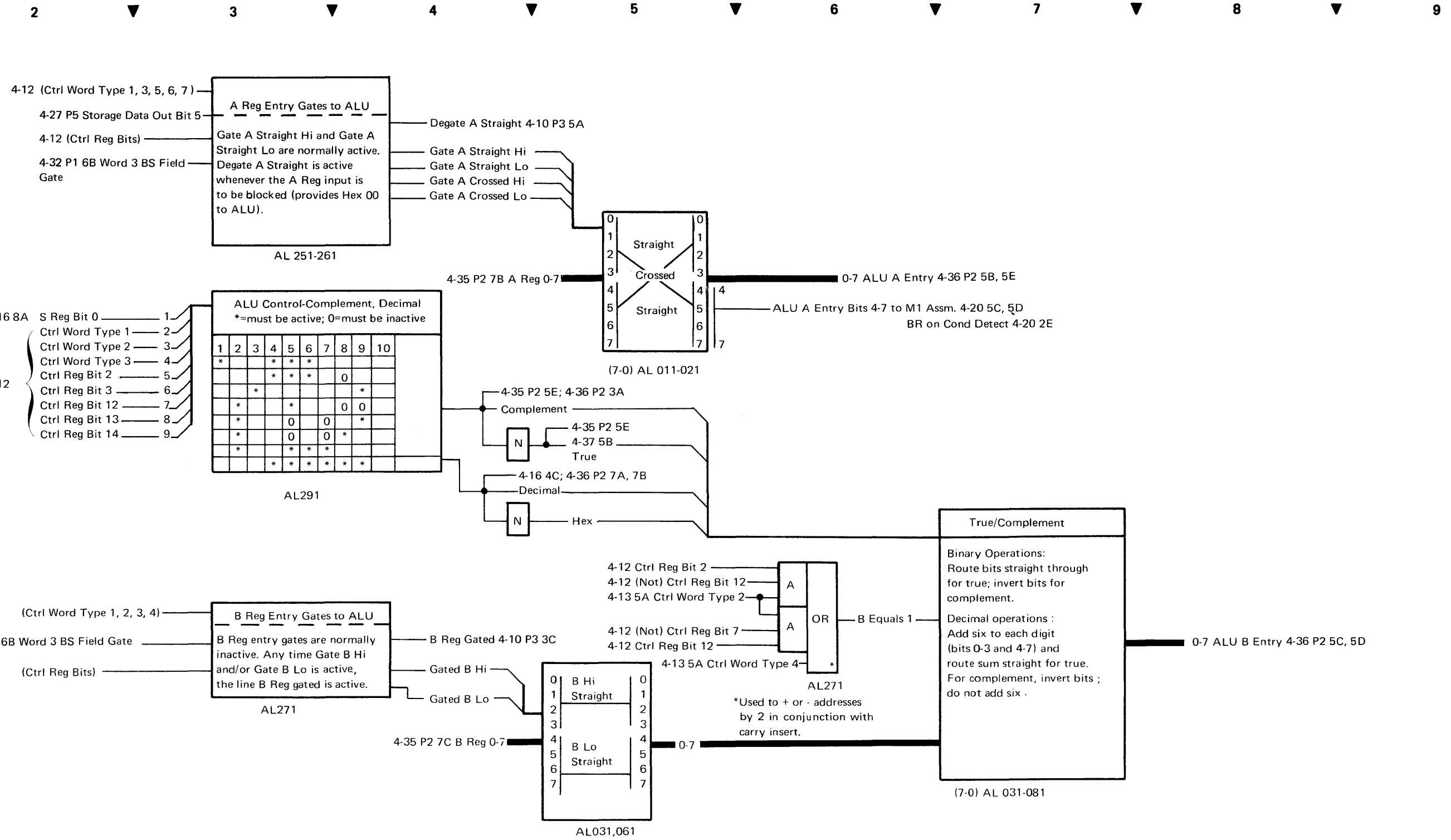


Diagram 4-36. ALU (Part 2 of 2)

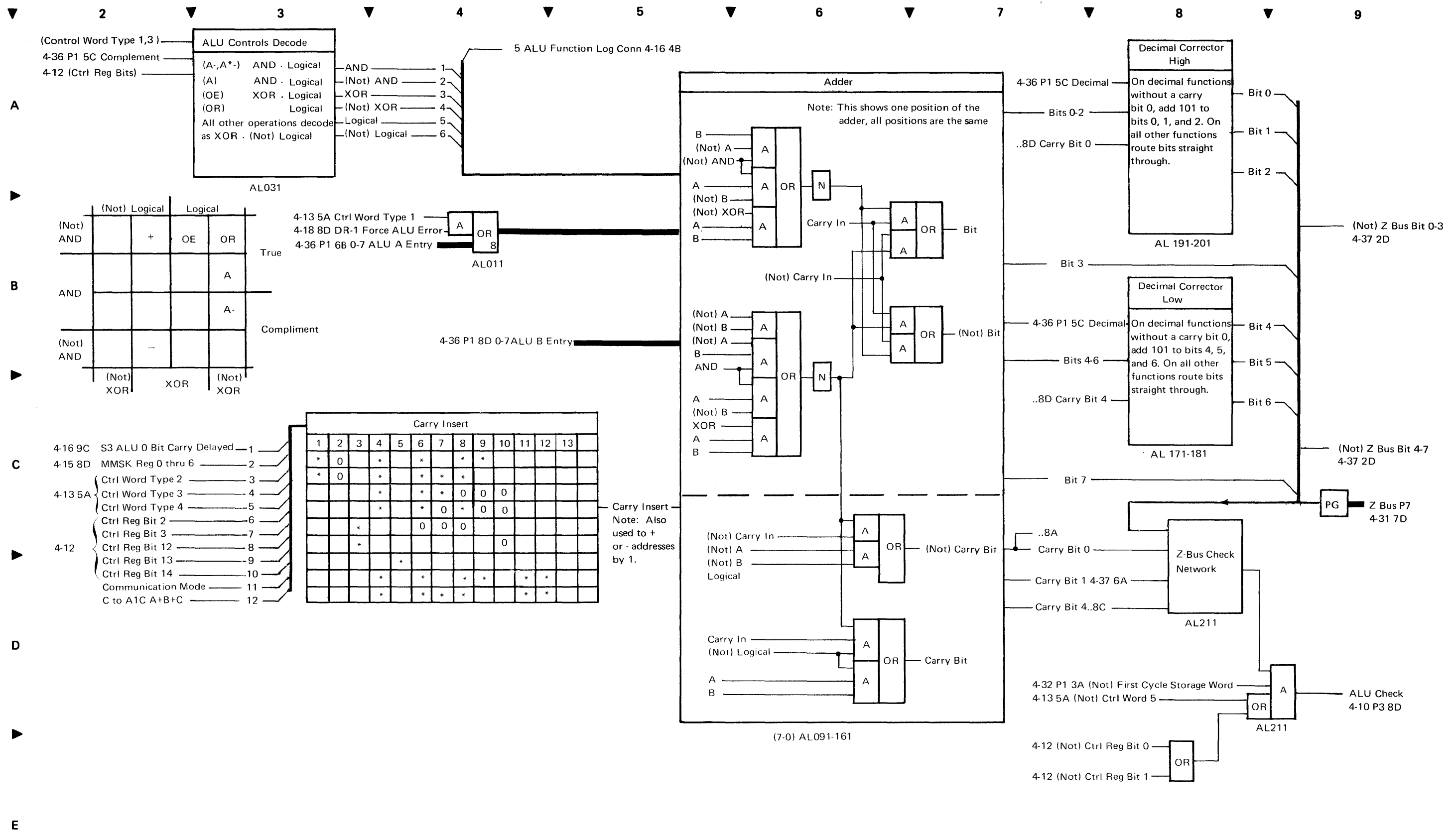


Diagram 4-37. D C Register

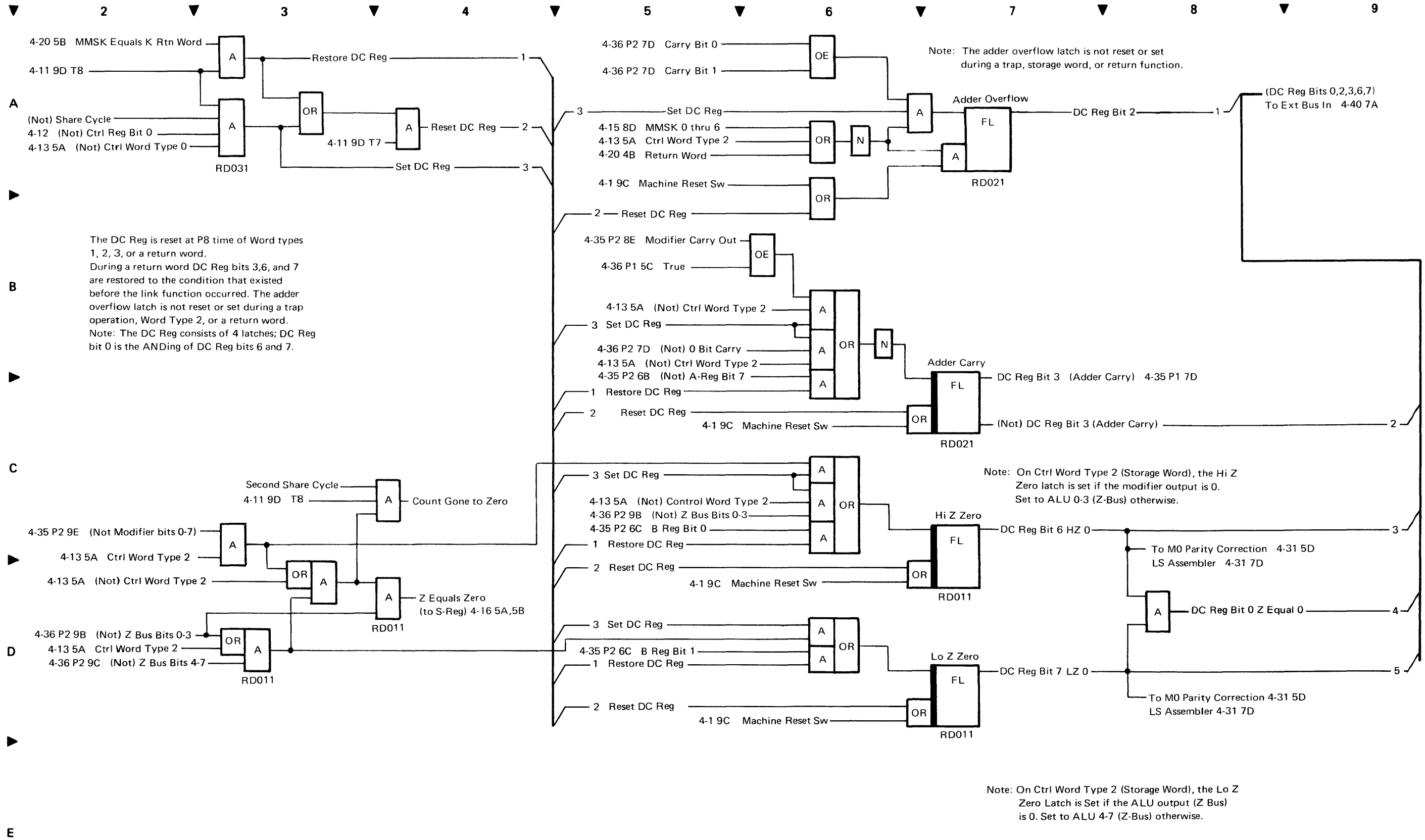


Diagram 4-40. External Facility (CPU Mode and Common) CPU Bus In

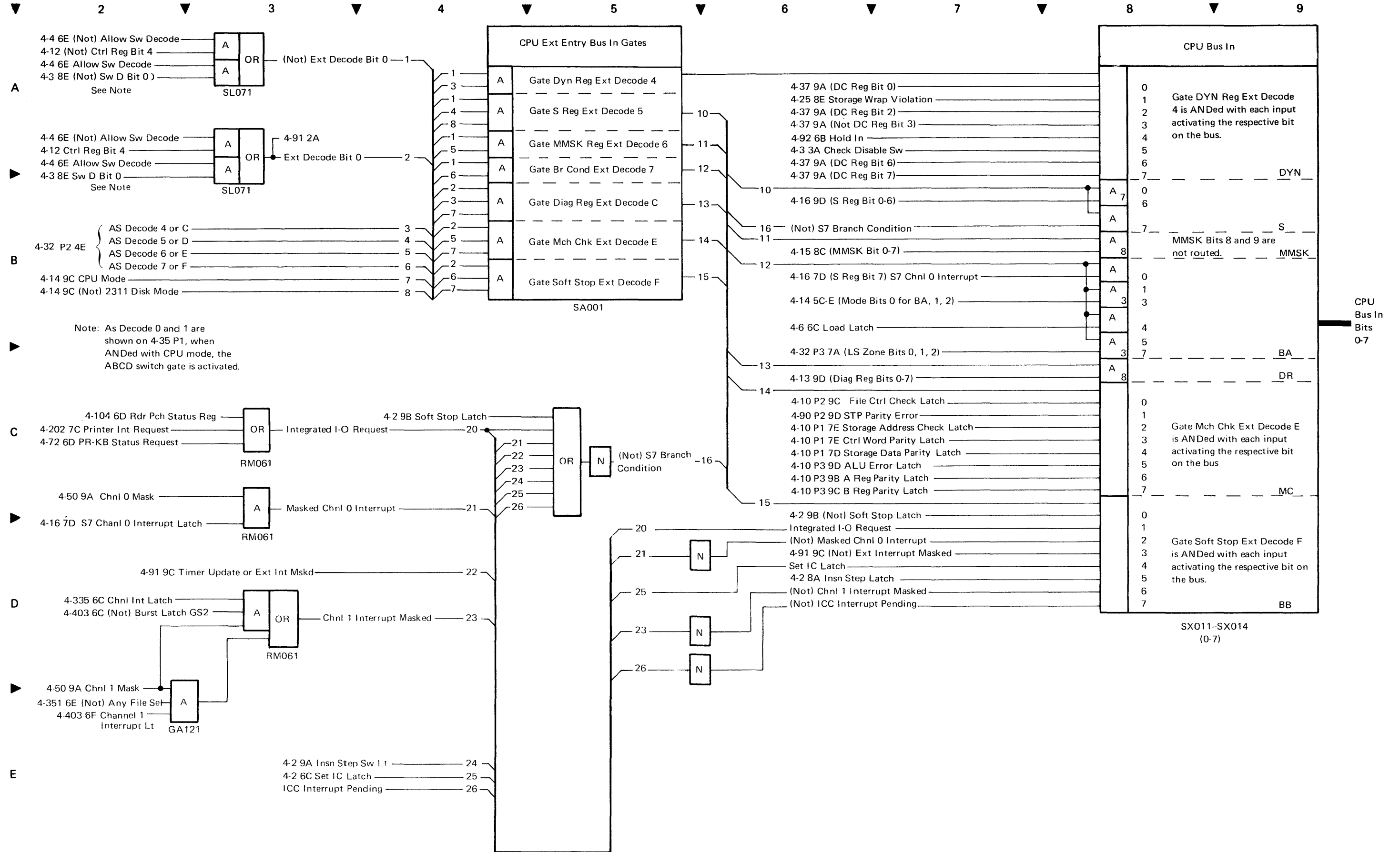


Diagram 4-41. External Facility (CPU Mode and Common) I-O CPU Bus In

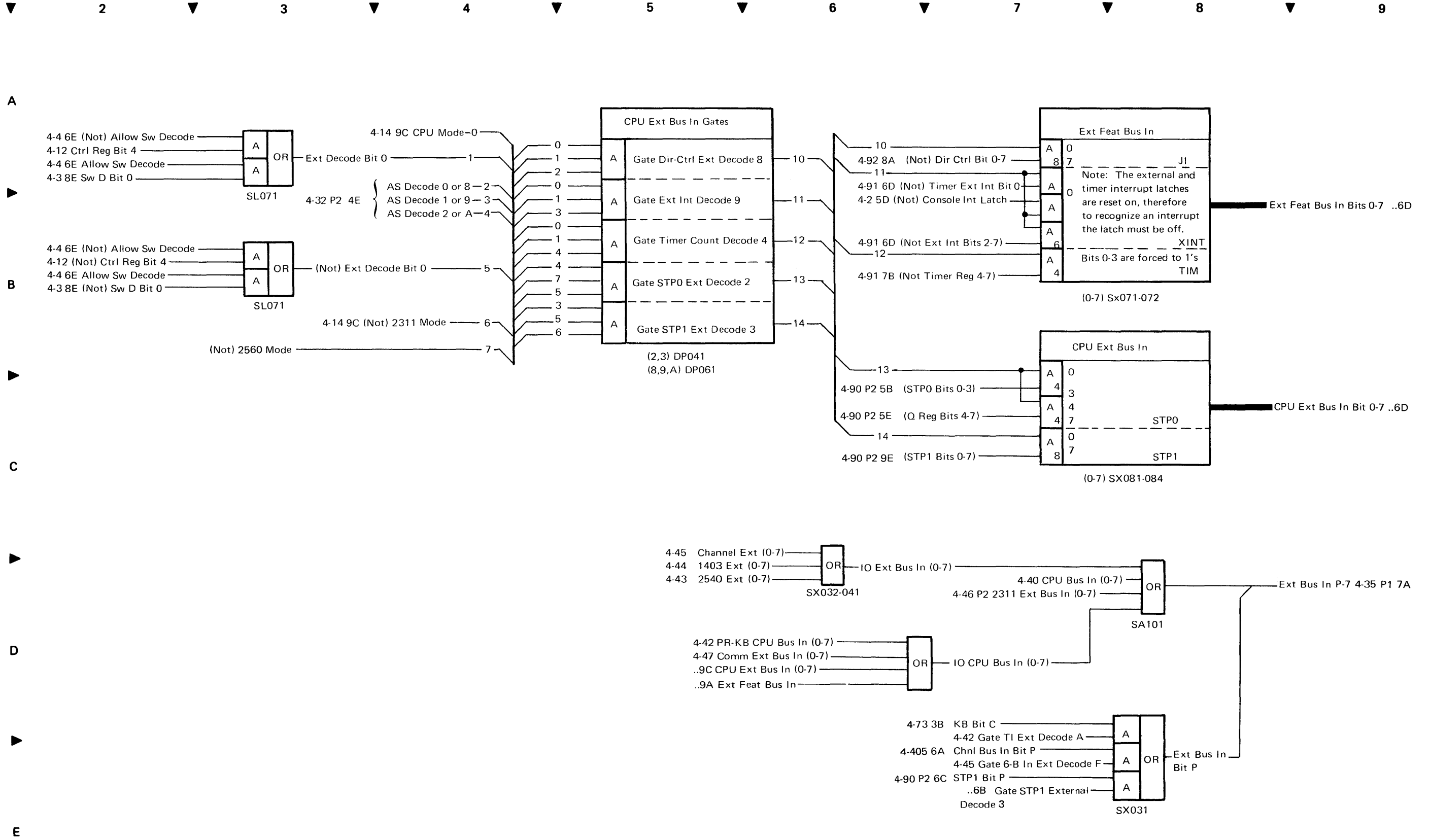


Diagram 4-42. External Facility (1052 Model) 1052 CPU Bus In

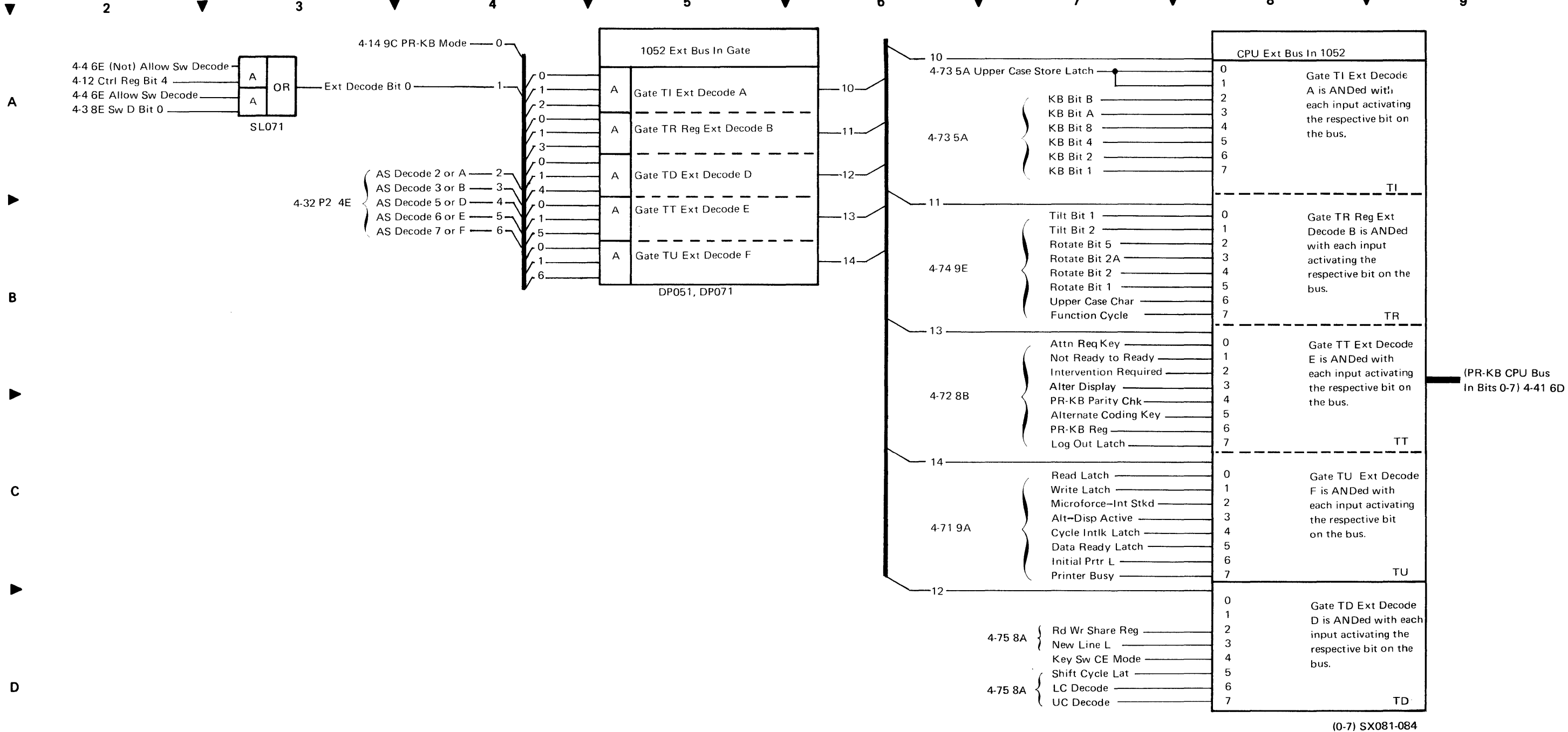


Diagram 4-43. External Facility (2540 Mode) 2540 Ext Bits 0-7

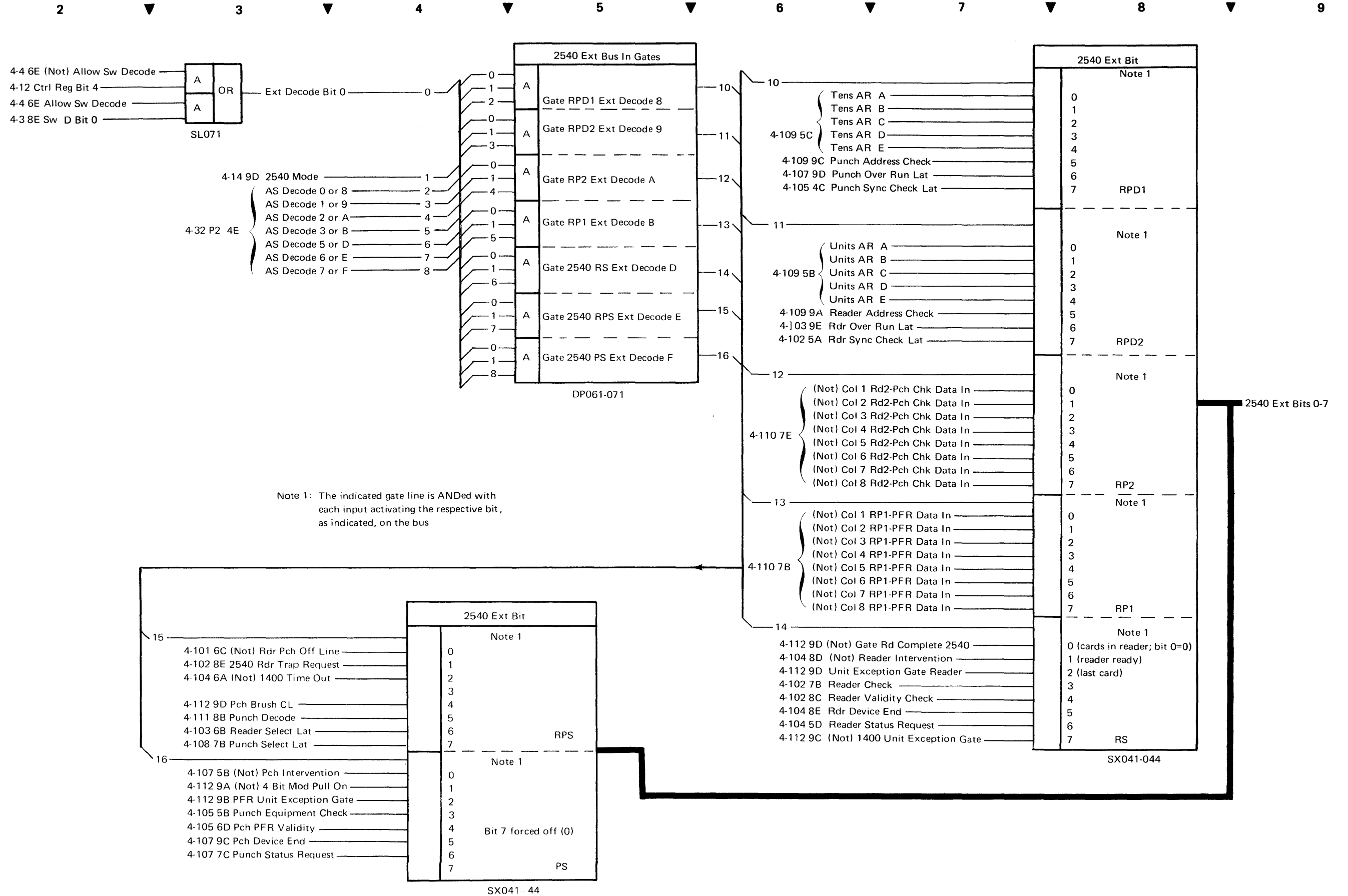


Diagram 4-44. External Facility (1403 Mode) 1403 External Bits

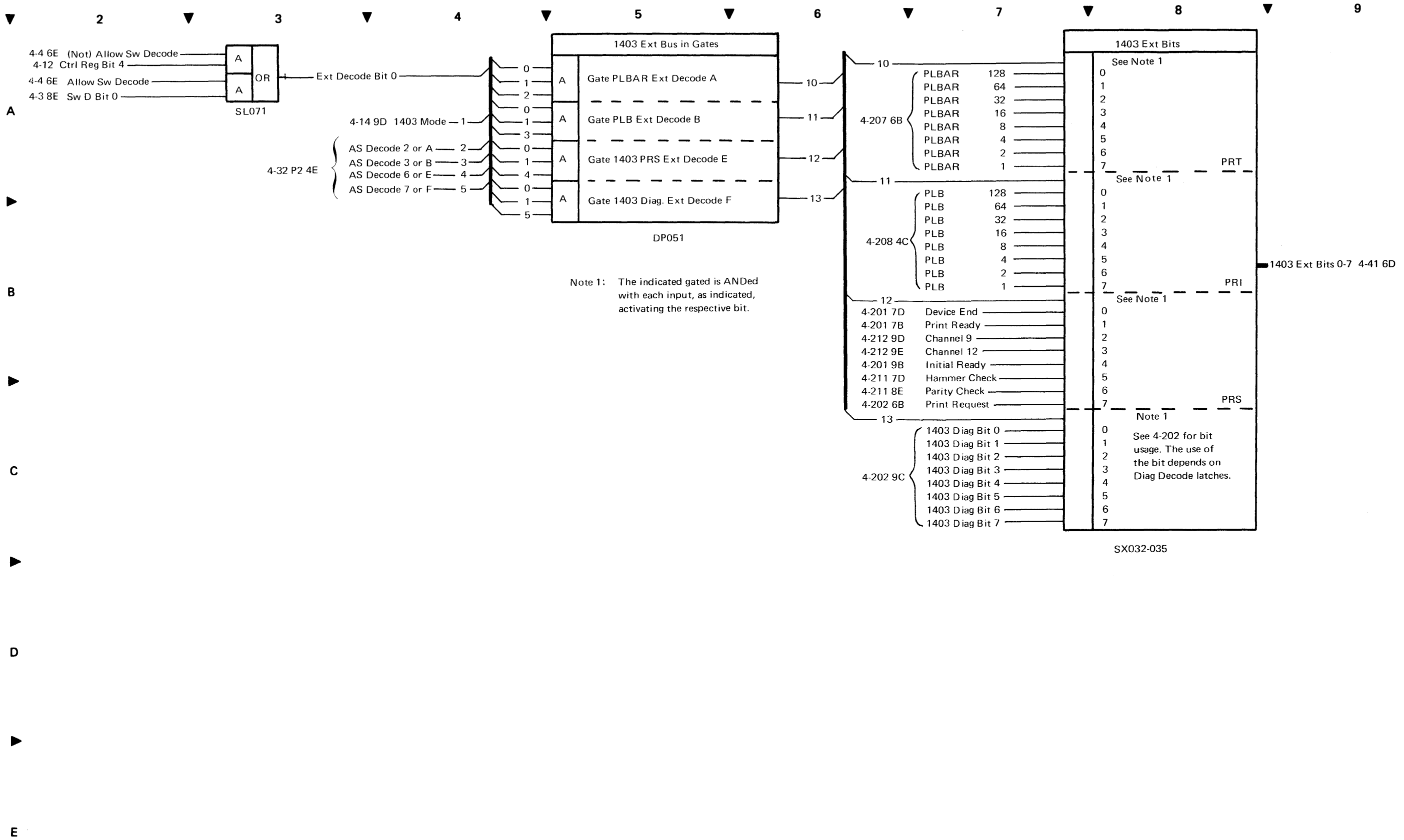


Diagram 4-45. External Facility (Channel Mode) Channel Ext Bus In

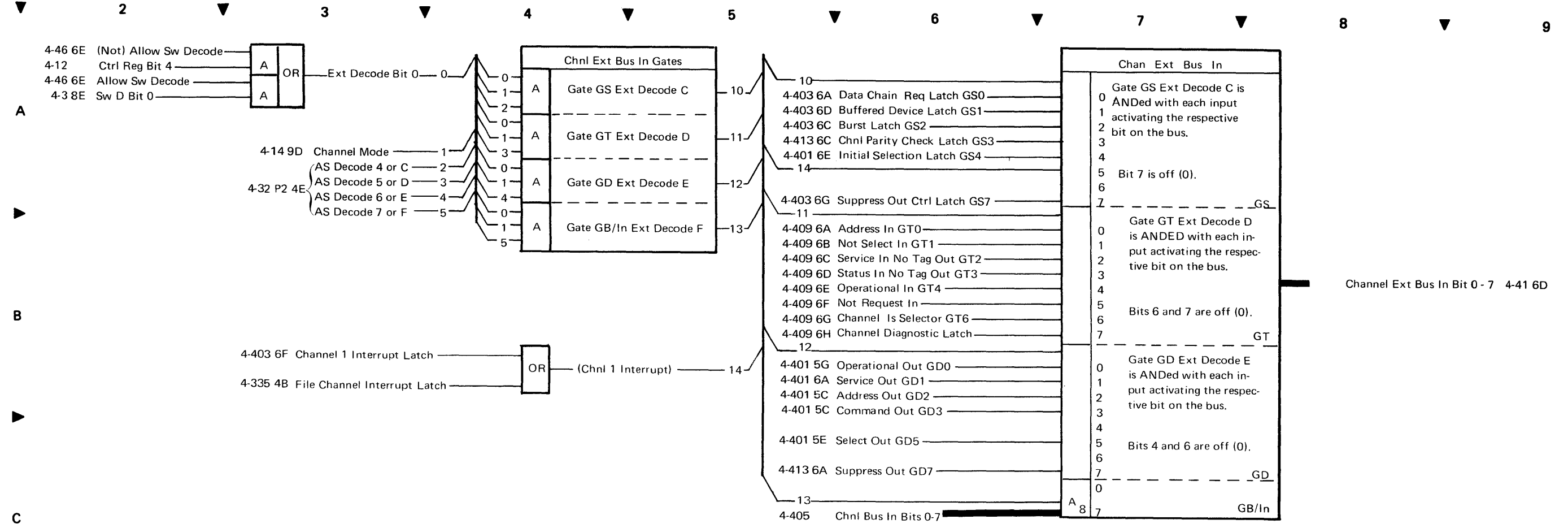
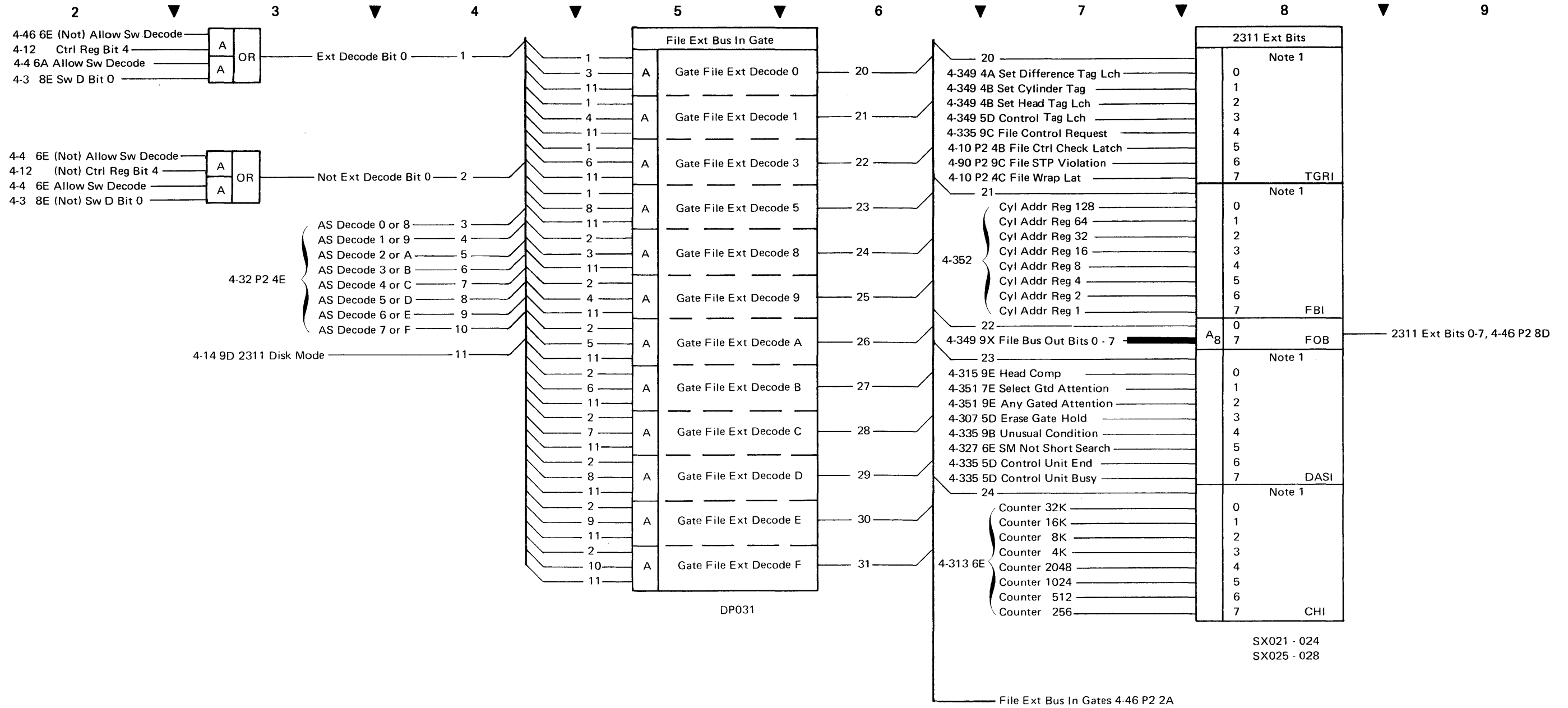
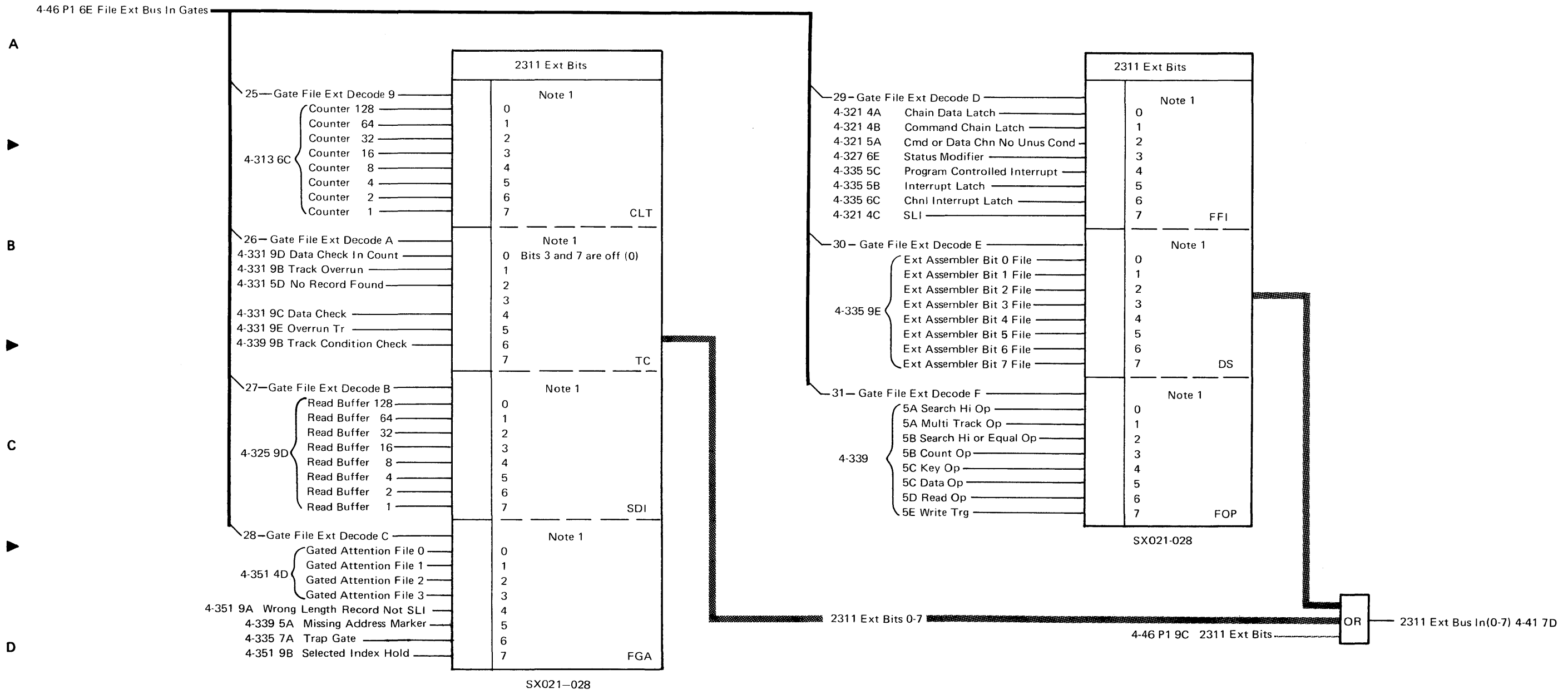


Diagram 4-46. External Facility (2311 Mode) 2311 Ext Bits (Part 1 of 2)



Note 1: The indicated gate line is ANDed with each input activating the respective bit, as indicated, on the bus.

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6 ▼ 7 ▼ 8 ▼ 9



Note 1: The indicated gate line is ANDed with each input activating the respective bit, as indicated, on the bus.

Diagram 4-47. External Facility (Communication Mode) Comm Ext Bus In

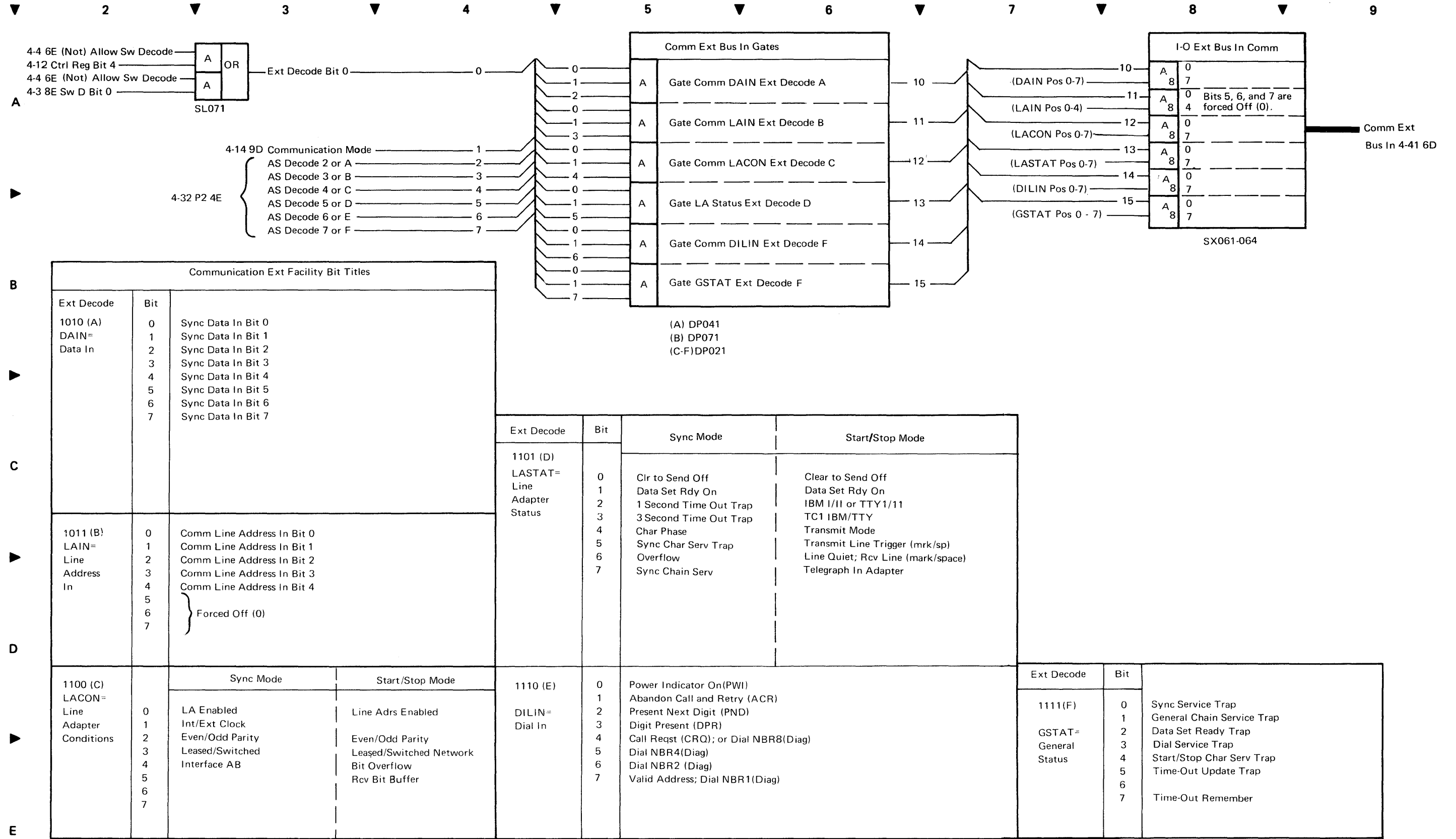


Diagram 4-50. System Mask, Mach Chk Mask, Wait State

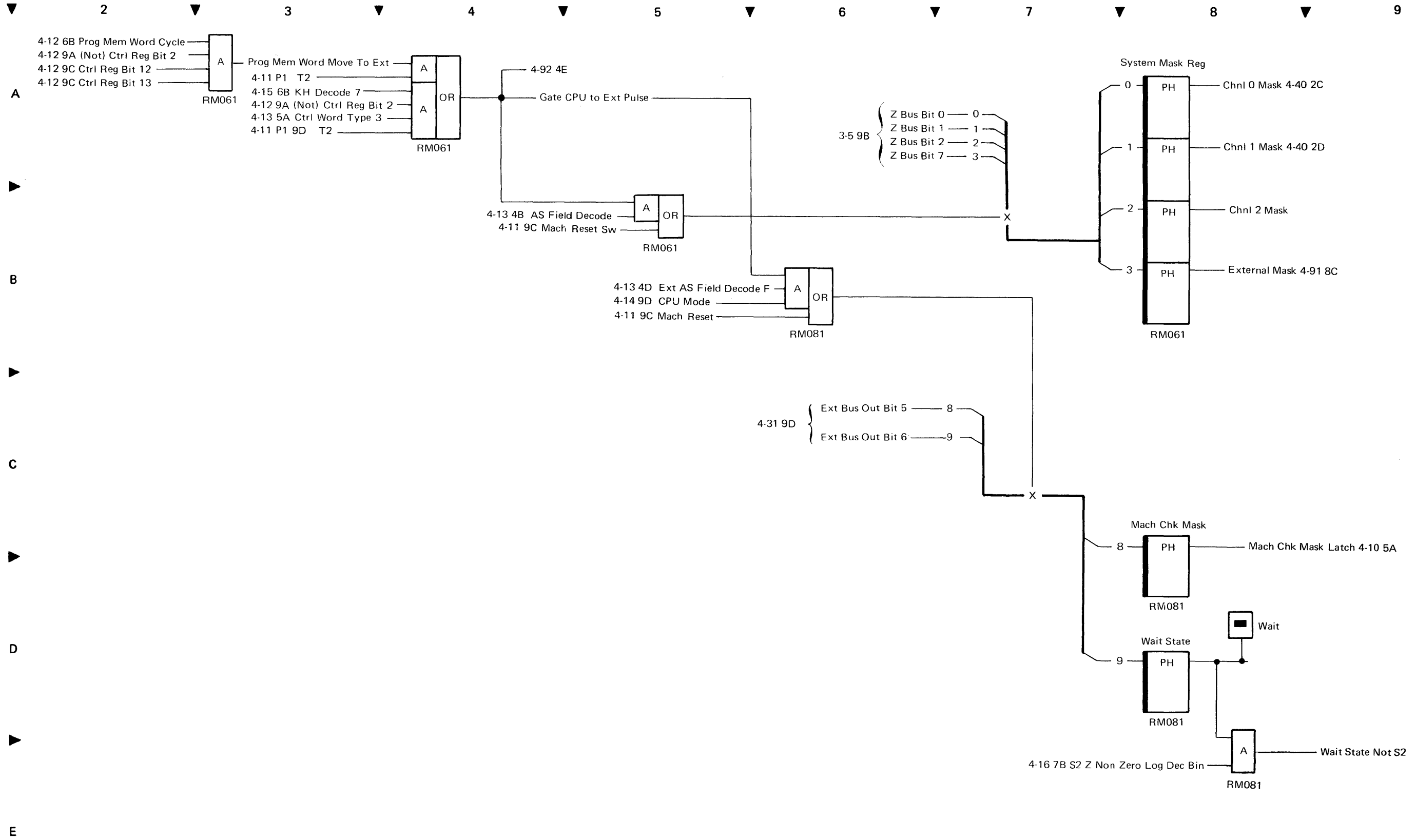


Diagram 4-70. External Out Interface (PR-KB)

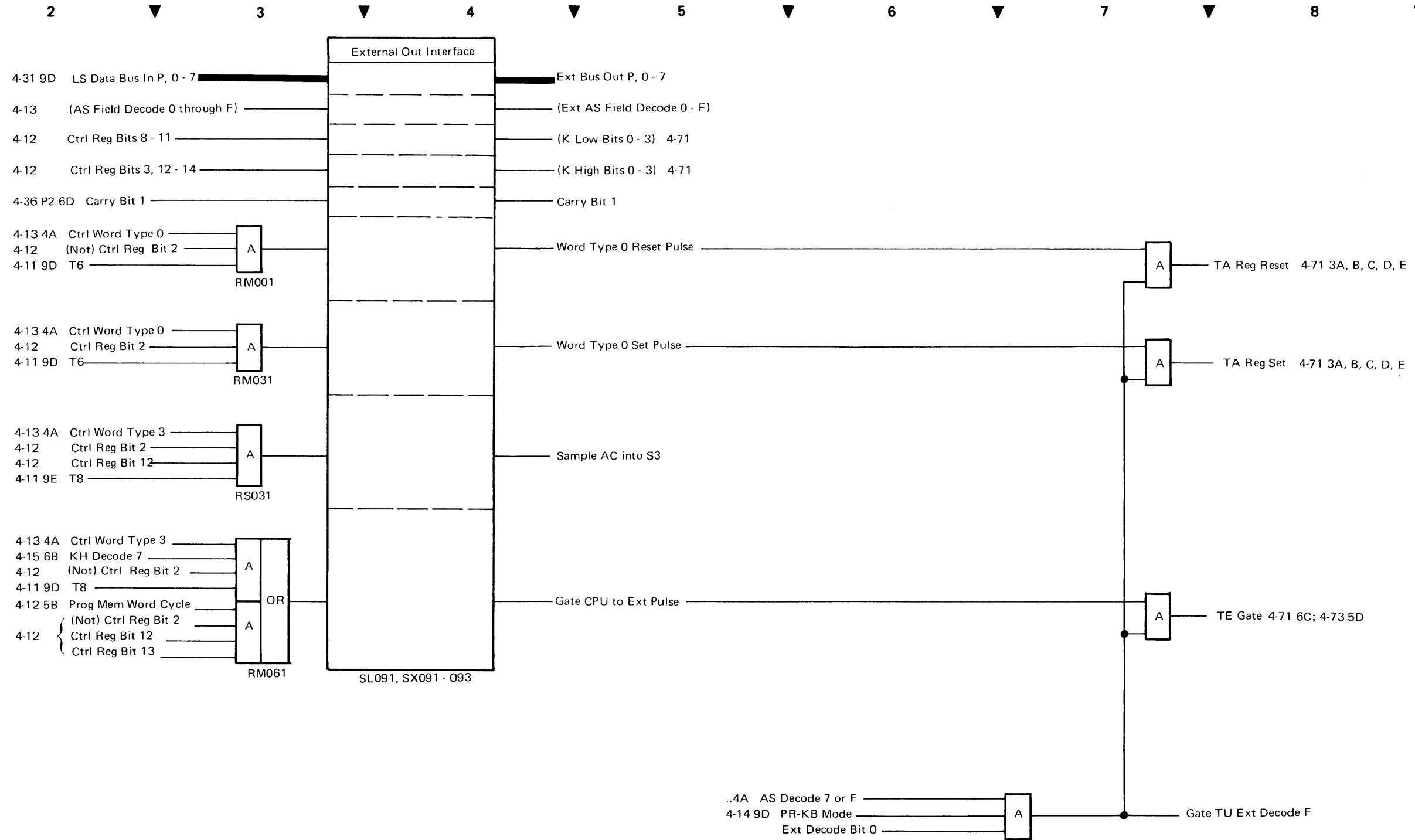


Diagram 4-71. TA (Controls Out) and TU (Branch Conditions) External Fields

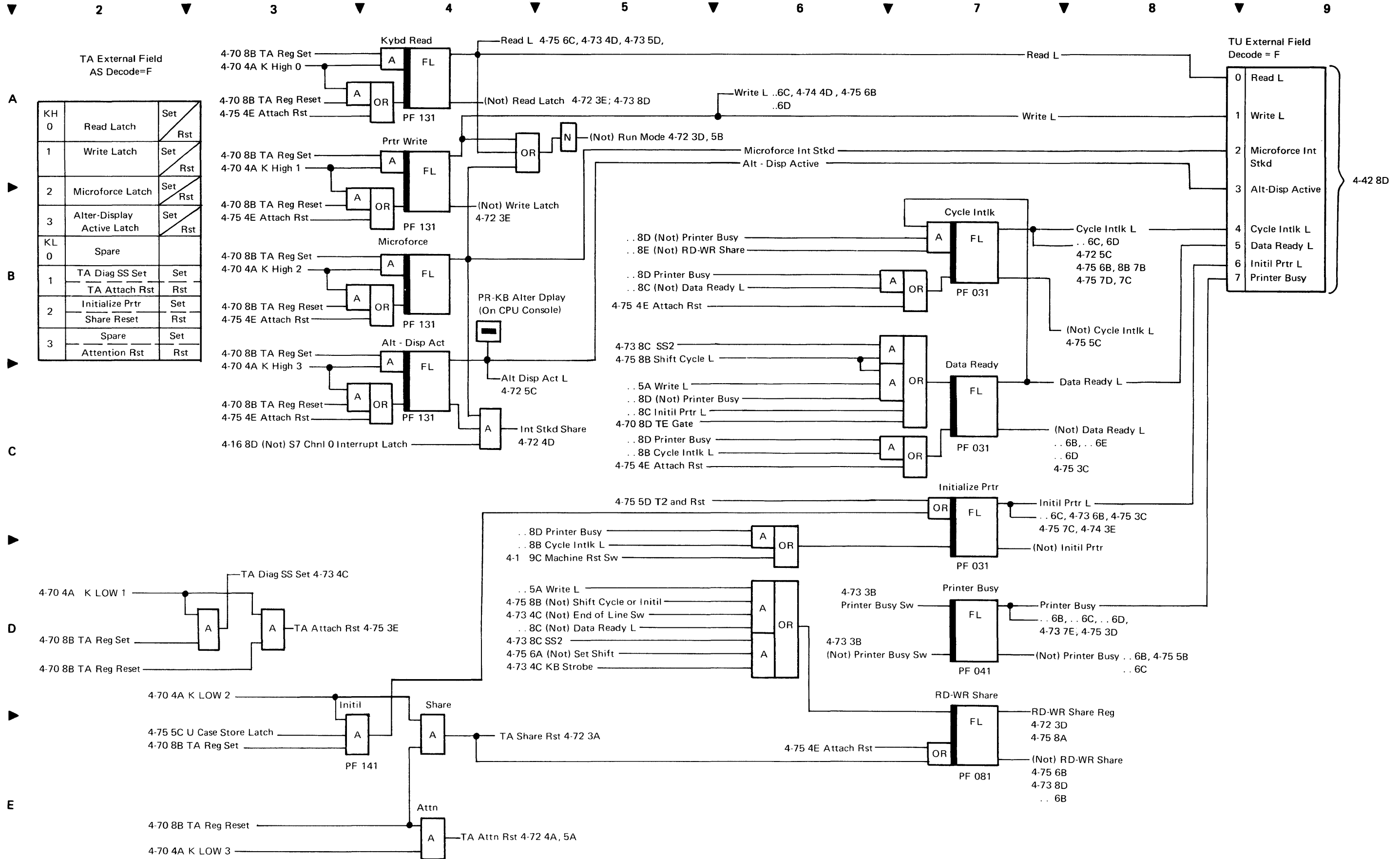
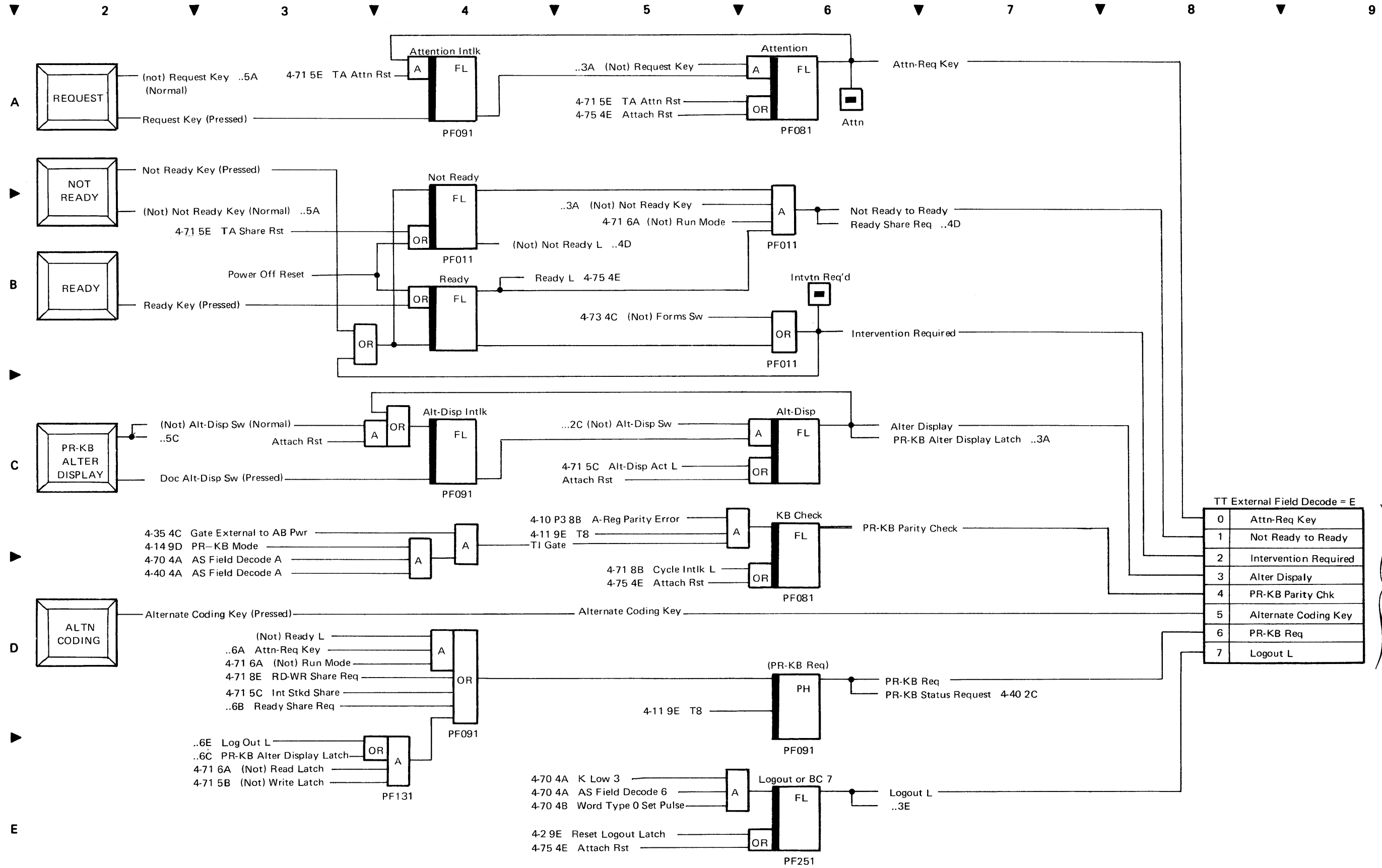


Diagram 4-72. TT External Field (Branch Conditions)



TT External Field Decode = E

0	Attn-Req Key
1	Not Ready to Ready
2	Intervention Required
3	Alter Display
4	PR-KB Parity Chk
5	Alternate Coding Key
6	PR-KB Req
7	Logout L

4-42 8C

Diagram 4-73. TI External Field and Single Shots

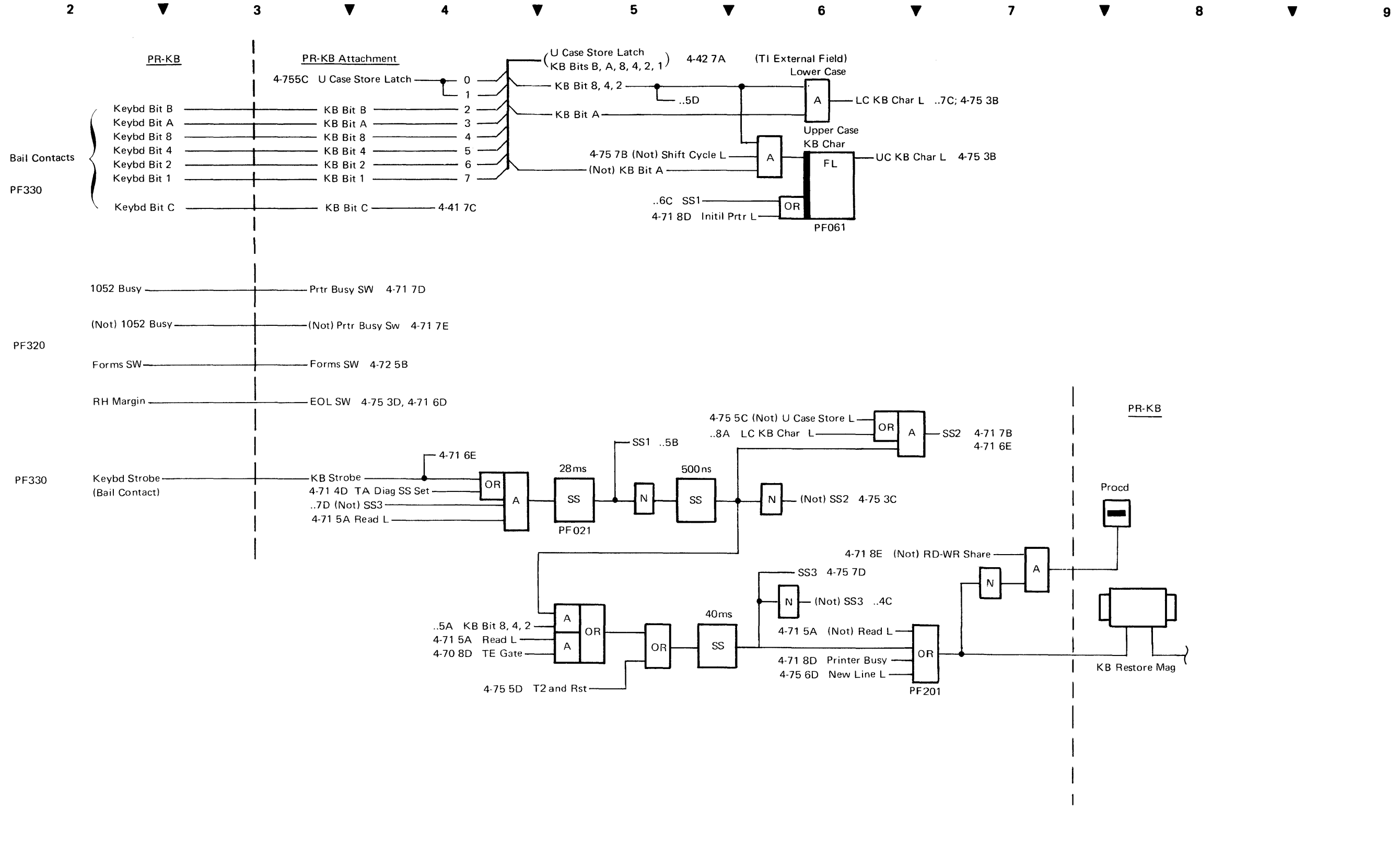
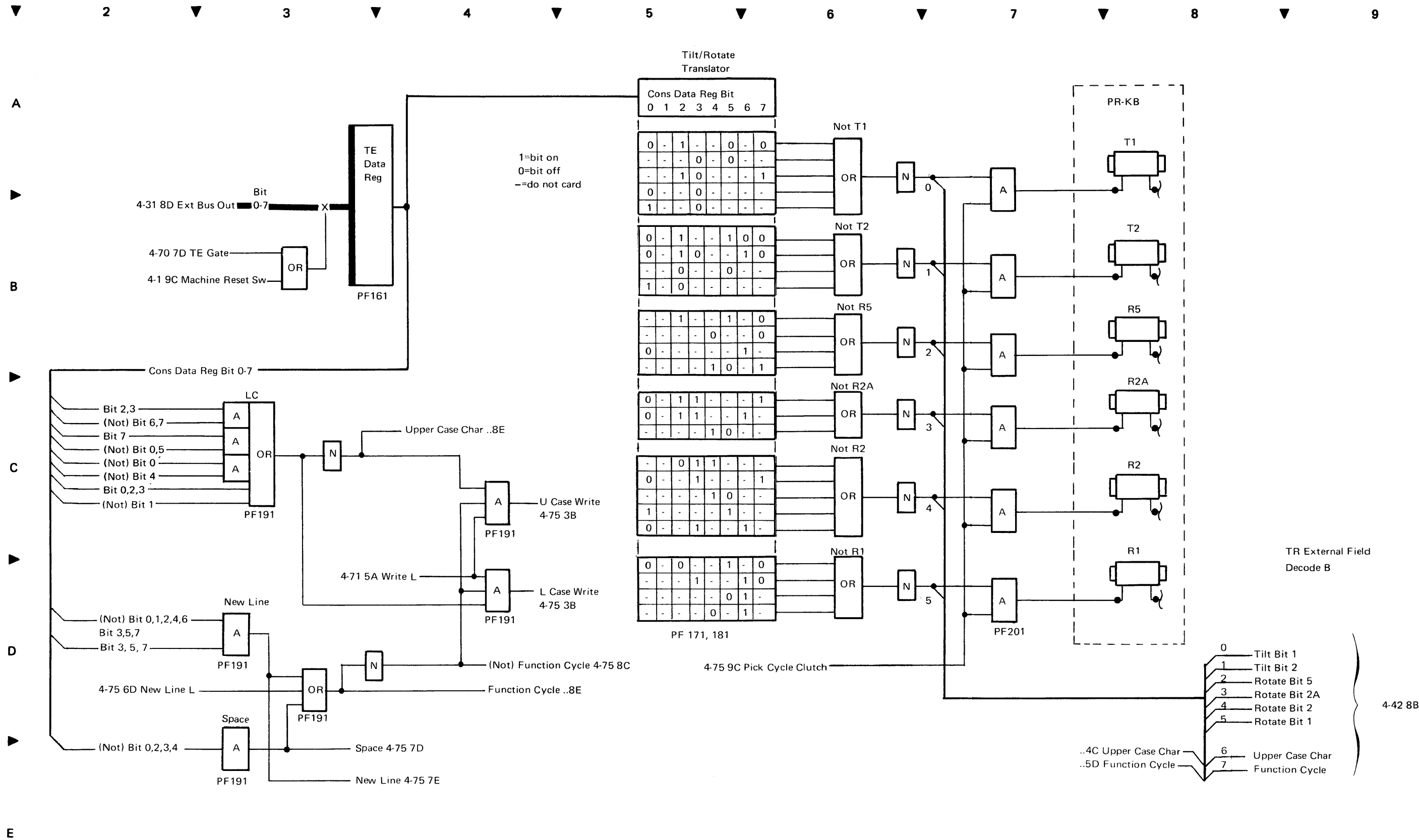


Diagram 4-74. TE Data Reg, Tilt Rotate Translator, Function/Decode and TR External



4-42 8B

Diagram 4-75. Function and Cycle Control

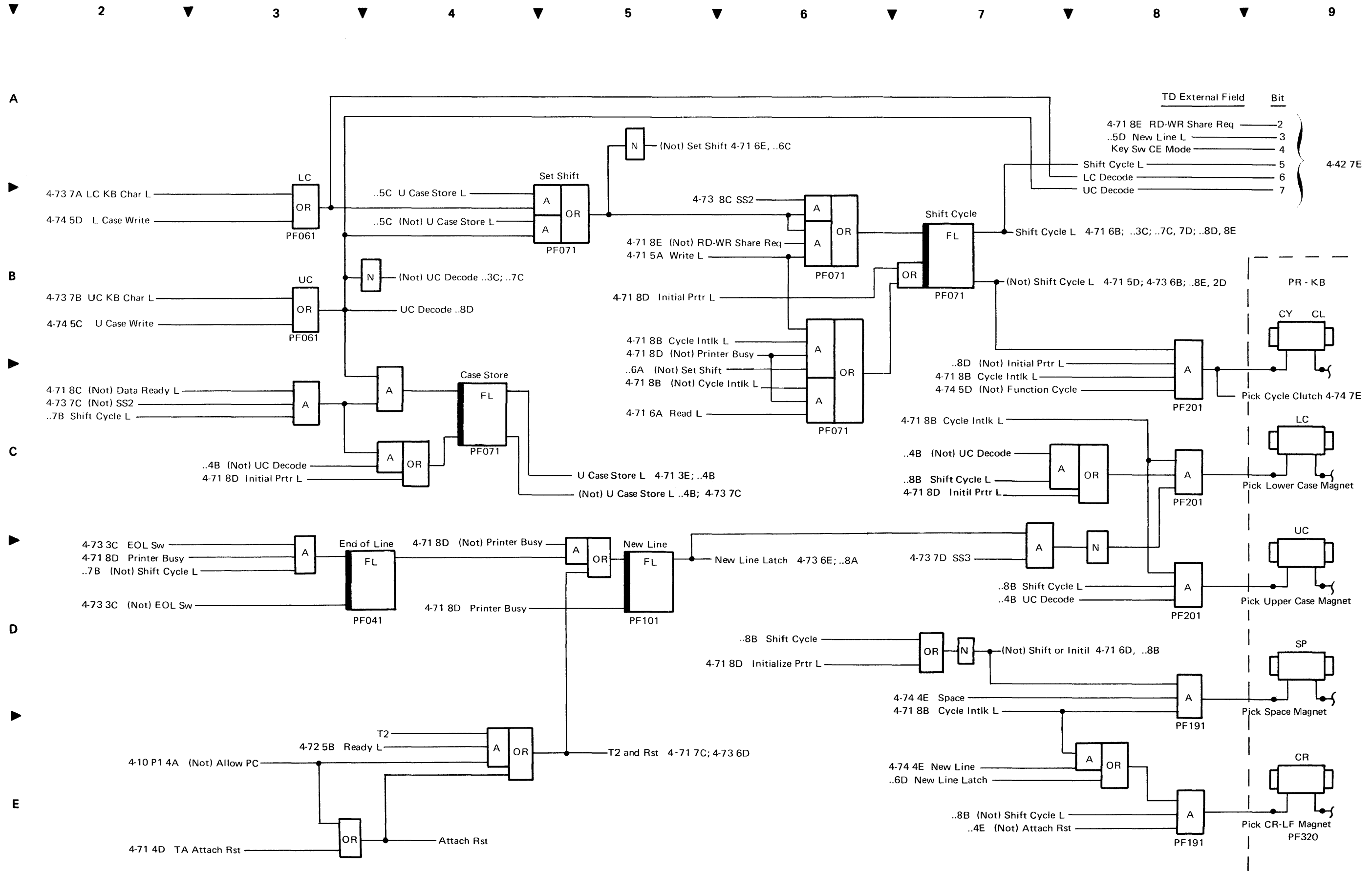
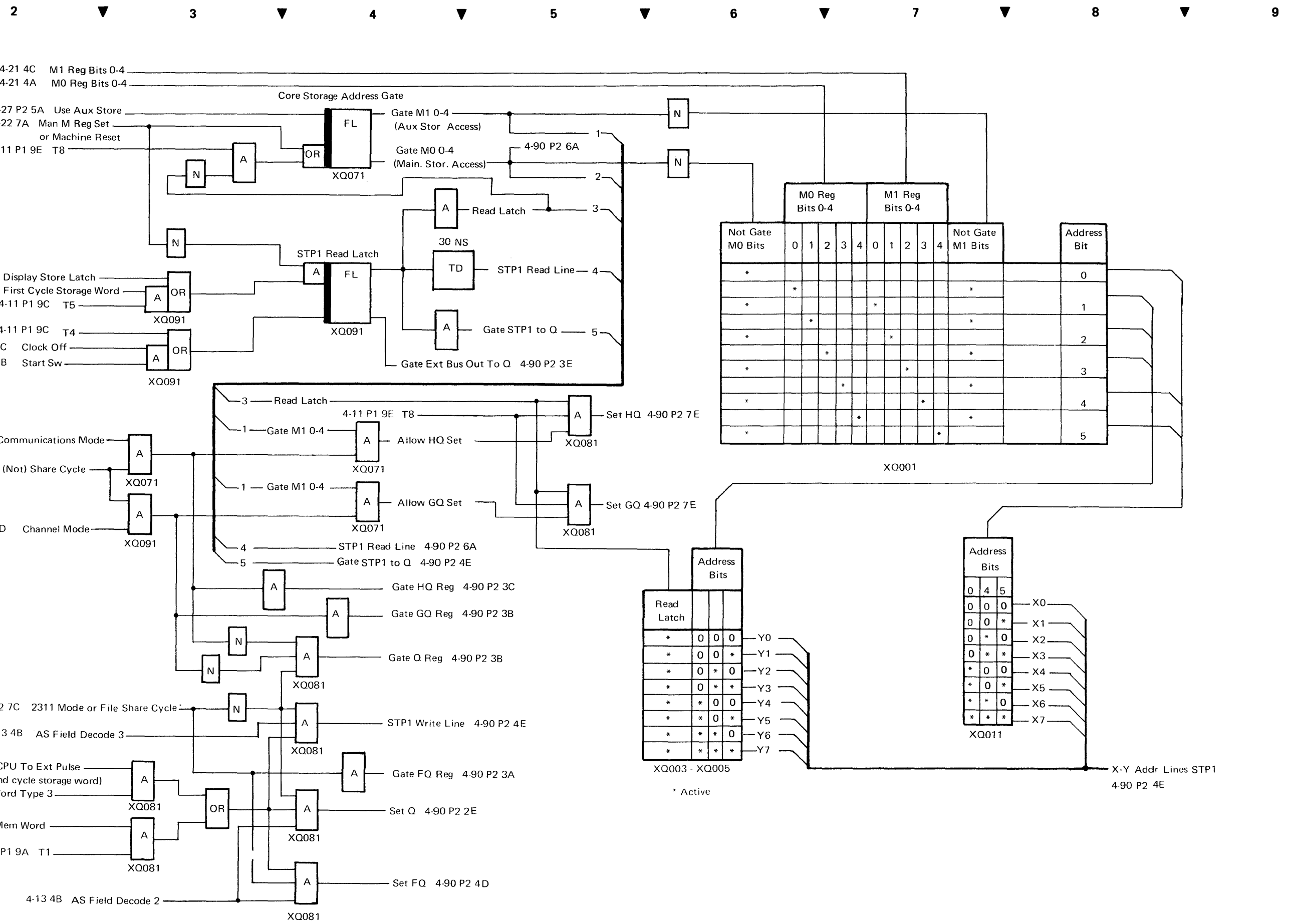


Diagram 4-90. Storage Protection (Part 1 of 2)



X-Y Addr Lines STP1
4-90 P2 4E

* Active

Diagram 4-90. Storage Protection (Part 2 of 2)

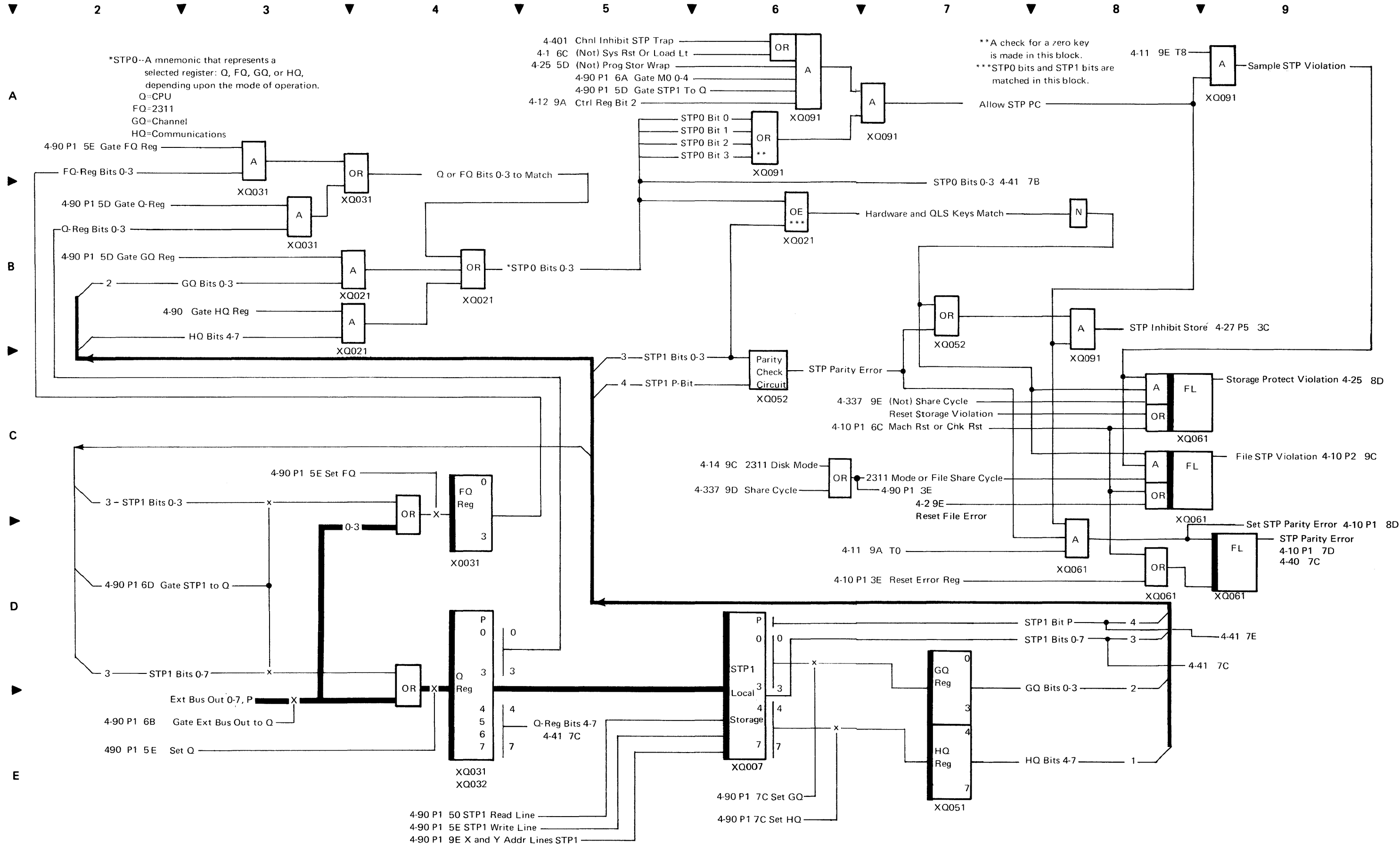


Diagram 4-91. Interval Timer, External Interrupt Register

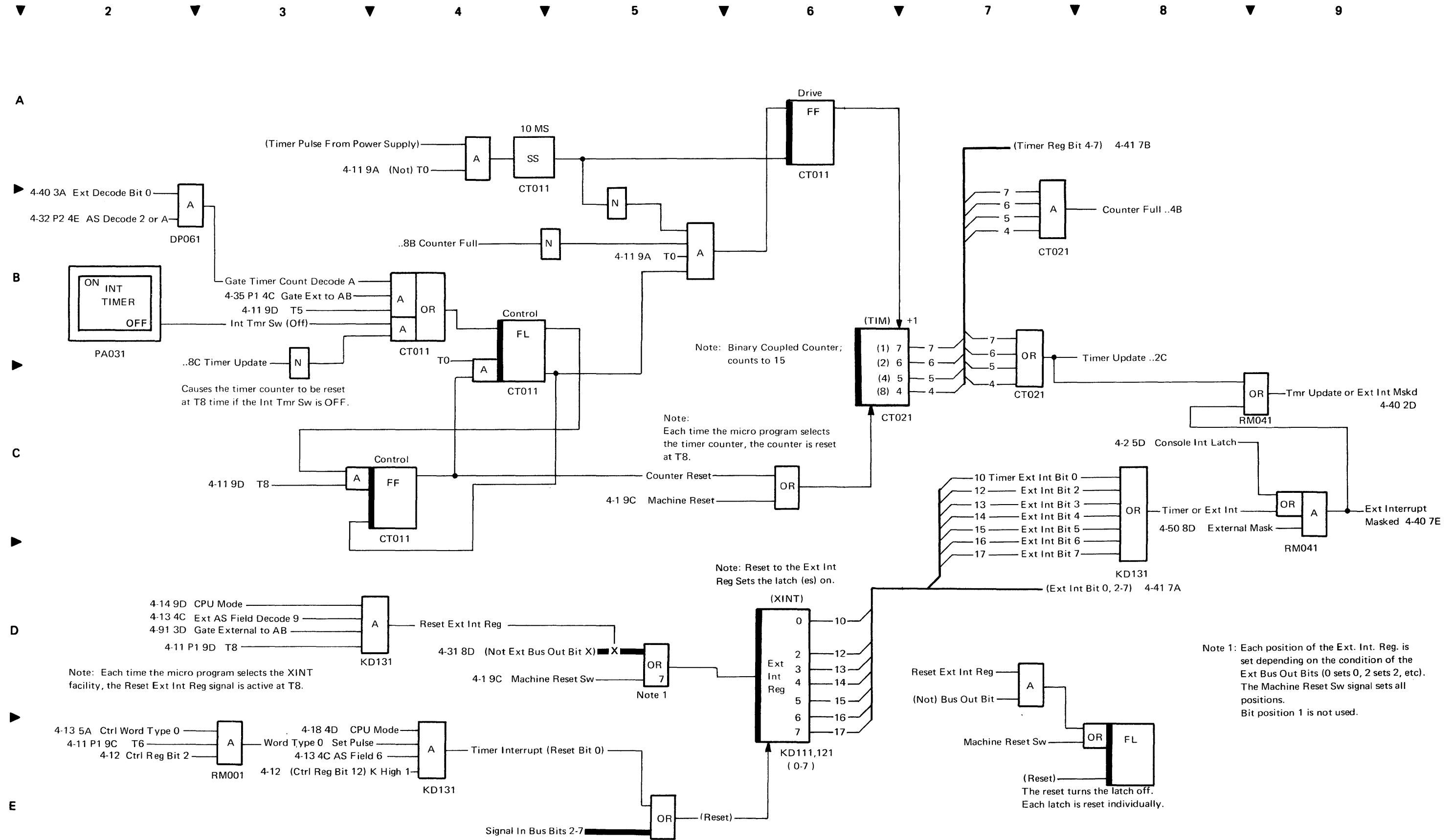


Diagram 4-92. Read-Direct Control

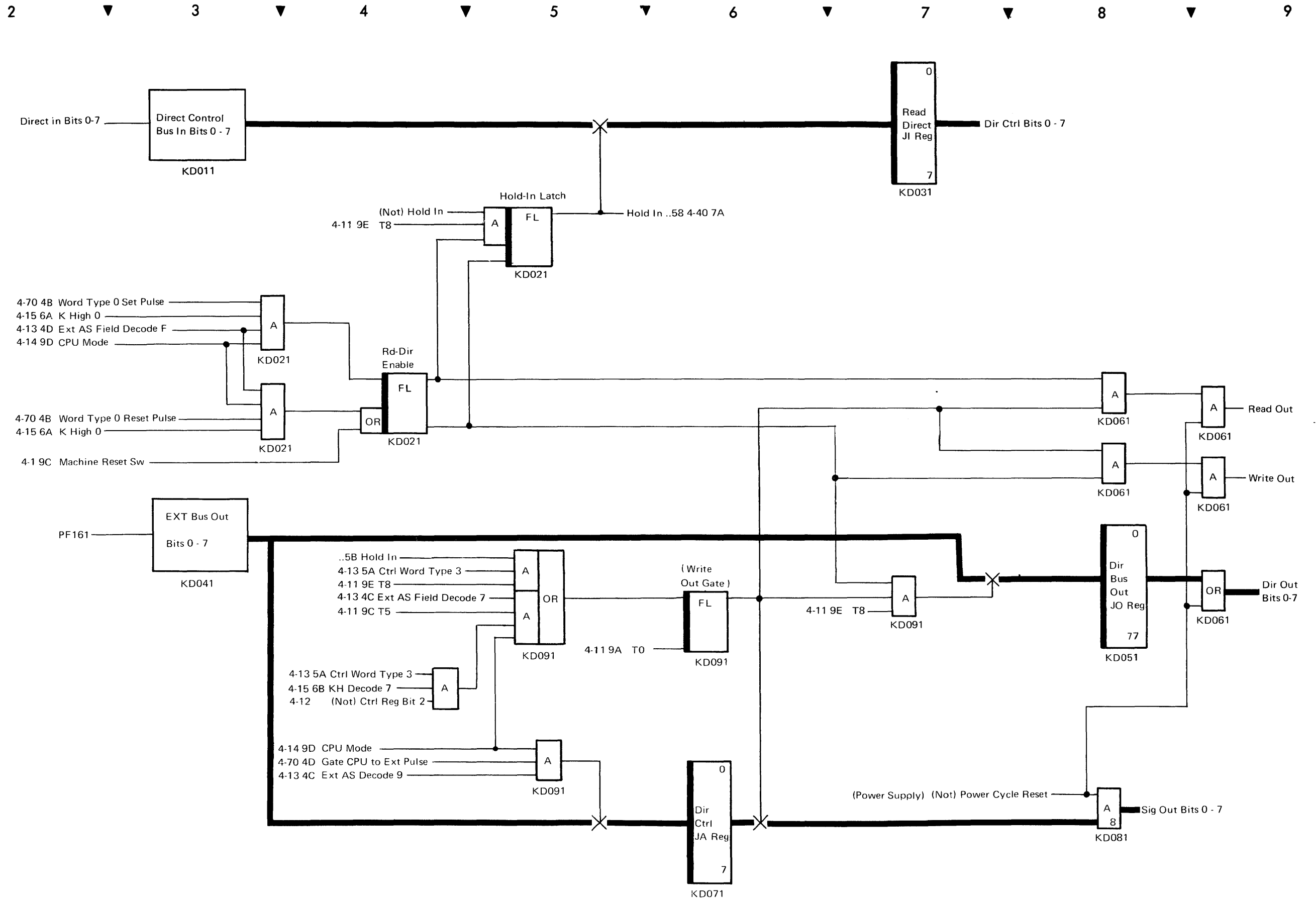


Diagram 4-100. External Out Interface (2540)

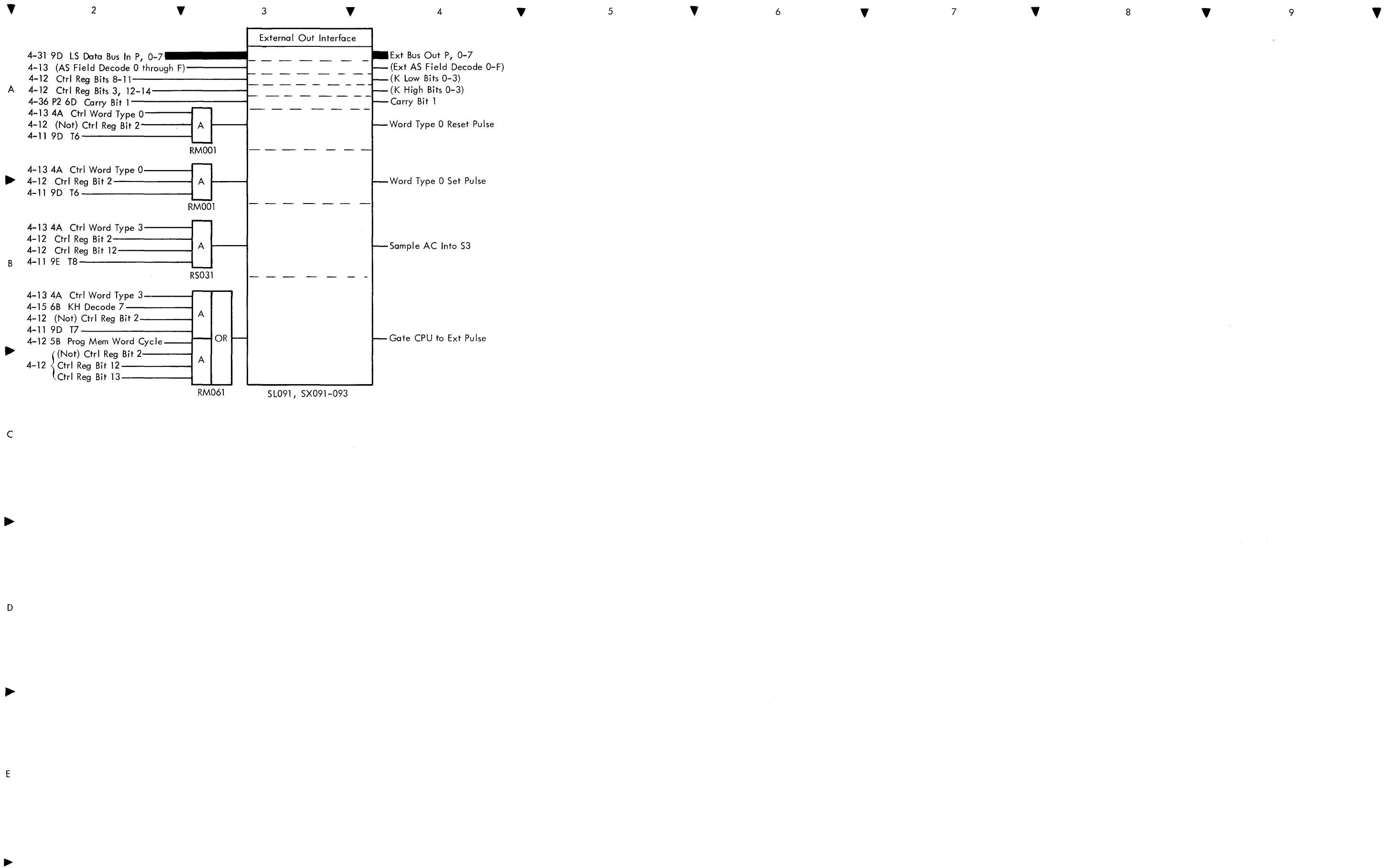


Diagram 4-101. Clock, Integrated Reset

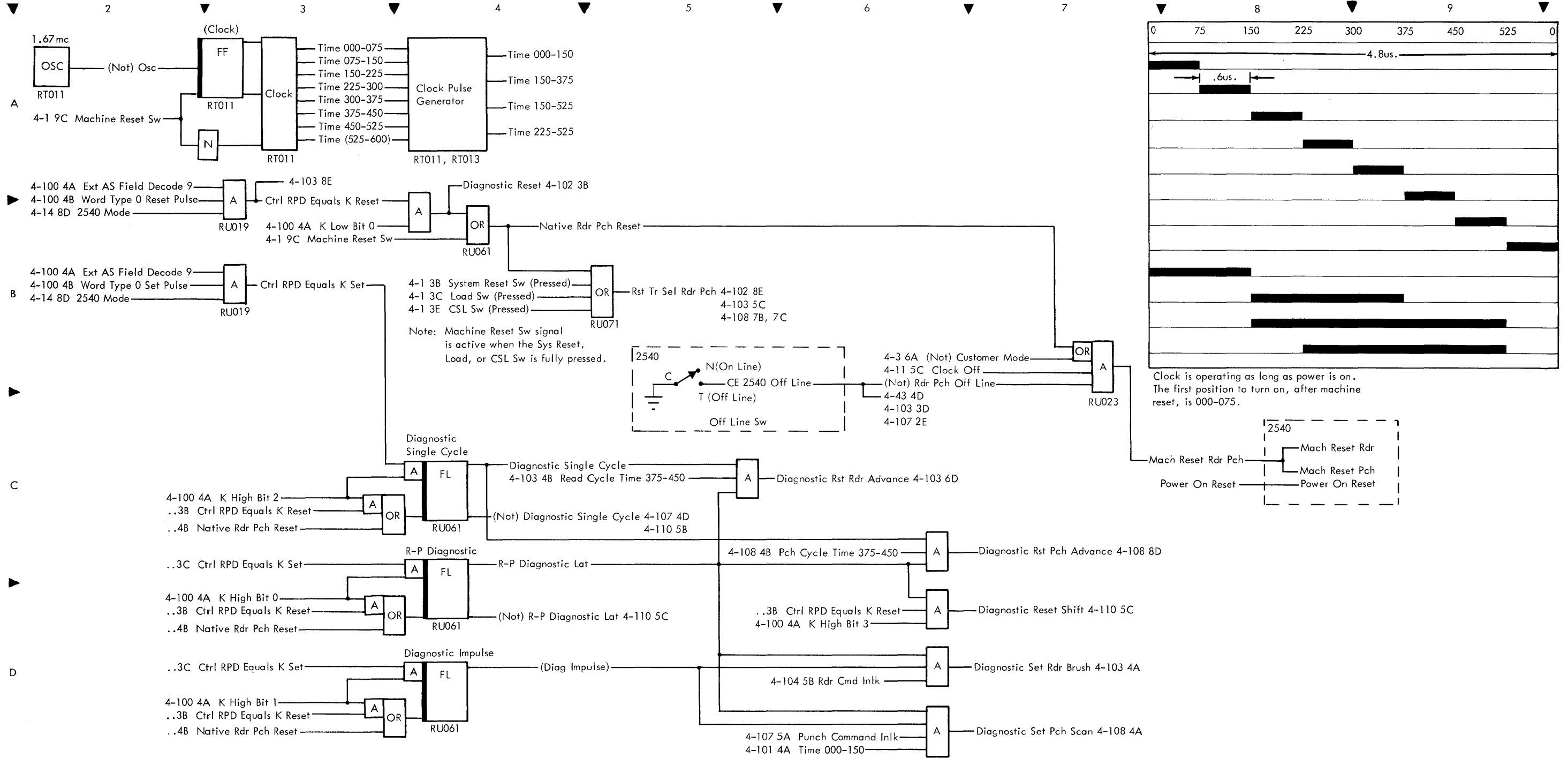
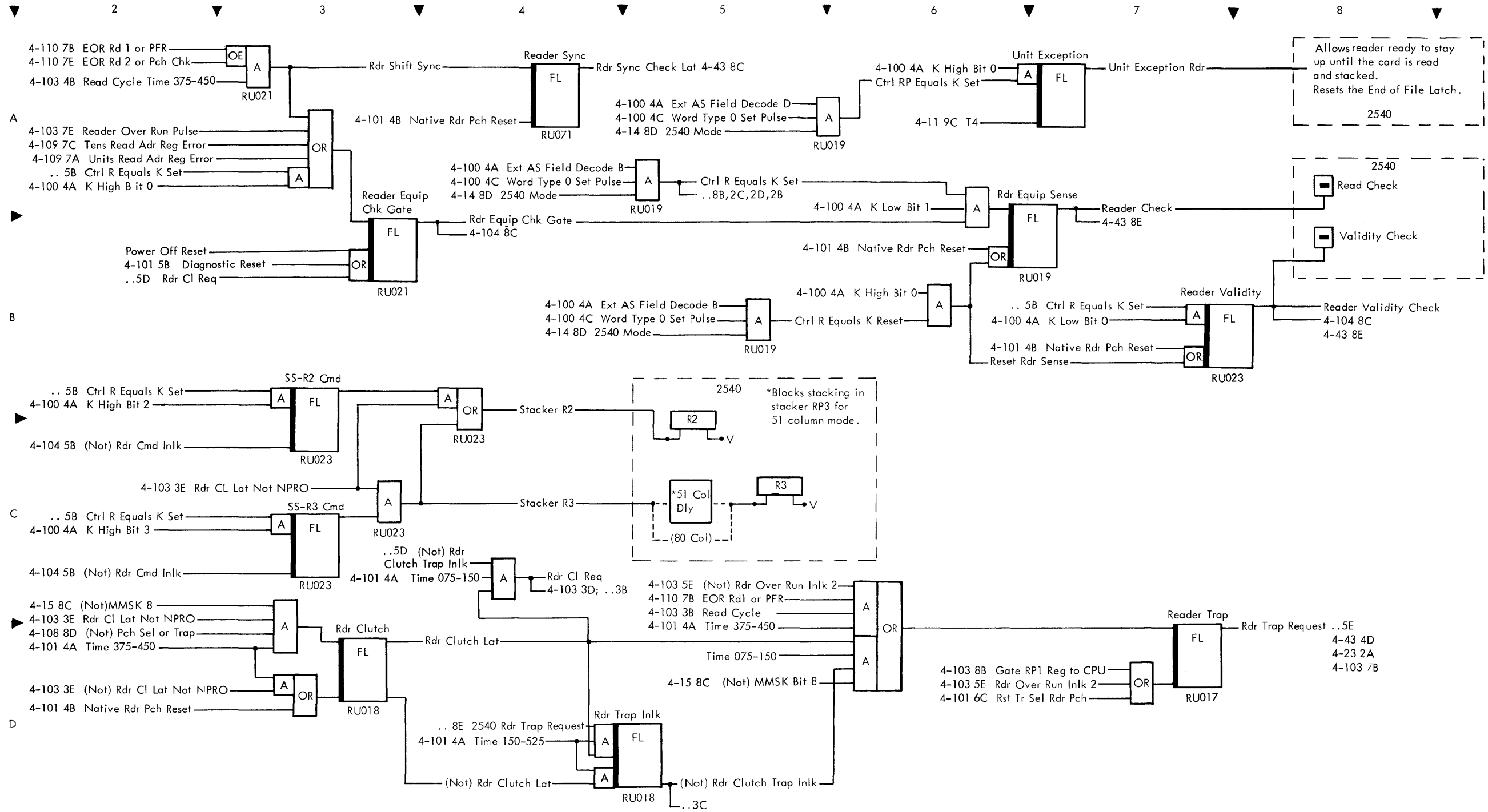


Diagram 4-102. Reader Checks, Stacker Select and Reader Traps



E

Diagram 4-103. Reader Controls

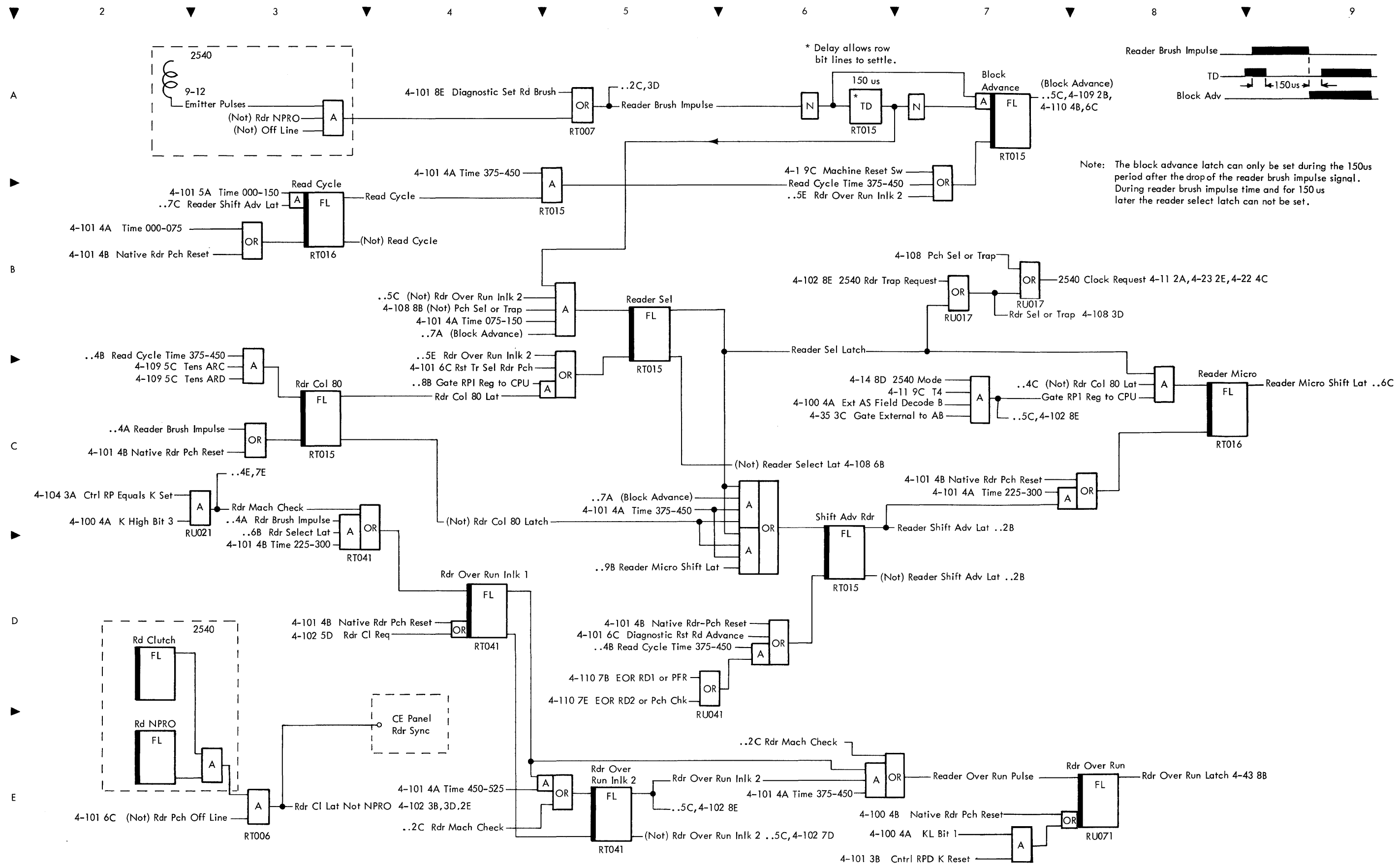


Diagram 4-104. Reader Controls, Status

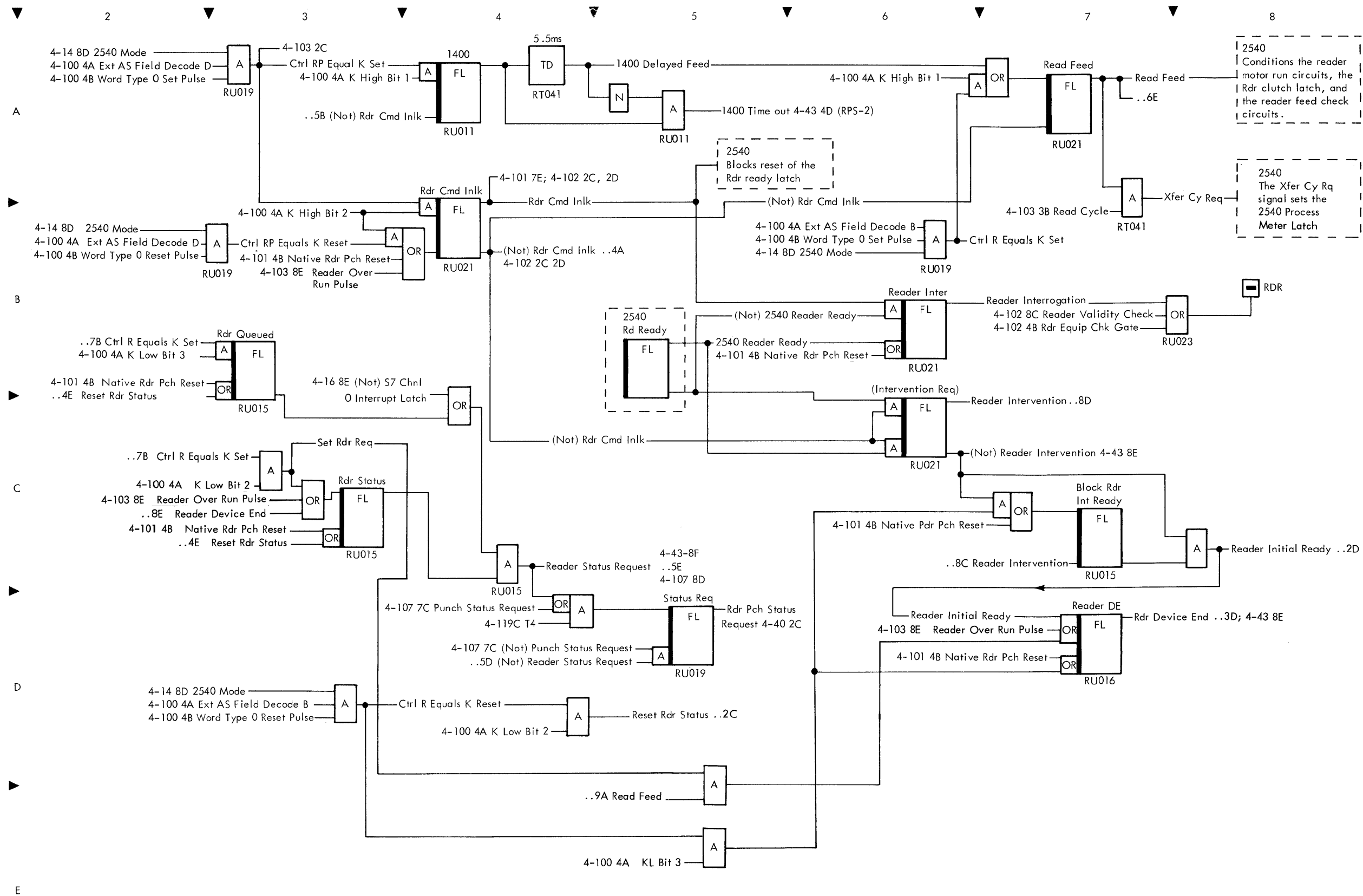


Diagram 4-105. Punch Checks

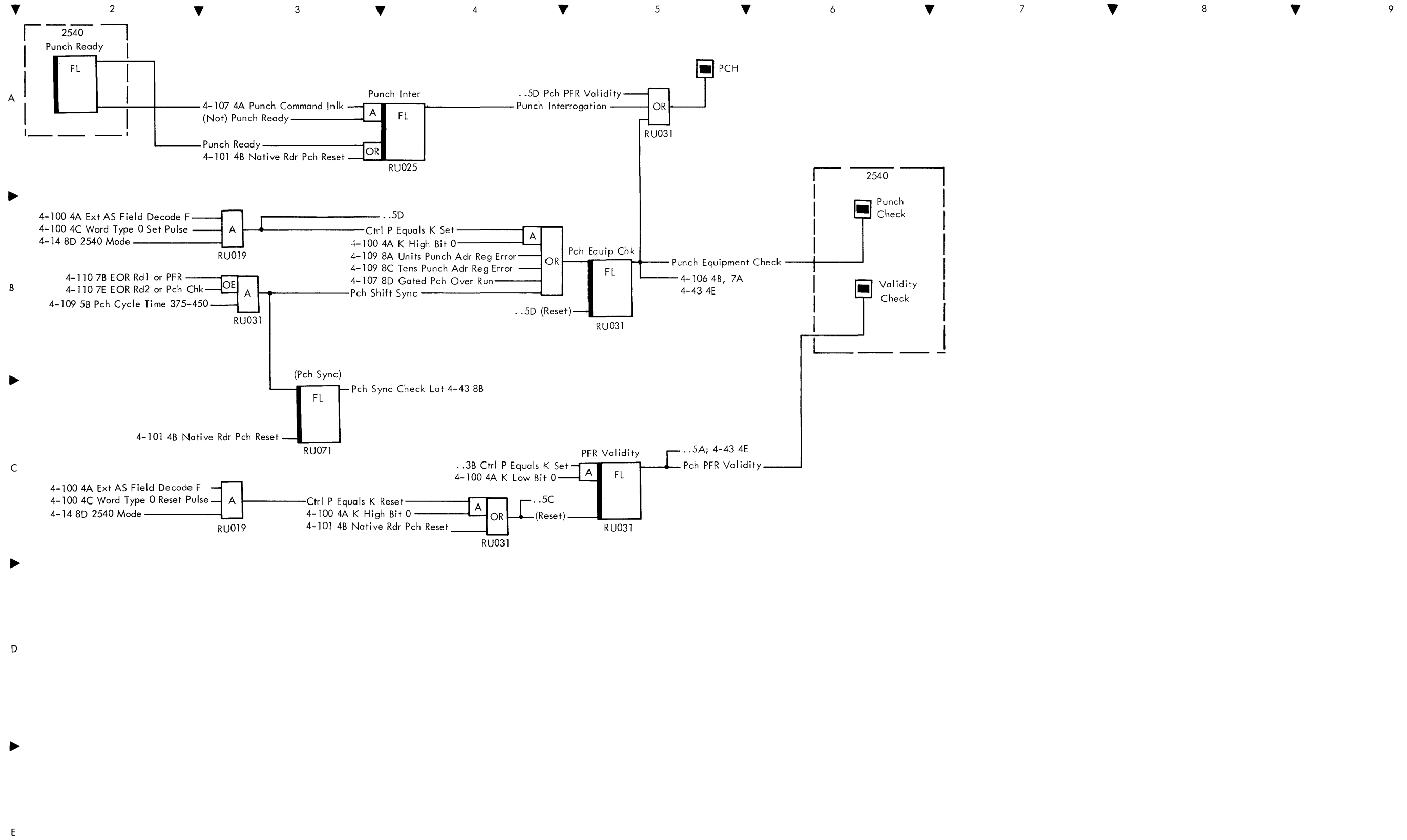
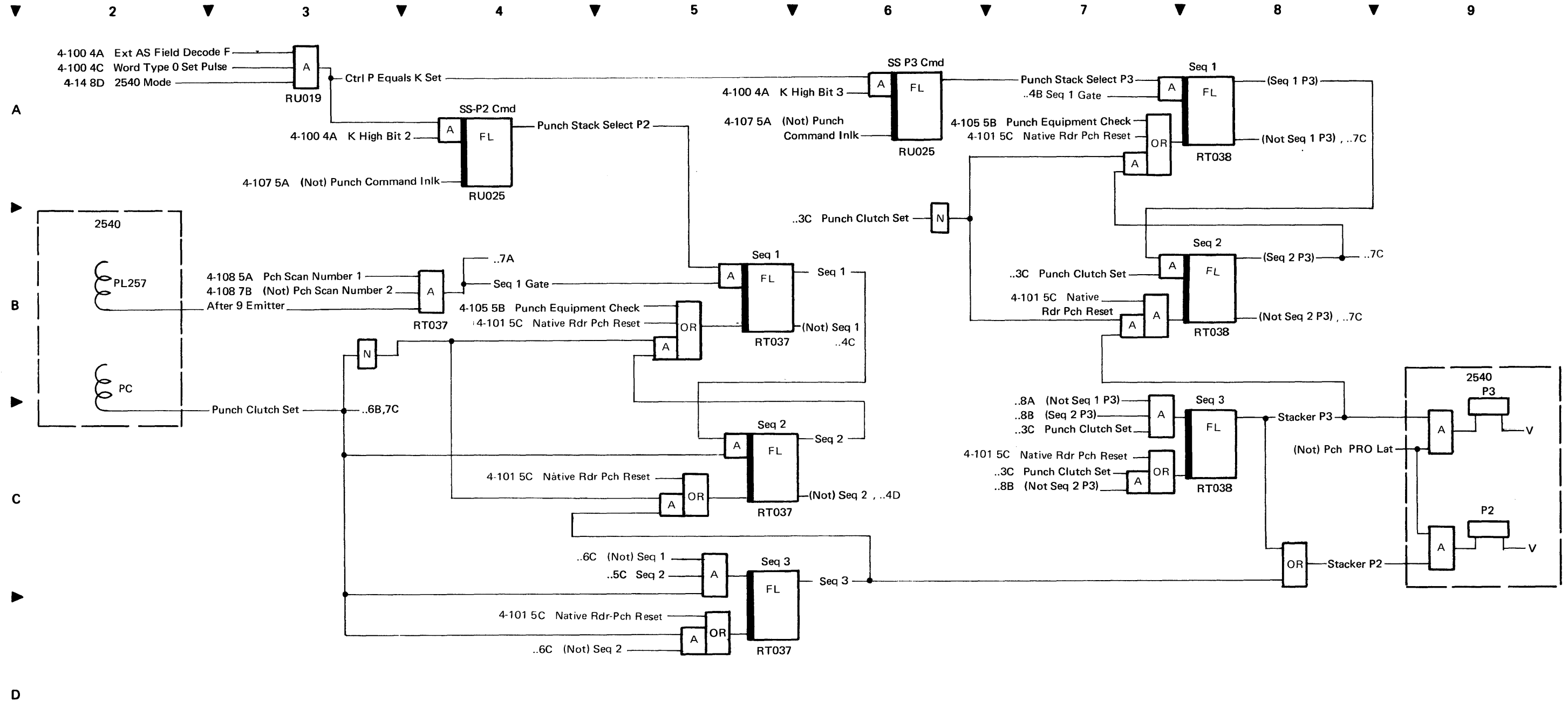


Diagram 4-106. Punch Stacker Selector



D

Cycle	Punch				Check				Stack			
	9	117	226	315	9	117	226	315	9	117	226	
1	Punch Clutch Set											
2	After 9 Emitter											
3	Sequence 1 Lat											
4	Sequence 2 Lat											
5	Sequence 3 Lat											
6	Stacker Magnet											
7	Stacker Px Cmd											
	Punch Cmd (Stacker info held one cycle by micro)				Reset by next Pch Cmd				52° Card at chute blade			

E

Diagram 4-107. Punch Controls, Status

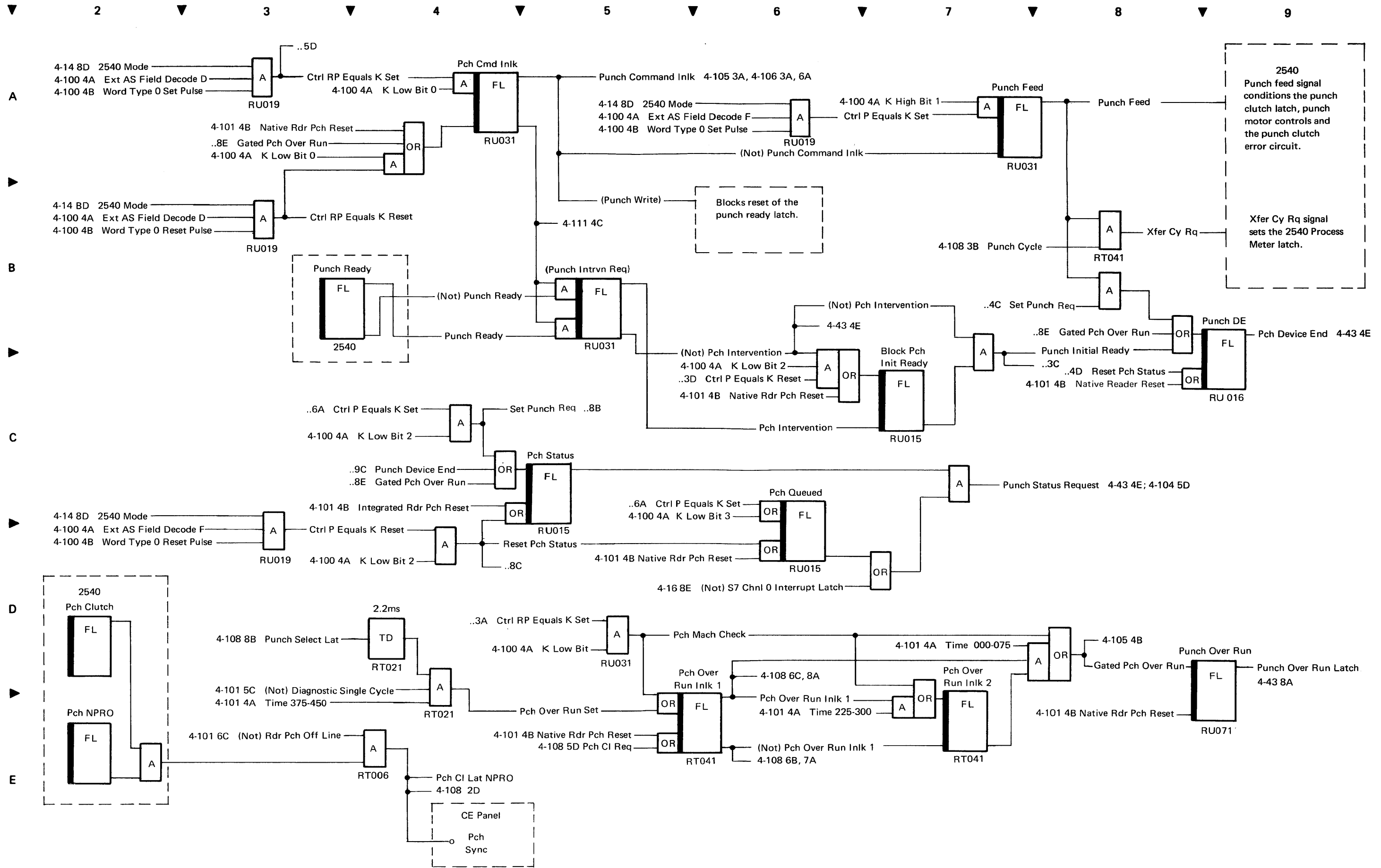


Diagram 4-108. Punch Controls, Trap

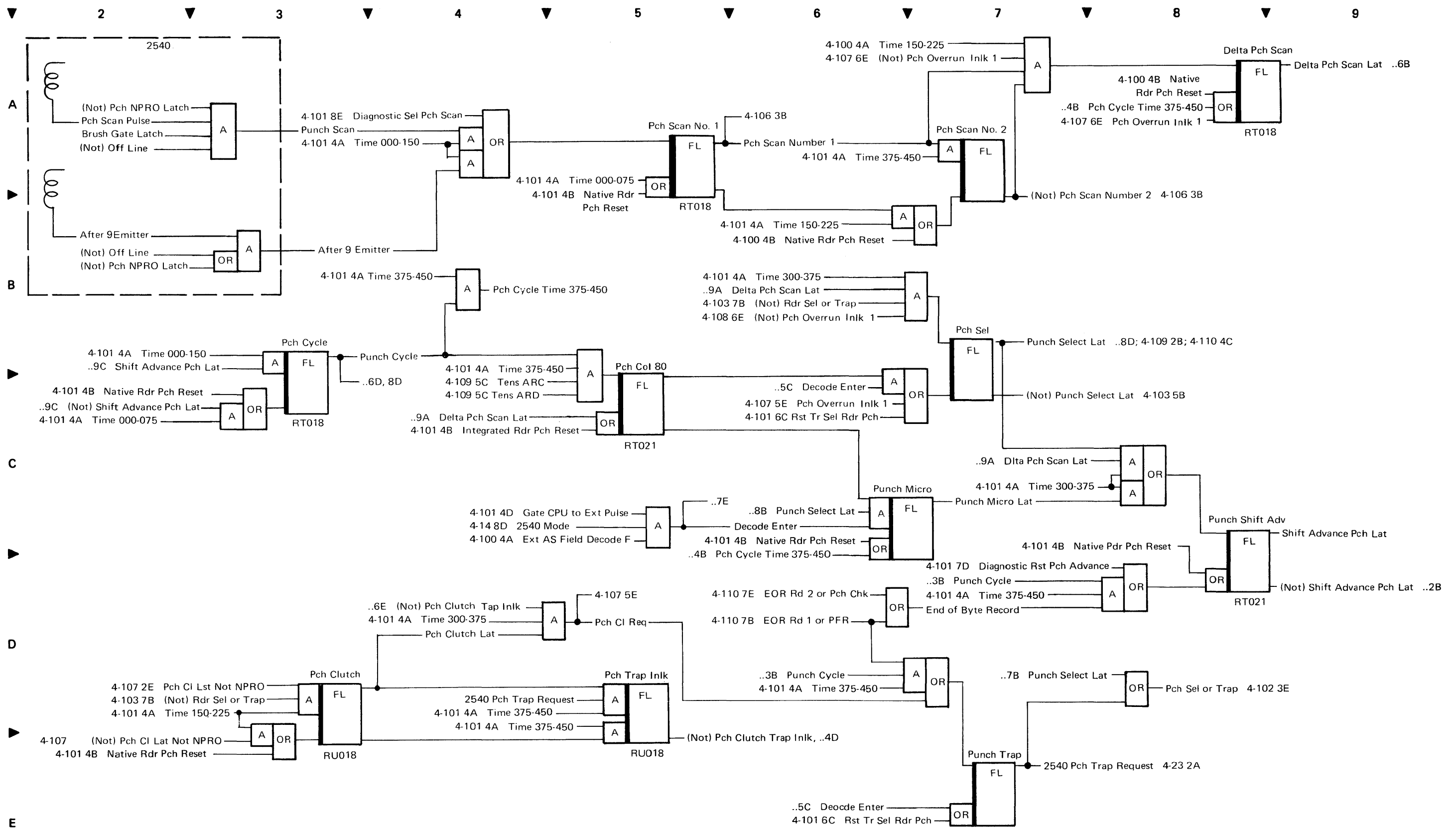
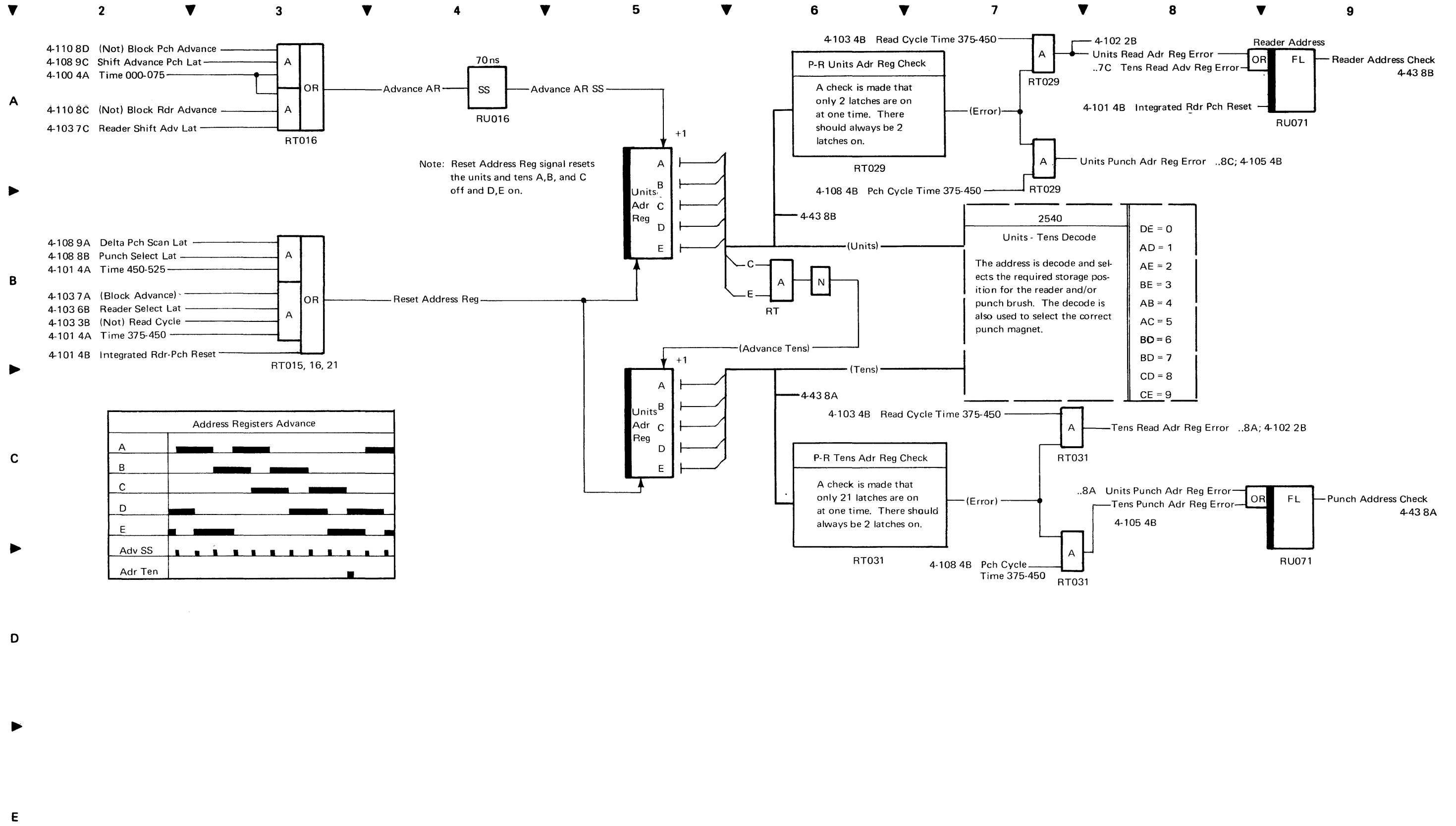


Diagram 4-109. Reader-Punch Unit Ten Address Registers



Address Registers Advance	
A	[Timing diagram showing pulses]
B	[Timing diagram showing pulses]
C	[Timing diagram showing pulses]
D	[Timing diagram showing pulses]
E	[Timing diagram showing pulses]
Adv SS	[Timing diagram showing pulses]
Adr Ten	[Timing diagram showing pulses]

Diagram 4-110. Rd 1-PFR, Rd 2-Pch Chk Shift Registers

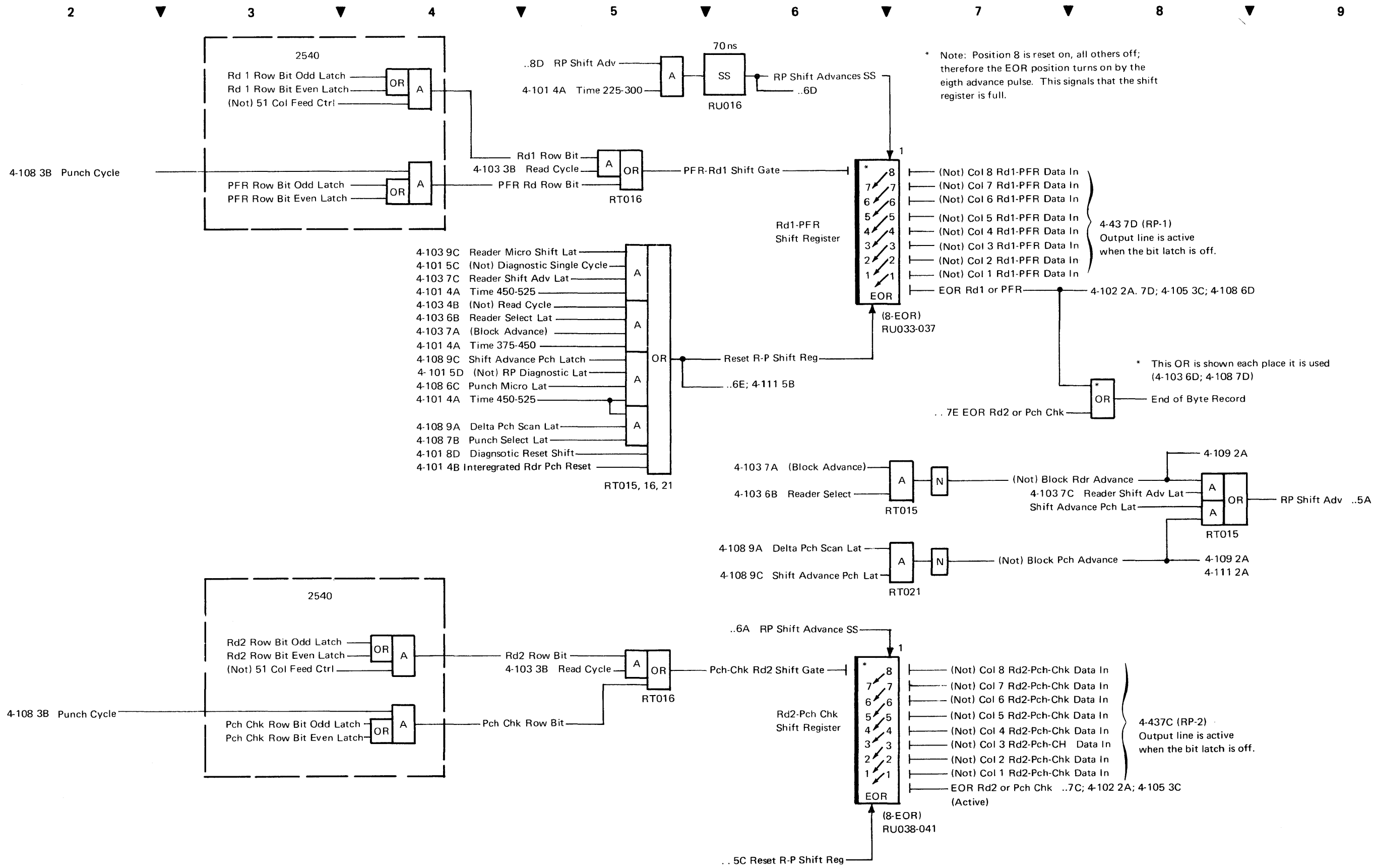


Diagram 4-111. Punch Decode Shift Reg. Rdr-Pch Transfer Timing

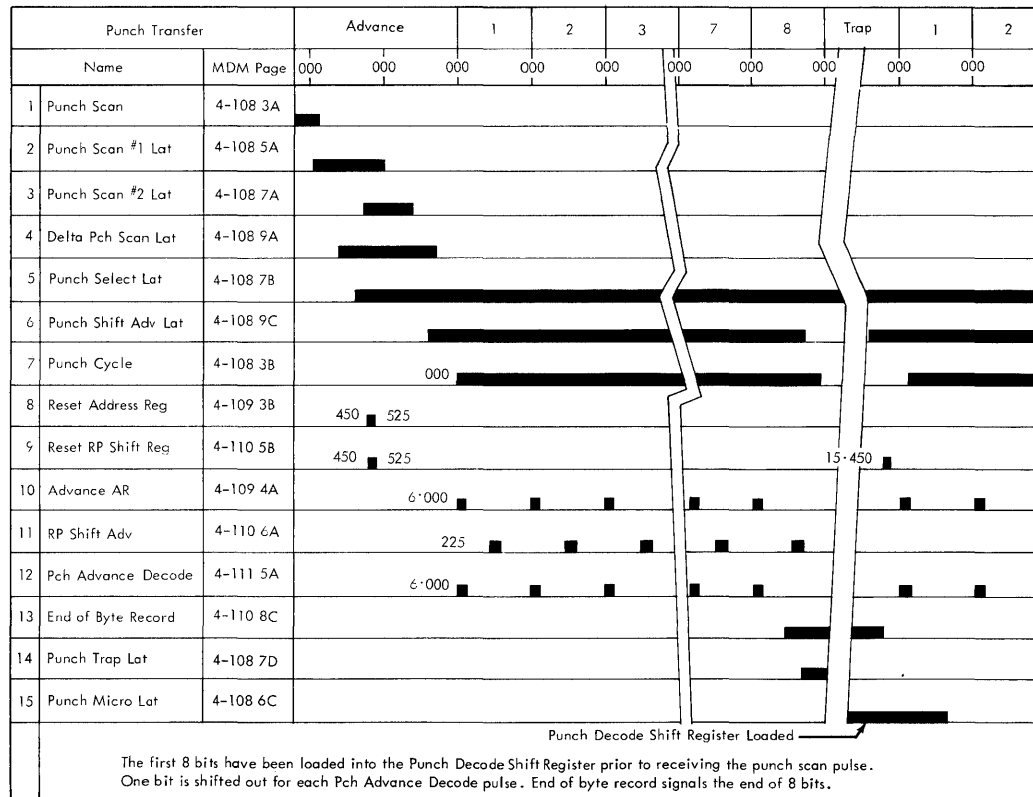
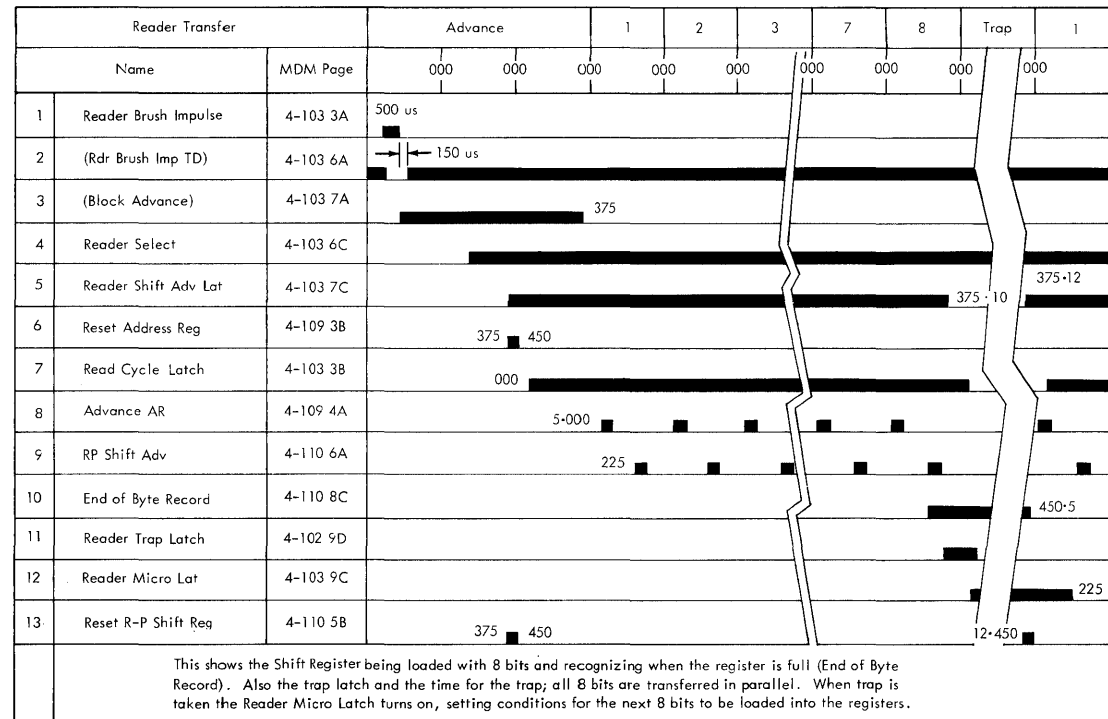
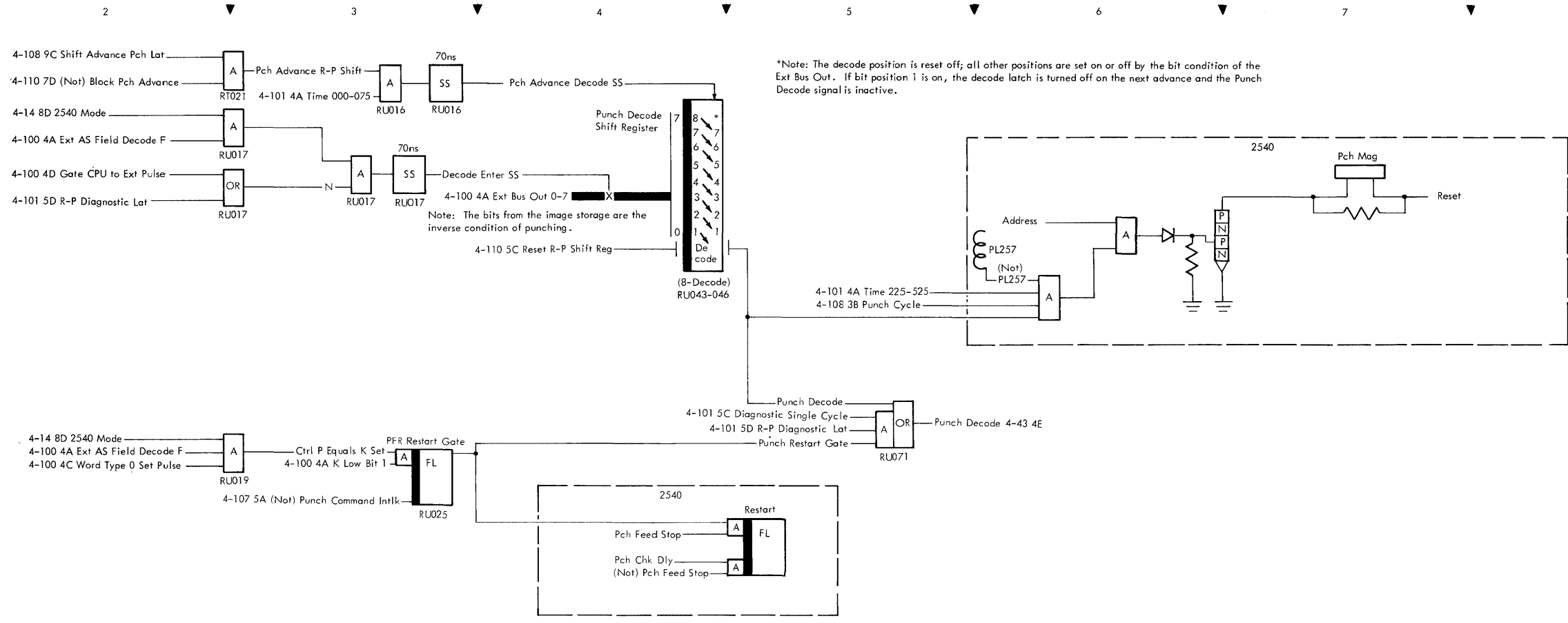


Diagram 4-112. Timing to 2540, 2540 Signal to External Facility

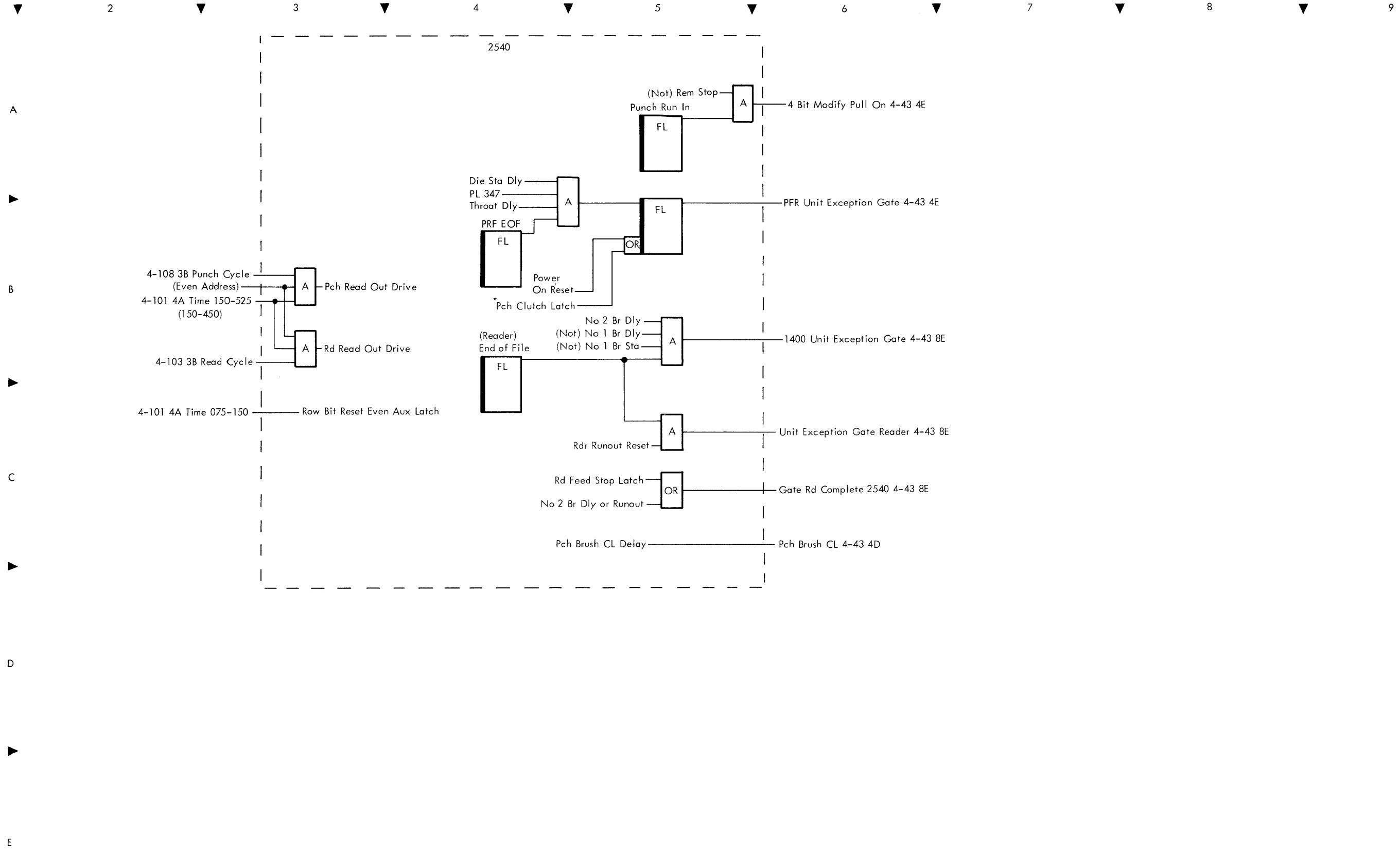
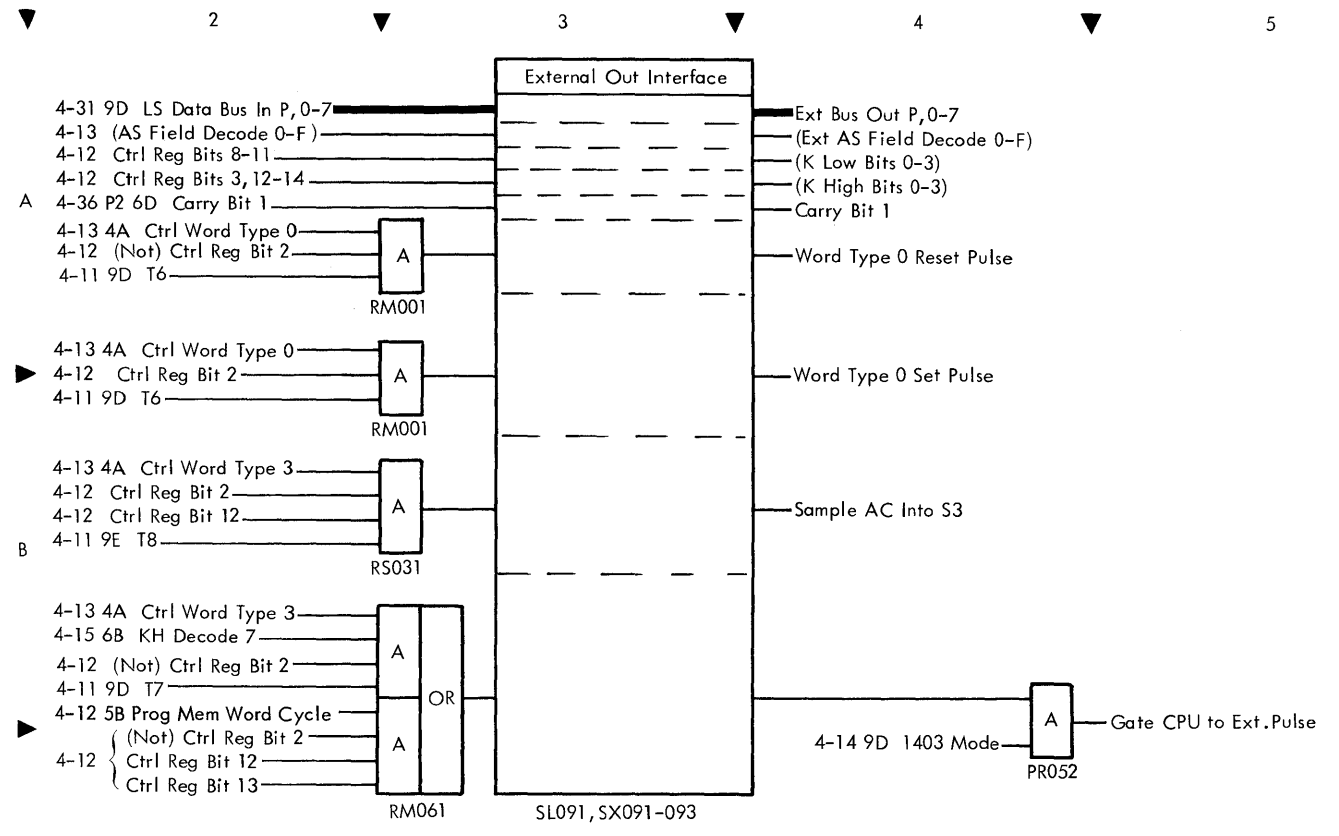
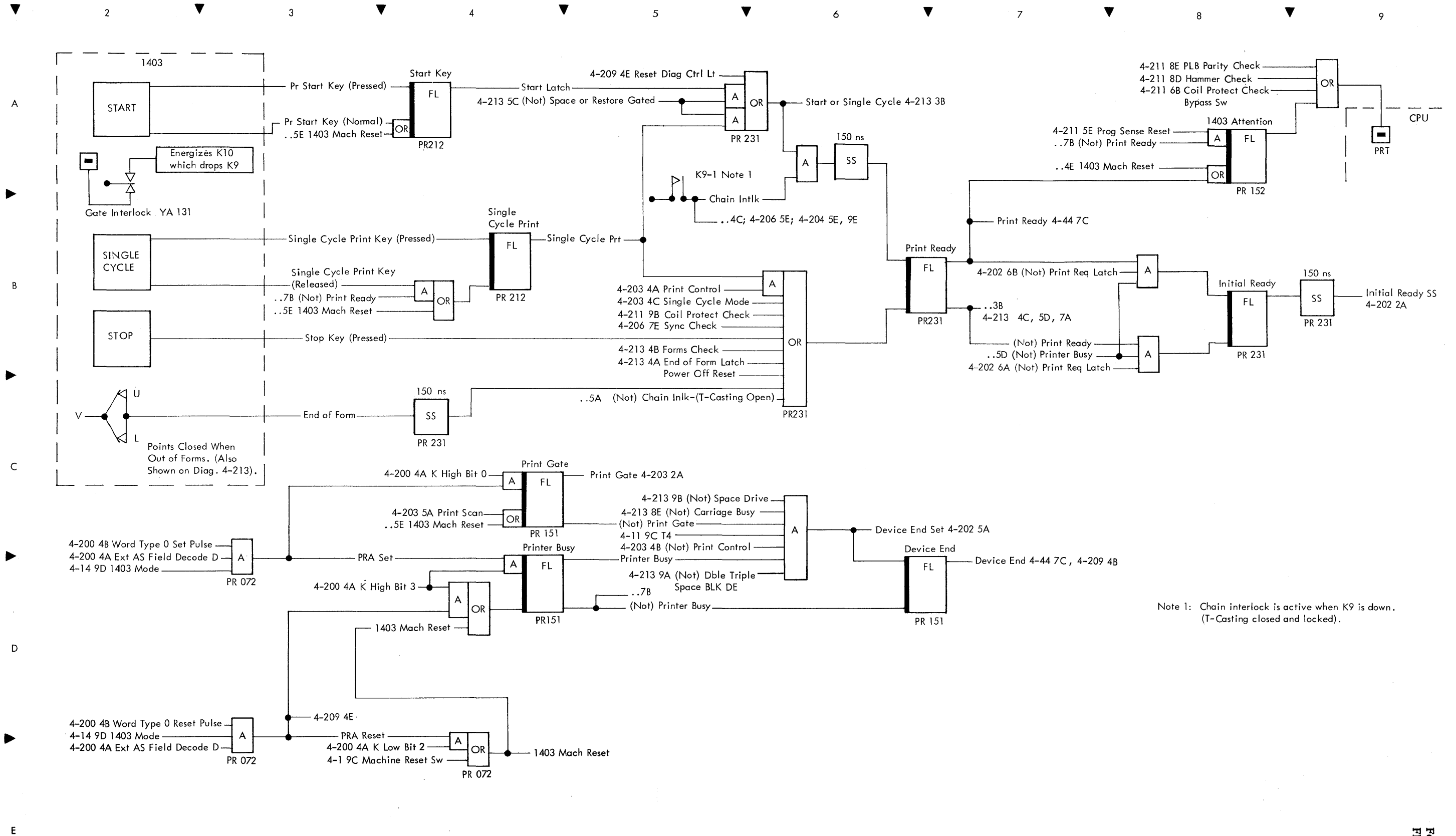


Diagram 4-200. External-Out Interface (Printer)

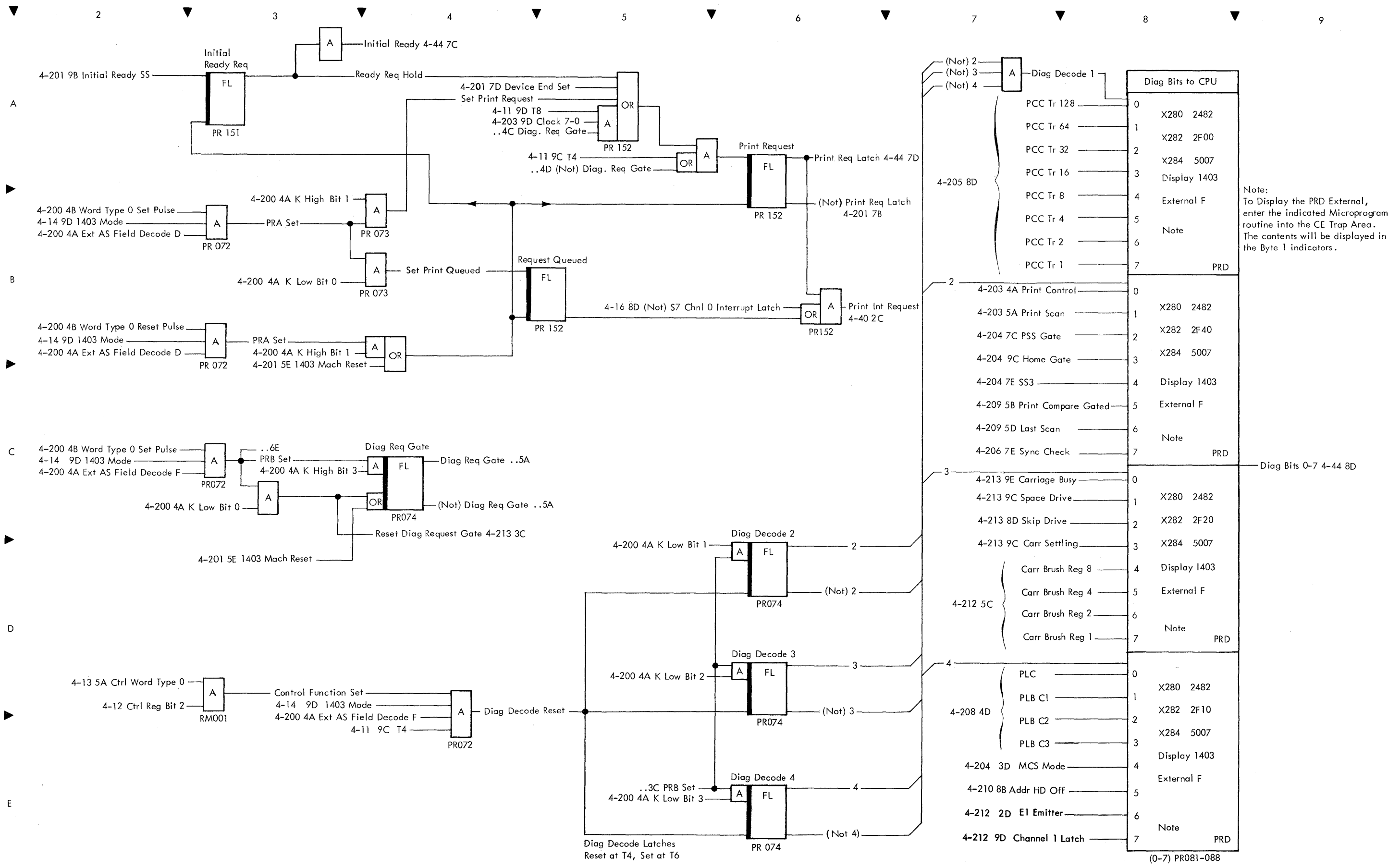


● Diagram 4-201. Printer Control and Status



Note 1: Chain interlock is active when K9 is down. (T-Casting closed and locked).

Diagram 4-202. Printer Controls, Status, and Diagnostic Bits to CPU



Note:
To Display the PRD External,
enter the indicated Microprogram
routine into the CE Trap Area.
The contents will be displayed in
the Byte 1 indicators.

Diag Bits 0-7 4-44 8D

Diag Decode Latches
Reset at T4, Set at T6

(0-7) PR081-088

2 3 4 5 6 7 8 9

* The input is a CE aid. If home gate is jumpered (back panel), the Print Control Latch can only turn on at home gate time. Printing will then always start with the PCC at a value of 01.

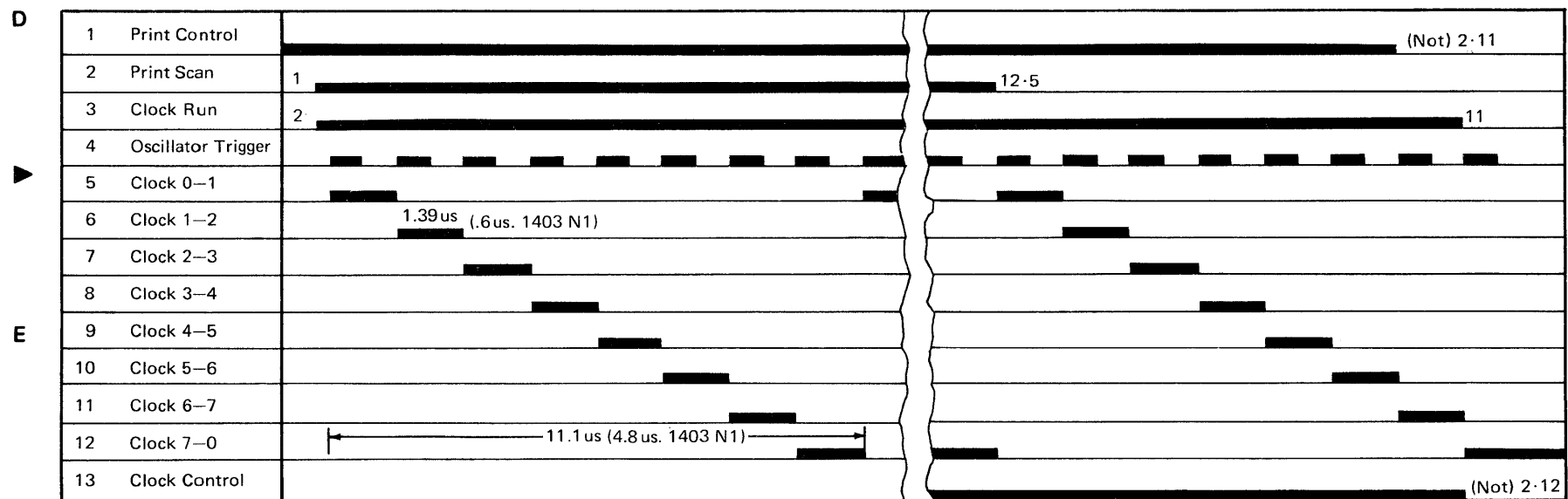
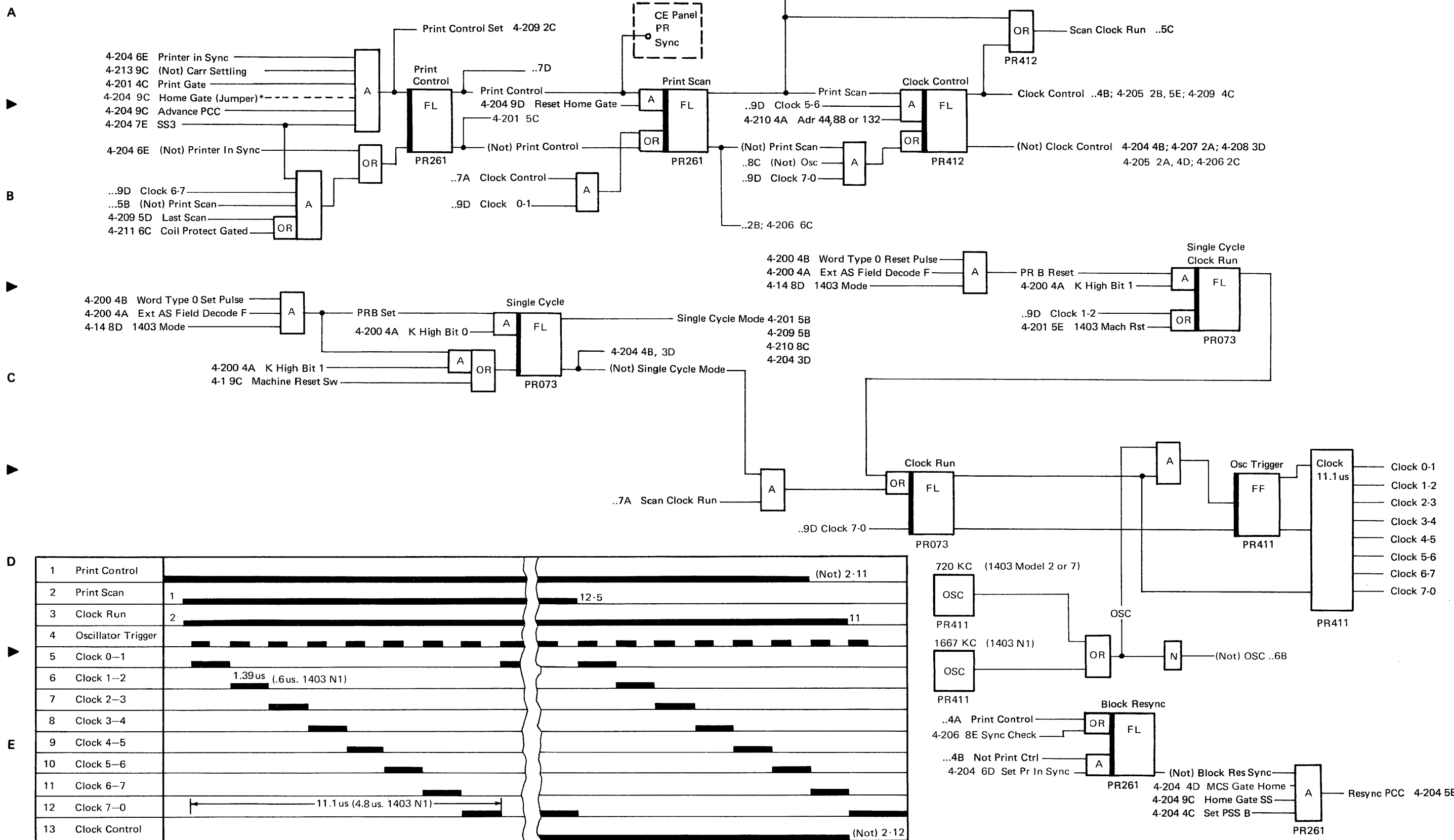
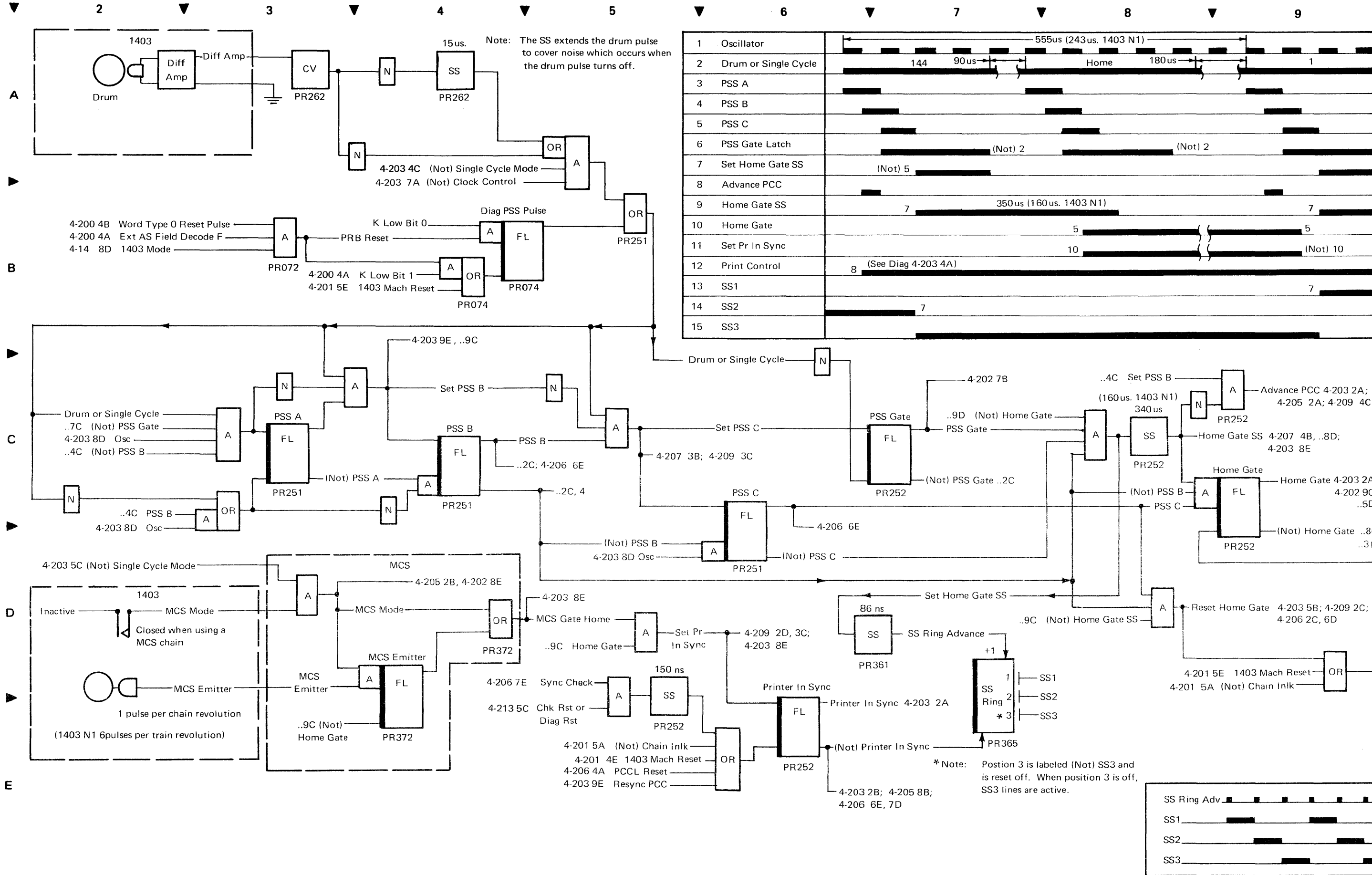


Diagram 4-204. PSS & SS Rings



2 3 4 5 6 7 8 9

A

A

B

A

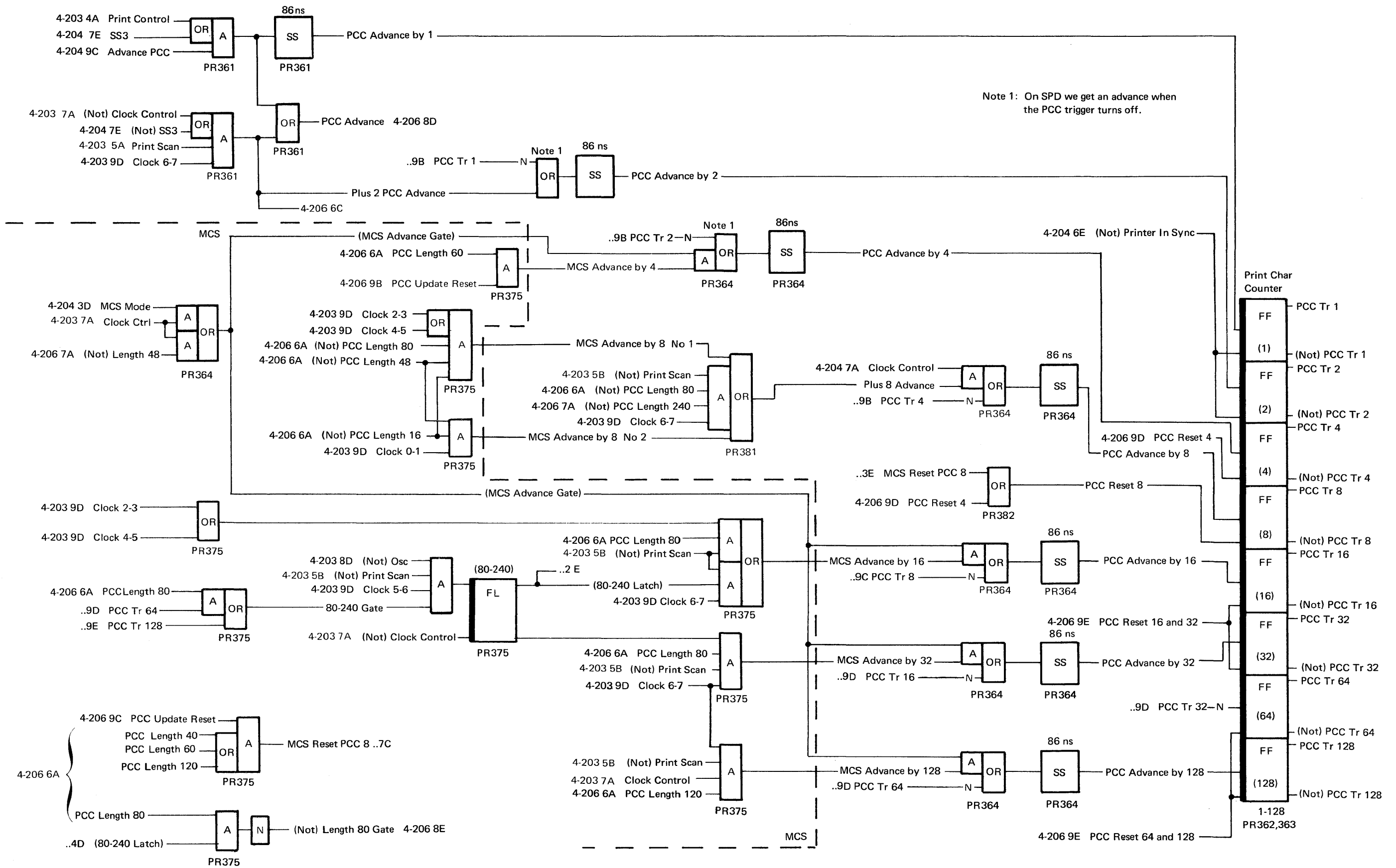
C

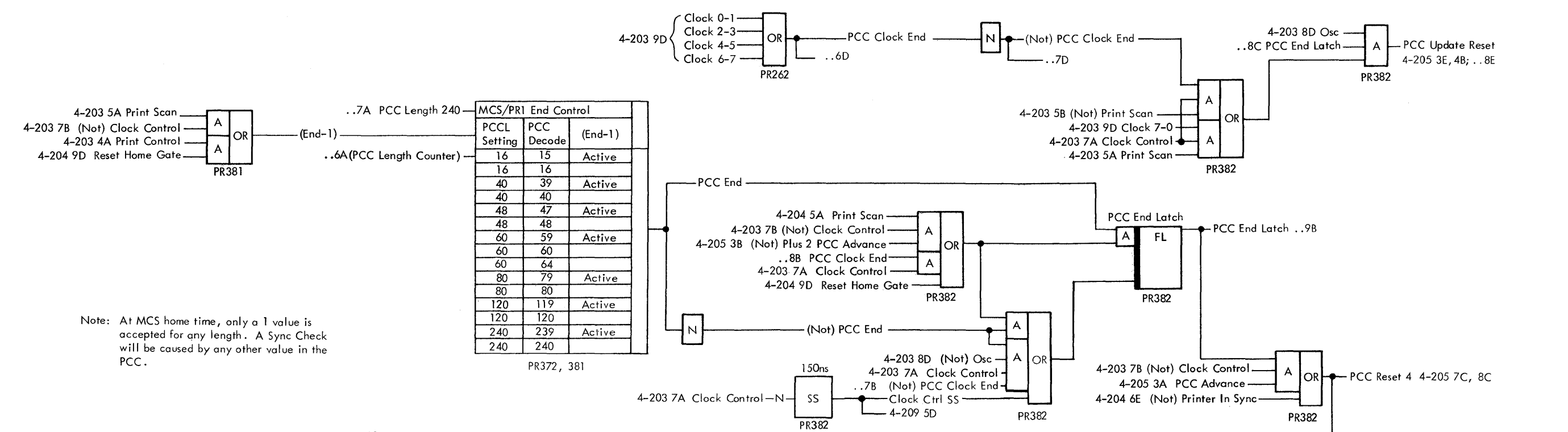
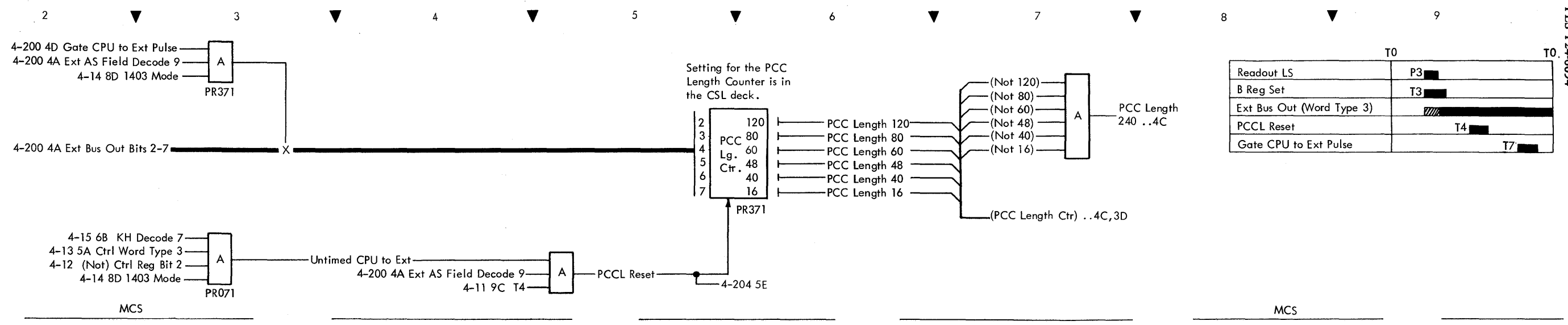
A

D

A

E





Note: At MCS home time, only a 1 value is accepted for any length. A Sync Check will be caused by any other value in the PCC.

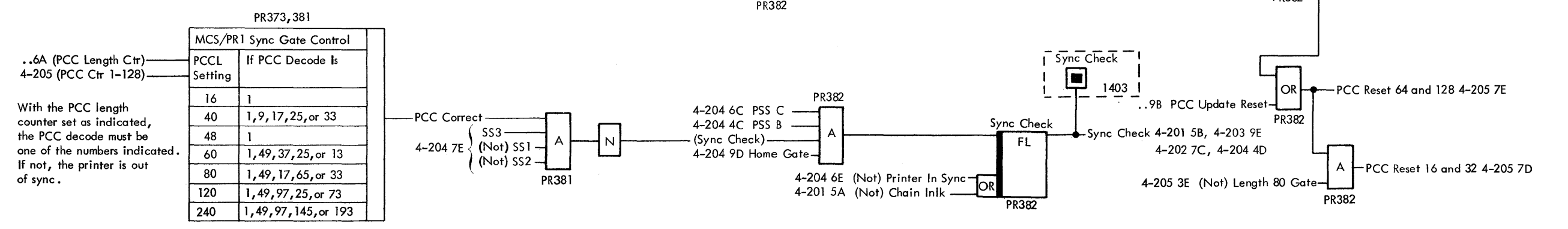
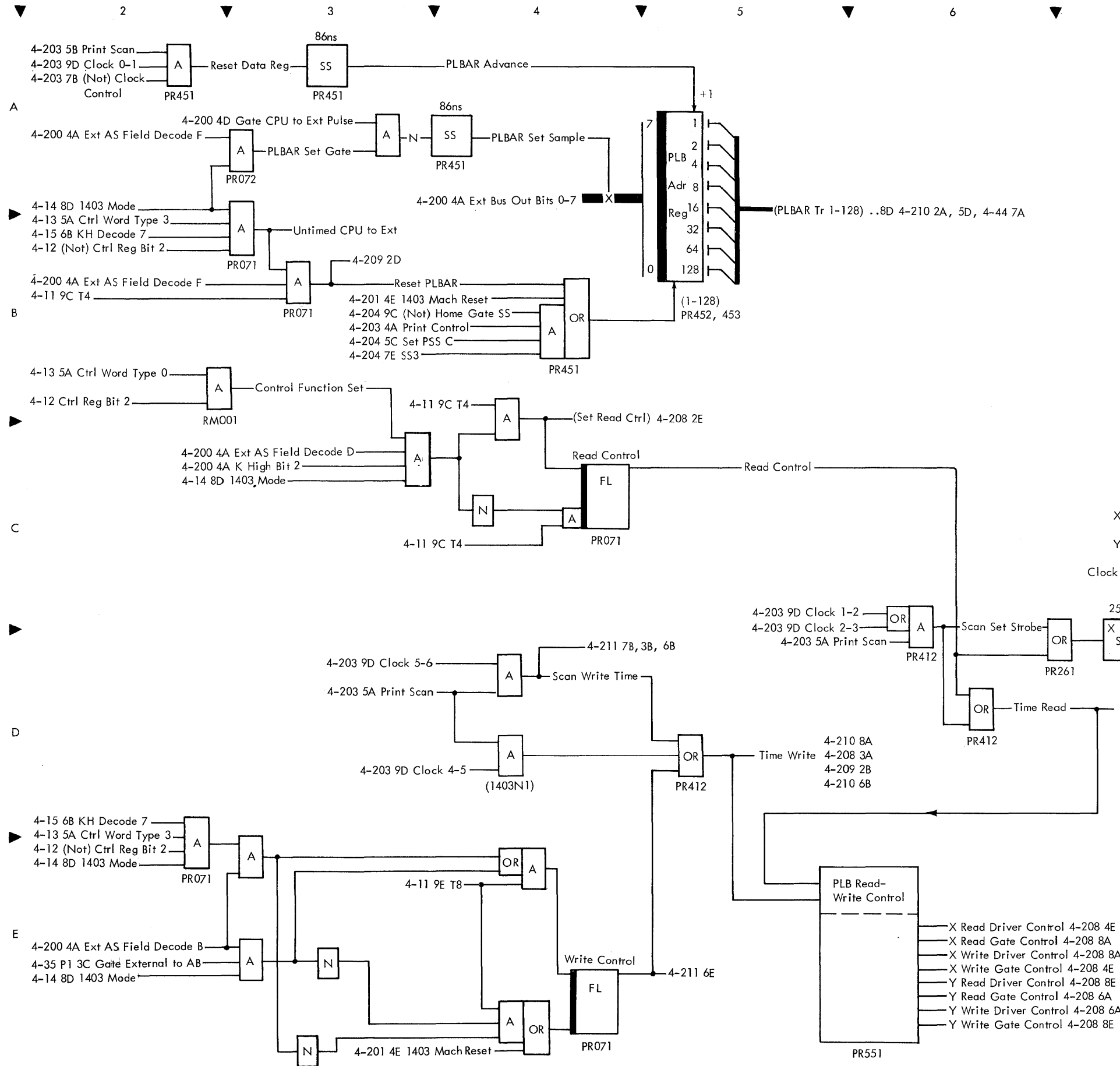
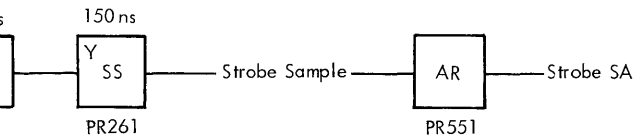
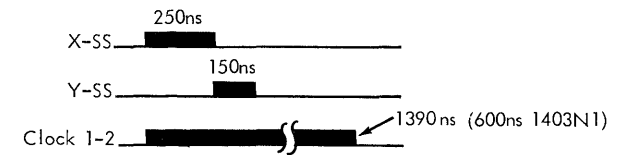


Diagram 4-207. PLBAR, PLB Controls



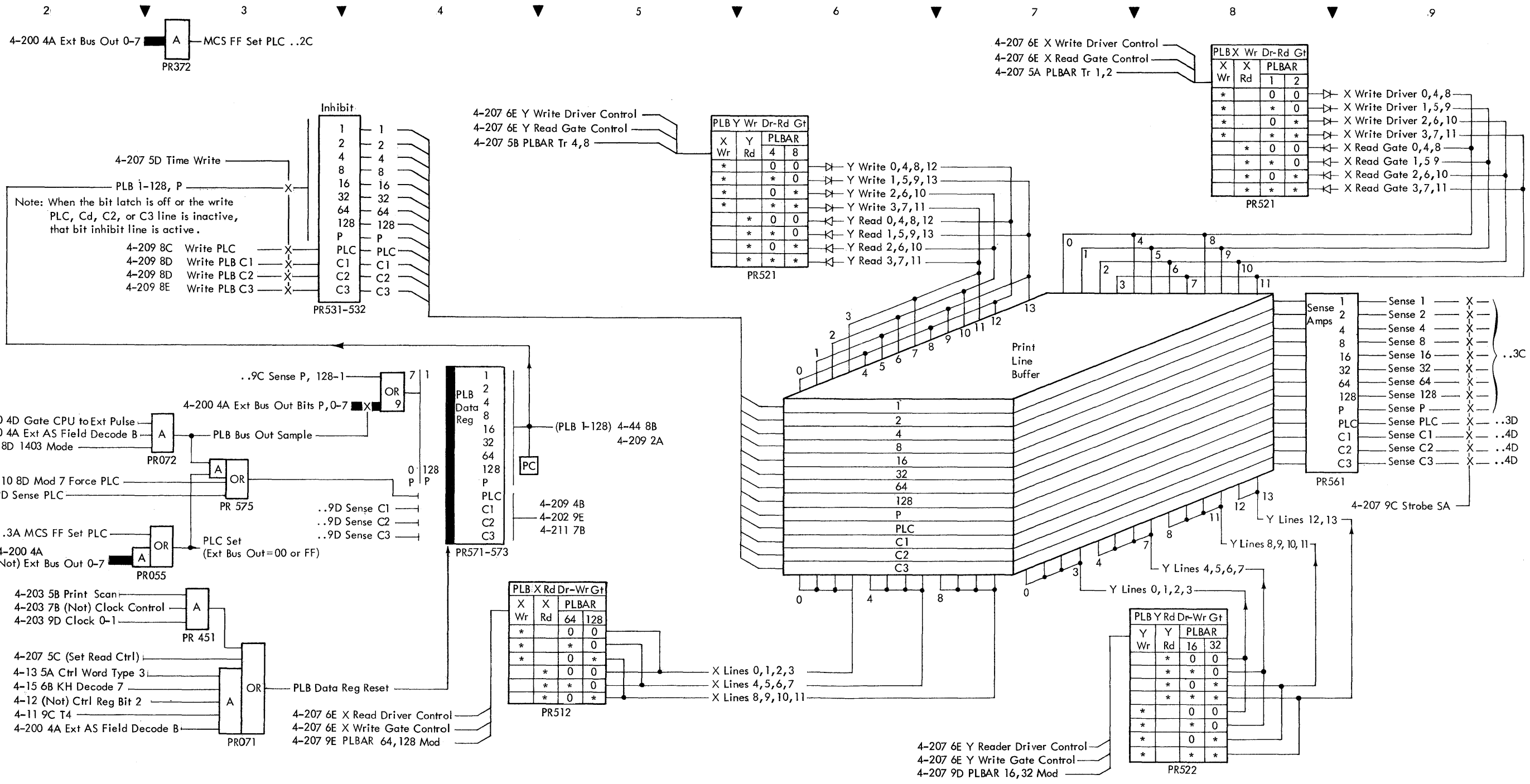
Read Data to CPU/Write Data from CPU																
■=Read or Write ▨=Write Only																
Cycle	Write PLBAR				Set Read Ctrl				Read/Write Data		Dummy					
Time	P	0	2	4	6	8	1	3	5	7	9	0	2	4	6	8
PLBAR Reset		■														
PLBAR Set						■										
Data Reg Reset												▨				
Data Reg Set													▨			
Read Control							■	■	■	■	■					
Write Control																■
Parity Sample																■
		Word Type 3				Word Type 0				Word Type X		Word Type 3		Word Type X		

Note: The PLBAR is set during PLB loading so print line character 1 is in buffer position 1, character 2 in position 45, character 3 in position 89, character 4 in position 2. This allows the PLBAR advance by +1 during printing. PLBAR 1, hammer 1; PLBAR 2, hammer 4; PLBAR 3, hammer 7; etc.



PLBAR Modified					
*must be active 0 must be inactive					
8	16	32	64	128	
0	*				PLBAR 16 Mod 4-208 8E
	*	0			
		*			PLBAR 32 Mod 4-208 8E
0		*			
			*		PLBAR 64 Mod 4-208 5E
0			*		
				*	PLBAR 128 Mod 4-208 5E
*	*	*		*	

PR456



2 3 4 5 6 7 8 9

4-200 4A Ext Bus Out 0-7 **A** PR372 MCS FF Set PLC ..2C

Inhibit

1 2 4 8 16 32 64 128 P PLC C1 C2 C3

4-207 5D Time Write

PLB i-128, P

Note: When the bit latch is off or the write PLC, Cd, C2, or C3 line is inactive, that bit inhibit line is active.

4-209 8C Write PLC
4-209 8D Write PLB C1
4-209 8D Write PLB C2
4-209 8E Write PLB C3

PR531-532

4-207 6E Y Write Driver Control
4-207 6E Y Read Gate Control
4-207 5B PLBAR Tr 4,8

PLB Y Wr Dr-Rd Gt		PLBAR		
X Wr	Y Rd	4	8	
*	0	0	0	Y Write 0,4,8,12
*	*	0	0	Y Write 1,5,9,13
*	0	*	*	Y Write 2,6,10
*	*	*	*	Y Write 3,7,11
*	0	0	0	Y Read 0,4,8,12
*	*	0	0	Y Read 1,5,9,13
*	0	*	*	Y Read 2,6,10
*	*	*	*	Y Read 3,7,11

PR521

4-207 6E X Write Driver Control
4-207 6E X Read Gate Control
4-207 5A PLBAR Tr 1,2

PLB X Wr Dr-Rd Gt		PLBAR		
X Wr	X Rd	1	2	
*	0	0	0	X Write Driver 0,4,8
*	*	0	0	X Write Driver 1,5,9
*	0	*	*	X Write Driver 2,6,10
*	*	*	*	X Write Driver 3,7,11
*	0	0	0	X Read Gate 0,4,8
*	*	0	0	X Read Gate 1,5,9
*	0	*	*	X Read Gate 2,6,10
*	*	*	*	X Read Gate 3,7,11

PR521

..9C Sense P, 128-1

4-200 4A Ext Bus Out Bits P, 0-7 **X**

4-200 4D Gate CPU to Ext Pulse
4-200 4A Ext AS Field Decode B
4-14 8D 1403 Mode

PR072

PLB Bus Out Sample

4-210 8D Mod 7 Force PLC
..9D Sense PLC

PR 575

..9D Sense C1
..9D Sense C2
..9D Sense C3

..3A MCS FF Set PLC
4-200 4A (Not) Ext Bus Out 0-7

PR055

PLC Set (Ext Bus Out=00 or FF)

PLB Data Reg

1 2 4 8 16 32 64 128 P PLC C1 C2 C3

PC

(PLB i-128) 4-44 8B
4-209 2A

4-209 4B
4-202 9E
4-211 7B

PR571-573

PLB X Rd Dr-Wr Gt		PLBAR		
X Wr	X Rd	64	128	
*	0	0	0	X Lines 0,1,2,3
*	*	0	0	X Lines 4,5,6,7
*	0	*	*	X Lines 8,9,10,11
*	*	0	0	
*	0	*	*	
*	*	0	0	

PR512

PLB Y Rd Dr-Wr Gt		PLBAR		
Y Wr	Y Rd	16	32	
*	0	0	0	Y Lines 0,1,2,3
*	*	0	0	Y Lines 4,5,6,7
*	0	*	*	Y Lines 8,9,10,11
*	*	0	0	Y Lines 12,13
*	0	*	*	
*	*	0	0	

PR522

4-203 5B Print Scan
4-203 7B (Not) Clock Control
4-203 9D Clock 0-1

PR 451

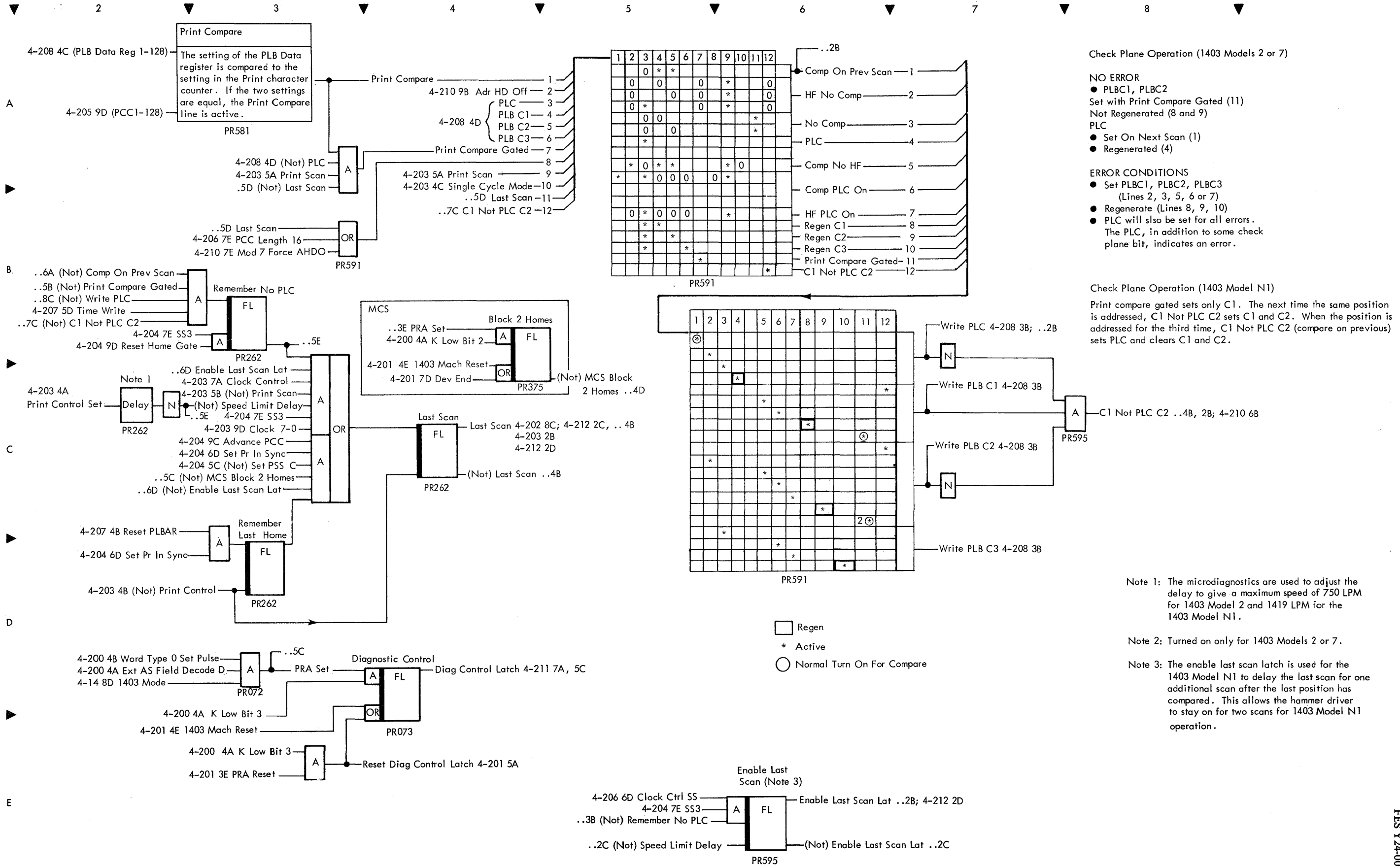
4-207 5C (Set Read Ctrl)
4-13 5A Ctrl Word Type 3
4-15 6B KH Decode 7
4-12 (Not) Ctrl Reg Bit 2
4-11 9C T4
4-200 4A Ext AS Field Decode B

PR071

PLB Data Reg Reset

4-207 6E X Read Driver Control
4-207 6E X Write Gate Control
4-207 9E PLBAR 64,128 Mod

Diagram 4-208. PLB Data Register and Print Line Buffer



Check Plane Operation (1403 Models 2 or 7)

NO ERROR

- PLBC1, PLBC2
- Set with Print Compare Gated (11)
- Not Regenerated (8 and 9)

PLC

- Set On Next Scan (1)
- Regenerated (4)

ERROR CONDITIONS

- Set PLBC1, PLBC2, PLBC3 (Lines 2, 3, 5, 6 or 7)
- Regenerate (Lines 8, 9, 10)
- PLC will also be set for all errors. The PLC, in addition to some check plane bit, indicates an error.

Check Plane Operation (1403 Model N1)

Print compare gated sets only C1. The next time the same position is addressed, C1 Not PLC C2 sets C1 and C2. When the position is addressed for the third time, C1 Not PLC C2 (compare on previous) sets PLC and clears C1 and C2.

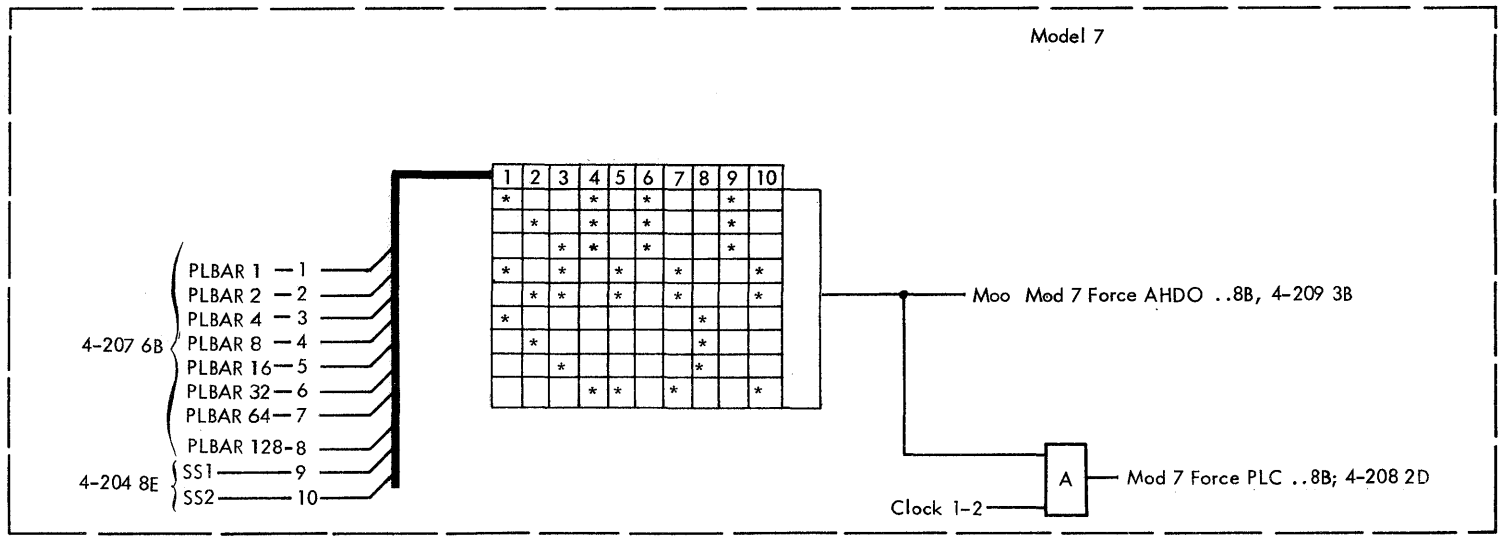
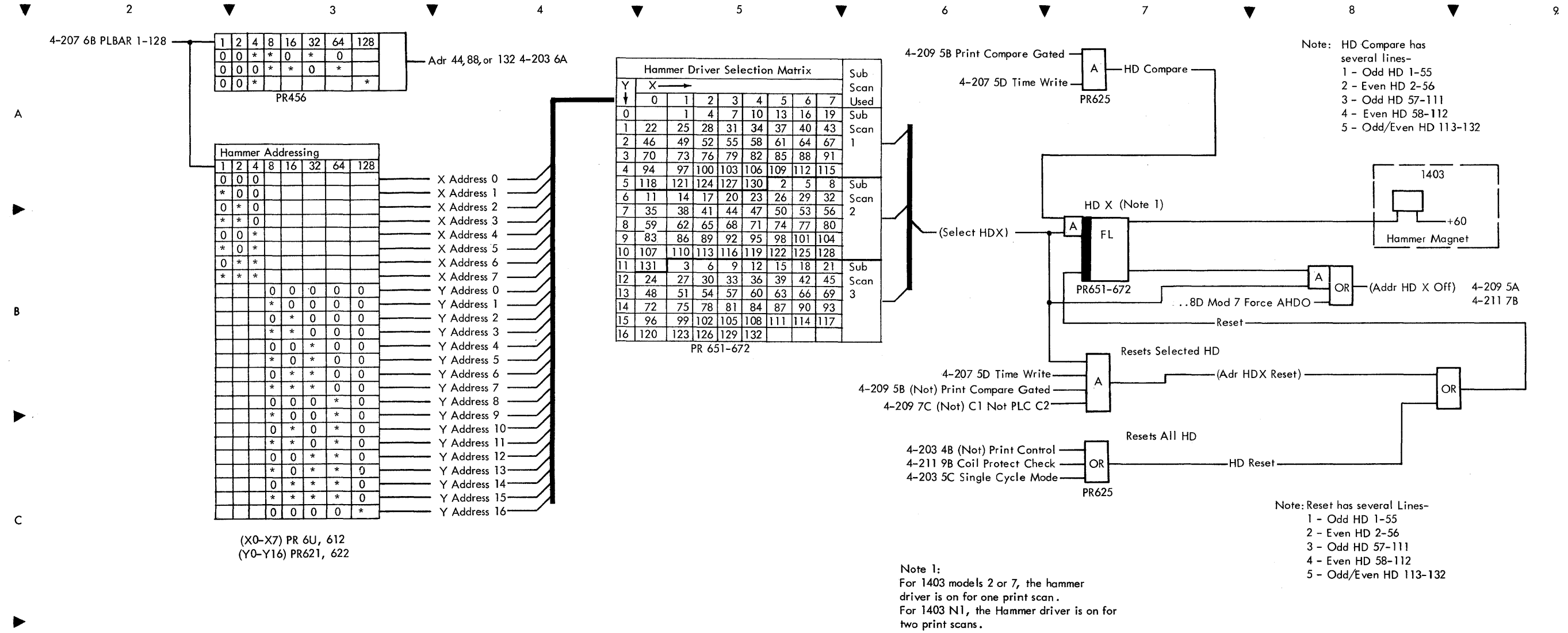
Note 1: The microdiagnostics are used to adjust the delay to give a maximum speed of 750 LPM for 1403 Model 2 and 1419 LPM for the 1403 Model N1.

Note 2: Turned on only for 1403 Models 2 or 7.

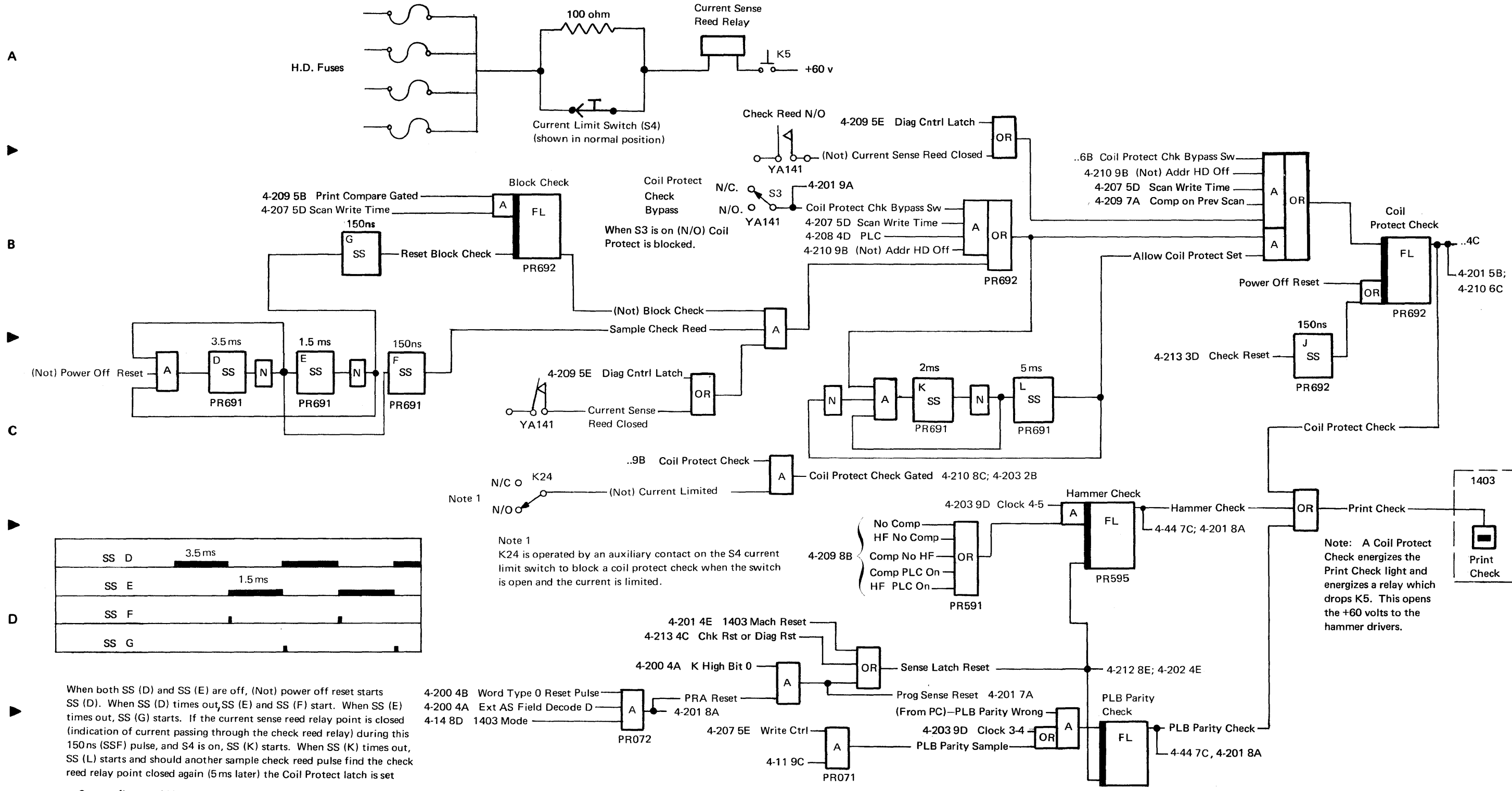
Note 3: The enable last scan latch is used for the 1403 Model N1 to delay the last scan for one additional scan after the last position has compared. This allows the hammer driver to stay on for two scans for 1403 Model N1 operation.

□ Regen
* Active
○ Normal Turn On For Compare

Diagram 4-210. Hammer Driver Matrix



2 3 4 5 6 7 8 9



When both SS (D) and SS (E) are off, (Not) power off reset starts SS (D). When SS (D) times out, SS (E) and SS (F) start. When SS (E) times out, SS (G) starts. If the current sense reed relay point is closed (indication of current passing through the check reed relay) during this 150 ns (SSF) pulse, and S4 is on, SS (K) starts. When SS (K) times out, SS (L) starts and should another sample check reed pulse find the check reed relay point closed again (5 ms later) the Coil Protect latch is set

Current flow could be due to turning a HD on due to print compare. If this is the case, the block check latch is set preventing the check. The block check latch is reset after every sample.

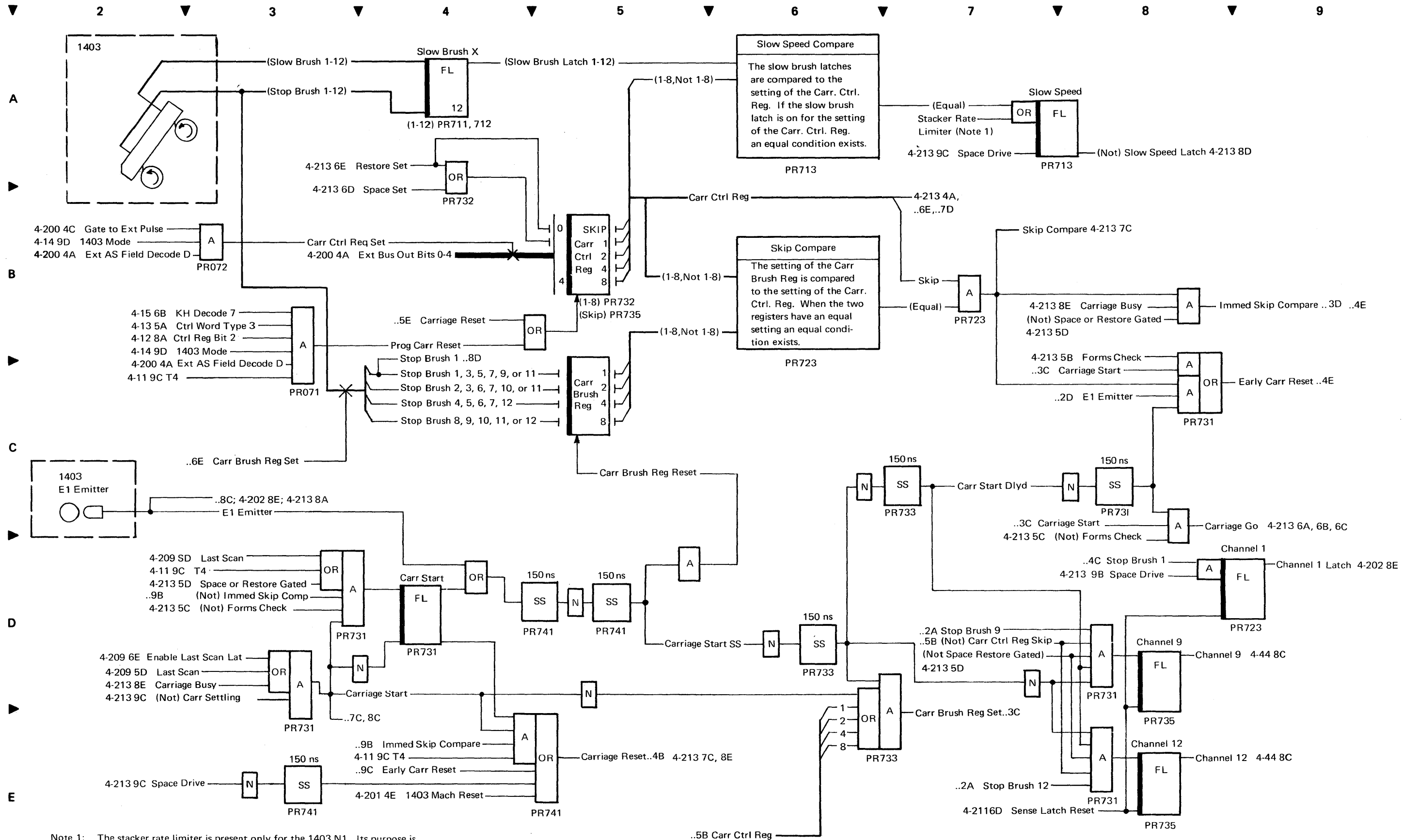
Coil protect is also set when an individual HD cannot be reset during print scans. This error can be bypassed with S3 (6B).

4-200 4B Word Type 0 Reset Pulse
 4-200 4A Ext AS Field Decode D
 4-14 8D 1403 Mode

Note 1
 With current limited coil protect checks can occur while in a print operation, but hammers do not fire and print ready is not dropped. The +60 volt line is limited by a 100 ohm resistor. This allows checking for the failing position while printing.

Note: A Coil Protect Check energizes the Print Check light and energizes a relay which drops K5. This opens the +60 volts to the hammer drivers.

Diagram 4-212. Carriage Compare and Channel Latches 1, 9, and 12



Note 1: The stacker rate limiter is present only for the 1403 N1. Its purpose is to determine that the carriage has been in high speed for such a length of time that 8 inches of paper has accumulated ahead of the stacker drive. The slow speed latch is set and the remainder of the skip is done in slow speed allowing the accumulated paper to be stacked.

Diagram 4-213. Carriage Drive and Checks

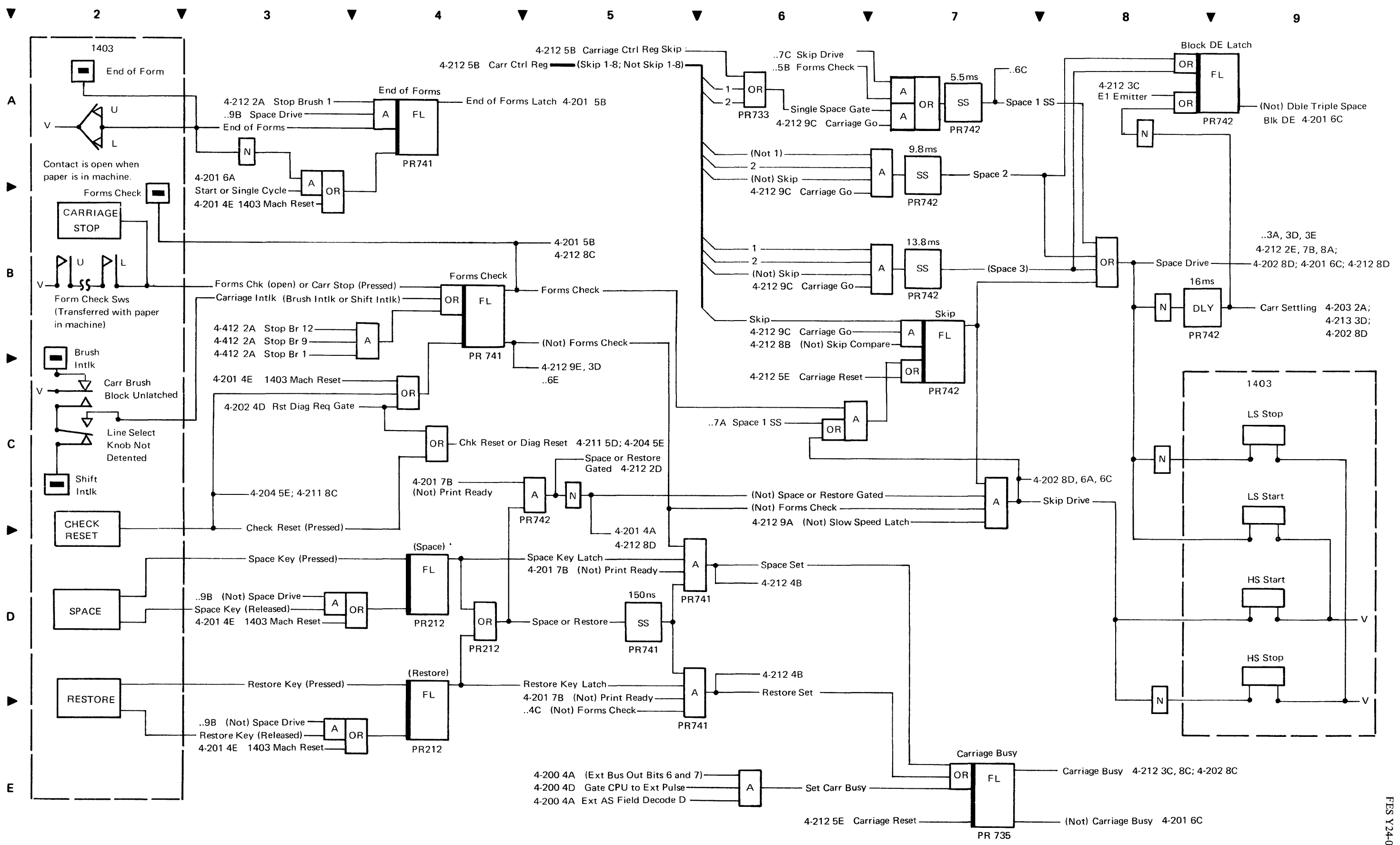


Diagram 4-301. Read and Write Data/Clock Pulse Controls

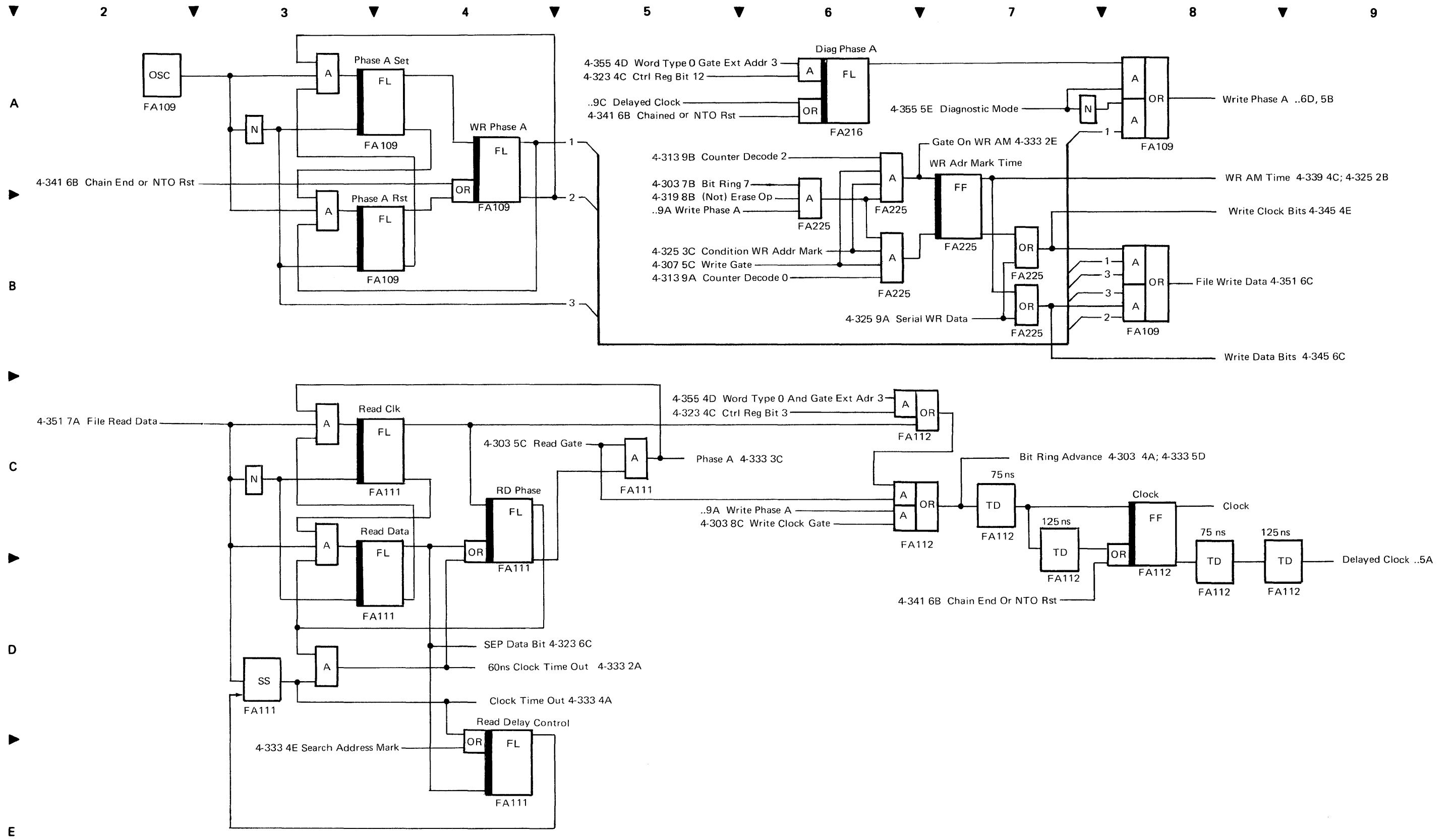


Diagram 4-303. Bit Ring and Read/Write Clock Gate Controls

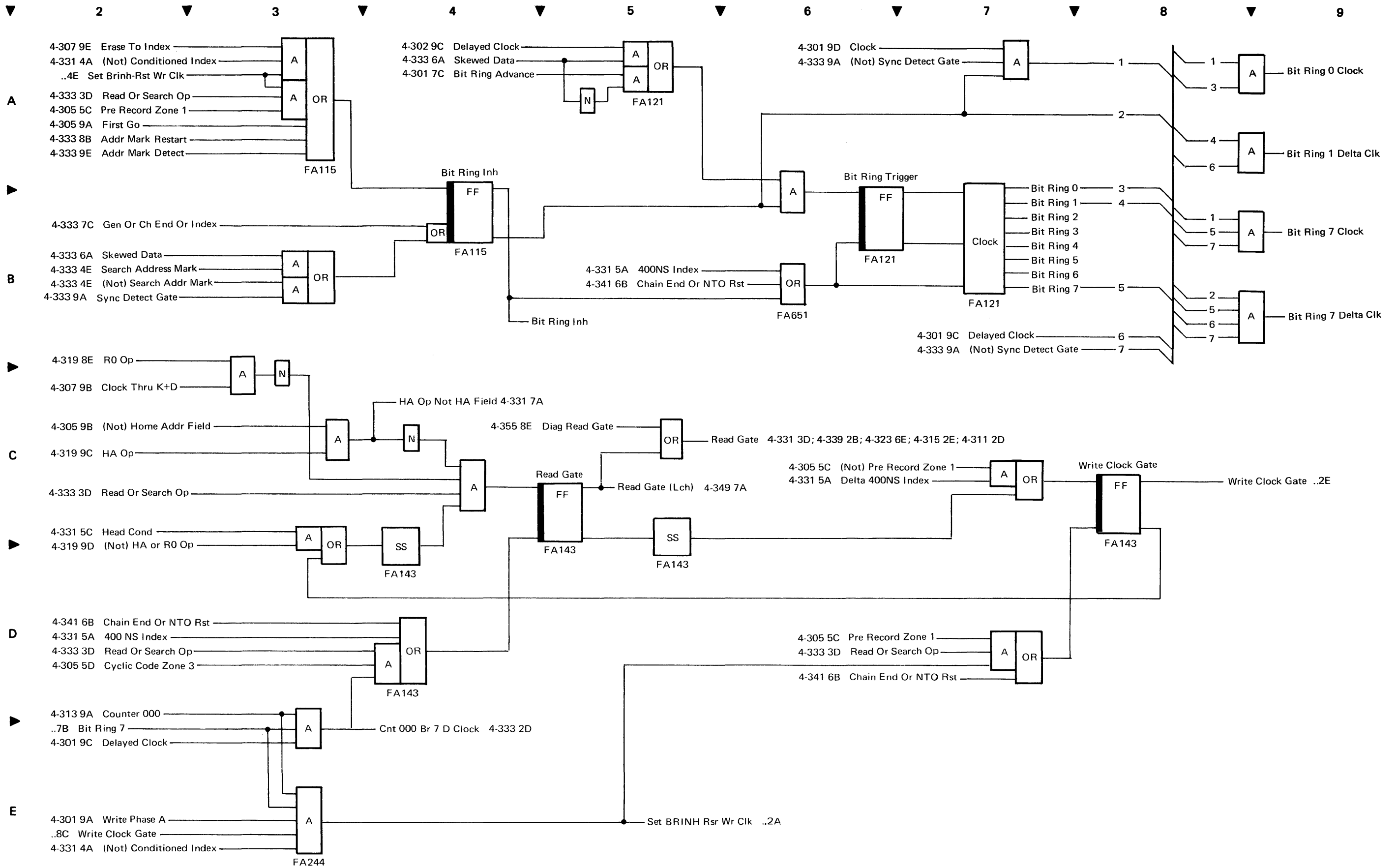
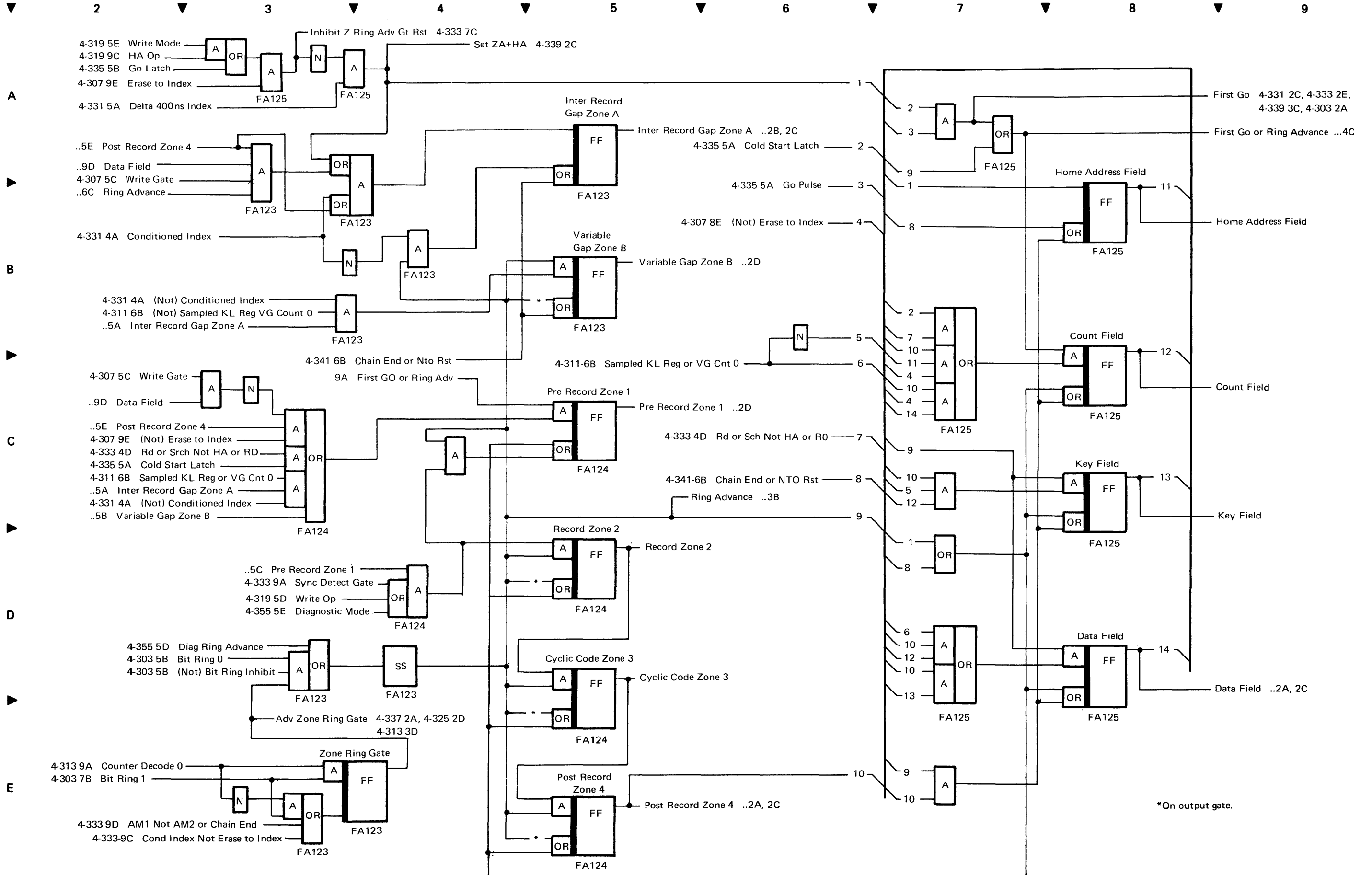


Diagram 4-305. Field and Zone Rings



*On output gate.

Diagram 4-307. Write/Erase Gates and Clock Thru

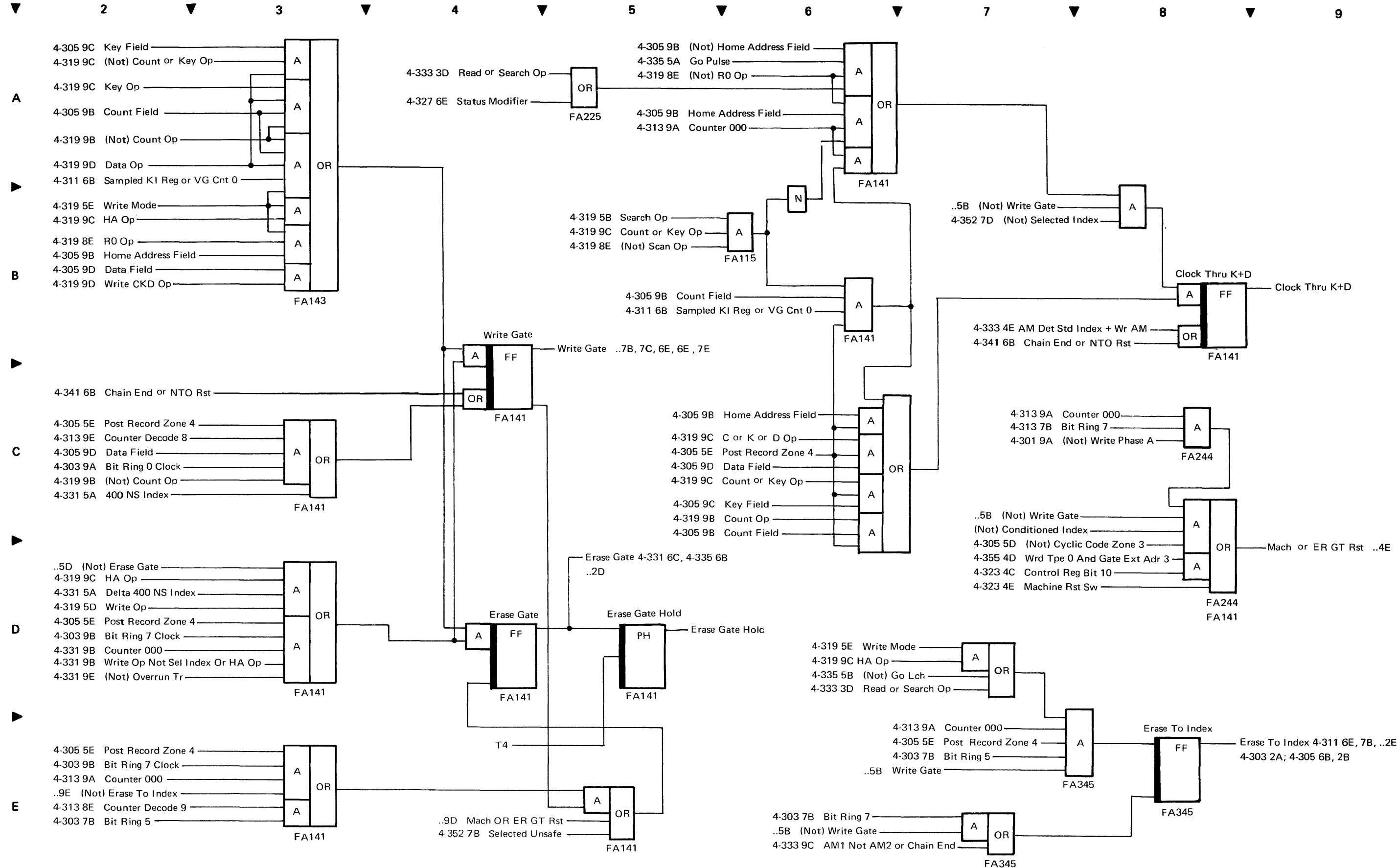


Diagram 4-311. Field Length Registers and Gap Controls

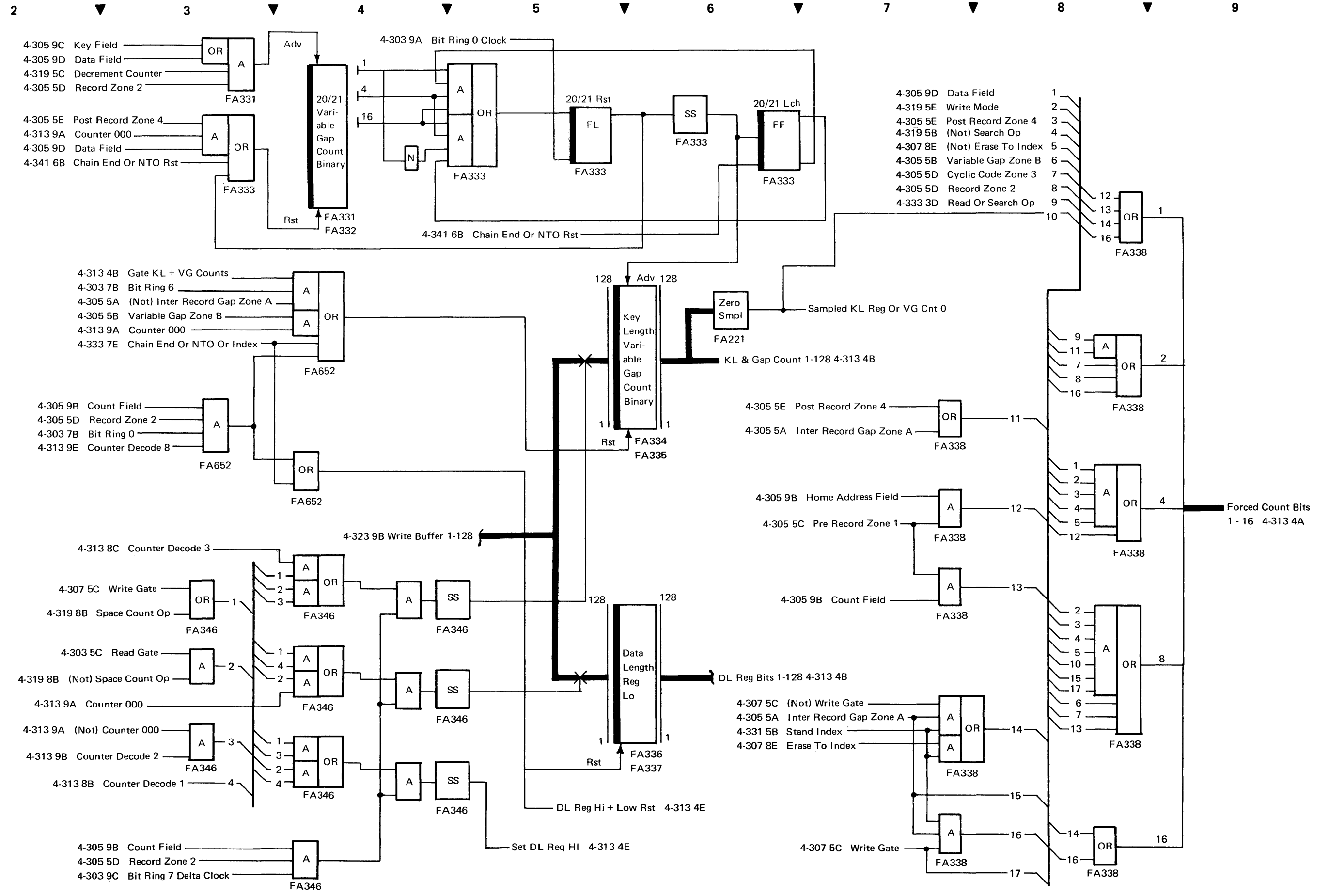
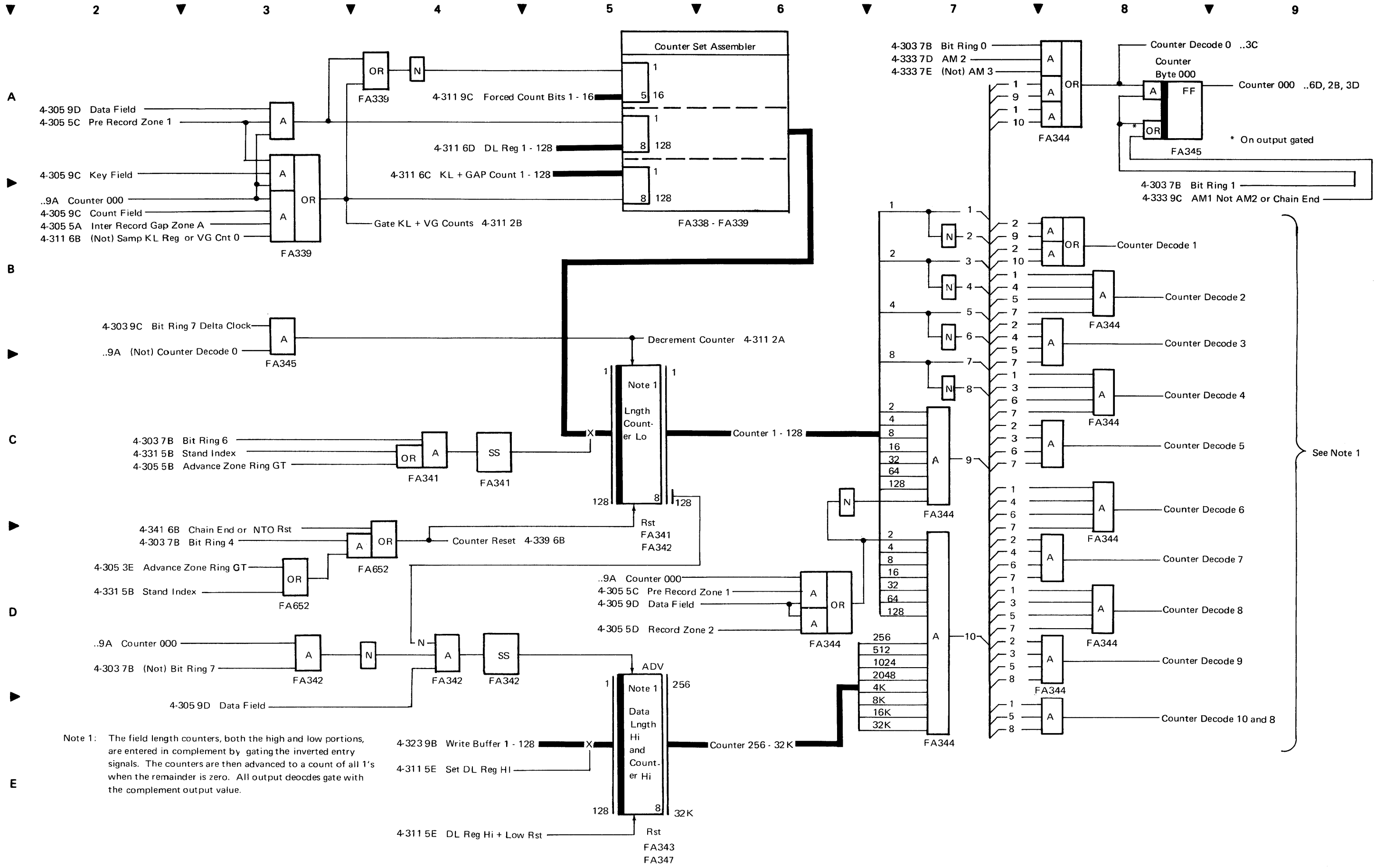


Diagram 4-313. Field Length Counters and Controls



Note 1: The field length counters, both the high and low portions, are entered in complement by gating the inverted entry signals. The counters are then advanced to a count of all 1's when the remainder is zero. All output decodes gate with the complement output value.

See Note 1

Diagram 4-315. Record Length Controls

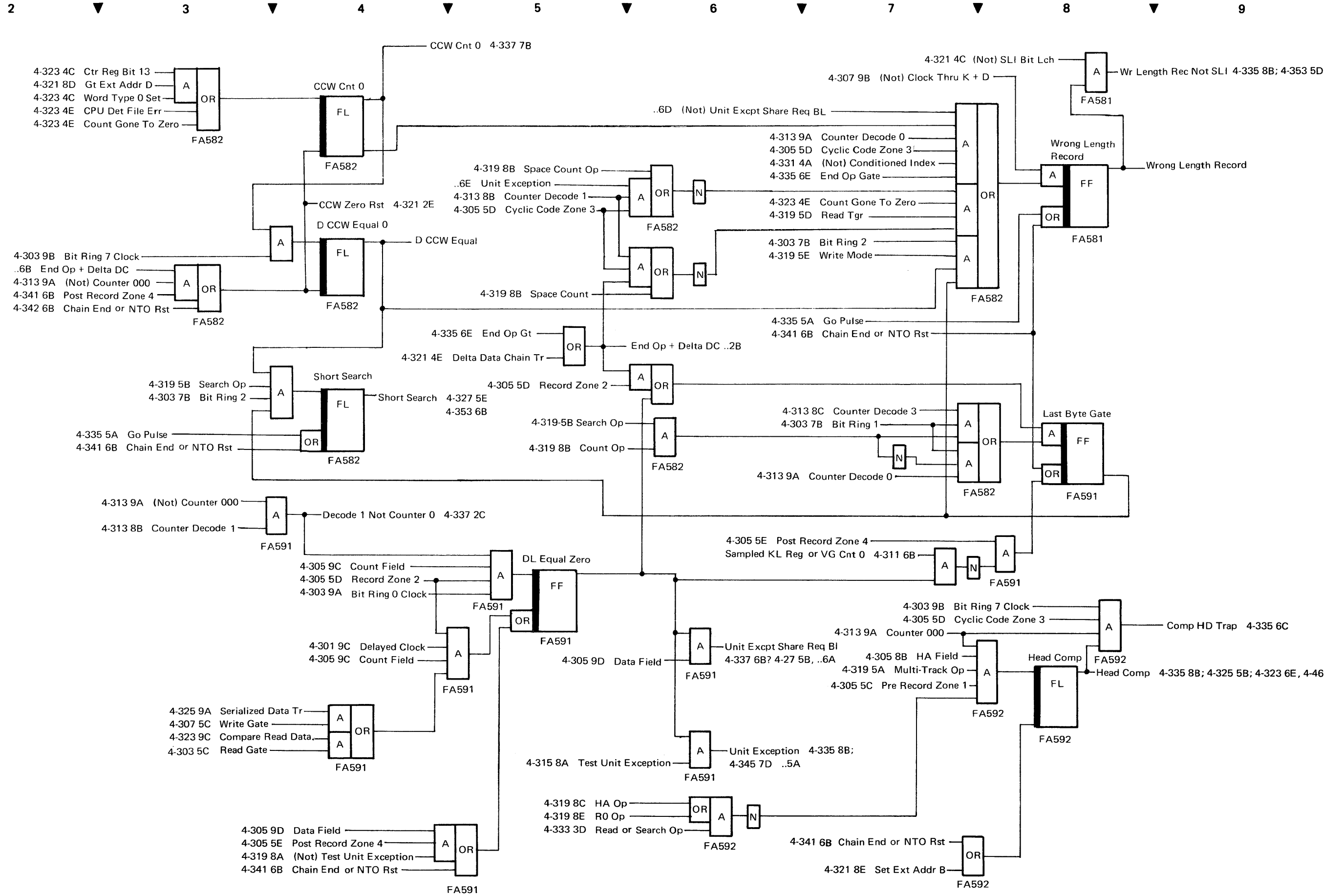


Diagram 4-319. OP Register and Decodes

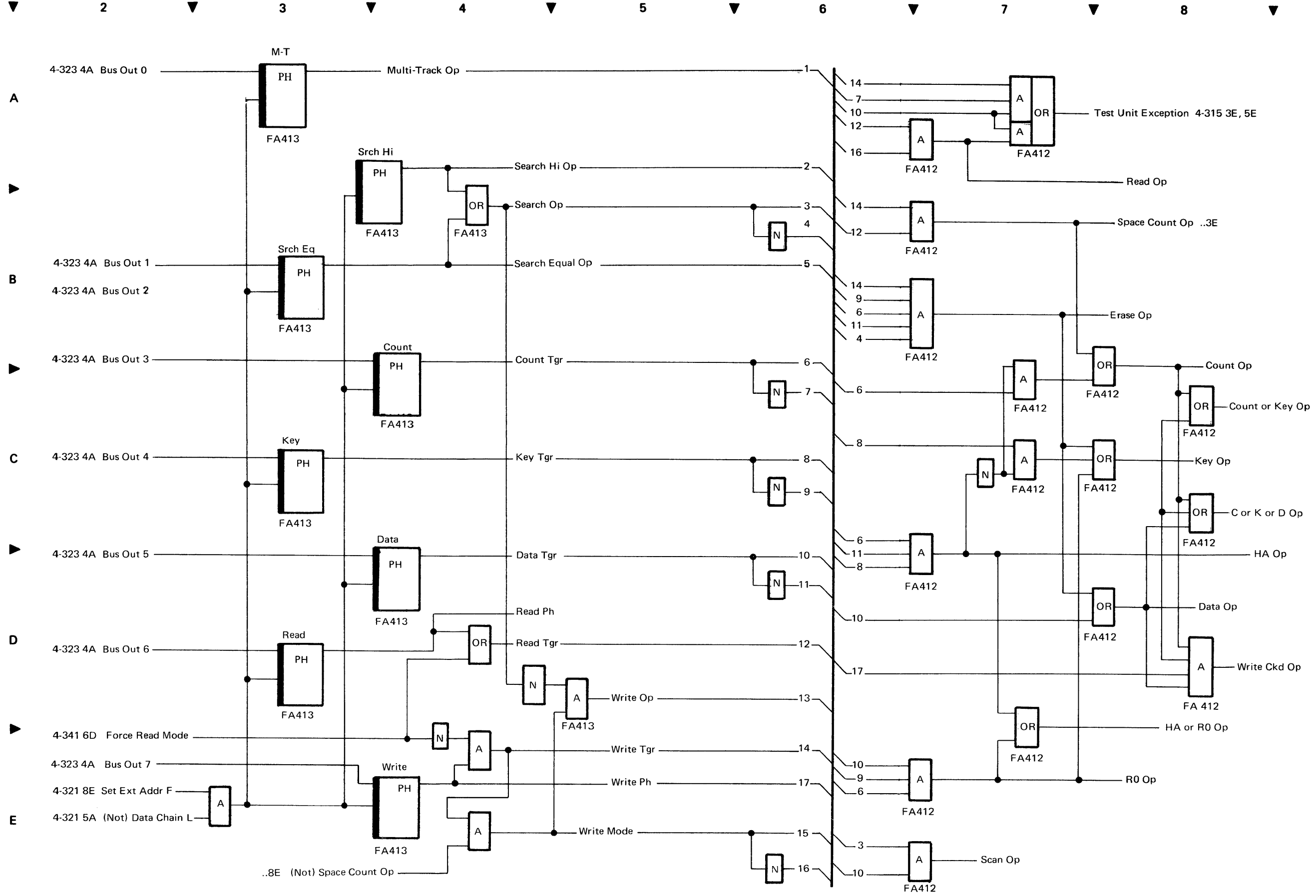


Diagram 4-321. CCW Flag Register and External Decodes

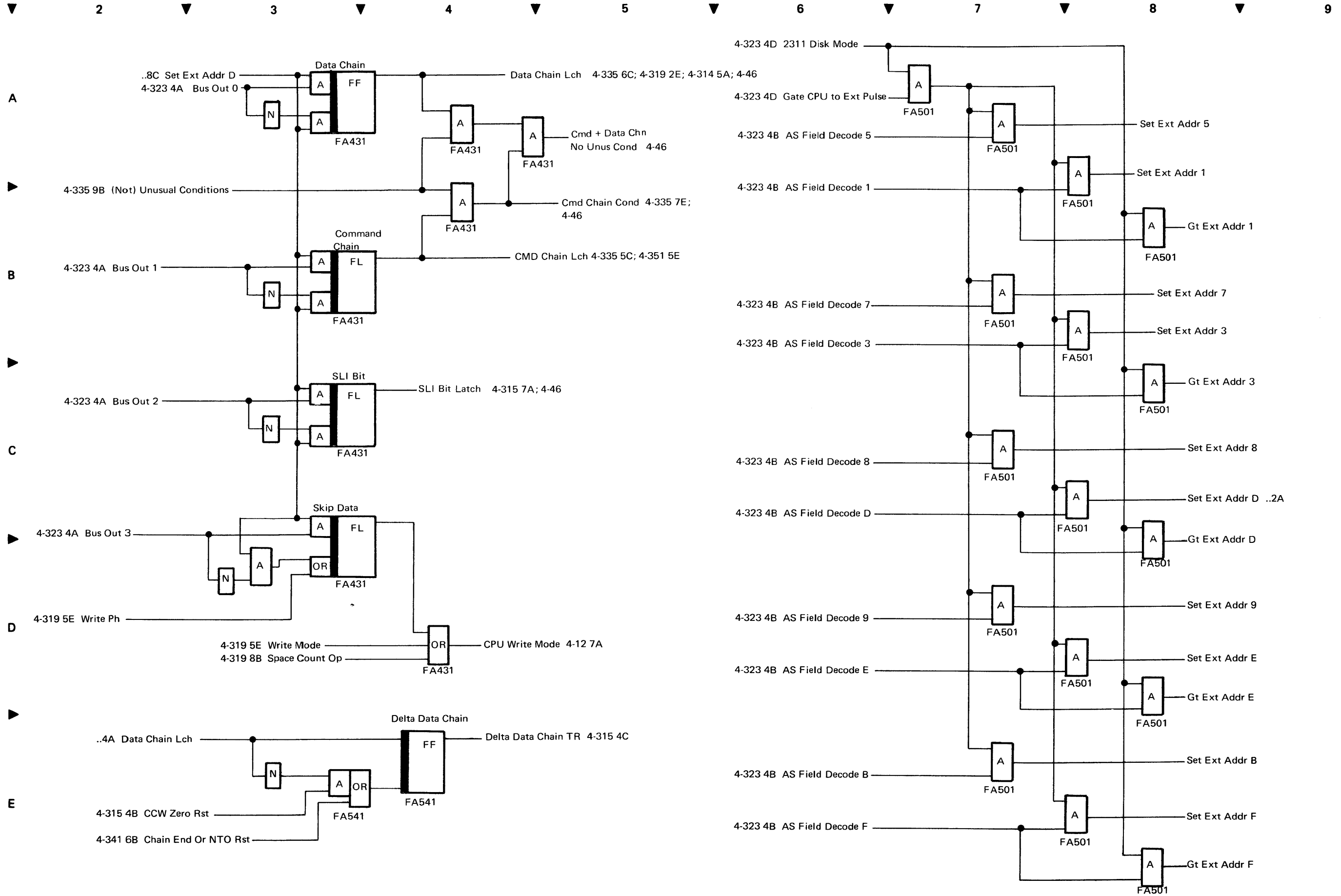


Diagram 4-323. Data Entry and Write Buffer Controls

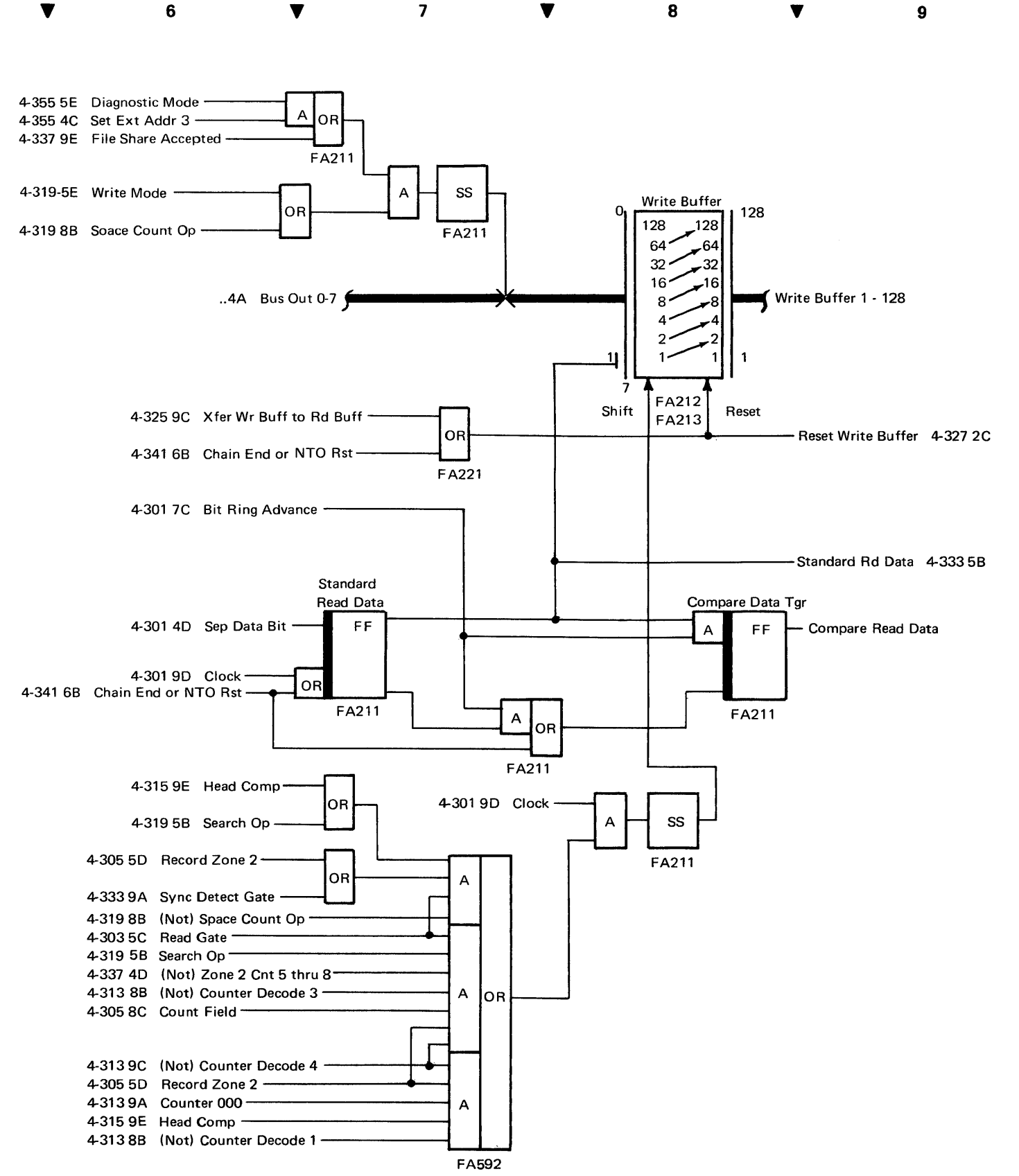
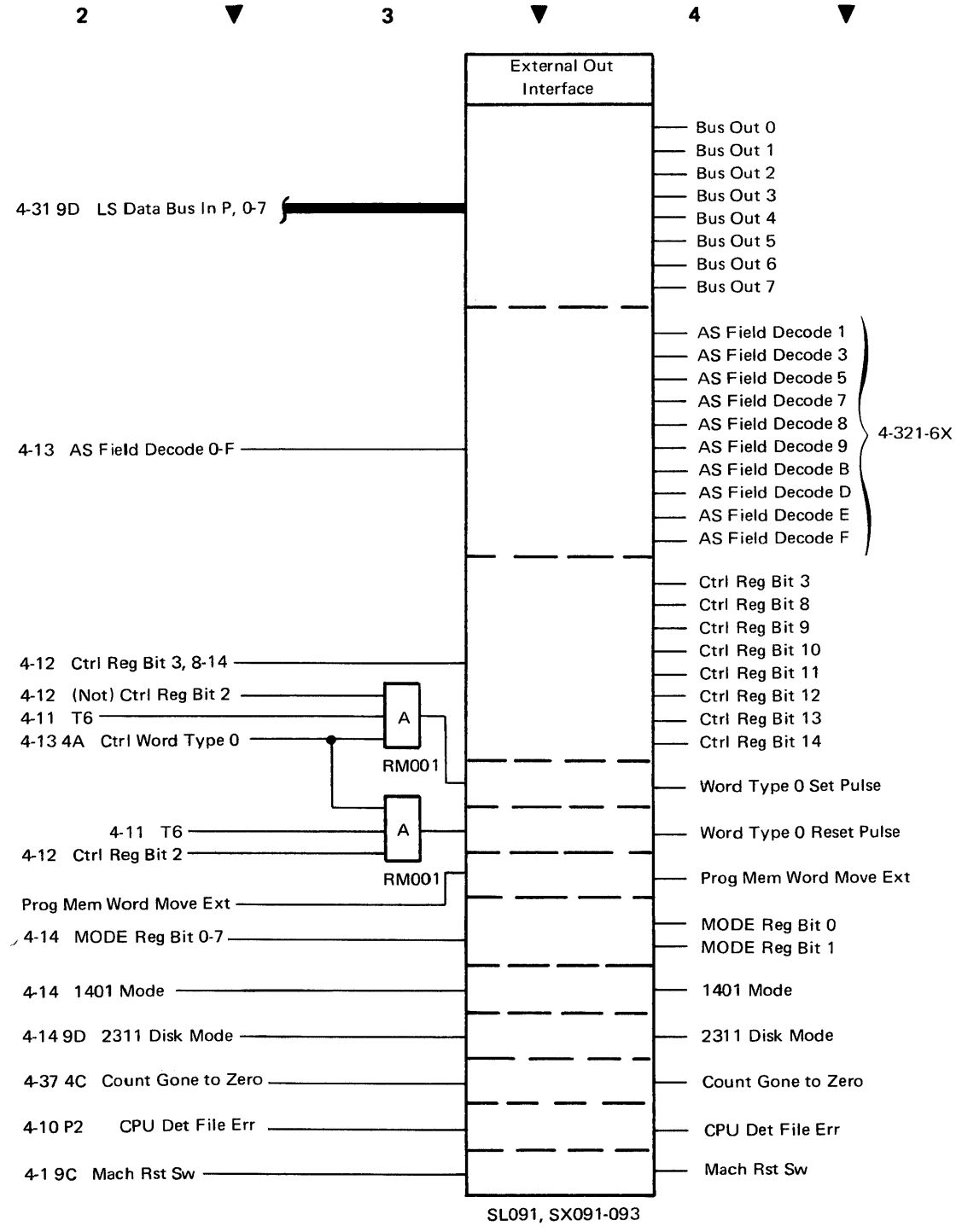


Diagram 4-325. Read Buffer and Assembler

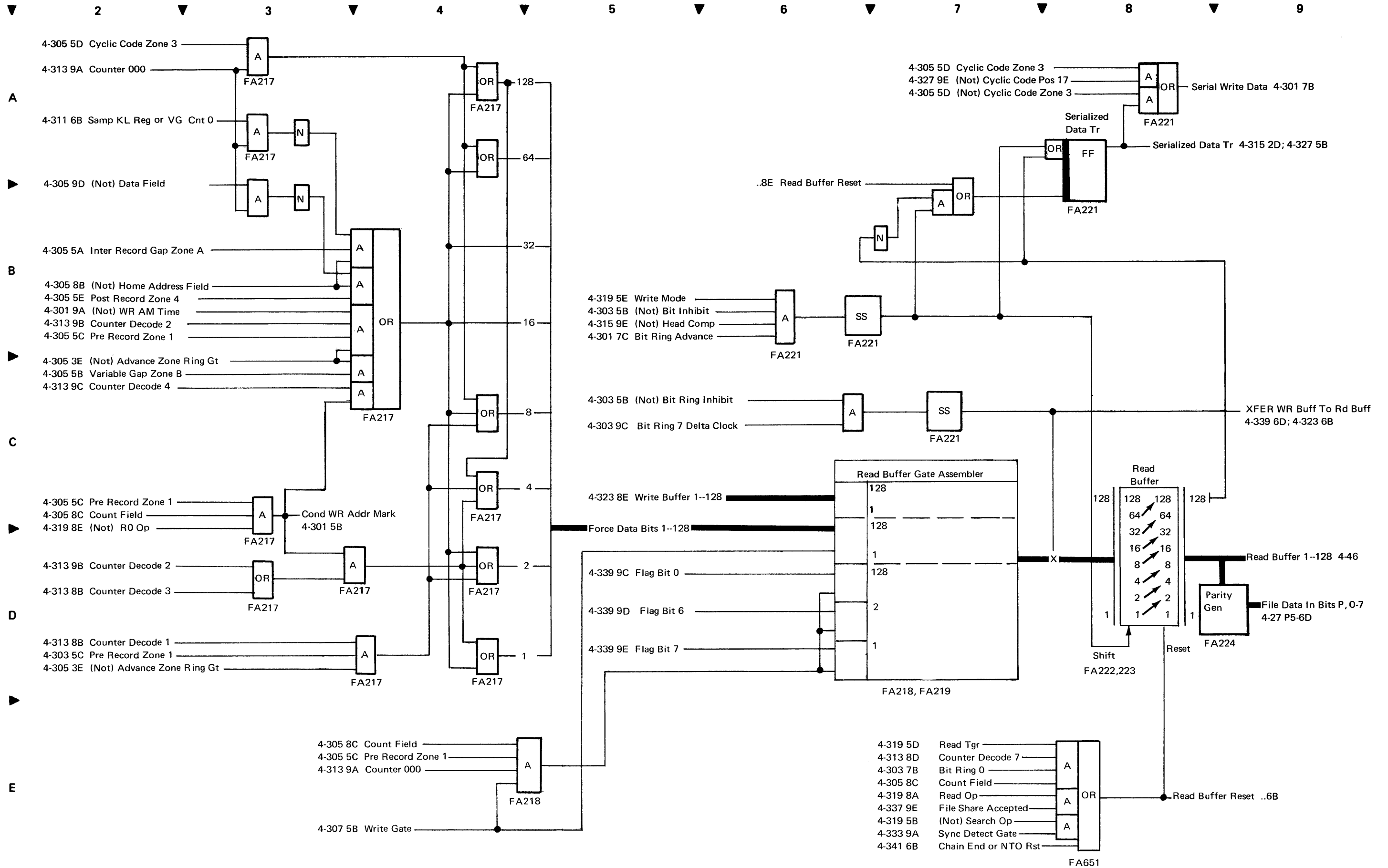


Diagram 4-327. Cyclic Code Controls and Compare

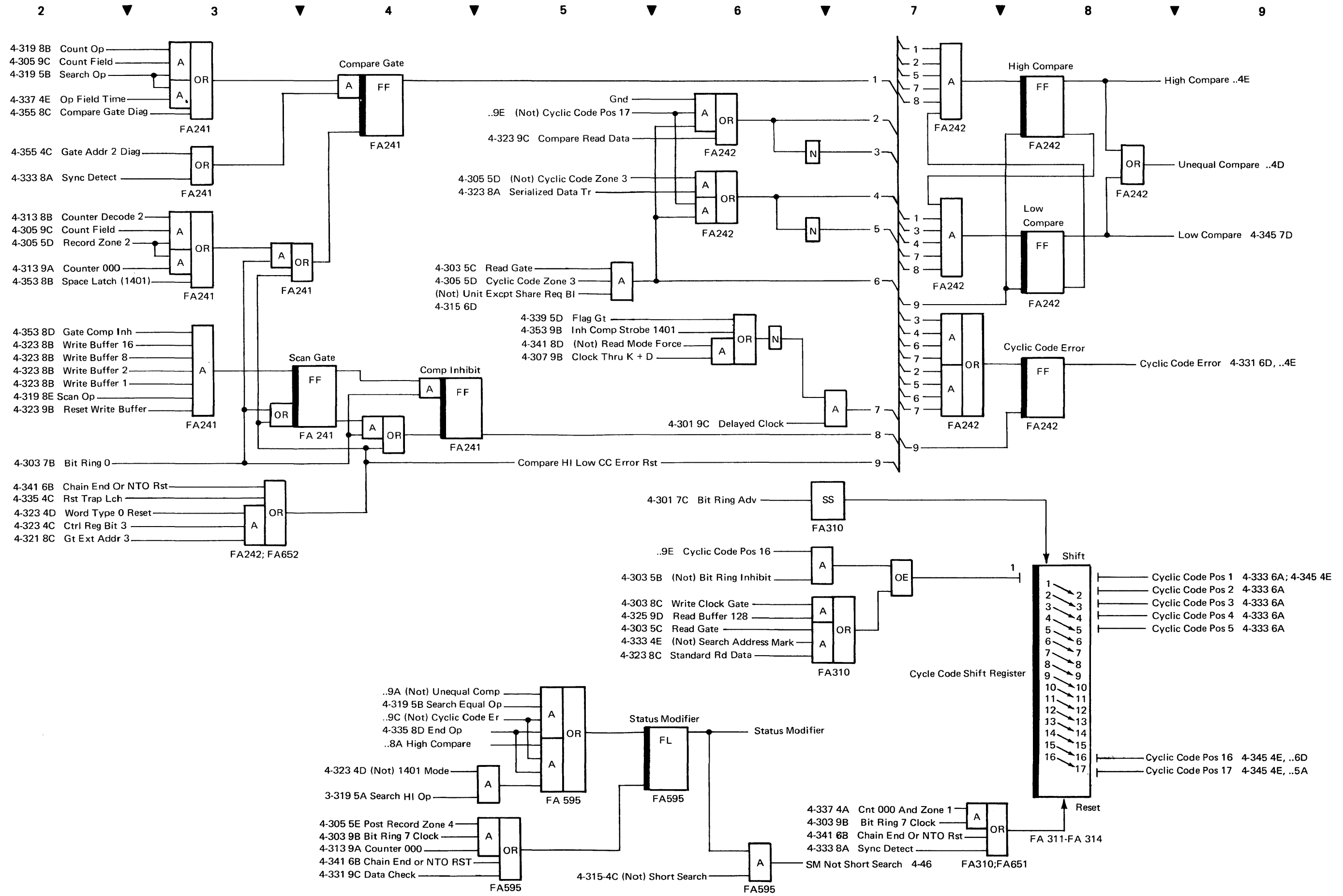


Diagram 4-331. Index Controls and Overrun Detection

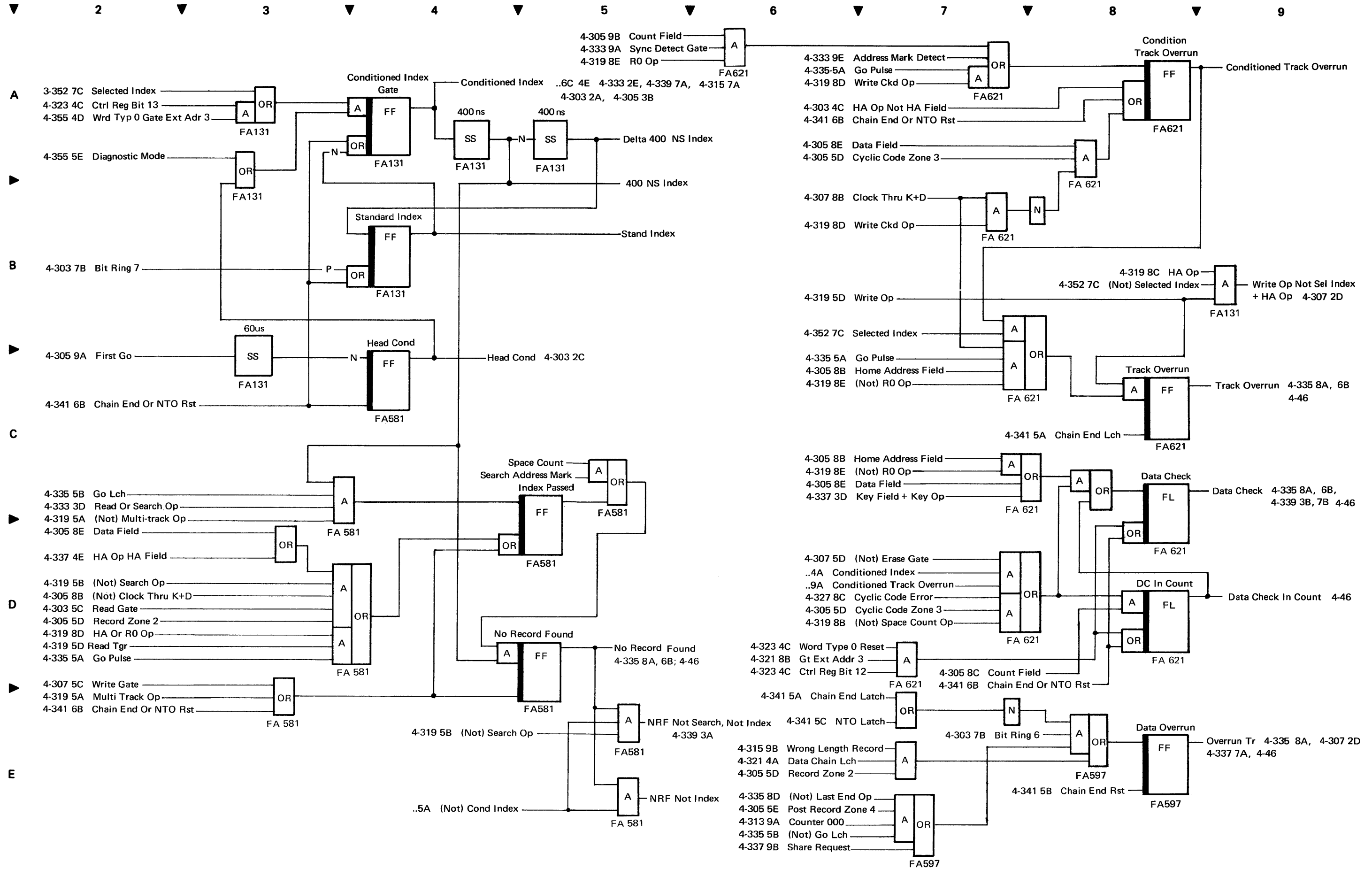


Diagram 4-333. Address Mark Search and Sync Detect

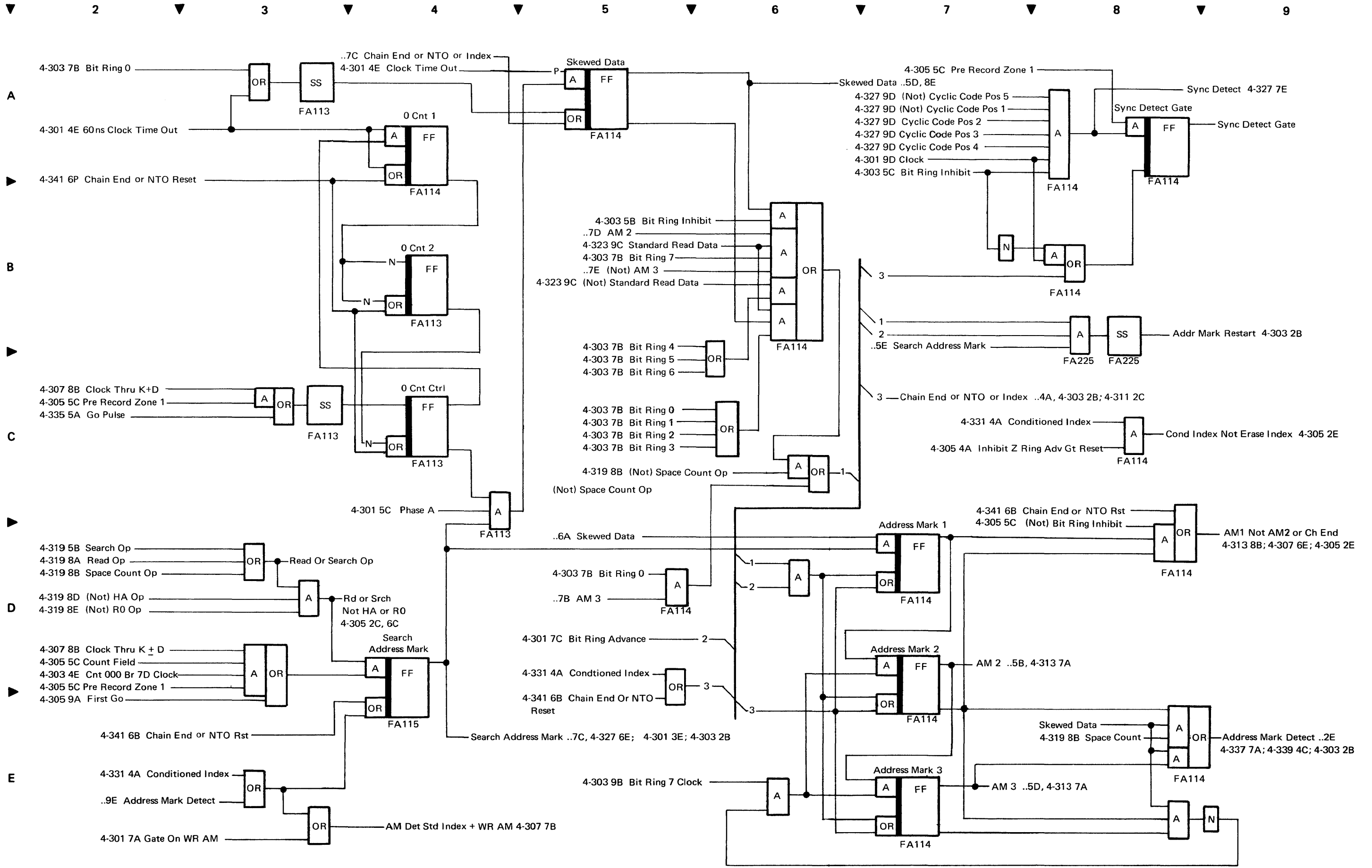


Diagram 4-335. Interrupt and Trap Controls

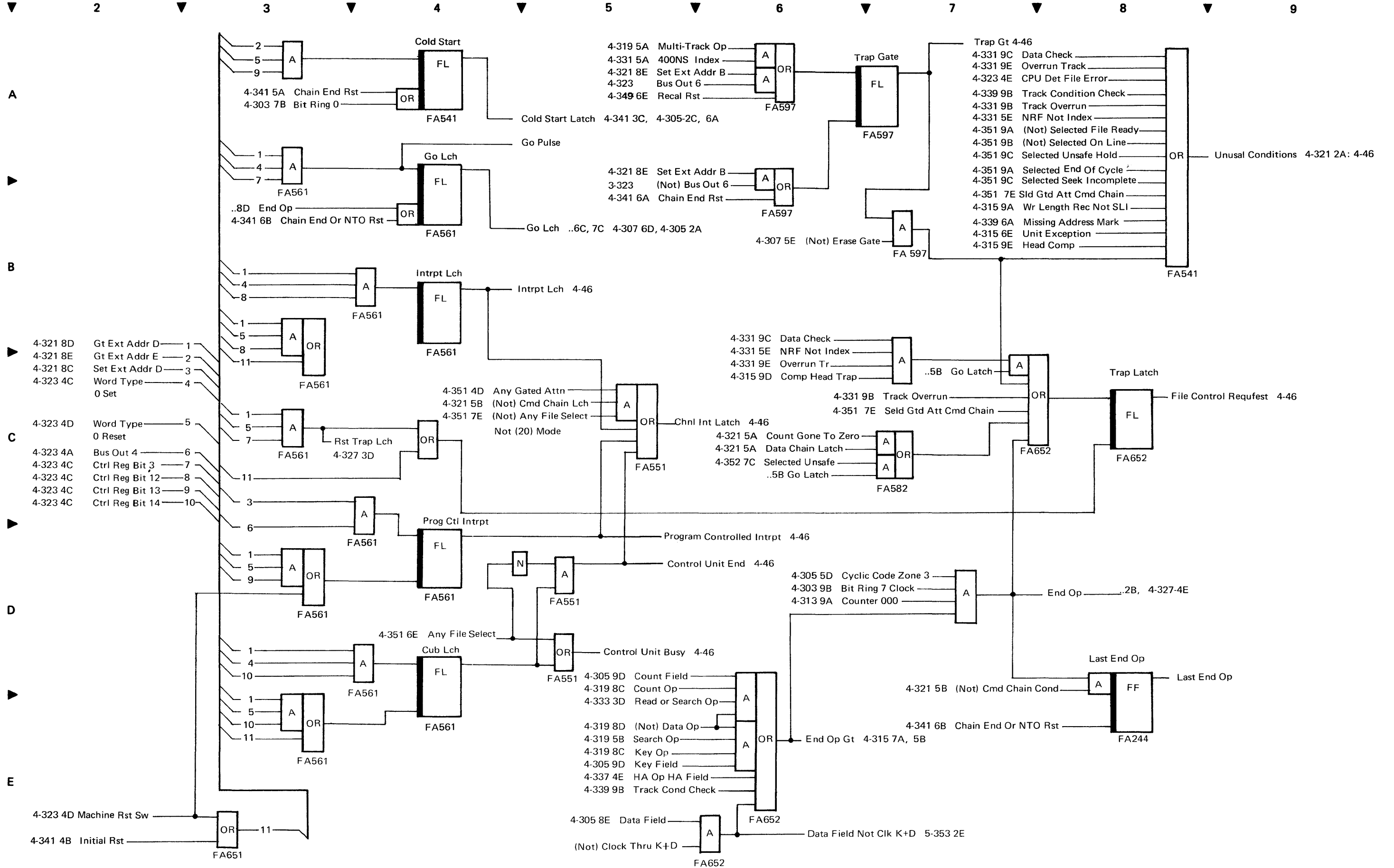


Diagram 4-337. Share Request Controls

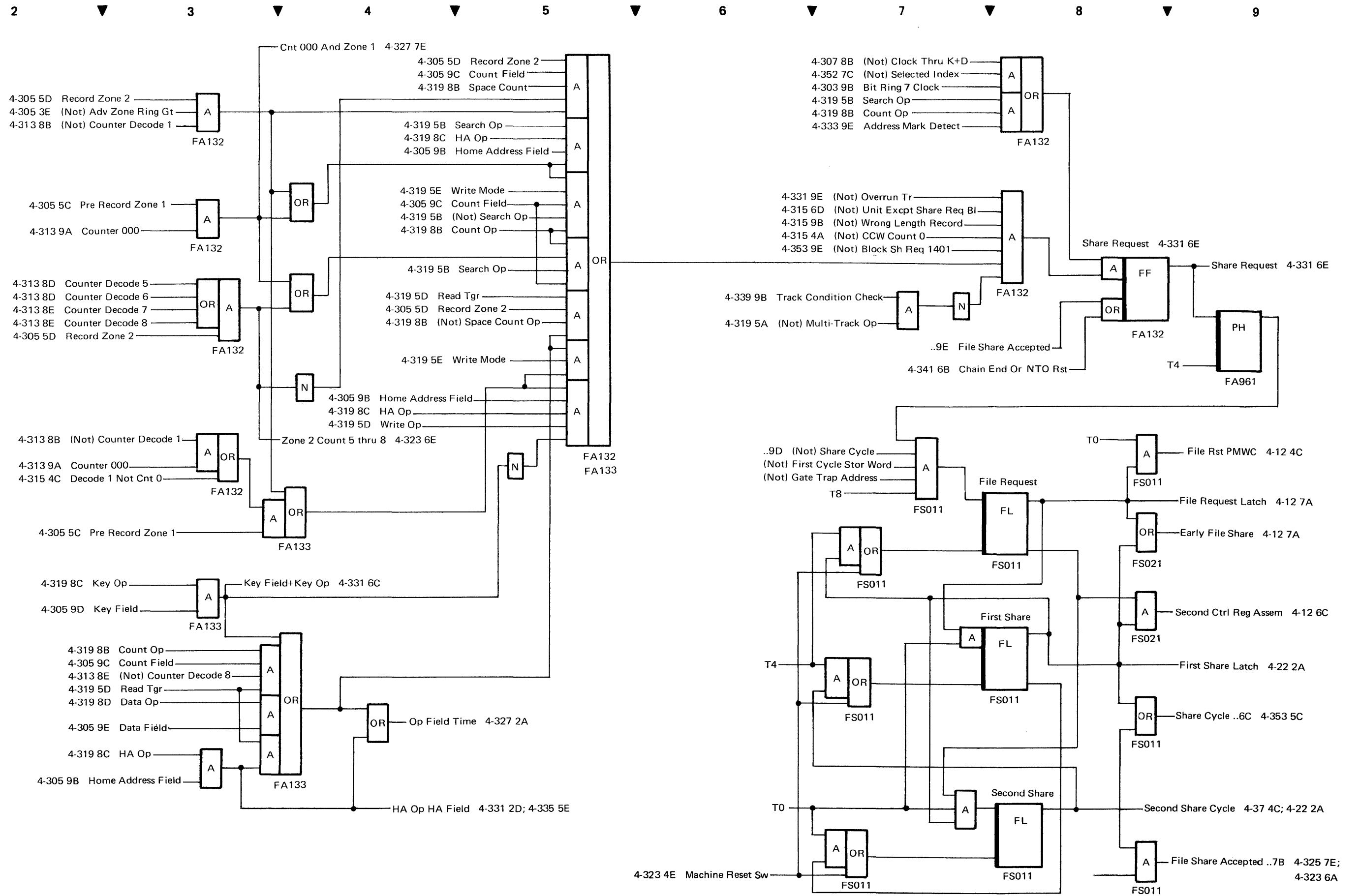


Diagram 4-339. Track Condition Flag Controls

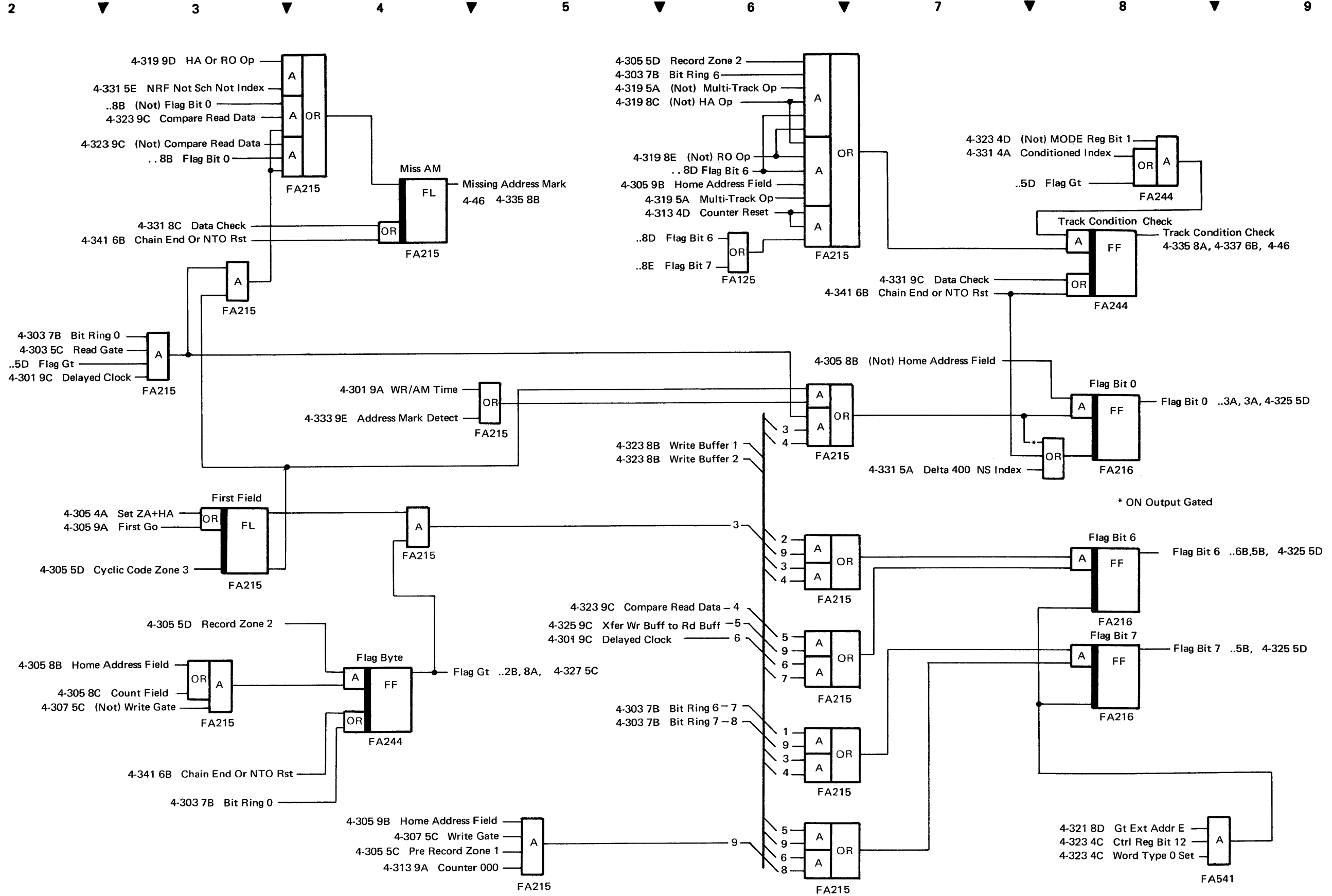


Diagram 4-341. Reset Controls

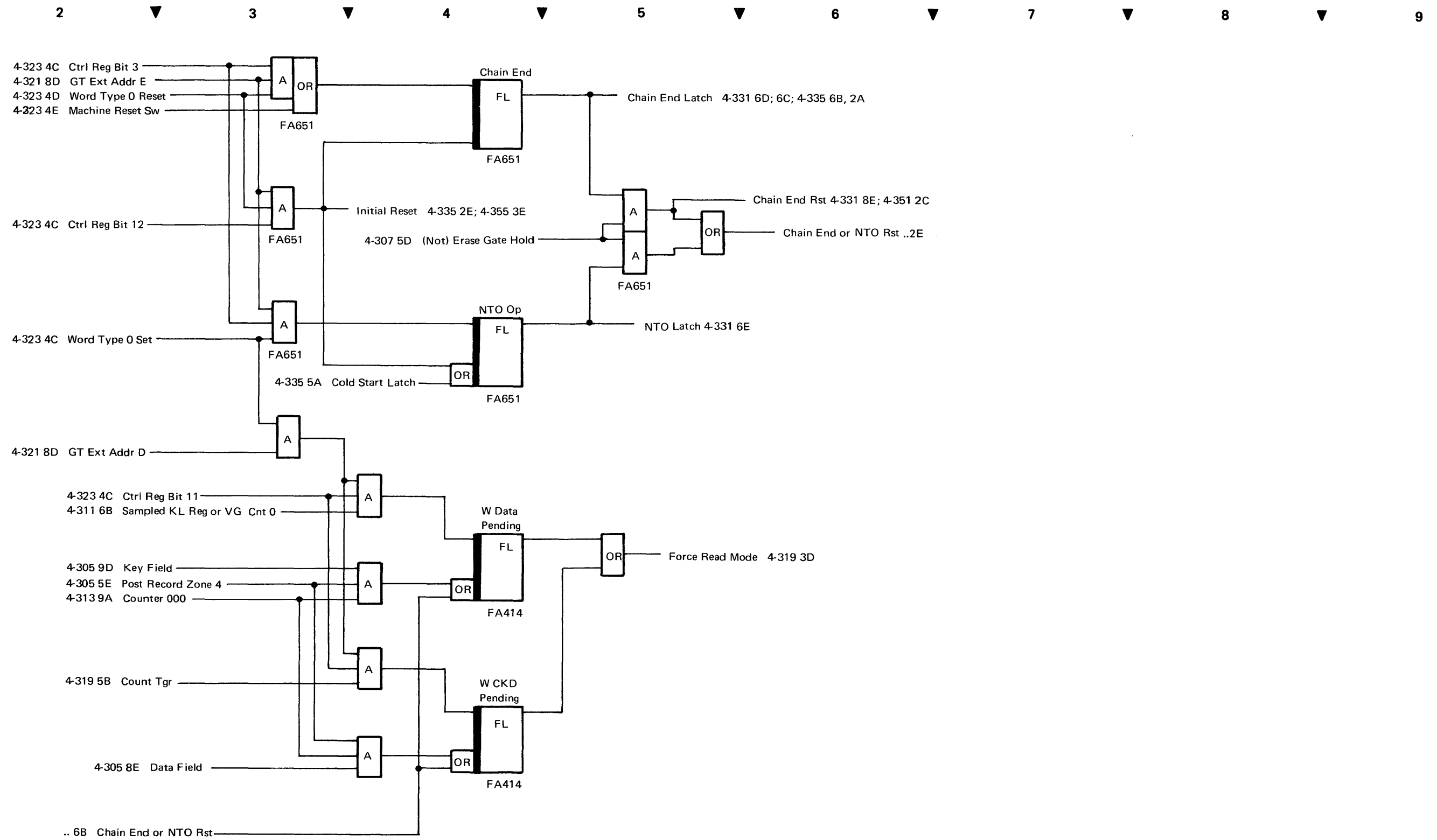
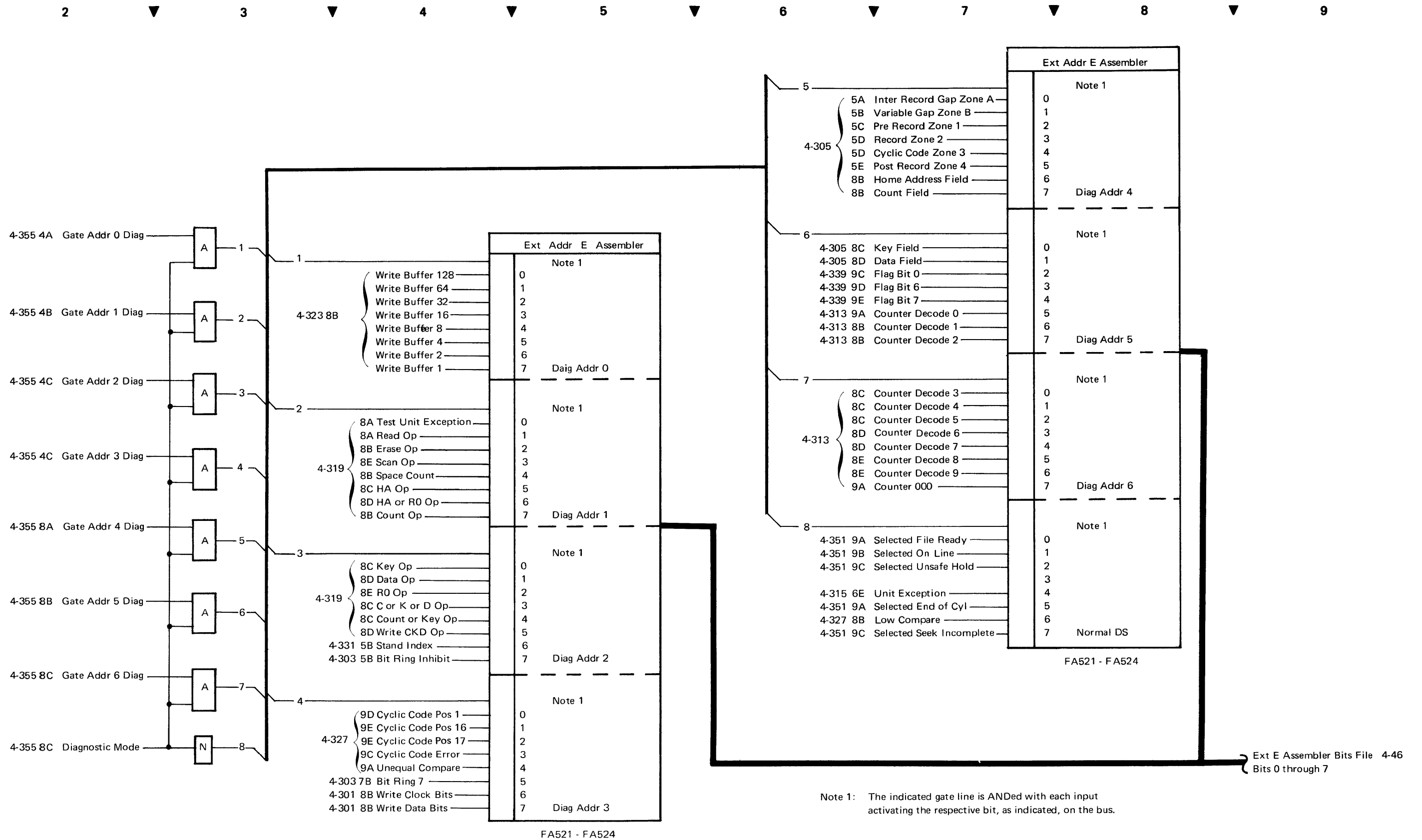


Diagram 4-345. External Decode E Assembler



FA521 - FA524

FA521 - FA524

Ext E Assembler Bits File 4-46
Bits 0 through 7

Diagram 4-349. File Interface File Bus and Tag Controls

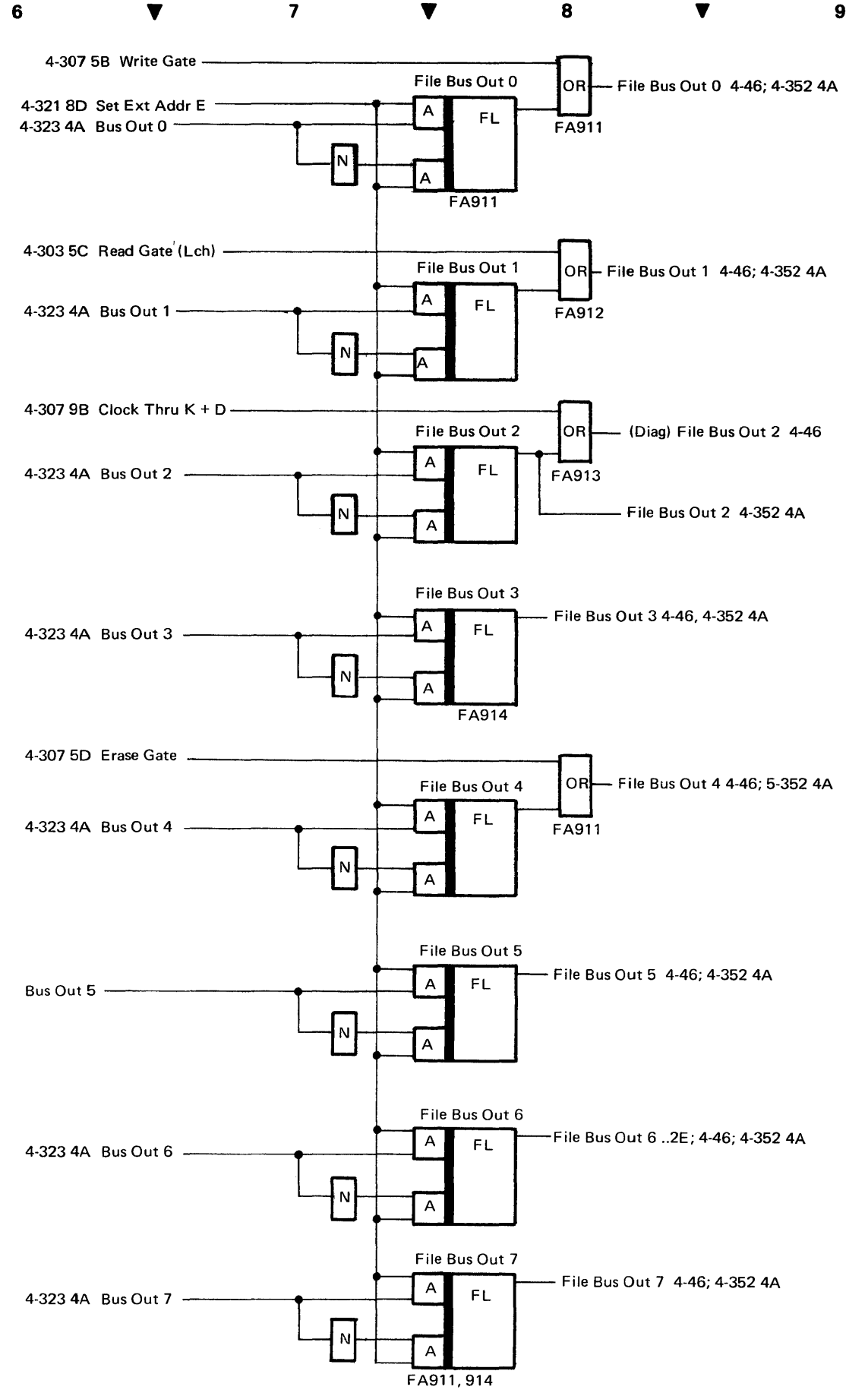
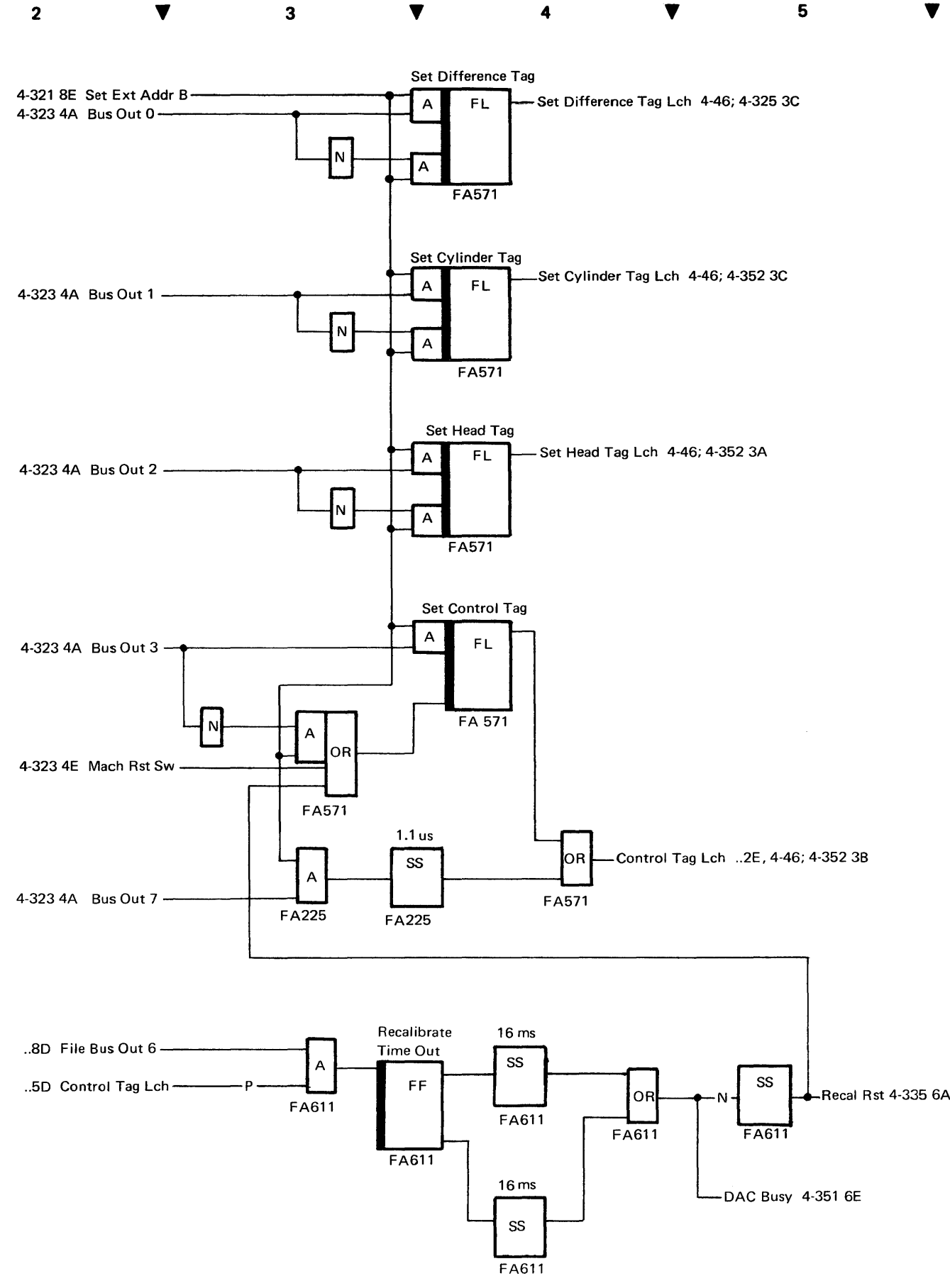


Diagram 4-351. File Interface Status and Module Selection

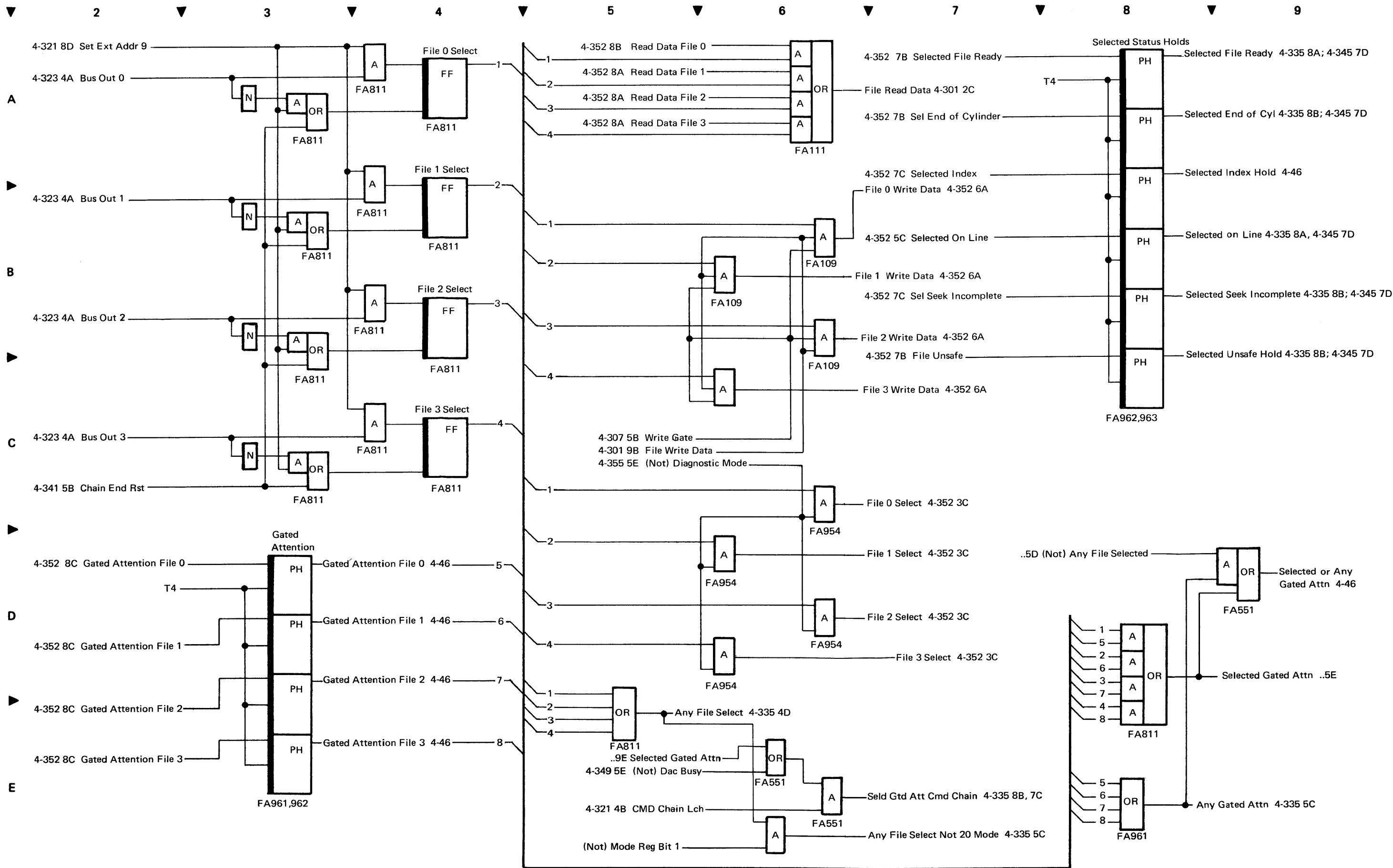


Diagram 4-352. File Interface

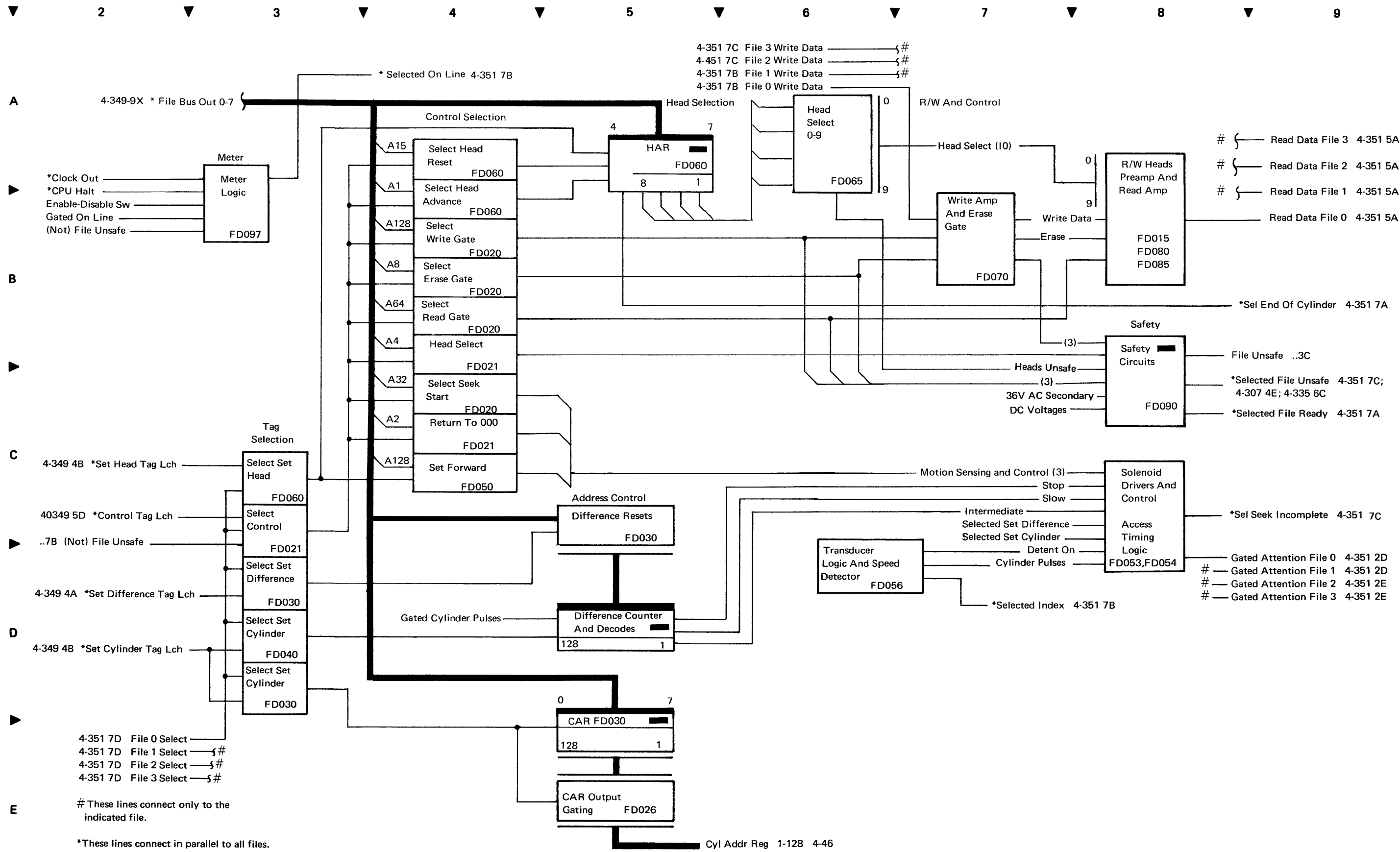


Diagram 4-353. 1401 Compatibility Controls

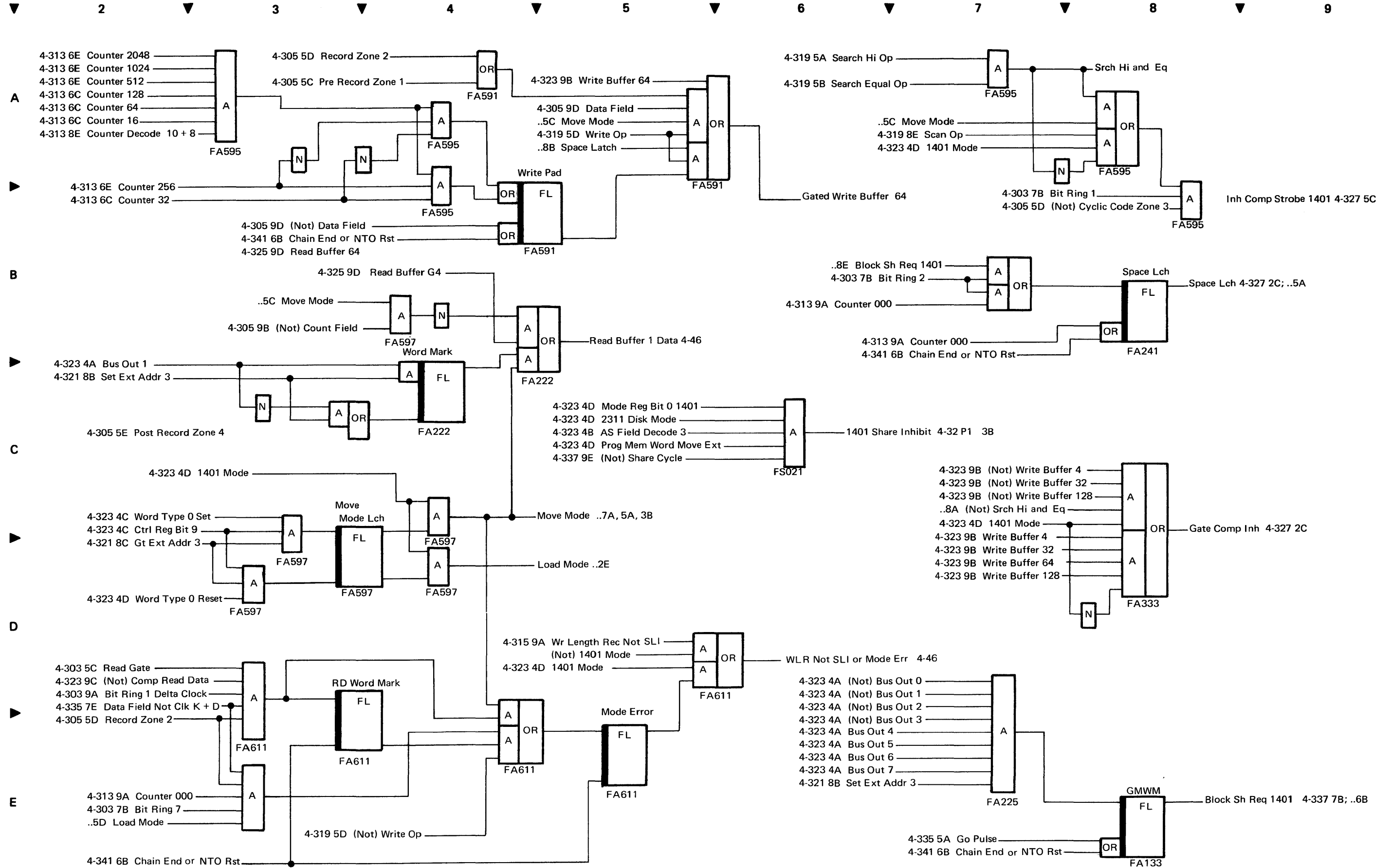
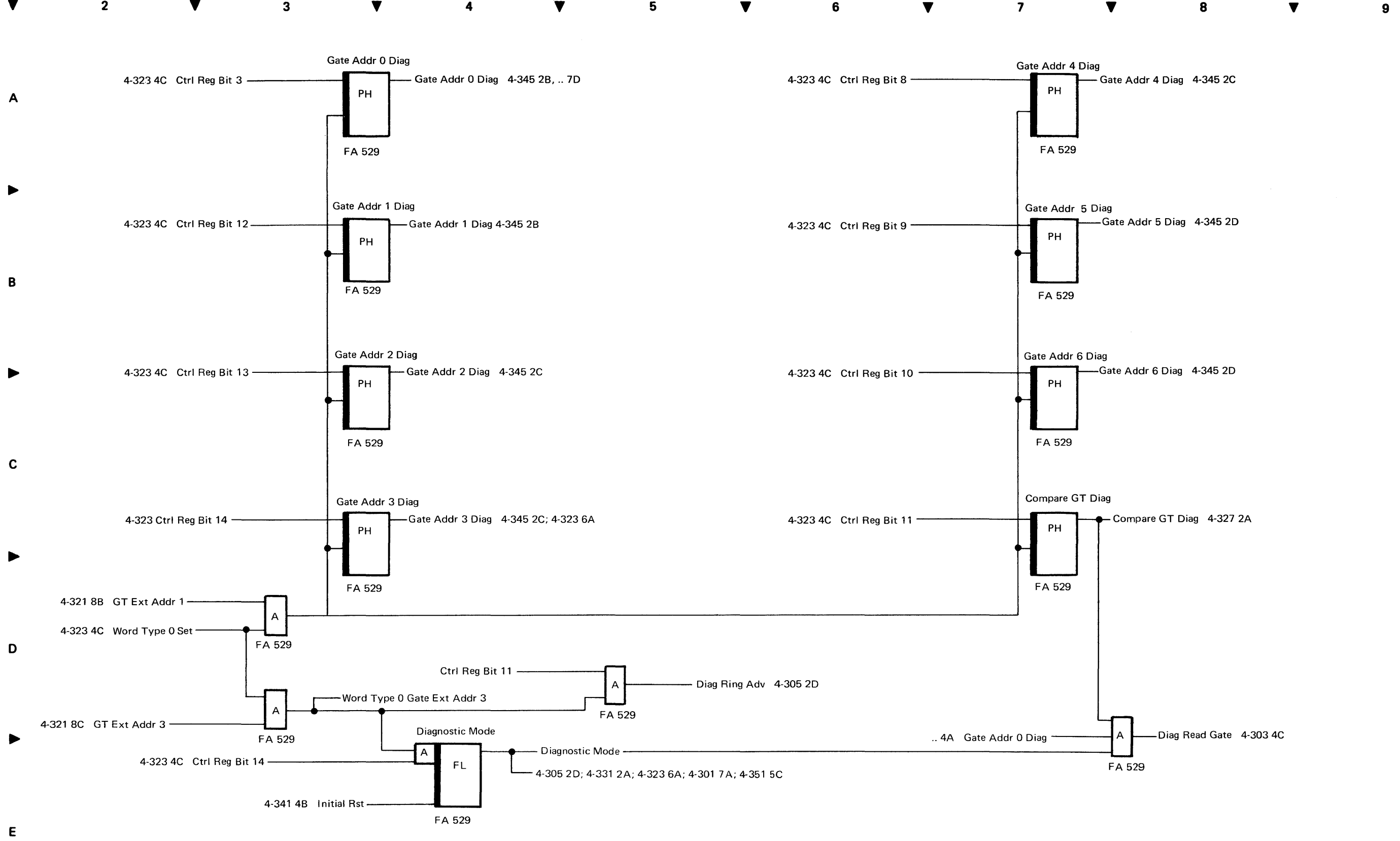


Diagram 4-355. Diagnostic Controls



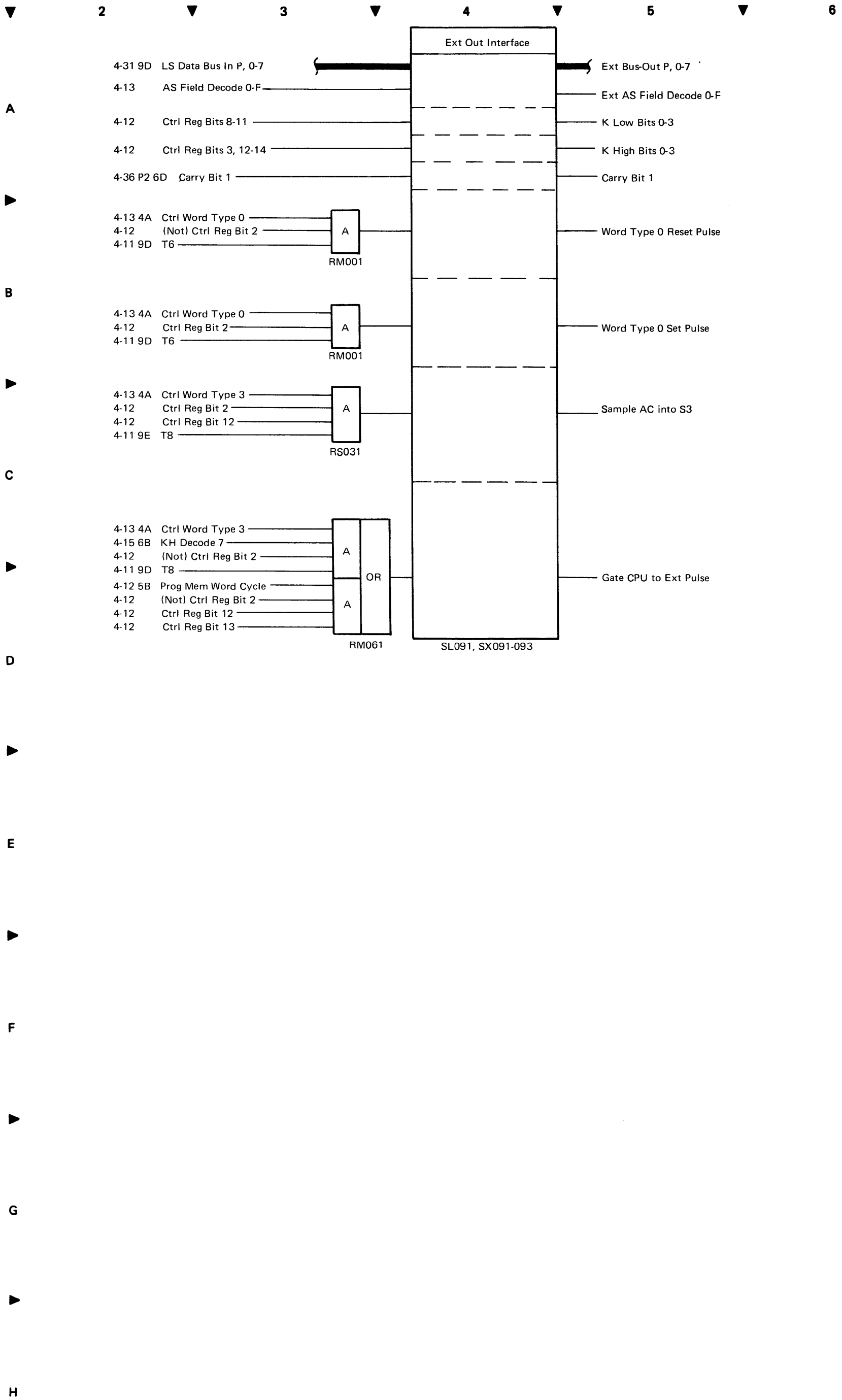


Diagram 4-400. External Out Interface Channel

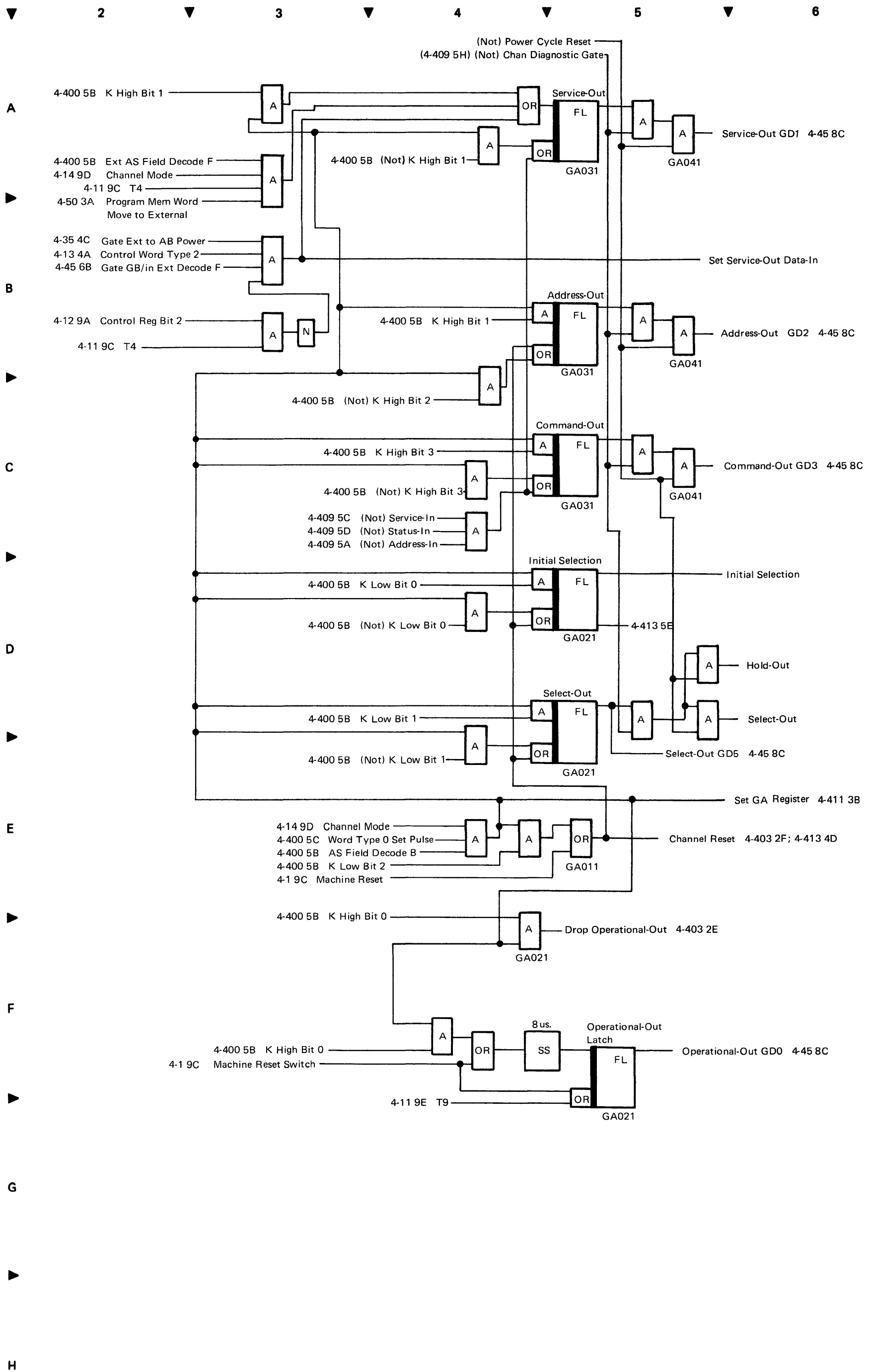


Diagram 4-401. Circuits Controlled by the Set/Reset GA Control Word

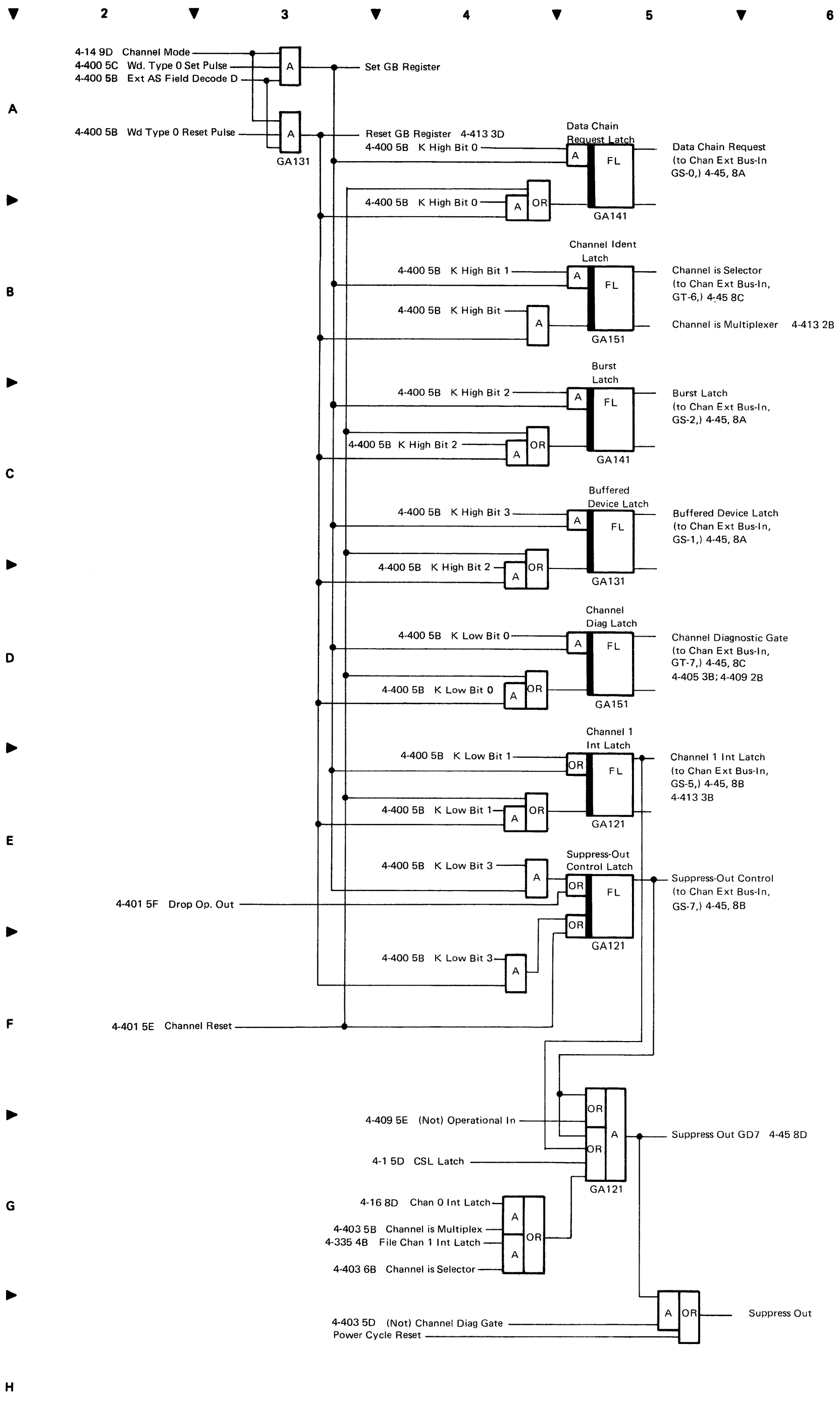


Diagram 4-403. Circuits Controlled by the Set/Reset GB Control Word

A
B
C
D
E
F
G
H

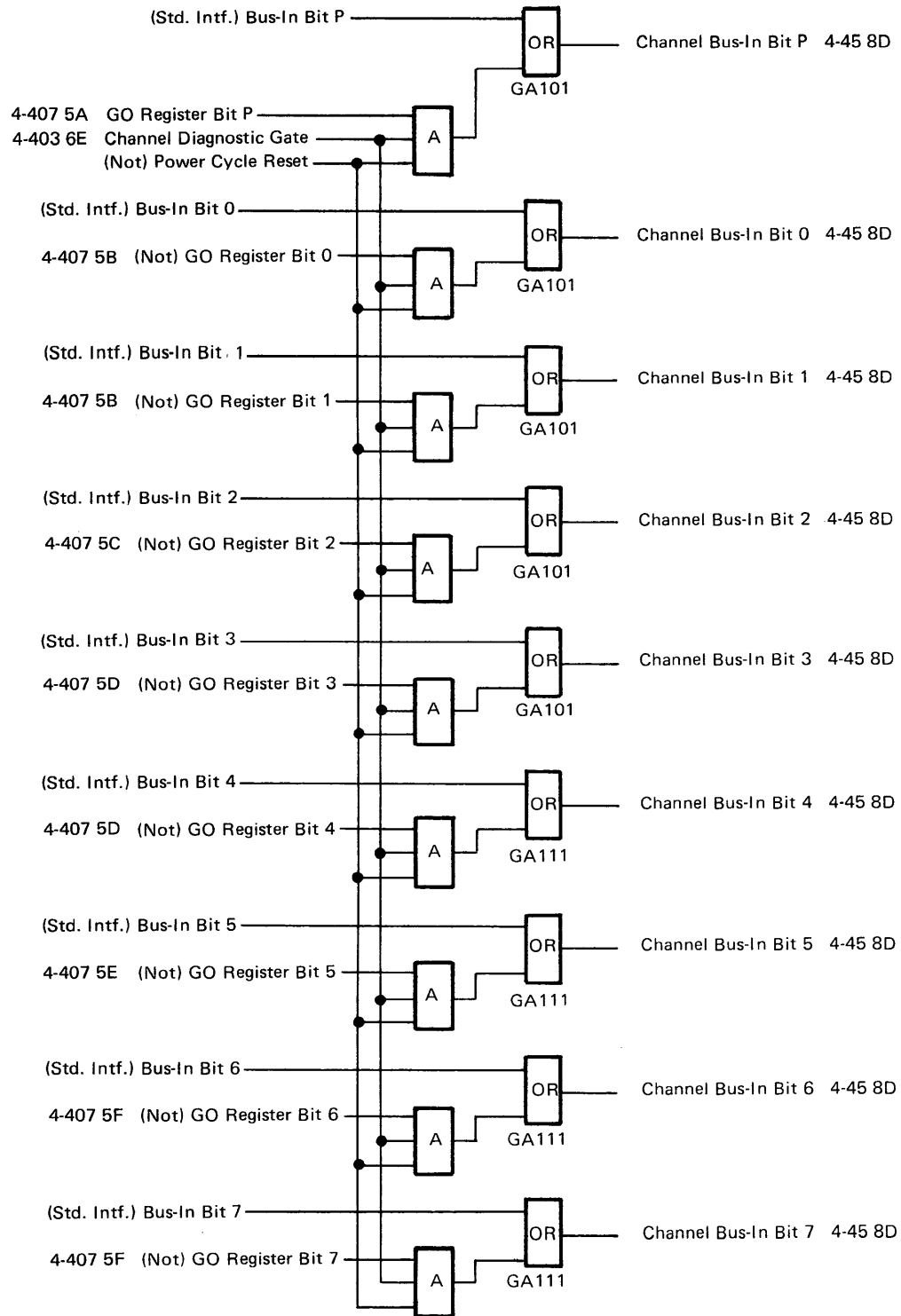


Diagram 4-405. Logic Diagram of the Bus/In Register (GI)

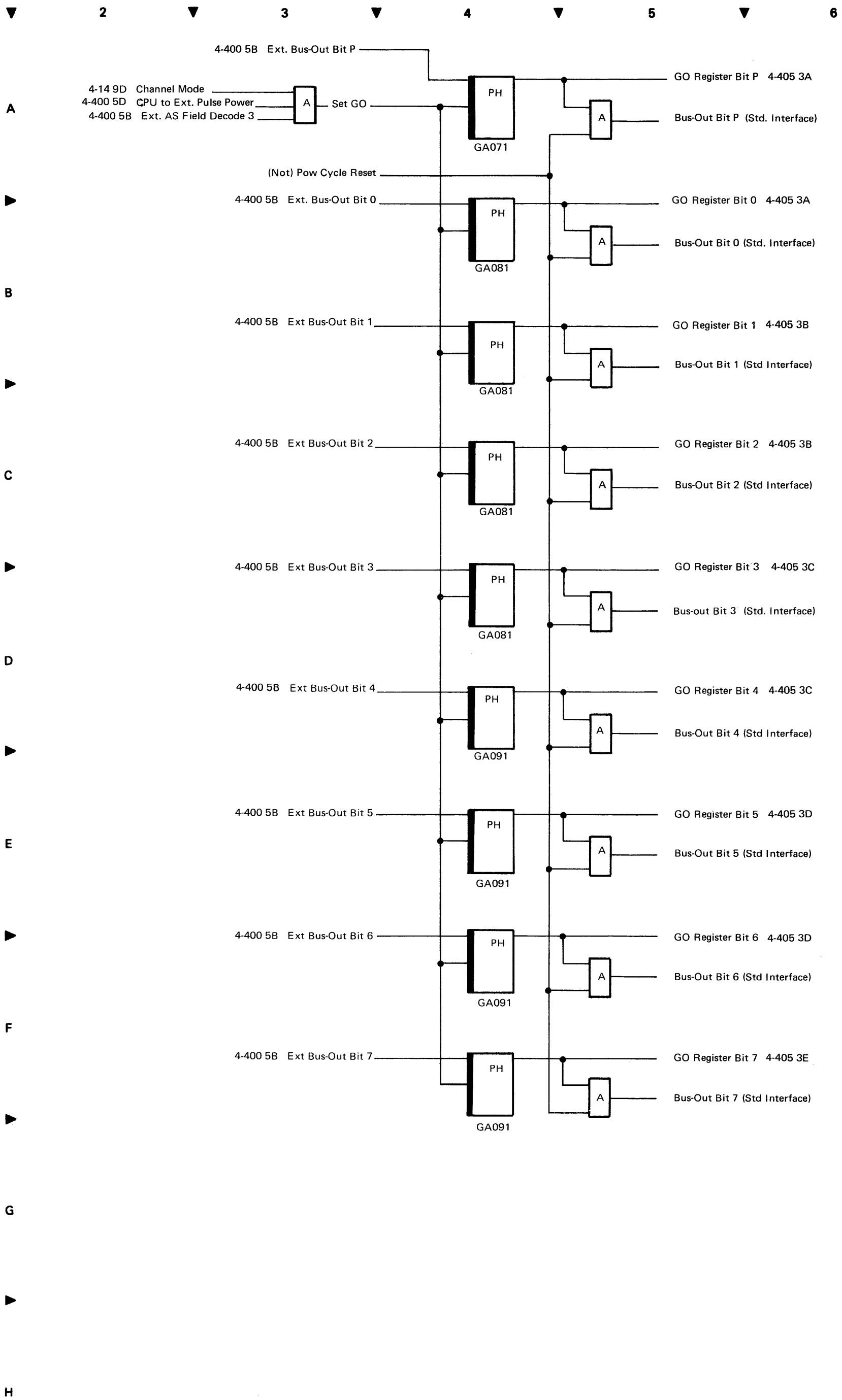


Diagram 4-407. Logic Diagram of the Bus/Out (GO) Register External Facility

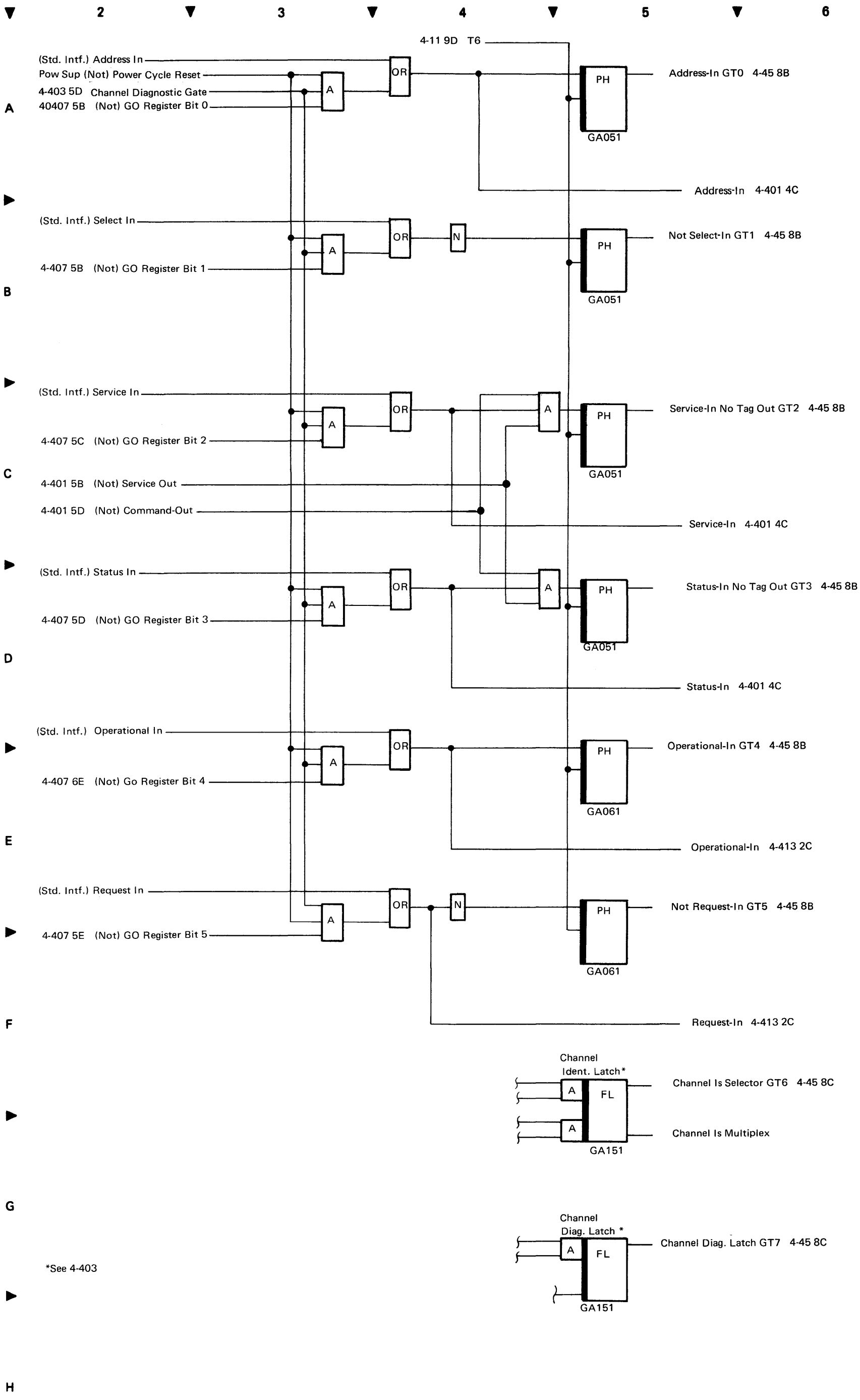


Diagram 4-409. Logic Diagram of the GT External Facility

▼

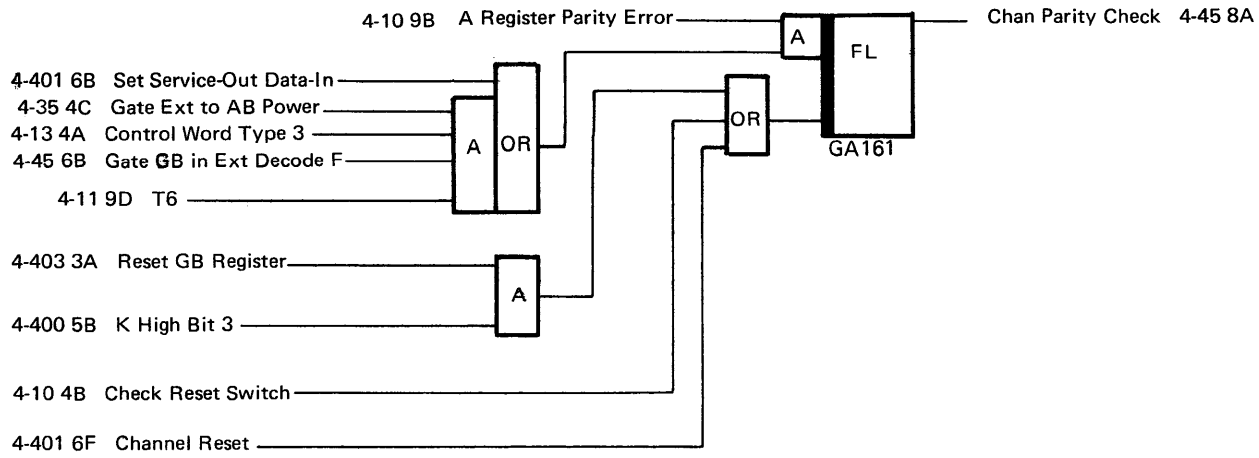
▼

▼

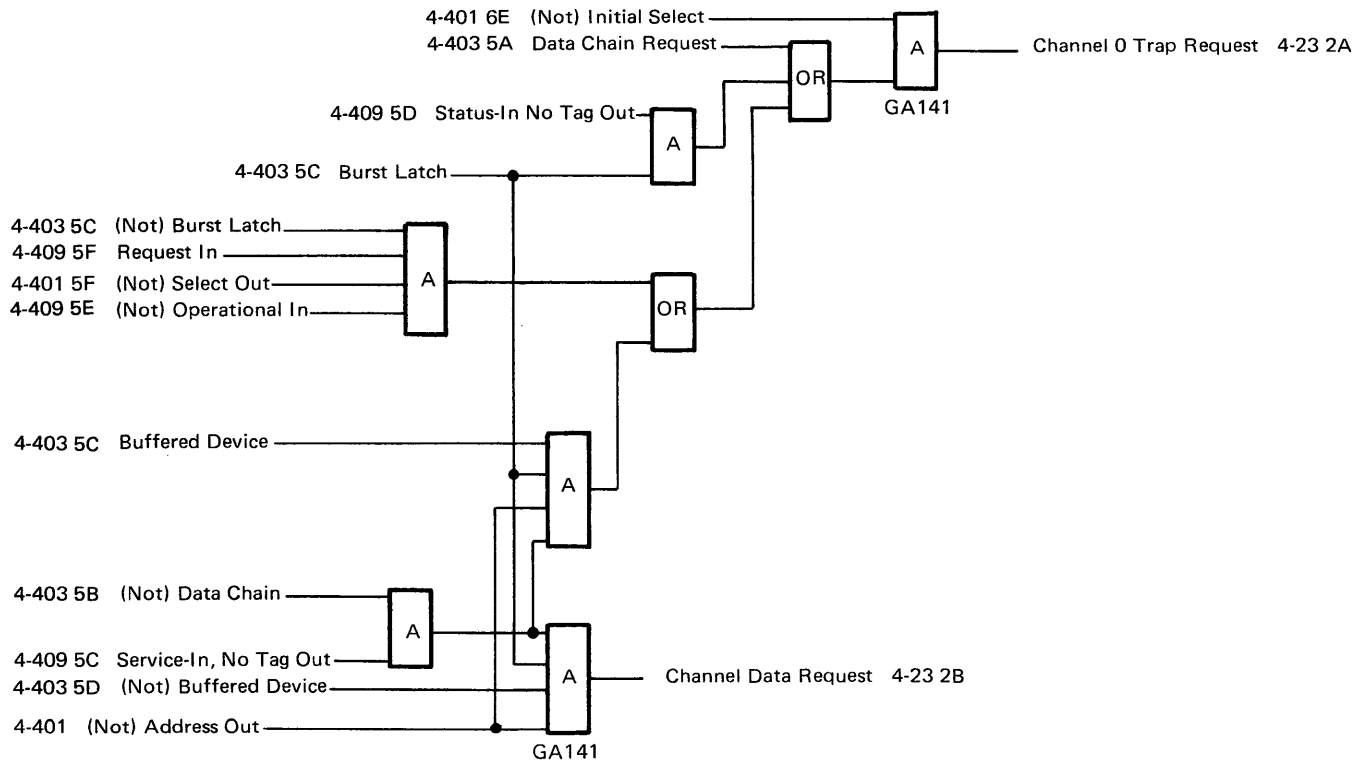
▼

▼

A



B



C

▼

D

▼

E

▼

F

▼

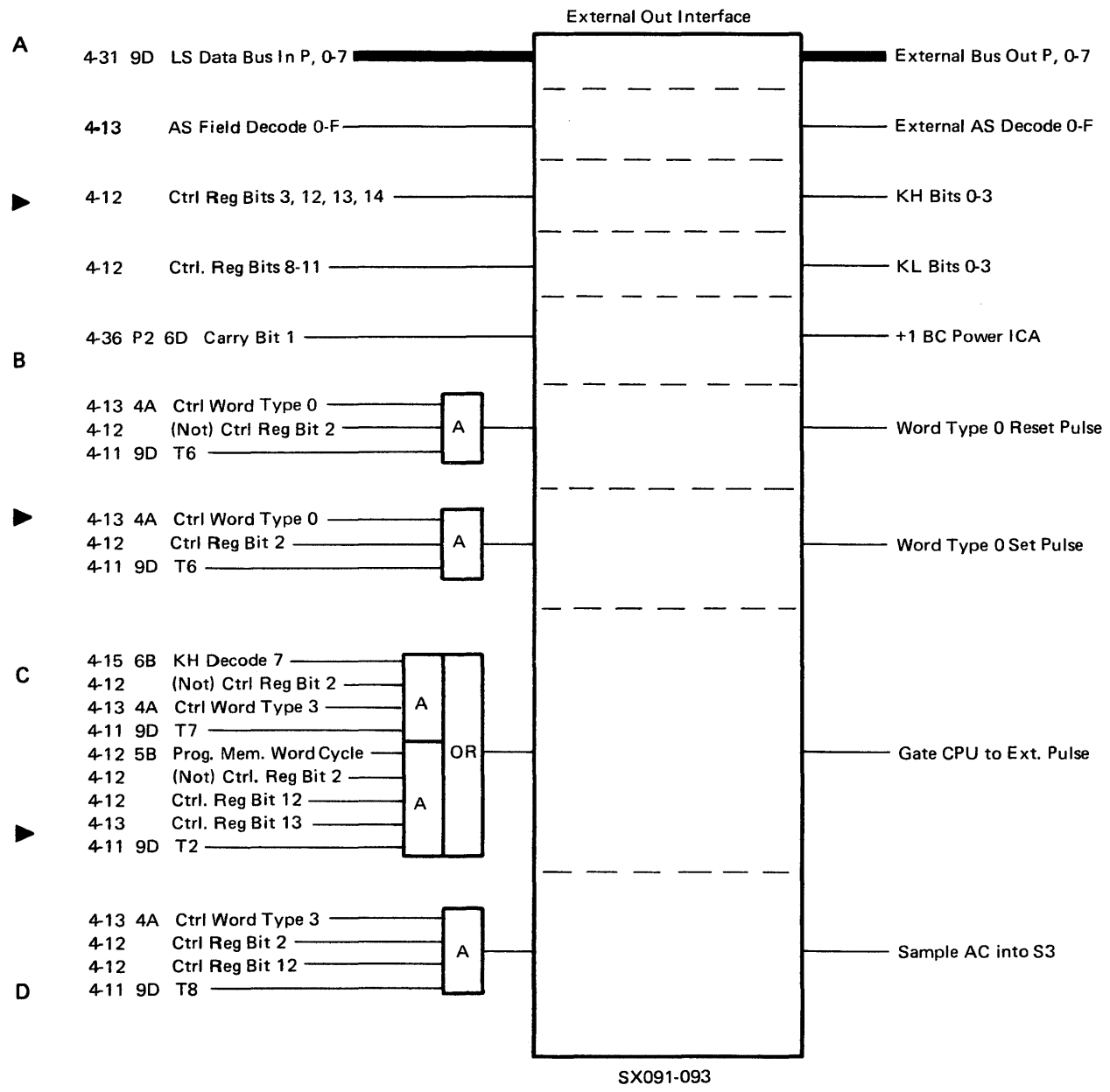
G

▼

H

Diagram 4-413. Development of Channel Parity Check, Trap Request, and Channel Data Request Signals

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6 ▼ 7 ▼ 8 ▼ 9



	ALD Location	MDM Location
Common Controls	HA004-HA142	4-500 to 4-525
Start/Stop LA0	HA201-HA209	↑ 4-527 to 4-535 ↓
Start/Stop LA1	HA211-HA219	
Start/Stop LA2	HA221-HA229	
Start/Stop LA3	HA231-HA239	
Start/Stop LA4	HA241-HA249	
Start/Stop LA5	HA251-HA259	
Telegraph LA0	HA401-HA409	
Telegraph LA1	HA411-HA419	
Telegraph LA2	HA421-HA429	
Telegraph LA3	HA431-HA439	
Telegraph LA4	HA441-HA449	
Telegraph LA5	HA451-HA459	
Synchronous LA	HA813-HA893	4-537 to 4-559
ACU 0	HA905-HA916	4-583 to 4-585
ACU 1	HA921-HA926	
Sync Int. Clock 1	HA971-HA978	4-587 to 4-591
Sync Int. Clock 2	HA981-HA988	

● Diagram 4-501. Clock Timings, Bus Out Buffer and CFW Buffer

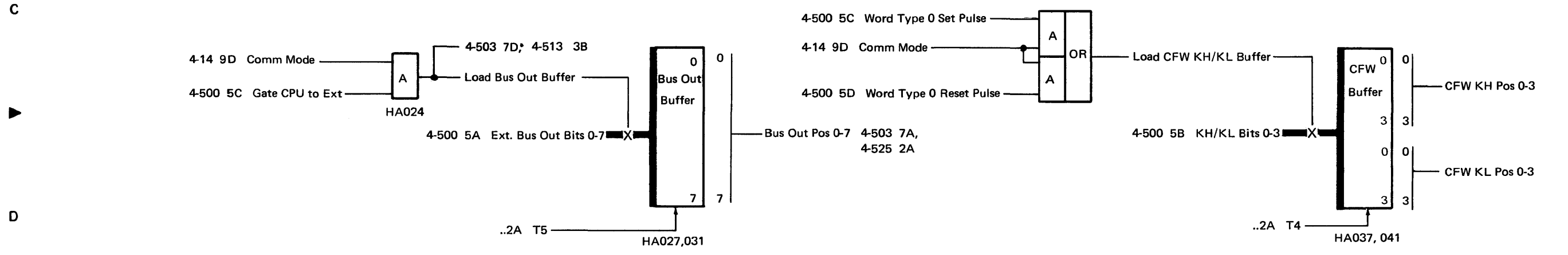
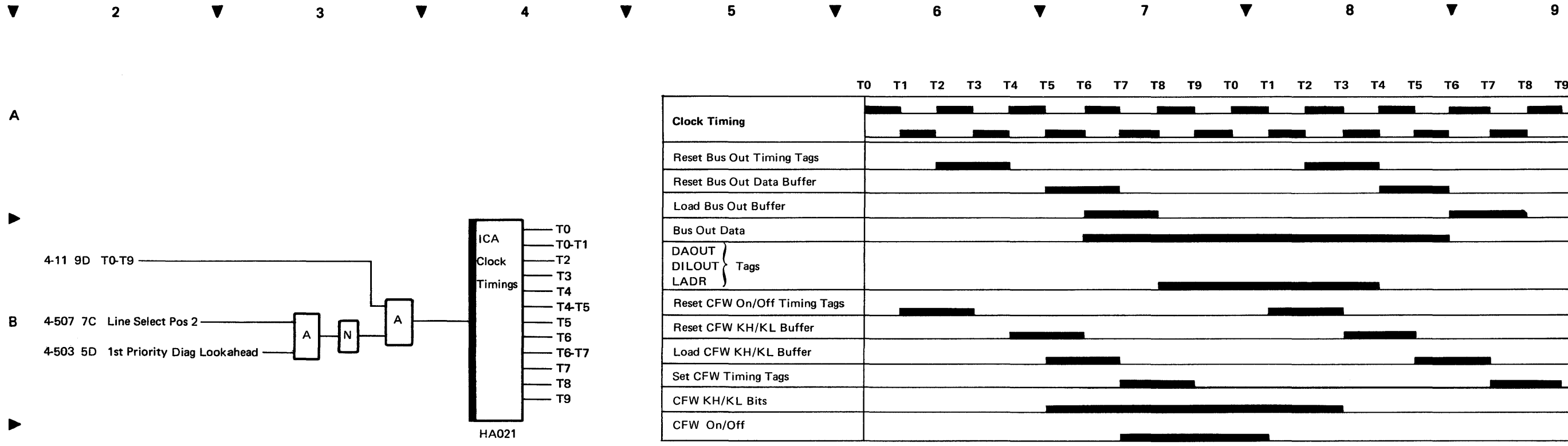


Diagram 4-503. CADR Register, LADR, DILOUT, and DAOUT Tags and DILIN External

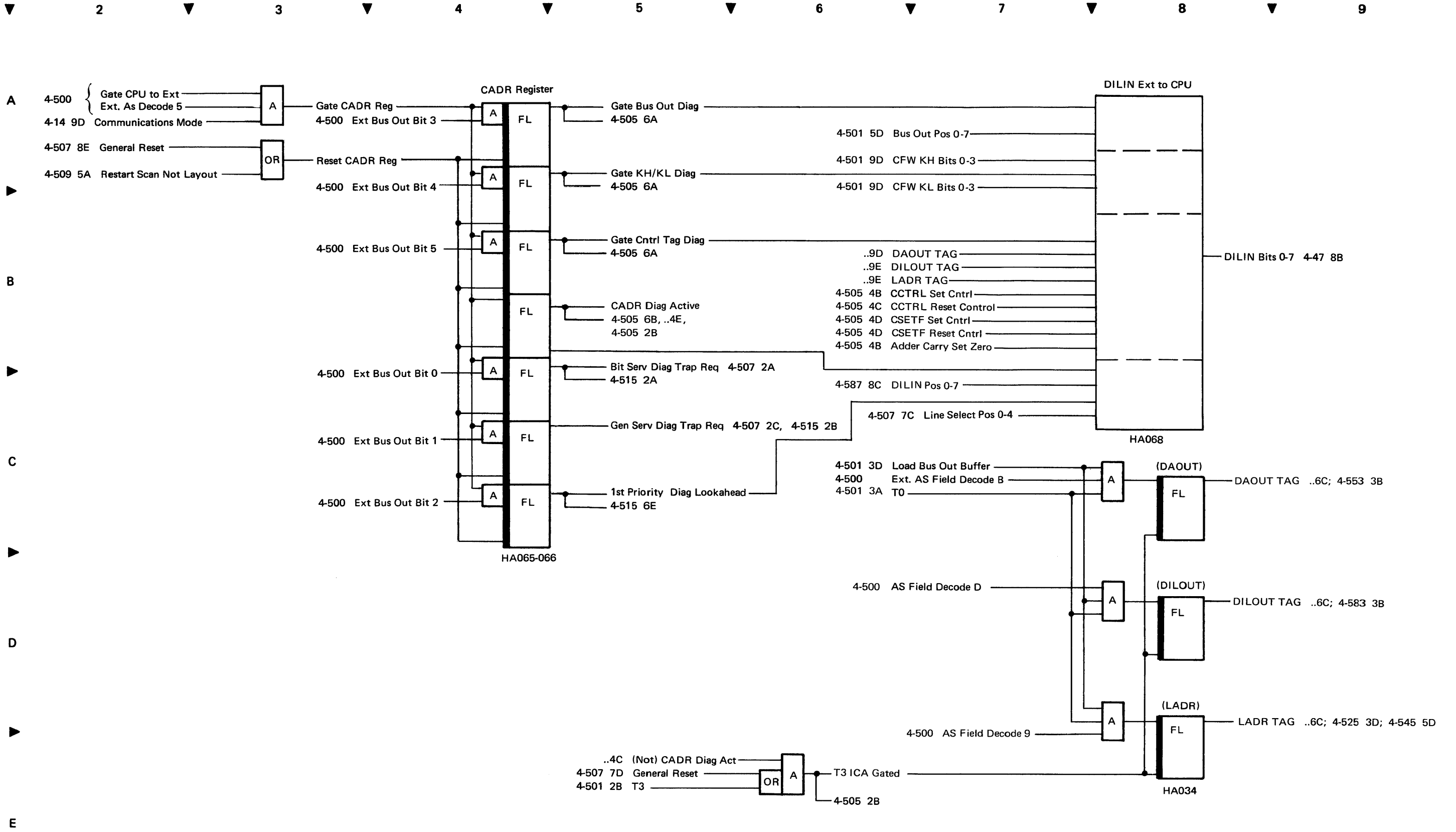
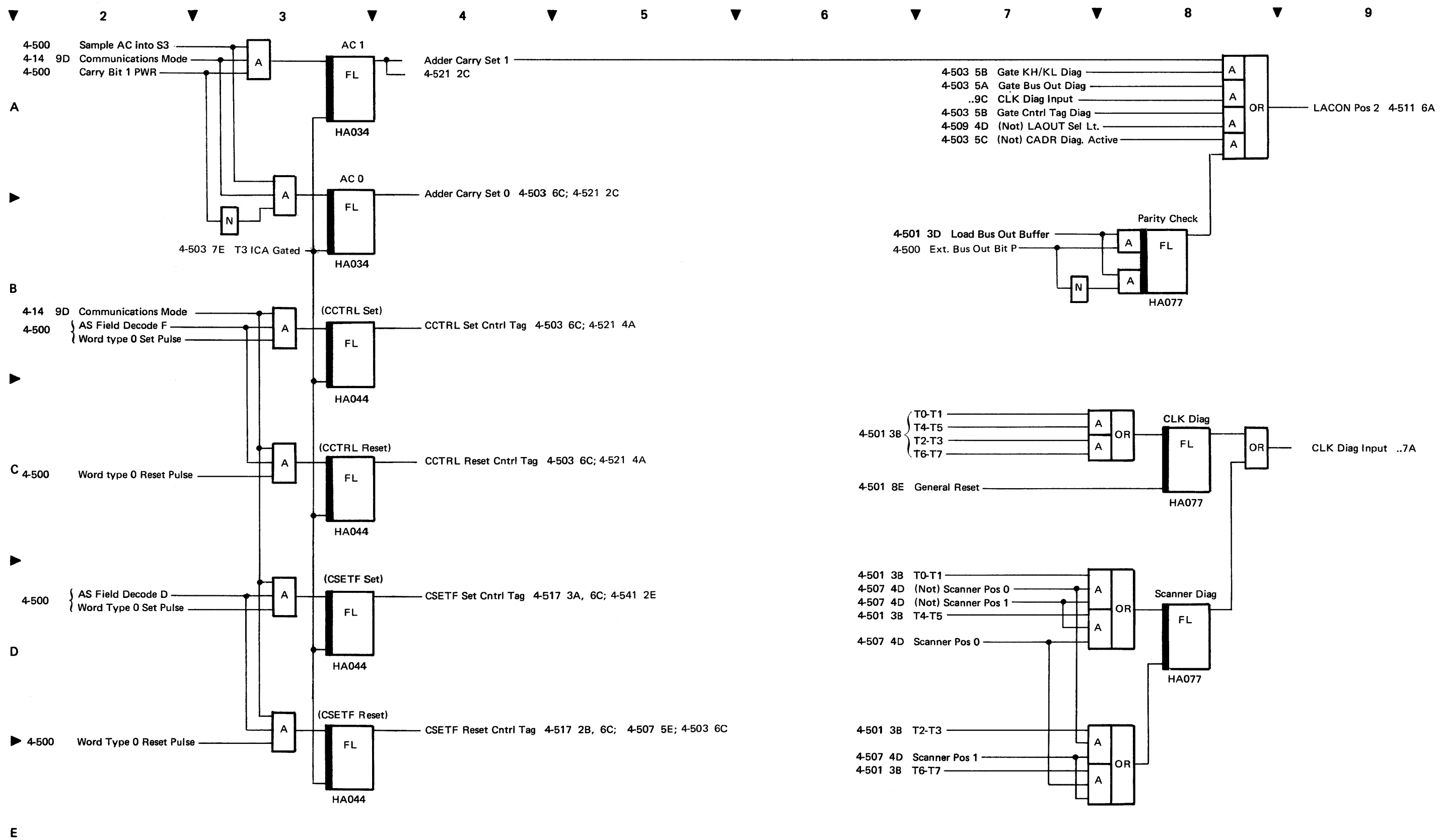
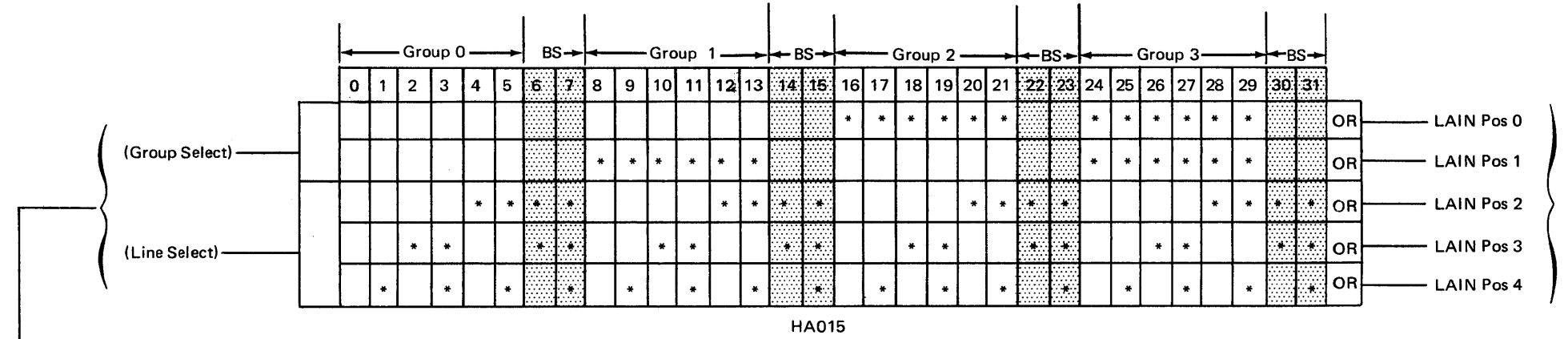


Diagram 4-505. Adder Carry, Set/Reset Word Control Tags, and LACON 2



2 3 4 5 6 7 8 9

A
B
C
D
E



4-47 4A

Note 1: Refer to ALD Logic HA000 for jumpering

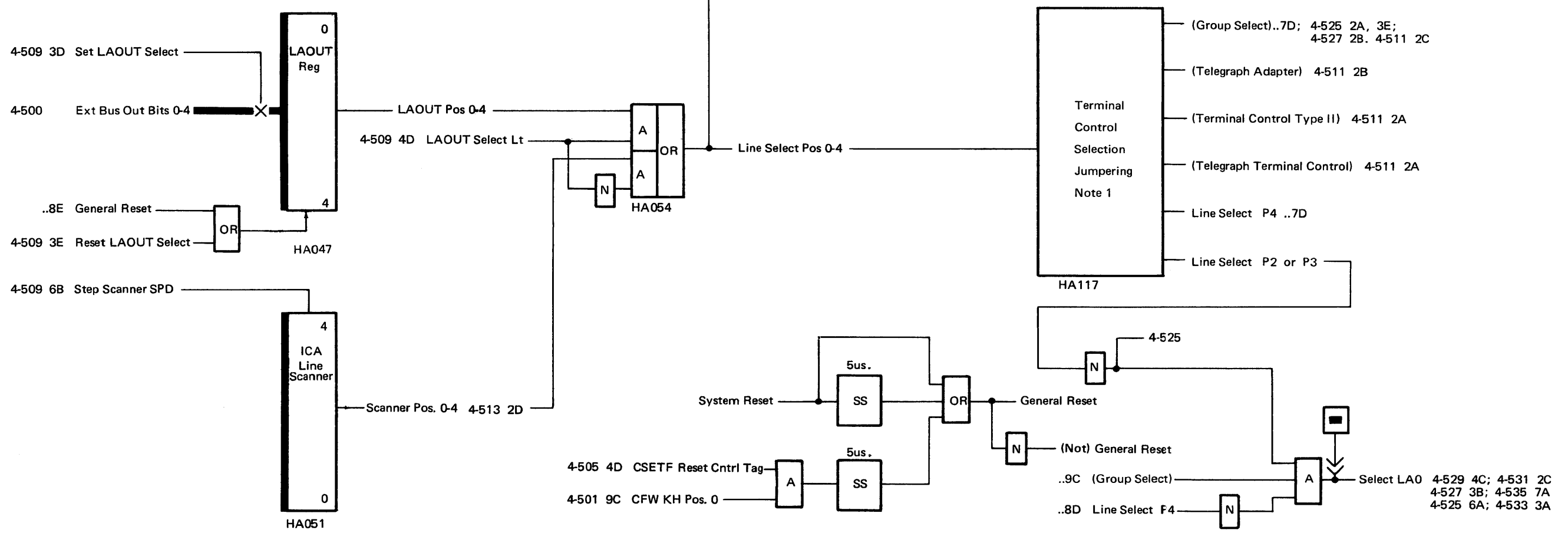
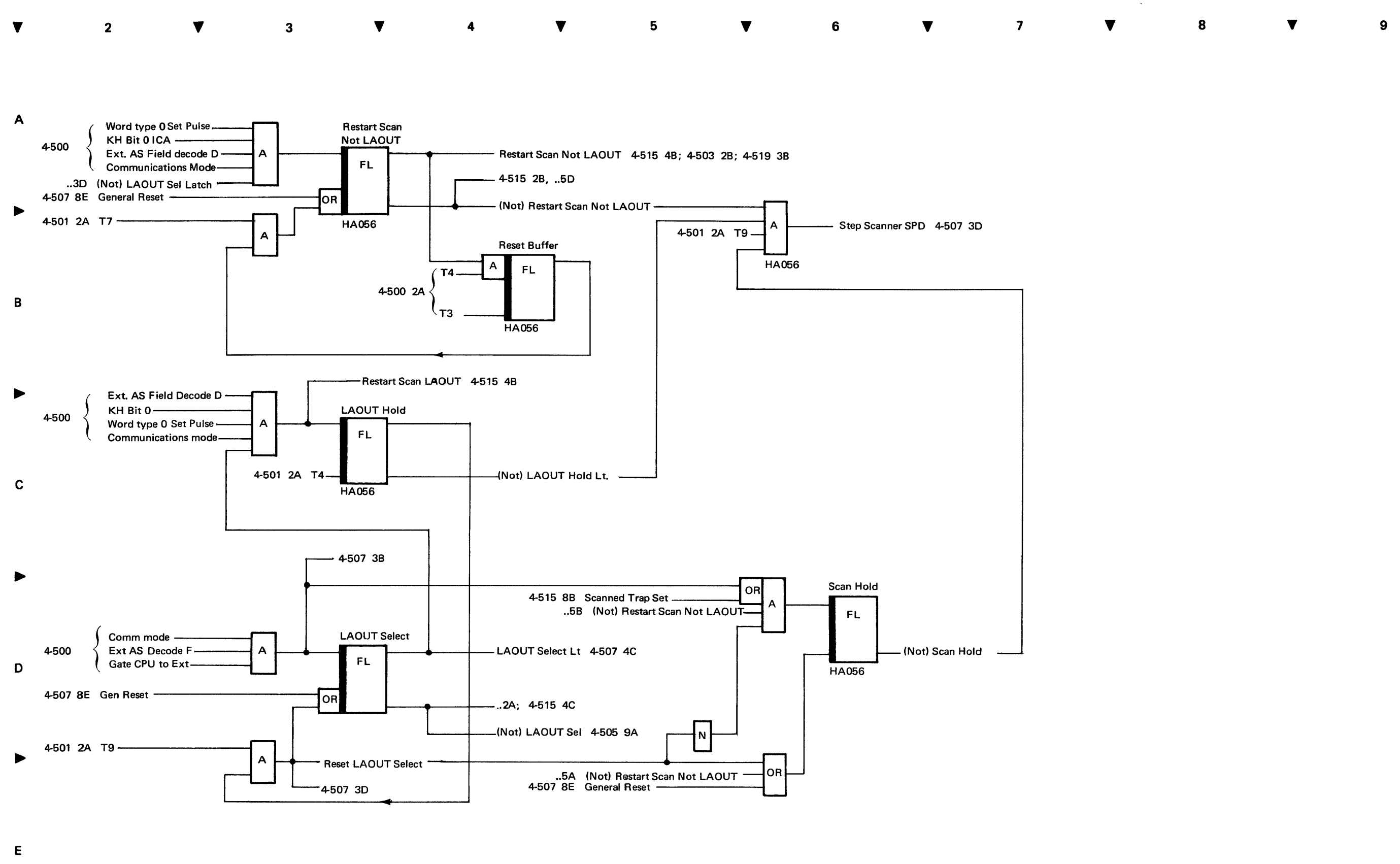


Diagram 4-509. Line Scanner Controls



▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6 ▼ 7 ▼ 8 ▼ 9

A

▲

B

▲

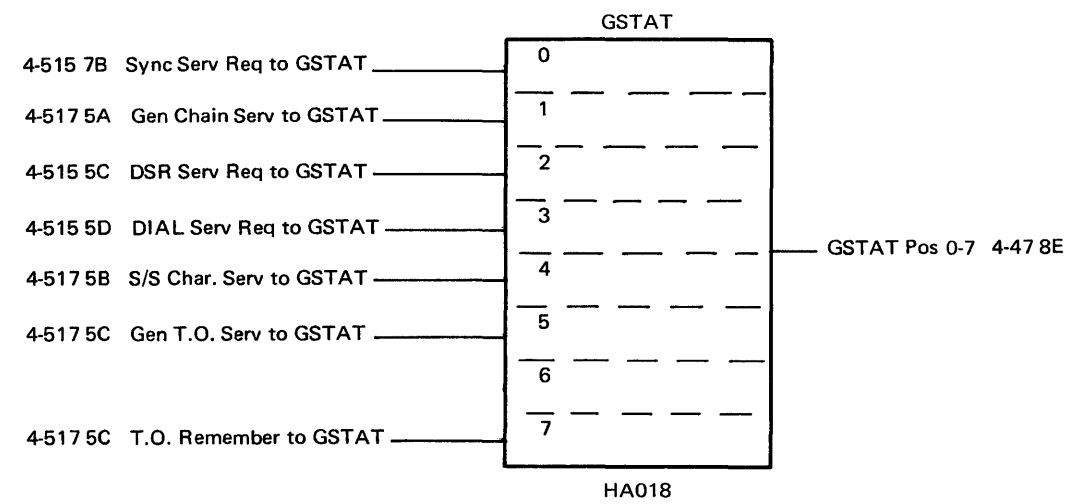
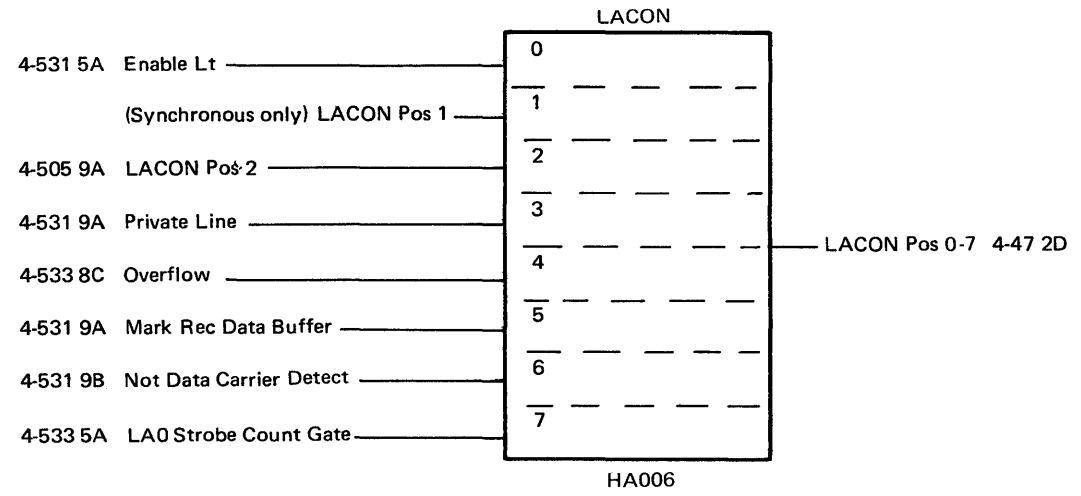
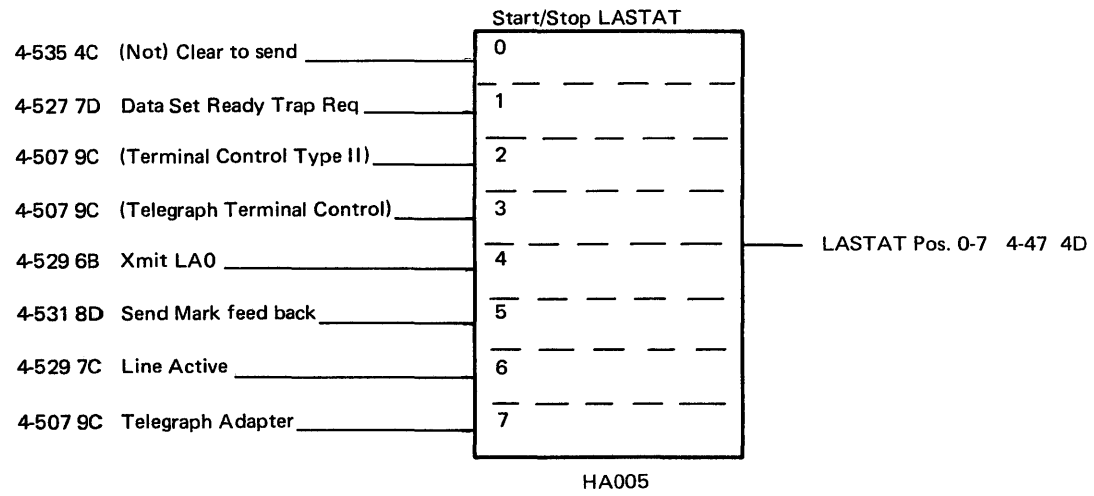
C

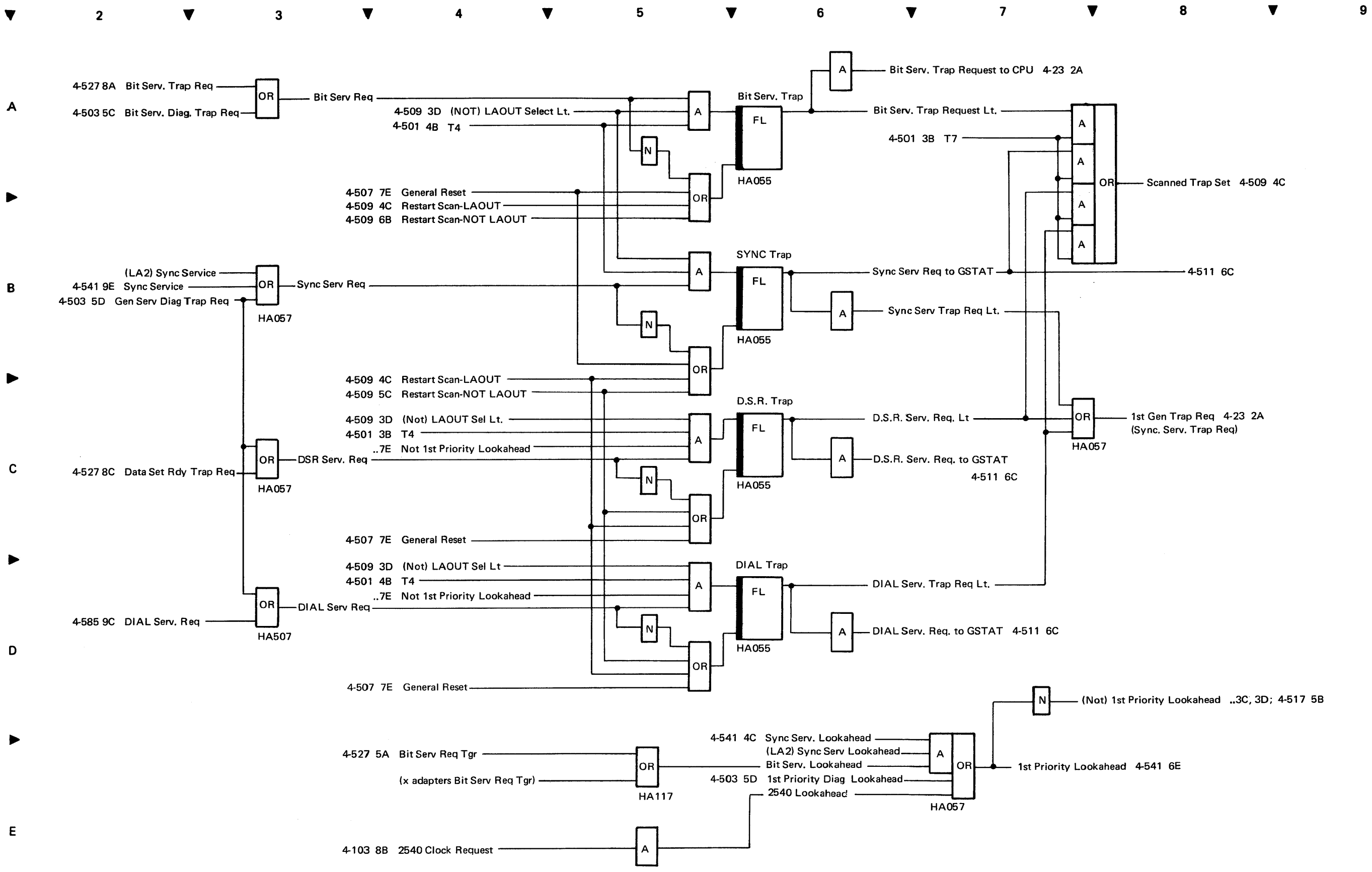
▲

D

▲

E





2 3 4 5 6 7 8 9

A

B

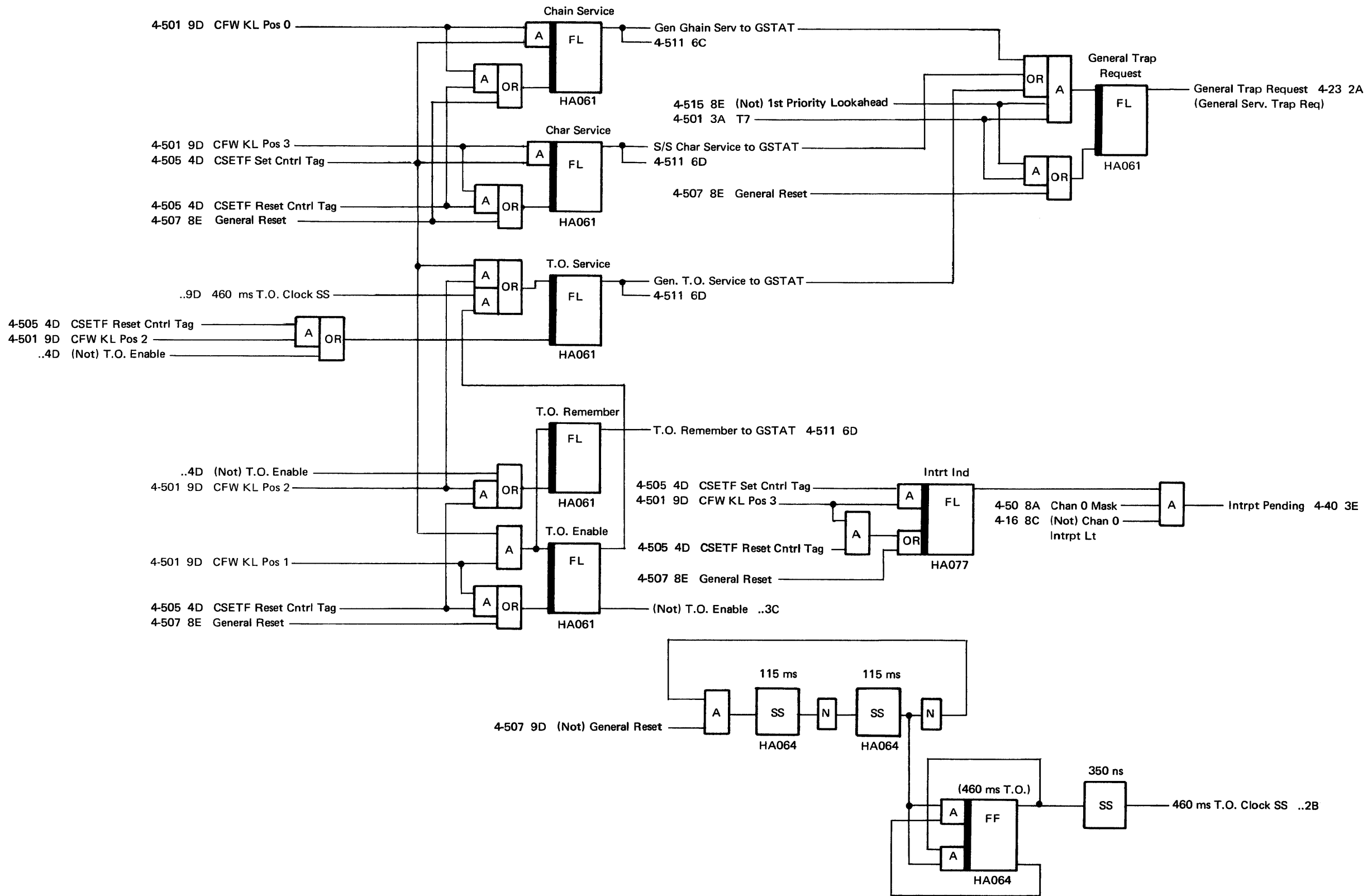
B

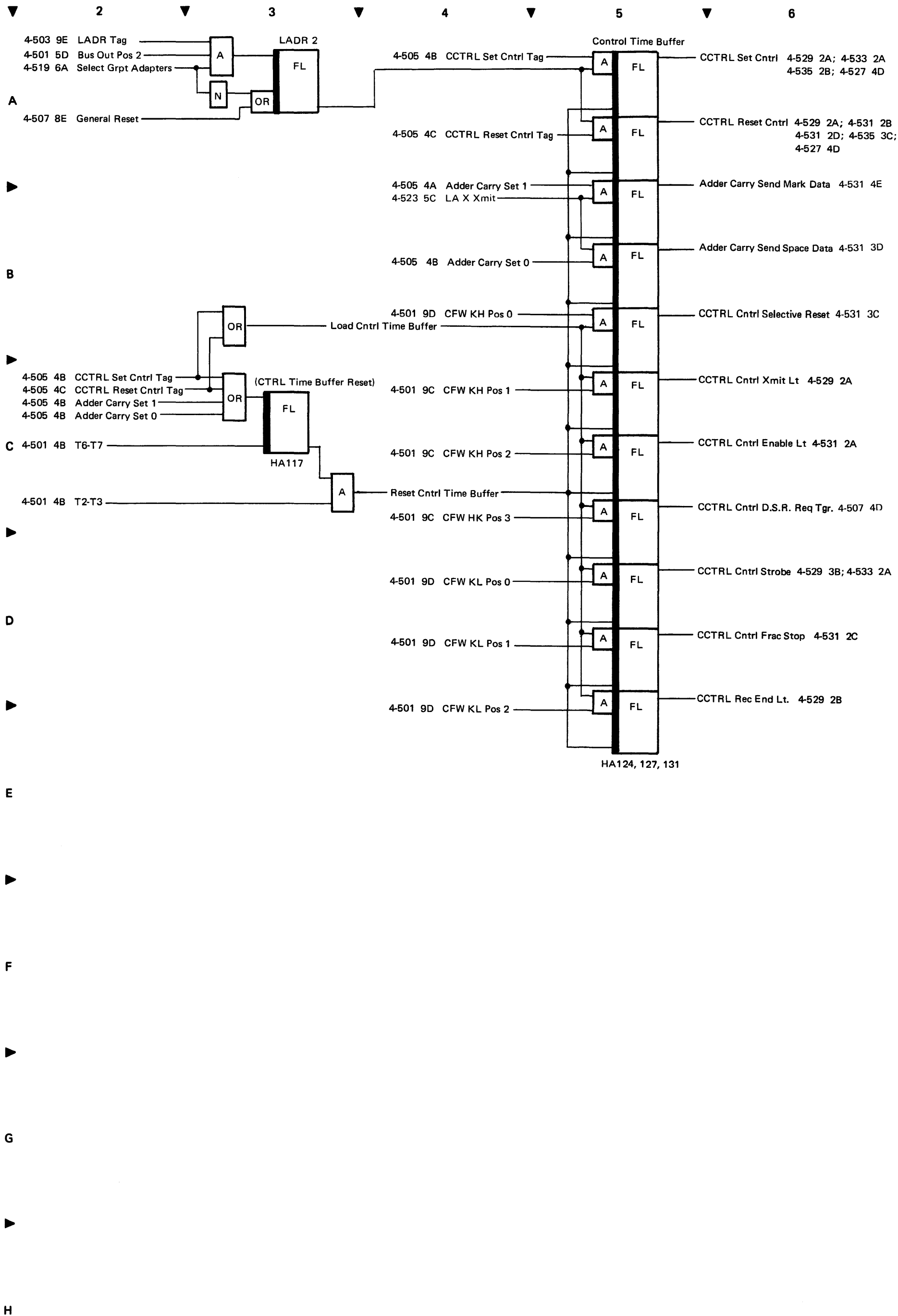
C

D

D

E

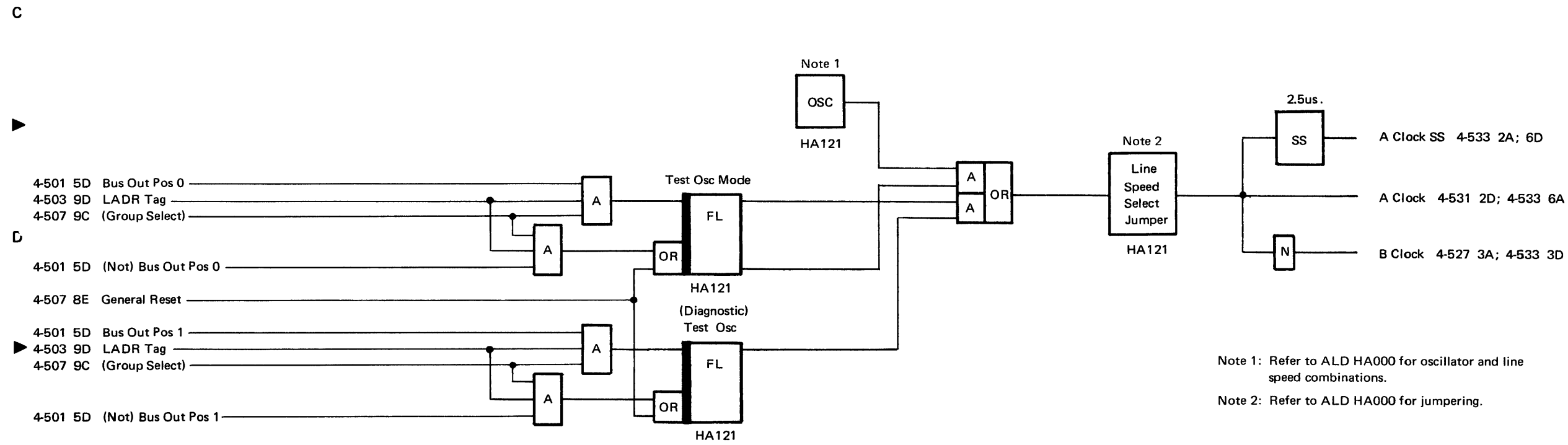
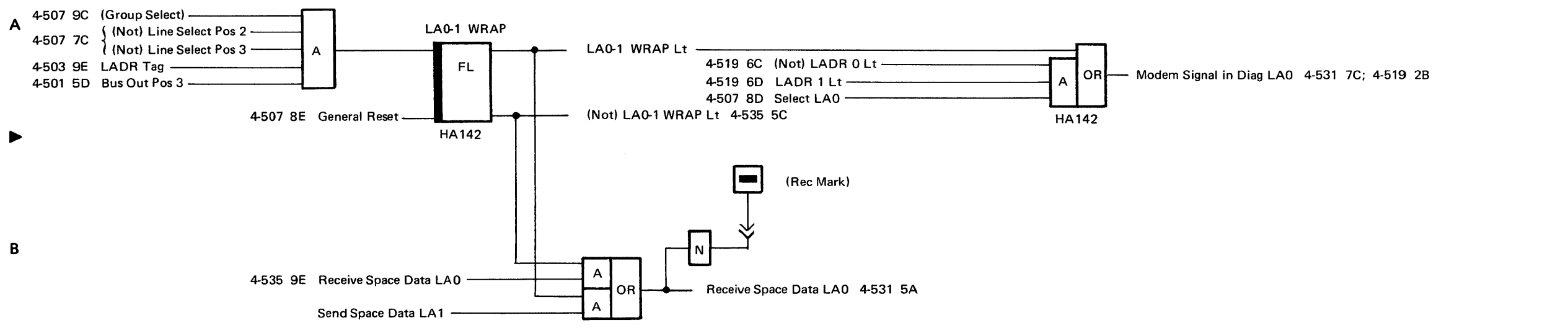




● Diagram 4-521. Control Tag Time Buffer

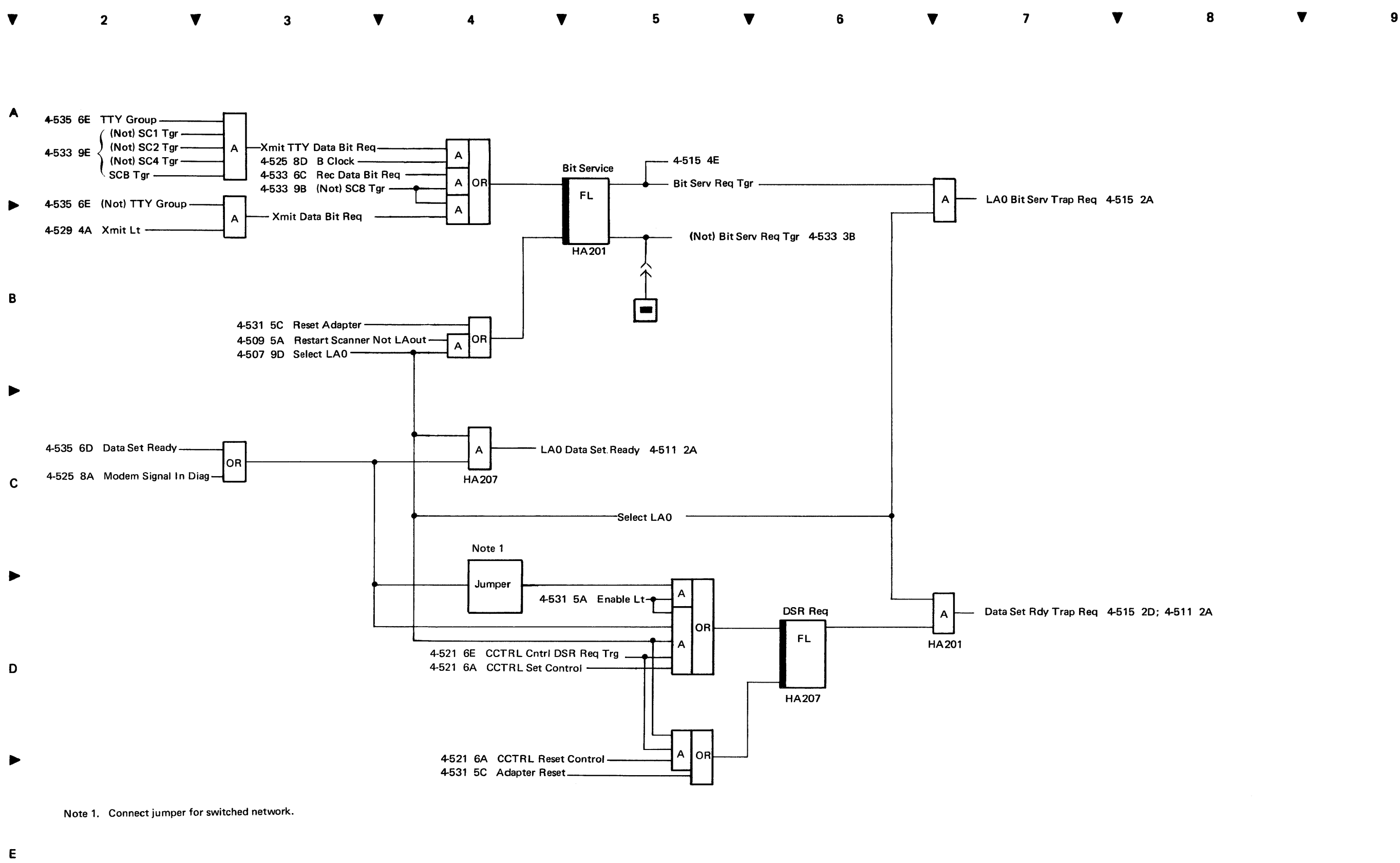
Diagram 4-525. Wrap Control and Data Modem Input

2 3 4 5 6 7 8 9

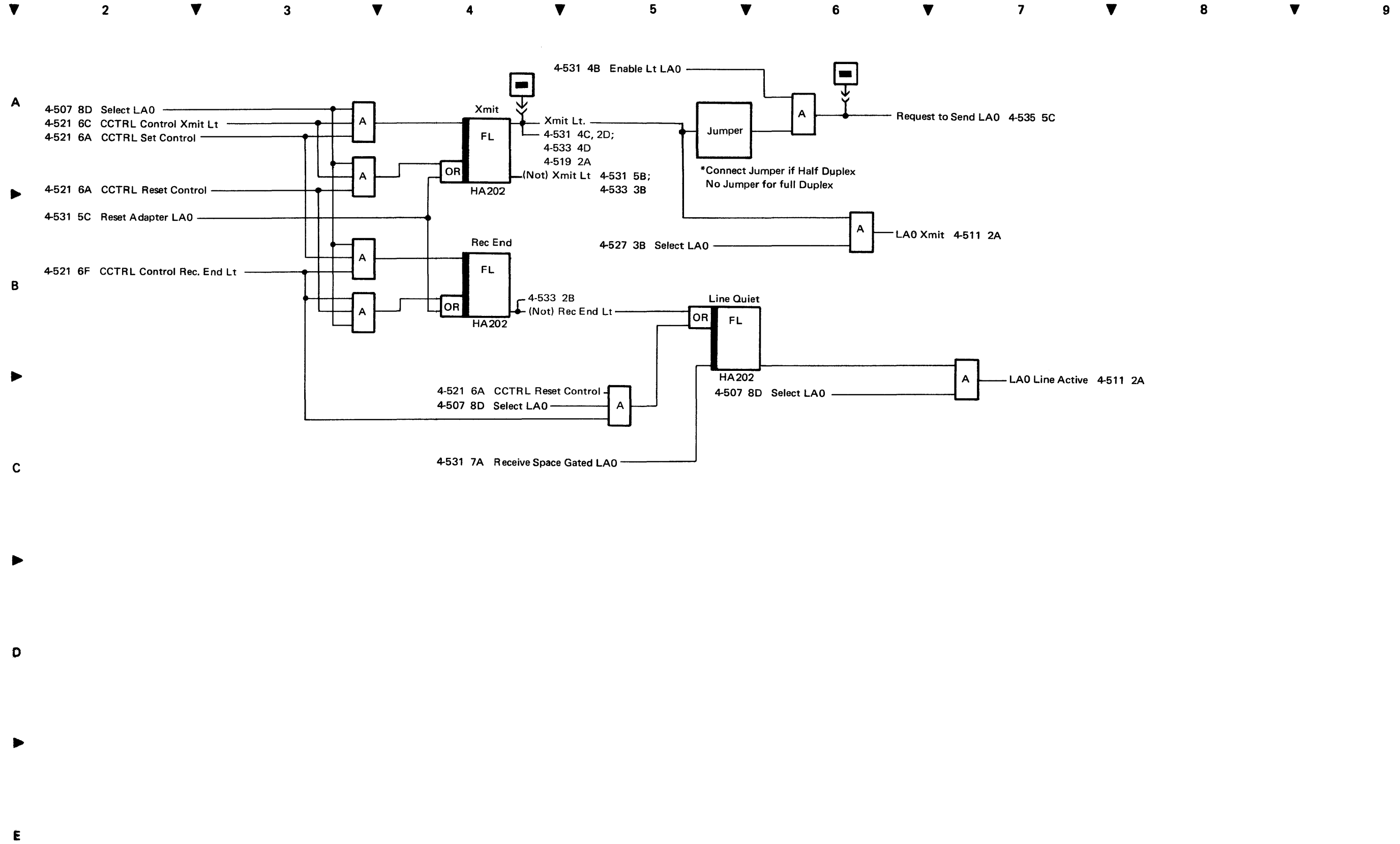


Note 1: Refer to ALD HA000 for oscillator and line speed combinations.
 Note 2: Refer to ALD HA000 for jumpering.

Diagram 4-527. Bit Service Request and Data Set Ready Request



● Diagram 4-529. Start/Stop Xmit Latch and Line Quiet Controls



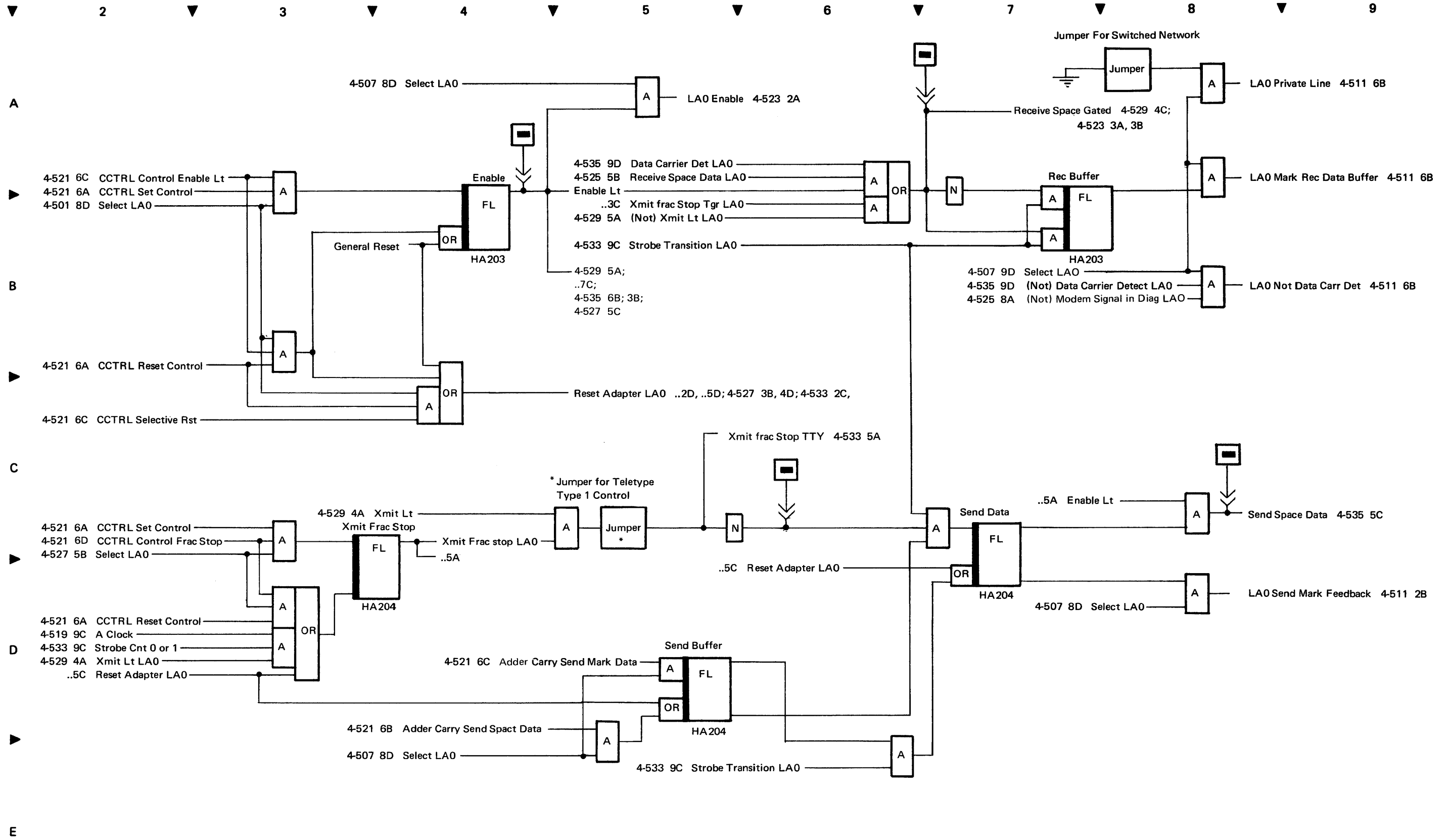


Diagram 4-533. Start/Stop Line Adapter Strobe Counter and Controls

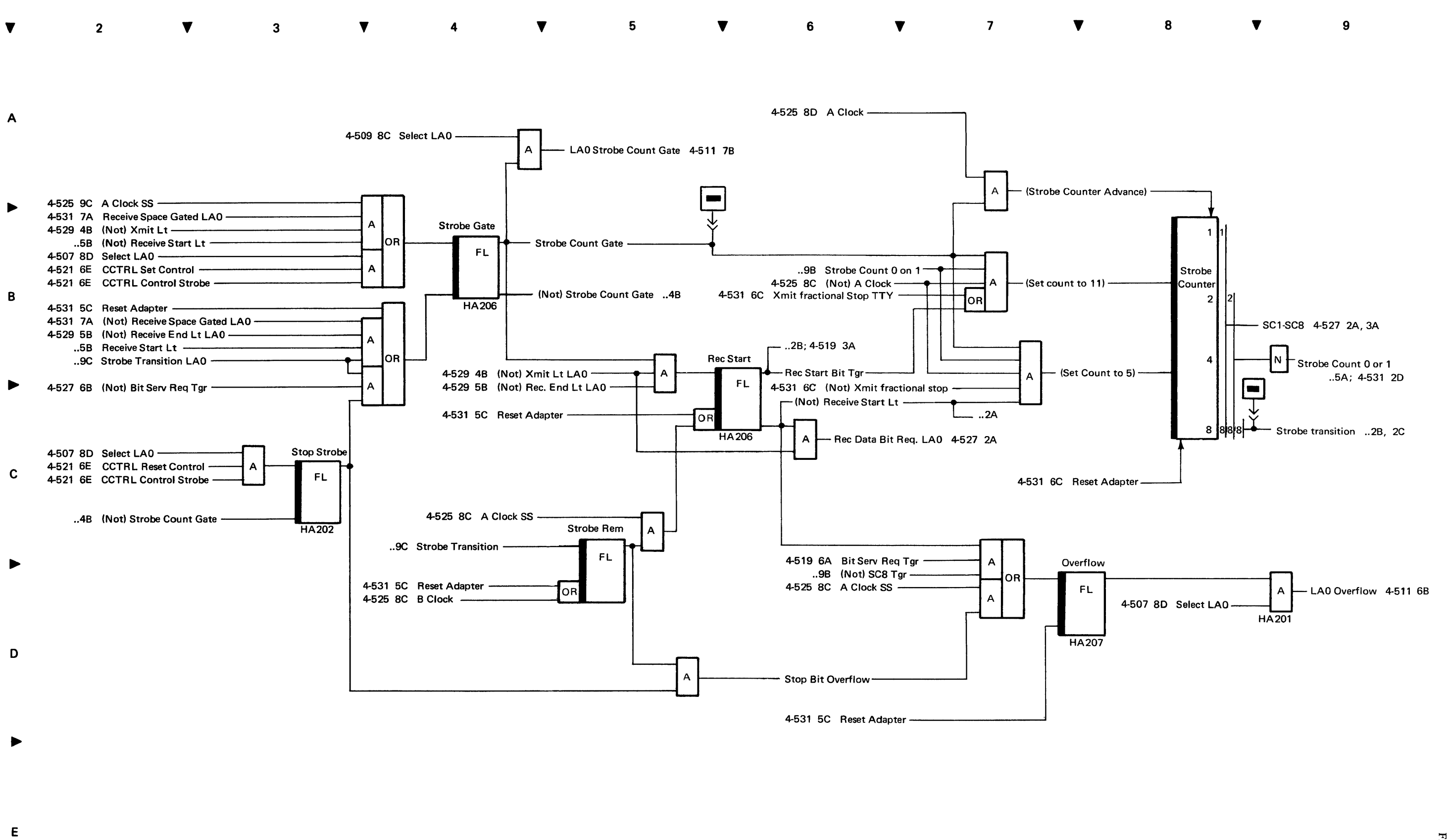


Diagram 4-535. Start/Stop EIA and Telegraph Interface

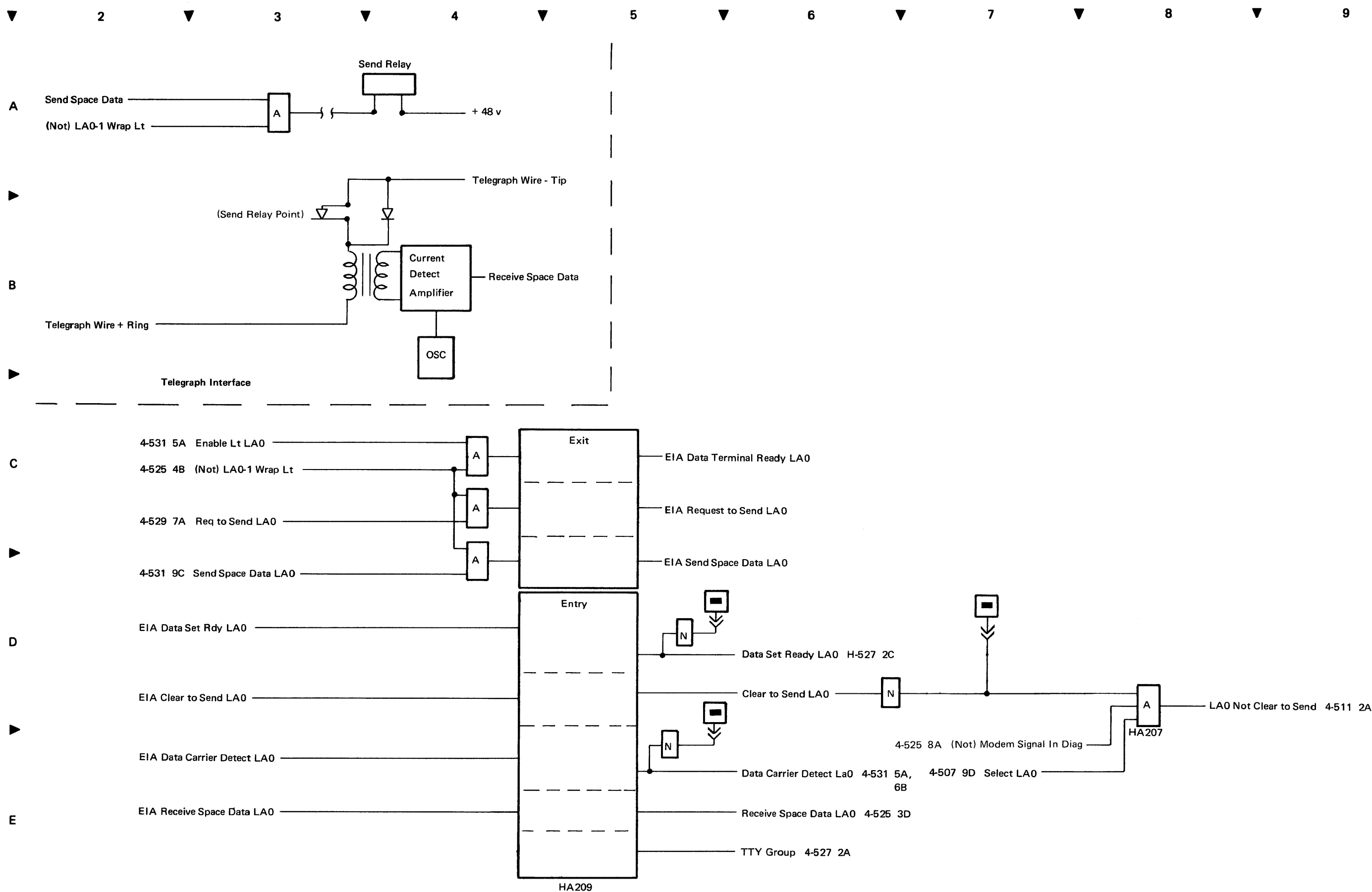
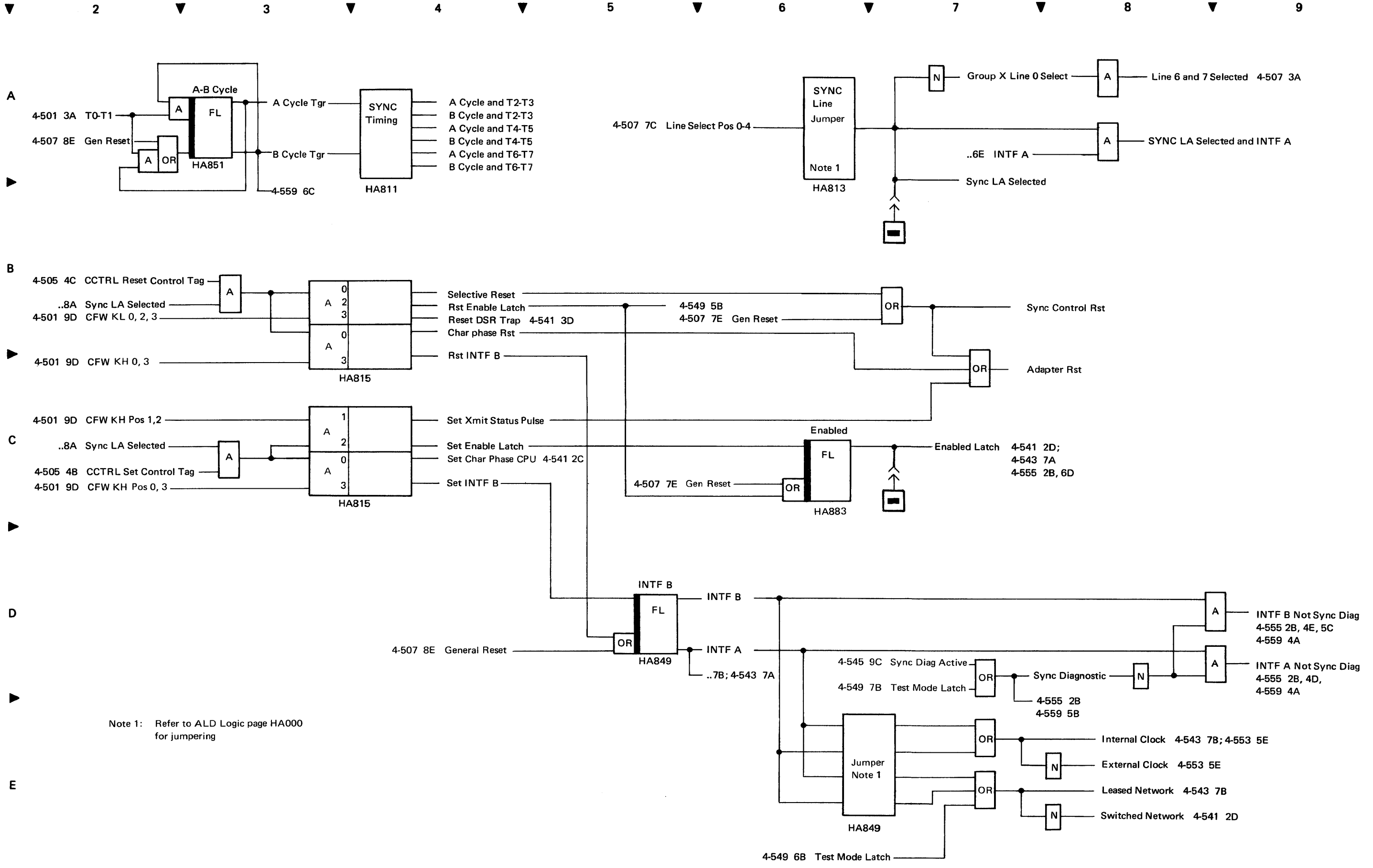


Diagram 4-537. Sync Timing and Line Adapter Selection



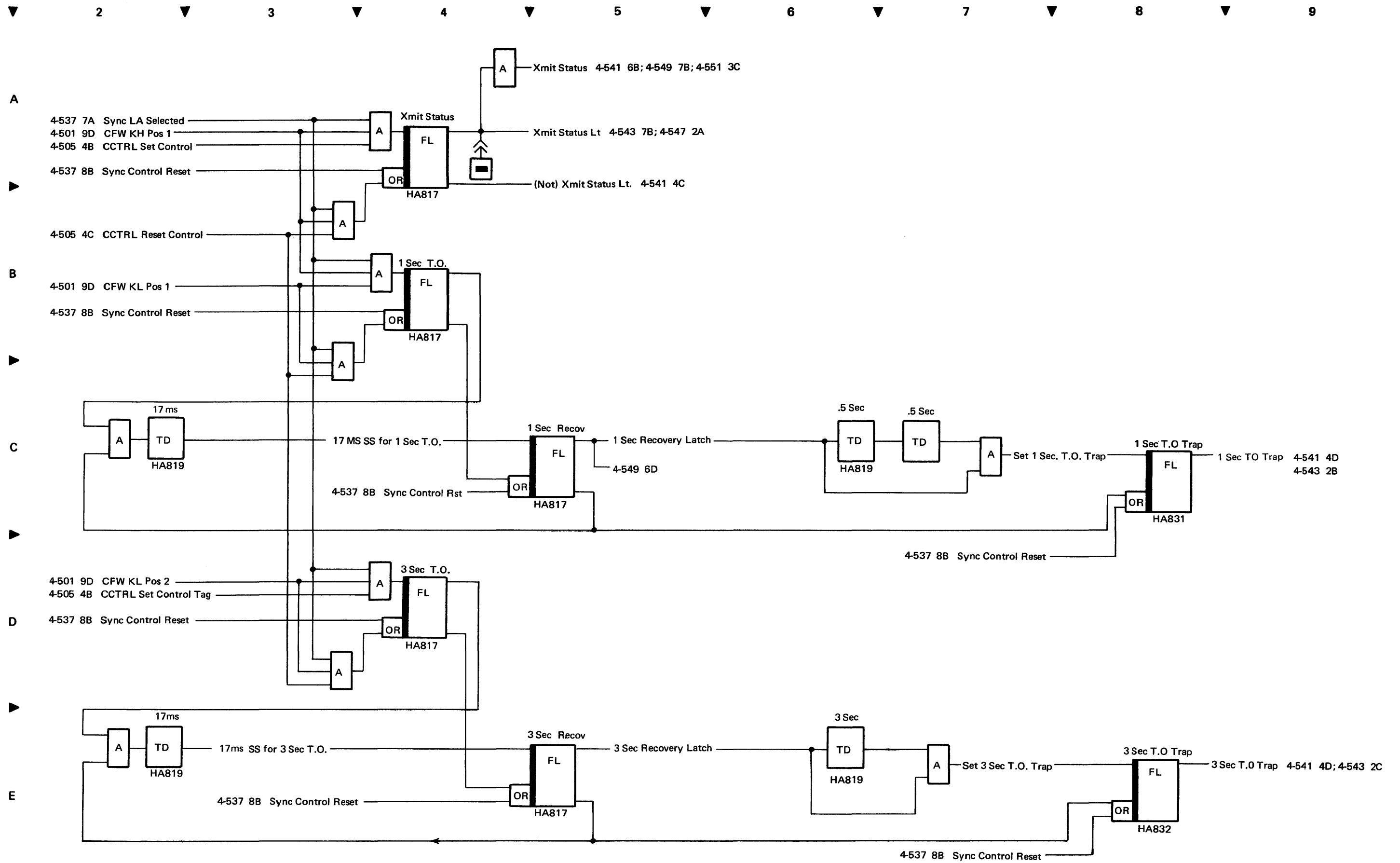


Diagram 4-541. Sync Traps

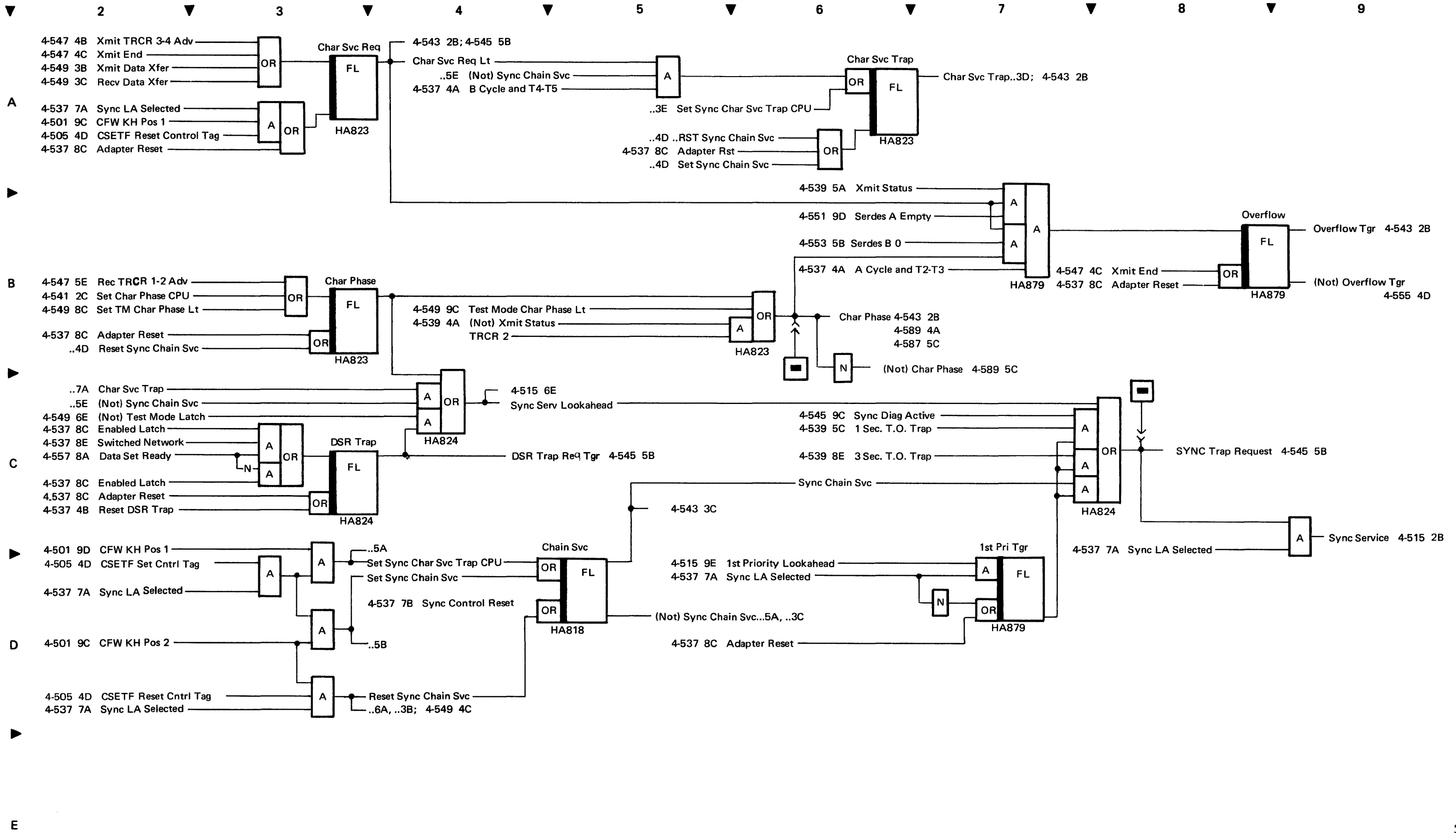


Diagram 4-543. Sync LASTAT and LACON

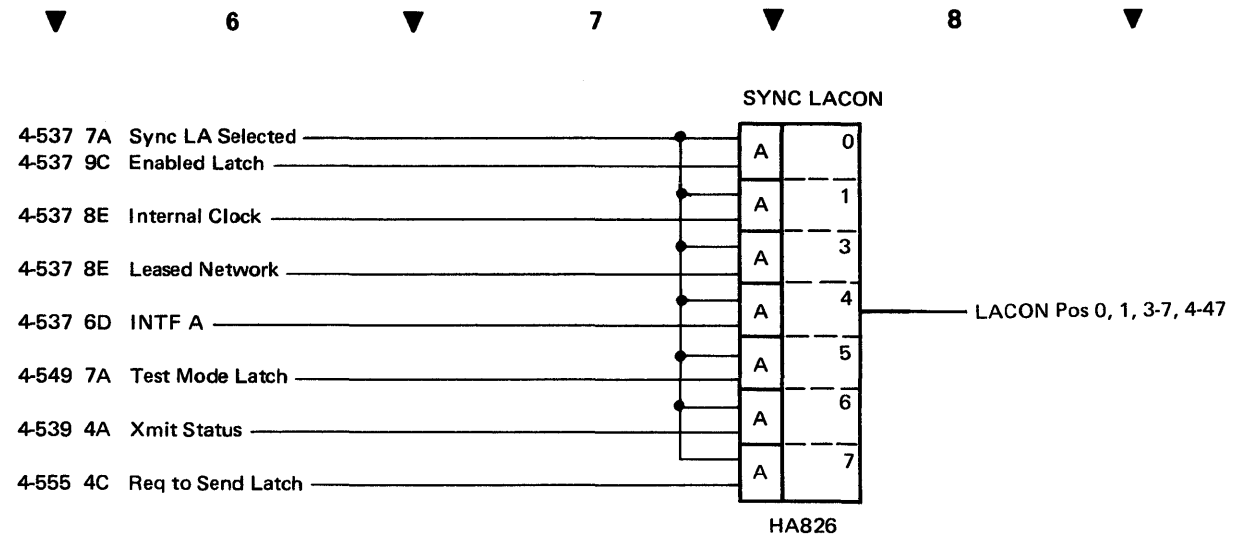
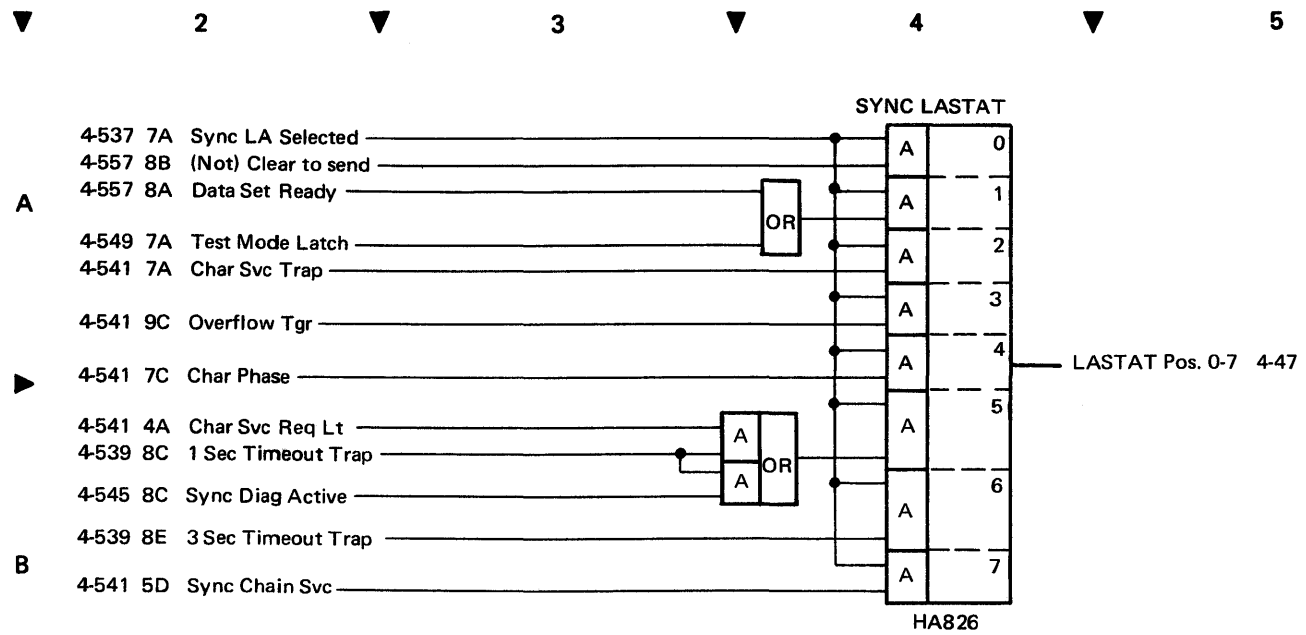


Diagram 4-545. Sync DAIN Bus and Sync LADR

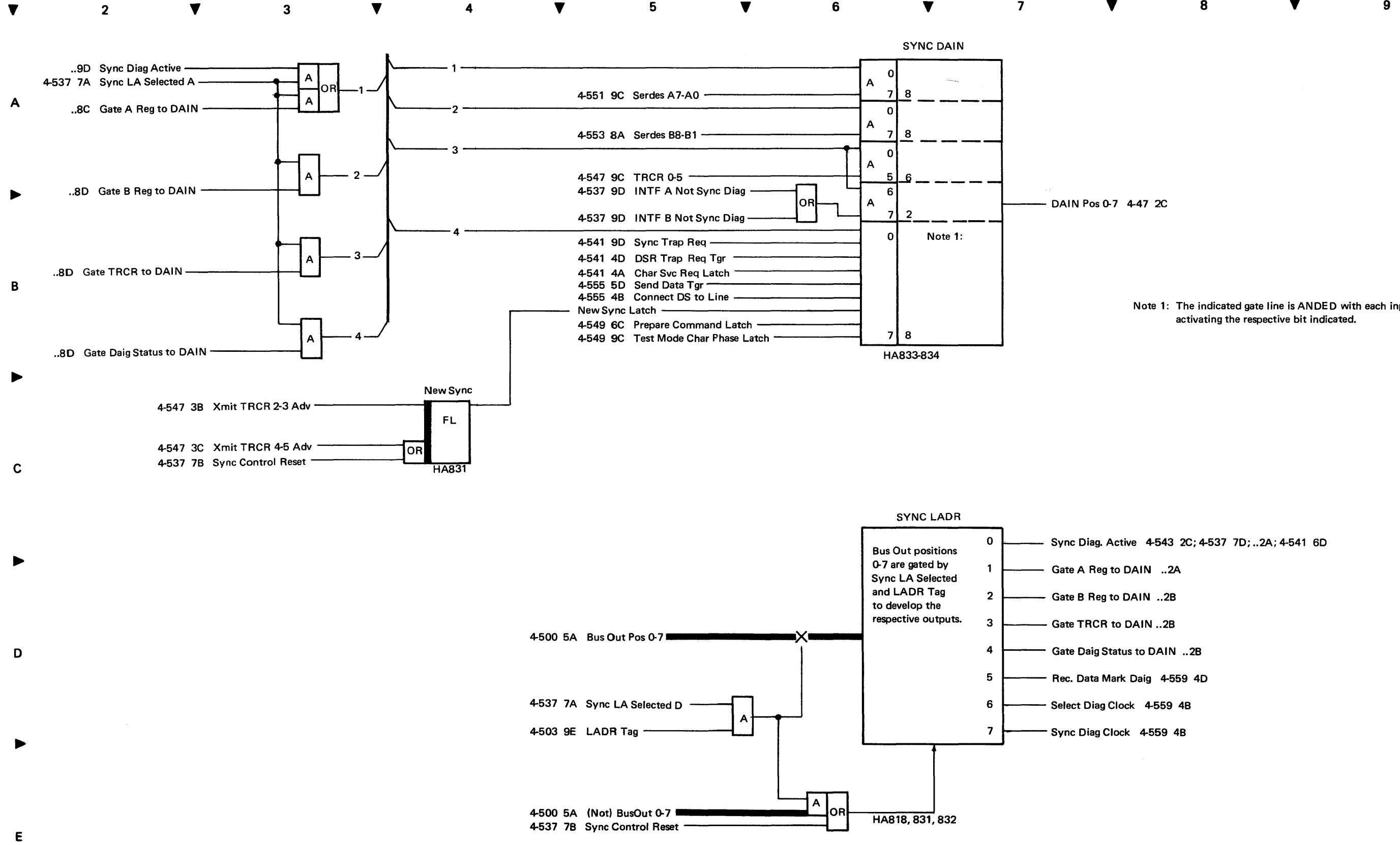


Diagram 4-547. Sync Transmit Receive Control Register (TRCR)

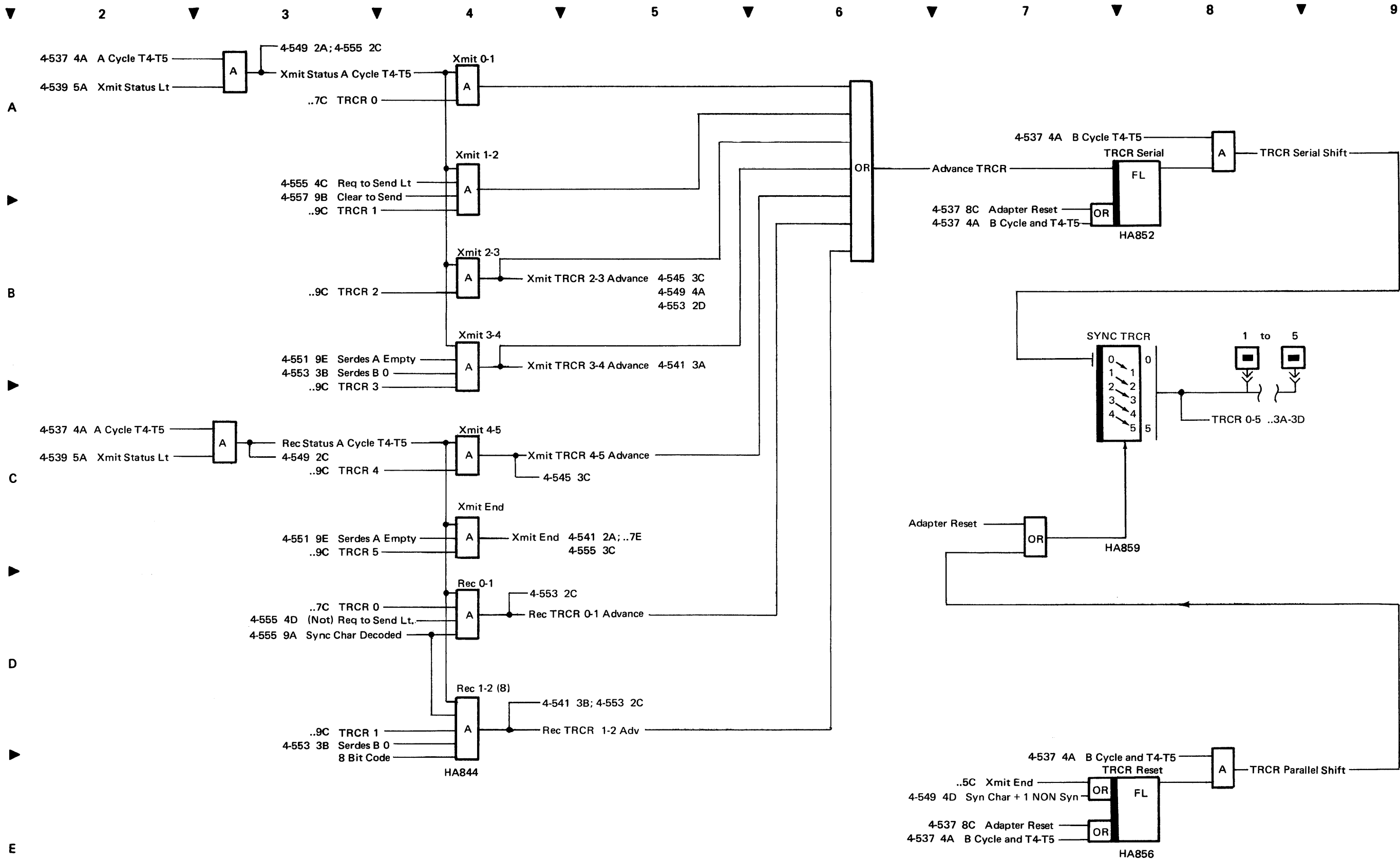
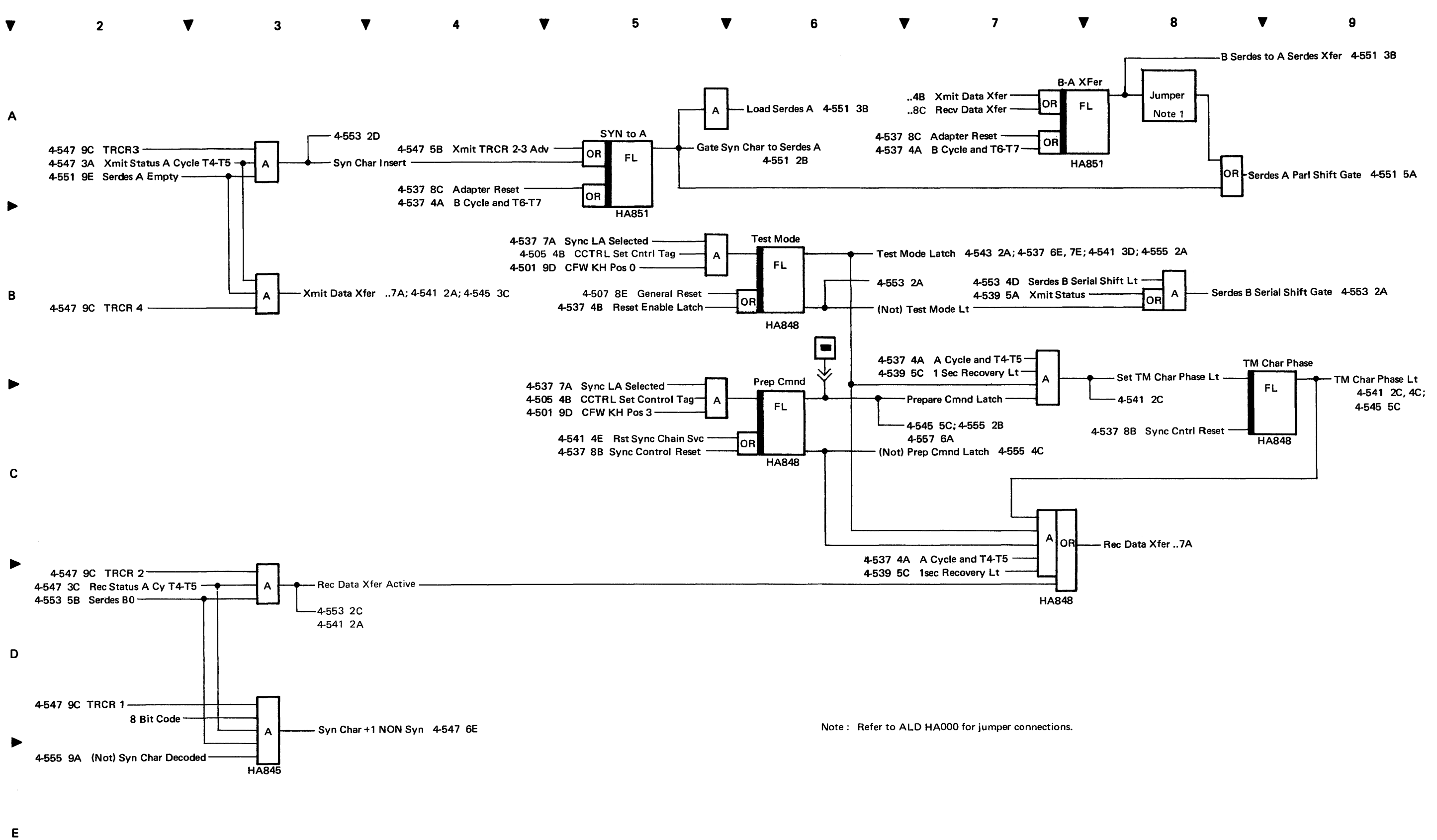
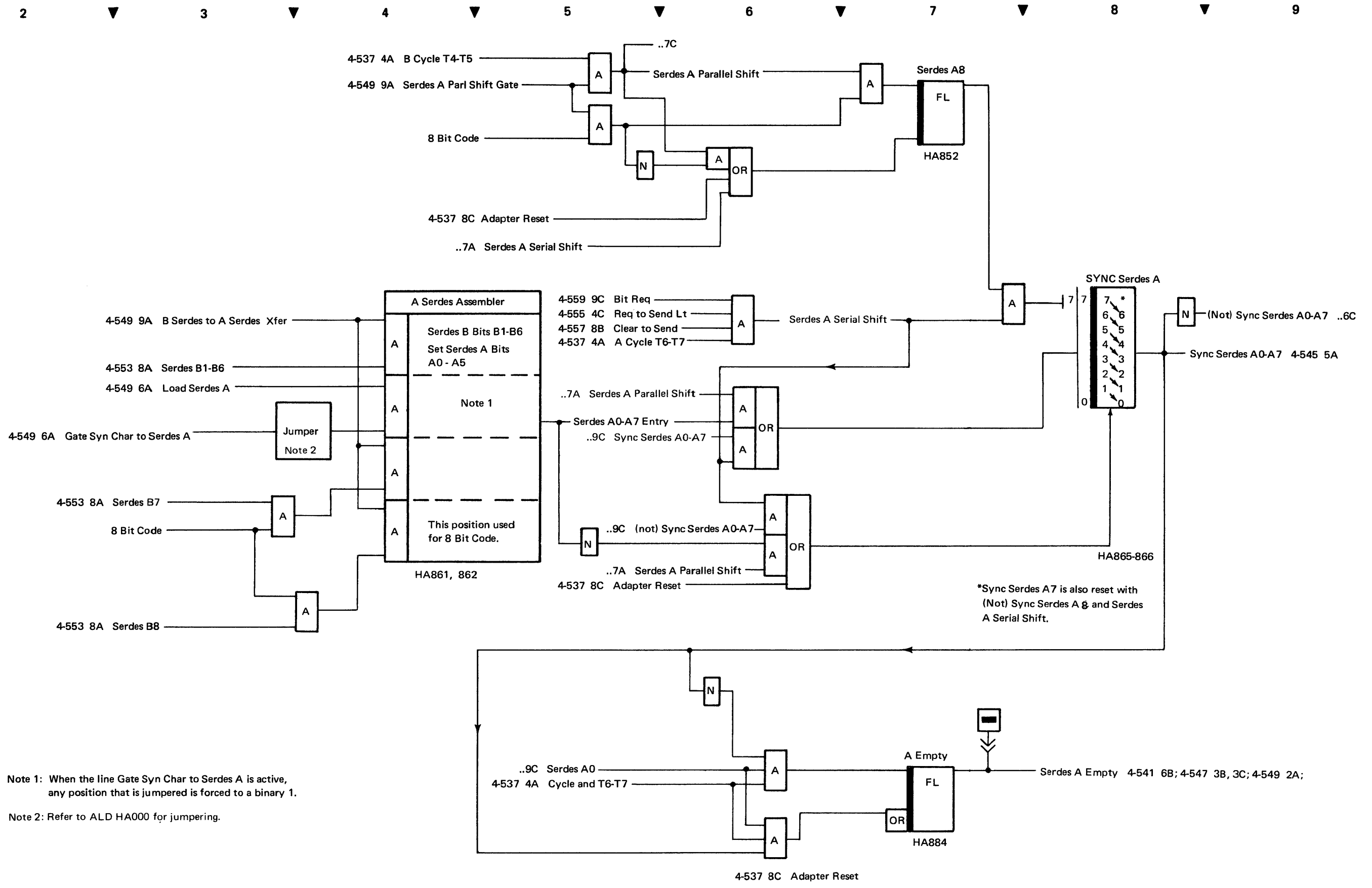


Diagram 4-549. Sync Xmit-Receive and Sync Test Mode Control





2
3
4
5
6
7
8
9

Note 1: When the line Gate Syn Char to Serdes A is active, any position that is jumpered is forced to a binary 1.

Note 2: Refer to ALD HA000 for jumpering.

*Sync Serdes A7 is also reset with (Not) Sync Serdes A 8 and Serdes A Serial Shift.

Diagram 4-553. Sync B Serdes and B Serdes Assembler

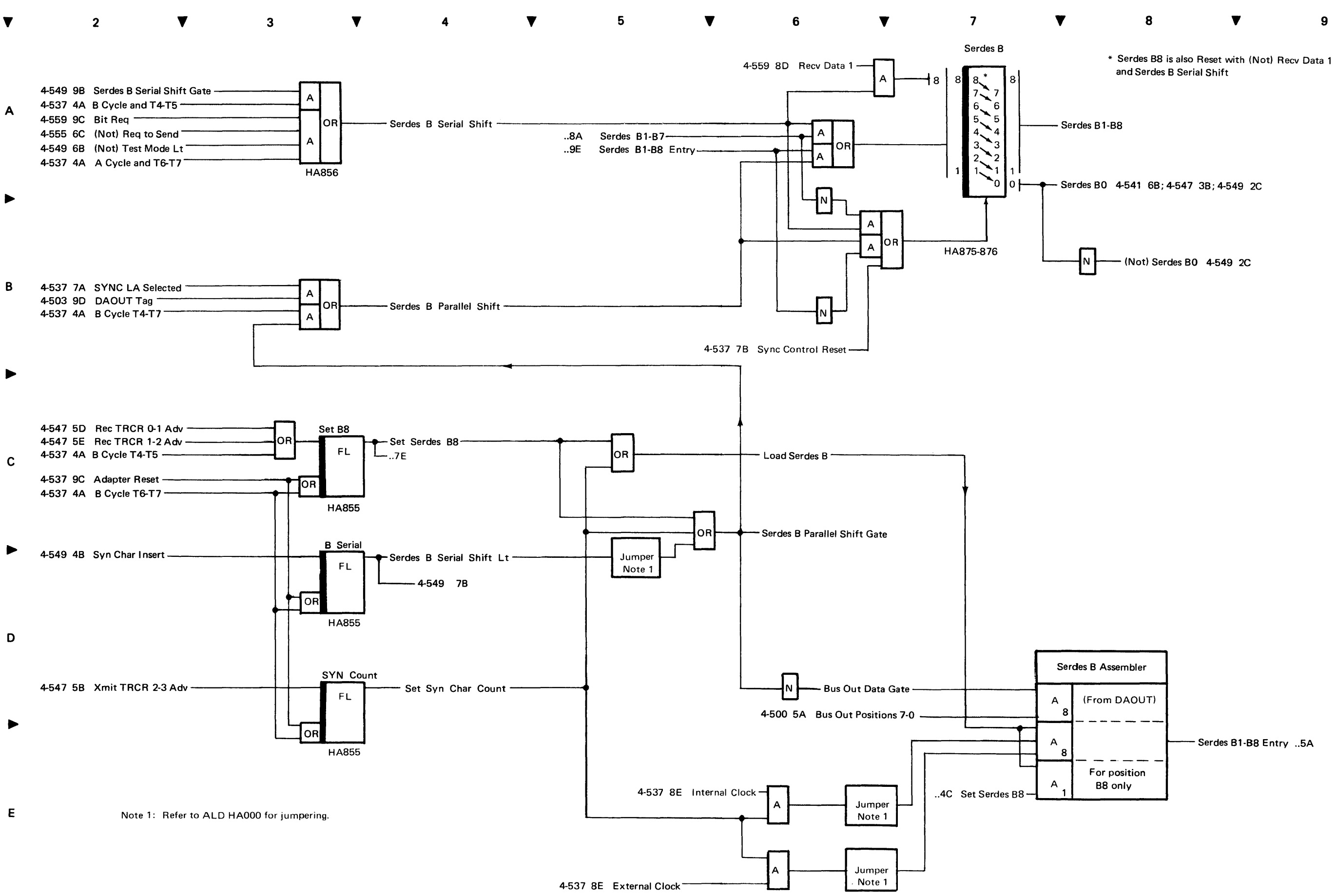


Diagram 4-555. Sync Request to Send, Send Data, and SYN Character Decode

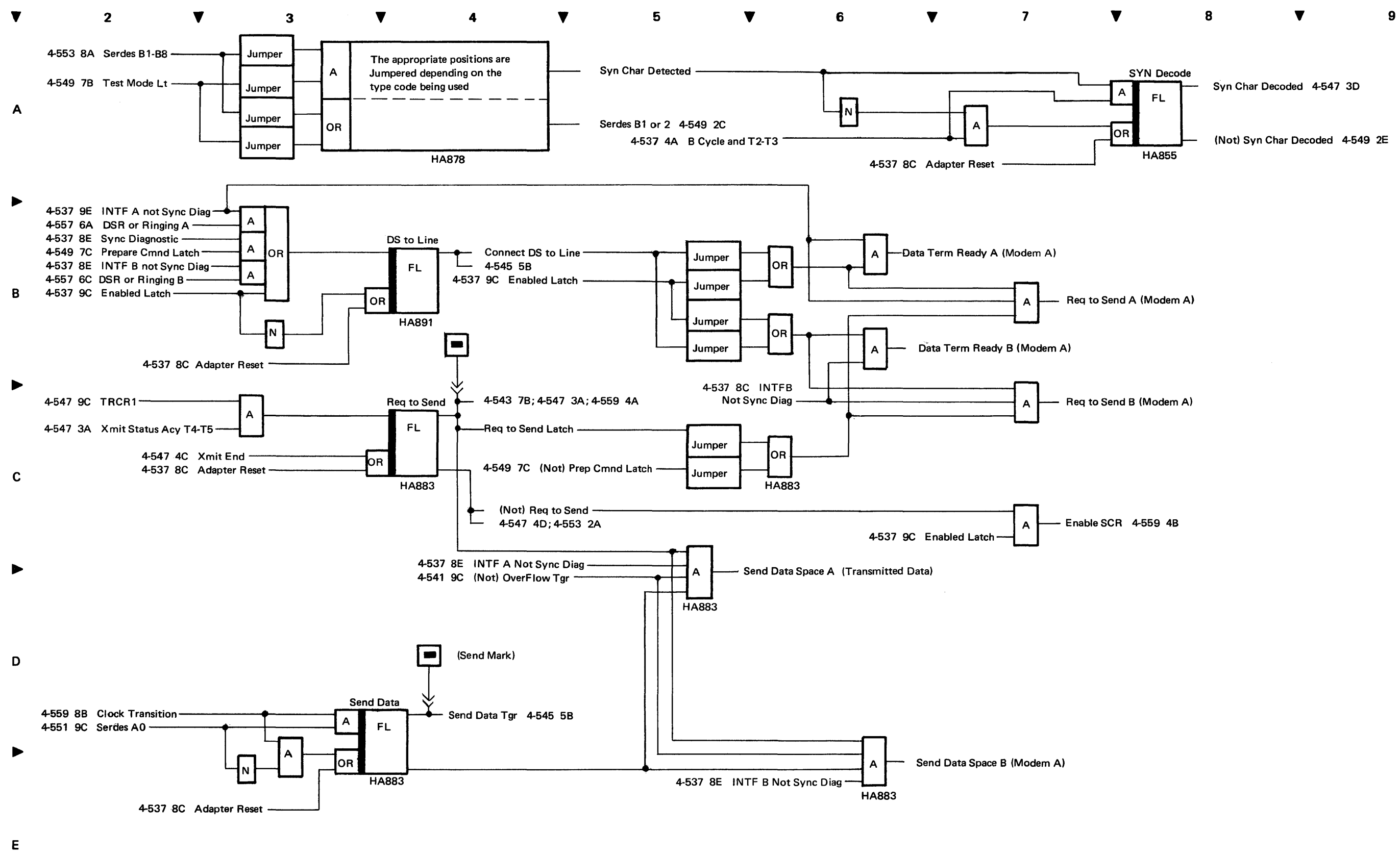


Diagram 4-557. Sync Data Set Interface

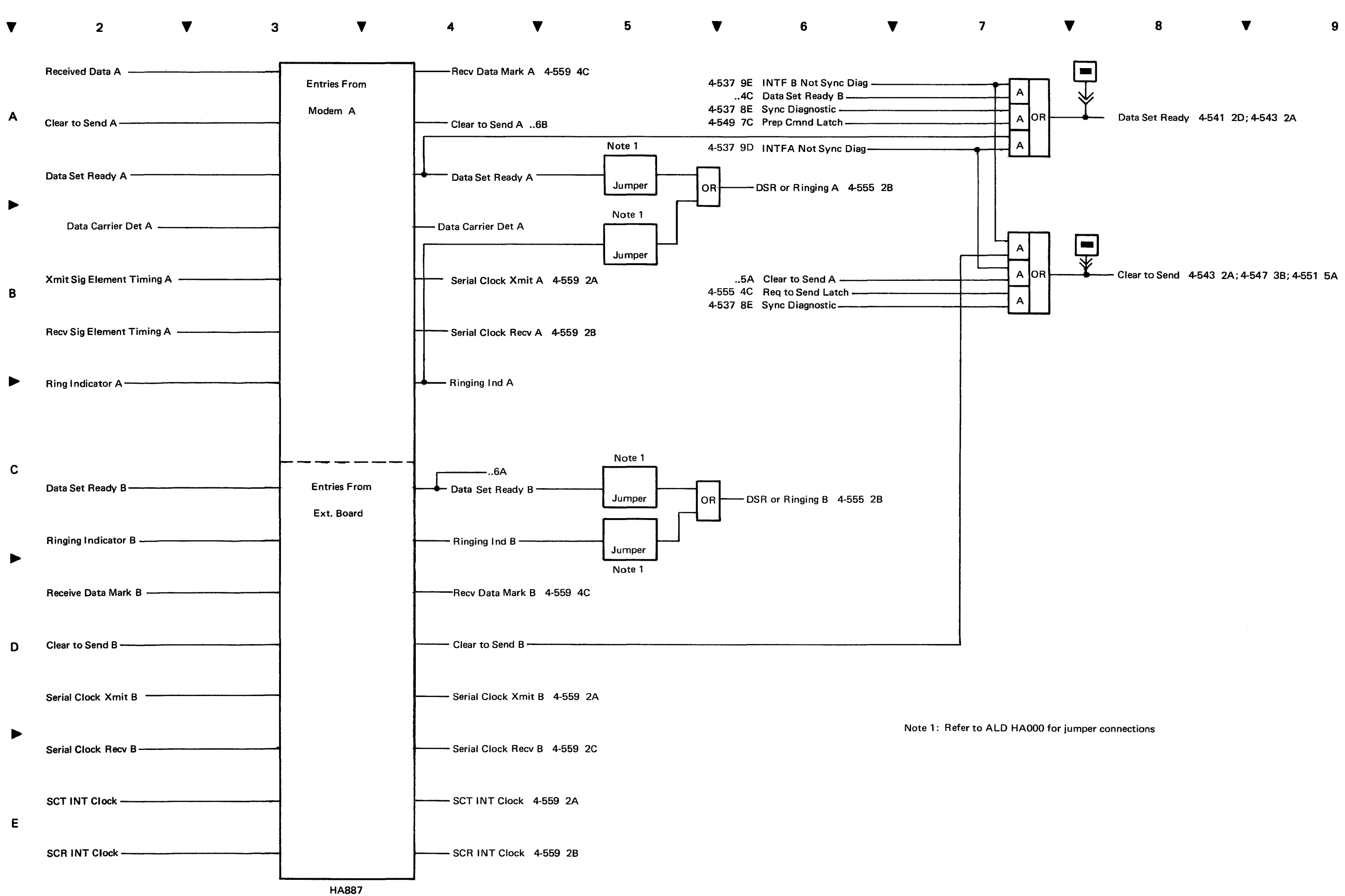
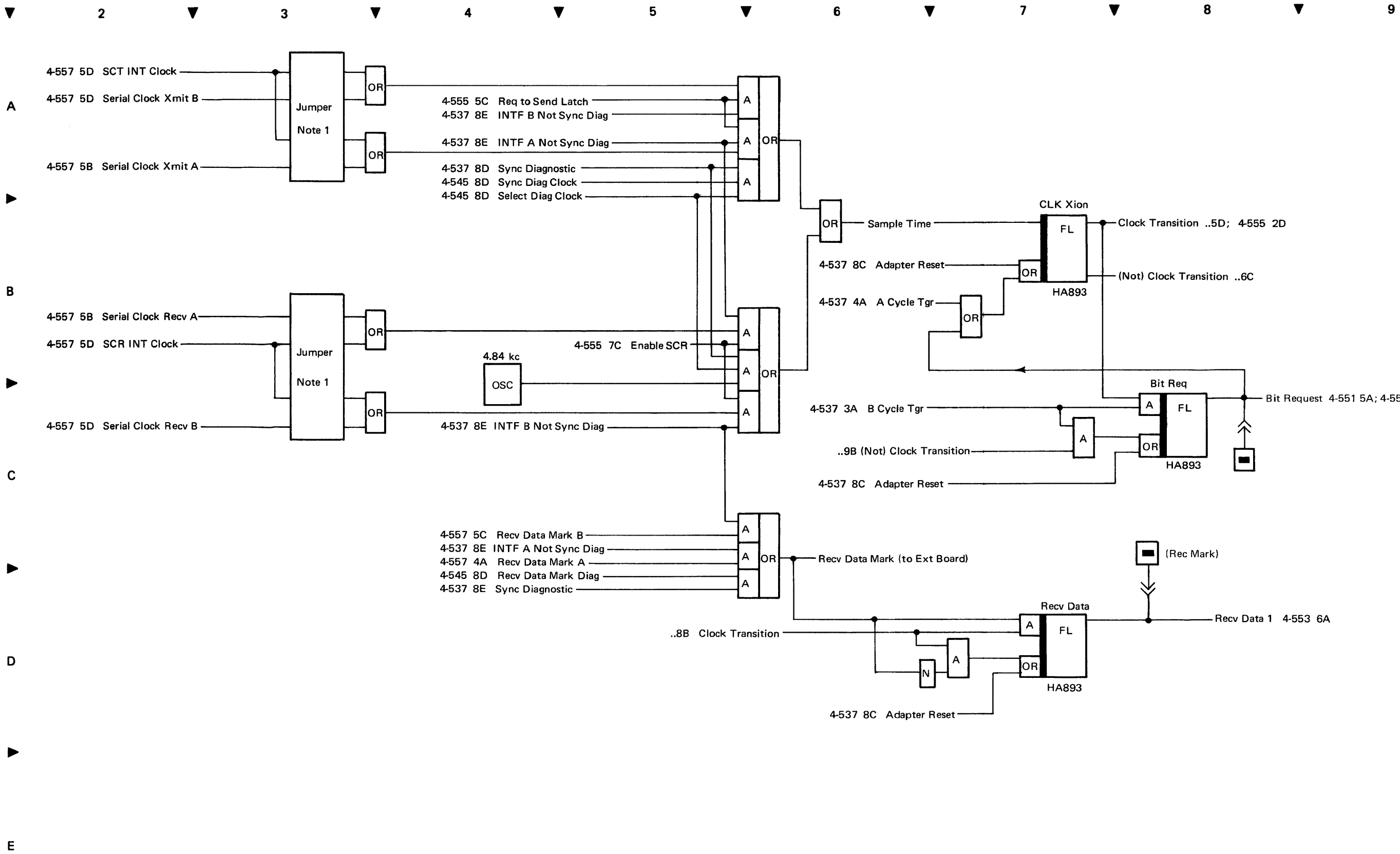
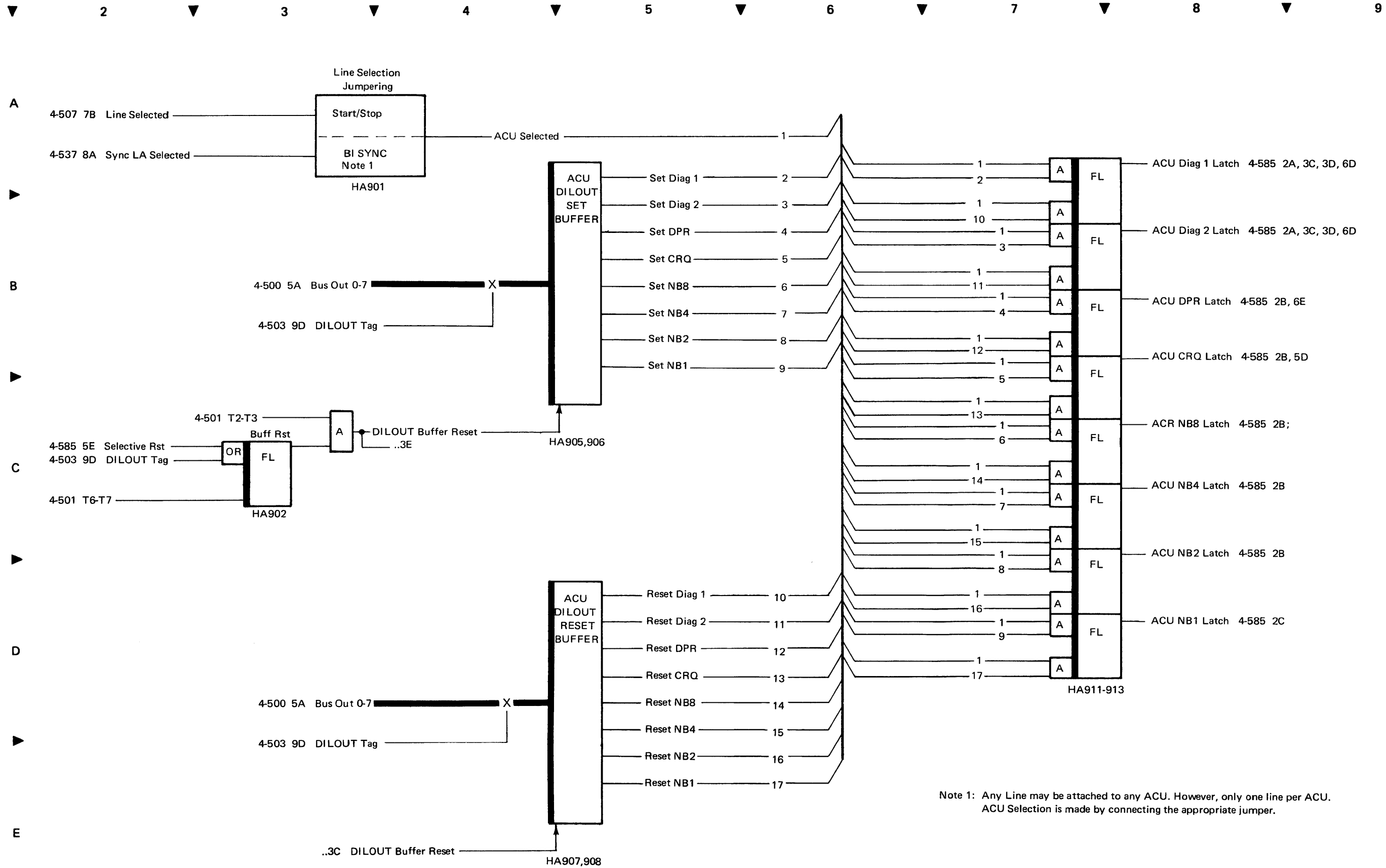


Diagram 4-559. Sync Data Set Clock Control



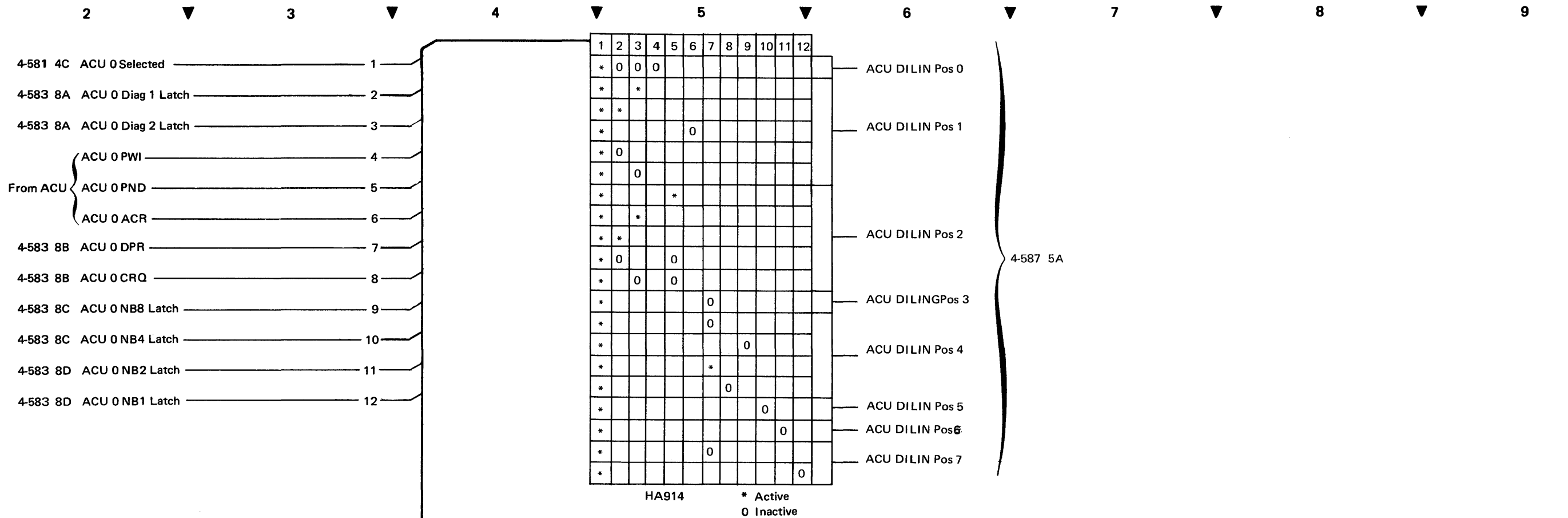
Note 1: Refer to ALD Logic Page HA000 for Jumpering.

Diagram 4-583. Automatic Calling Unit (ACU) DILOUT Buffer



Note 1: Any Line may be attached to any ACU. However, only one line per ACU. ACU Selection is made by connecting the appropriate jumper.

Diagram 4-585. Automatic Calling Unit (ACU) DILIN and Trap Request



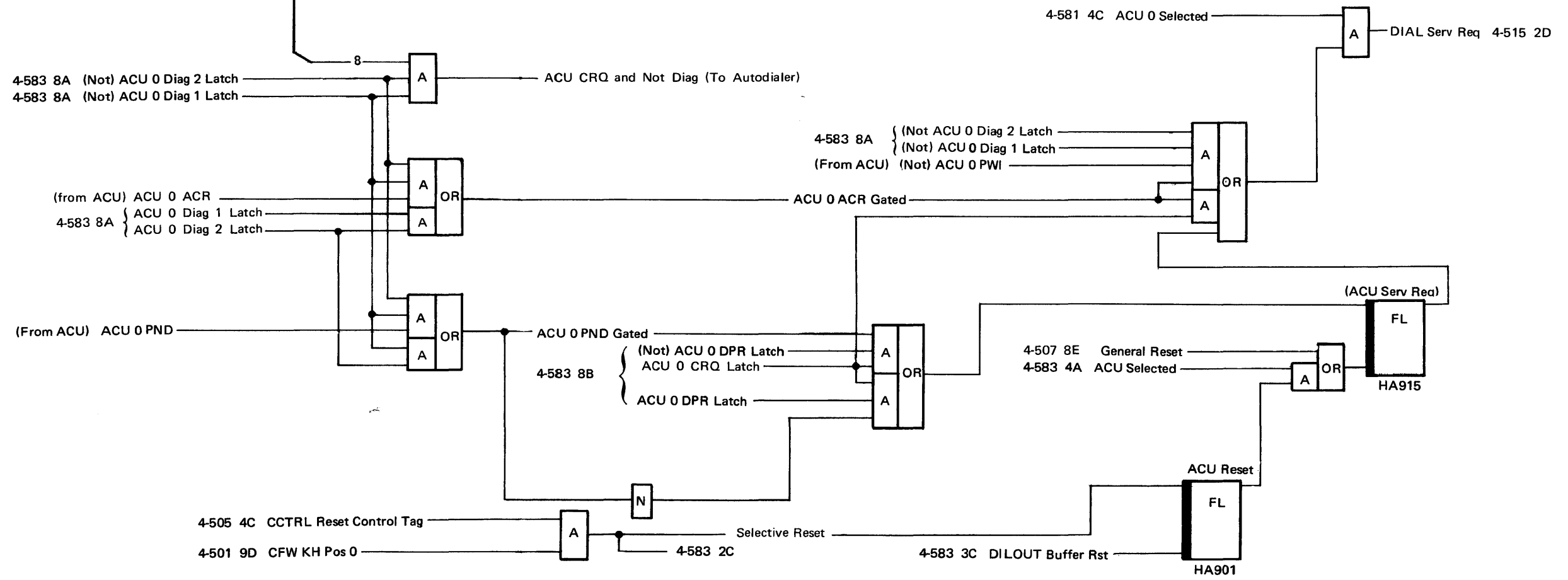
A

B

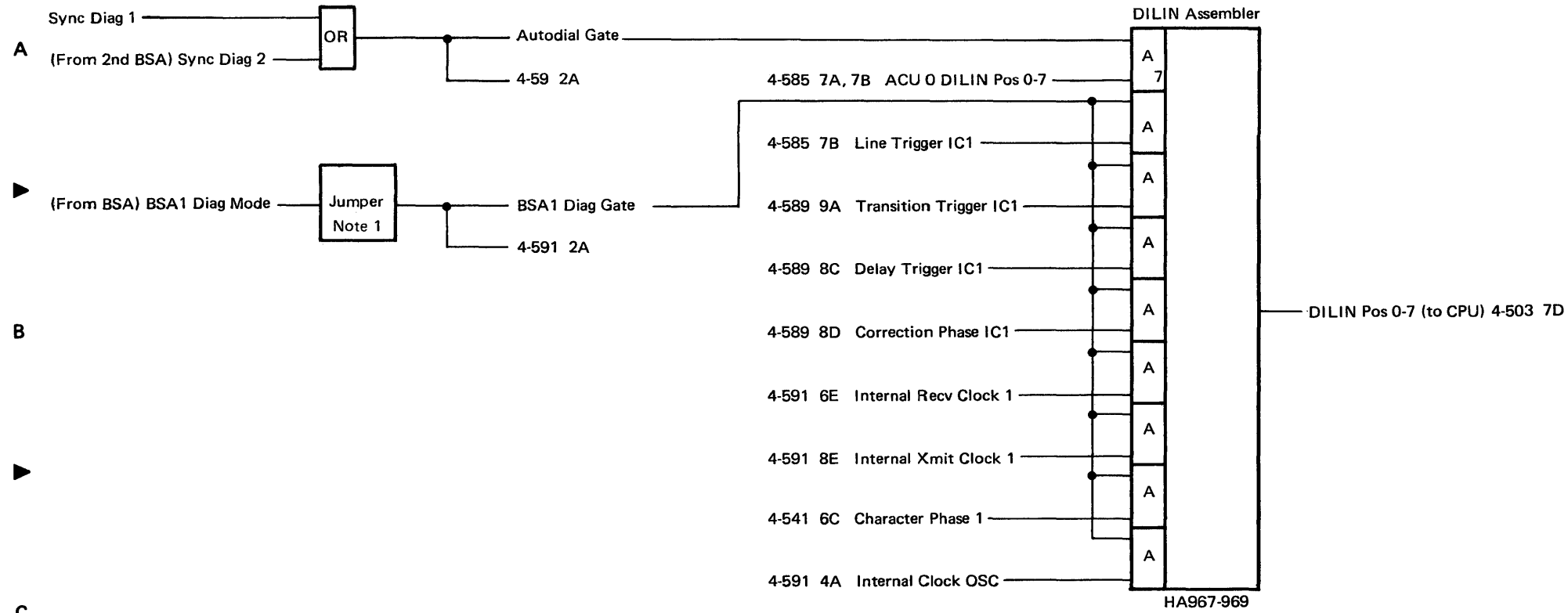
C

D

E



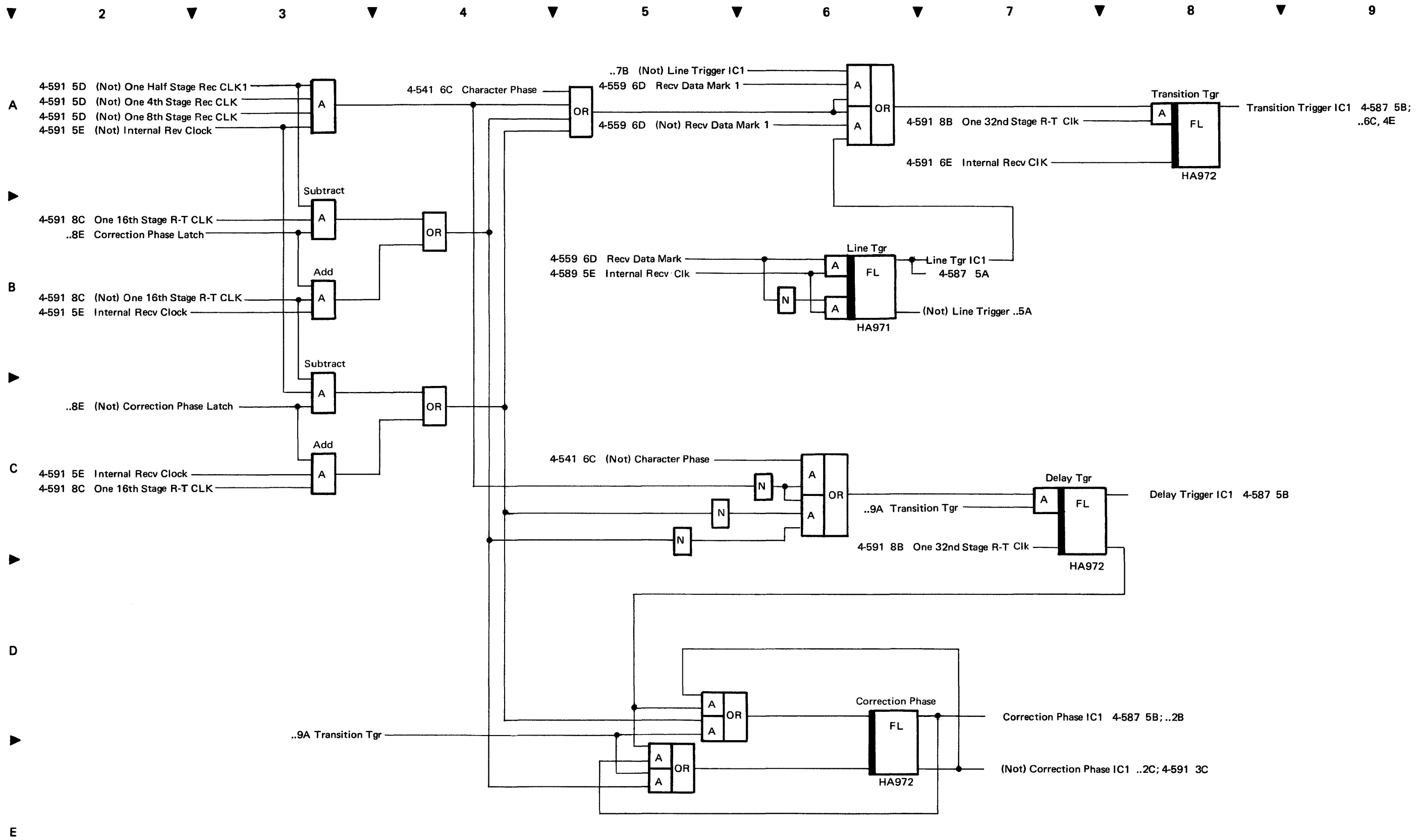
▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6 ▼ 7 ▼ 8 ▼ 9



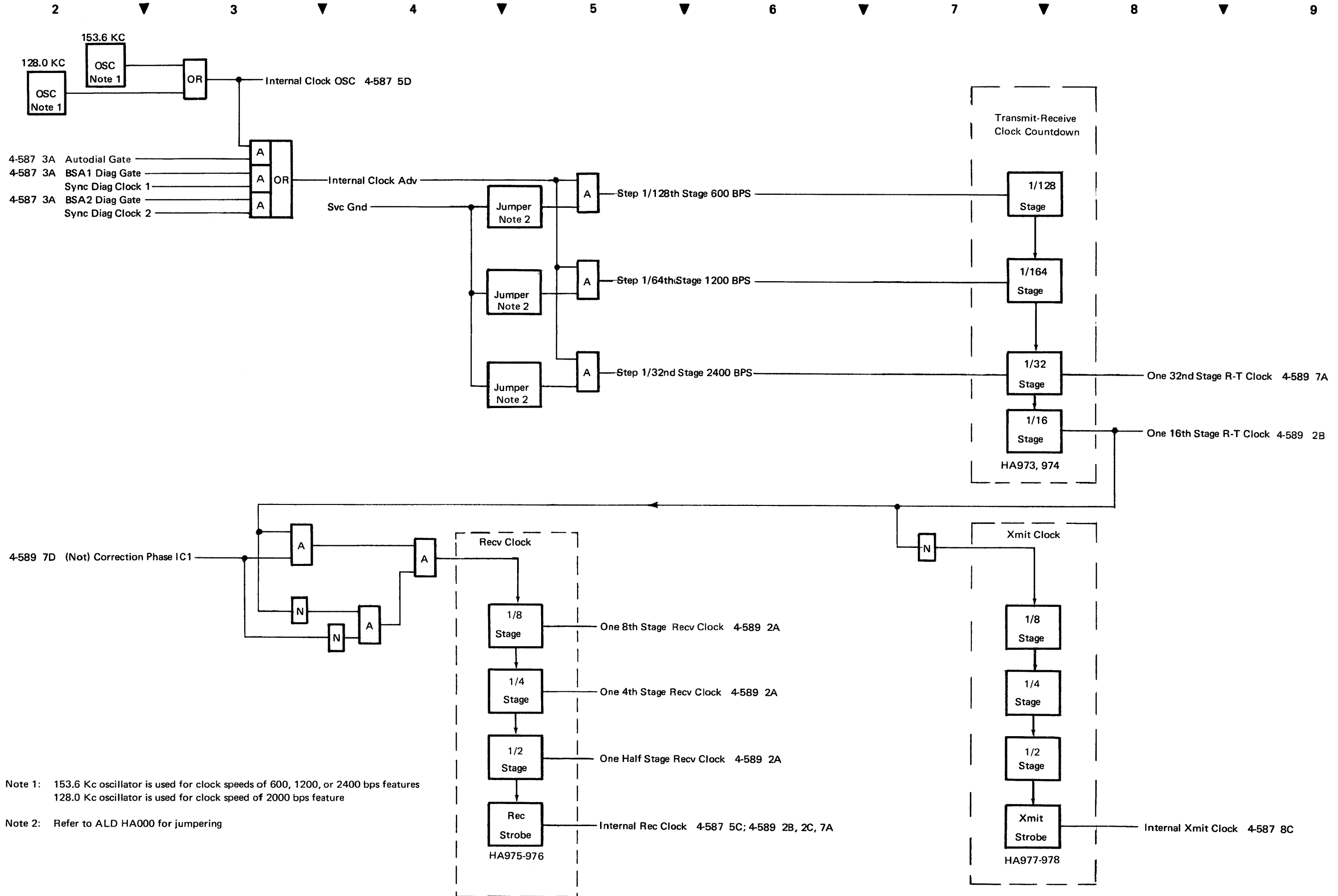
Note 1: Refer to ALD HA000 for jumpering.

C
▼
D
▼
E

Diagram 4-589. Sync Internal Clock (IC) Phase Correction



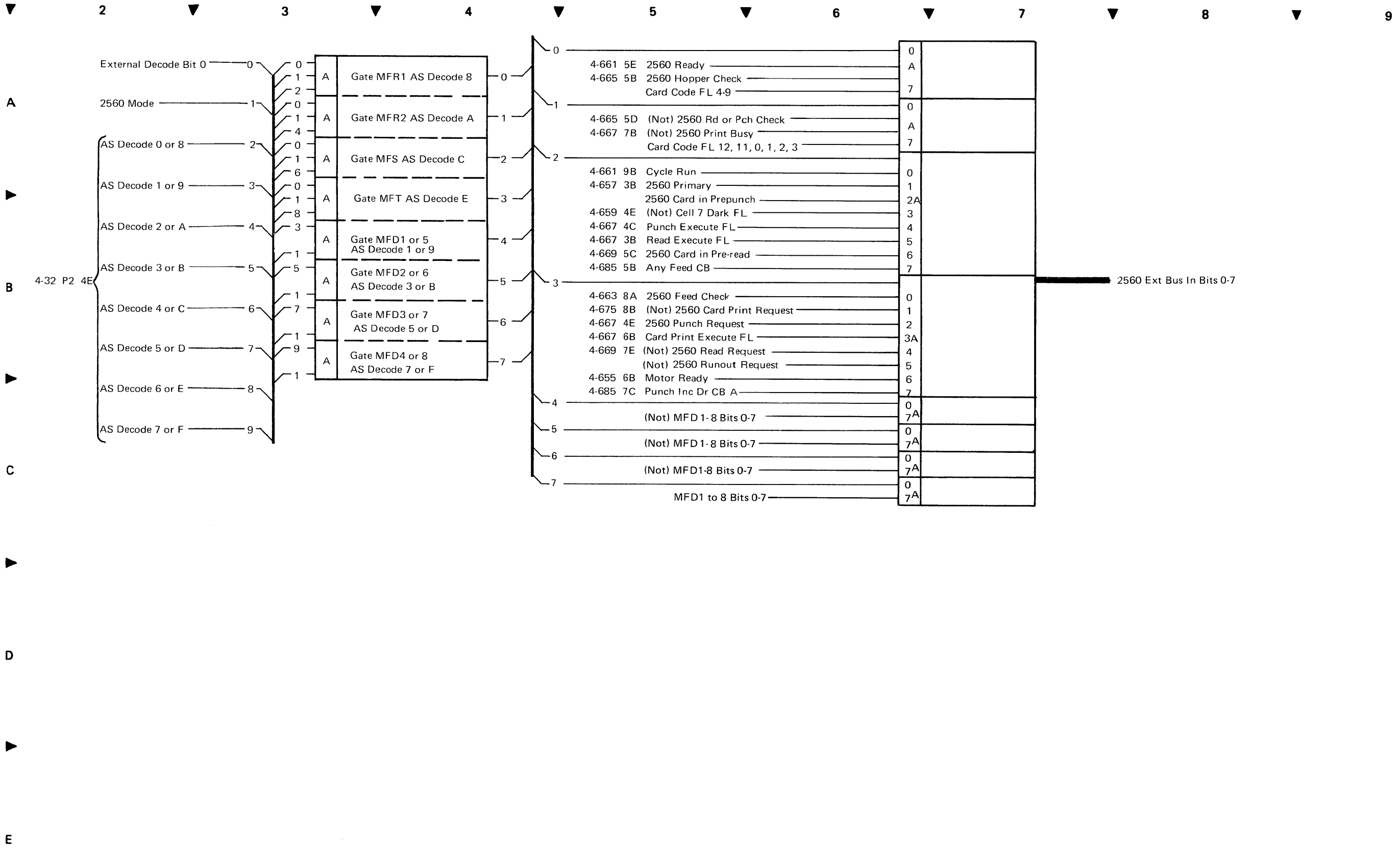
● Diagram 4-591. Sync Internal Clock (IC) Receive-Transmit Clock, Receive Clock, and Transmit Clock



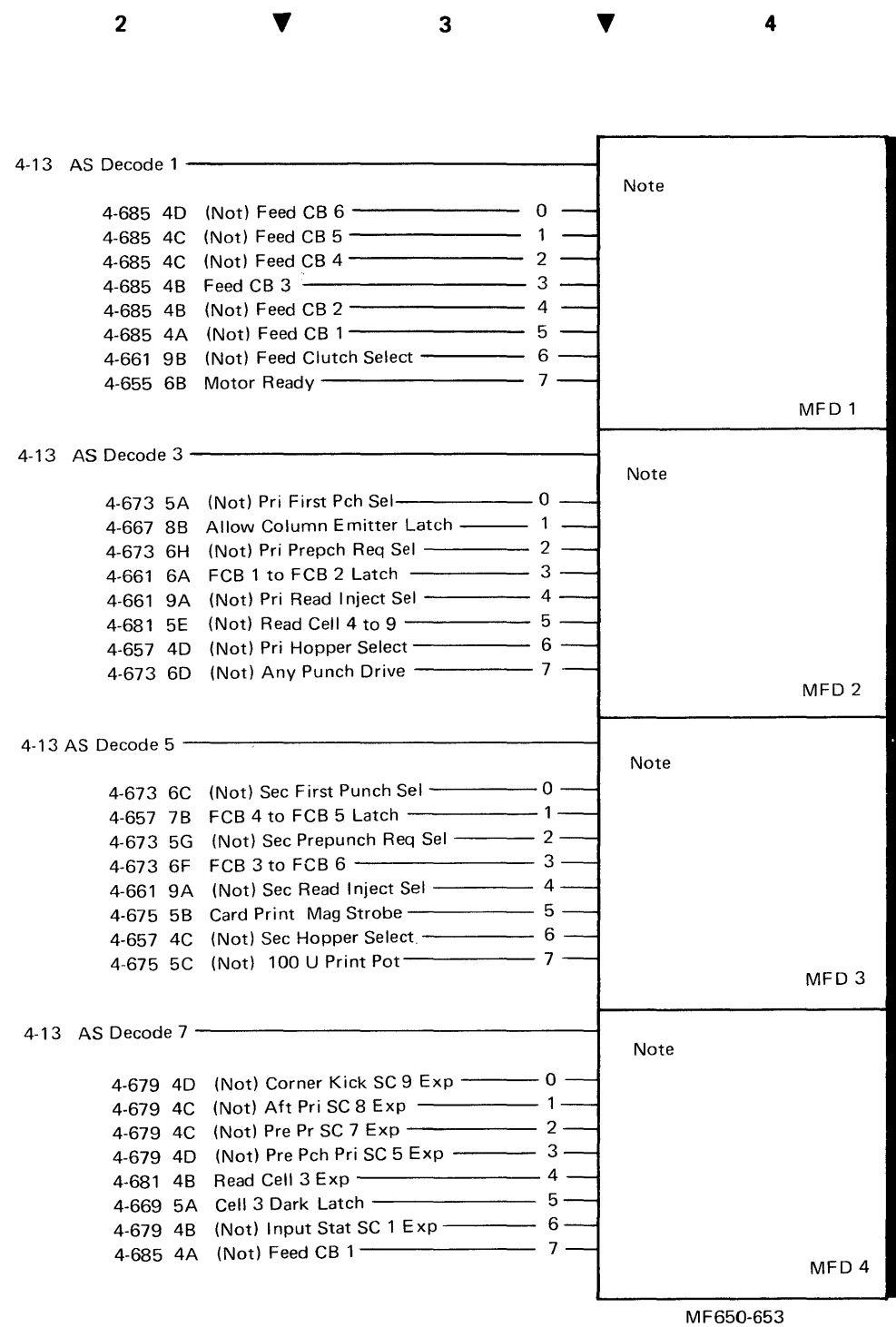
Note 1: 153.6 Kc oscillator is used for clock speeds of 600, 1200, or 2400 bps features
128.0 Kc oscillator is used for clock speed of 2000 bps feature

Note 2: Refer to ALD HA000 for jumpering

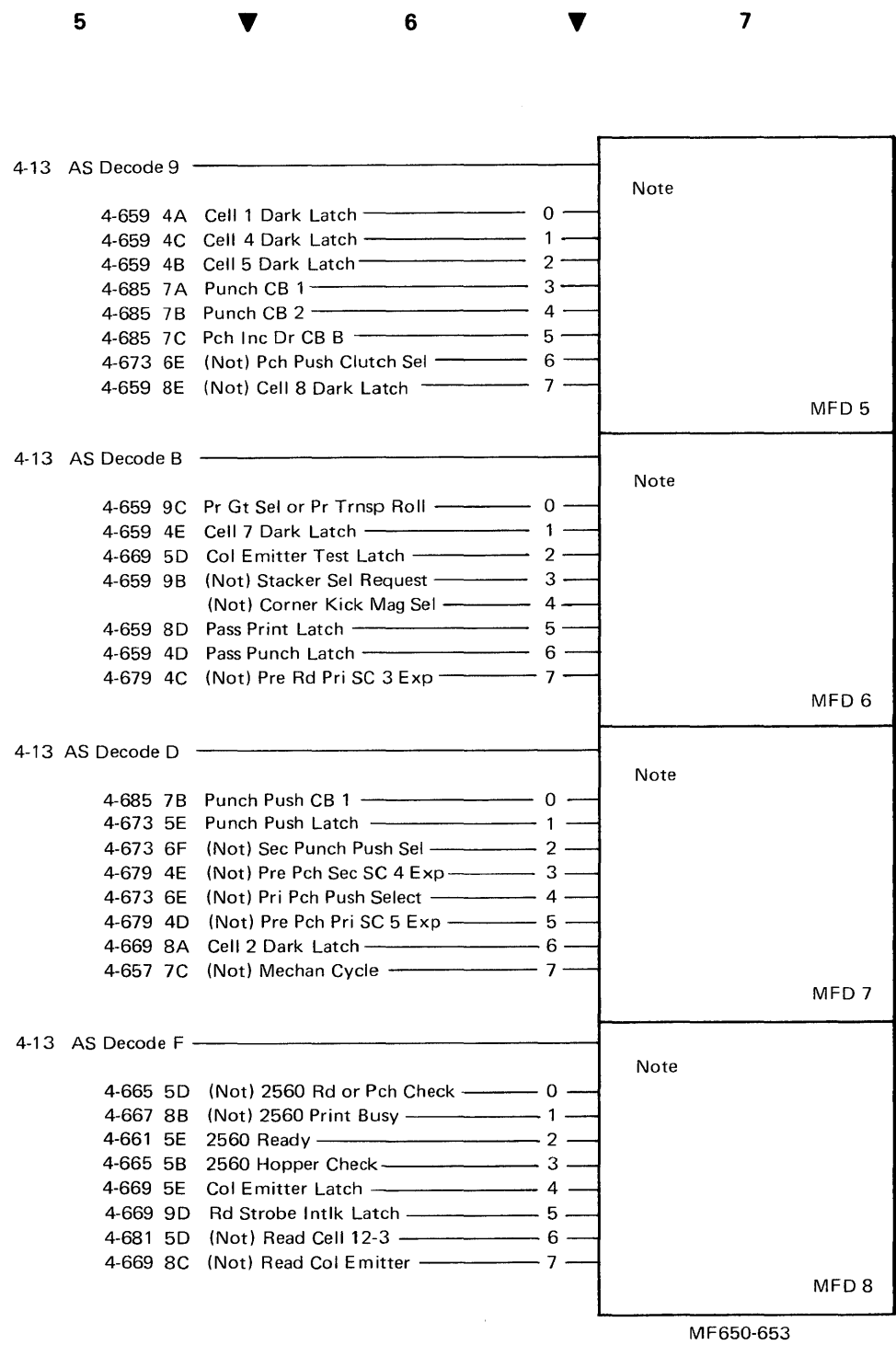
Diagram 4-651. External Facilities for the IBM 2560 Attachment (2560 Mode)



A
B
C
D
E



MF650-653



MF650-653

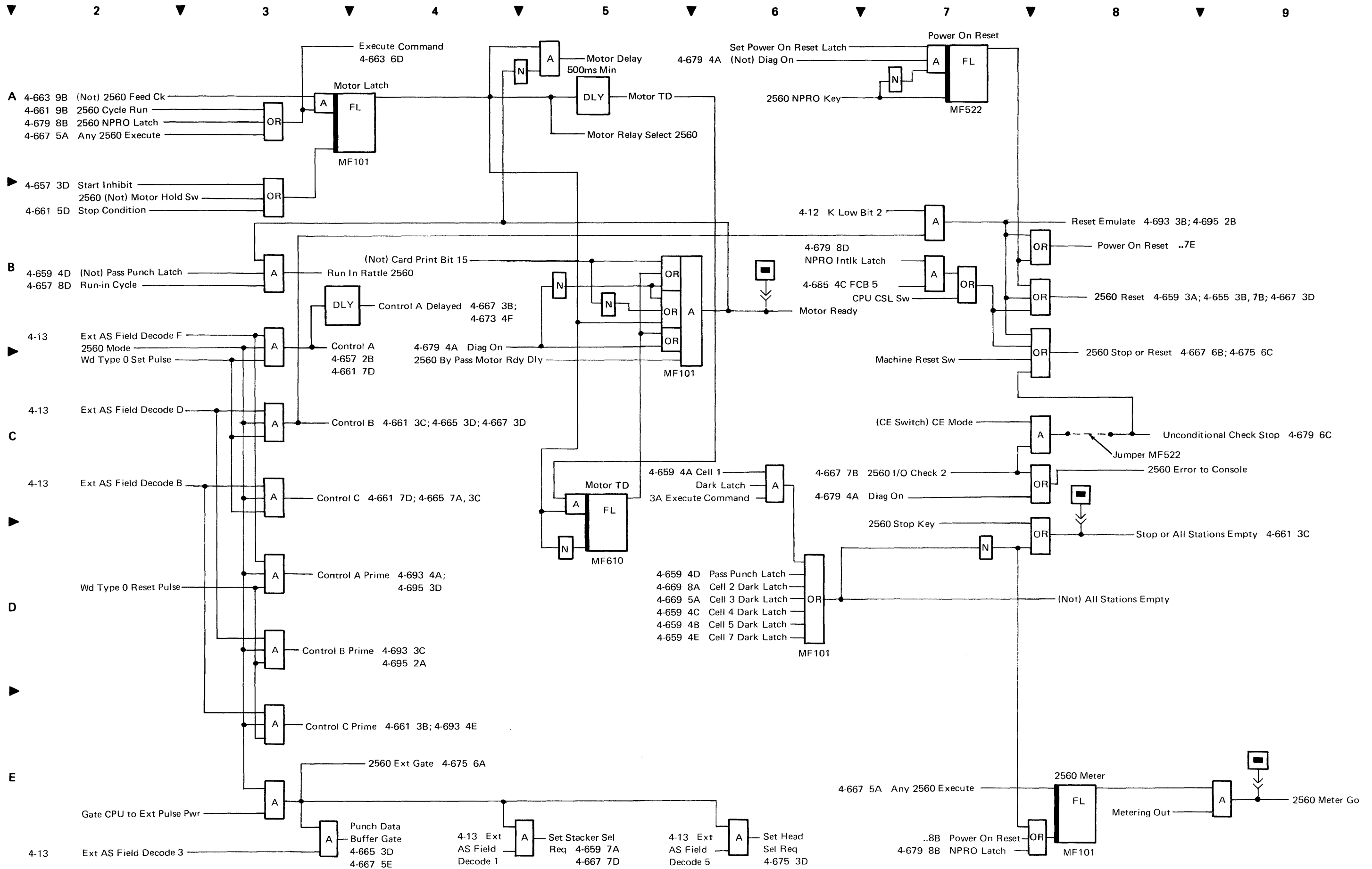
Note:

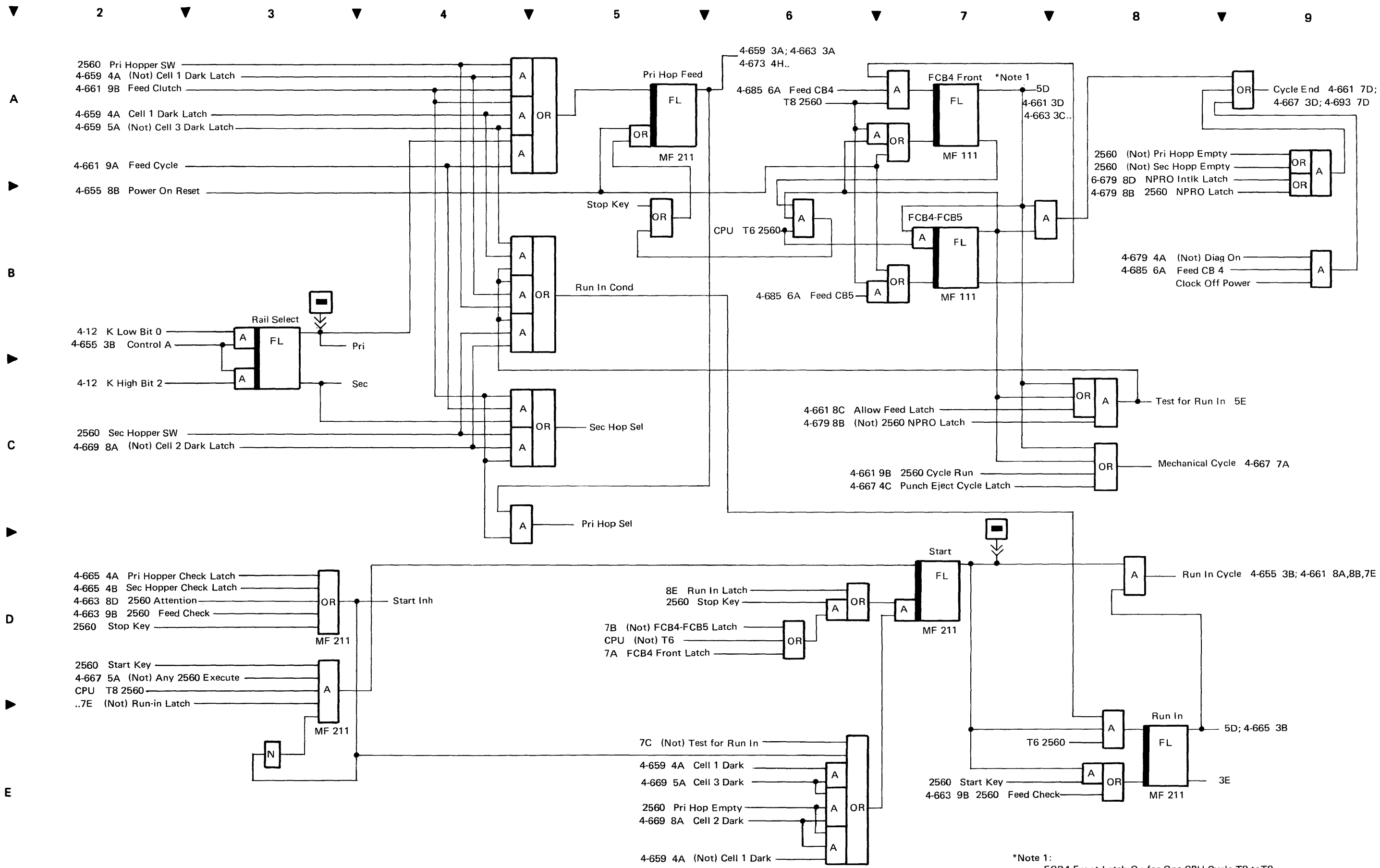
The indicated gates (AS Decodes) are ANDed with the inputs to produce signals on the input bus bits 0-7 for those signals present.

Output further gated in SX051-054 with the AS decodes so that (Not) conditions on this page produce inputs to the appropriate bus-in lines.

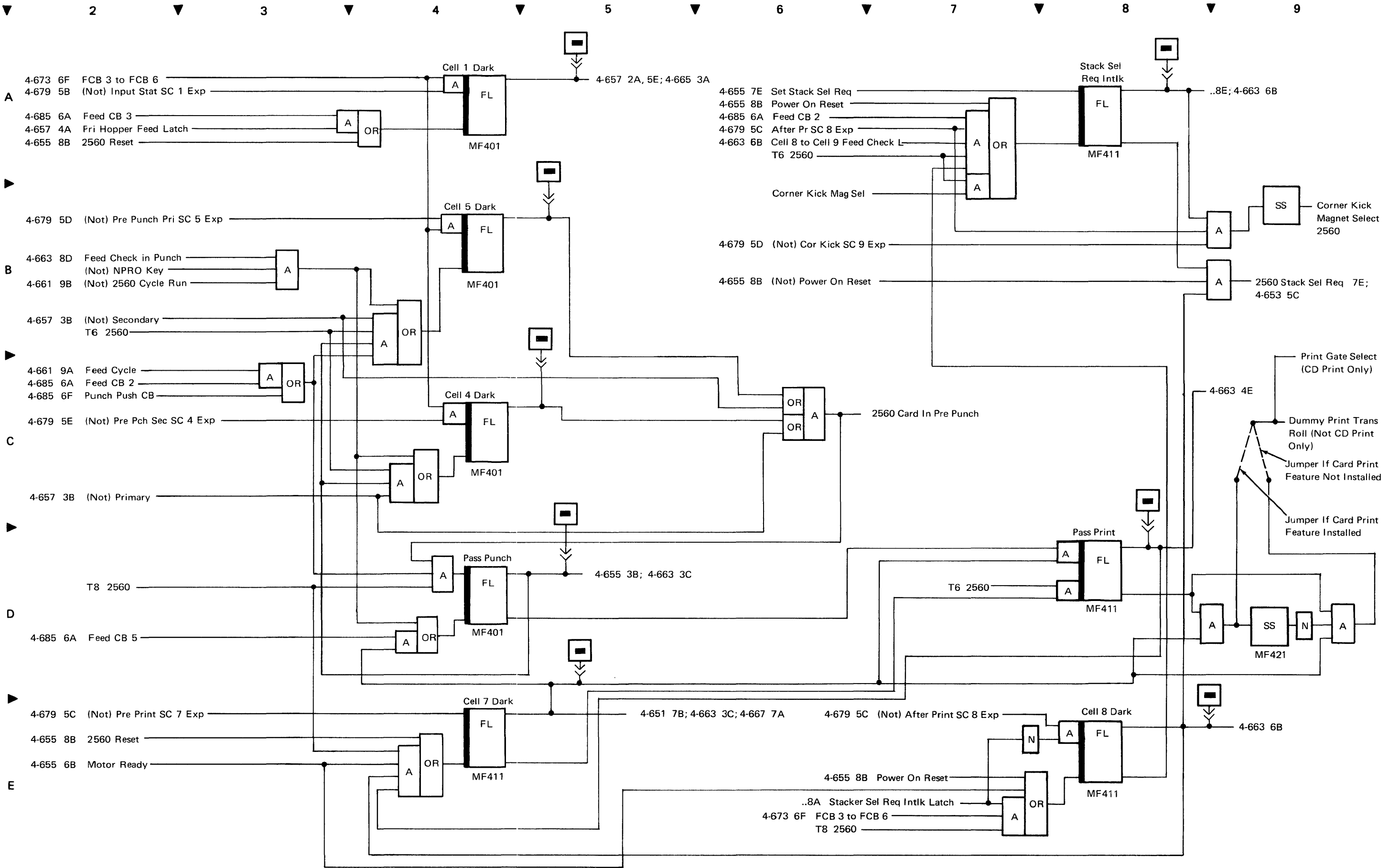
MFD 1 to 8. Bits 0 to 7 to SX051-054

Diagram 4-655. 2560 Reset and Stop, Motor Control, CPU Gate Controls





*Note 1:
FCB4 Front Latch On for One CPU Cycle T8 to T8



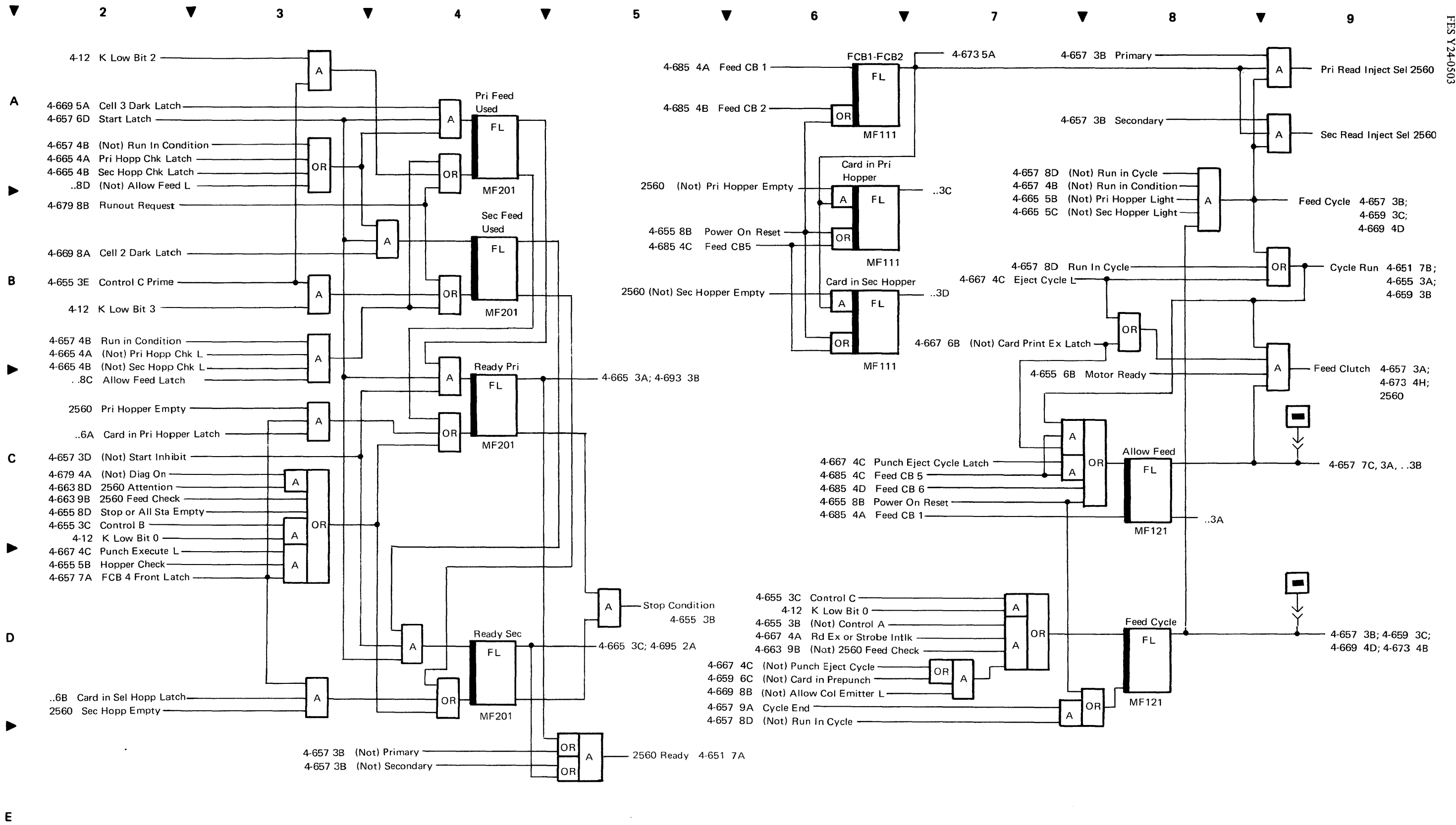


Diagram 4-663. Check Latches and Feed Check (2560)

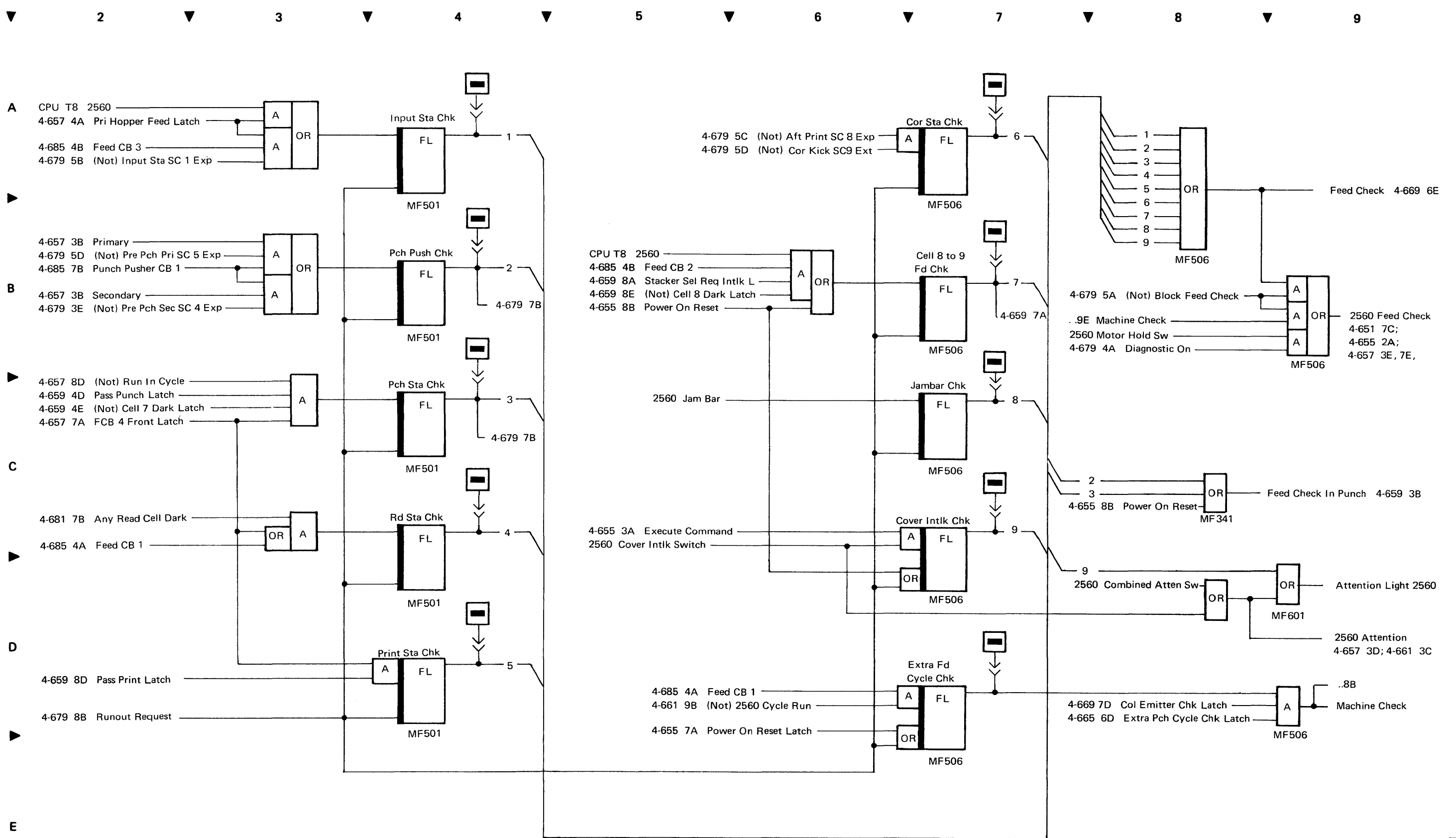
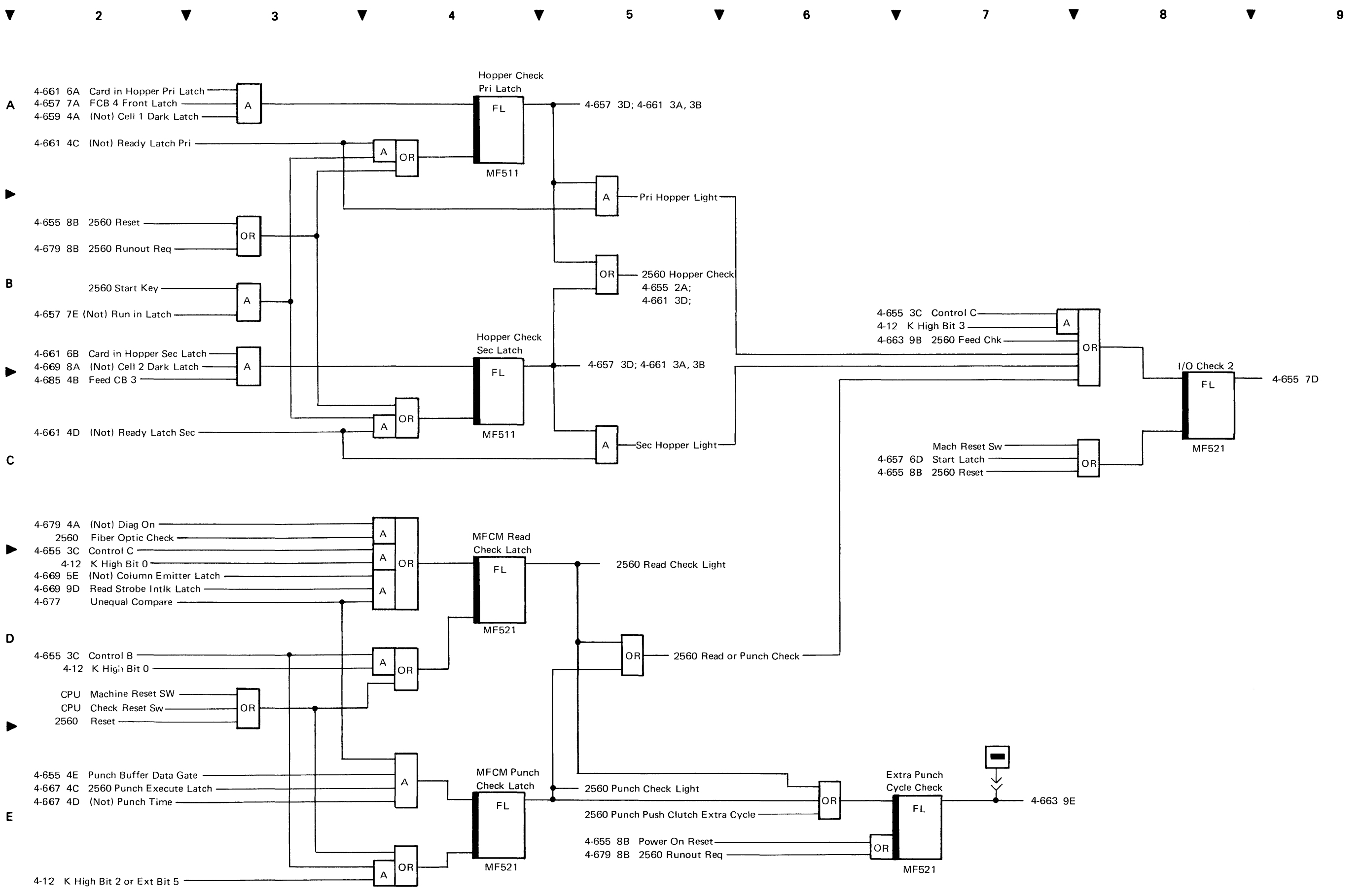
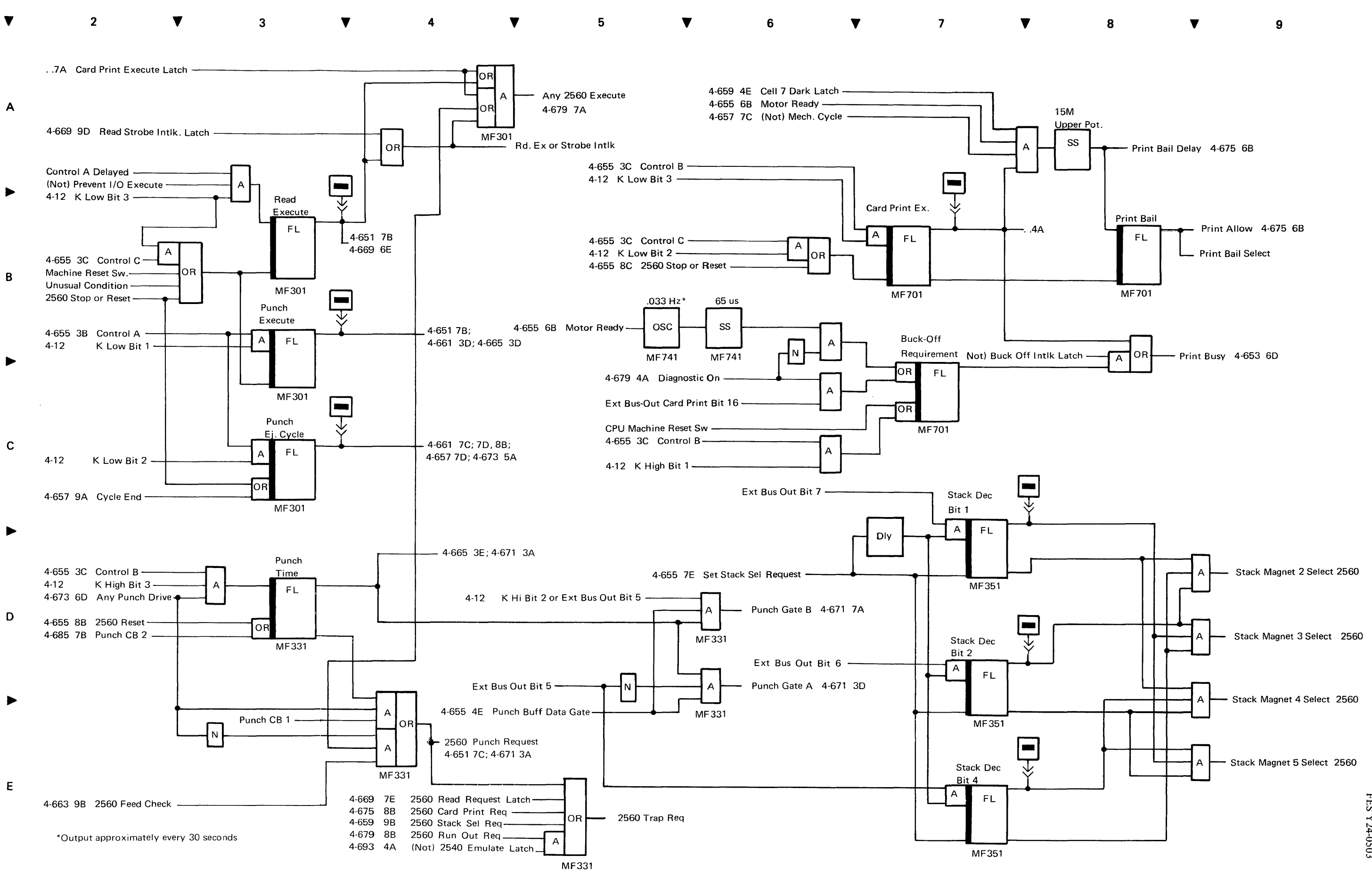


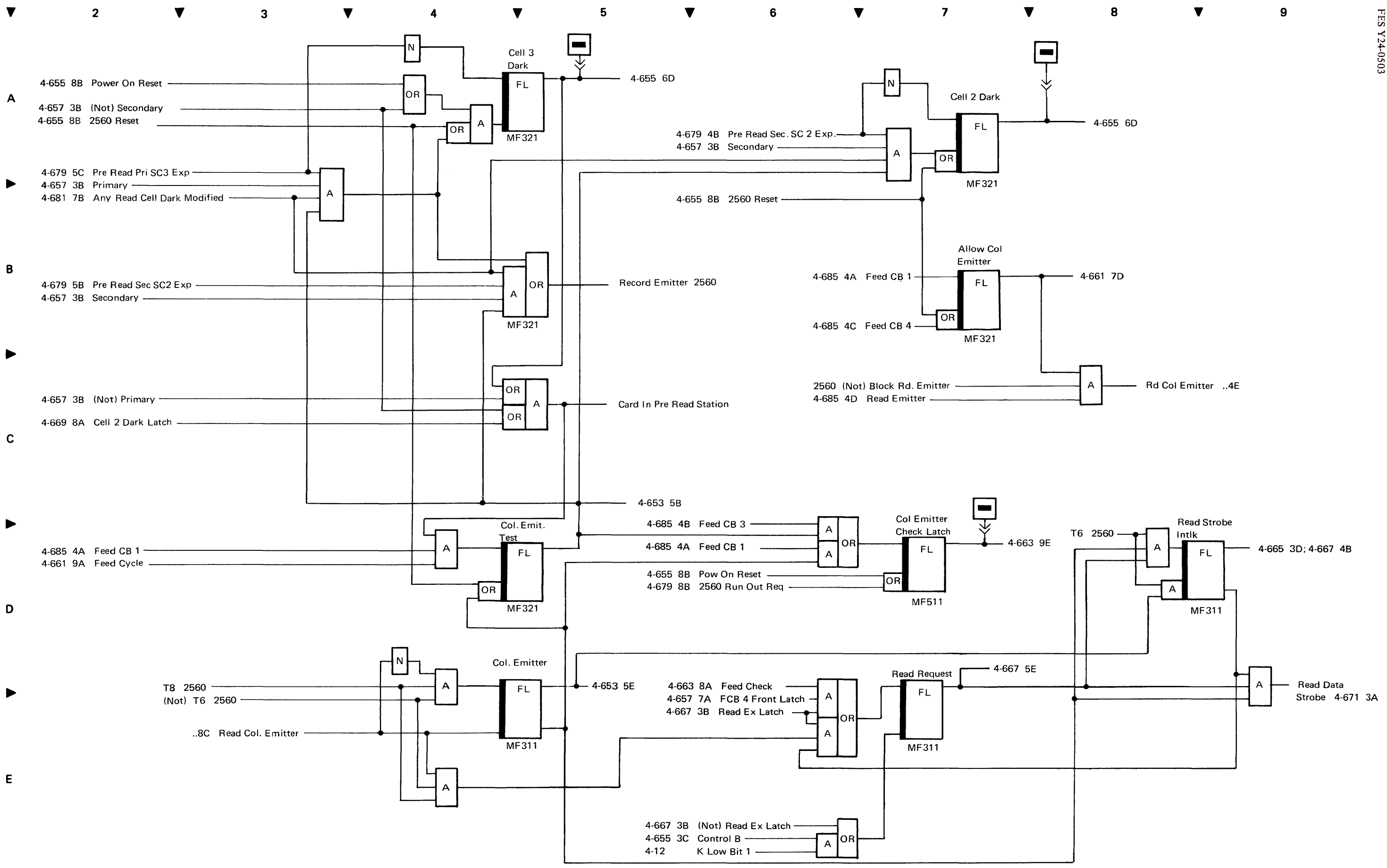
Diagram 4-665. Check Latches

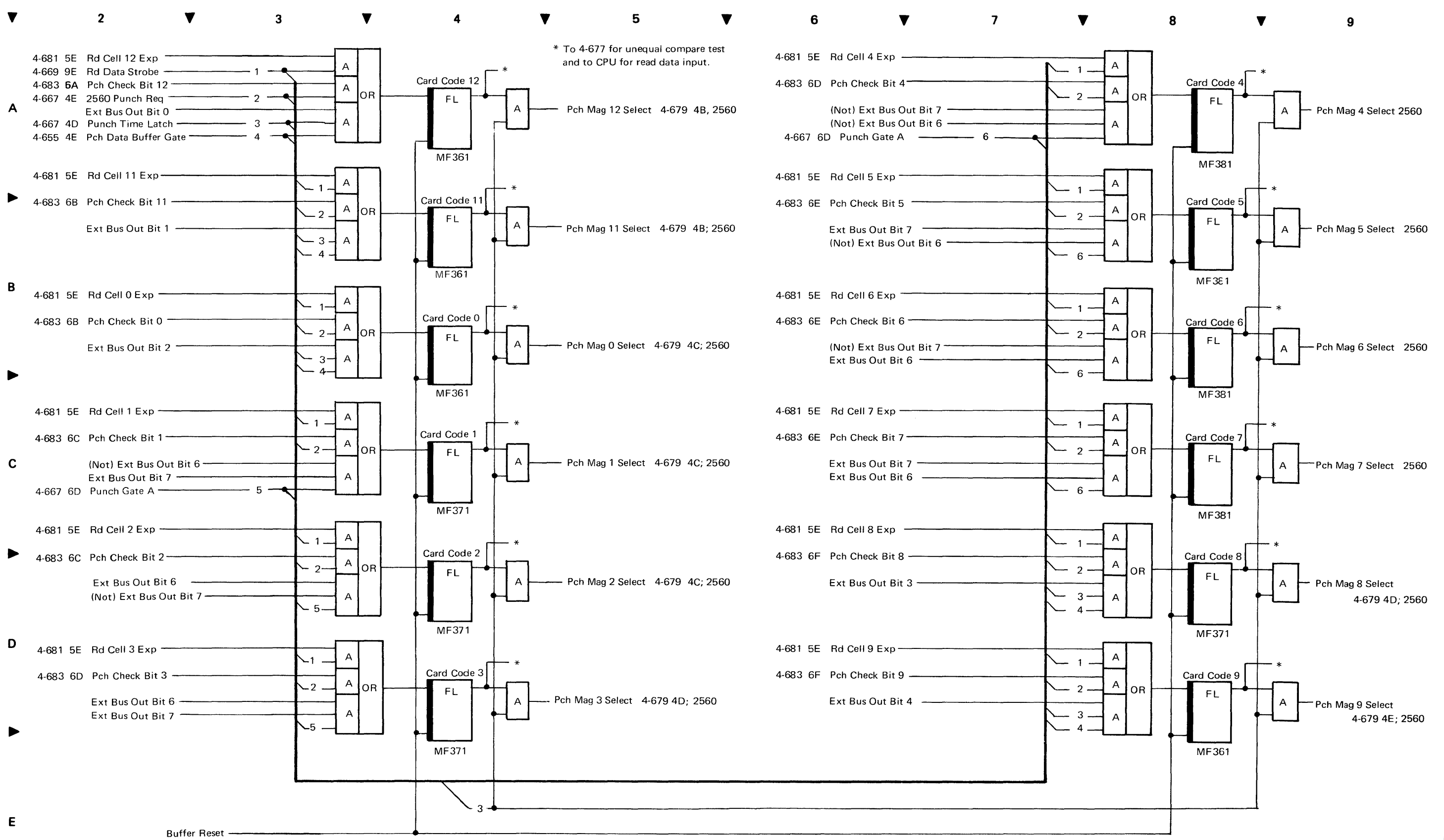




*Output approximately every 30 seconds

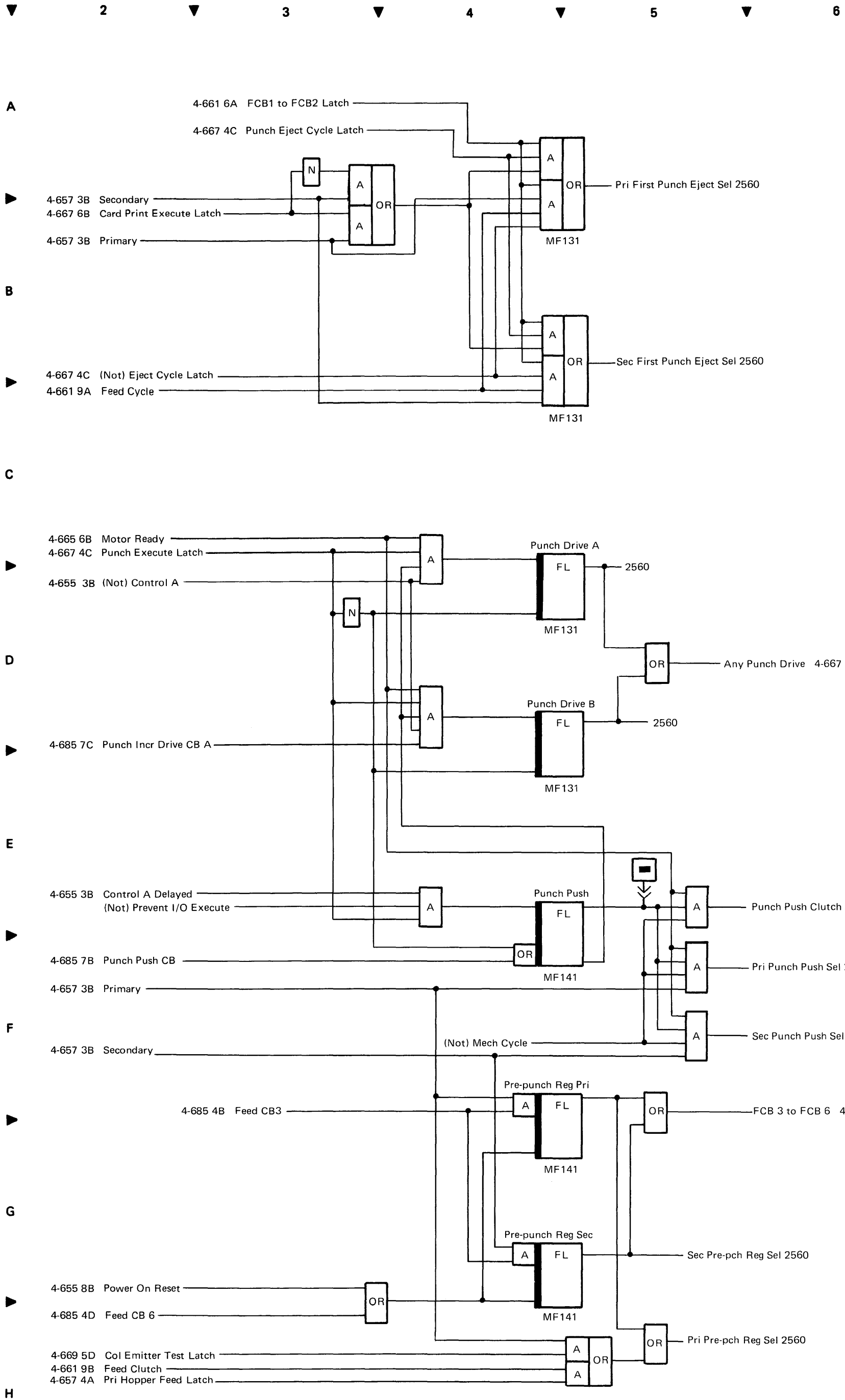
Diagram 4-669. Read Request, Column Emitter, Read Strobe Interlock





* To 4-677 for unequal compare test and to CPU for read data input.

* To 4-677 for unequal compare test and to CPU for read data input.



● Diagram 4-673. Punch Feed and Drive Control, Punch Push Control (2560)

2

3

4

5

6

7

8

9

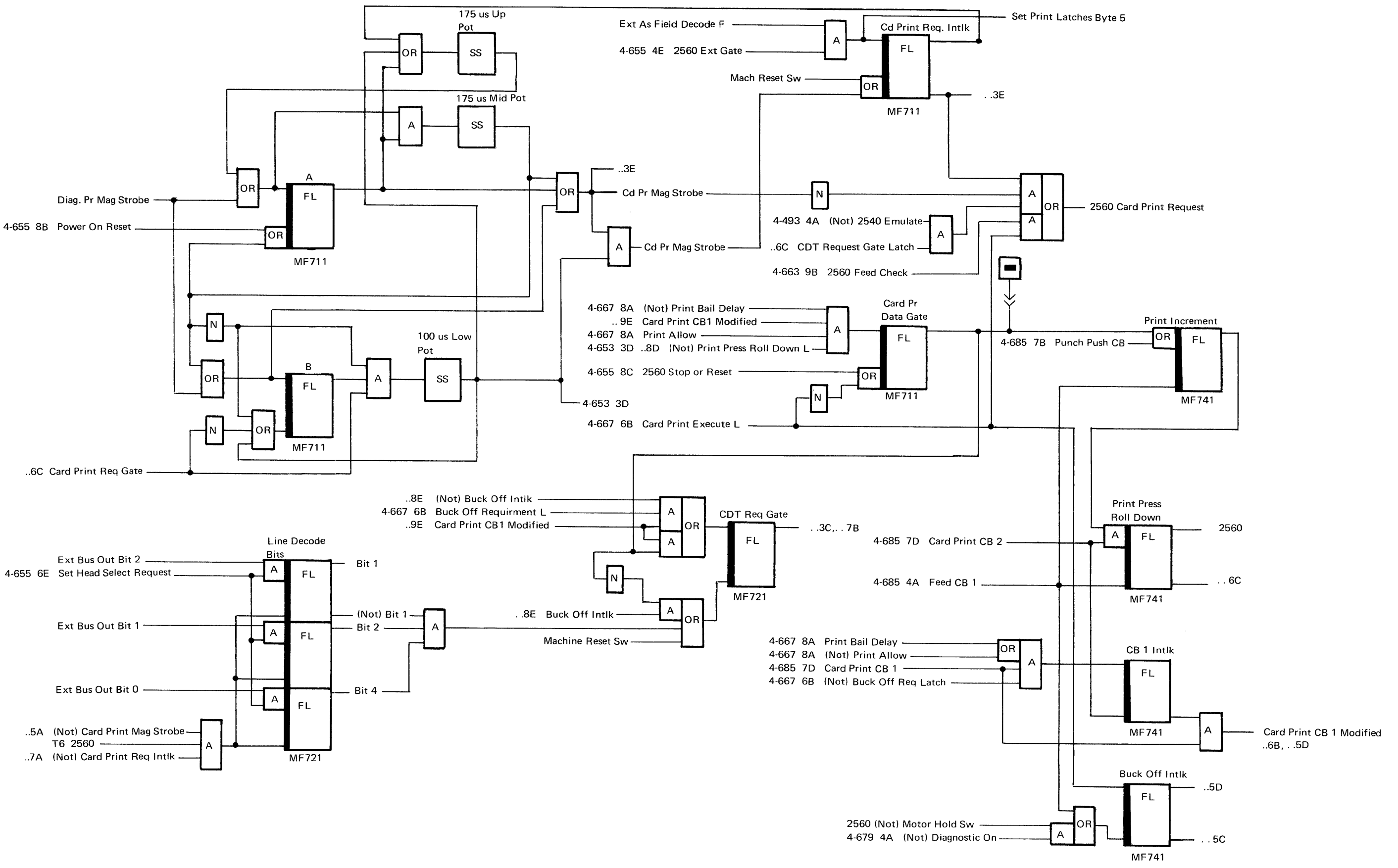
A

B

C

D

E



▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6

Card Code Latch Set	Conditions for Satisfying <u>Not Unequal Compare</u>			Result
	Read Cell Exp	(or)	Ext Bus-Out Bits	
12	12		0 =	Not Unequal Compare
11	11		1 =	
0	0		2 =	
1	1		7, not 5, not 6 =	
2	2		5, 6, not 7 =	
3	3		6, 7, not 5 =	
4	4		5, not 6, not 7 =	
5	5		5, 7, not 6 =	
6	6		5, 6, not 7 =	
7	7		5, 6, 7 =	
8	8		3 =	
9	9		4 =	

B The Read and Punch Compare Check circuit tests for (1) the presence of the proper read cell exposed during a read cycle and (2) the presence of the proper external bus-out bits during a punch cycle. The table shows the conditions required to satisfy not unequal compare for each card code latch set. For example, when card code latch 12 is set, either read cell 12 exposed or external bus-out bit 0 must be present to produce the not unequal compare signal.

▶

C

▶

D

▶

E

▶

F

▶

G

▶

H

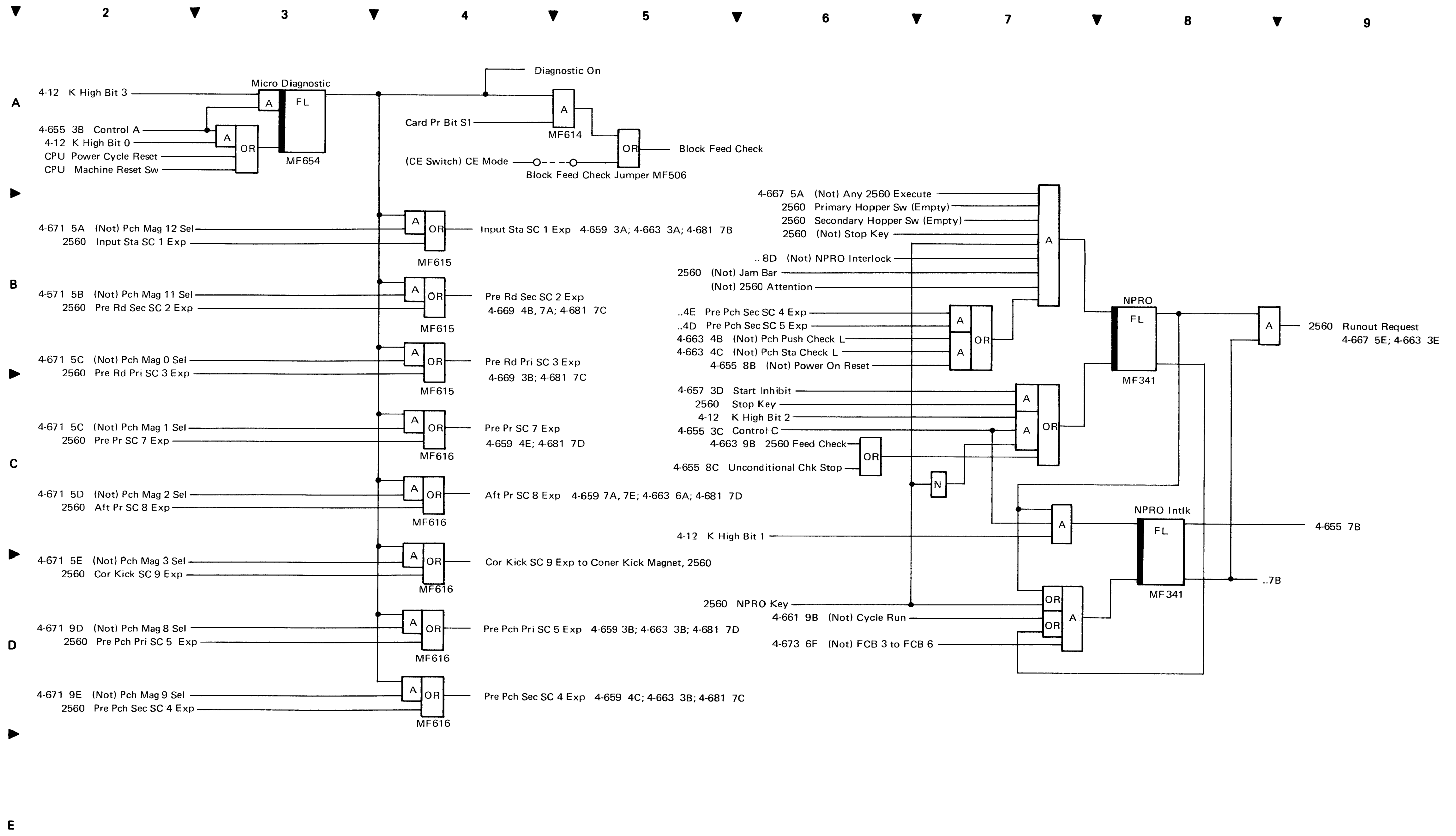
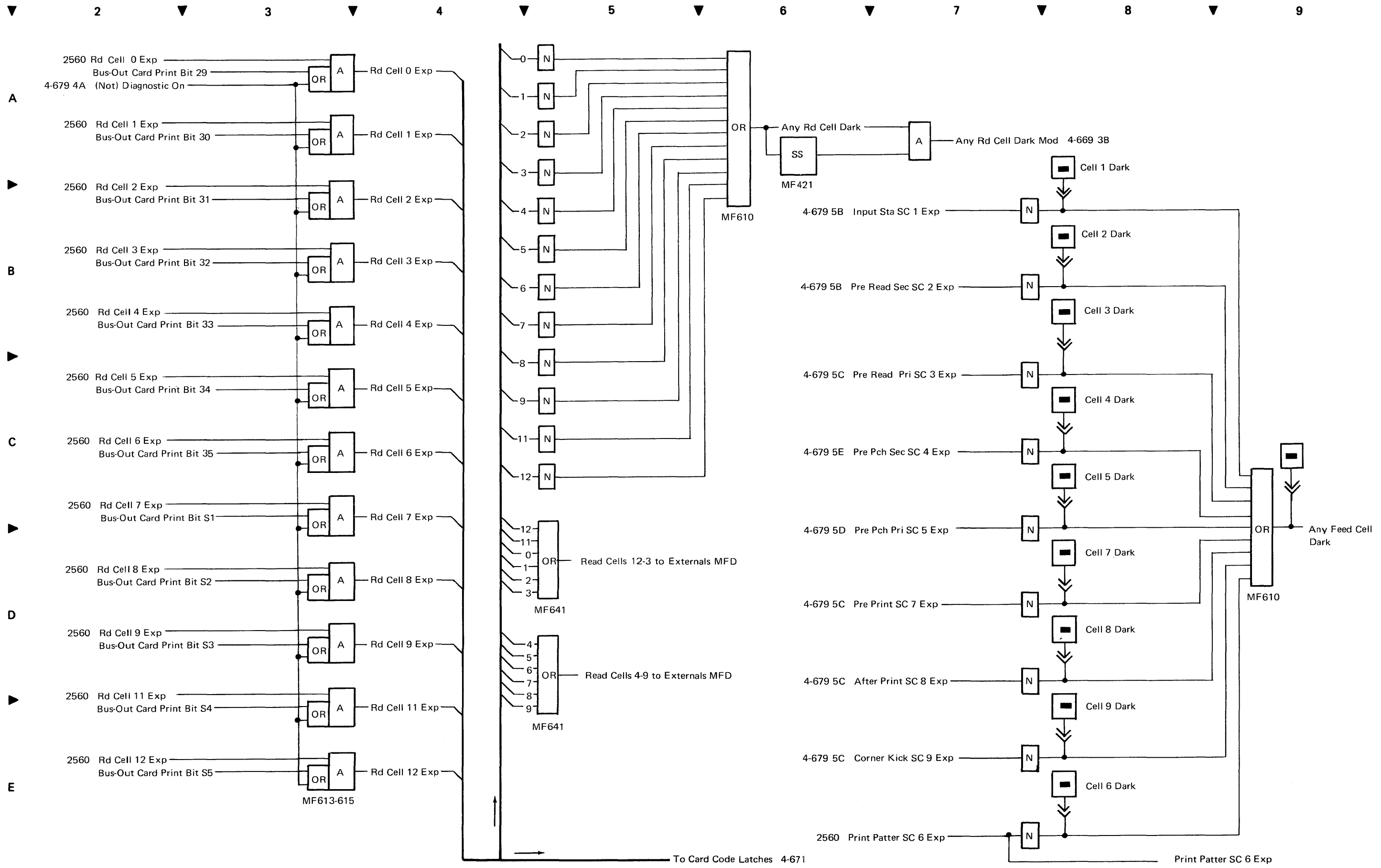
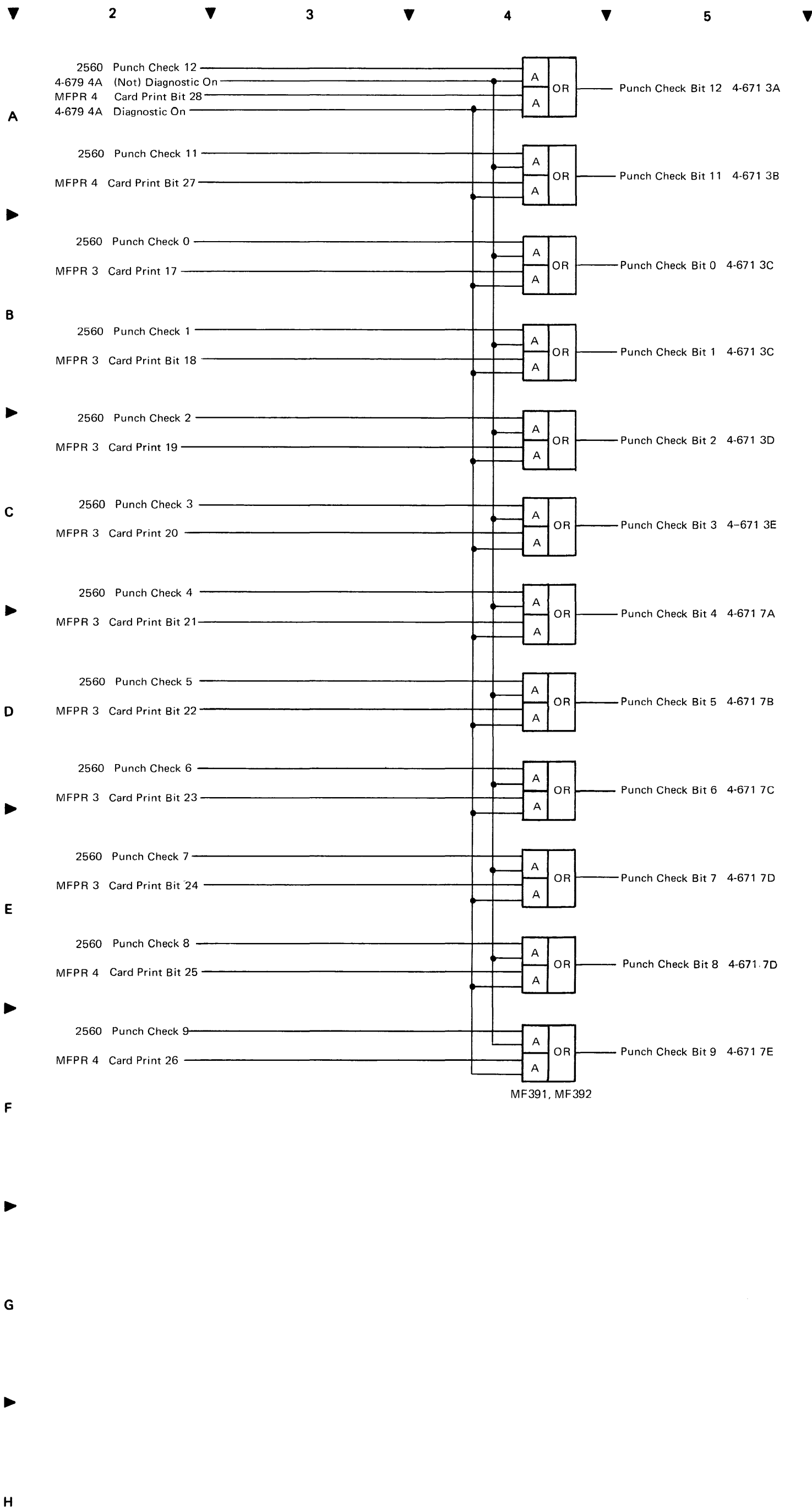
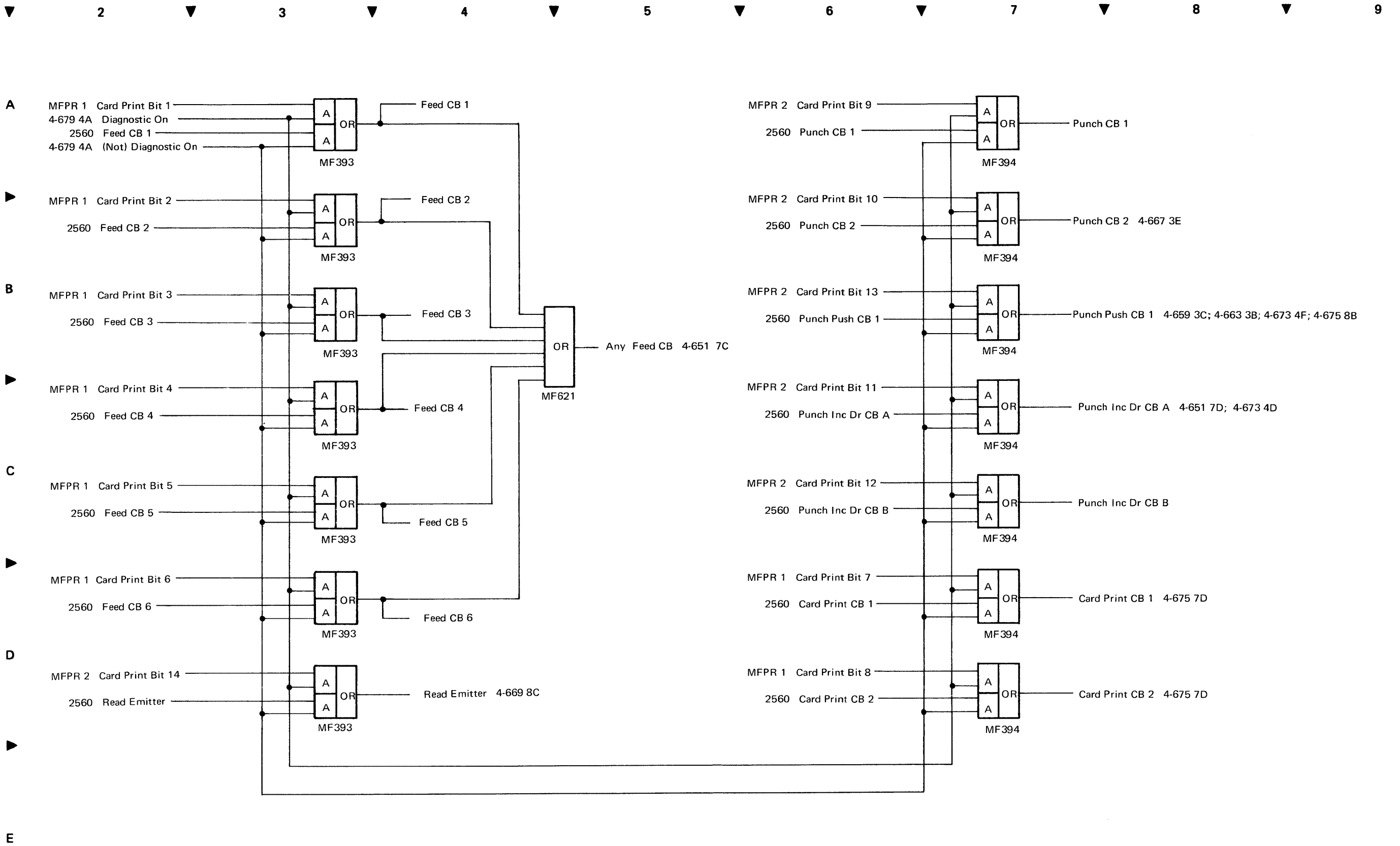


Diagram 4-681. Read Solar Cells, Diagnostic SC Wrap, Any Feed or Read Cell Dark





●Diagram 4-683. Punch Check and Diagnostic Gating



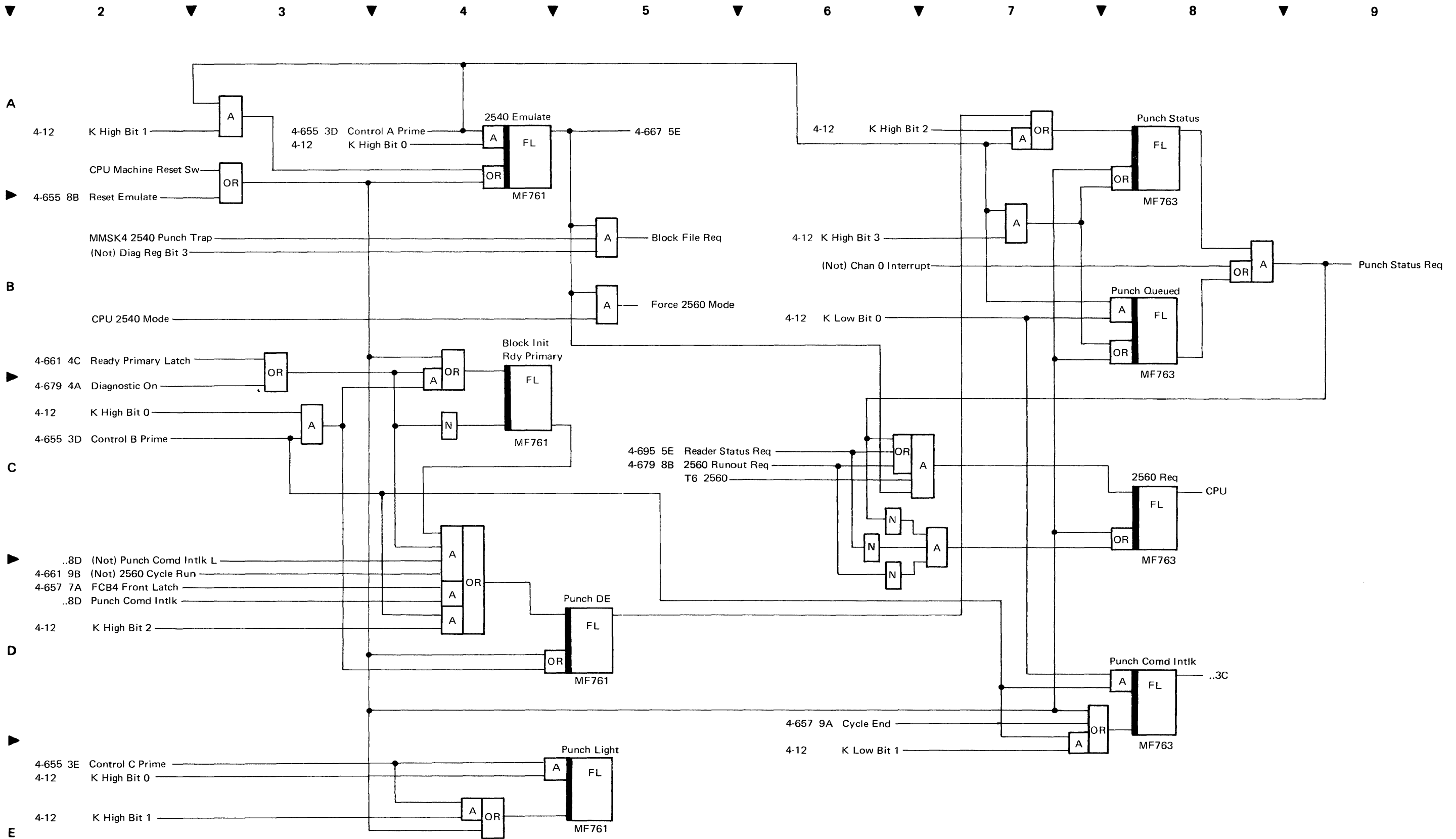


Diagram 4-695. 2540 Emulation Control, Read

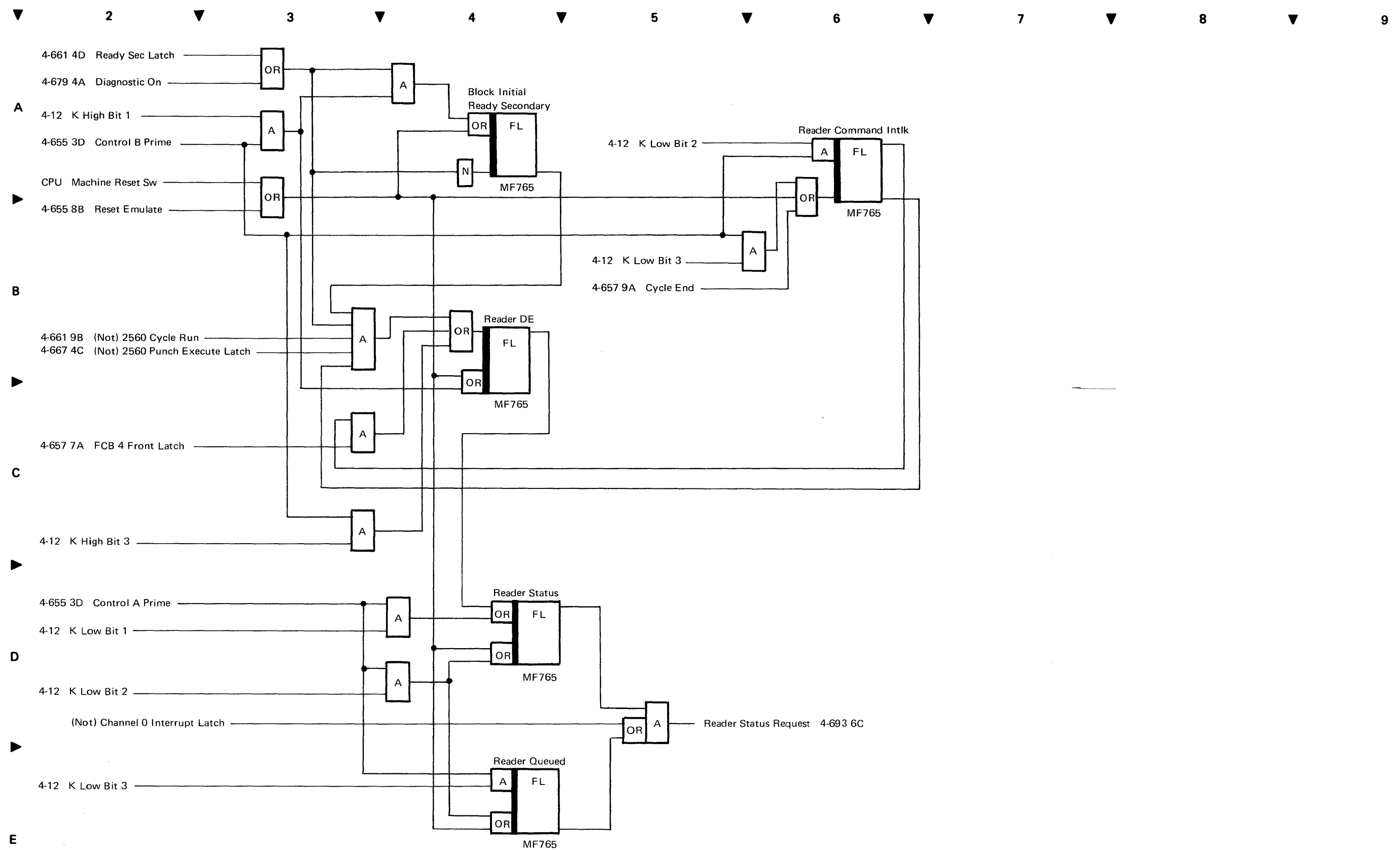
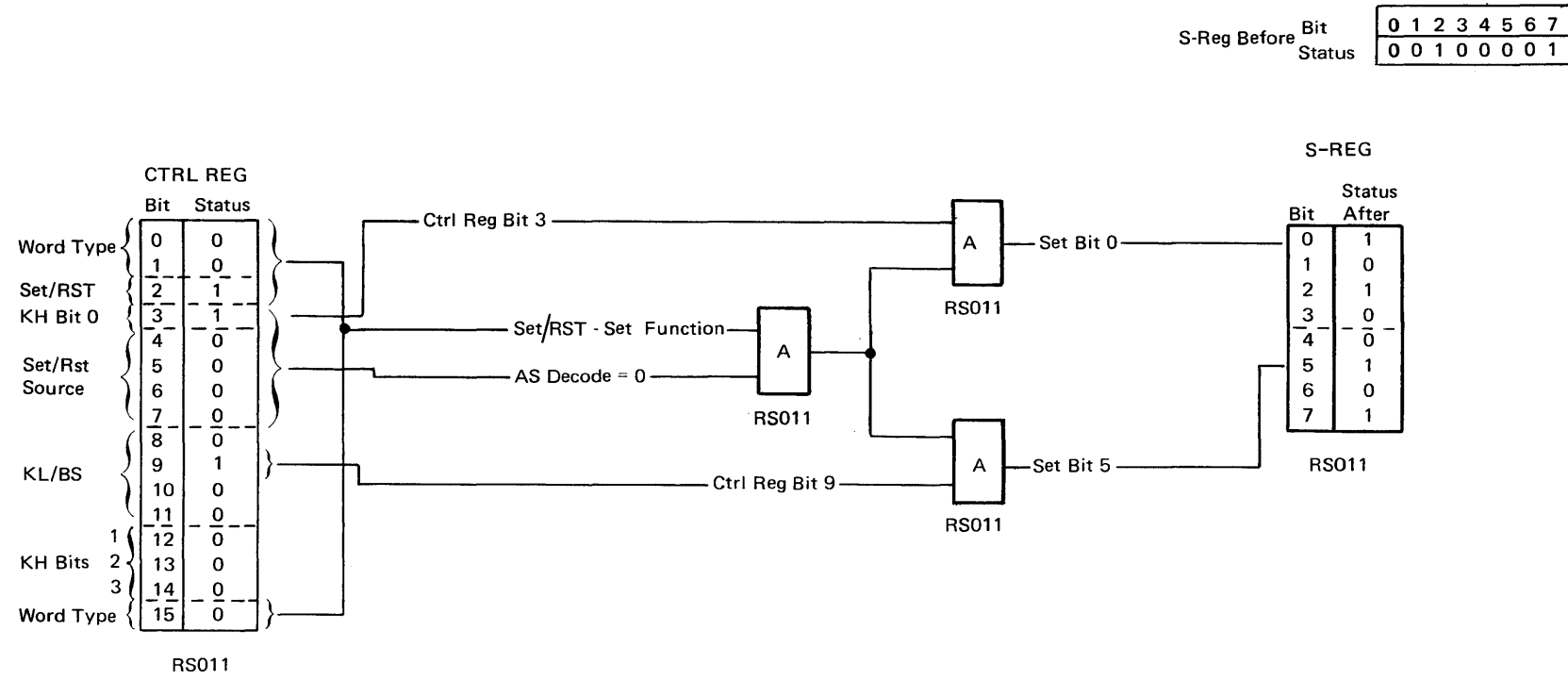


Diagram 5-1. Set/Reset Word (Word Type 0), SET S K=84.



C EXAMPLE STATEMENT

SET S K = 84

Objectives:

1. Set the bits in the S-Register that correspond to the bits of the K value of the Set/RST Word.
The bits of the S-Register that are not addressed by bits of the K-Field, are not affected.

Note: Bits 1 and 2 of the S-Register cannot be set by the Set/RST Word, but may be reset by the Set/RST Word.

Diagram 5-2. Set Reset Word Link Function (Word Type 0)

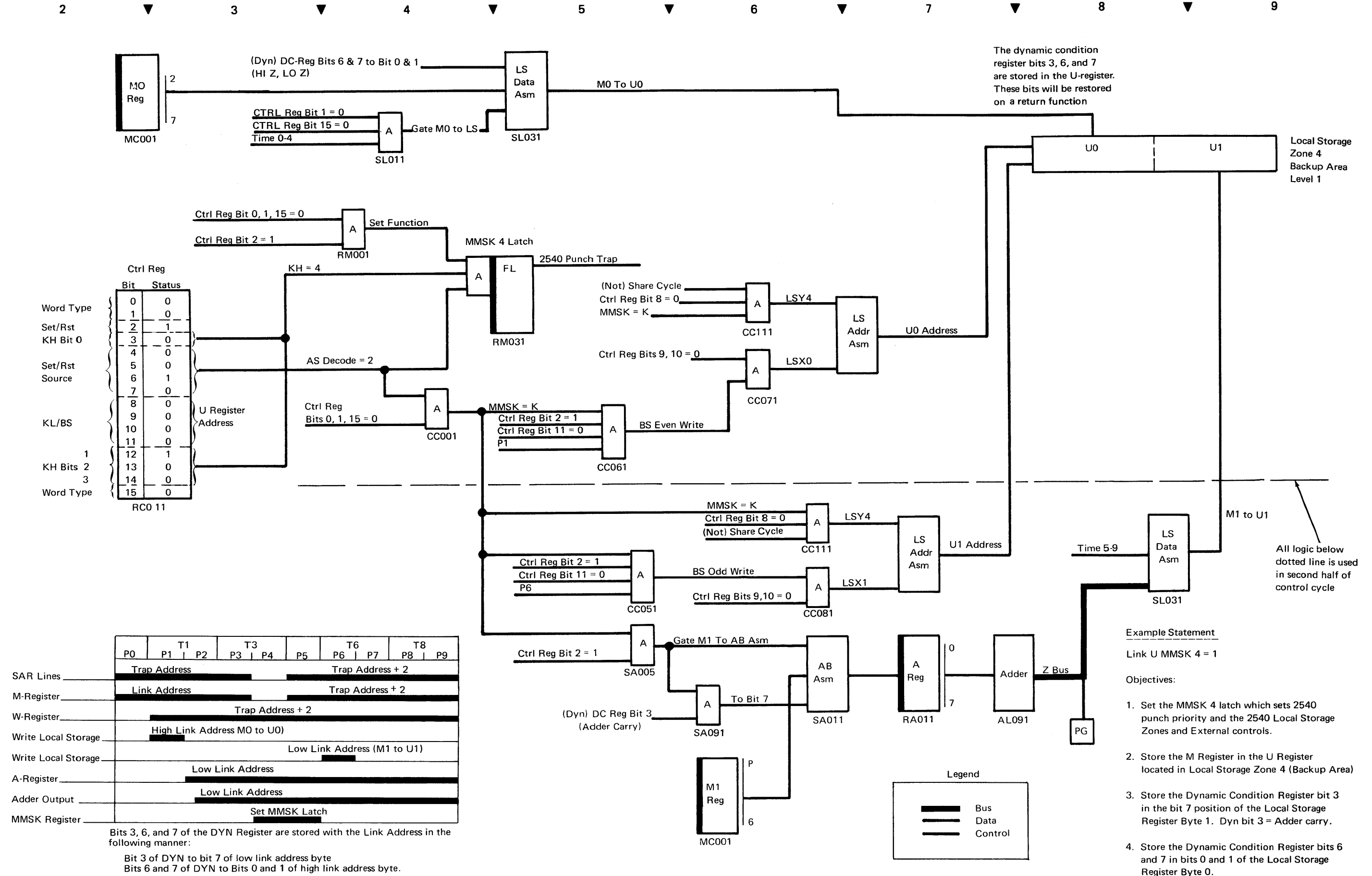
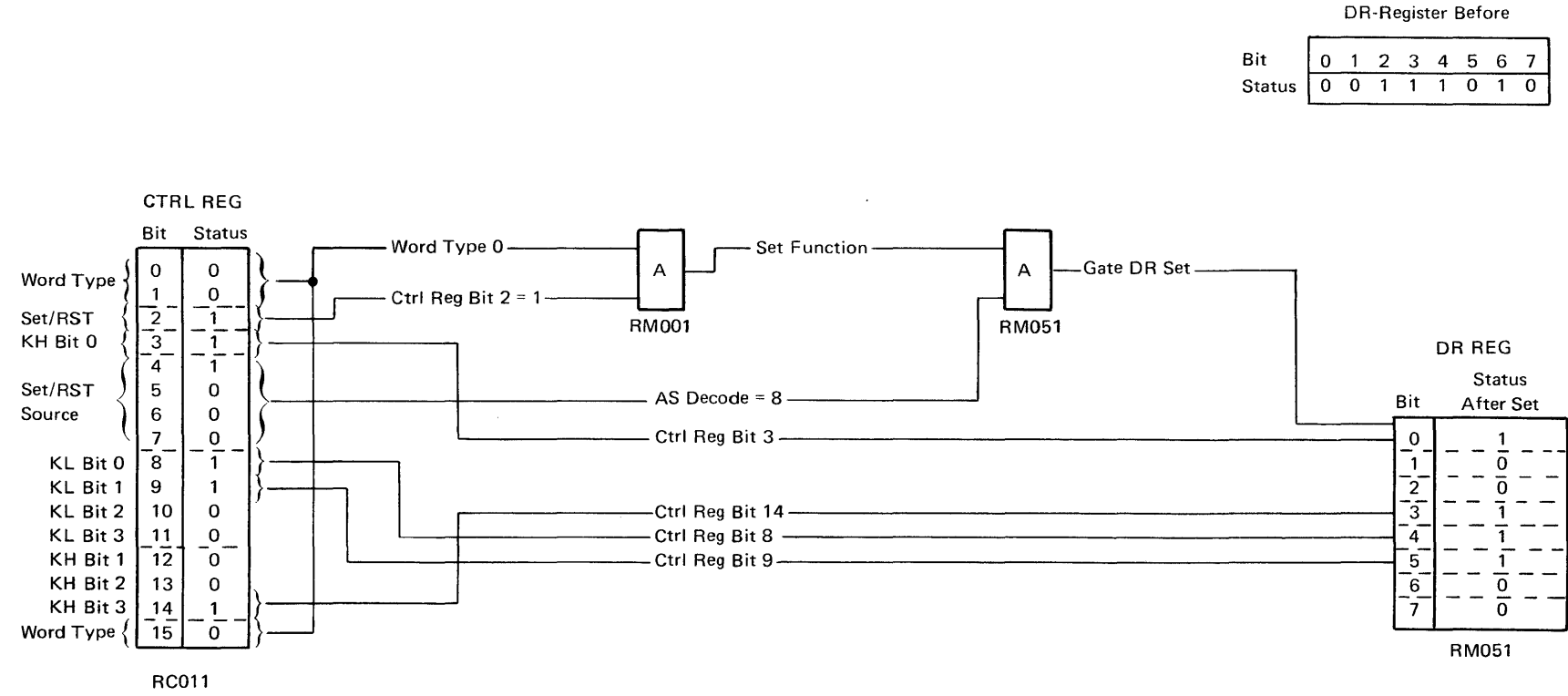


Diagram 5-3. Set/Reset Word (Word Type 0), SET DR K=9C



Example Statement

As Seen in Microlistings

Set DR K = 9C

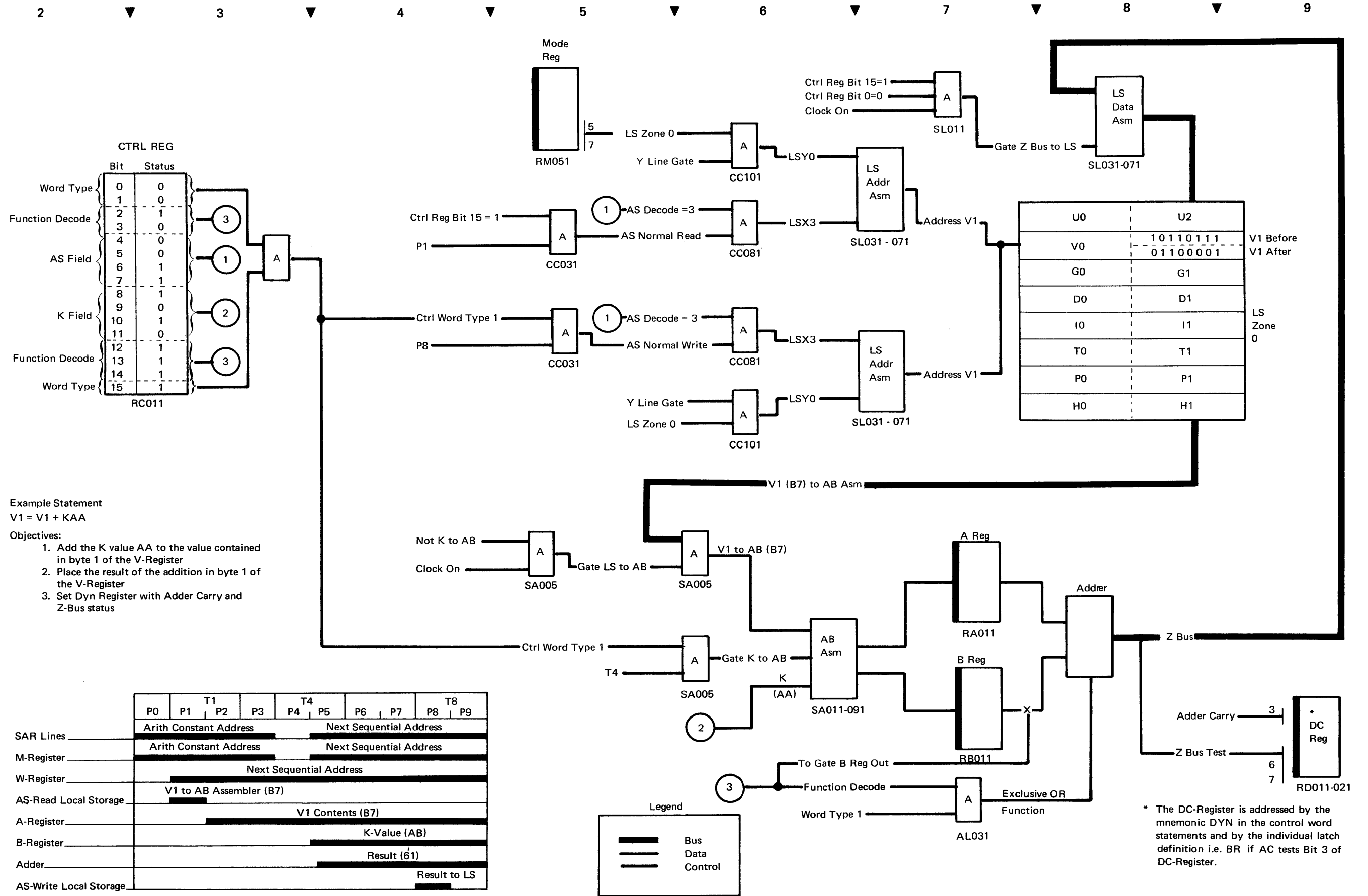
Objectives:

1. Set the DR Register to the K value of the Set/RST Word.

The DR (Diagnostic Register) is set to the value represented in the K field of the Set/RST Word.

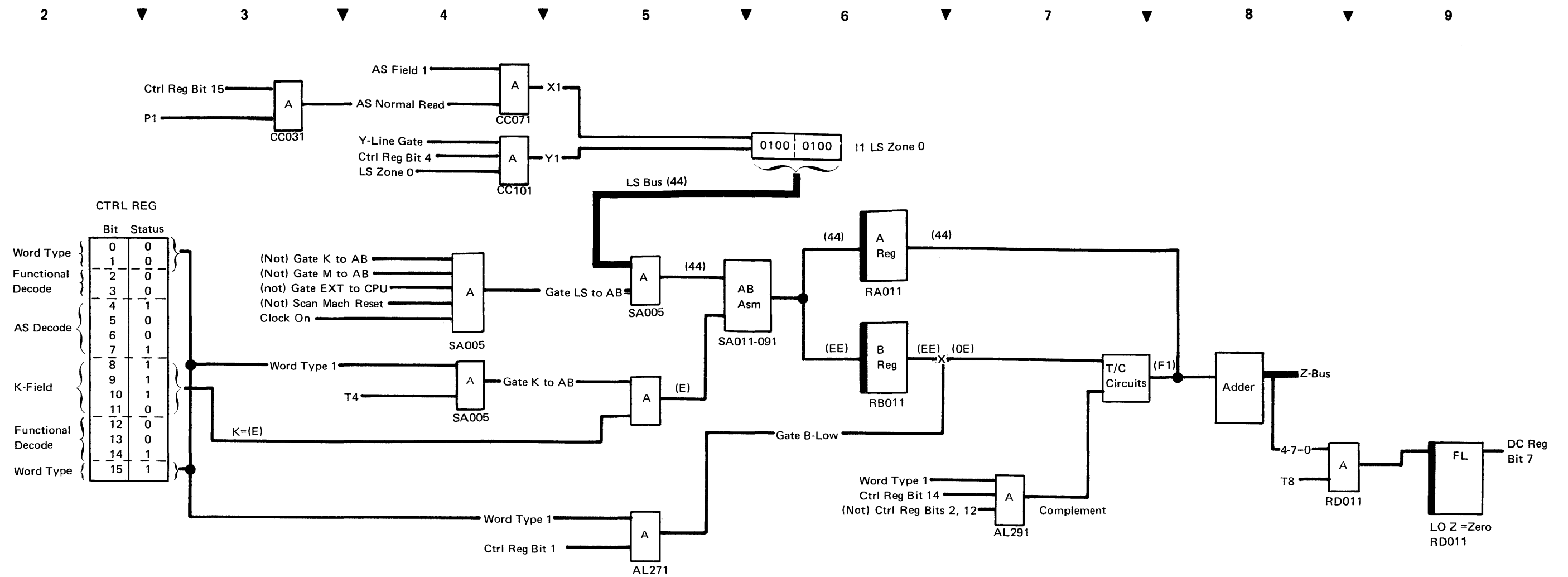
Note: The bits of the DR Register that are not addressed by bits of the K field, are reset.

Diagram 5-4. Arith Constant Word (Word Type 1)



* The DC-Register is addressed by the mnemonic DYN in the control word statements and by the individual latch definition i.e. BR if AC tests Bit 3 of DC-Register.

Diagram 5-5. Arithmetic Constant Word (Z=A, A-, KL) Type

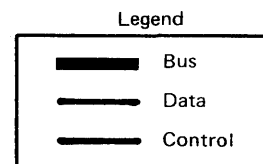


Example Statement

Z=I1, A-, KOE

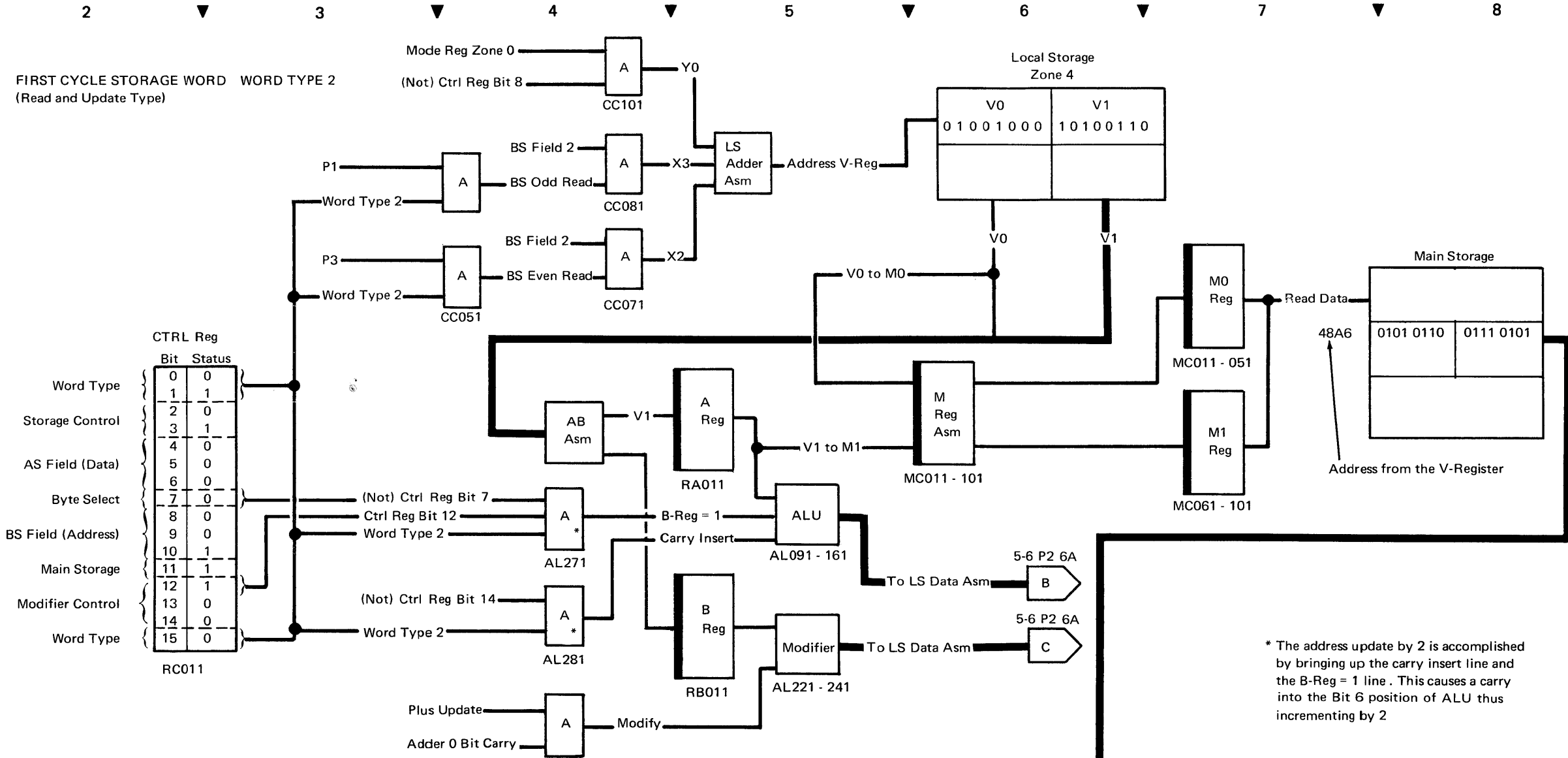
Objectives:

1. Read the byte of data from the local storage location I1. Gate to the A-Register (44).
2. Place the K-value (E) in the B-Register (EE).
3. Gate the low B-Register to the True/Complement circuits and complement.
4. AND the complement result to the A-Register. Place the result (40) on the Z-Bus.
5. Set the DC-Register 7 bit to indicate the low Z - Bus is equal to zero.



	P0	P1	T1	P2	P3	P4	T4	P5	P6	P7	P8	T8	P9
SAR Lines	Arith Constant Address				Next Sequential Address								
M-Register	Arith Constant Address				Next Sequential Address								
W-Register	Next Sequential Address												
AS Read Local Storage	I1 (44)												
A-Register	I1 Contents (44)												
B-Register	K-Value (EE)												
Adder	Result (40)												
DC Bit 7 Set												LOZ=0	

Diagram 5-6. First Cycle Storage Word (Word Type 2) (Part 1 of 2)



SECOND CYCLE STORAGE WORD WORD TYPE 2 (Read and Update Type)

FIRST HALF SECOND CYCLE

Example Word RDH U V + 2

Objectives:

1. Read the address from the V-Register Place in the M-Register (1st Cycle)
2. Read the data from Main Storage (1st Cycle)
3. Store the data read from Main Storage into the U-Register. (2nd Cycle)
4. Update by 2 the V-Register contents and store back in the V-Register(2nd Cycle)

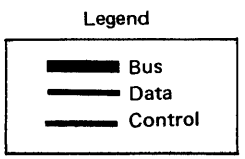
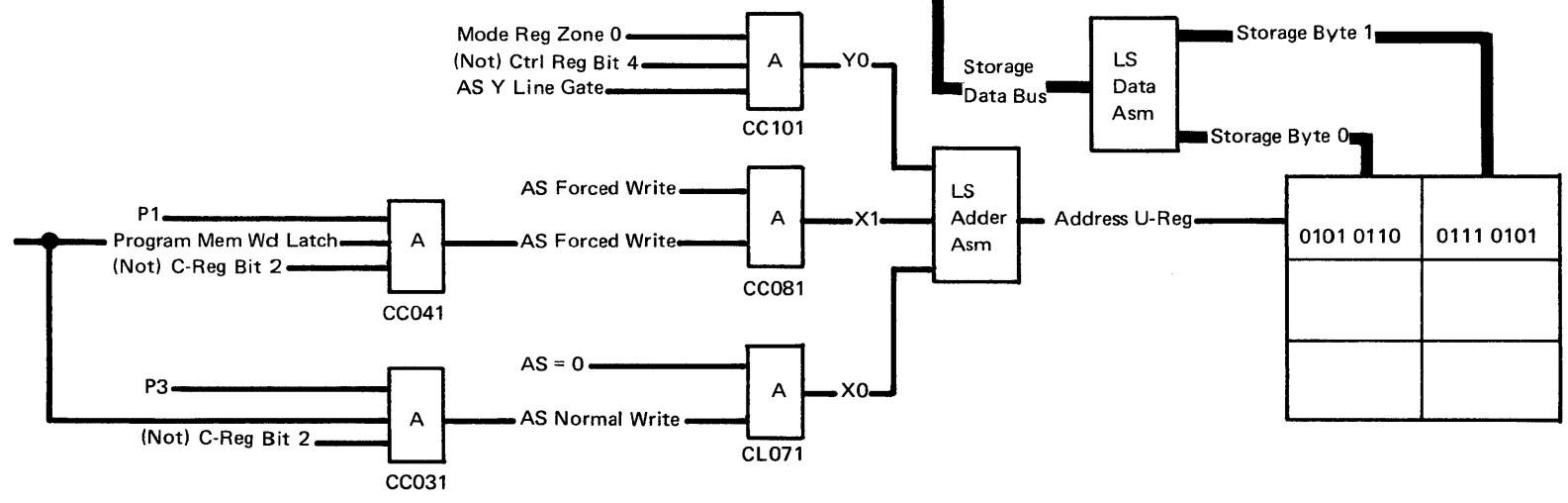
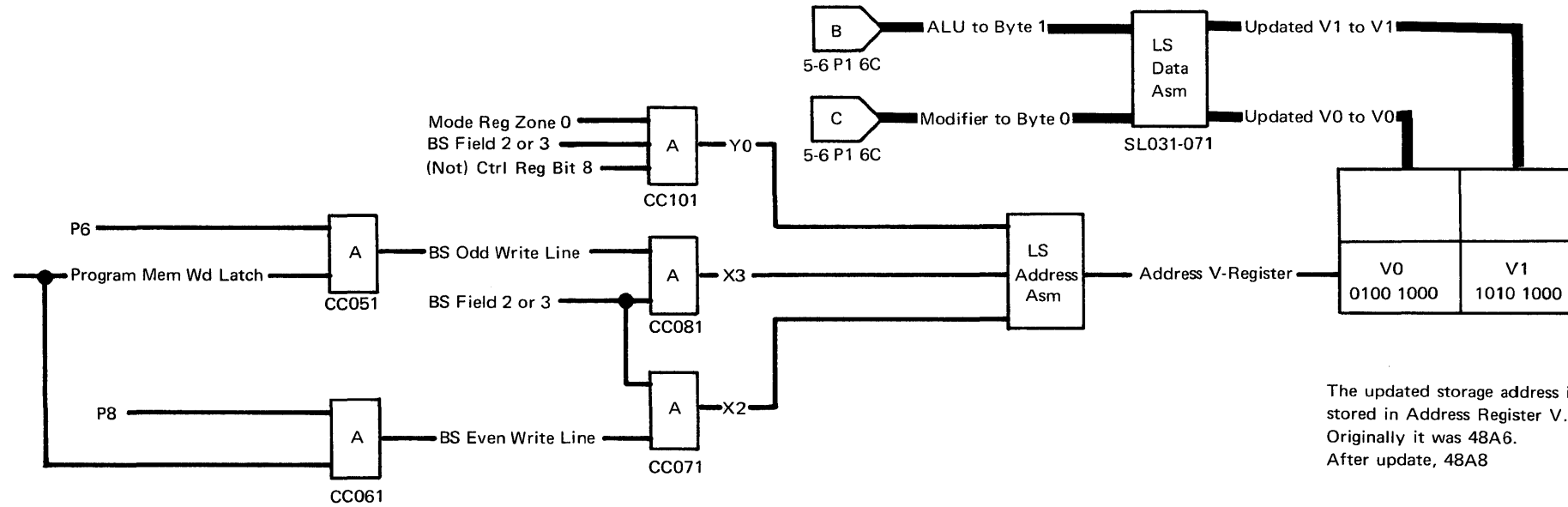


Diagram 5-6. Second Cycle Storage Word (Word Type 2) (Part 2 of 2)

2 3 4 5 6 7 8 9

SECOND HALF
SECOND CYCLE



The updated storage address is stored in Address Register V. Originally it was 48A6. After update, 48A8

	FIRST-CYCLE STORAGE WORD									SECOND-CYCLE STORAGE WORD																	
	P0	T1	P2	P3	T3	P4	P5	T5	P6	T7	P7	P8	P9	P0	T1	P2	P3	T3	P4	P5	P6	T6	P7	P8	T8	P9	
SAR Lines	Storage Word Address									Indirect Address From Local Storage (48A6)									Next Seq. Ctrl. Wd. Addr.								
M-Register	Storage Word Address									Indirect Address From Local Storage (48A6)									Next Seq. Ctrl. Wd. Addr.								
W-Register	Next Sequential Control Word Address																										
Storage Data Register	Storage Control Word (5675) Data Accessed From Storage																										
LS Odd Read	Low Byte Indirect Address (V1=A6)																										
LS Even Read	High Byte Indirect Address (V0=48)																										
LS Odd Write	Odd Data Byte (75)																										
LS Even Write	Even Data Byte (56)																										
LS Odd Write	Low Updated Indirect Address (A8)																										
LS Even Write	High Updated Indirect Address (48)																										
A-Register	Low Byte Indirect Address (V1=A6)																										
B-Register	High Byte Indirect Address (V0=48)																										
Adder	Updated Low Indirect Address (A8)																										
Modifier	No Adder Carry-High Byte Indirect Address (48)																										

Legend

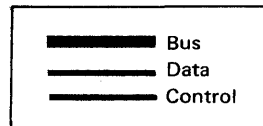


Diagram 5-7. Storage Word (Double Byte Modify) Word Type 2

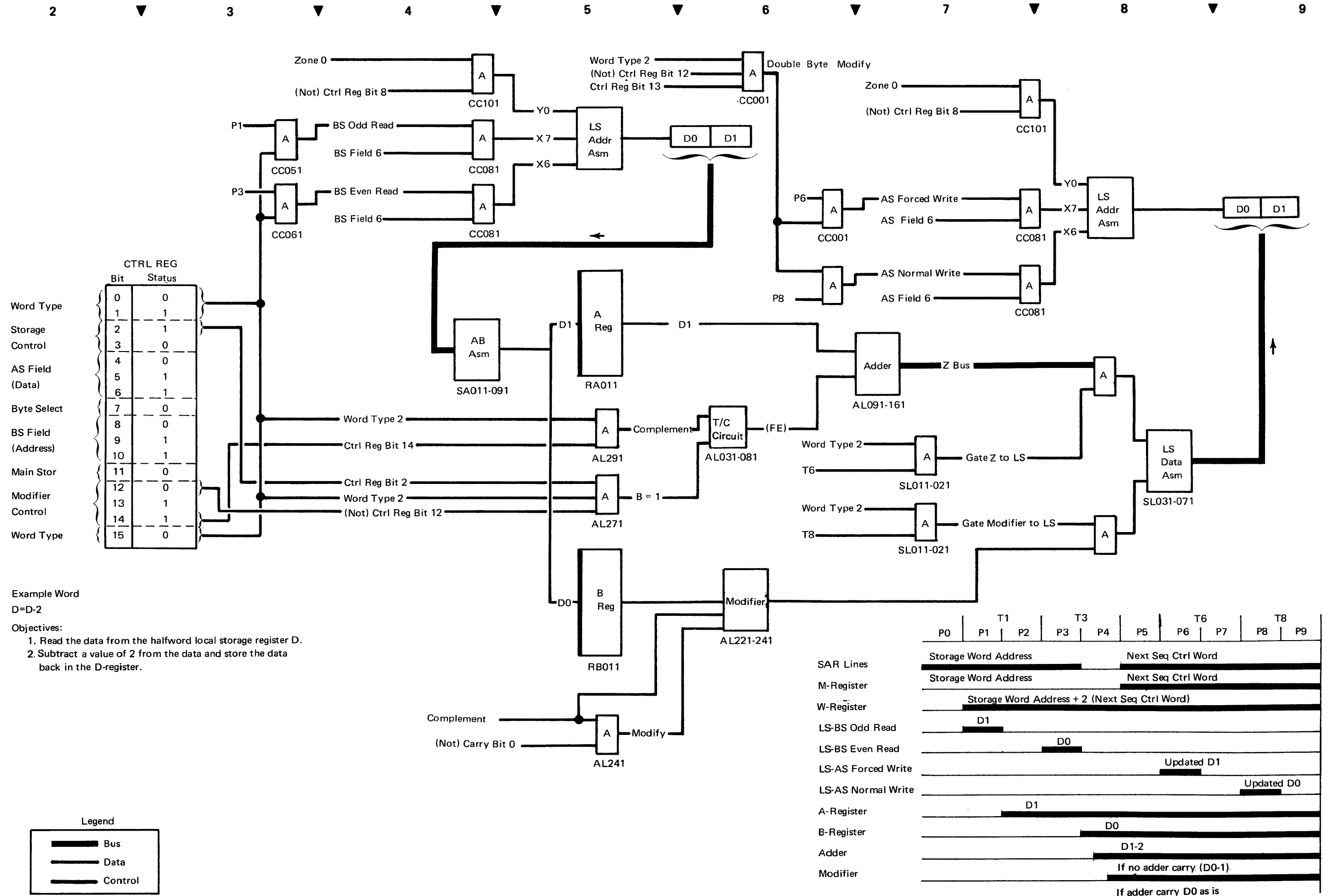
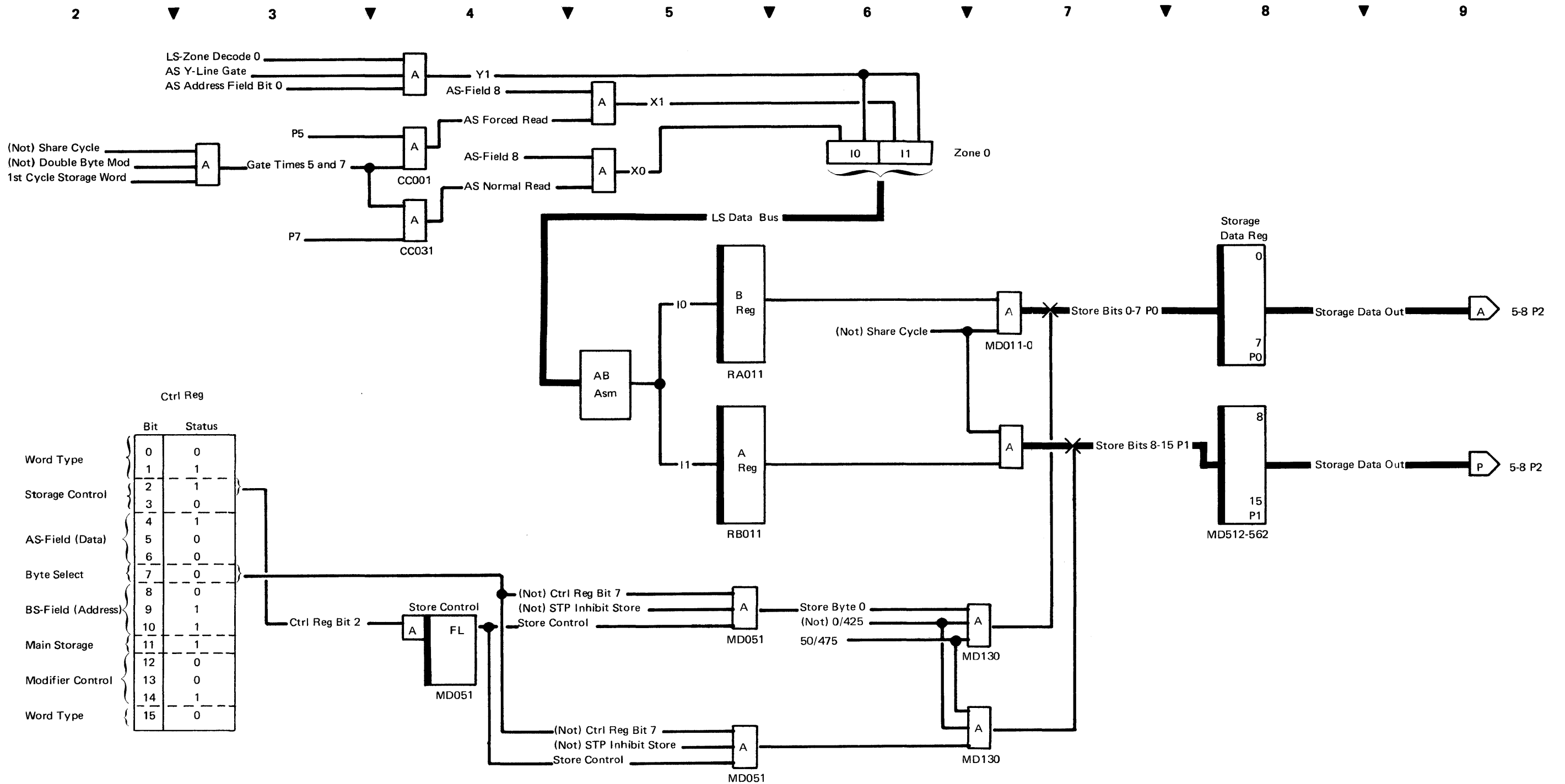


Diagram 5-8. Direct Addressable Control Storage, Storage Word Type 2 (Part 1 of 2)



Ctrl Reg	
Bit	Status
0	0
1	1
2	1
3	0
4	1
5	0
6	0
7	0
8	0
9	1
10	1
11	1
12	0
13	0
14	1
15	0

Example Word

STH I DC,9E

Objectives:

1. Read out the halfword located in the I-Register
f local storage.
2. Store the halfword at the direct control storage address (9E).

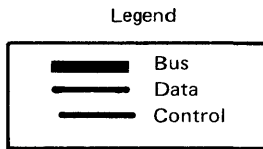
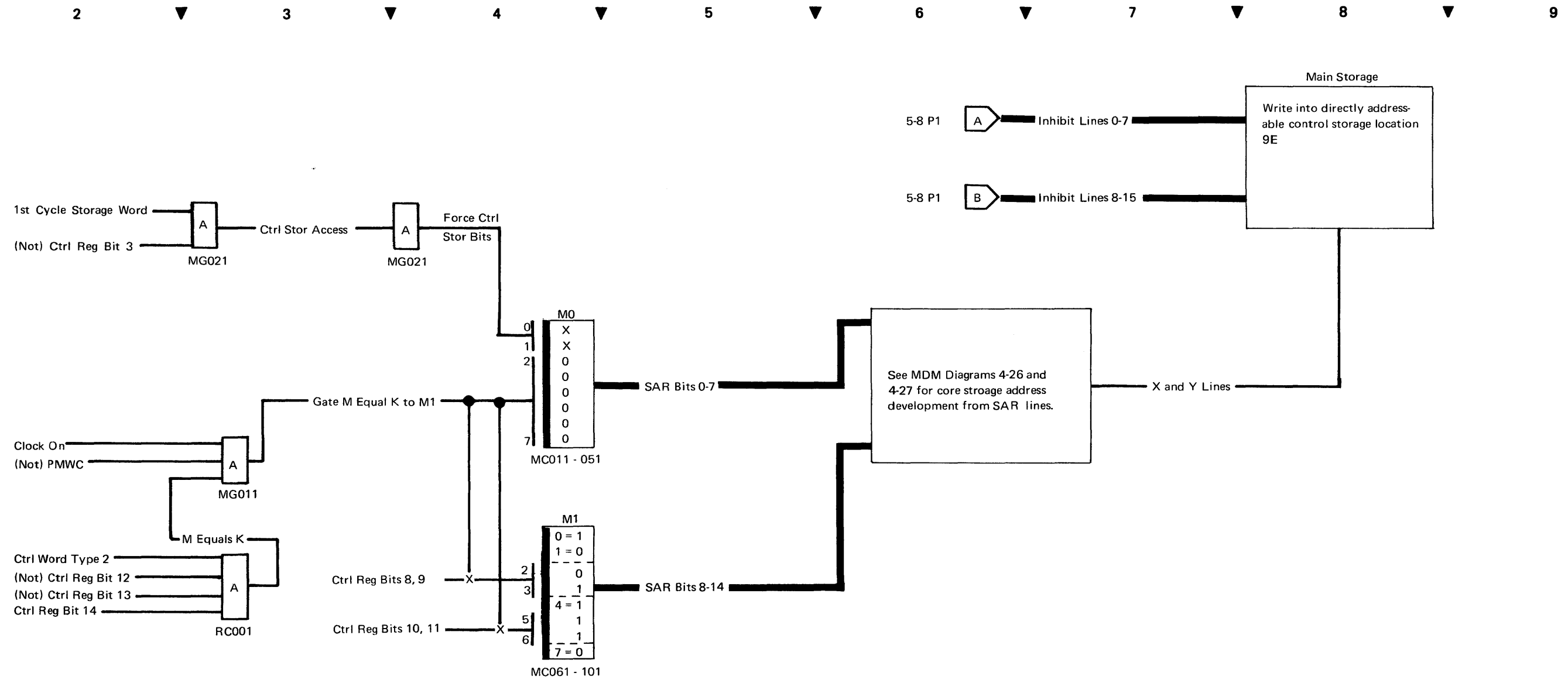


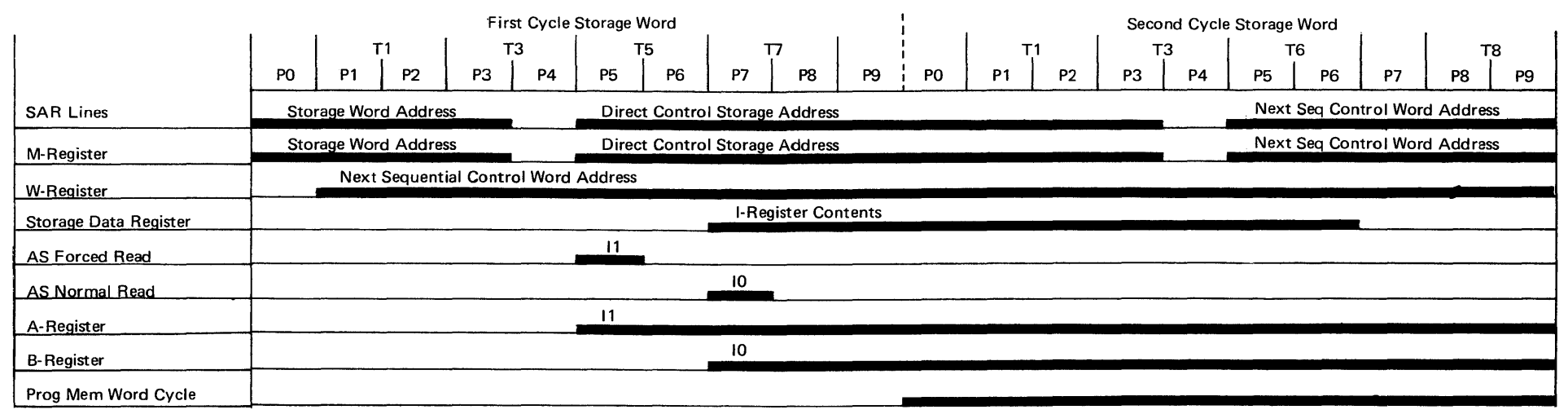
Diagram 5-8. Direct Addressable Control Storage, Storage Word Type 2 (Part 2 of 2)



Bits 0 and 1 of M0 are set according to storage size:

Core Size	Bits 01
16K	01
24K	10
32K	10
48K	11

Bits 0 and 4 of M1 are forced to 1.
 Bits 1 and 7 of M1 are forced to 0.
 Bits 2, 3, 5, and 6 are set by Ctrl Reg Bits 8, 9, 10, and 11 respectively.



Refer to MDM Diagram 4-27 for write timing into core storage.

Diagram 5-9 Move/Arithmetic Word (Word Type 3)

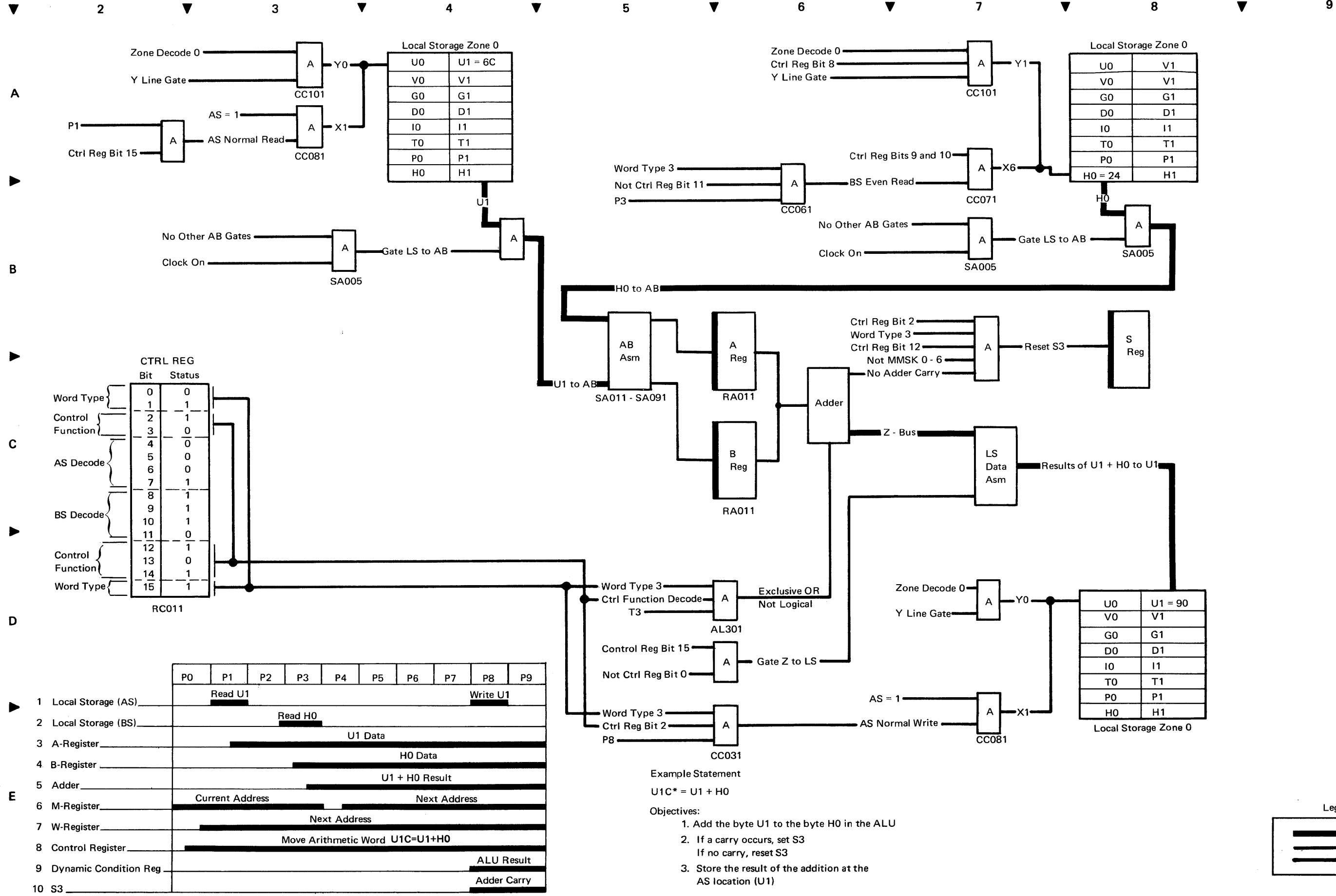


Diagram 5-10. Move/Arithmetic Word (External to LS Move)

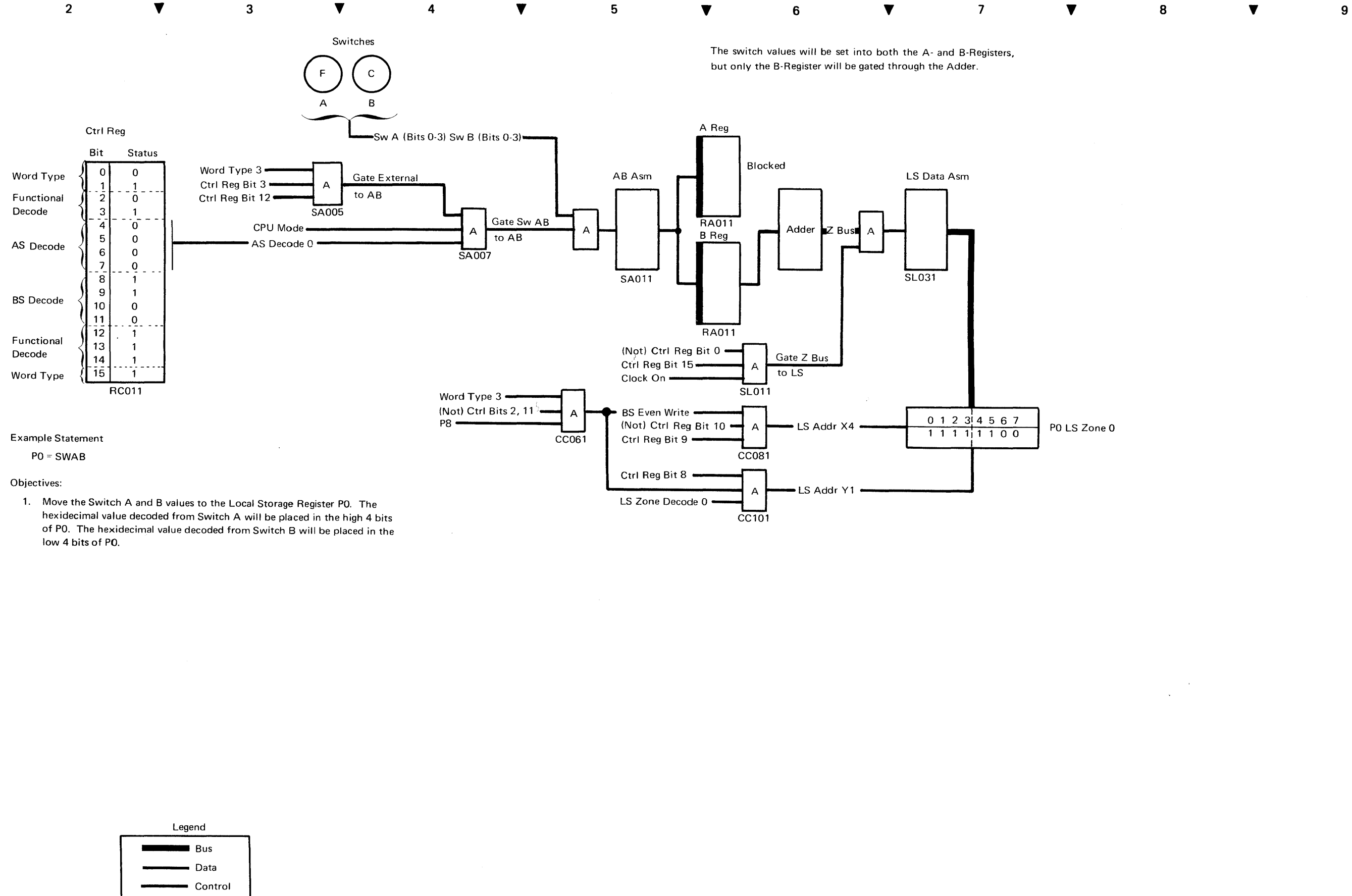
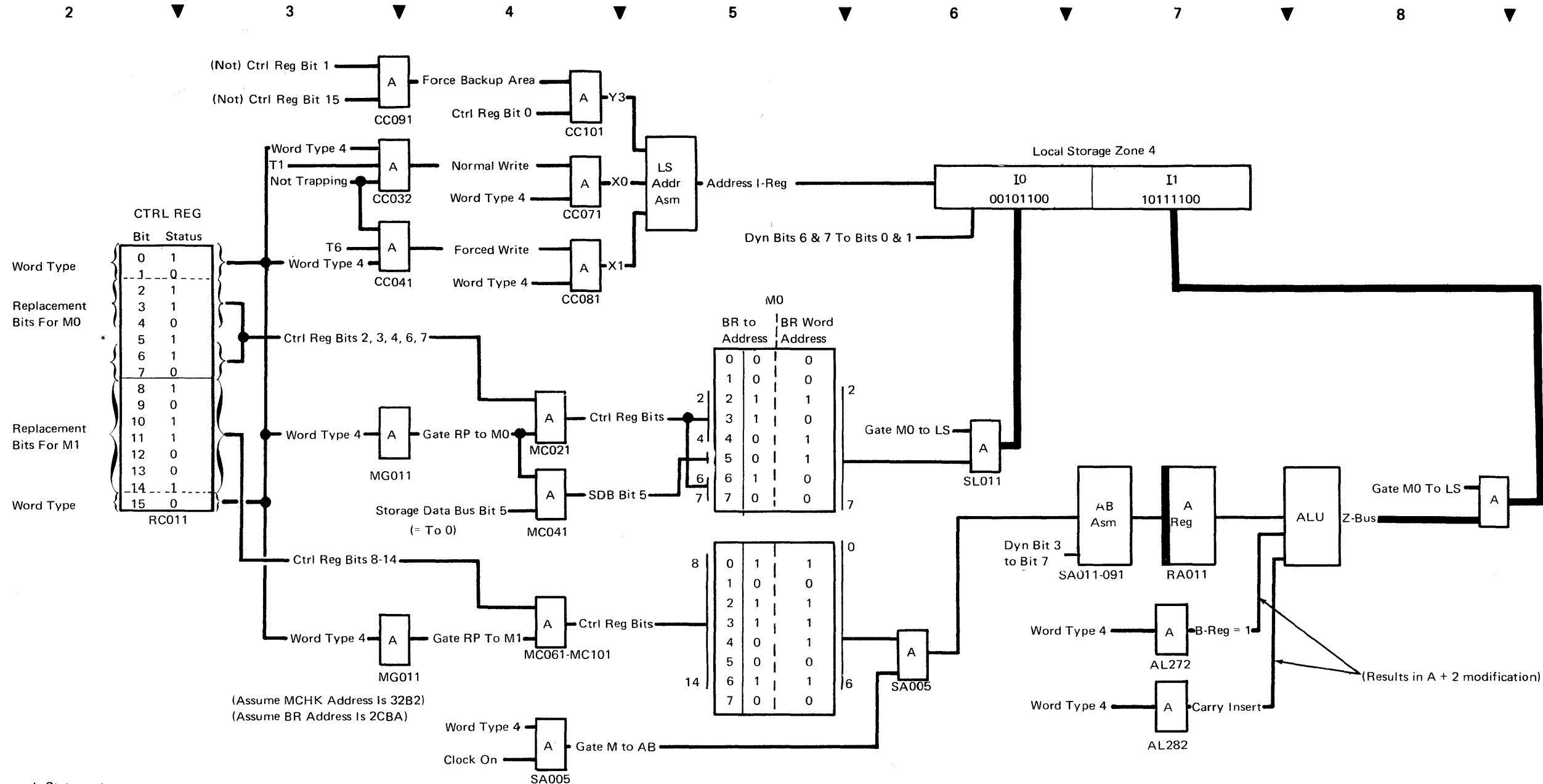


Diagram 5-11. Unconditional Branch Word (Word Type 4)



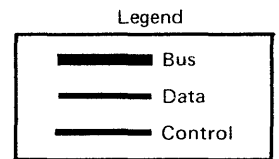
D Example Statement

Next Address	Statement
MCHK	BR

Objective:

1. Replace the designated M0 and M1 Bits with the replacement bits from the BR control word. The address of the BR word will be incremented by 2 and stored in the I-Register backup area (Zone 4). There is no bit distinction between a BAL (Branch and Link) and a BR word

* Ctrl Reg Bit 5 is set to a 1 for this word, as it is for a BR conditional and branch mask word. The storage data bus bit 5 is used as the replacement bit 5 for the M0 register.

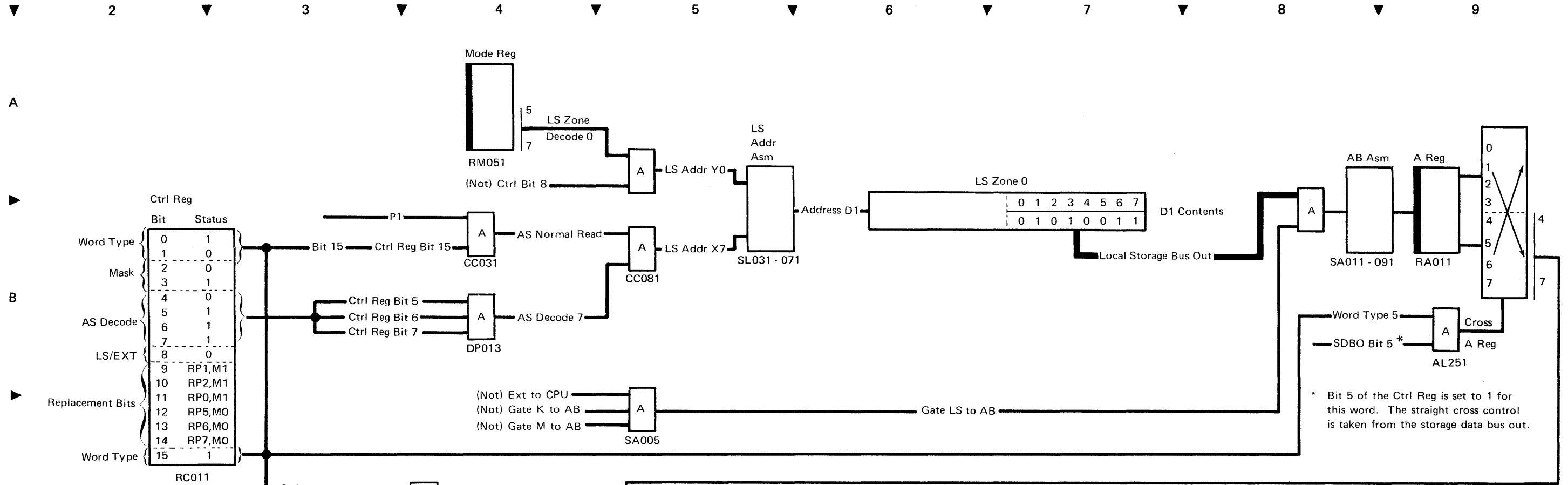


	P0	T1	P2	P3	P4	P5	T6	P7	P8	P9
SAR Lines	BR UNC Address (2CBA)			Branch to Address (32B2)						
M-Register	BR UNC Address (2CBA)			Branch to Address (32B2)						
W-Register	BR UNC Address + 2 (Not Gated) (2CBC)									
*Normal Write LS (Even)	M0-Reg Contents ** (2C)									
A-Register	M1-Register Contents (BA)									
Adder	M1-Register Contents + 2 (BC)									
*Forced Write LS (Odd)	M1-Reg + 2 ** (BC)									

*The address of the next sequential control word following the branch unconditional word is stored in the I-Register of local storage zone 4. This is done whether the word is designated BR or BAL on the microlisting.

**DYN-Register Bits 6 and 7 are stored in Bits 0, 1 of I0 at P1 time. DYN-Register Bit 3 is stored in Bit 7 of I1 at P6 time.

Diagram 5-12. Branch on Mask Word (Word Type 5)



Example Statement

N = D1 Bits 1 2 3

Objectives:

1. Address the D1 byte in Local Storage for the zone in effect; in this example zone 0.
2. Use bits 1, 2, and 3 of D1 to set bits 4, 5, and 6 of M1.
3. Insert the replacement bits from the control word into M0 and M1.

Assume: Ctrl Reg Bit 9 = 0, 10 = 1, 11 = 1
 12 = 1, 13 = 0, 14 = 1

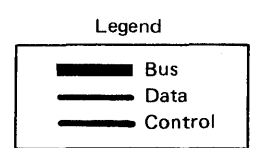
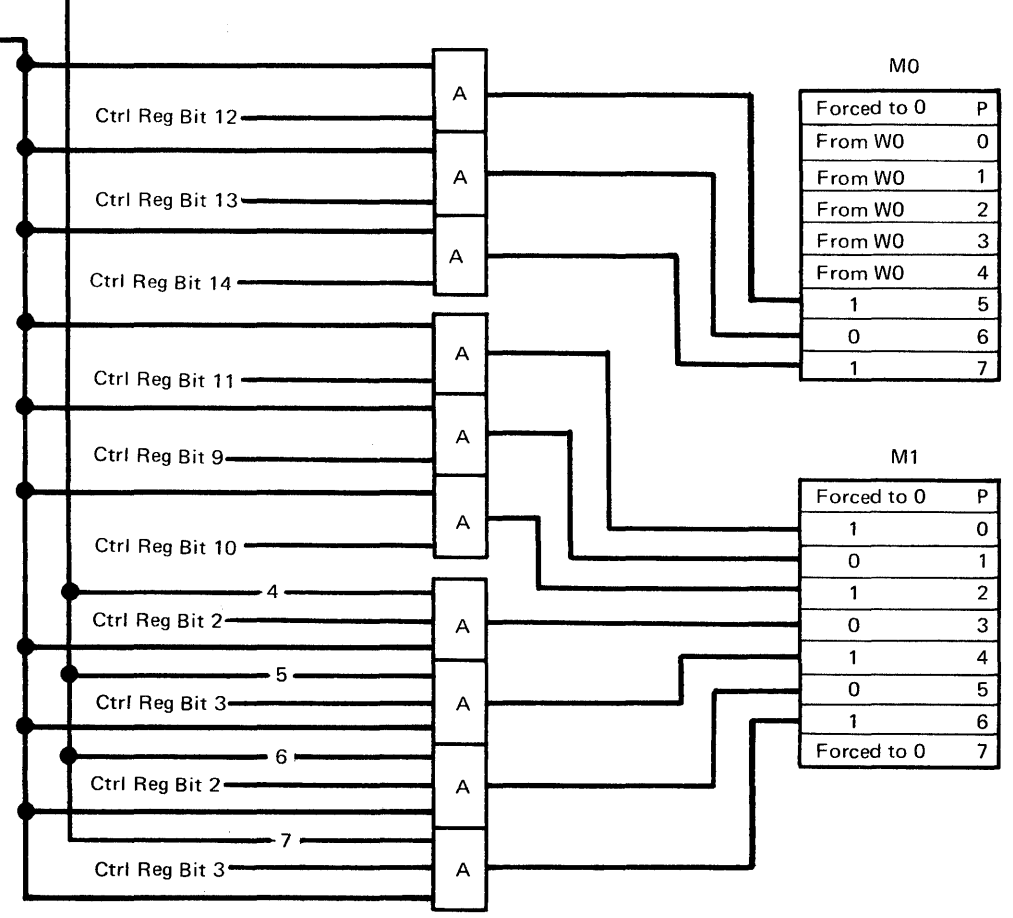
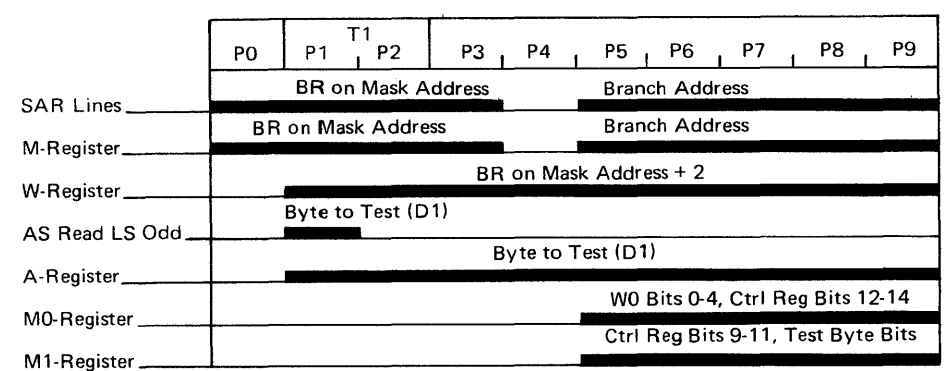
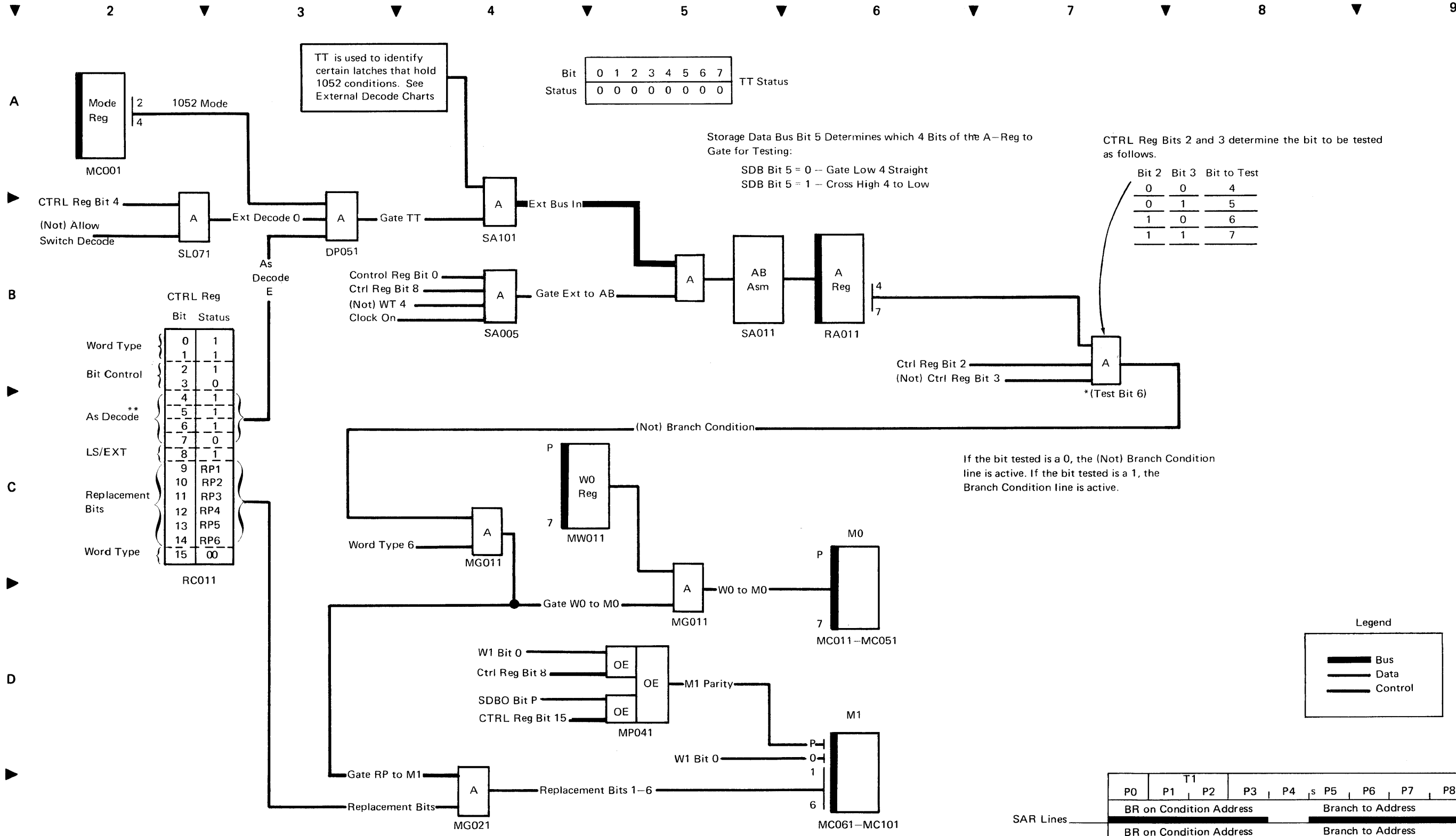


Diagram 5-13. Branch on Condition Word (Word Type 6 or 7)



Example Statement
 BR IF TT Bit 6=0

Objectives:

1. Address the External facility TT which contains information pertaining to 1052 Status.
2. Branch to an address specified by the replacement bits in the control word if bit 6 of TT = 0. (Branching takes place by loading the M1 Register with the replacement bits).

* Bit 6 of TT, if equal to 1, indicates 1052 request.

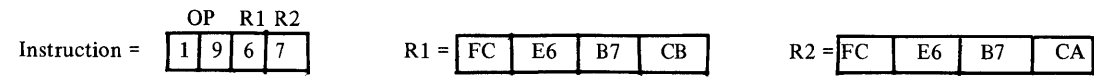
** Bit 5 of the CTRL Register is forced to a 1 for this word. Storage Data Bus Bit 5 is tested for A-Register straight or cross gating.

	P0	T1		P3	P4	P5	P6	P7	P8	P9
SAR Lines	BR on Condition Address				Branch to Address					
M-Register	BR on Condition Address				Branch to Address					
W-Register	BR on Condition Address + 2 (Partially Gated)									
External Access	Byte to Test (TT)									
A-Register	Byte to Test (TT)									
M0-Register	W0 Register									
M1-Register	W1 Bit 1, Ctrl Reg Bits 9-14									

Diagram 5-14. Machine Listing Operational Example (Compare Op)

Hex addr	Hex wrd	Next addr	Name	Next label CICY	Statement	Comments	Statement No.
12E6	5498		I-Start 3		RDH G I+2		CICY008
12E8	B435	CICY016		OPHI N	N=G0H		CICY009
12A2	B015	CICY148	OPHI 1	OPIX N	N=G0L		CICY017
1292	AABC	CBIN005	OPIX 9	CBIN RROP19	BR		CICY157
CBIN							
2ABC	9F64	CCOM036	RROP19	CCOM CRGET	BAL		CBIN005
CCOM							
IF64	55B3		CRGET		T1=G1XH		CCOM036
IF66	52A8				RDH V AS,T+2		CCOM037
IF68	50AA				RDH U AS,T-2		CCOM038
IF6A	55BB				T1=G1H		CCOM039
IF6C	56A8				RDH D AS,T+2		CCOM040
IF6E	5EAA				BDH H AS,T-2		CCOM041
IF70	100E				RST S K=F0		CCOM042
IF72	128E				RTN		CCOM043
CBIN							
2ABE	924A	CBIN009		CXCOMP	BR		CBIN006
124A	B69A	CCOM086		CXCOMP	CCOM CSLOOP	BAL	CBIN009
CCOM							
369A	3002		CSLOOP		SET S K=90		CCOM086
369C	7F1D		CXLOOP		H1C=H1,+ ,U1+C		CCOM087
369E	7E0D				H0C=H0,+ ,U0+C		CCOM088
36A1	773D				D1C=D1,+ ,V1+C		CCOM089
36A2	762D				D0C=D0,+ ,V0+C		CCOM090
36A4	1288				RTN		CCOM091
CBIN							
124C	E4D0	CBIN012		OVER	BR IF NOVFL		CBIN010
124E	168D				D0=D0,OE,K80		CBIN011
1250	E5D7	CBIN015	OVER	NZO	BR IF S2=1		CBIN012
1252	2C07				P0=0		CBIN013
1254	81F5	CICY005			CICY ISTART N N=S BITS67		CBIN014
1256	C645	CBIN018	NZO	ALOW	BR IF D0.0=1		CBIN015
1258	2C25				P0=0,OR,K20		CBIN016
125A	81F5	CICY005			CICY ISTART N N=S BITS67		CBIN017
1244	2C35		ALOW		P0=0,OR,K30		CBIN018
1246	81F5	CICY005			CICY ISTART N N=S BITS67		CBIN019

This example shows only the portion of each microroutine used by the compare op. The control words in the final CBIN routine block that are not used are shaded.



Read out instruction and place in G-register. G =

19	67
----	----

Test Op-code and branch to proper routine.

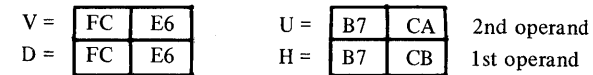
Branch to common routine to read out operands.

Read out operands and place in local storage in preparation for compare.

T-register is set up to use as an indirect address register.

First, read out general purpose reg 7 (2nd operand).

Then read out general purpose reg 6 (1st operand).



Branch to common routine to compare.

Set S0 to indicate complement addition.

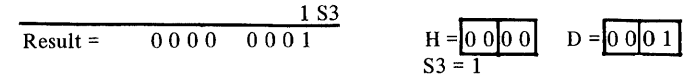
Set S3 to provide "Hot One" for first addition.

2nd operand is complemented and added to 1st operand.

1st oper = F C E 6 B 7 C B

Comp

2nd oper = 0 3 1 9 4 8 3 4



Test for adder overflow. There is none, therefore, the branch is taken to test S2. S2 is set to 1 during the complement addition performed in the CCOM routine to indicate that the result was not zero.

Branch to test D0 bit 0. D0 bit 0 is not one, therefore, P0 is set to a value of 20. The high hex digit of P0 is the condition code; a hex 2 indicates that the first operand is larger than the second operand.

Branch to I cycles to continue machine instruction processing.

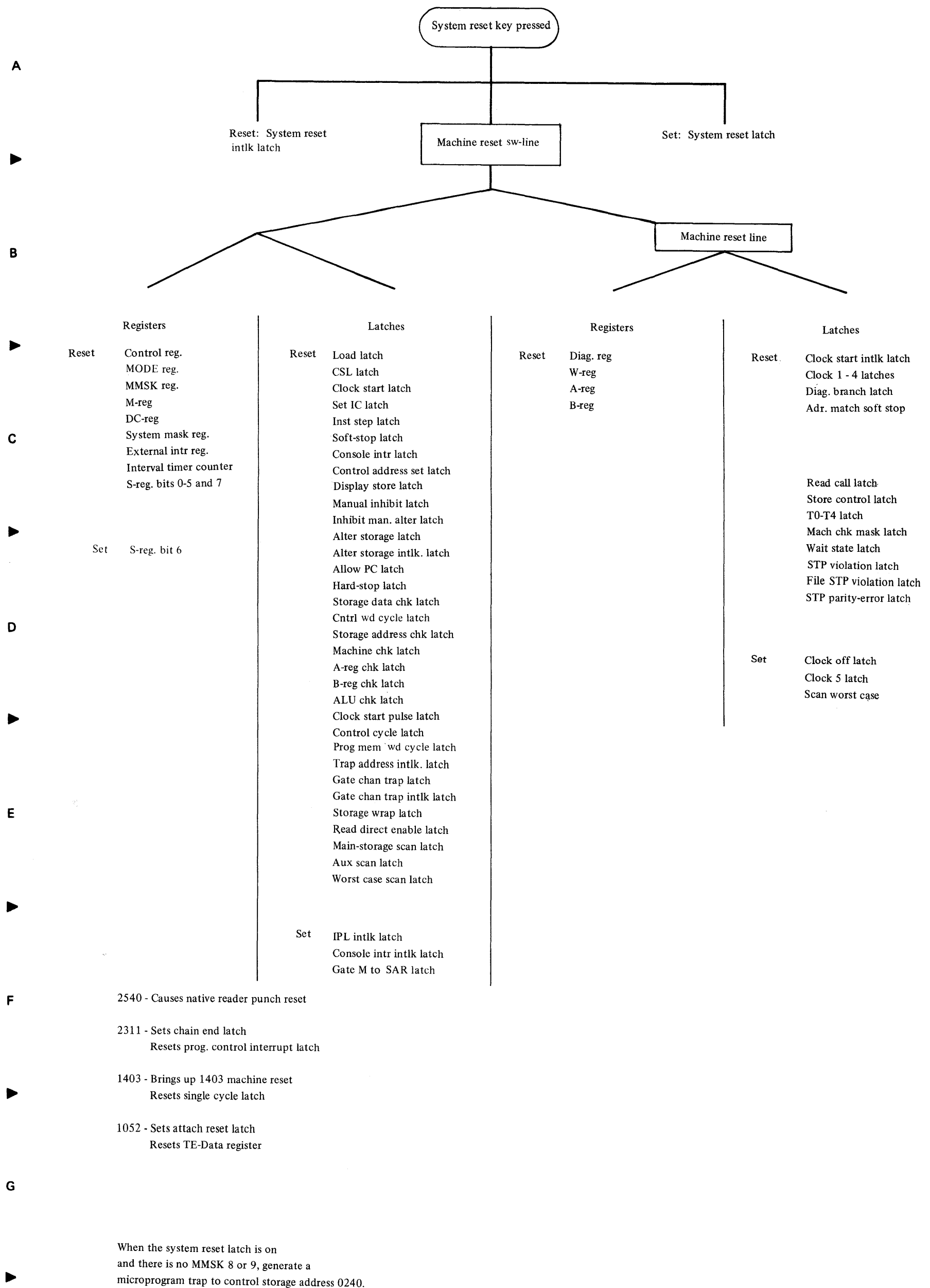
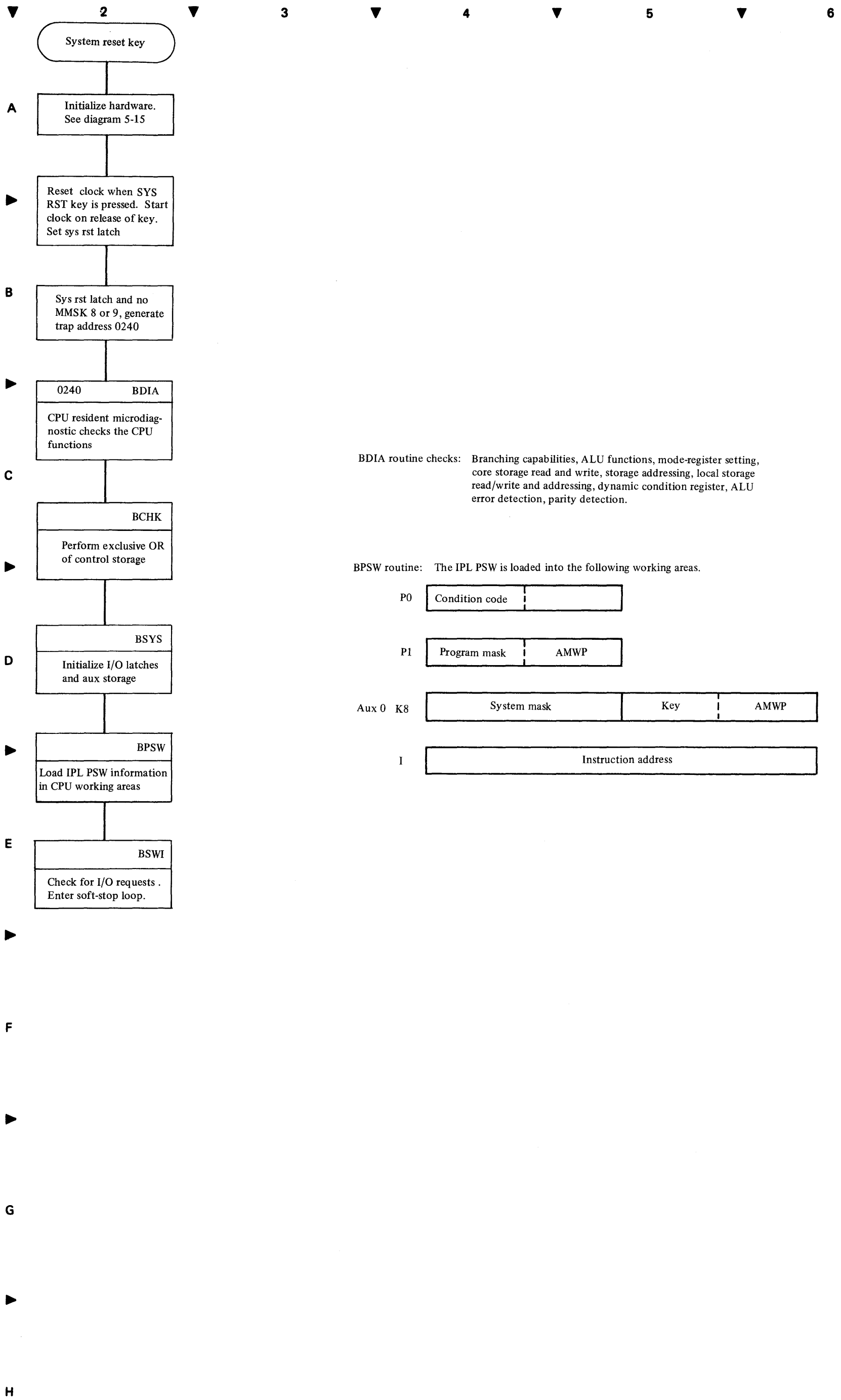


Diagram 5-15. System Reset Key Hardware Function



BDIA routine checks: Branching capabilities, ALU functions, mode-register setting, core storage read and write, storage addressing, local storage read/write and addressing, dynamic condition register, ALU error detection, parity detection.

BPSW routine: The IPL PSW is loaded into the following working areas.

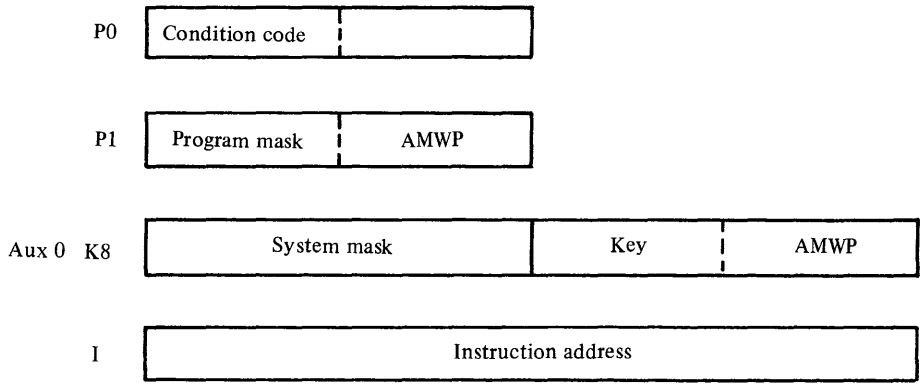
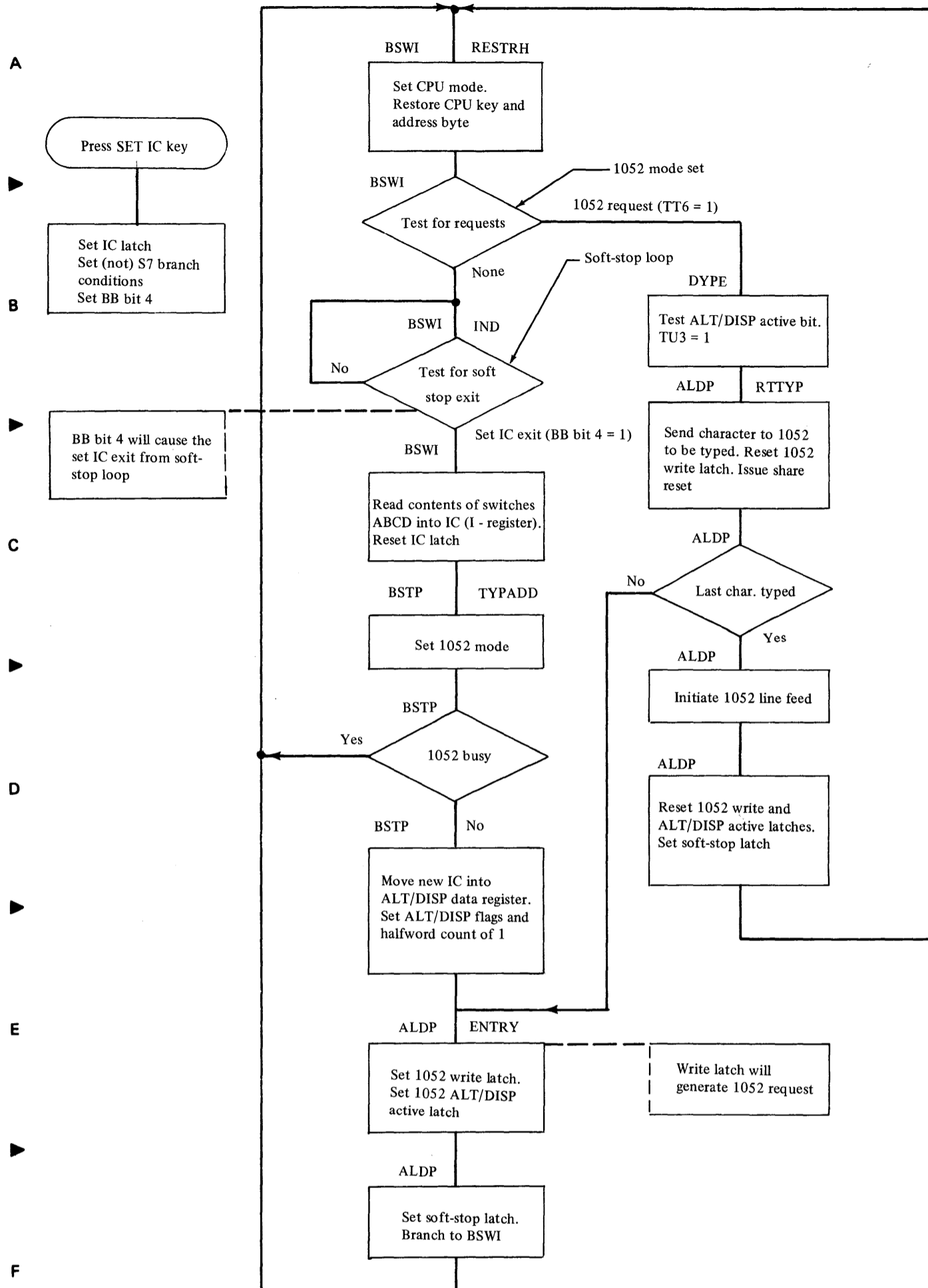


Diagram 5-16. System Reset Key



The SET IC key is effective only in the soft-stop condition.

Objectives:

1. Set IC latch.
2. Exit from soft-stop loop.
3. Place address from switches ABCD into instruction counter.
4. Print new address on the 1052.
5. Return to soft-stop loop.

Diagram 5-17. Set I C Key Function

Conditions:

Microprogram is in soft-stop loop. Assume that the previous operation was set 1C or address stop.

Objectives:

1. Turn mode switch to insn step position.
2. Press start key to exit from soft-stop loop.
3. Execute current instruction.
4. Return to 1-cycles and recognize (not) S7 branch condition.
5. Set insn step latch (BC0).
6. Type out instruction counter. Return to soft-stop loop to await PR-KB request after each character or function.
7. Wait in soft-stop loop until start key is pressed again (step 2).

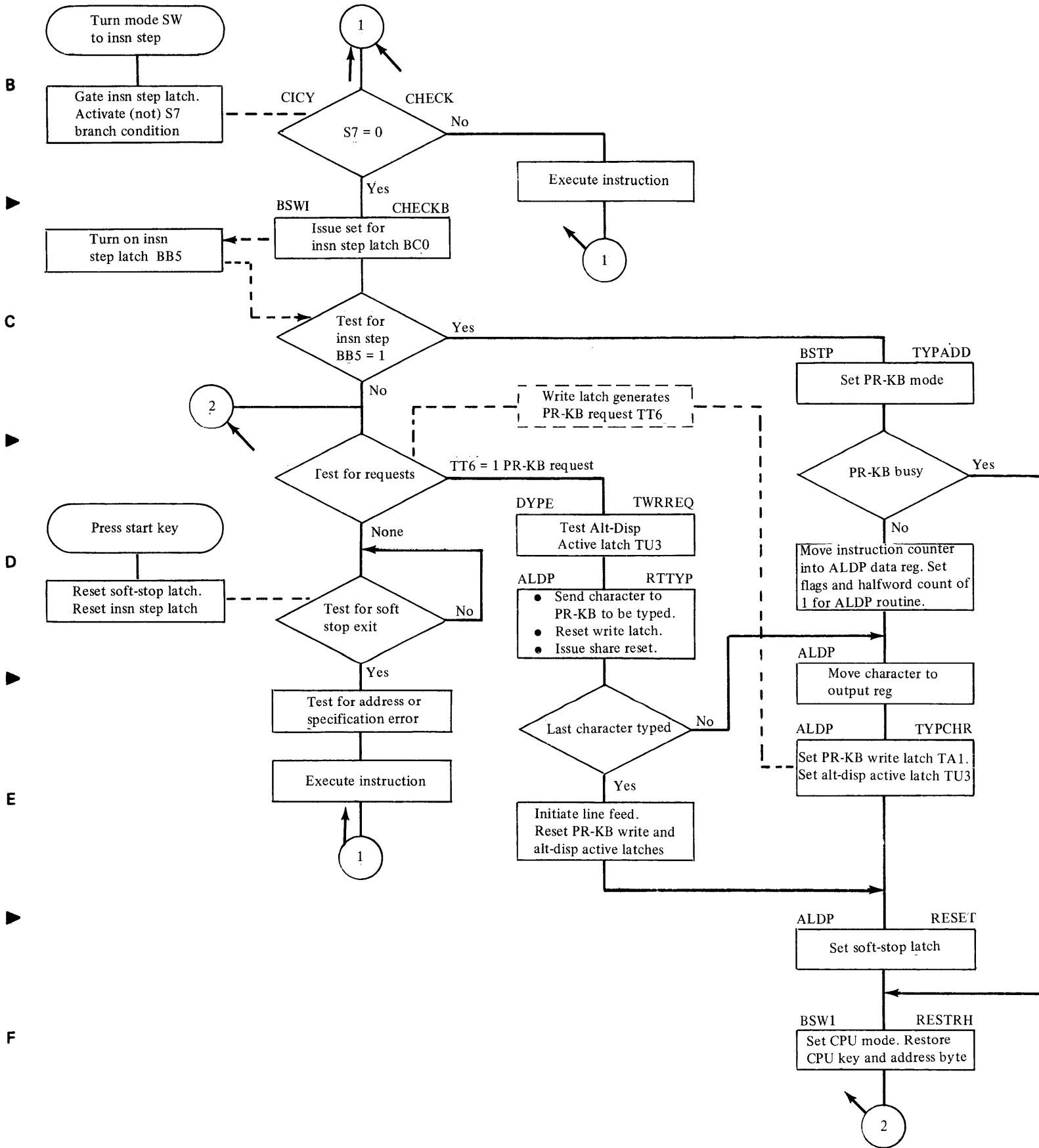


Diagram 5-18. Instruction Step Function

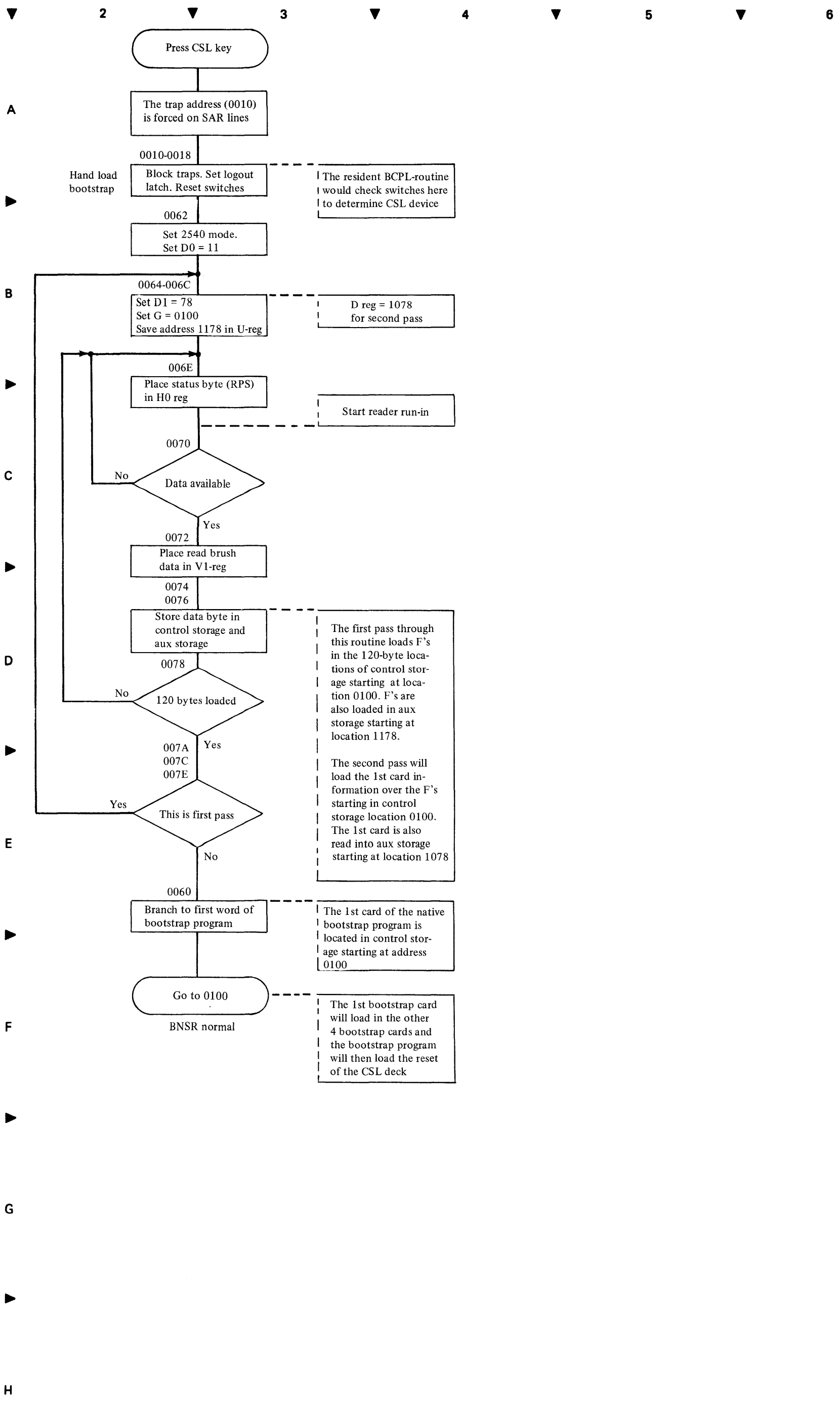
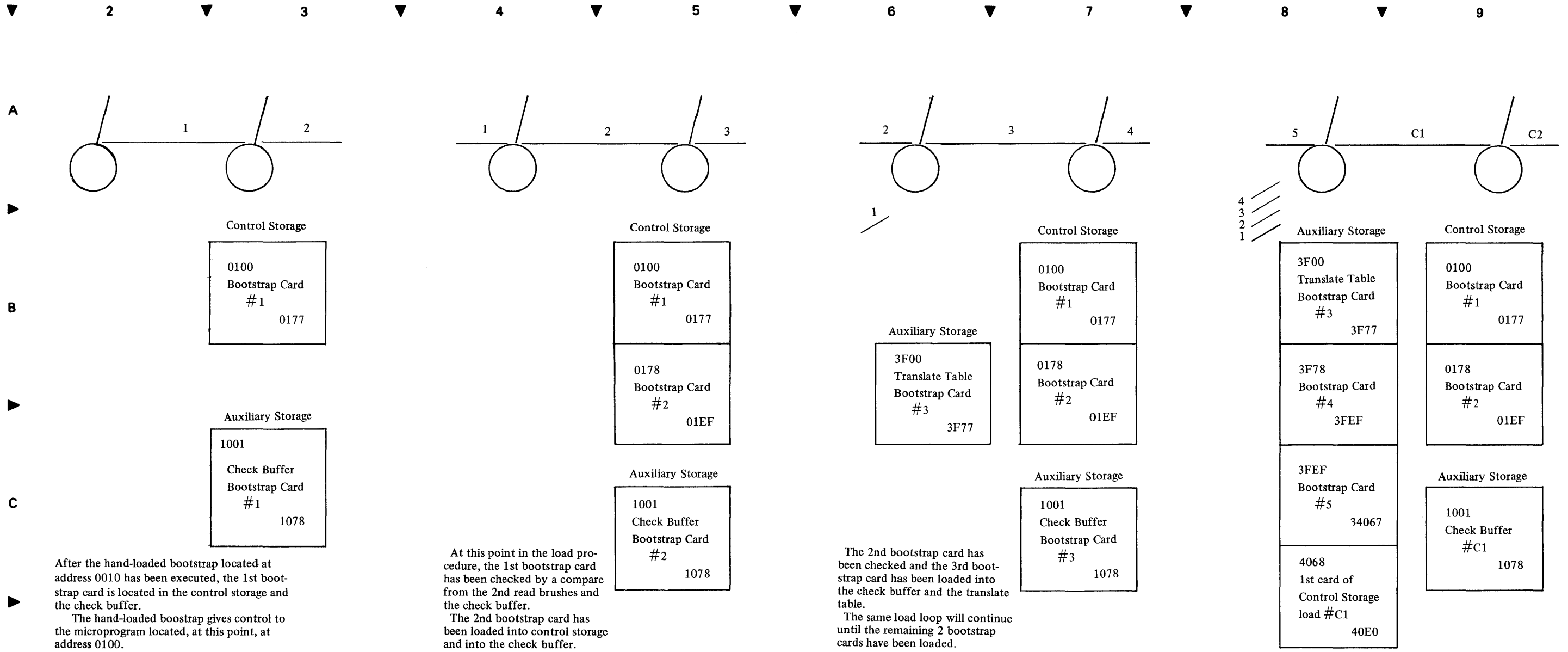


Diagram 5-19. CSL for Integrated 2540 (Part 1 of 3)



After the hand-loaded bootstrap located at address 0010 has been executed, the 1st bootstrap card is located in the control storage and the check buffer.
 The hand-loaded bootstrap gives control to the microprogram located, at this point, at address 0100.
 The second bootstrap card load and 1st bootstrap card check begin.

At this point in the load procedure, the 1st bootstrap card has been checked by a compare from the 2nd read brushes and the check buffer.
 The 2nd bootstrap card has been loaded into control storage and into the check buffer.

The 2nd bootstrap card has been checked and the 3rd bootstrap card has been loaded into the check buffer and the translate table.
 The same load loop will continue until the remaining 2 bootstrap cards have been loaded.

All 5 bootstrap cards have now been loaded and the 1st card of the CSL deck has been loaded into the check buffer and into a portion of auxiliary storage beneath the translate table.
 As the C1 card is read at the 2nd read brushes, the bootstrap program builds a translate table address area (1080 - 10F7) in aux stor.
 The addresses formed will be used to address the translate table, built by cards 3, 4 and 5, to find the hex values to be loaded into control storage.

Card Image Example For First Card Of CSL Deck See CHART 2

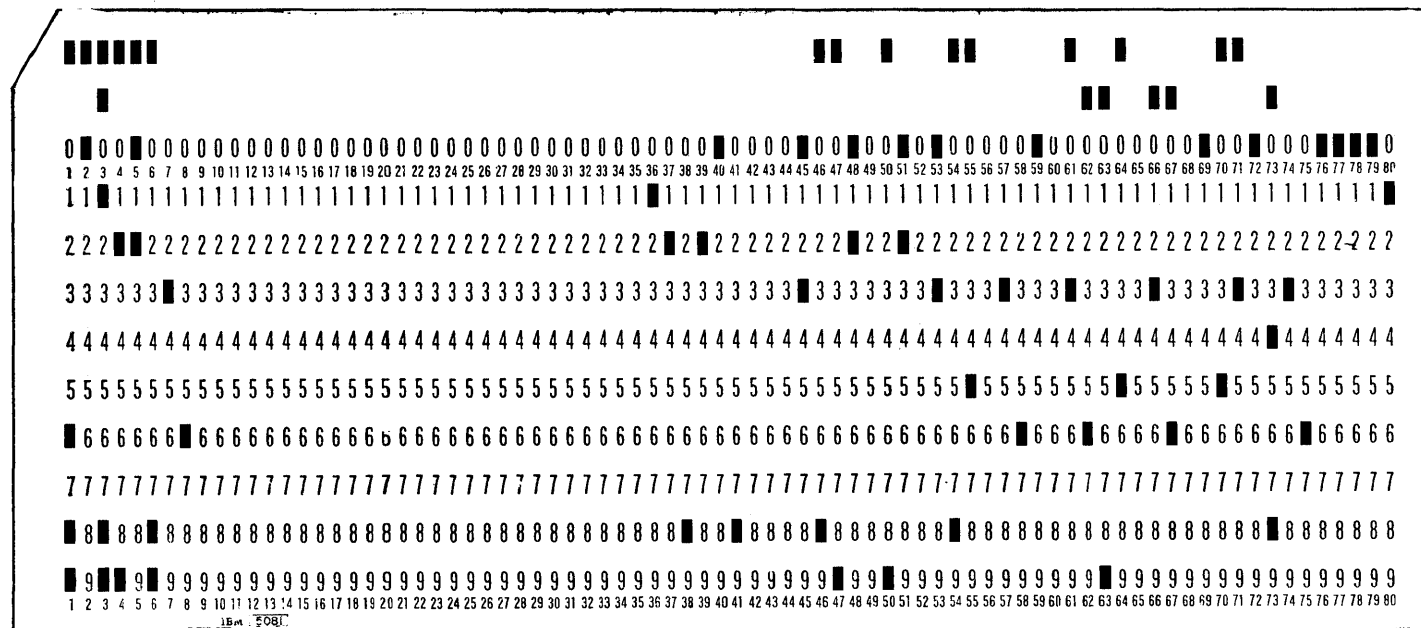


Diagram 5-19. CSL for Integrated 2540 (Part 3 of 3)

2 Entry point for the start of CSL READ is at label

BNSR NORMAL

As the CSL card is read at the 2nd read brushes it is checked against the check buffer. The translate table address area is built.

For each row that is read and tested, a specific bit combination is ORed into the table whenever a punch is detected in a column.

Bit Combination	Row
40	9
80	8
07	7
06	6
05	5
04	4
03	3
02	2
01	1
08	0
10	11
20	12

The table development shown in this diagram uses the card shown in diagram 5-15 Chart 1.

After the address table is built, the bootstrap program uses the address table to address the translate table to look up the hex data to be used in the loading of storage.

3

9-Row

Column	1	2	3	4	5	6	7	8
Starting Address	40	40	40	40				
is 1080								
Aux Storage								
9								
17								
25								
33								
41							40	
49	40							
51							40	
65								
73								

8-Row

C0	C0	40	C0					
80								
	40							
80								

7-Row

C0	C0	40	C0					
80								
	40							
80								

5

6-Row

C6	C0	40	C0					06
80								
	40							
	06							
80	06							

5-Row

C6	C0	40	C0					06
80								
	40							
	06							
80	06							

4-Row

C6	C0	40	C0					01
80								
	40							
	06							
84	06							

6

3-Row

C6	C0	40		C0	03	06
80						
	40					
	03	06				
84	03	06				

2-Row

C6	C0	42	02	C0	03	06
80						
	40	02				
	03	06				
84	03	06				

1-Row

C6	C1	42	02	C0	03	06
80						
	40	02				
	03	06				
84	03	06				

7

0-Row

C6	08	C1	42	0A	C0	03	06
80							
84							

11-Row

C6	08	D1	42	0A	C0	03	06
80							
94							

12-Row

E6	28	F1	62	2A	E0	03	06
80							
94							

A

▲

B

▲

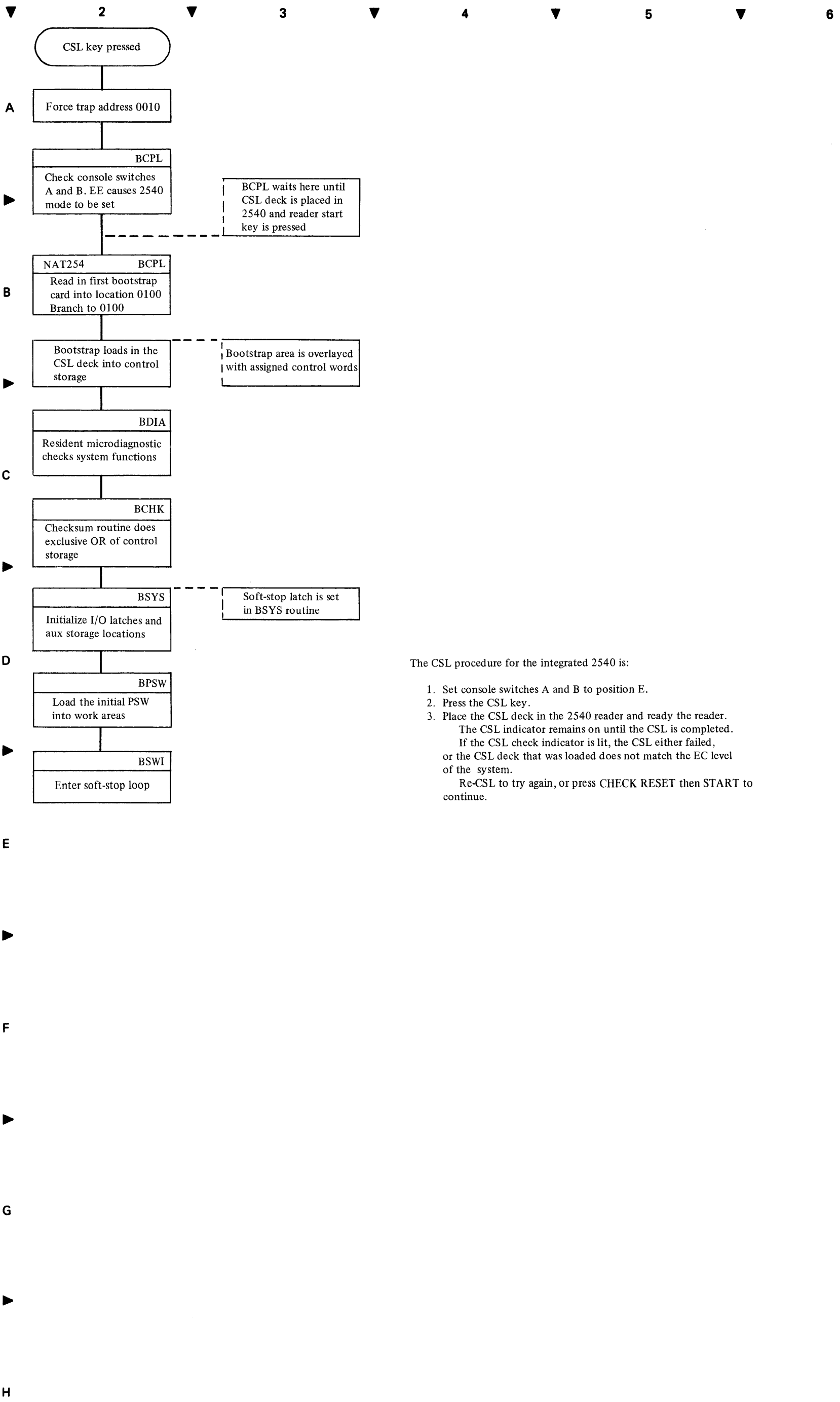
C

▲

D

▲

E



The CSL procedure for the integrated 2540 is:

1. Set console switches A and B to position E.
2. Press the CSL key.
3. Place the CSL deck in the 2540 reader and ready the reader.
 The CSL indicator remains on until the CSL is completed.
 If the CSL check indicator is lit, the CSL either failed,
 or the CSL deck that was loaded does not match the EC level
 of the system.
 Re-CSL to try again, or press CHECK RESET then START to
 continue.

Diagram 5-20. CSL With Integrated 2540

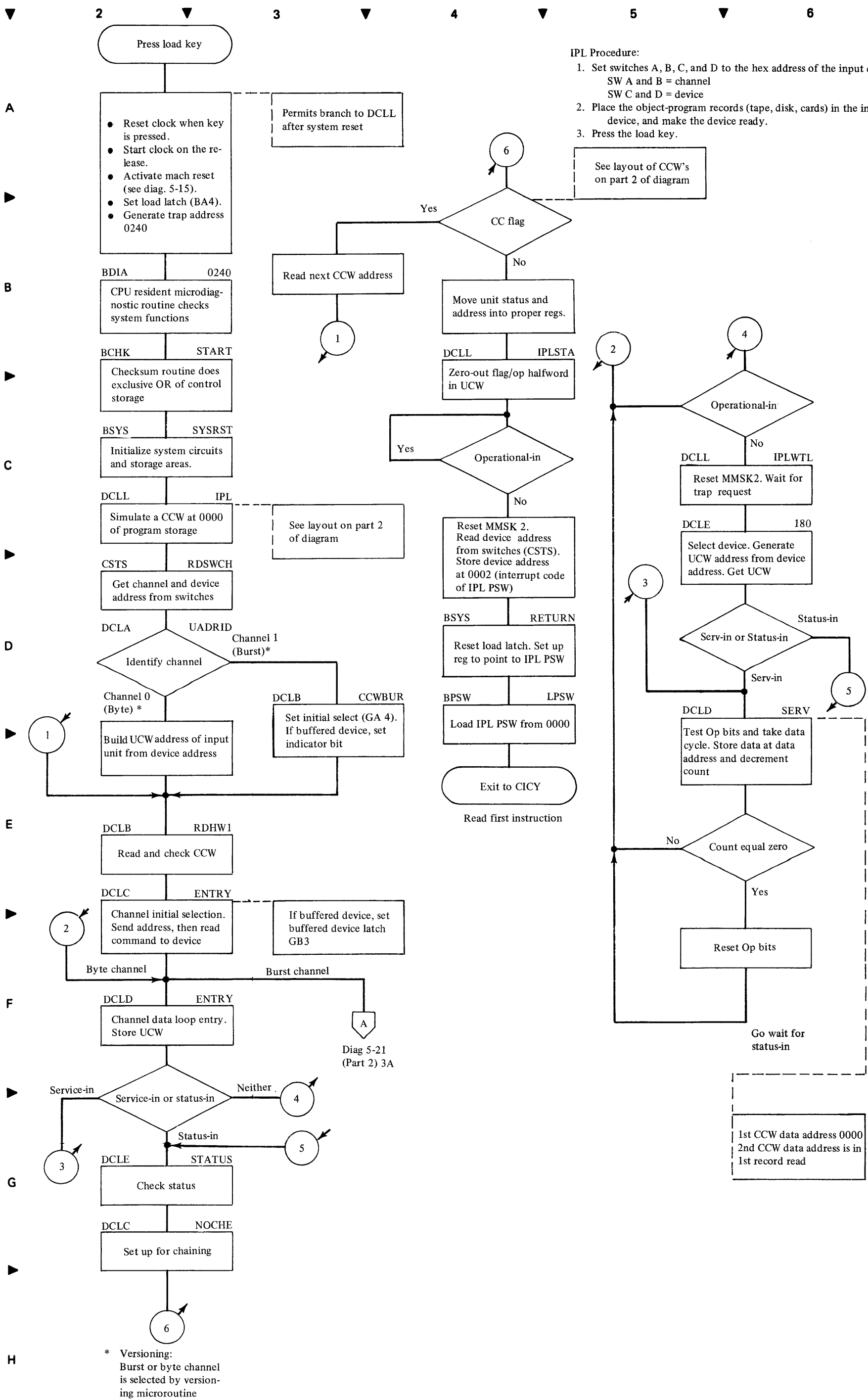


Diagram 5-22. IPL Load Operation and Byte Channel (Part 1 of 2)

A
B
C
D
E
F
G
H

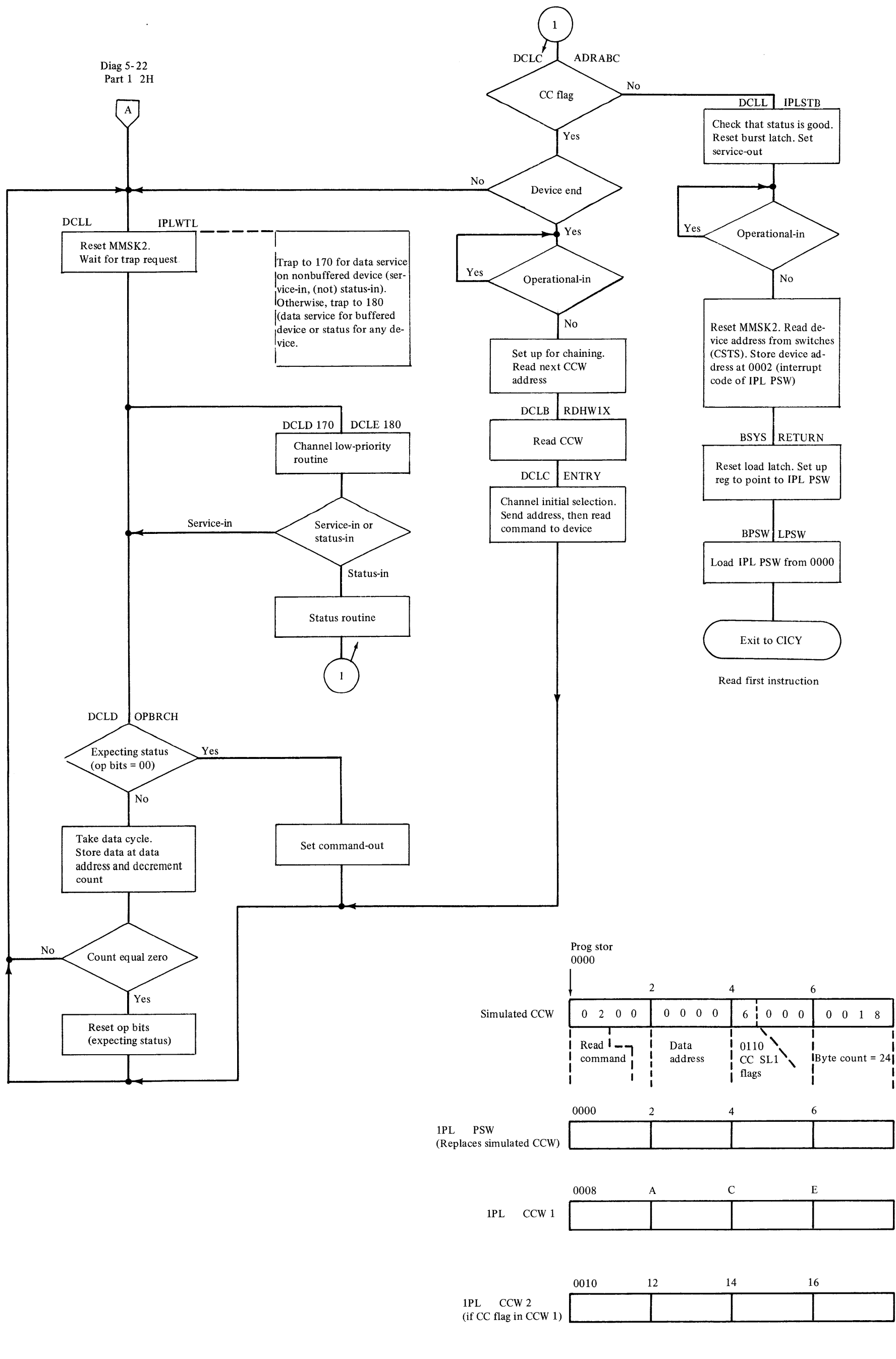


Diagram 5-22. IPL Load Burst Channel (Part 2 of 2)

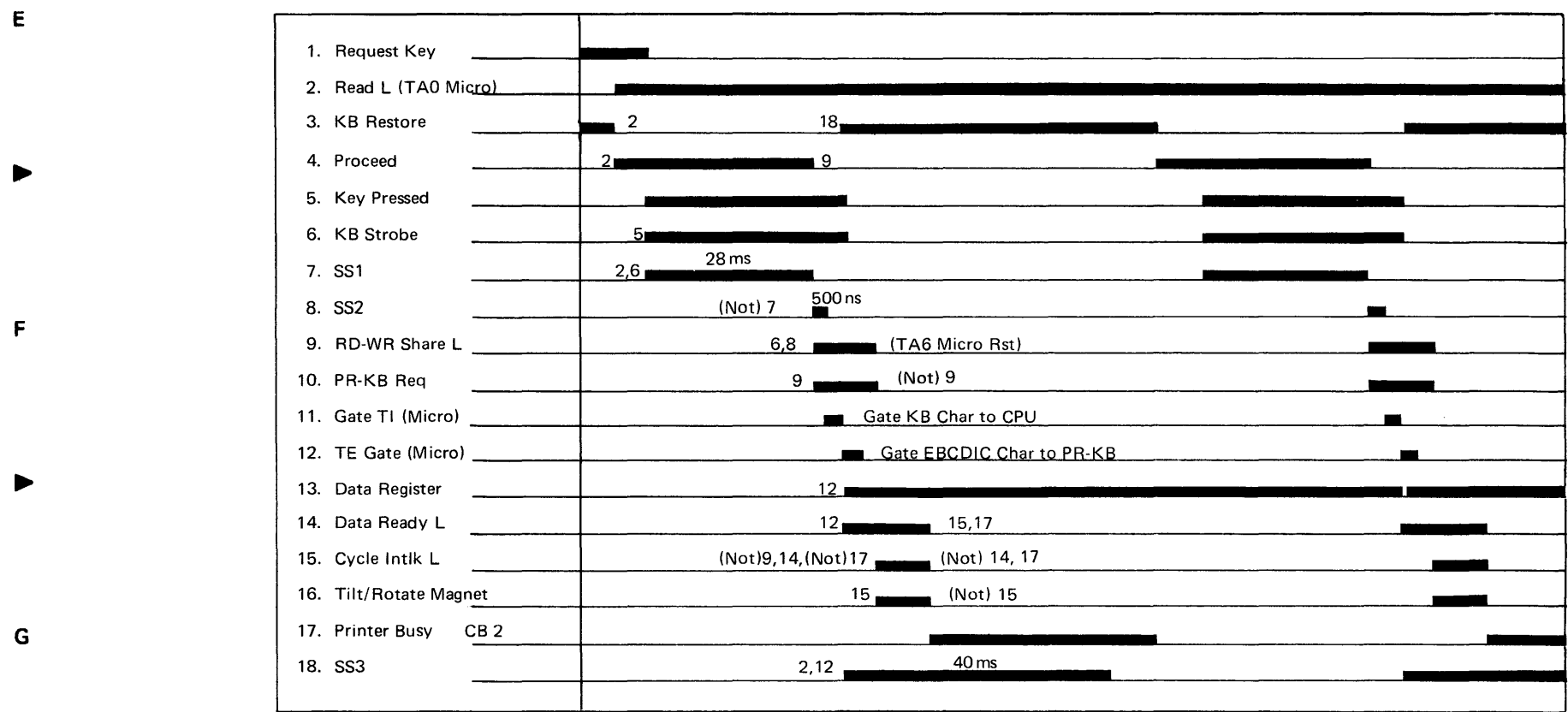
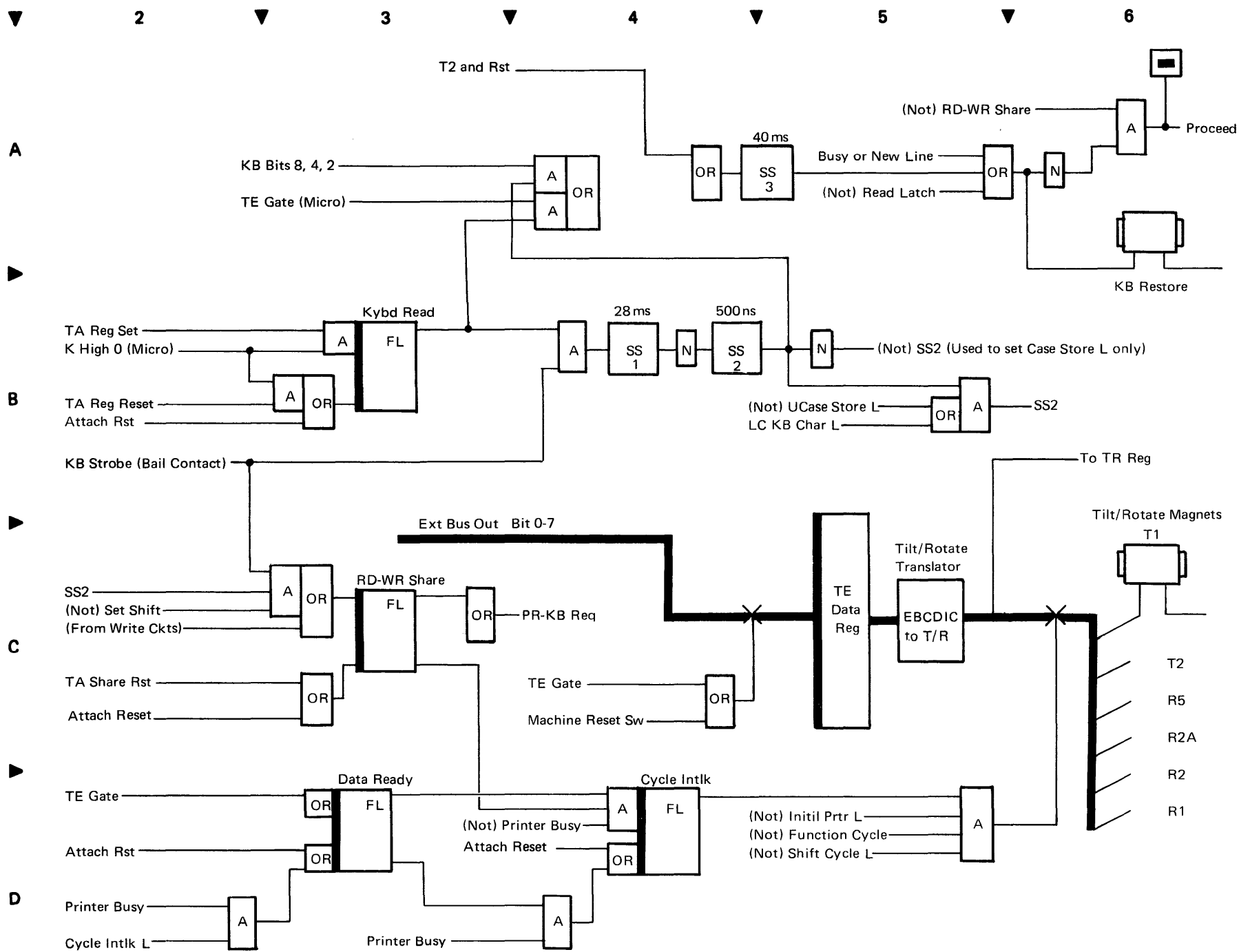
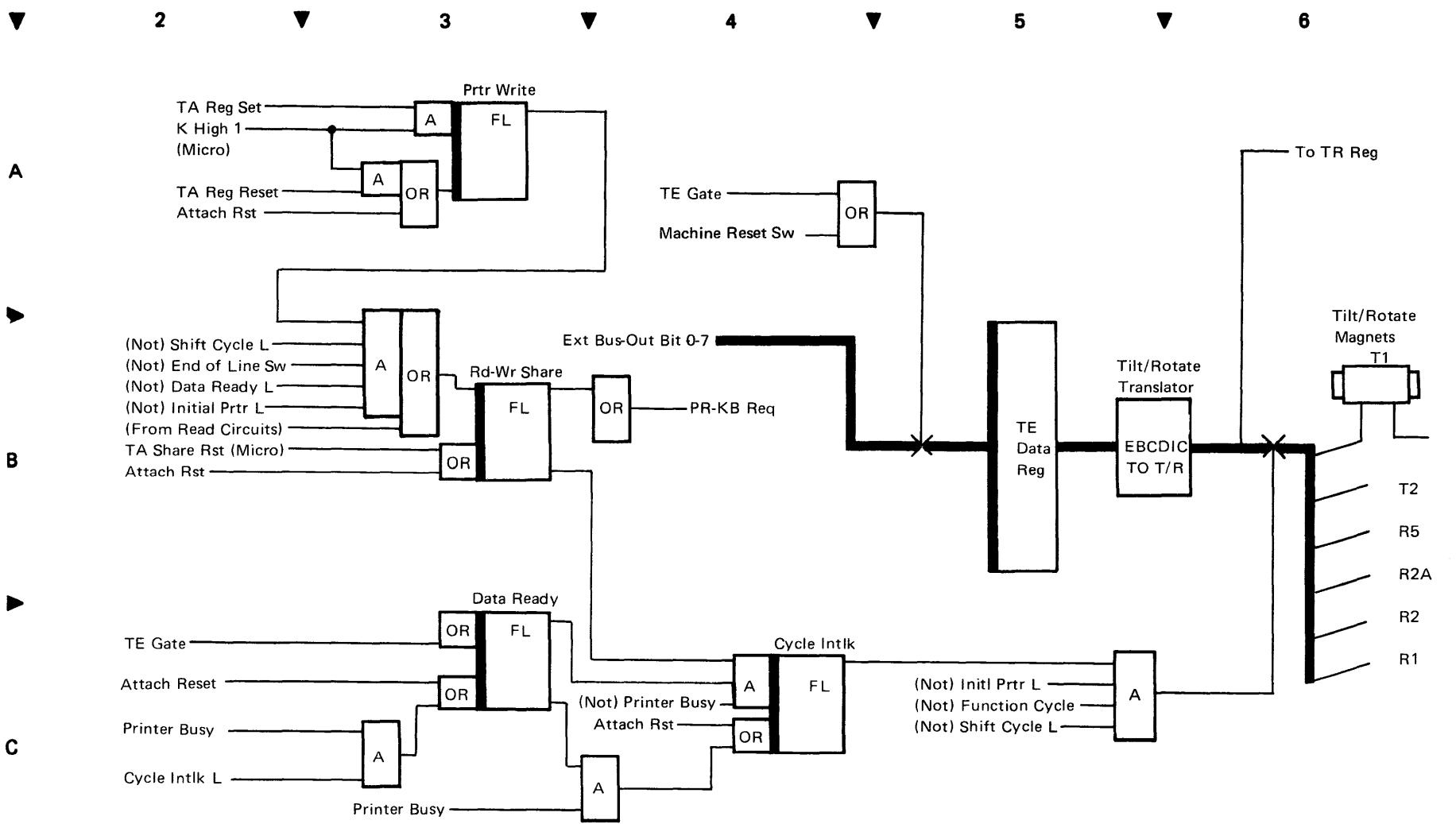


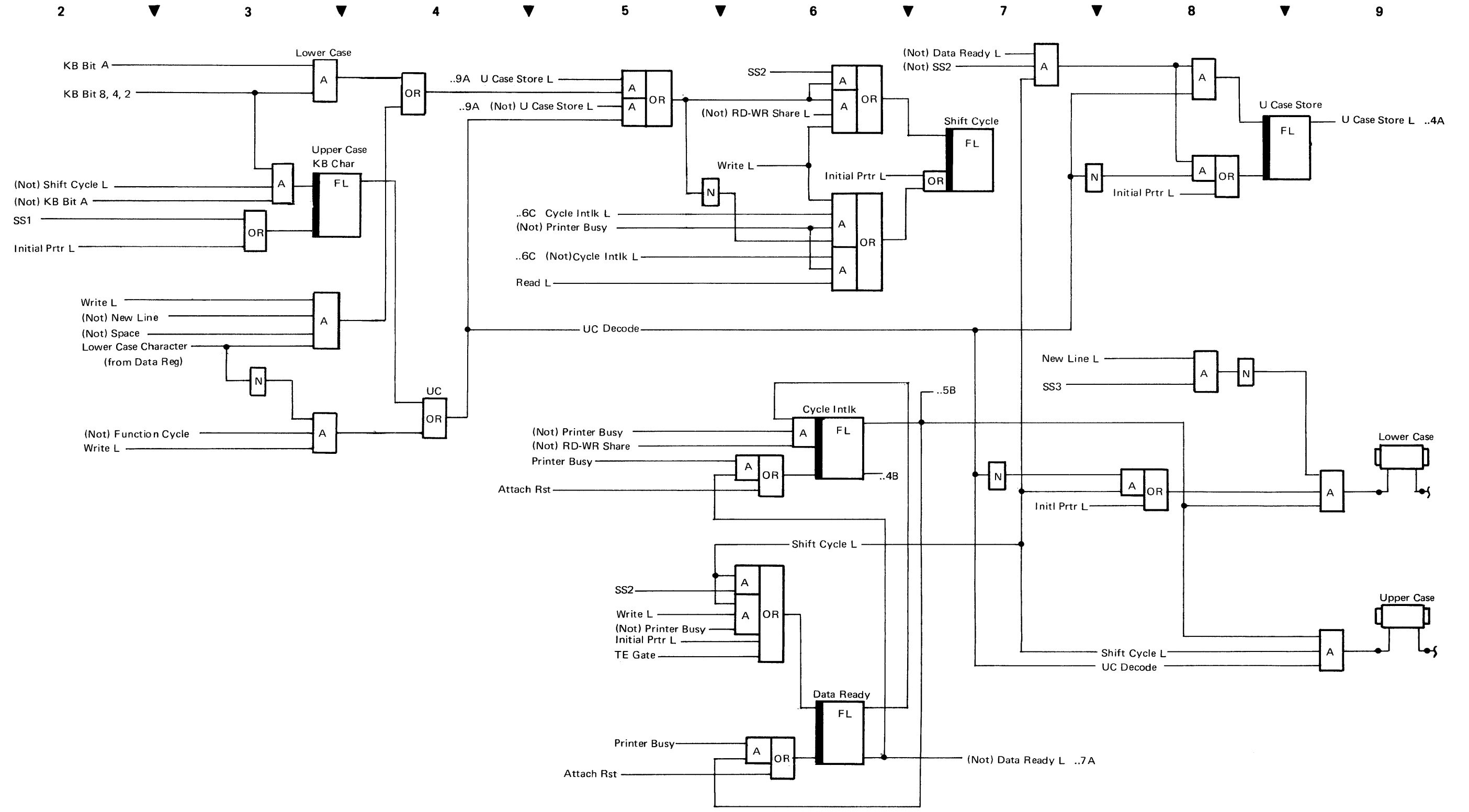
Diagram 5-71. 1052 Read Operation



1. Write L (TA1 Micro)	[Signal Pulse]	
2. RD-WR Share L	1 Share Rst TA6	(Not)5
3. PR-KB Req	2 (Not)2	[Signal Pulse]
4. TE Gate (Micro)	[Signal Pulse]	[Signal Pulse]
5. Data Ready L	4	8, 6
6. Cycle Intlk L	(Not) 2,5 (Not) 8	8, (Not)5 (Not)2,5,(Not)8
7. Tilt/Rotate Magnets	6	(Not) 6
8. Printer Busy CB2	[Signal Pulse]	[Signal Pulse]

Diagram 5-72. 1052 Write Operation

Diagram 5-73. PR-KB Case Shift (Part 1 of 2)



	2	3	4	5	6
1 Read Latch	[Signal Trace]				
2 Shift Key (Upper) KB Bits 842	[Signal Trace]				
3 KB Strobe	[Signal Trace]				
4 SS1	1, 3	[Signal Trace]			
5 SS2	(Not) 4 [Signal Trace]				
6 Lower Case KB Character	[Signal Trace]				
7 Upper Case KB Character L	(Not) 10, 2, (Not) 4 [Signal Trace] 4				
8 UC Decode	7 [Signal Trace] (Not) 7				
9 Set Shift	8, (Not) 15 [Signal Trace] 15				
10 Shift Cycle L	5, 9 [Signal Trace] (Not) 12, (Not) 14				
11 Data Ready L	5, 10 [Signal Trace] 12, 14				
12 Cycle Interlock L	11, (Not) 14 [Signal Trace] (Not) 11, 14				
13 Upper Case Magnet	8, 10, 12 [Signal Trace] (Not) 12				
14 Printer Busy (CB 7)	[Signal Trace]				
15 U Case Store L	(Not) 5, 8, 10, (Not) 11 [Signal Trace]				
16 SS3	5, 7 [Signal Trace] 40ms				
17 KB Restore	16 [Signal Trace] (Not) 14				
18 Character Key	[Signal Trace]				

Upper Case Shift (Read Operation)

1 U Case Store L	[Signal Trace] 7, 12, (Not) 9				
2 Write Latch (TA1 Micro)	[Signal Trace]				
3 RD-WR Share L	2	10			2, (Not) 9, (Not) 12 [Signal Trace]
4 PR-KB Request	3	(Not) 3			3 [Signal Trace]
5 TE Gate (Micro)	[Signal Trace]				
6 Char in Data Reg	5 [Signal Trace]				
7 LC Decode	6 [Signal Trace]				
8 Set Shift	1, 7 [Signal Trace] (Not) 1				
9 Data Ready L	[Signal Trace] 2, 12 (Not) 14				
10 Share Reset (TA6 Micro)	[Signal Trace]				
11 Cycle Intlk L	(Not) 3, 9, (Not) 14 [Signal Trace] (Not) 9, 14 (Not) 3, 9, (Not) 14 [Signal Trace]				
12 Shift Cycle L	(Not) 3, 2, 8 [Signal Trace] 2, (Not) 8, 11, (Not) 14 [Signal Trace]				
13 Lower Case Magnet	7, 11, 12 [Signal Trace] (Not) 11				
14 Printer Busy CB 7	[Signal Trace]				
15 Tilt/Rotate Magnets	[Signal Trace] 6, 11, (Not) 12				

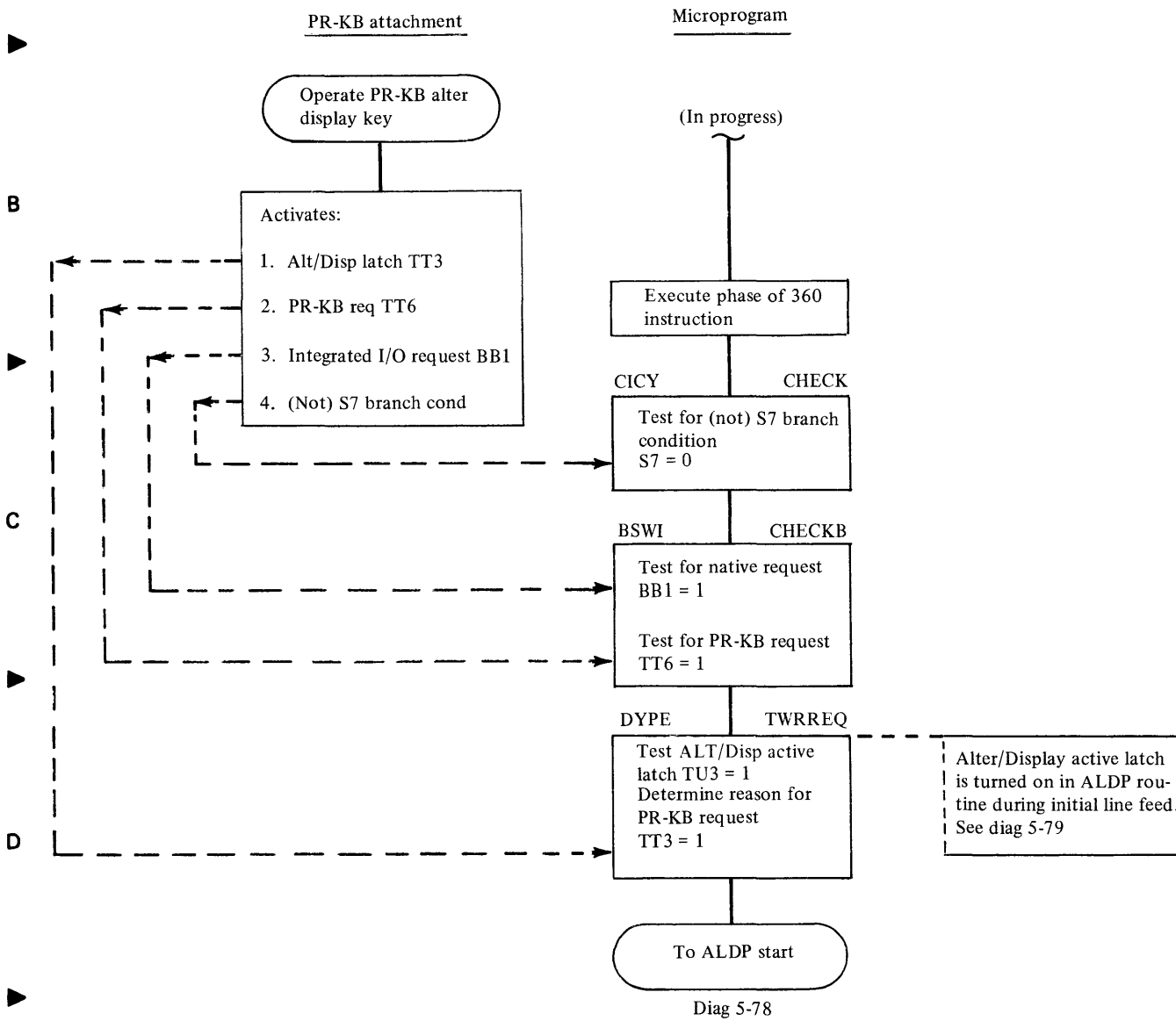
Shift To Lower Case During Write Operation

Diagram 5-73. PR-KB Case Shift (Part 2 of 2)

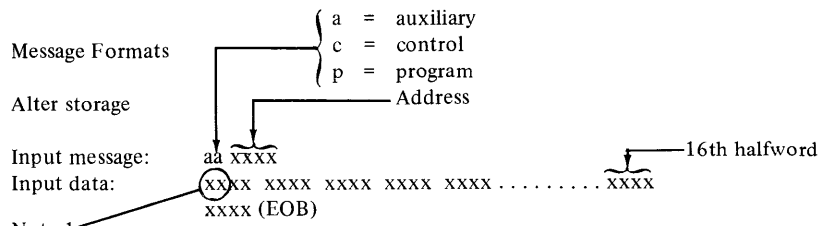
Objective: Start a PR-KB alter or display operation.

- Assume:
1. PR-KB alter display switch is operated during the execute phase of a 360 arithmetic or logic instruction.
 2. No other I/O requests or interrupts are pending.

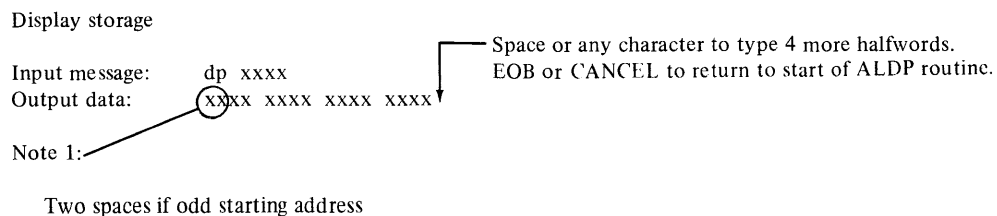
A



E



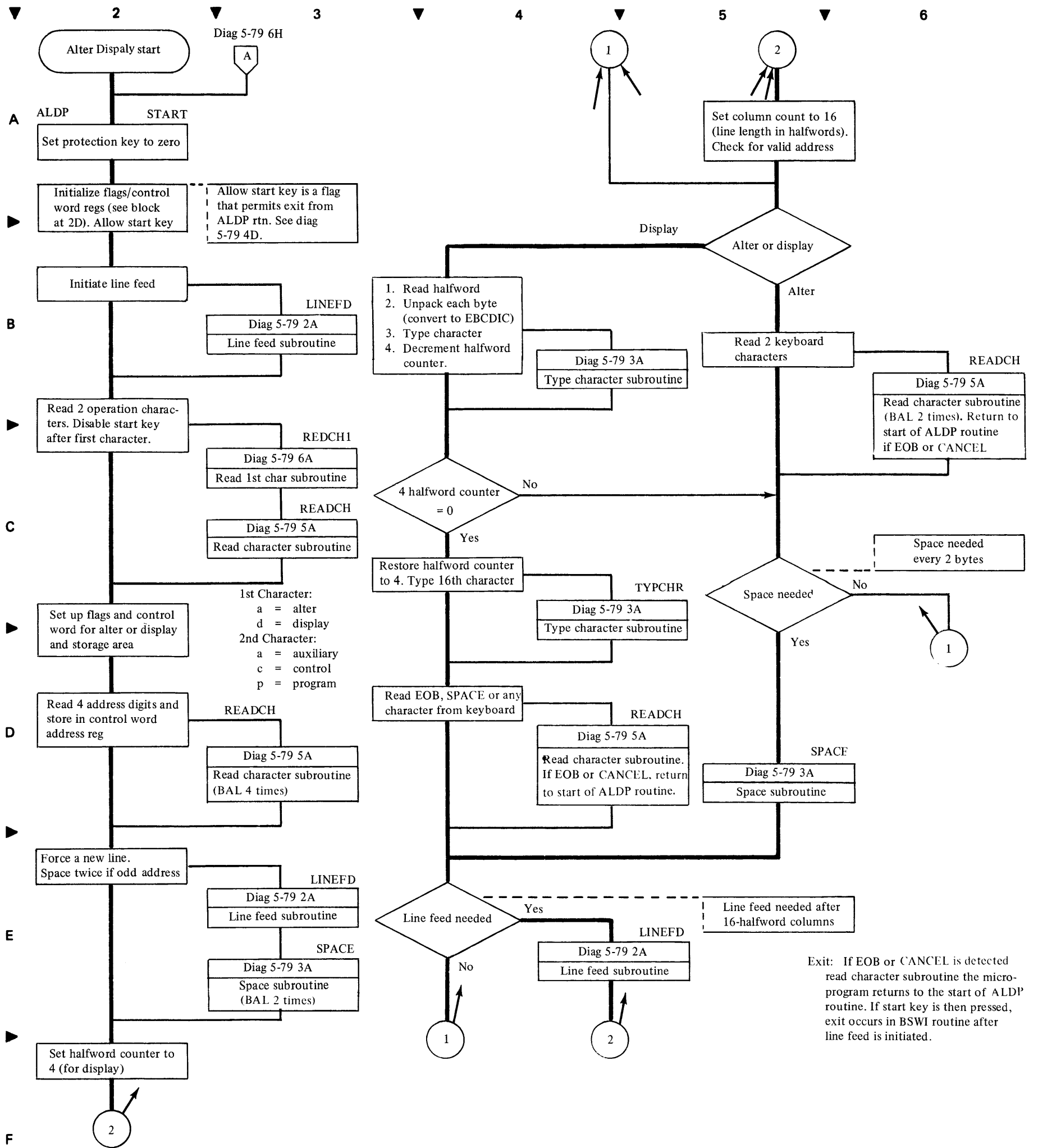
F



G

H

Diagram 5-77. PR-KB Alter-Display Start



Exit: If EOB or CANCEL is detected read character subroutine the micro-program returns to the start of ALDP routine. If start key is then pressed, exit occurs in BSWI routine after line feed is initiated.

Diagram 5-78. PR-KB Alter-Display Operation

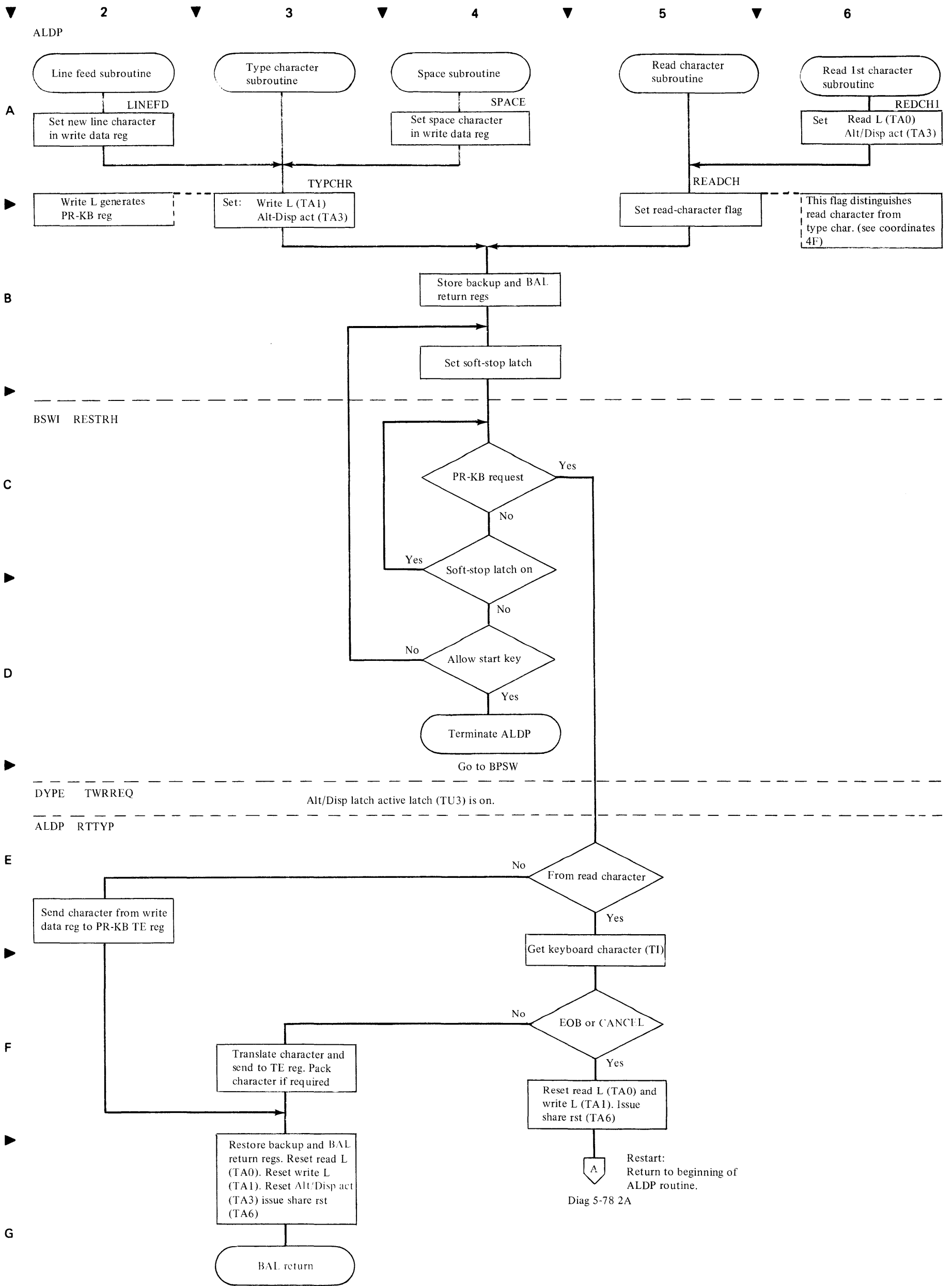
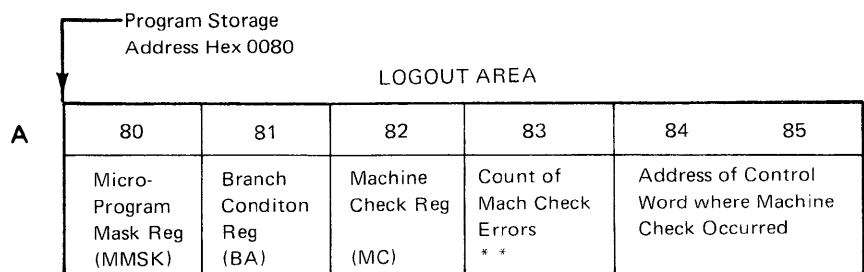


Diagram 5-79. PR-KB Alter/Display Subroutines

Note: This diagram shows machine check logout only. For channel interface control check, layout of logout area is changed as follows:

Byte
 82 GS chnl ext conds
 84 GT chnl ext conds
 85 GD chnl Ext conds
 86-87 Unit ID



- | | | |
|-----------------------------|--------------------|-----------------------------|
| 0 Channel High Trap | 0 Chnl 0 Interrupt | *0 File Control Check |
| 1 2311 Disk Control Trap | 1 Mode Bit 0 | 1 Storage Protect Check |
| 2 Channel Low Trap | 2 Mode Bit 1 | 2 Storage Address Check |
| 3 2540 Reader Trap | 3 Mode Bit 2 | 3 Control Word Parity Latch |
| 4 2540 Punch Trap | 4 IPL Latch | 4 Storage Data Parity Latch |
| 5 Communication Bit Service | 5 LS Zone Bit 0 | 5 ALU Error Latch |
| 6 Communication Char Serv | 6 LS Zone Bit 1 | 6 A-Reg Parity Latch |
| 7 Level 1 Priority Hold | 7 LS Zone Bit 2 | 7 B-Reg Parity Latch |

** Bits 0-1 are logout code (00 for machine check)

* Bit 0=1 indicates that the machine check indicated in bits 1-7 occurred while in 2311 Disk Mode (not File Share Cycle)

Conditions

The microprogram traps to address 0220 if all of the following conditions are satisfied:

1. MMSK bit 8 and 9 off. (Not system reset, CSL, IPL or prior machine check)
2. The Mach Chk Mask latch (MW bit 5) is on. This latch is set if PSW bit 13 is on when the PSW is loaded (BPSW routine).
3. The Mach Chk latch turns on. The conditions that turn the Mach Chk latch on are indicated by the MC-Reg shown at the top of this page.

Objectives

A. Machine Check During I/O Trap

1. Terminate I/O operation.
2. Attempt I/O interrupt.
3. Store logout information and print logout area before next CPU instruction.

B. Machine Check, Not I/O Trap

1. Take machine check interrupt. Store machine check old PSW and load new PSW.
2. Store logout information.
3. Print logout area.

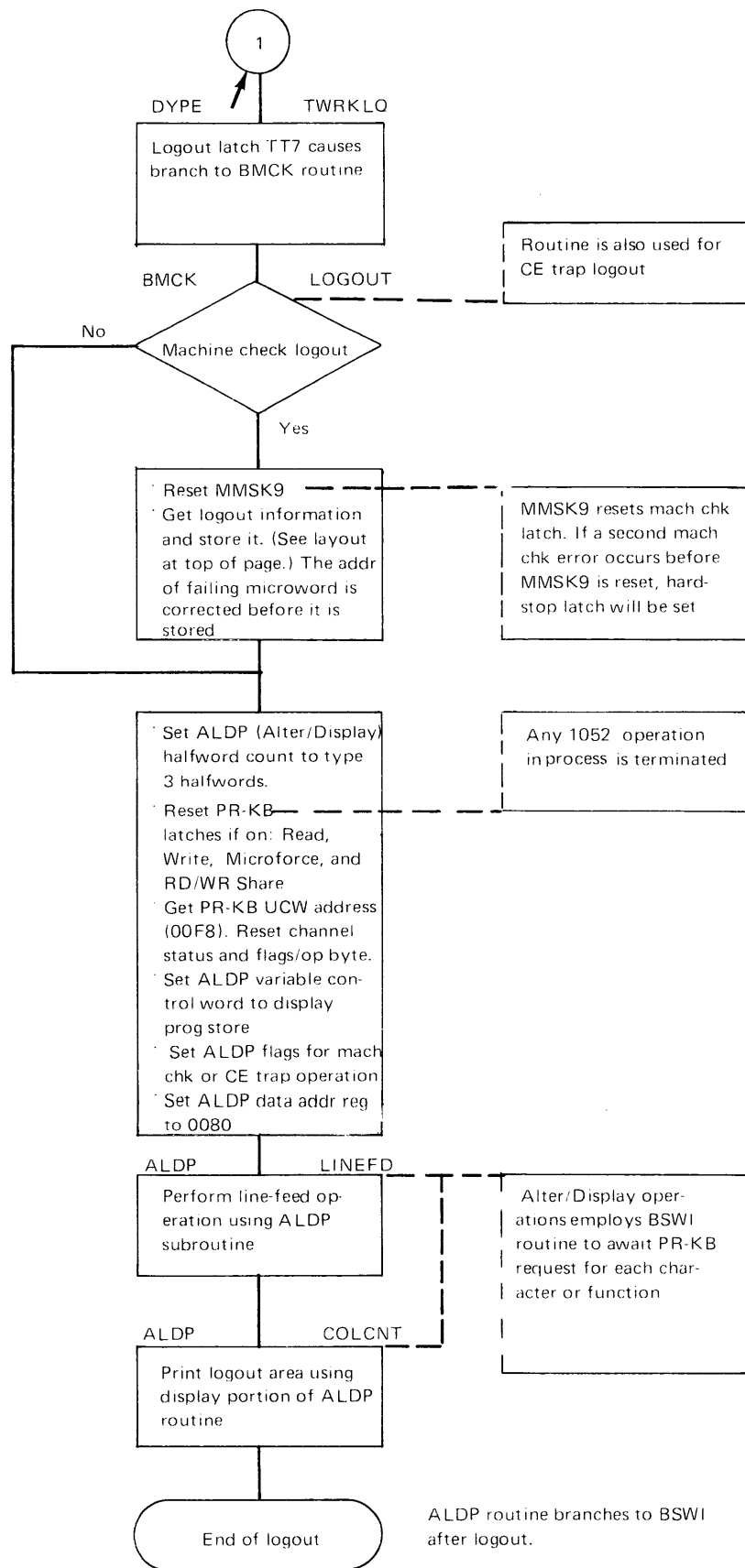
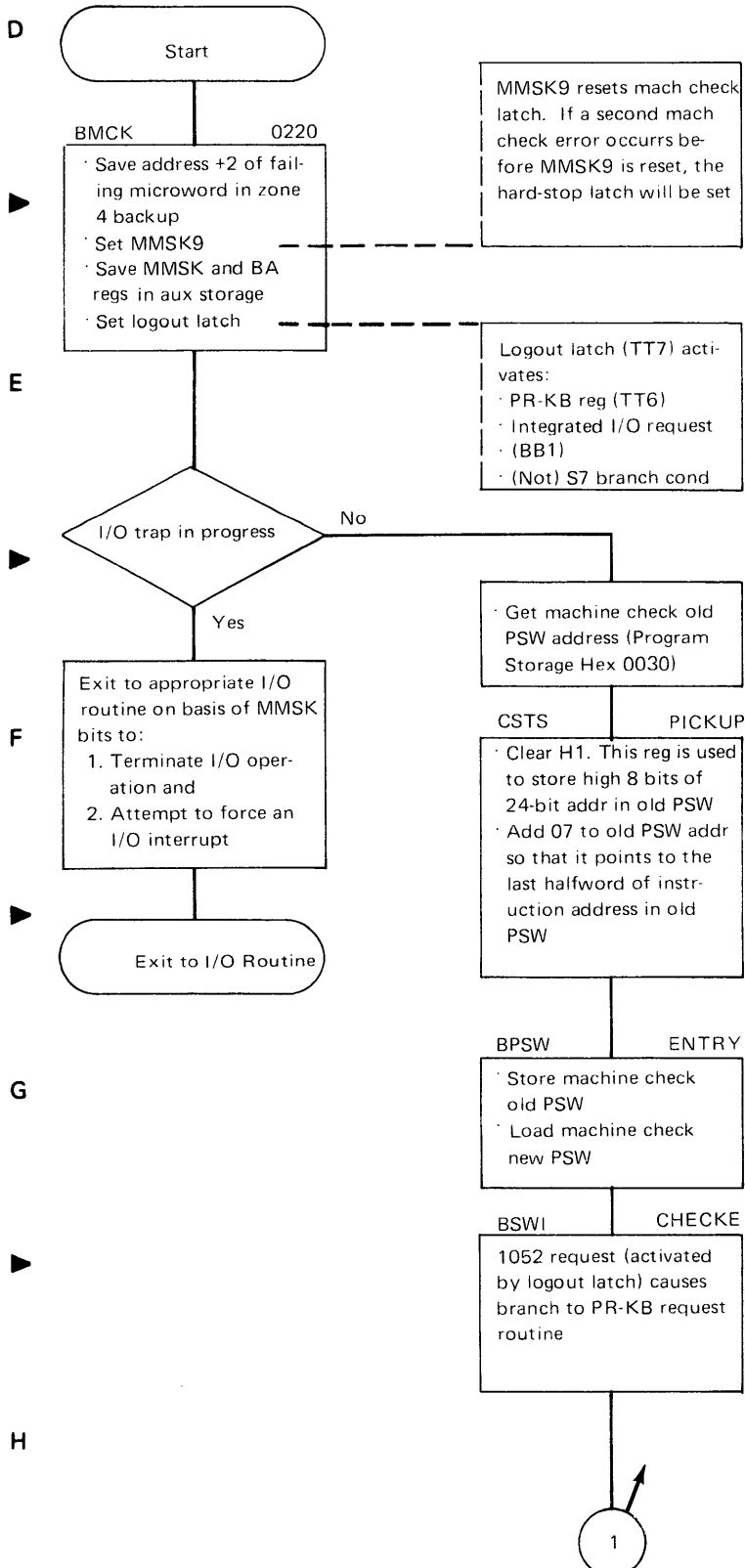


Diagram 5-80. Mach Check Logout

Diagram 5-85. Move Arithmetic Word, External Facility to Local Storage (Word Type 3)

Move/Arithmetic Word (Word Type 3)
(External Facility to Local Storage)

*STP0 is an external register determined (gated) by the contents of the mode register (TR052 or MDM4-14).
Refer to MDM4-90, Part 1 for STP0 and Q-Reg gating:
CPU Mode: STP0=Q-Reg
2311 Mode: STP0=FQ-Reg
Channel Mode: STP0=GQ-Reg
Communications Mode=HQ-Reg

A

B

C

D

E

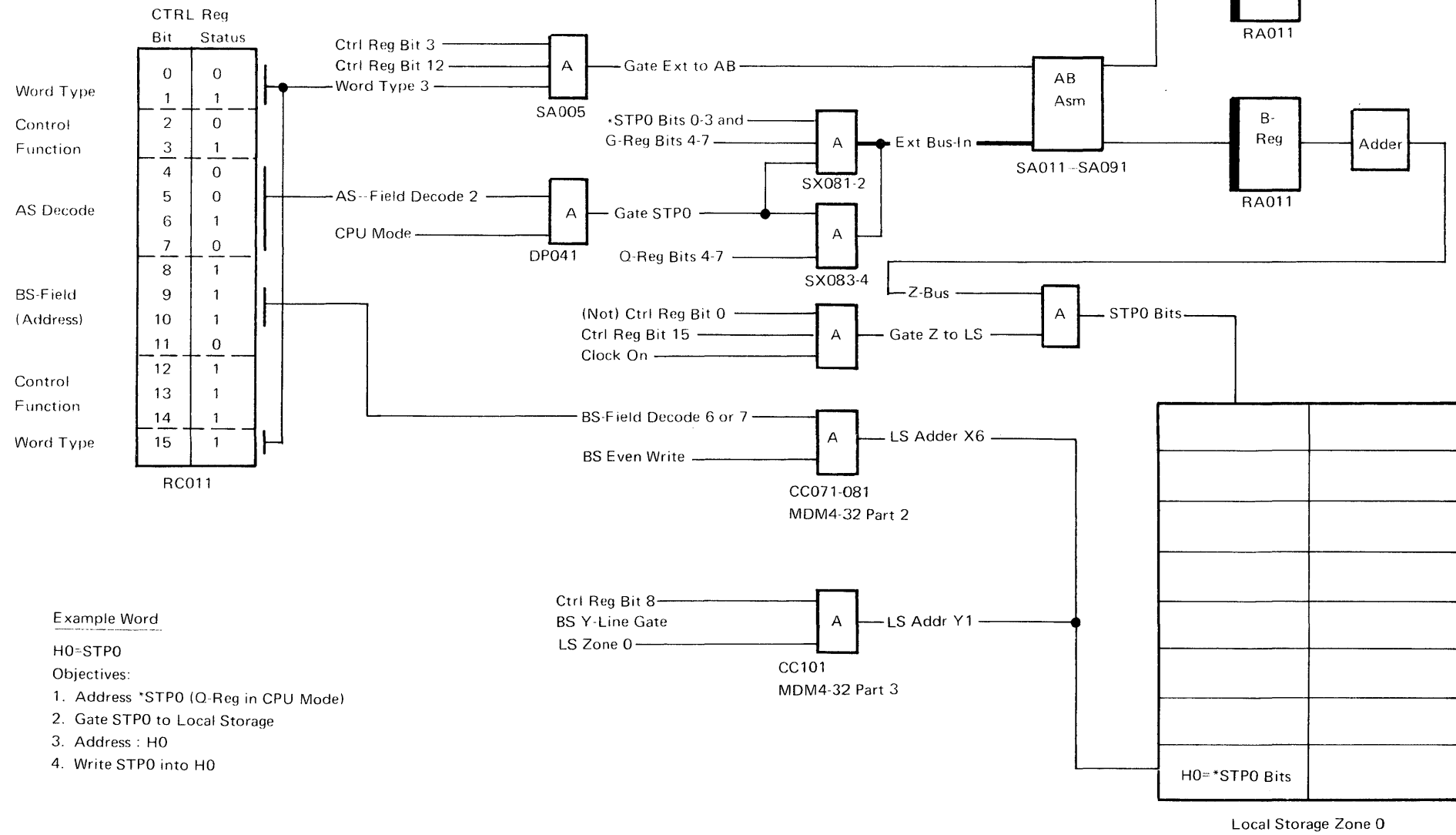
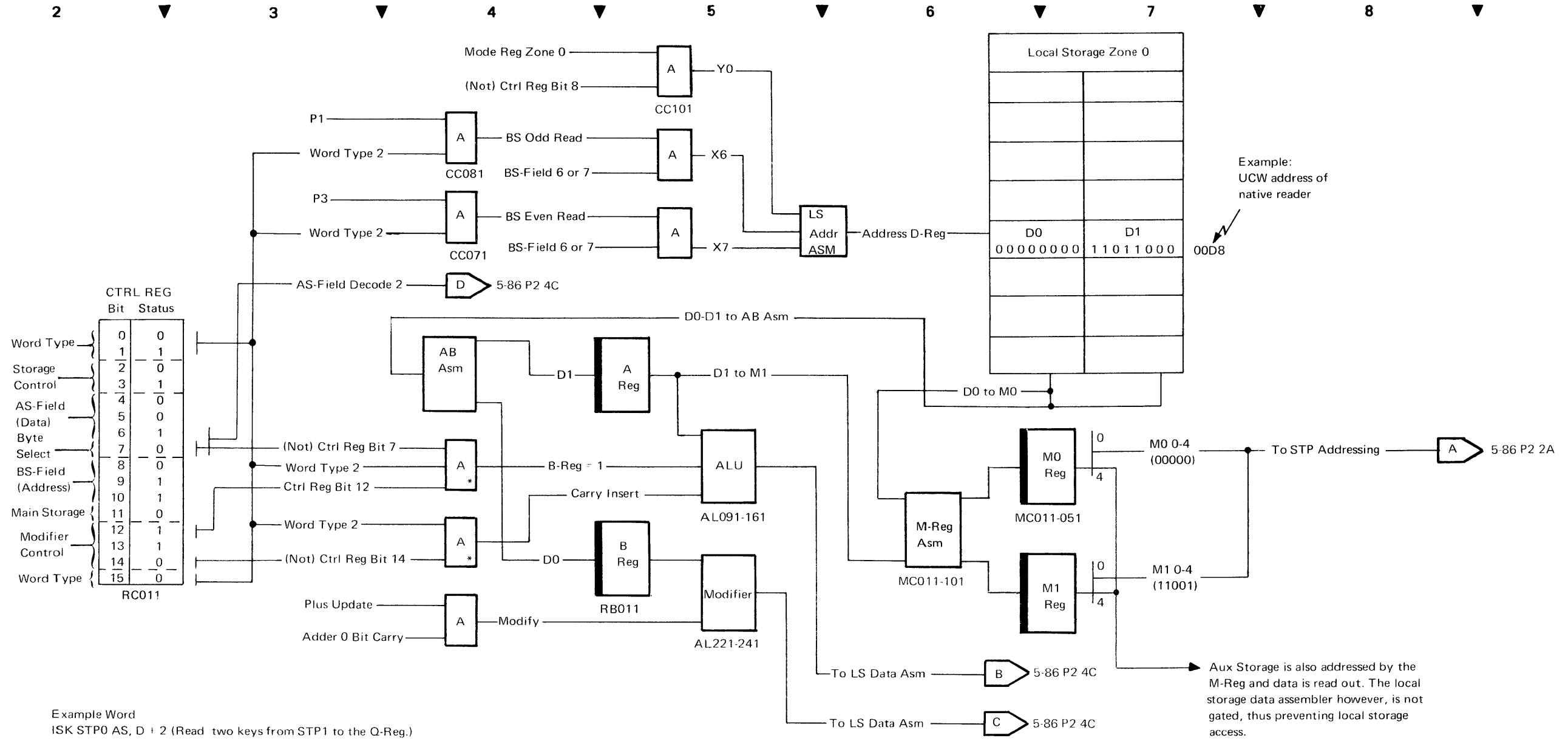


Diagram 5-86. Storage Word, Insert Storage Key (Word Type 2) (Part 1 of 2)



Example Word
 ISK STP0 AS, D + 2 (Read two keys from STP1 to the Q-Reg.)
 Objectives:
 1. Read the indirect address from D-Register (UCW address) and place in M-Register.
 2. Read halfword from auxiliary storage address by M-Reg and block.
 3. Read out halfword from STP1 address by M-Register to Q-Register.
 4. Update the indirect address by 2.

* The address update by 2 is accomplished by bringing up the carry insert line and the B-Reg line, causing a carry into the bit-6 position of ALU, thus incrementing by 2.

Example:
 UCW address of native reader
 00D8

To STP Addressing → 5 86 P2 2A

Aux Storage is also addressed by the M-Reg and data is read out. The local storage data assembler however, is not gated, thus preventing local storage access.

A

B

C

D

E

Diagram 5-86. Storage Word, Insert Storage Key (Word Type 2) (Part 2 of 2)

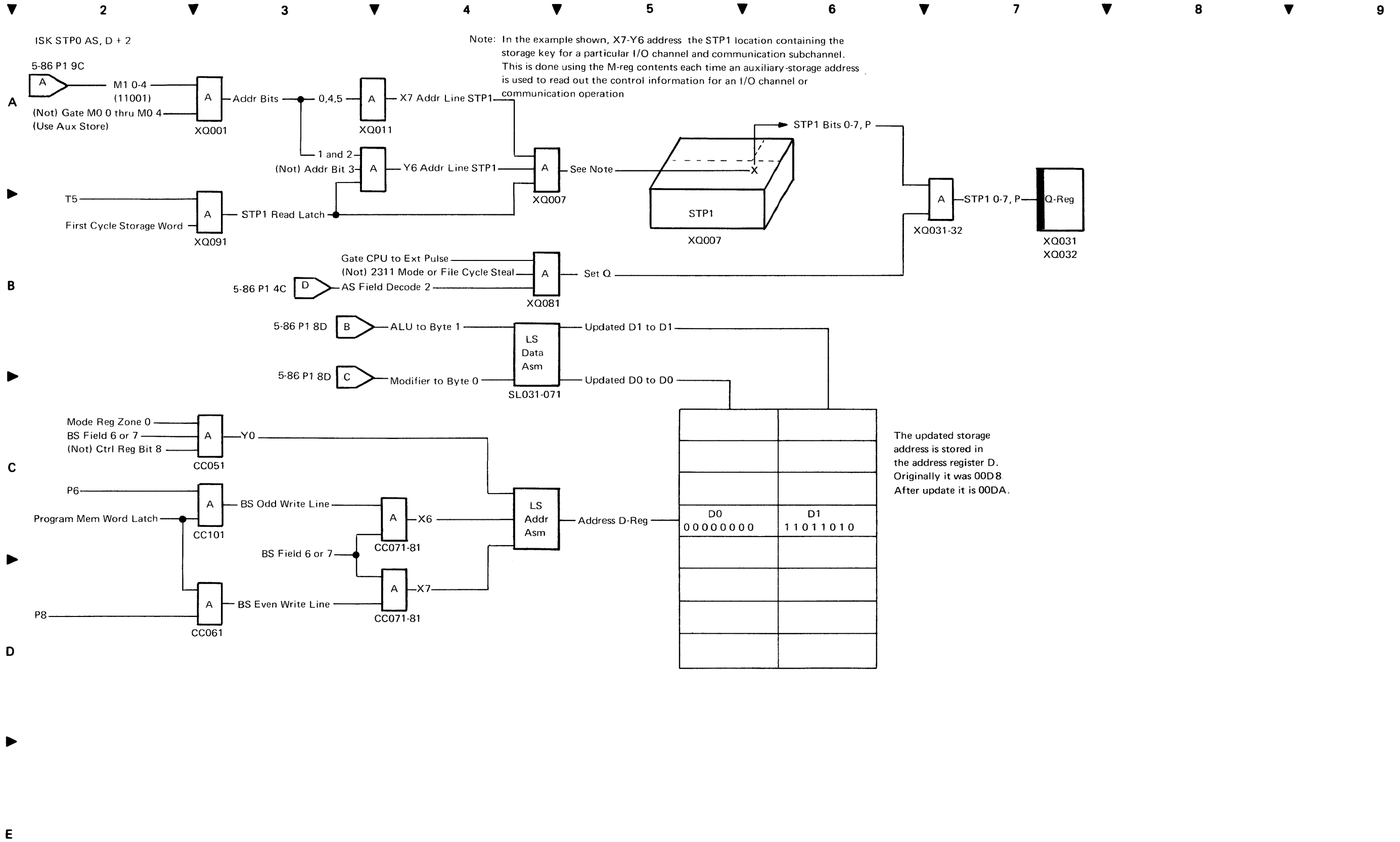
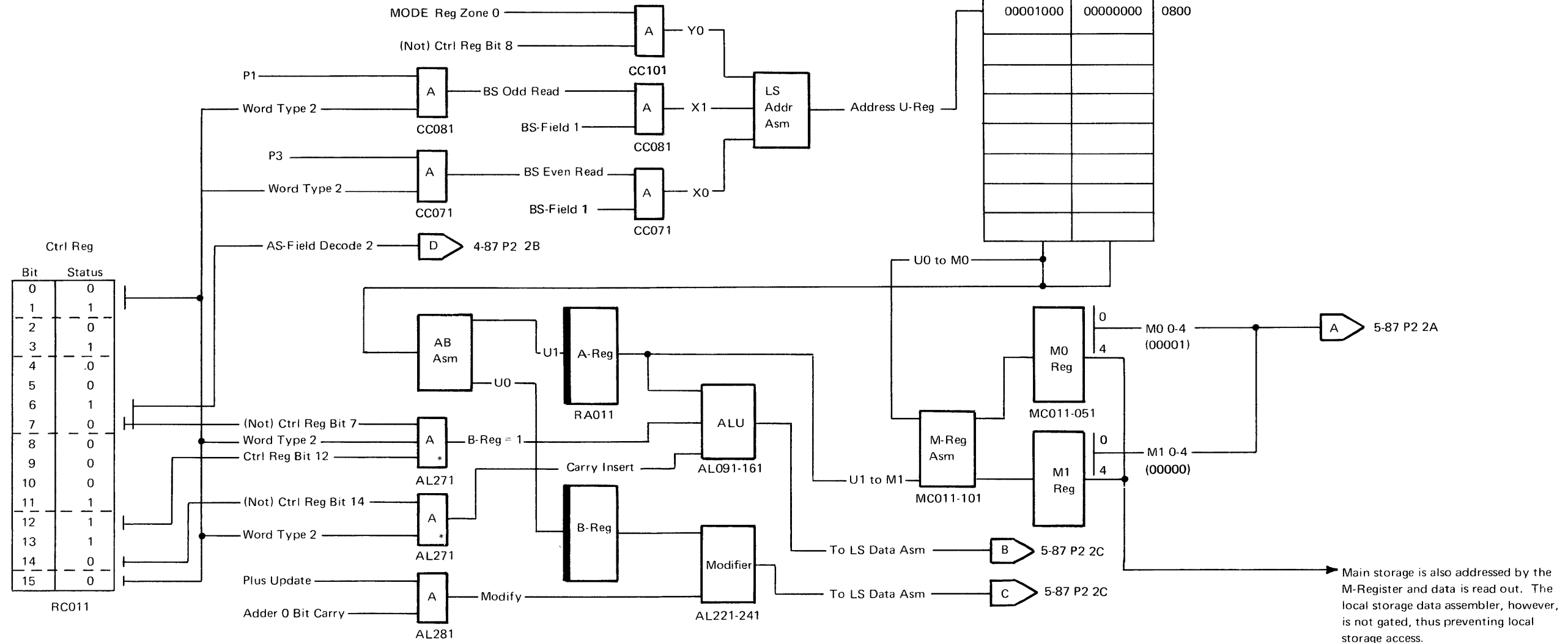


Diagram 5-87. Stor. Word, Insert Stor. Key Function (Part 1 of 2)

First Cycle Storage Word (Word Type 2)
(External Facility Access and Update Type)



Example Word
ISK STP0 U + 2 (Read Key from STPL into the Q-Reg)

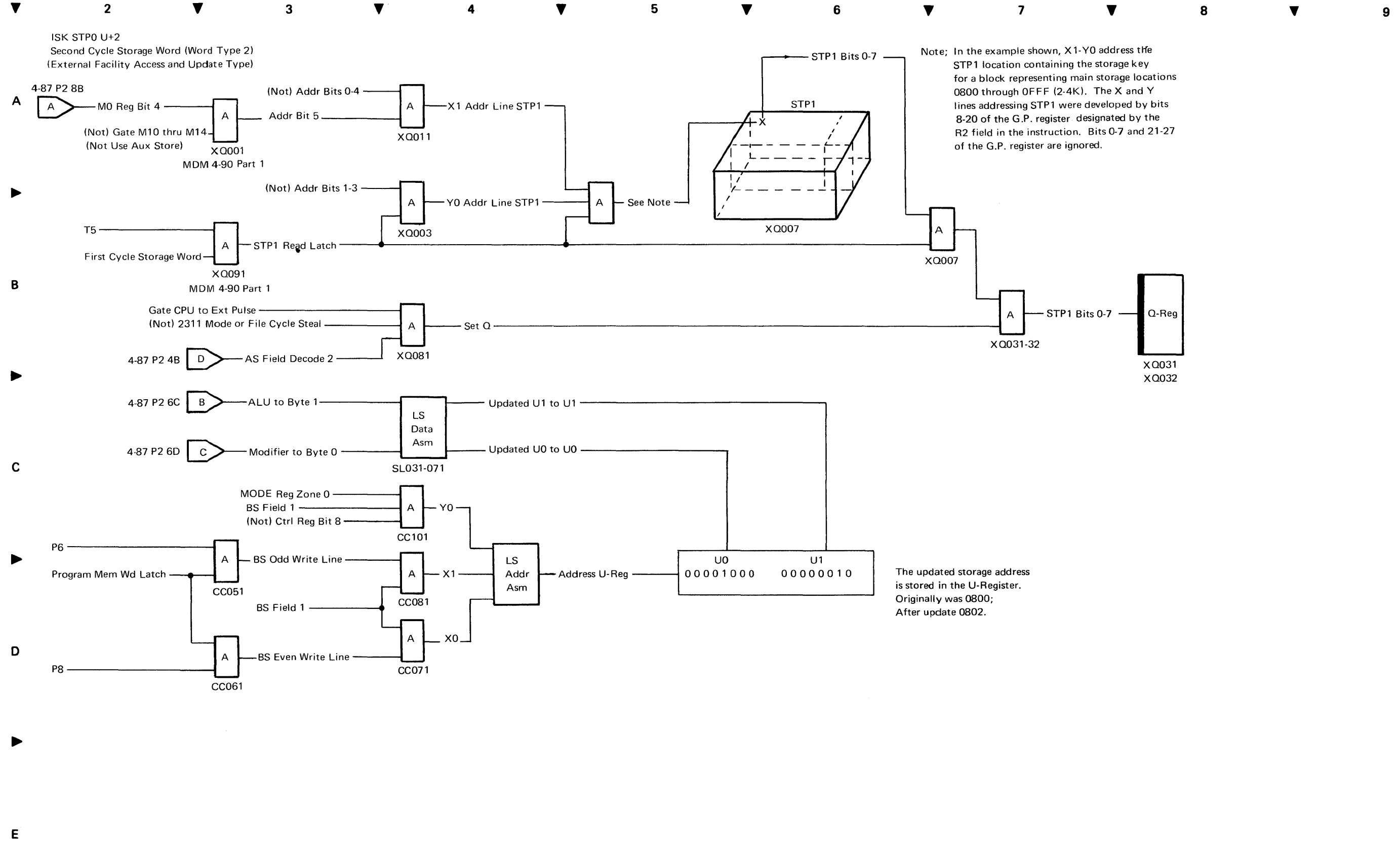
Objectives;

1. Read the indirect address from U-Register and place in the M-Register (1st Cycle).
2. Read data from program storage and block (1st Cycle).
3. Read out the storage key from STP1 (addressed by the M-Register) into the Q-Register.
4. Update the indirect address by 2.

* The address update by 2 is accomplished by bringing up the carry insert line and the B-Register = 1 line, causing a carry into the Bit-6 position of ALU, thus incrementing by 2.

Main storage is also addressed by the M-Register and data is read out. The local storage data assembler, however, is not gated, thus preventing local storage access.

Diagram 5-87. Stor. Word, Insert Stor. Key Function (Part 2 of 2)



First Cycle Storage Word (Word Type 2)
(External Data Reg. Access and Update Type)

CTRL REG Bit Status	
Word Type	0 0
	1 1
Storage Control	2 0
	3 1
AS-Field (Data) Byte	4 0
	5 0
Select BS-Field (Address)	6 1
	7 1
Main Stor.	8 0
	9 0
Modifier Control	10 0
	11 1
	12 1
	13 1
	14 0
Word Type	15 0

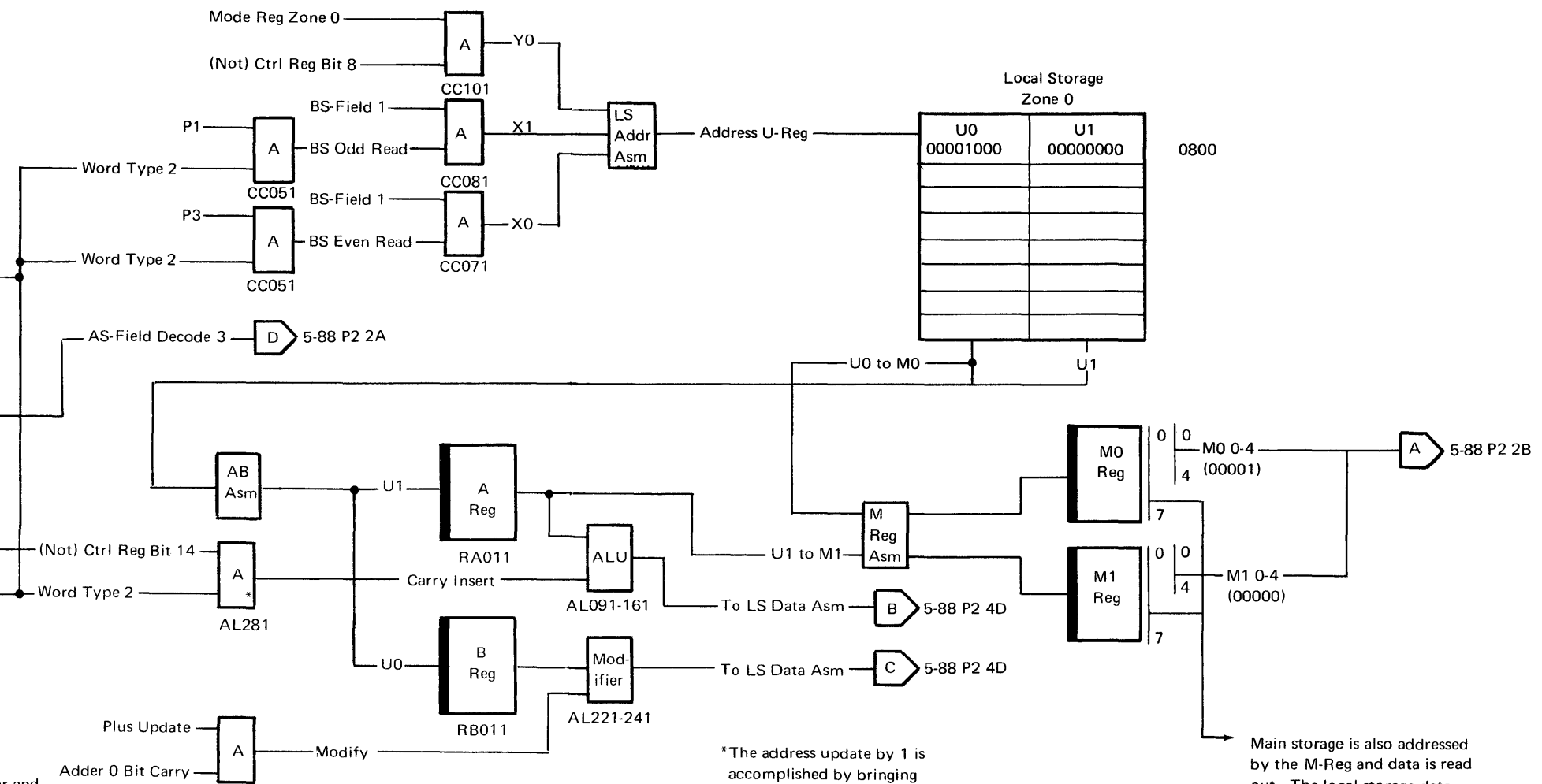
RC011

Example Word

SSK STP1 U+1

Objectives:

1. Read the indirect address from U-Register and place in the M-Register (1st cycle).
2. Read byte from program storage and block (1st cycle).
3. Gate the Q-Register to STP1 (external local storage) addressed by the M-Register.
4. Update the indirect address by 1.



*The address update by 1 is accomplished by bringing up the carry insert line that causes a carry into the bit position of ALU incrementing by 1.

Main storage is also addressed by the M-Reg and data is read out. The local storage data assembler however, is not gated, thus preventing local storage access.

A

B

C

D

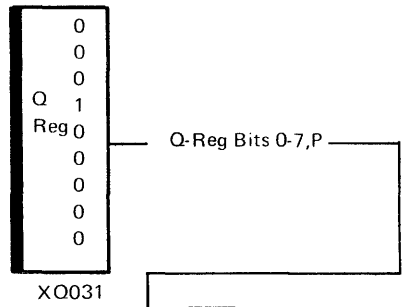
E

*In this example, only M0 bit 4 is active, thus only address bit 5 is developed.

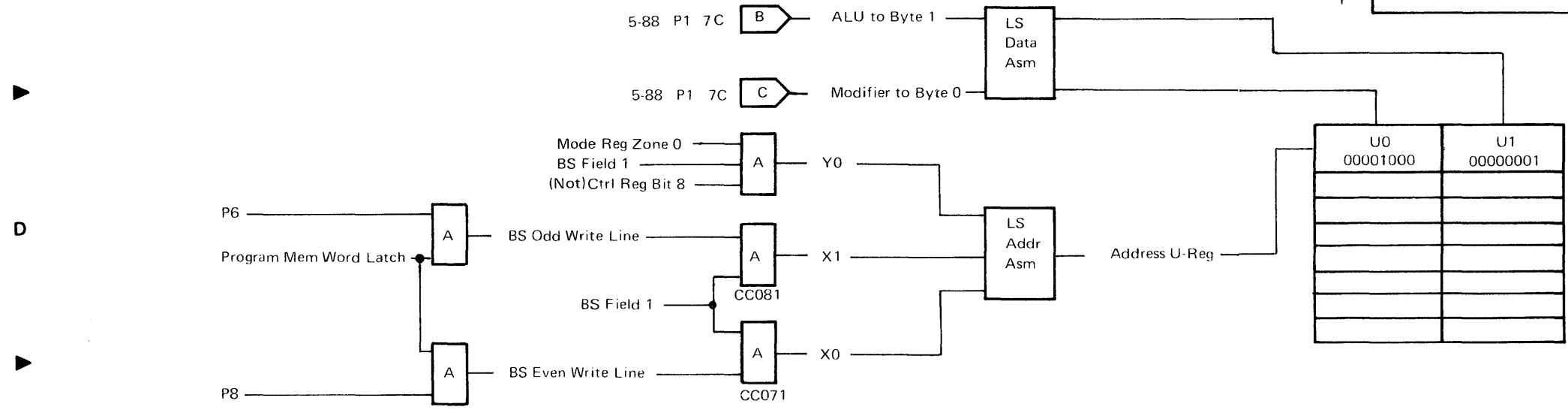
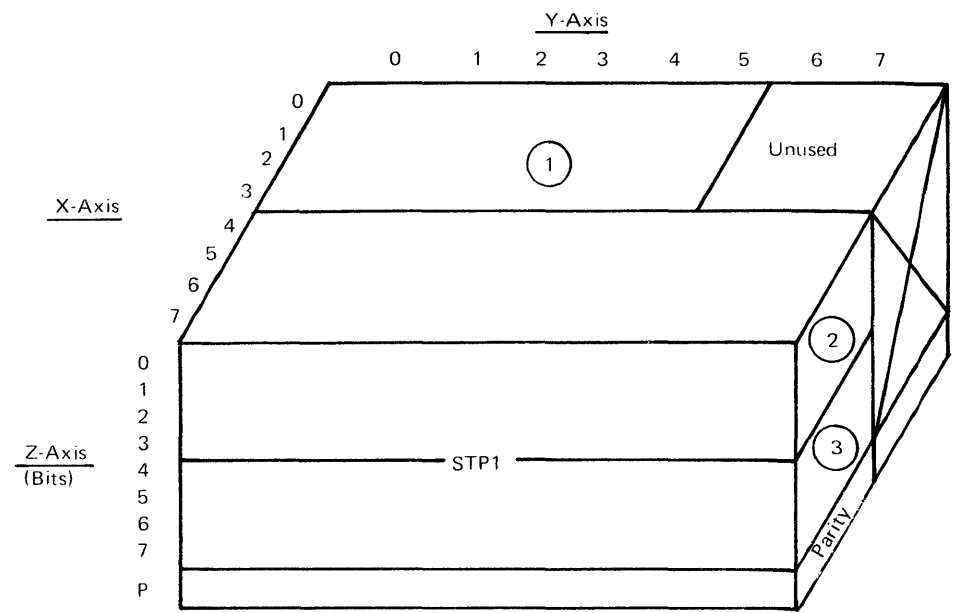
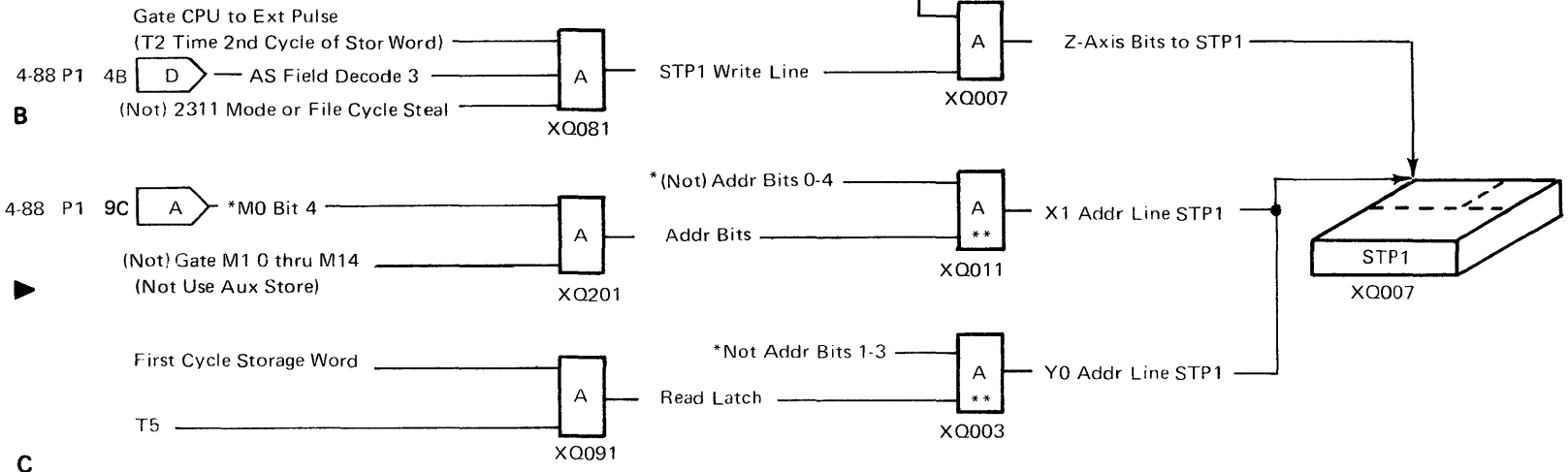
STP1 Storage Allocations

- 1 Program Storage Keys-X:0-3, Y:0-5, Z:0-3
- 2 Channel Keys-X:4-7, Y:0-7, Z:0-3
- 3 Communications Keys-X:4-7, Y:0-7, Z:4-7

A SSK STP1 U+1
Second Cycle Storage Word (Word Type 2)
(External Data Reg Access and Update Type)



**Refer to Diag 4-90 Part 1 for details on X-Y address lines STP1.



0801

The updated storage address is stored in the U-Register. Originally it was 0800. After update it is 0801.

Run In Objectives:

- Feed three cards into the reader.
- Data from first card in the column image buffer.
- First card checked for hole count errors.
- Data from second card in the row image buffer.

A

B

C

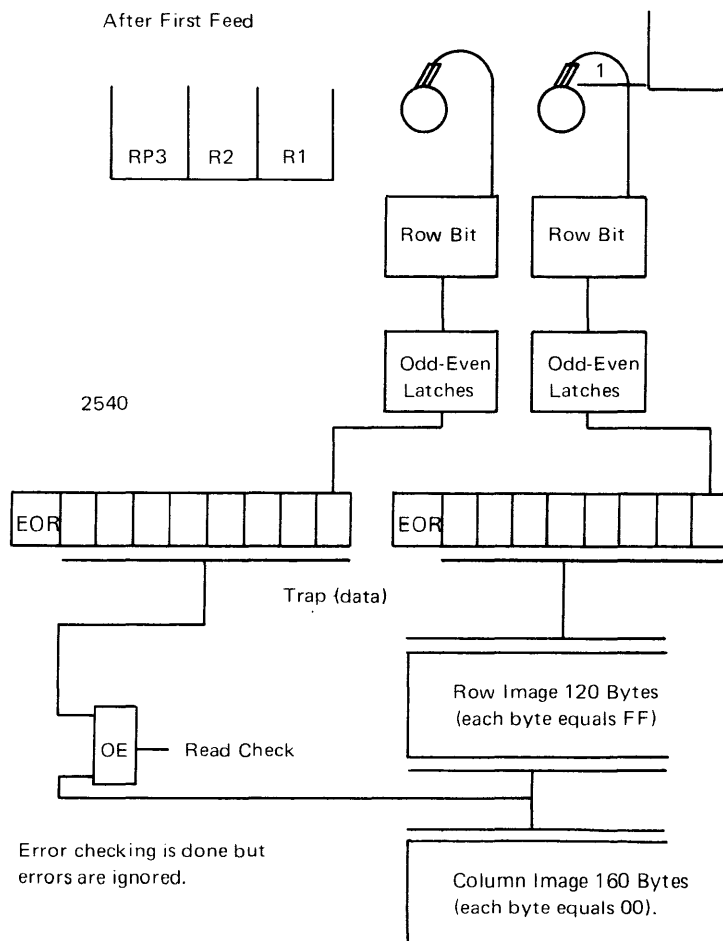
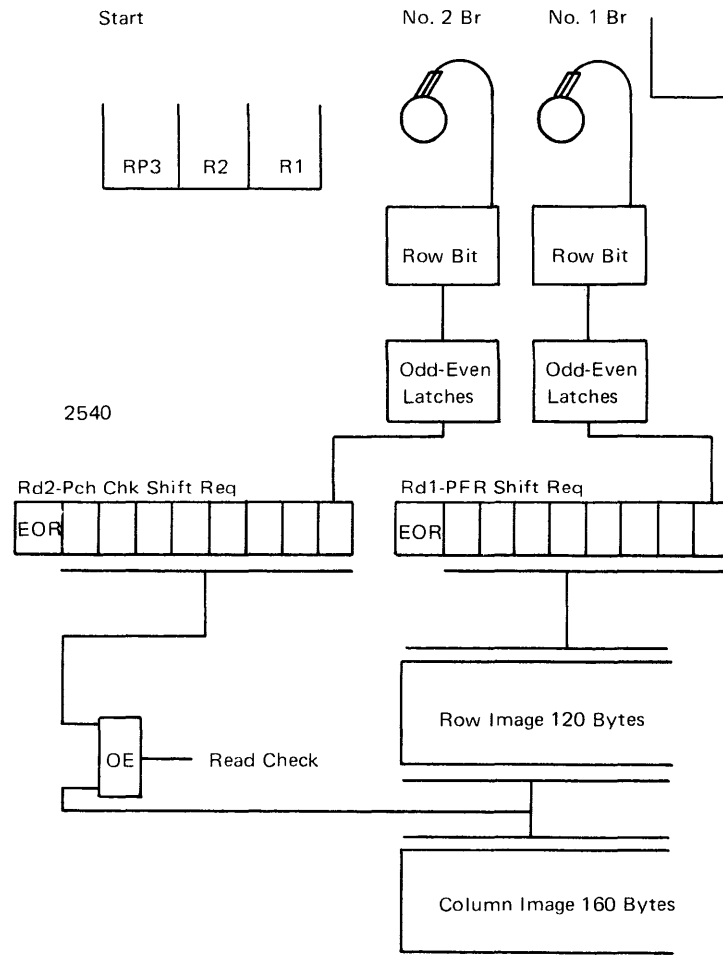
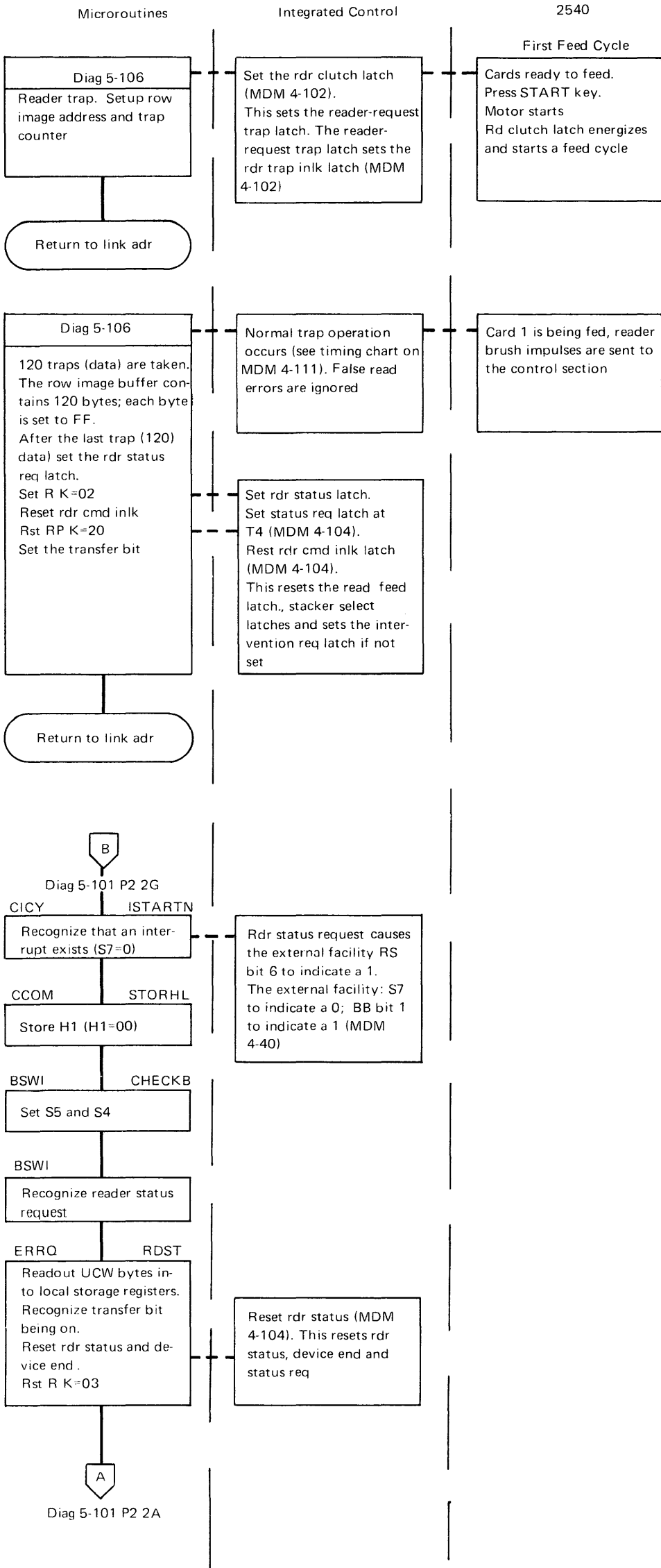
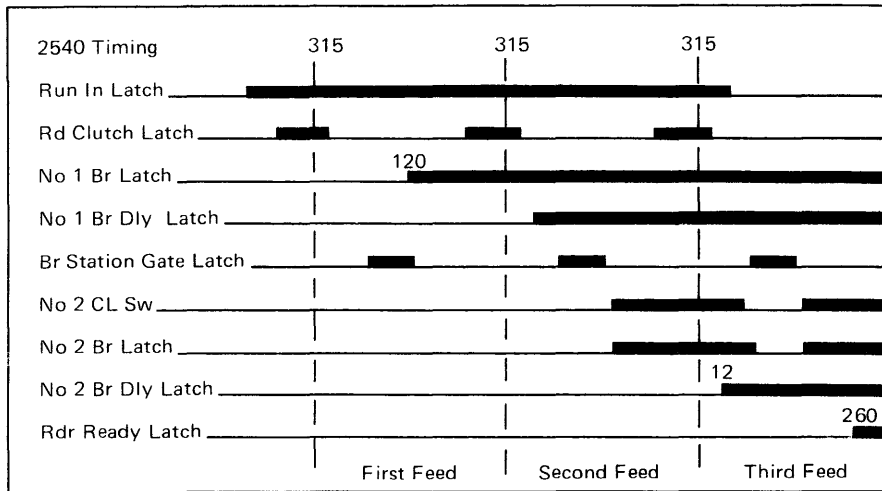
D

E

F

G

H



Error checking is done but errors are ignored.

No data read, so row image set to FF (compliment of input data). Transfer of row image to column image is done.

Diagram 5-101. Reader Run In (Part 1 of 3)

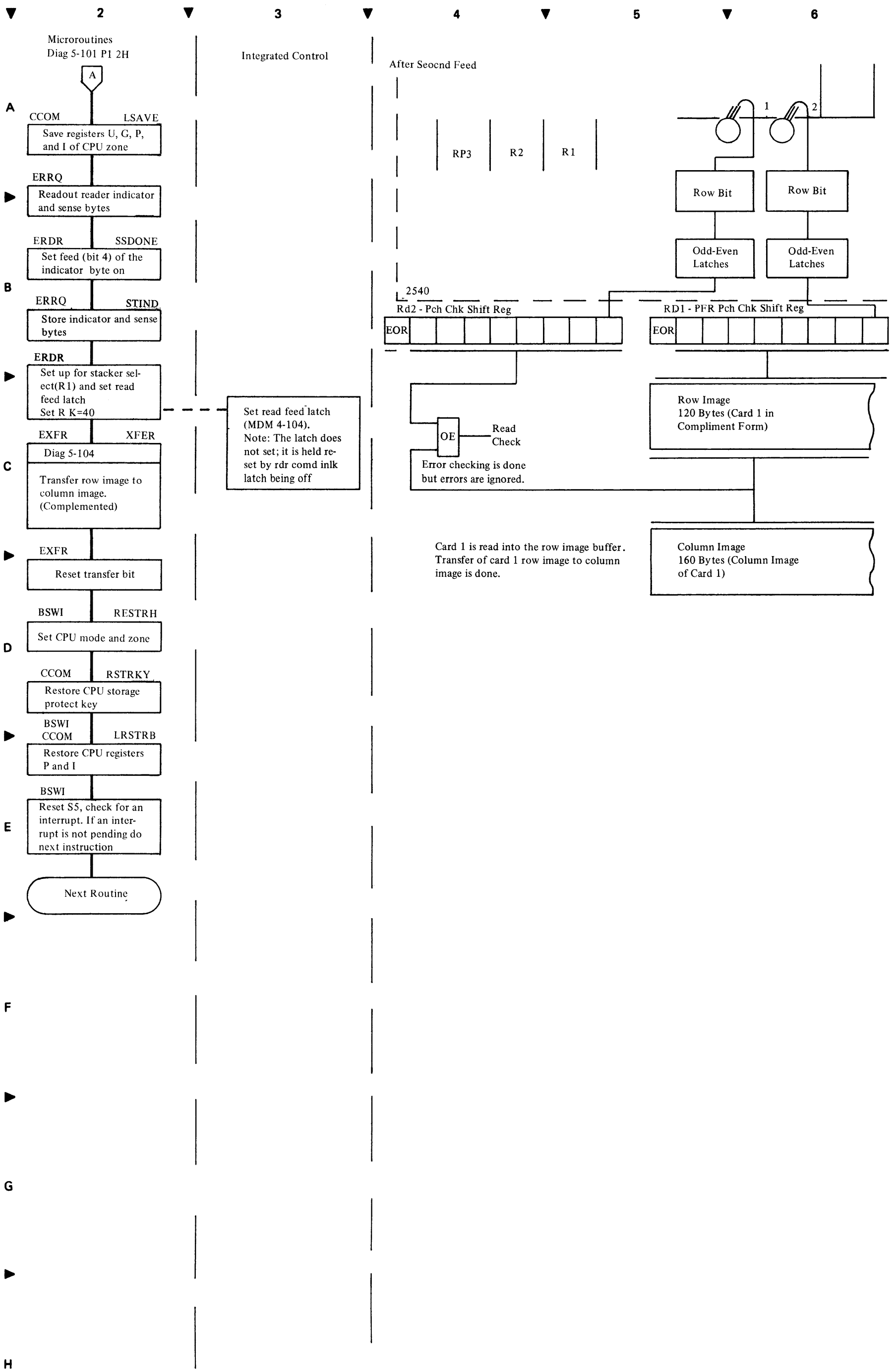


Diagram 5-101. Reader Run-In (Part 2 of 3)

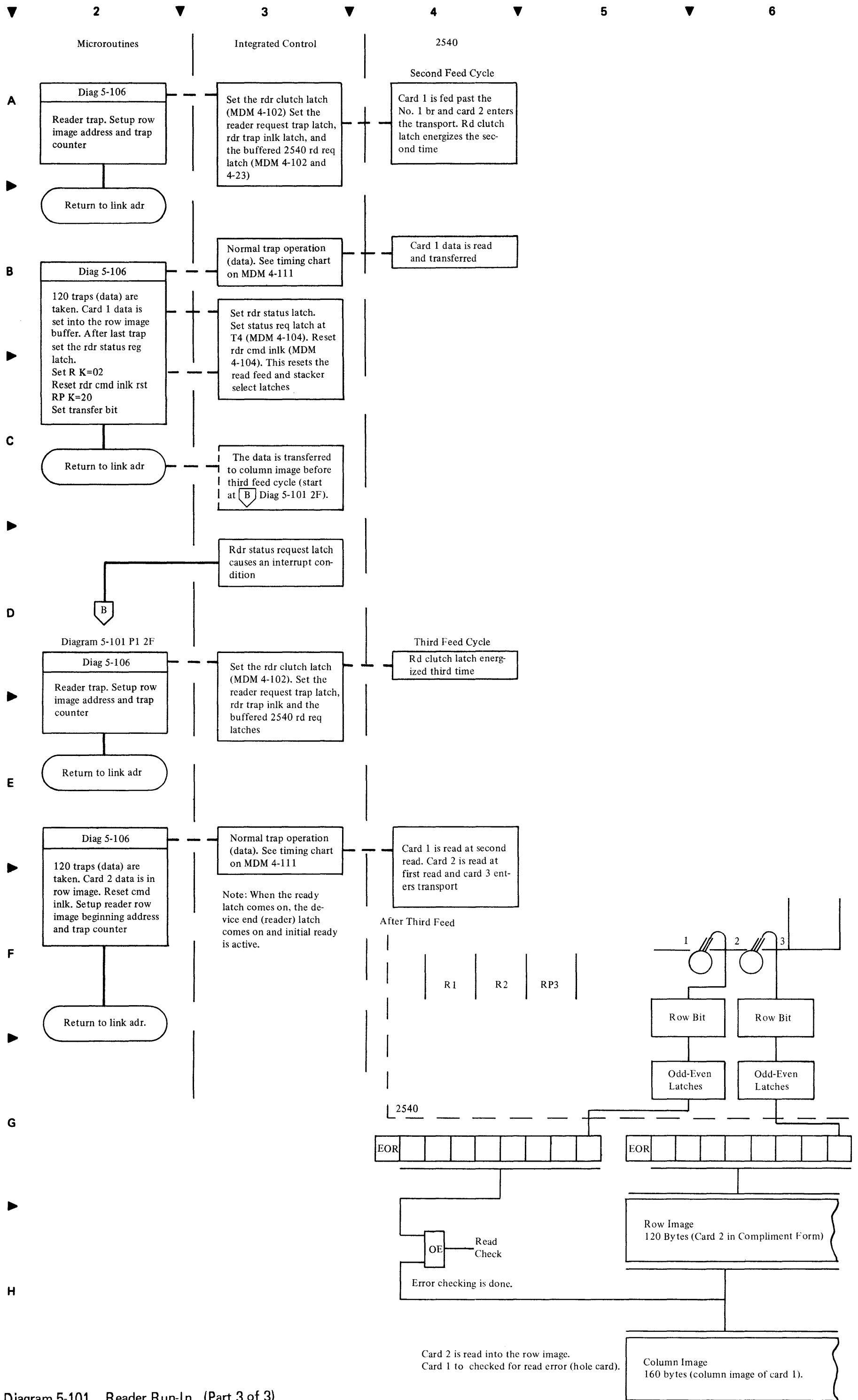


Diagram 5-101. Reader Run-In (Part 3 of 3)

Instruction: Start I/O (9C).
 Command: Read and feed, select stacker R2 (Mode 1)

Conditions: First command after run-in.
 Status bytes and flag byte clear.
 Card 1 data is in column-image buffer.
 Card 2 data is in row-image buffer.

- A**
- Objectives:**
1. Set up reader UCW.
 2. Set up for read and feed command.
 3. Translate card 1 data and store into main storage.
 4. Check validity of each character.
 5. Set up reader for feed and stacker select.
 6. Set channel-end.
 7. Start card feed.
 8. Transfer (card 2) row-image to column-image.
 9. Read card 3 and set into row-image buffer (via traps).
 10. Read card 2 from second read brushes and compare to information read out of row-image for card 1.
 11. Set reader check if one occurs.
 12. Set device-end, reset reader command and SS latches.

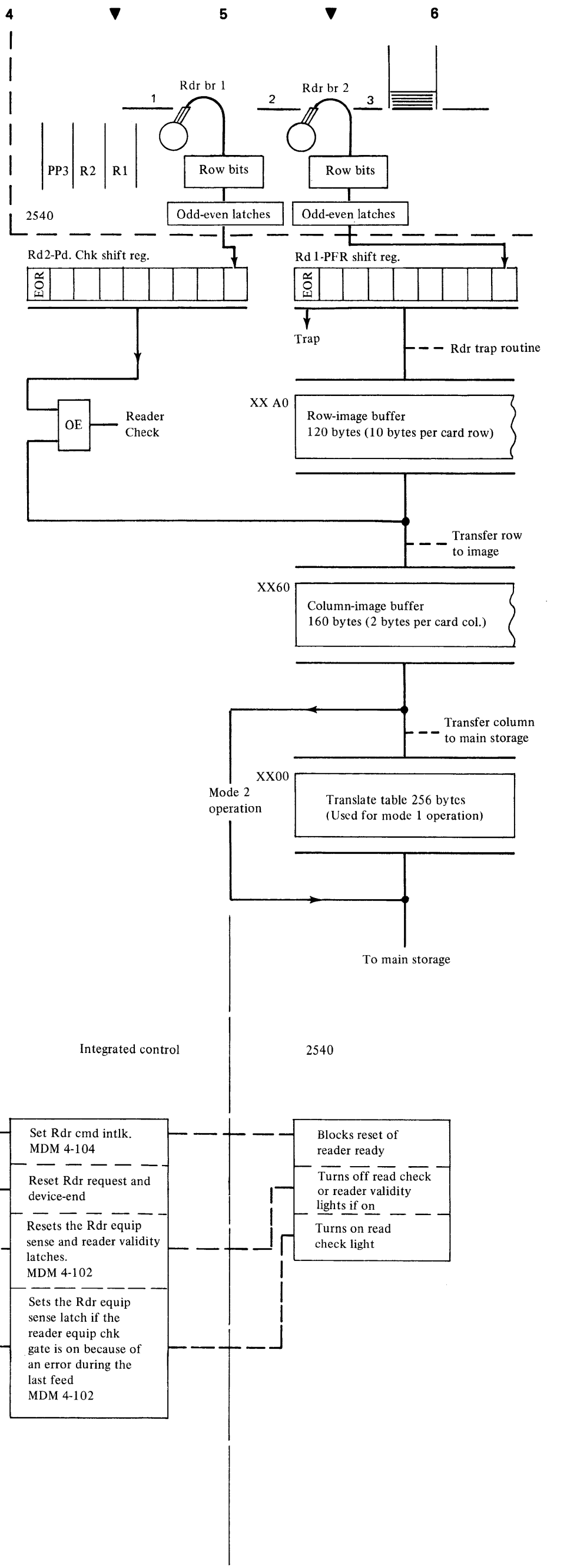
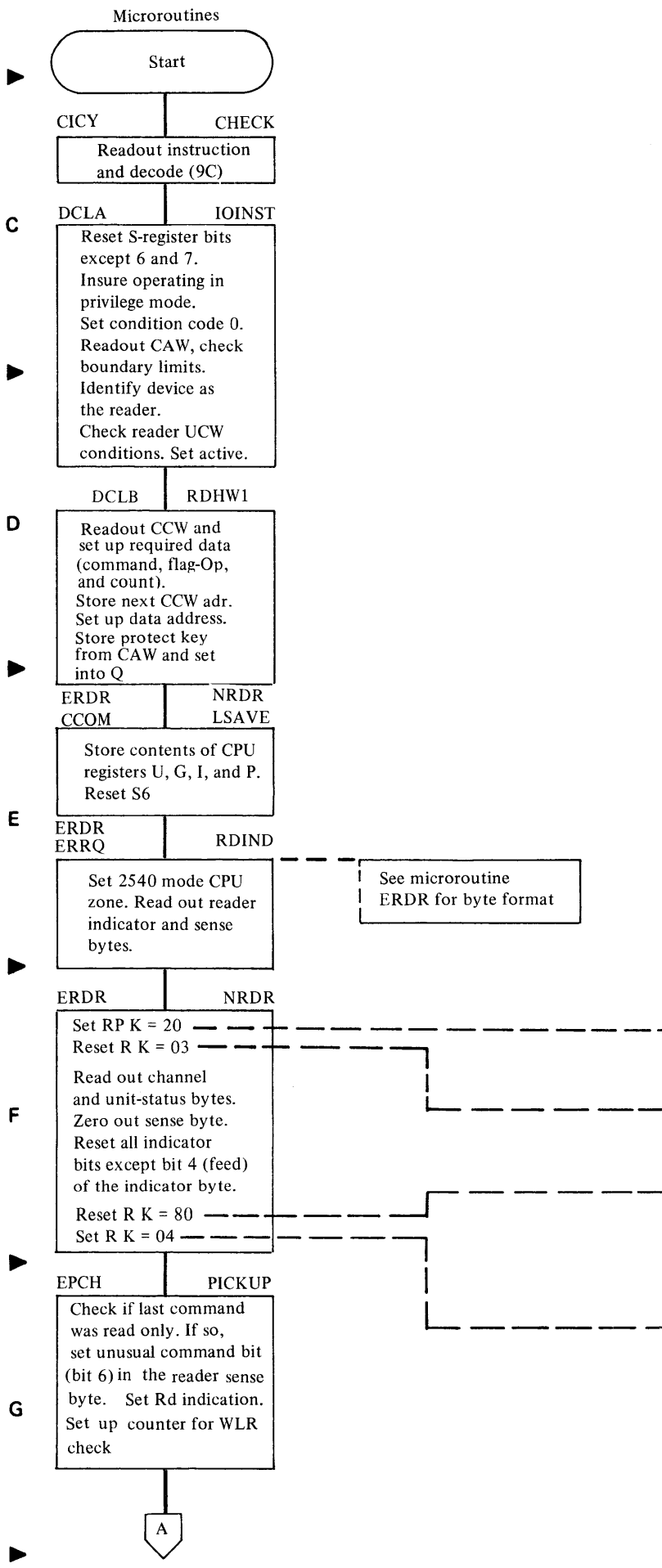


Diagram 5-103. Read Feed and Stacker Select (Reader) (Part 1 of 3)

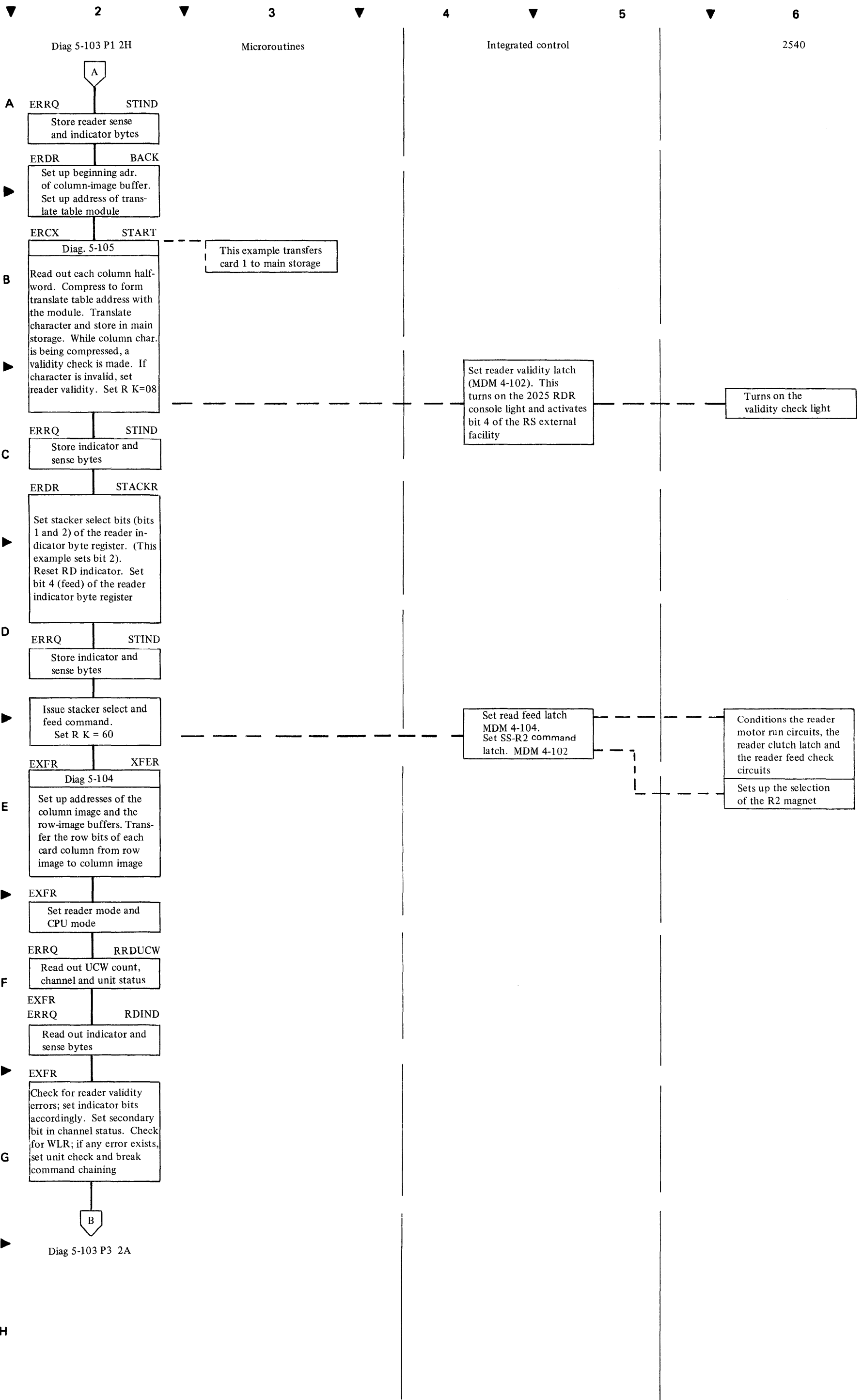


Diagram 5-103. Read Feed and Stacker Select (Part 2 of 3)

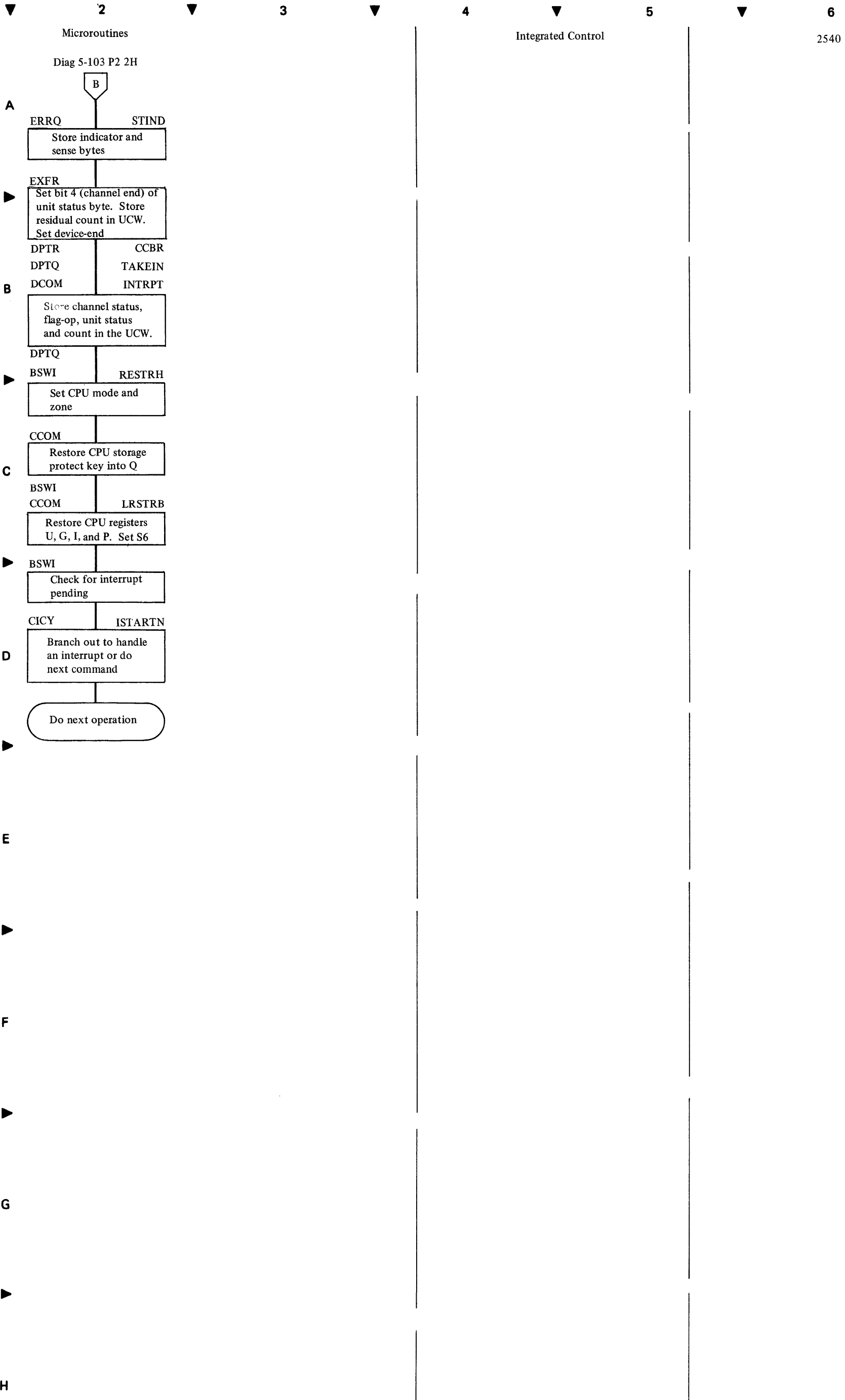
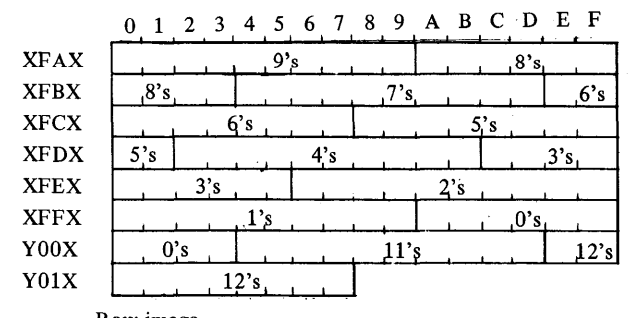
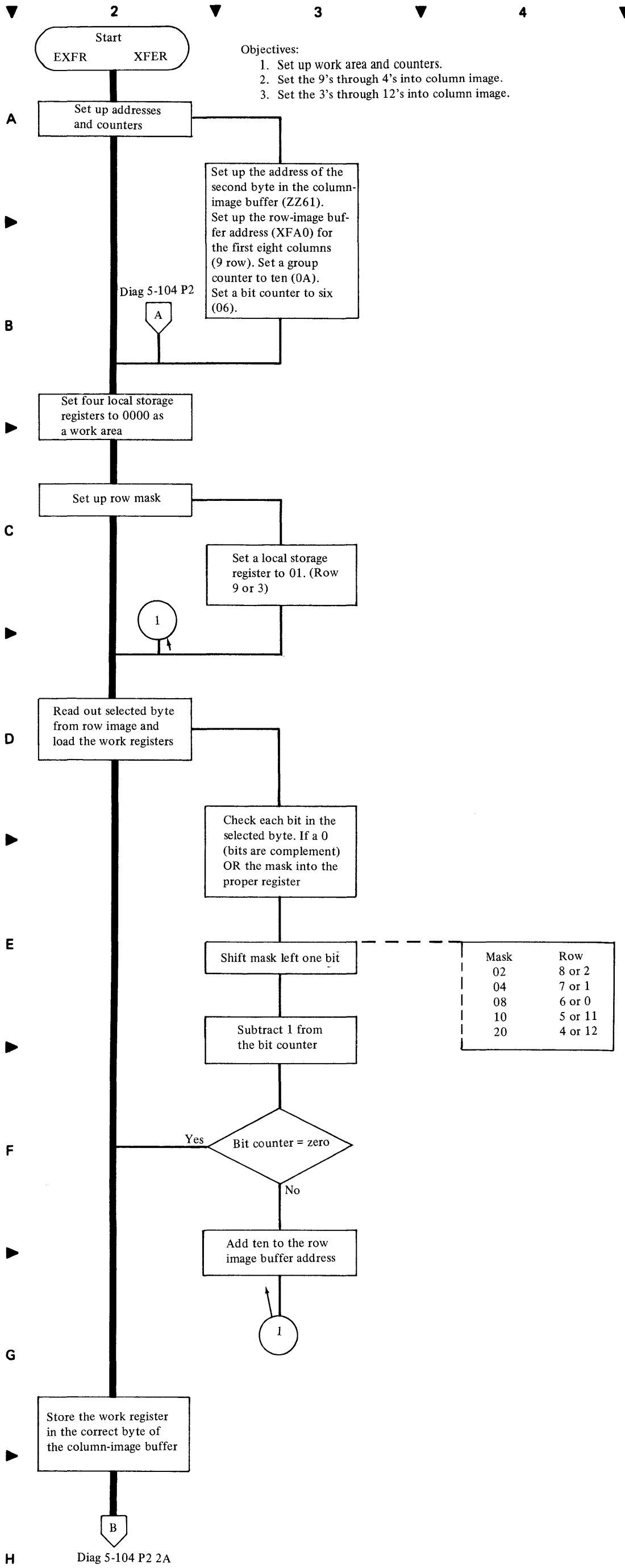


Diagram 5-103. Read Feed and Stacker Select (Part 3 of 3)



Row image

0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
Y01X									1	2	3	4			
Y02X	5	6	7	8	9	10	11	12							
Y03X	13	14	15	16	17	18	19	20							
Y04X	21	22	23	24	25	26	27	28							
Y05X	29	30	31	32	33	34	35	36							
Y06X	37	38	39	40	41	42	43	44							
Y07X	45	46	47	48	49	50	51	52							
Y08X	53	54	55	56	57	58	59	60							
Y09X	61	62	63	64	65	66	67	68							
Y0AX	69	70	71	72	73	74	75	76							
Y0BX	77	78	79	80											

Column Image

Example:
First eight columns contain A, b1, TEST b1 I----

Row-image address	contains
XFA0	FE - 1111 1110
XFAA	FF - 1111 1111
XFB4	FF - 1111 1111
XFBE	FF - 1111 1111
XFC8	EF - 1110 1111
XFD2	FF - 1111 1111
XFDC	DB - 1101 1011
XFE6	F7 - 1111 0111
XFF0	7F - 0111 1111
XFFA	D3 - 1101 0011
Y004	FF - 1111 1111
Y00E	6E - 0110 1110

Work registers after loaded with 9's through 4's for columns 1 through 8.

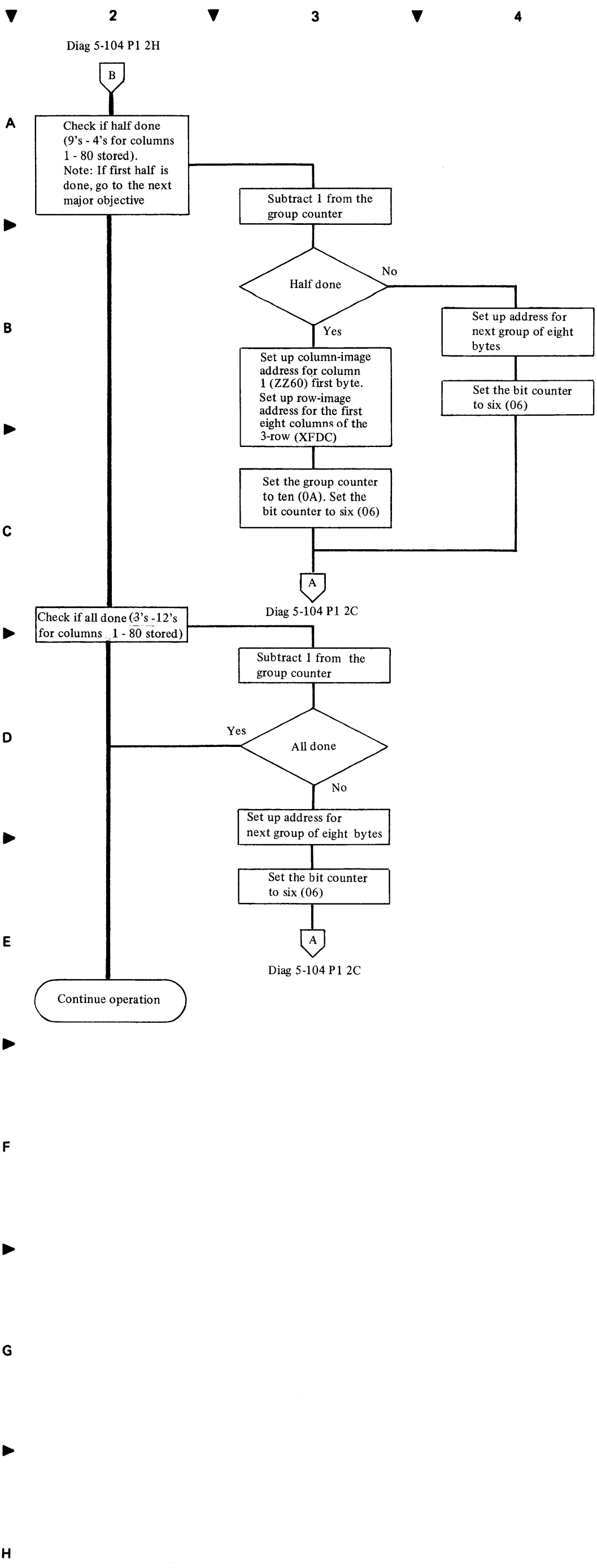
Byte 0	Byte 1	R1	Byte 0	Byte 1
00010000	00000001		Col. 4	Col. 8
00000000	00000000	R2	Col. 3	Col. 7
00000000	00000000	R3	Col. 2	Col. 6
00000000	00000000	R4	Col. 1	Col. 5

Store work registers into column image.

Work Register	Byte into	Column-image Adr
R - 4	0	Y019
R 3	0	Y01B
R 2	0	Y01D
R 1	0	Y01F
R 4	1	Y021
R 3	1	Y023
R 2	1	Y025
R 1	1	Y027

(continued in Part 2)

Diagram 5-104. Row Image to Column Image (Part 1 of 2)



Example (continued from Part 1)

Work registers loaded with 3's
through 12's for columns 1 through 8.

Byte 0	Byte 1		Byte 0	Byte 1
00100000	00100000	R1	Col. 4	Col. 8
00001001	00000000	R2	Col. 3	Col. 7
00000000	00001001	R3	Col. 2	Col. 6
00100100	00001010	R4	Col. 1	Col. 5

Store work register into column image.
Work register - byte into column-image adr.

R4	0	Y01B
R3	0	Y018
R2	0	Y01C
R1	0	Y01E
R4	1	Y020
R3	1	Y022
R2	1	Y024
R1	1	Y027

Column-image buffer for first eight columns
contents (in hex):

								Col 1	Col 2	Col 3	Col 4				
0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
								2400	0000	0900	2010				
0A00	0900	0000	2001												
								Col 5	Col 6	Col 7	Col 8	Col 9			

Diagram 5-104. Row Image to Column Image (Part 2 of 2)

A

Objectives:

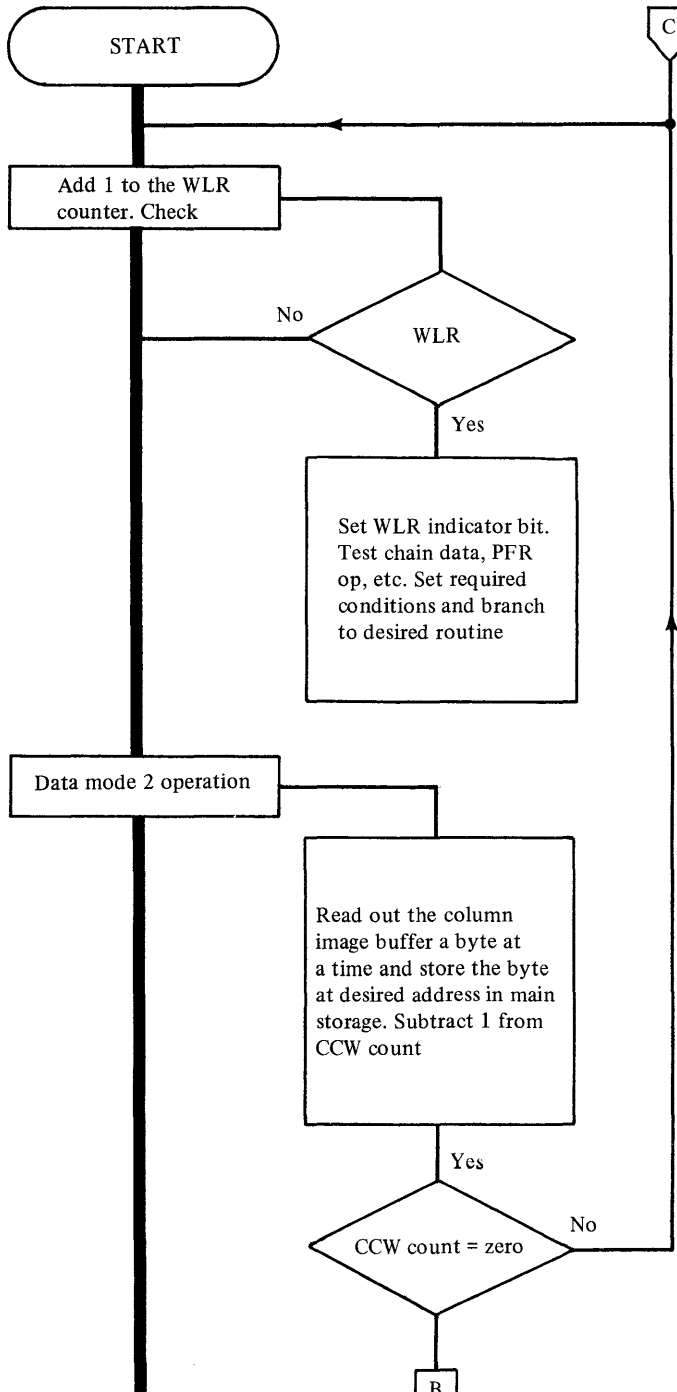
- Mode 1 -
1. Check column-image character for validity (2 bytes).
 2. Compress column-image character to develop translate table address.
 3. Store translated character at desired location in main storage.
 4. Check for wrong length record.
- Mode 2 -
1. Read out column-image buffer 1 byte at a time and store in main storage at the desired location.
 2. Check for wrong length record.

0	1	2	3	4	5	6	7	0	1	2	3	4	5	6	7
X	X	12	11	0	1	2	3	X	X	4	5	6	7	8	9

0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
Y01X	-	-	-	-	-	-	-	1	2	3	4				
Y02X	5	6	7	8	9	10	11	12							
Y03X	13	14	15	16	17	18	19	20							
Y04X	21	22	23	24	25	26	27	28							
Y05X	29	30	31	32	33	34	35	36							
Y06X	37	38	39	40	41	42	43	44							
Y07X	45	46	47	48	49	50	51	52							
Y08X	53	54	55	56	57	58	59	60							
Y09X	61	62	63	64	65	66	67	68							
Y0AX	69	70	71	72	73	74	75	76							
Y0BX	77	78	79	80	-	-	-	-							

B

Diag 5-105 P2 2G



C

D

E

F

G

H

Column image

0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F	
XX0X	40	F1	F2	F3	F4	F5	F6	F7	F0	61	E2	E3	E4	E5	E6	E7
XX1X	61	D1	D2	D3	D4	D5	D6	D7	D0	A1	A2	A3	A4	A5	A6	A7
XX2X	50	C1	C2	C3	C4	C5	C6	C7	C0	81	82	83	84	85	86	87
XX3X	6A	91	92	93	94	95	96	97	70	B1	B2	B3	B4	B5	B6	B7
XX4X	F9	31	32	33	34	35	36	37	E9	21	22	23	24	25	26	27
XX5X	D9	11	12	13	14	15	16	17	A9	E1	62	63	64	65	66	67
XX6X	C9	01	02	03	04	05	06	07	89	41	42	43	44	45	46	47
XX7X	99	51	52	53	54	55	56	57	B9	71	72	73	74	75	76	77
XX8X	F8	79	7A	7B	7C	7D	7E	7F	E8	69	E0	6B	6C	6D	6E	6F
XX9X	D8	59	5A	5B	5C	5D	5E	5F	A8	A0	AA	AB	AC	AD	AE	AF
XXAX	C8	49	4A	4B	4C	4D	4E	4F	88	80	8A	8B	8C	8D	8E	8F
XXBX	98	90	9A	9B	9C	9D	9E	9F	B8	B0	BA	BB	BC	BD	BE	BF
XXCX	38	39	3A	3B	3C	3D	3E	3F	28	29	2A	2B	2C	2D	2E	2F
XXDX	18	19	1A	1B	1C	1D	1E	1F	68	20	EA	EB	EC	ED	EE	EF
XXEX	08	09	0A	0B	0C	0D	0E	0F	48	00	CA	CB	CC	CD	CE	CF
XXFX	58	10	DA	DB	DC	DD	DE	DF	78	30	FA	FB	FC	FD	FE	FF

2540 Reader translate table (hex code)

Example: Mode 1 operation, card column contains a period (12 - 3 - 8).

Even byte	Odd byte
00100001	00000010

Even byte	Odd byte
00100001	00001000

Even byte	Odd byte
10100001	00001000

Even byte	Odd byte
10100000	00001000

Set even byte bits 6 and 7

Even byte	Odd byte
10100011	00001000

Column Bits 123		
0	0	1

Even byte is the compressed byte that forms the translate table low two hex address digits. For this example it is A3, which reads out a hex code of 4B. Hex code for a period is 4B.

Diag 5-105 P2 2A

Diagram 5-105. Read Column Image to Storage (Part 1 of 2)

Diag 5-105 P1 2

A

Check column bits 4, 5, 6 and 7

Col. bits 4, 5, 6 and 7 are zero

Check bits 1, 2, and 3. Set required bits in the even byte or set validity error

Translate or validity

Translate

2

Validity

1

Col. Bits			Set bits	Do
1	2	3		
0	0	0	Compressed byte ok	Translate
0	0	1	Set bits 6 and 7 of even byte	Translate
0	1	0	Set bit 6 of even byte	Translate
0	1	1	Use compressed byte as is	Validity
1	0	0	Set bit 7 of even byte	Translate
1	0	1	Use compressed byte as is	Validity
1	1	0	Use compressed byte as is	Validity
1	1	1	Use compressed byte as is	Validity

Check column bits 1, 2, and 3

Col. bits 1, 2, and 3 are zero

Set bit 5 of the even byte (character requires at least a 4)

If col. bit 4 is a 1, byte is compressed. If 0, must be a 5, 6, or 7

Col. bit 4 is a 1

Col. bits 5, 6, and 7 are zero

Set validity check (set R K = 08)

Translate or validity

Translate

1

Col. Bits			Set bits	Do
5	6	7		
0	0	0	Compressed byte ok	Translate
0	0	1	Set bits 6 and 7 of even byte	Translate
0	1	0	Set bit 6 of even byte	Translate
0	1	1	Use compressed byte as is	Validity
1	0	0	Set bit 7 of even byte	Translate
1	0	1	Use compressed byte as is	Validity
1	1	0	Use compressed byte as is	Validity
1	1	1	Use compressed byte as is	Validity

Do a table lookup for translate character. (The compressed byte even, is the low byte of the translate table address)

Store translated character in main storage at the desired location

Subtract 1 from CCW count. Check

CCW count = zero

Test chain data, PFR op etc. Set required condition and branch to desired routine

Diag 5-105 P1 3E

B

Diag 5-105 P1 4B

C

H

Diagram 5-105. Read Column Image to Storage (Part 2 of 2)

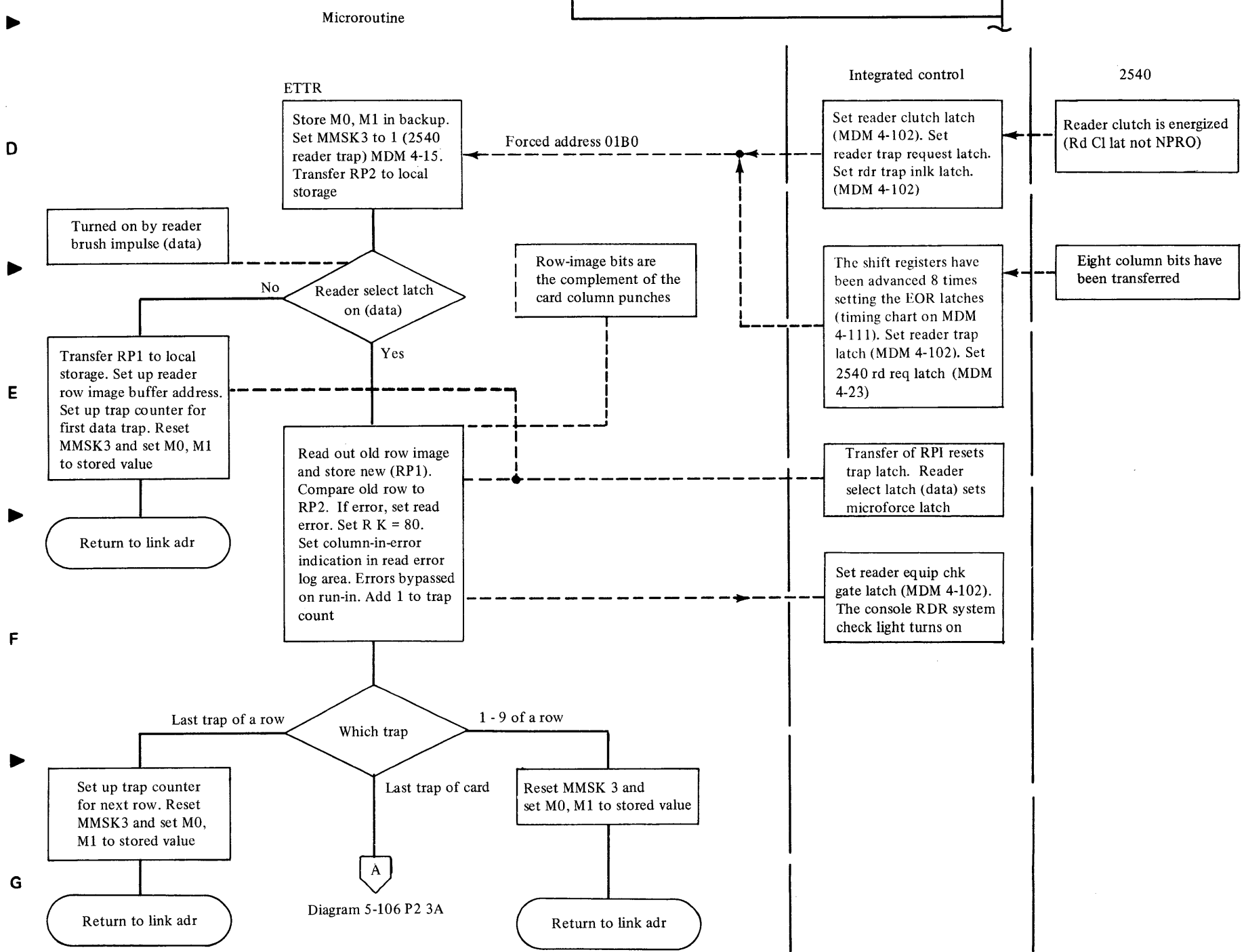
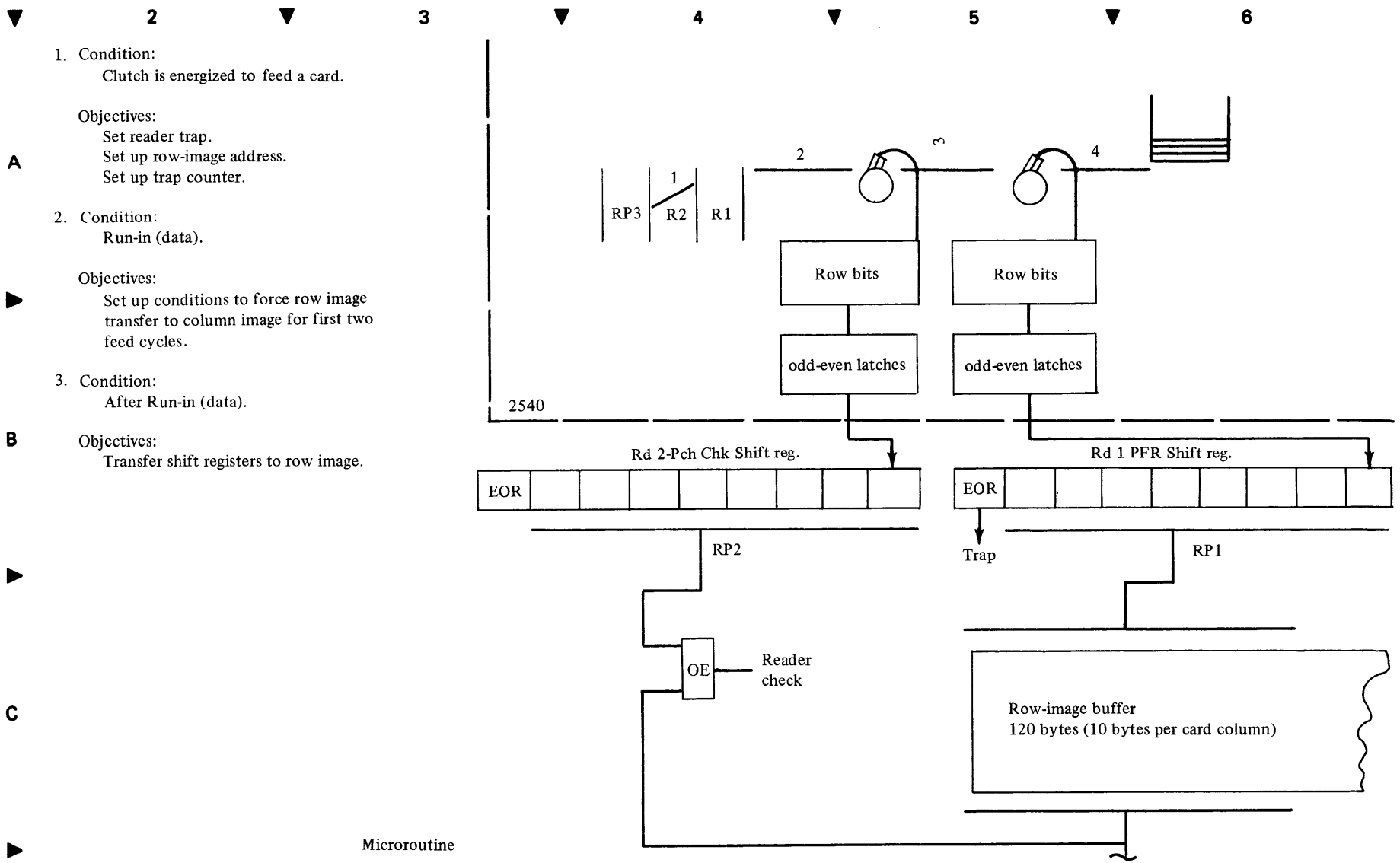
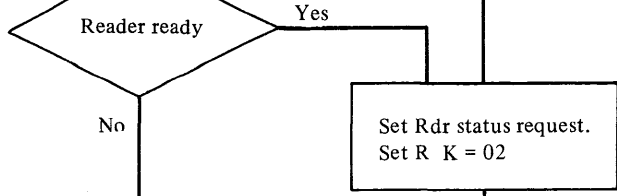
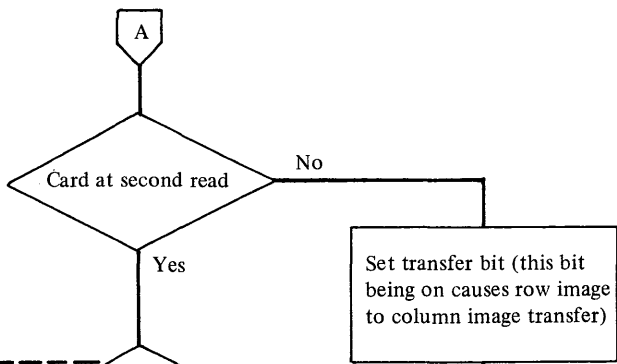


Diagram 5-106. Reader Trap (Part 1 of 2)

Diag 5-106 P130

A
B
C
D
E
F
G
H

Reader ready should be active after the first card has been read at the second read station



Reset cmd inlk
Rst PR K = 20
Set up reader row image beginning addresses and trap counter
Restore M0, M1, Reset MMSK 3.

Return to link address

Set Rdr status request.
Set R K = 02

Reset cmd inlk. Rst PR K = 20. Set up reader row image beginning address and trap counter.

Return to link address

Set the rdr status latch (MDM 4-104).
Note: This turns on Device-end latch if read feed is on. A test of 2540 external facility RS bit 6 indicates a 1 (MDM 4-45). At T4 time, set the status req latch (MDM 4-104). A test of external facility S7 indicates a 0, while a test of BB bit 1 indicates a 1. (MDM 4-40)

Reset rdr cmd inlk latch (MDM-104). Reset of the rdr cmd inlk resets the read feed latch (MDM 4-104) and reader stacker select latches. (MDM 4-102).

Diagram 5-106. Reader Trap (Part 2 of 2)

Objective: Handle status (channel-end and/or device-end) except for IPL on the reader or punch.

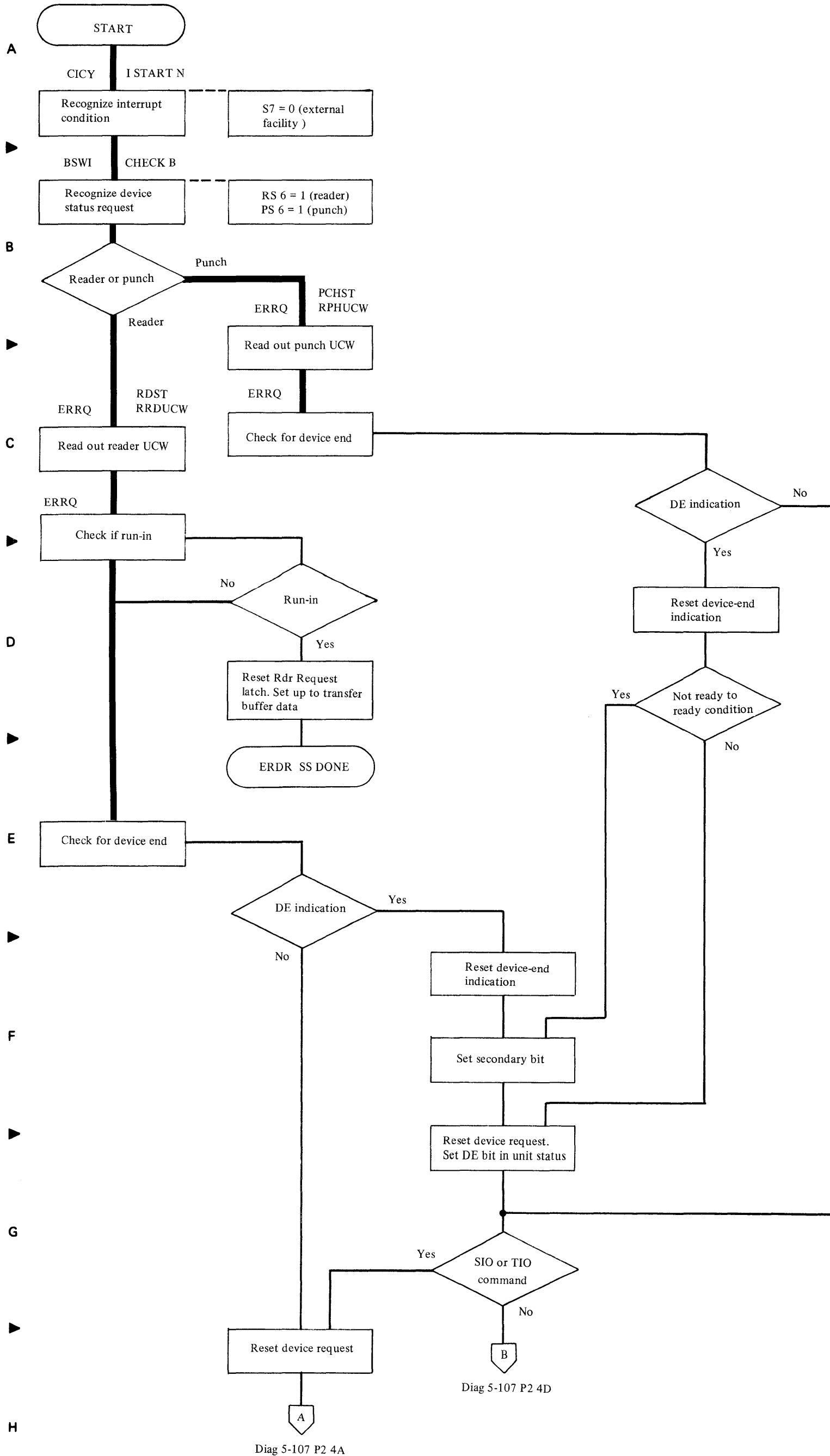


Diagram 5-107. Reader-Punch Status (Part 1 of 2)

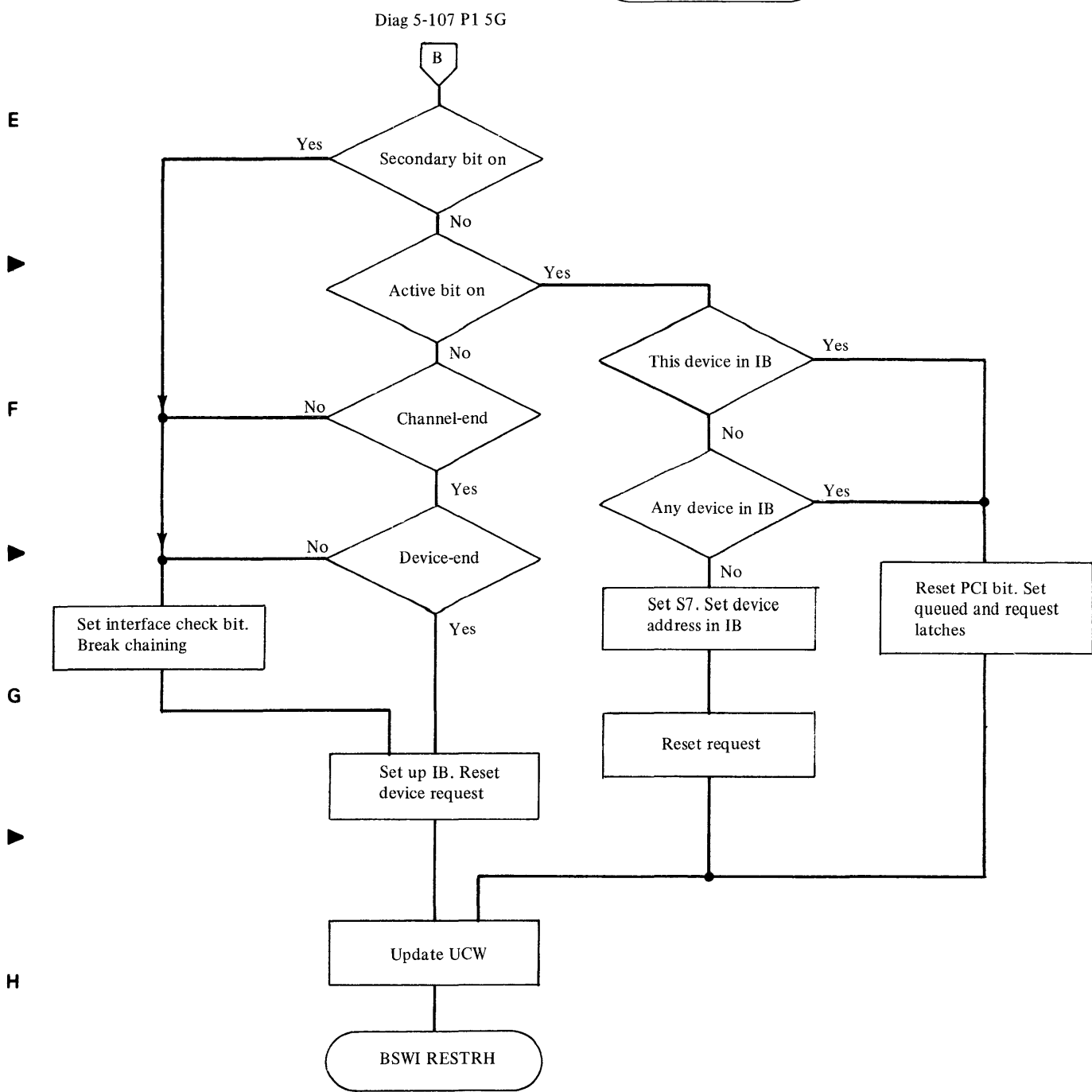
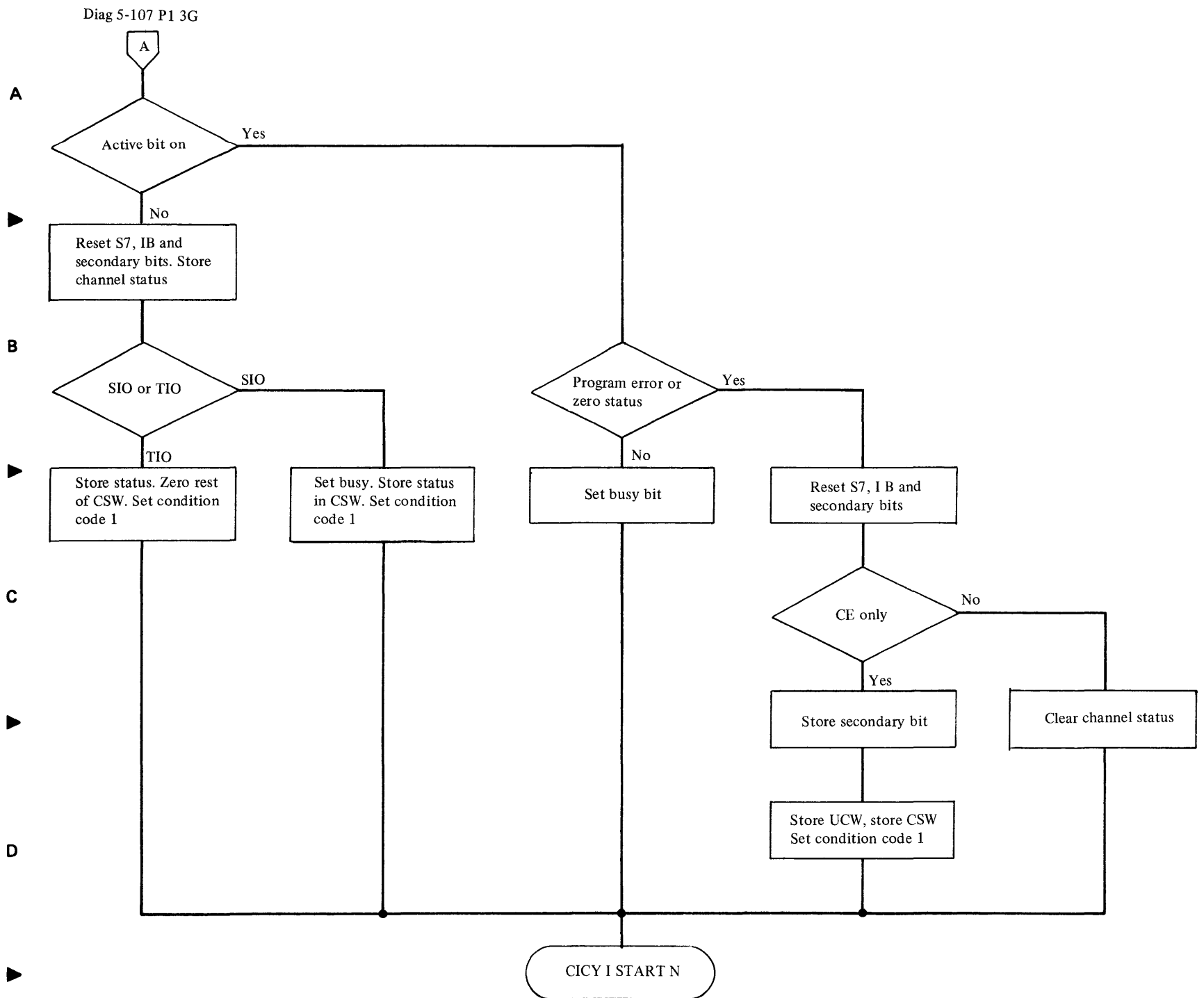


Diagram 5-107. Reader-Punch Status (Part 2 of 2)

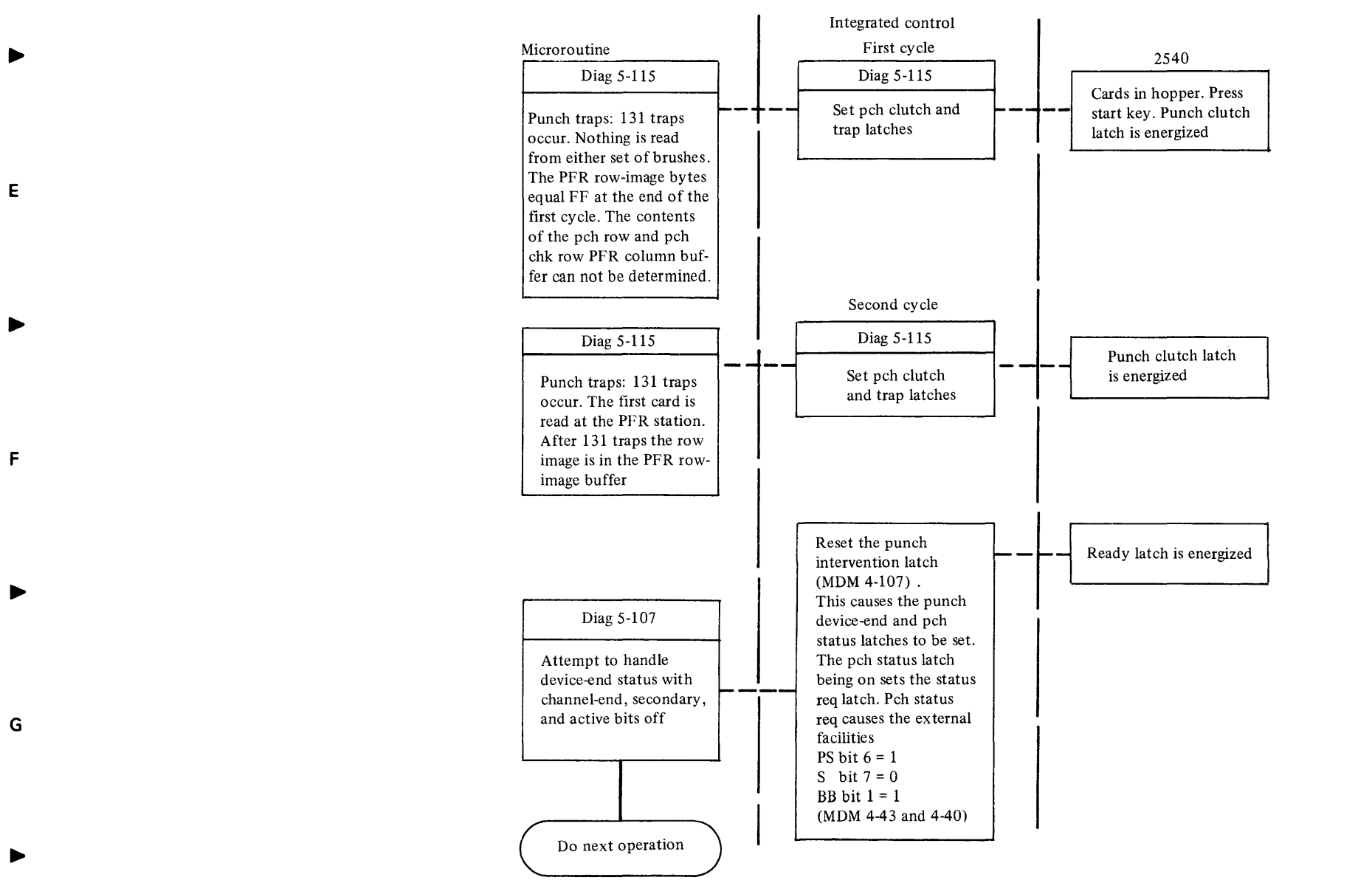
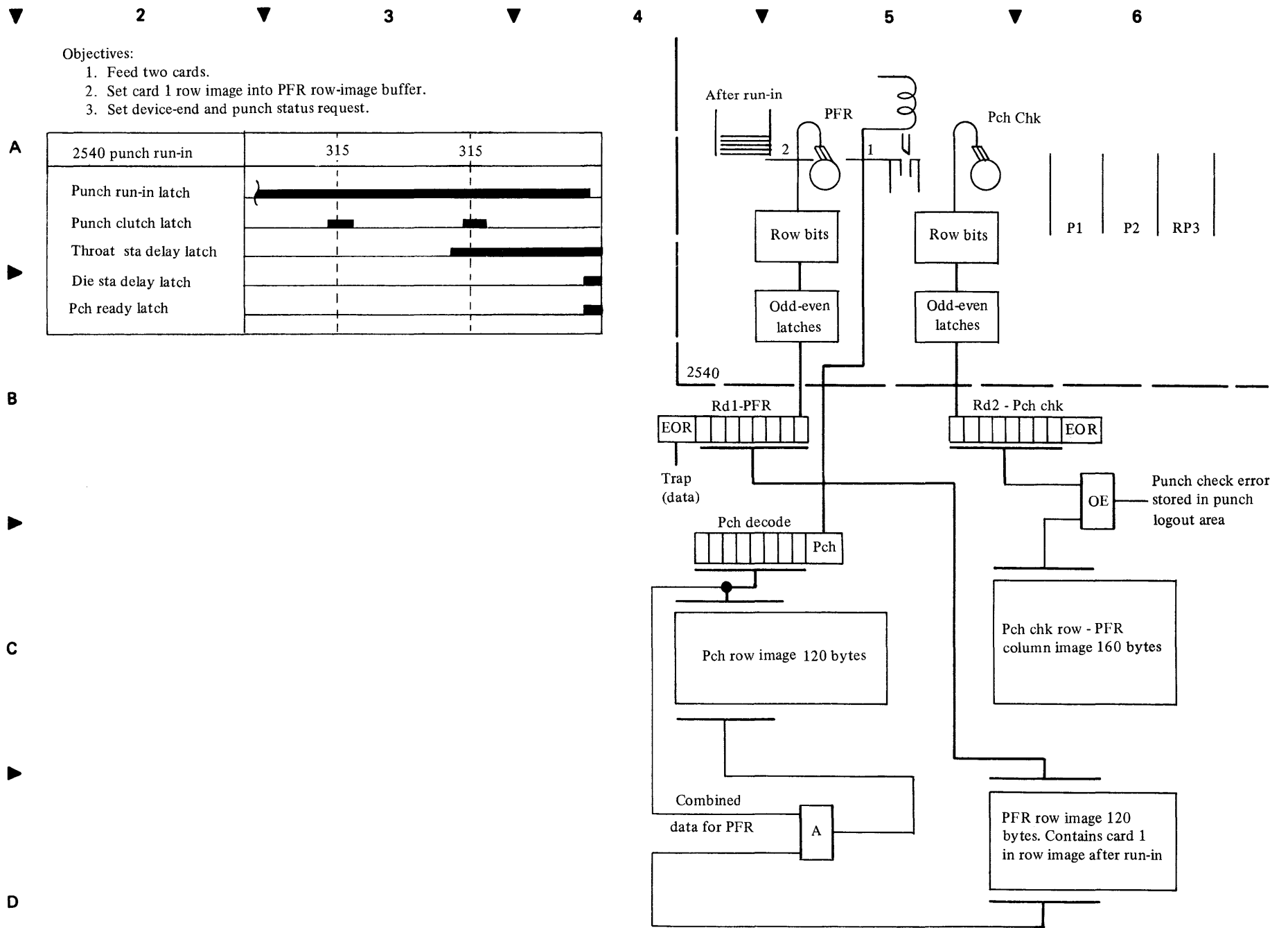
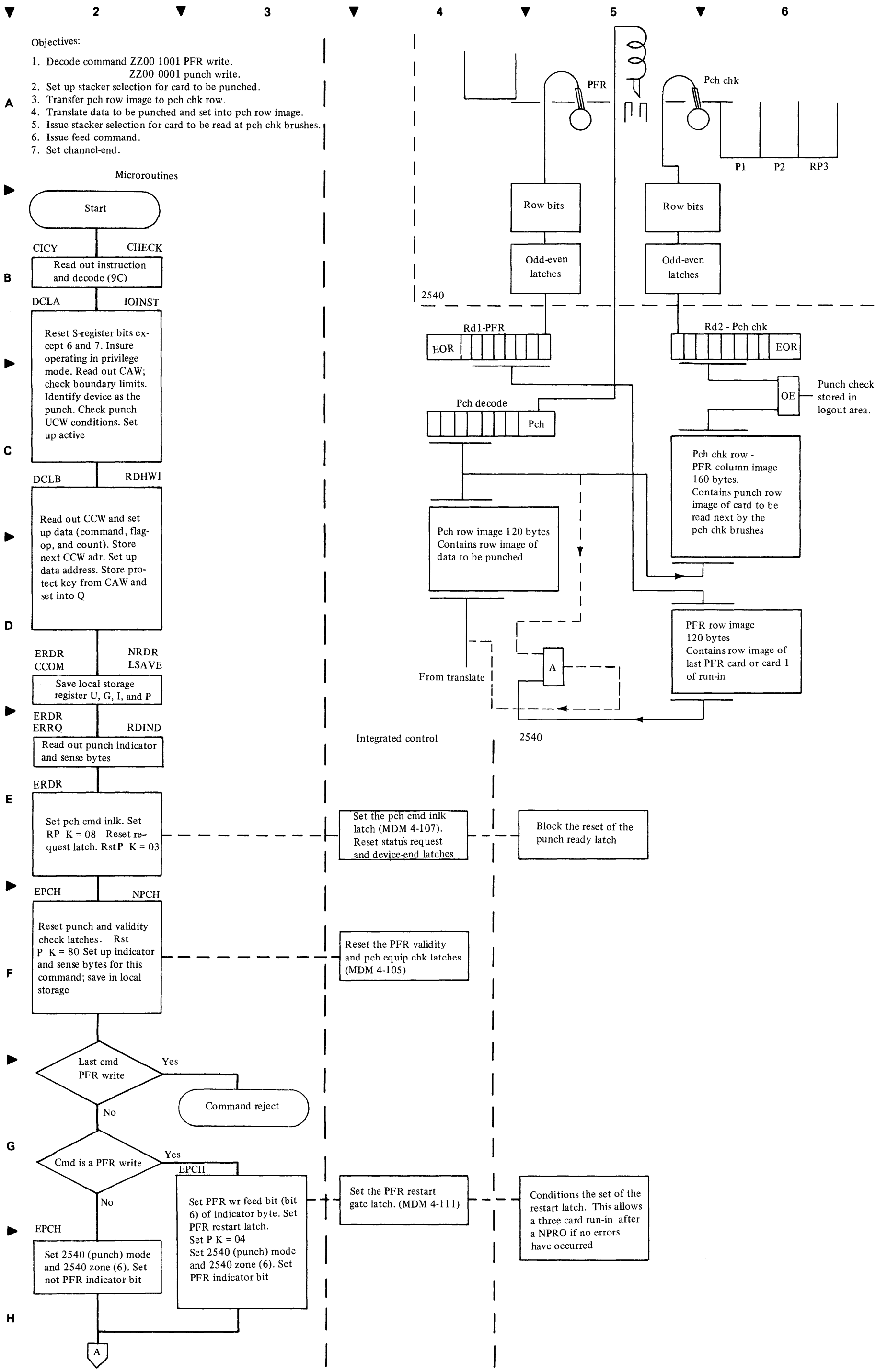


Diagram 5-111. Punch Run-In (Normal)



Diag 5-112 P2 2A

Diagram 5-112. Start I/O (Punch Write) (Part 1 of 3)

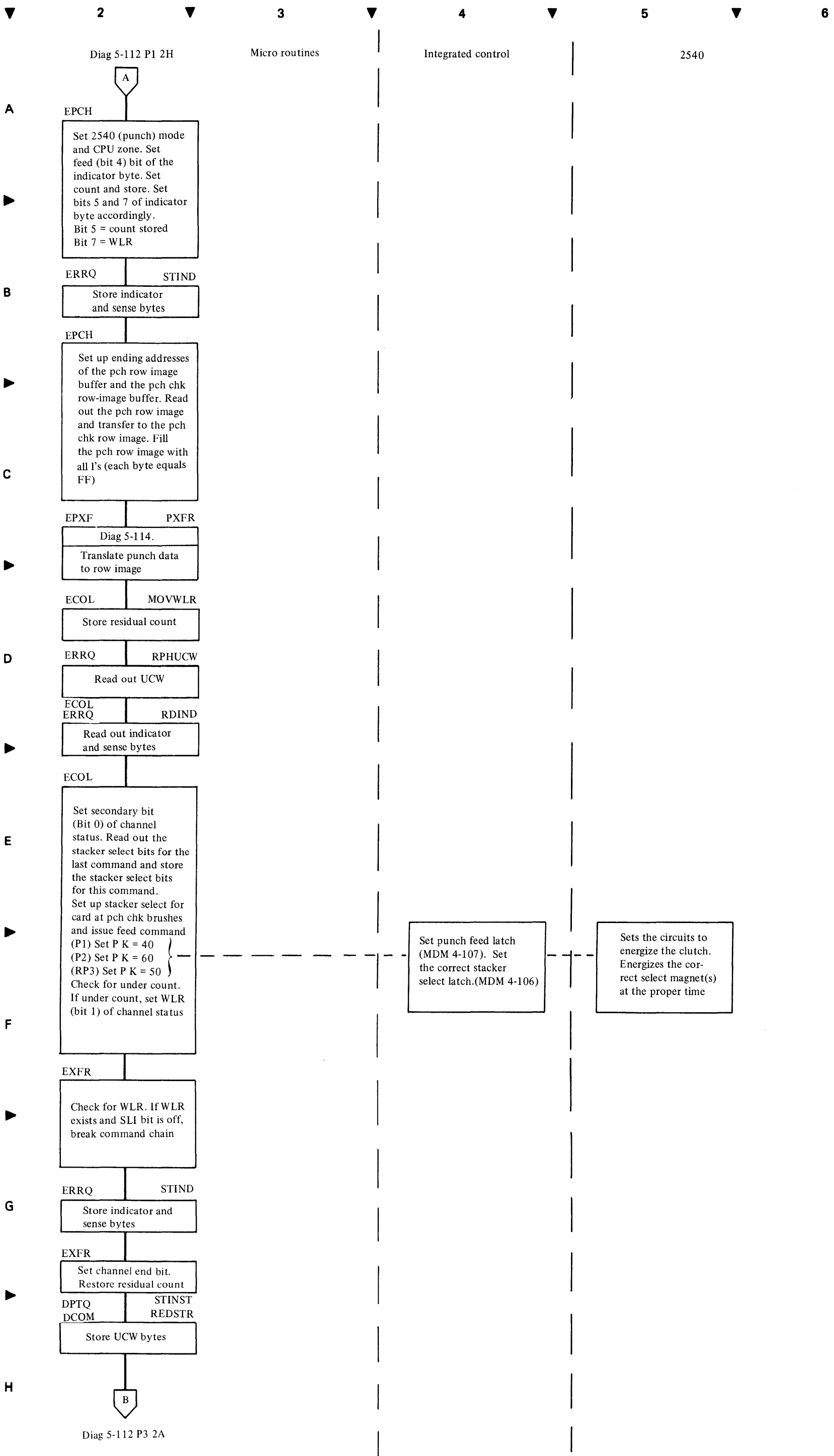


Diagram 5-112. Start I/O (Punch Write) (Part 2 of 3)

Diag 5-112 P2 2H

B

DPTQ
BSWI

RESTRH

Set CPU mode and zone

CCOM

RSTRKY

Restore CPU storage
protect key into Q

CCOM

LRSTRB

Restore local storage
register (CPU zone)

BSWI

Check for interrupt
pending

CICY

ISTARTN

Branch out to handle
interrupt or do next
command

Do next operation

A

▶

B

▶

C

▶

D

▶

E

▶

F

▶

G

▶

H

Diagram 5-112. Start I/O (Punch Write) (Part 3 of 3)

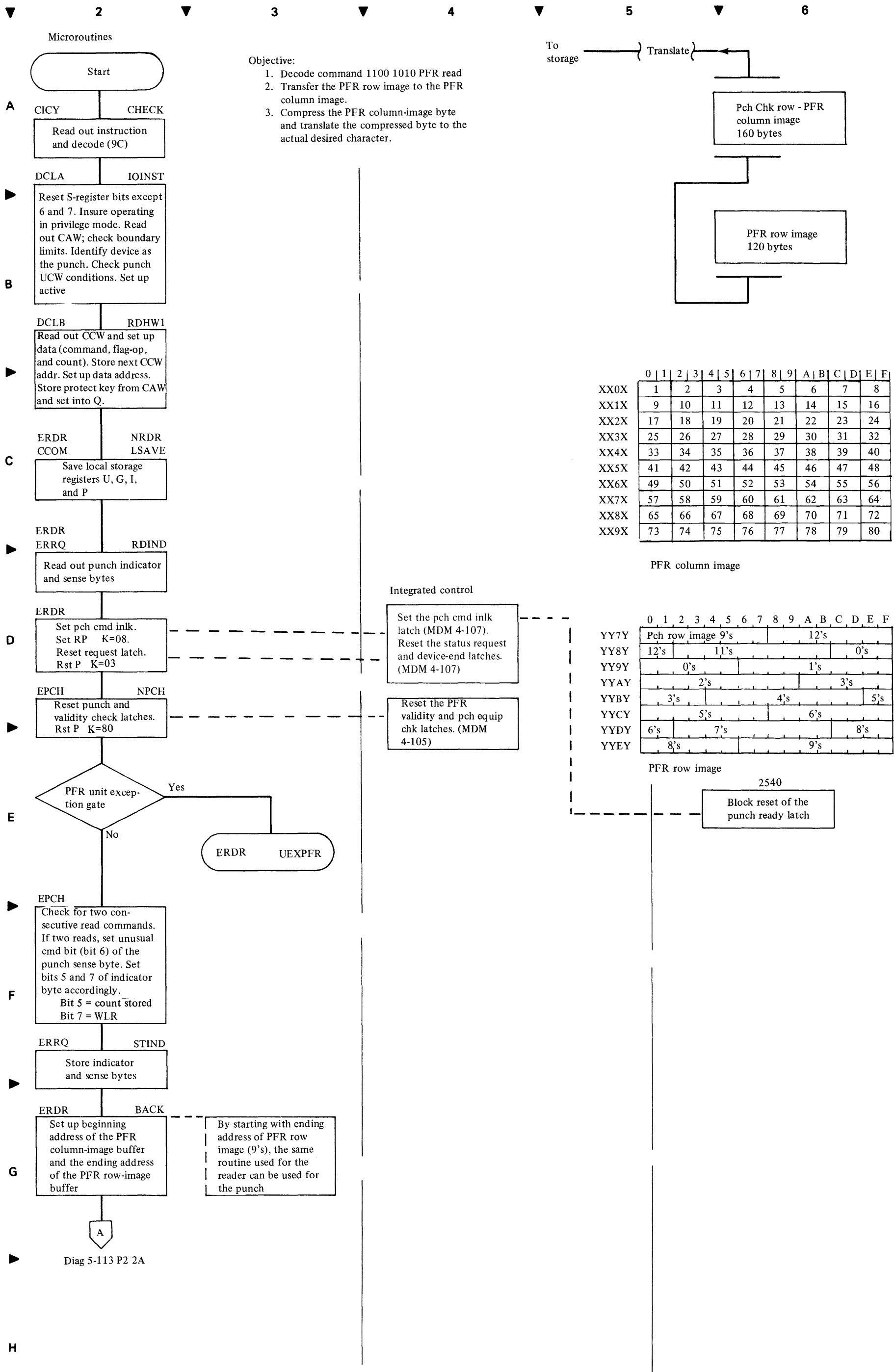


Diagram 5-113. Punch Feed Read (Part 1 of 2)

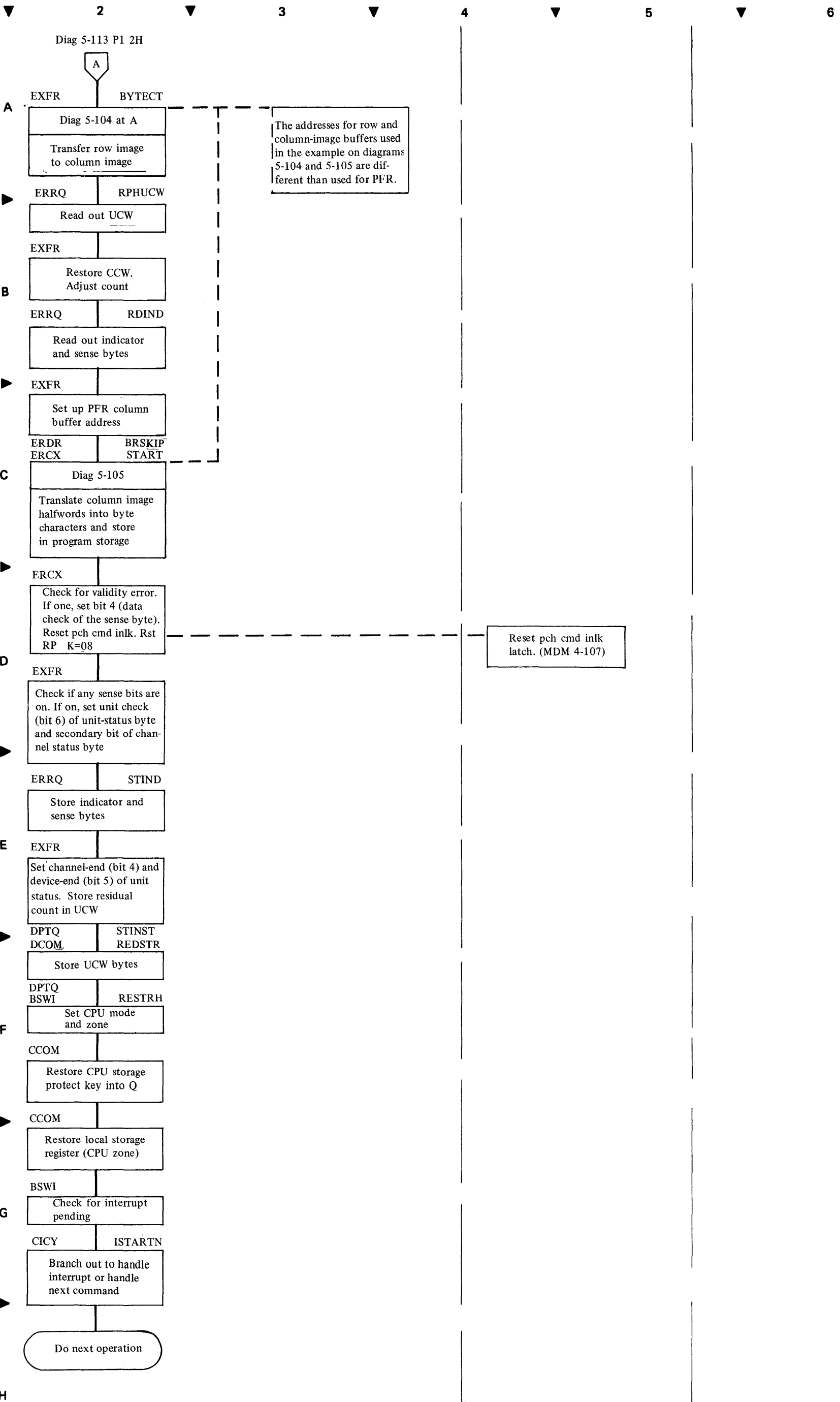
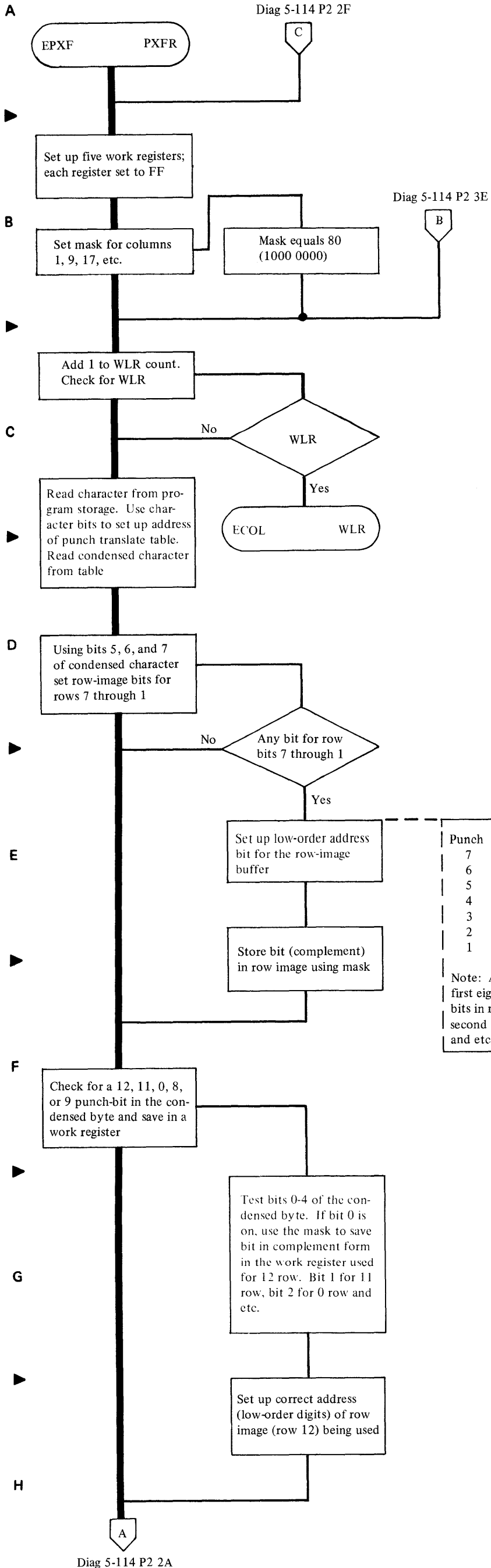


Diagram 5-113. Punch Feed Read (Part 2 of 2)

Objectives:

1. Set up work area and counter.
2. Translate data to be punched and set into punch row image in complement form.



	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
XX0X	12's								11's							
XX1X	11's				0's								1's			
XX2X	1's				2's								4's			
XX3X	2's		3's						4's				5's			
XX4X	4's				5's								7's			
XX5X	6's						7's									
XX6X	7's				8's								9's			
XX7X	9's															

Punch row-image buffer

	0	1	2	3	4	5	6	7	8	9	A	B	C	D	E	F
ZZ0Z	B9	89	8A	8B	8C	8D	8E	8F	98	99	9A	9B	9C	9D	9E	9F
ZZ1Z	D9	49	4A	4B	4C	4D	4E	4F	58	59	5A	5B	5C	5D	5E	5F
ZZ2Z	79	29	2A	2B	2C	2D	2E	2F	38	39	3A	3B	3C	3D	3E	3F
ZZ3Z	F9	09	0A	0B	0C	0D	0E	0F	18	19	1A	1B	1C	1D	1E	1F
ZZ4Z	00	A9	AA	AB	AC	AD	AE	AF	B8	91	92	93	94	95	96	97
ZZ5Z	80	C9	CA	CB	CC	CD	CE	CF	D8	51	52	53	54	55	56	57
ZZ6Z	40	21	6A	6B	6C	6D	6E	6F	78	31	C0	33	34	35	36	37
ZZ7Z	E0	E9	EA	EB	EC	ED	EE	EF	F8	11	12	13	14	15	16	17
ZZ8Z	B1	A1	A2	A3	A4	A5	A6	A7	B0	A8	B2	B3	B4	B5	B6	B7
ZZ9Z	D1	C1	C2	C3	C4	C5	C6	C7	D0	C8	D2	D3	D4	D5	D6	D7
ZZAZ	71	61	62	63	64	65	66	67	70	68	72	73	74	75	76	77
ZZBZ	F1	E1	E2	E3	E4	E5	E6	E7	F0	E8	F2	F3	F4	F5	F6	F7
ZZCZ	A0	81	82	83	84	85	86	87	90	88	BA	BB	BC	BD	BE	BF
ZZDZ	60	41	42	43	44	45	46	47	50	48	DA	DB	DC	DD	DE	DF
ZZEZ	32	69	22	23	24	25	26	27	30	28	7A	7B	7C	7D	7E	7F
ZZFZ	20	01	02	03	04	05	06	07	10	08	FA	FB	FC	FD	FE	FF

Punch translate table (condensed byte)

Bits	0	1	2	3	4	5	6	7
Punch	12	11	0	8	9	X	X	X
Condensed byte								
	0	0	1	1				
	0	1	0	2				
	0	1	1	3				
	1	0	0	4				
	1	0	1	5				
	1	1	0	6				
	1	1	1	7				

Example:

First eight columns (data) to be punch are 1 bl FOX bl RA.

Work registers

1	1	1	1	1	1	1	1	1	12 Row
2	1	1	1	1	1	1	1	1	11 Row
3	1	1	1	1	1	1	1	1	0 Row
4	1	1	1	1	1	1	1	1	8 Row
5	1	1	1	1	1	1	1	1	9 Row

Read data character for column 1; 1 = F1.

Read out condensed byte using data character as low-digit address. ZZ F1 = 01.

Condensed byte = 0000 0001.

Check bits 5, 6, and 7 (001). This provides a row-image address of XX1E. The byte at this address is for the first eight columns of the 1 row. Bit 0 is for column 1. Prior to this time all of row image has been set to 1's. Exclusive ORing the mask 80 with FF results in 7F. This identifies column 1 of the card, to be punched with a 1 punch. Store result into row image at the same address.

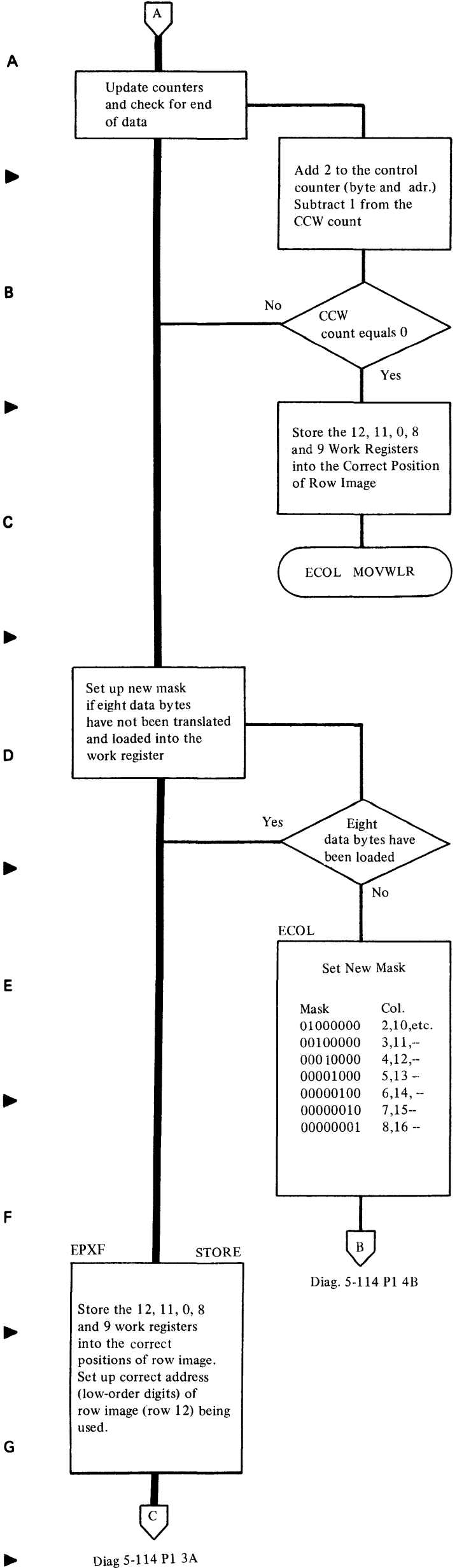
Because condensed byte bits 0-4 are all zero, nothing is stored in the work register.

Update the counters.
Set up new mask for column 2; 40.

Read out second data character; bl=40
Read out condensed byte using data character as a low-digit address. ZZ 40 = 00.
Condensed byte = 0000 0000.

Diagram 5-114. Load Punch Row Image (Part 1 of 2)

Diag 5 - P12H



Because testing of the byte indicates no punches nothing is stored or loaded into the work registers.
 Update the counters.
 Setup new mask for column 3; 20.
 Read out third data character; F = C6.
 Read out condensed byte using data character as a low-digit address. ZZC6 = 86.
 Condensed byte = 10000110.
 Check bits 5, 6, and 7 (110). This provides a row-image address of XX50. The byte at this address is for the first eight columns of the 6 row. Bit 2 is for column 3. Exclusive ORing the mask 20 with FF results in DF. This identifies column 3 of the card, to be punched with a 6 punch. Store result into row image at the same address.
 Test of condensed byte bits 0-4 indicates that bit 0 is on. This causes the mask 20 to be exclusive Ored with work register 1. The results in work register 1 set to DF.
 Update the counters.
 Set up new mask for column 4; 10.
 Continue routine until eight-byte (data) have been loaded into row image and work registers.
 For this example the work registers contain the following

Work Registers

1	1 1 0 1 1 1 1 0	12 Row
2	1 1 1 0 1 1 0 1	11 Row
3	1 1 1 1 0 1 1 1	0 Row
4	1 1 1 1 1 1 1 1	8 Row
5	1 1 1 1 1 1 0 1	9 Row

Transfer the work registers to the correct locations in row image.
 Row-image bytes for the first eight columns for this example are:

Row	Address	Byte
12	XX00	11011110
11	XX0A	11101101
0	XX14	11110111
1	XX1E	01111110
2	XX28	11111111
3	XX32	11111111
4	XX3C	11111111
5	XX46	11111111
6	XX50	11001111
7	XX5A	11110111
8	XX64	11111111
9	XX6E	11111101

The address for row image now points to the next set of bytes (eight more columns).
 Set the five work register to FF and repeat routine for next eight columns.

ECOL

Mask	Col.
01000000	2,10,etc.
00100000	3,11,--
00010000	4,12,--
00001000	5,13 --
00000100	6,14, --
00000010	7,15--
00000001	8,16 --

EPXF STORE

Store the 12, 11, 0, 8 and 9 work registers into the correct positions of row image. Set up correct address (low-order digits) of row image (row 12) being used.

Diag. 5-114 P1 4B

Diag 5-114 P1 3A

Diagram 5-114. Load Punch Row Image (Part 2 of 2)

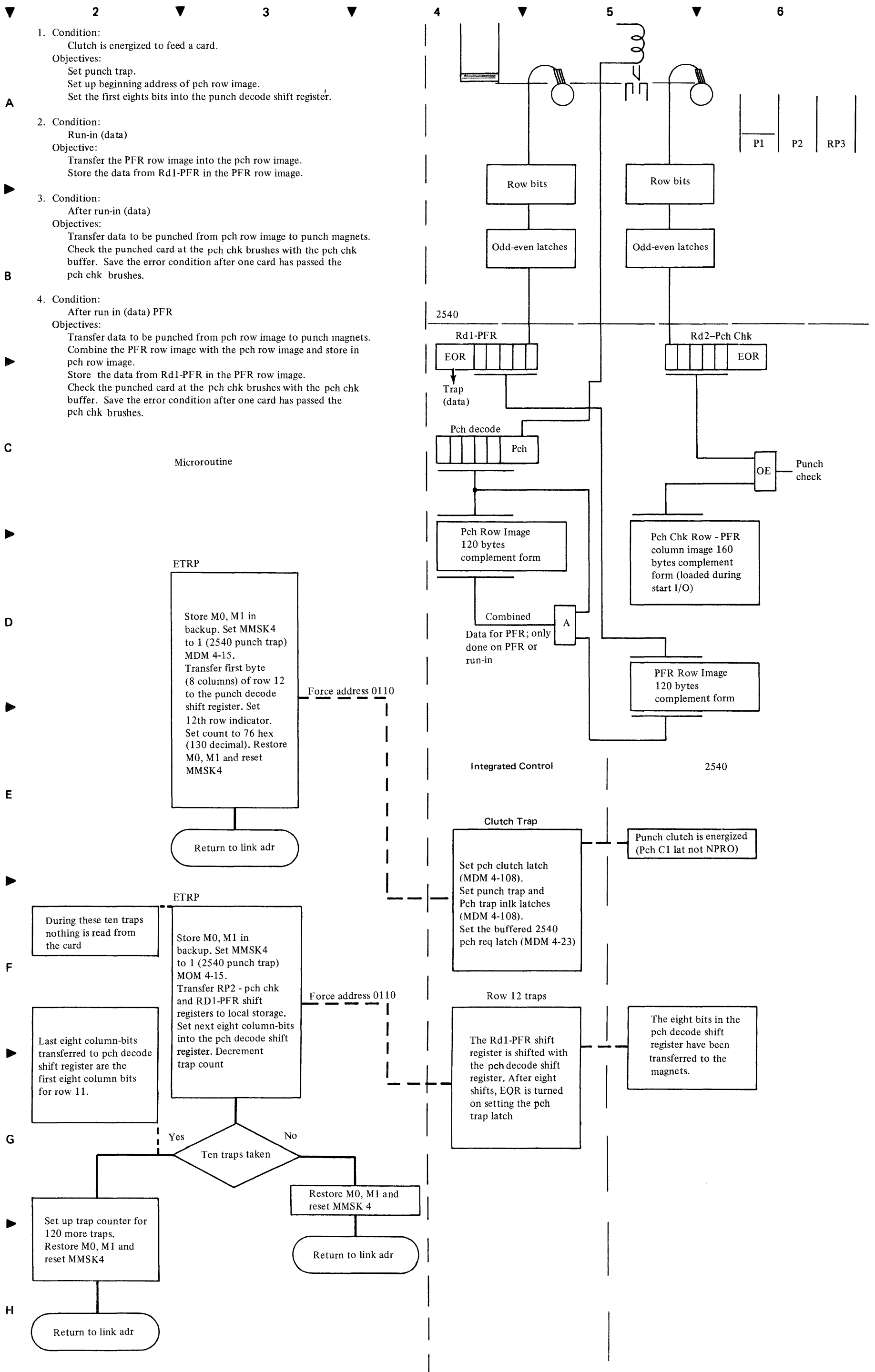


Diagram 5-115. Punch Trap (Part 1 of 2)

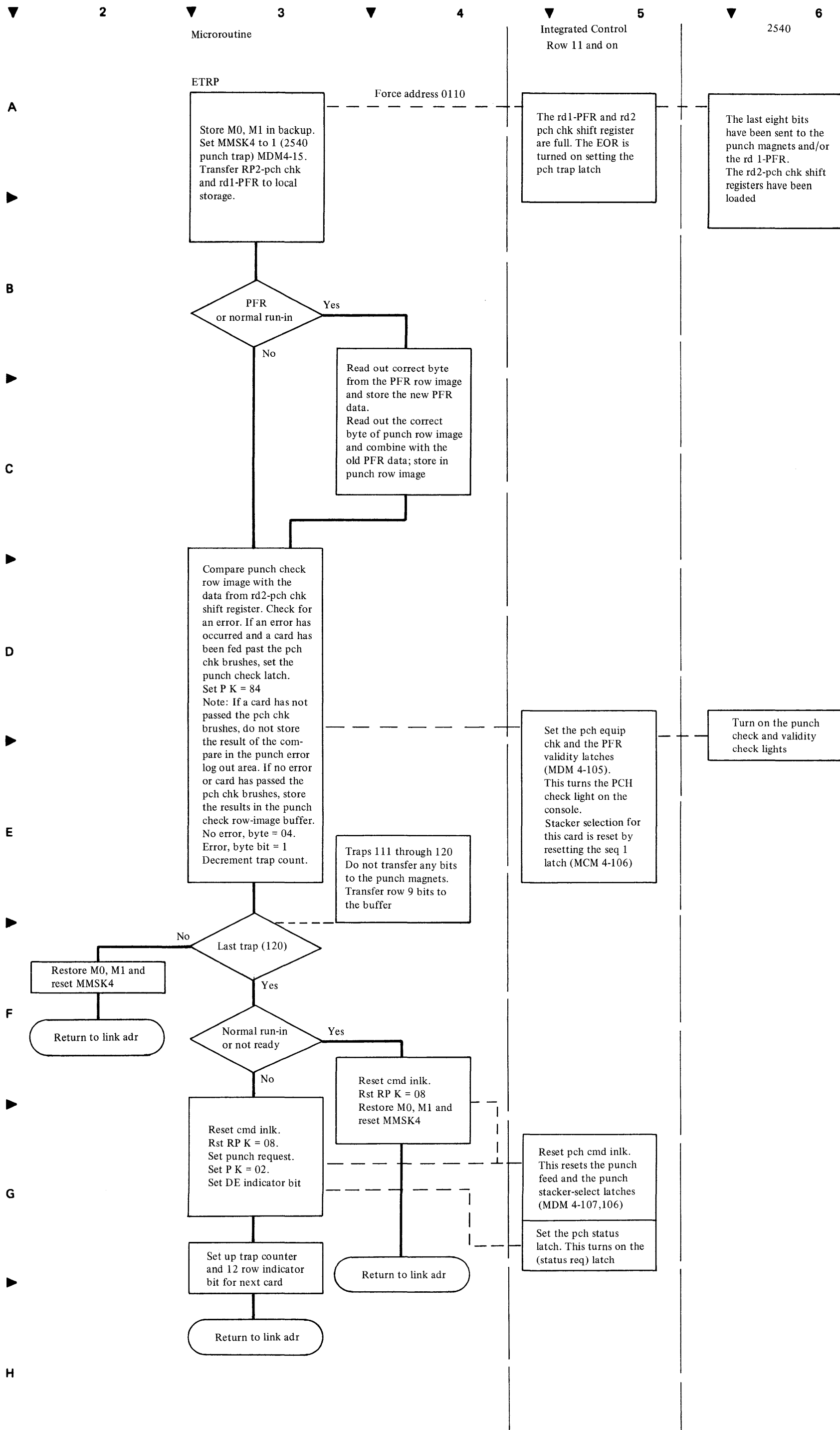


Diagram 5-115. Punch Trap (Part 2 of 2)

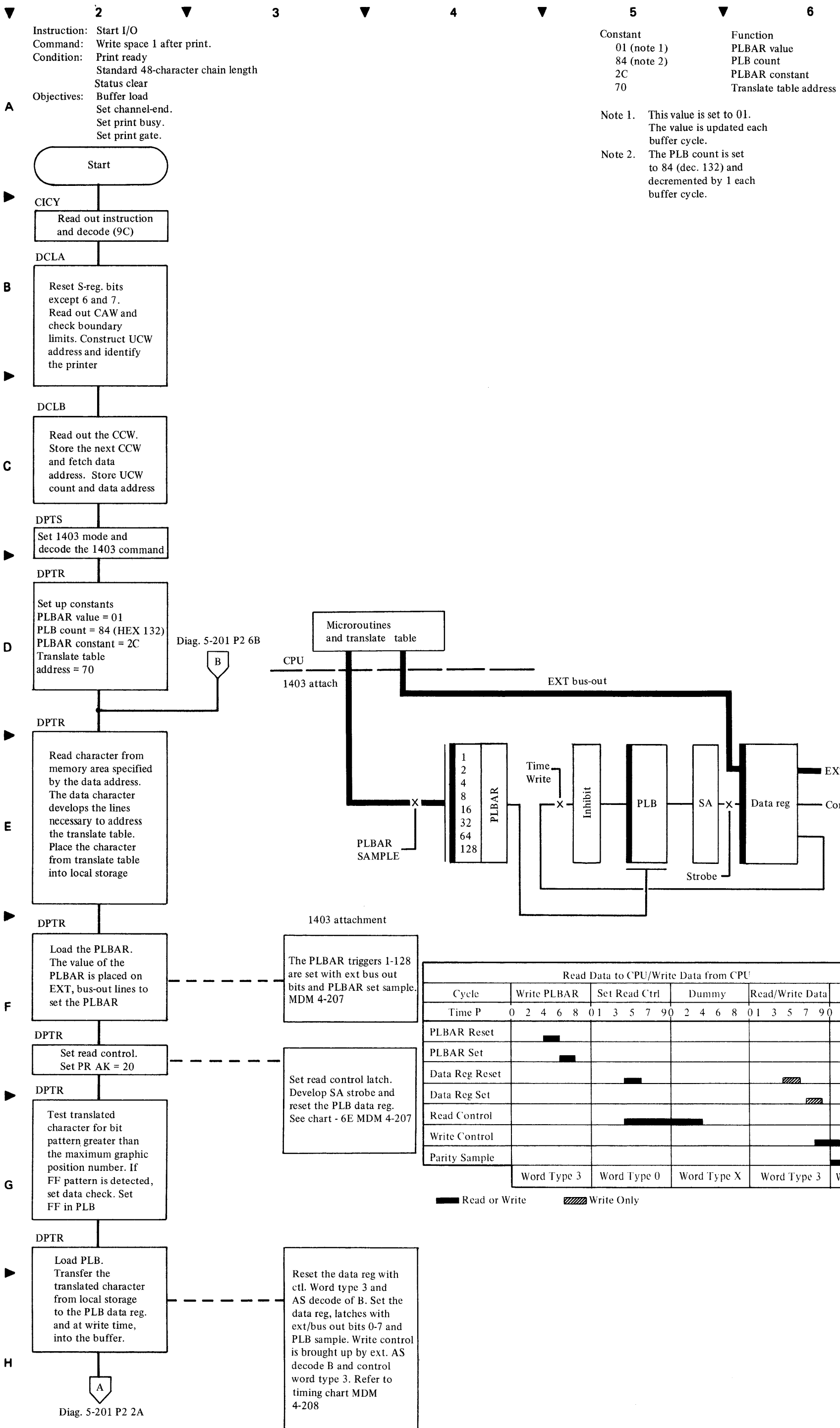
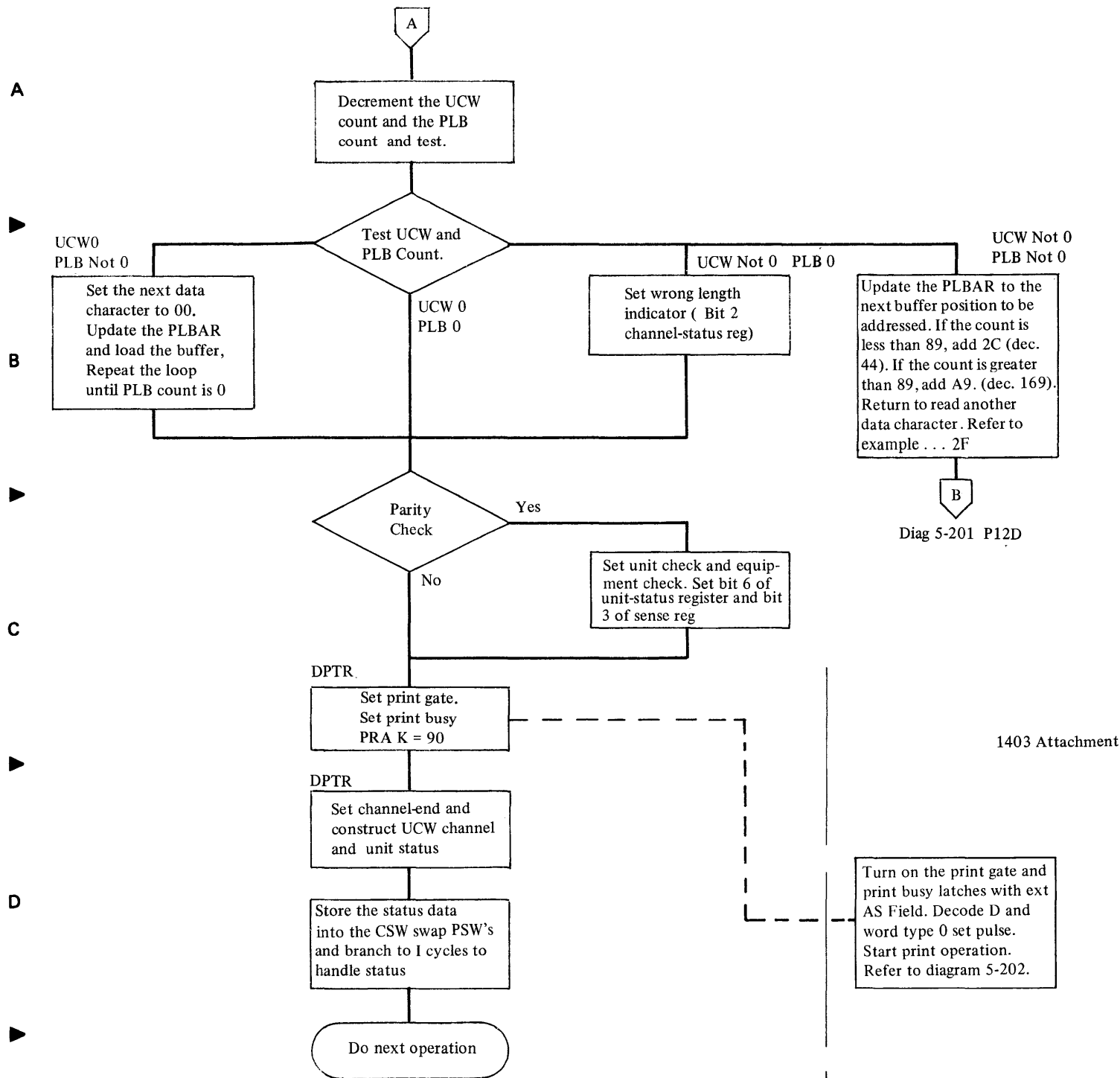


Diagram 5-201. Buffer Load (Part 1 of 2)

Diag 5-201 P13H



Example of PLBAR update

PLBAR VALUE	01	(dec. 01)
Constant	+2C	
Updated PLBAR	<u>2D</u>	(dec. 45)

PLBAR	2D	
Constant	+2C	
	<u>59</u>	(dec. 89)

PLBAR	59	
Constant	+A9	
	<u>02</u>	(dec. 02)

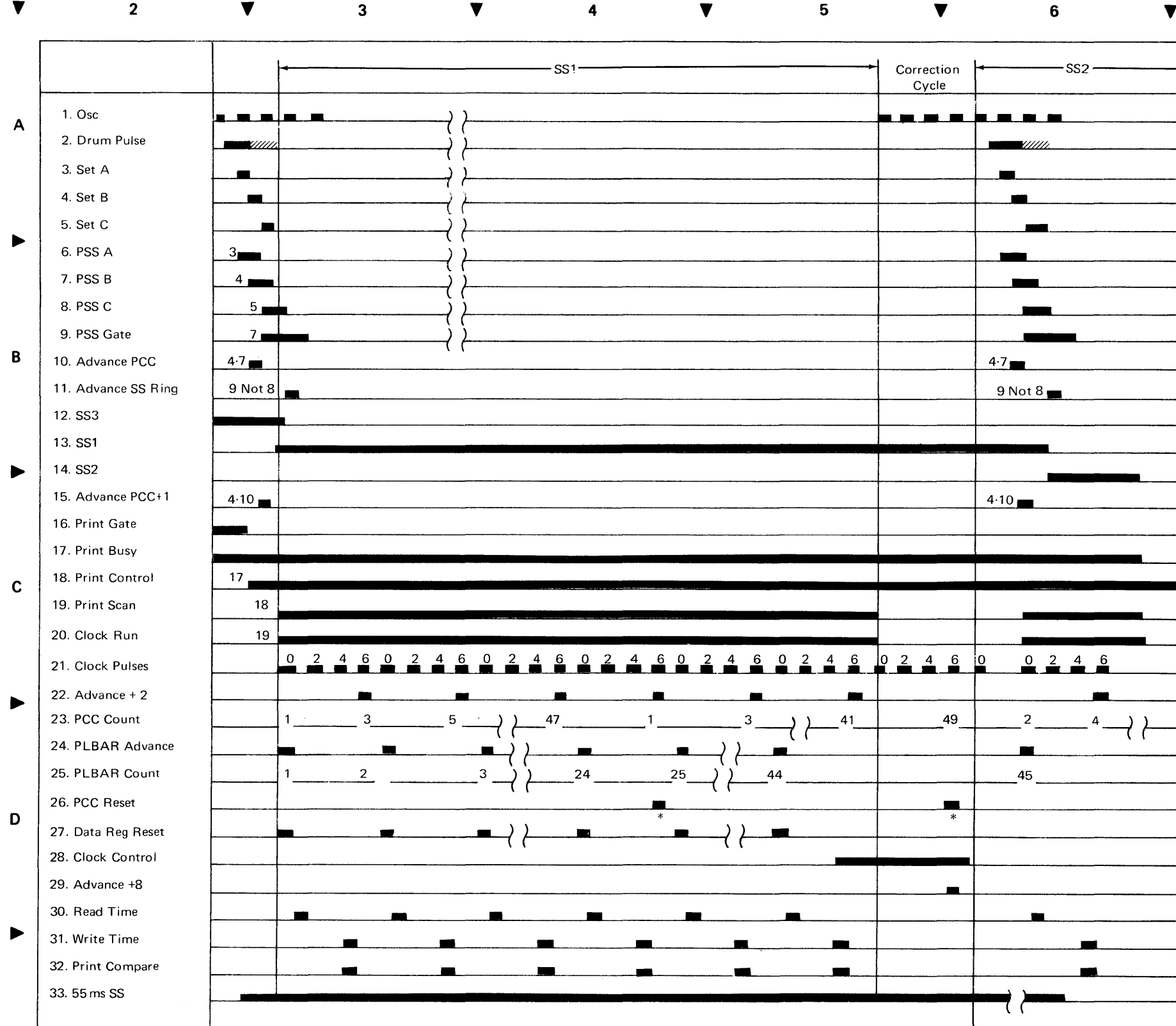
PLBAR	02	
Constant	+2C	
	<u>2E</u>	(dec. 46)

PLBAR	2E	
Constant	+2C	
	<u>5A</u>	(dec. 90)

PLBAR	5A	
Constant	+A9	
	<u>03</u>	(dec. 03)

Diagram 5-201. Buffer Load (Part 2 of 2)

Diagram 5-202. Print Operation



Example: Print Model 25

Buffer Position 1 2 3 4 5 → 44

Character (M)(E)(2)

Print Position 1 4 7 10 13 → 130

Buffer Position 45 46 47 48 49 → 88

Character (O)(L)(5)

Print Position 2 5 8 11 14 → 131

Buffer Position 89 90 91 92 93 → 132

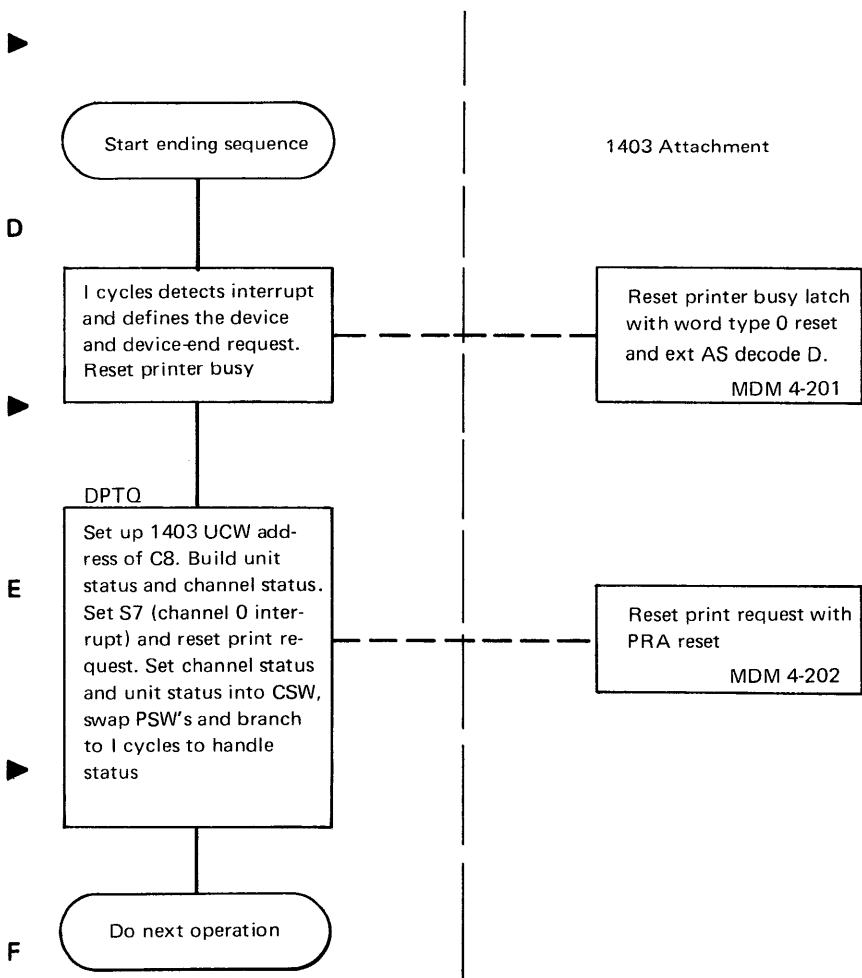
Character (D)(SP)

Print Position 3 6 9 12 15 → 132

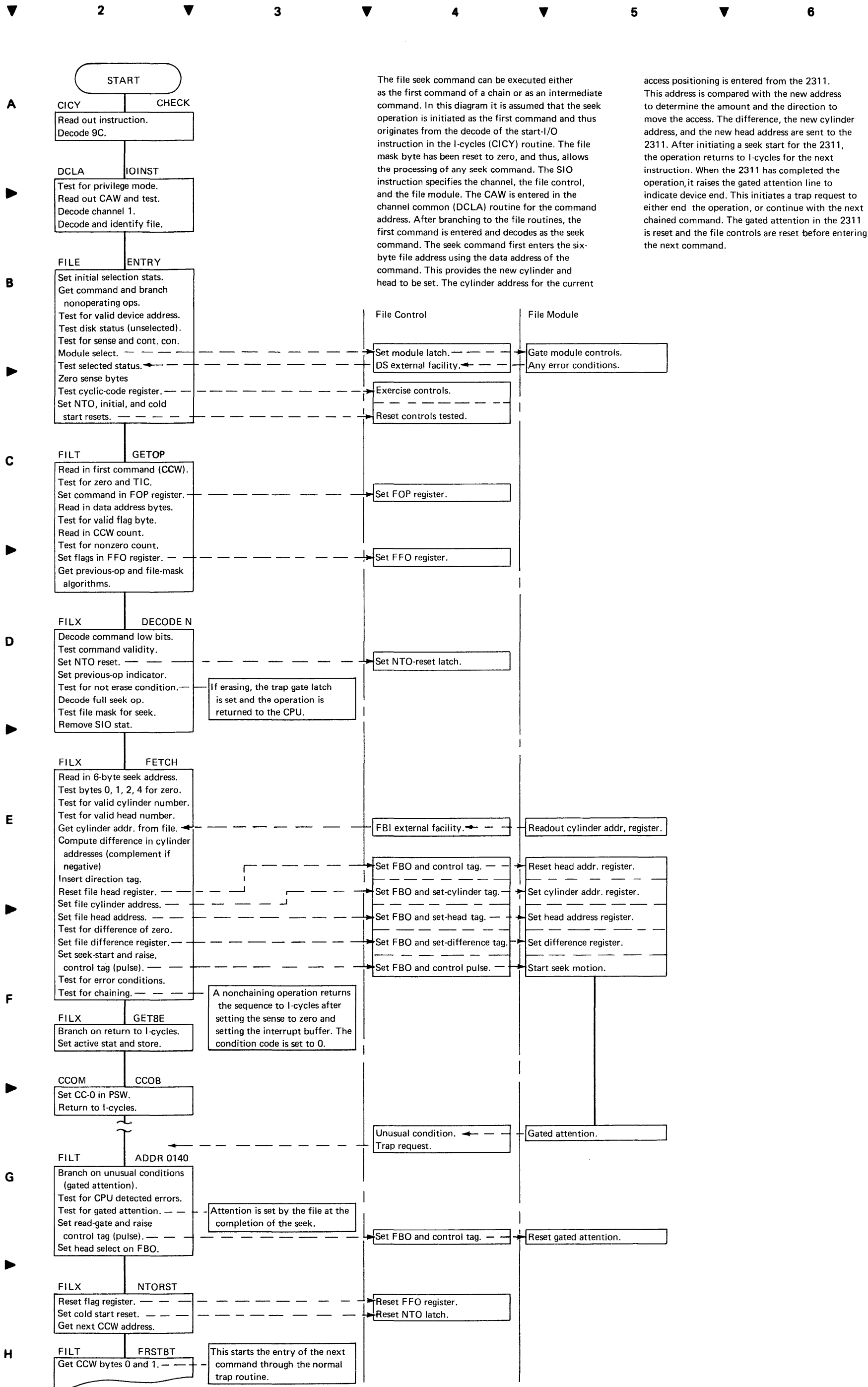
E * The Pcc reset during clock control resets triggers 16-128.
At all other times, the PCC reset resets triggers 4-128

2 3 4 5 6
Carriage Operation: Space 1 after print.

A	1. SS3	
	2. Print Control	
	3. Rem No PLC	
	4. 55MS Single Shot	
	5. Last Scan	1-3, Not 4
B	6. Carriage Start	5-Not 15
	7. Carriage Start SS	6 150 ns
	8. Carriage Br. Reg. Reset	7 150 ns
	9. Carriage Br. Reg. Set SS	Not 6 150 ns
	10. Carriage St. delayed SS	Not 9 150 ns
	11. Carriage Go SS	Not 10 150 ns
	12. Carriage Go	11 150 ns
	13. Space 1 SS	12 5-5 ms
	14. Space Drive	13
	15. Space Extended	13
C	16. Low Speed Start	13
	17. Carriage Settling SS	Not 14
	18. Low Speed Stop	Not 14
	19. Device End	Not 15
	20. Print Request	Not 15



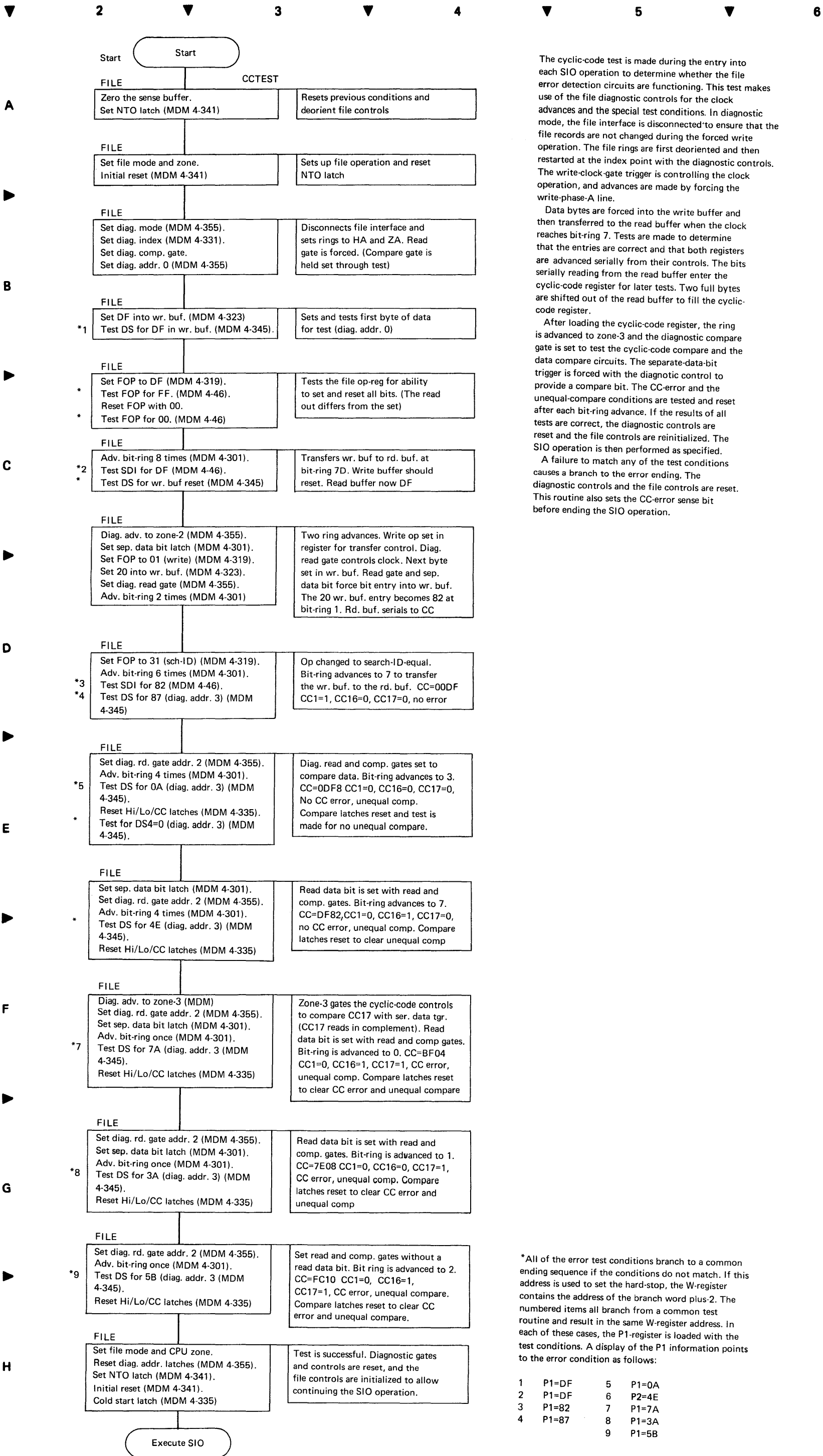
● Diagram 5-203. Space 1 After Print



The file seek command can be executed either as the first command of a chain or as an intermediate command. In this diagram it is assumed that the seek operation is initiated as the first command and thus originates from the decode of the start-I/O instruction in the I-cycles (CICY) routine. The file mask byte has been reset to zero, and thus, allows the processing of any seek command. The SIO instruction specifies the channel, the file control, and the file module. The CAW is entered in the channel common (DCLA) routine for the command address. After branching to the file routines, the first command is entered and decodes as the seek command. The seek command first enters the six-byte file address using the data address of the command. This provides the new cylinder and head to be set. The cylinder address for the current

access positioning is entered from the 2311. This address is compared with the new address to determine the amount and the direction to move the access. The difference, the new cylinder address, and the new head address are sent to the 2311. After initiating a seek start for the 2311, the operation returns to I-cycles for the next instruction. When the 2311 has completed the operation, it raises the gated attention line to indicate device end. This initiates a trap request to either end the operation, or continue with the next chained command. The gated attention in the 2311 is reset and the file controls are reset before entering the next command.

● Diagram 5-301. Seek Operation, File



The cyclic-code test is made during the entry into each SIO operation to determine whether the file error detection circuits are functioning. This test makes use of the file diagnostic controls for the clock advances and the special test conditions. In diagnostic mode, the file interface is disconnected to ensure that the file records are not changed during the forced write operation. The file rings are first deoriented and then restarted at the index point with the diagnostic controls. The write-clock-gate trigger is controlling the clock operation, and advances are made by forcing the write-phase-A line.

Data bytes are forced into the write buffer and then transferred to the read buffer when the clock reaches bit-ring 7. Tests are made to determine that the entries are correct and that both registers are advanced serially from their controls. The bits serially reading from the read buffer enter the cyclic-code register for later tests. Two full bytes are shifted out of the read buffer to fill the cyclic-code register.

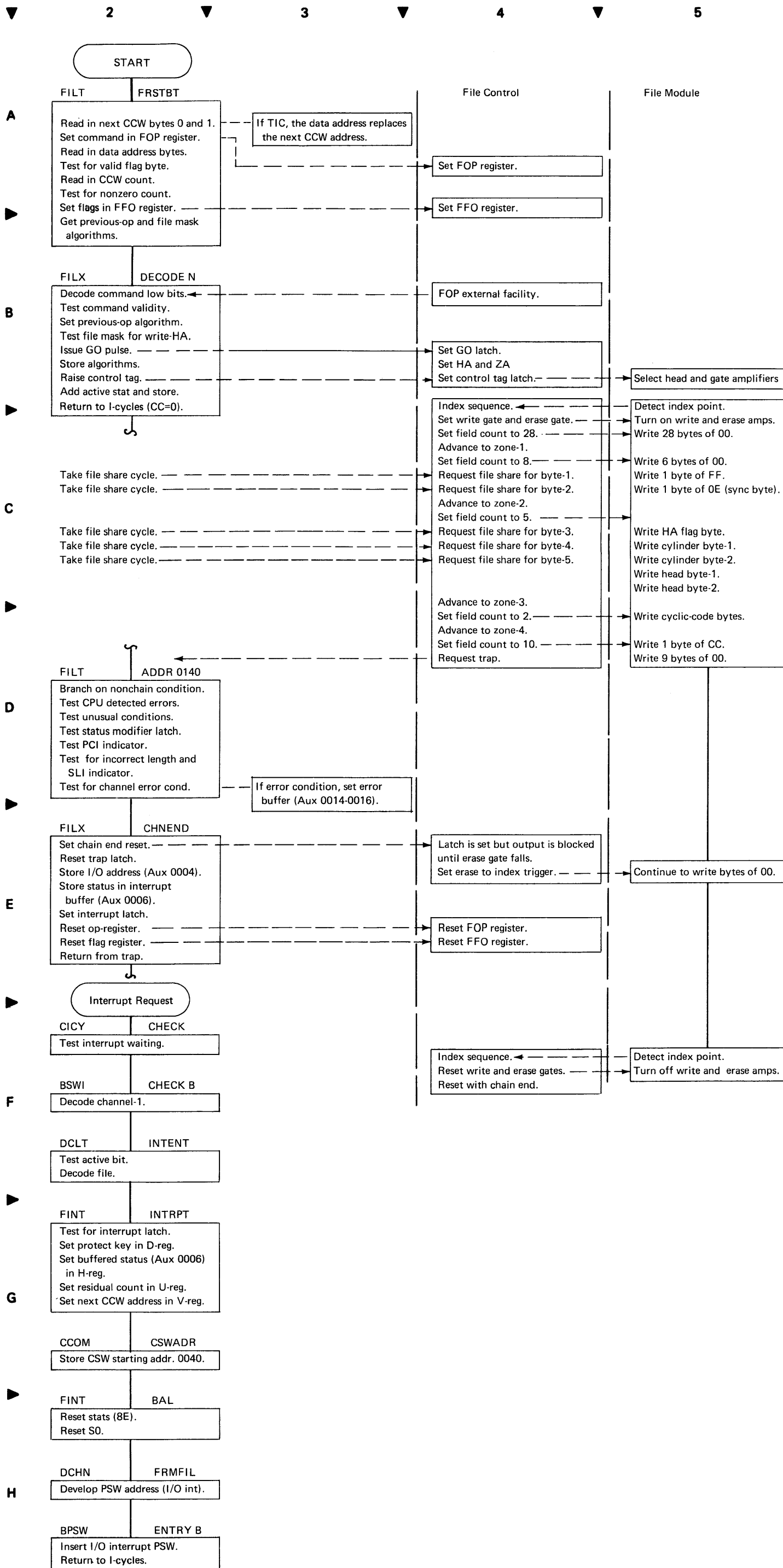
After loading the cyclic-code register, the ring is advanced to zone-3 and the diagnostic compare gate is set to test the cyclic-code compare and the data compare circuits. The separate-data-bit trigger is forced with the diagnostic control to provide a compare bit. The CC-error and the unequal-compare conditions are tested and reset after each bit-ring advance. If the results of all tests are correct, the diagnostic controls are reset and the file controls are reinitialized. The SIO operation is then performed as specified.

A failure to match any of the test conditions causes a branch to the error ending. The diagnostic controls and the file controls are reset. This routine also sets the CC-error sense bit before ending the SIO operation.

*All of the error test conditions branch to a common ending sequence if the conditions do not match. If this address is used to set the hard-stop, the W-register contains the address of the branch word plus-2. The numbered items all branch from a common test routine and result in the same W-register address. In each of these cases, the P1-register is loaded with the test conditions. A display of the P1 information points to the error condition as follows:

- 1 P1=DF 5 P1=0A
- 2 P1=DF 6 P2=4E
- 3 P1=82 7 P1=7A
- 4 P1=87 8 P1=3A
- 9 P1=5B

● Diagram 5-302. 510 Cyclic Code Test



The write home address command for the file cannot be performed without first setting the file mask to allow the operation. This diagram assumes that the file mask command has been executed and that the write home address command is chained to it but that no other command follows. The operation remains in the initial sequence after setting the mask and returns to the trap routine to enter the next CCW. The new command is entered and decoded as the write home address. The flags, the data address, and the count are also entered from the CCW.

A test is made for the file mask condition to allow the operation. The file control waits for the 2311 to reach the index point before starting the write operation by setting the rings to the home address field and zone-A. After writing the home address gap, the home address is written with its cyclic-code bytes. The device end condition for the command initiates a trap request for the next command. When no command is chained, the GO pulse is not raised before the end of zone-4 and results in the setting of the erase to index latch. The microroutine sets the interrupt latch and loads the buffer before ending the operation.

The interrupt routine loads the ending information into the CSW for program analysis when permitted by the system mask.

●Diagram 5-303. Write Home Operation, File

The read-HA operation has less restrictions than the other commands for use. It does not require a previous search, mask, or seek operation. It is assumed for this diagram that a seek command that caused access motion has preceded, and therefore, the entry is made through the trap routine. It is also assumed that no command follows. If the command is chained, the operation would branch at the second entry of the trap routine.

The read-HA requires the index point and the rings set to HA field and zone-A. The file control waits for the index point indication from the disk file before advancing. A space of nineteen bytes is clocked in before advancing to zone-1. No address-mark is used with the home address field. The read data is entered into the cyclic code register to sample the bits for the sync byte. When the last five bits of the byte are sensed in the correct order, the sync detect signal is developed

to advance the ring to zone-2. A field count of five is set into the counter. All five bytes are deserialized and transferred to the storage area defined by the data address of the CCW. The flag byte is also used to set the track flag latches. During zone-3 the two byte cyclic code developed while reading the five bytes is compared with the two bytes read from the track. In zone-4 the write clock is used to count the ten bytes without reading. During zone-4, the trap routine is testing for an additional chained command. When no command is chained, the chain end reset stops the file control operation. The operation ends by storing the interrupt buffer, setting the interrupt latch, and perform the necessary resets to end the sequence before returning from the trap.

A

B

C

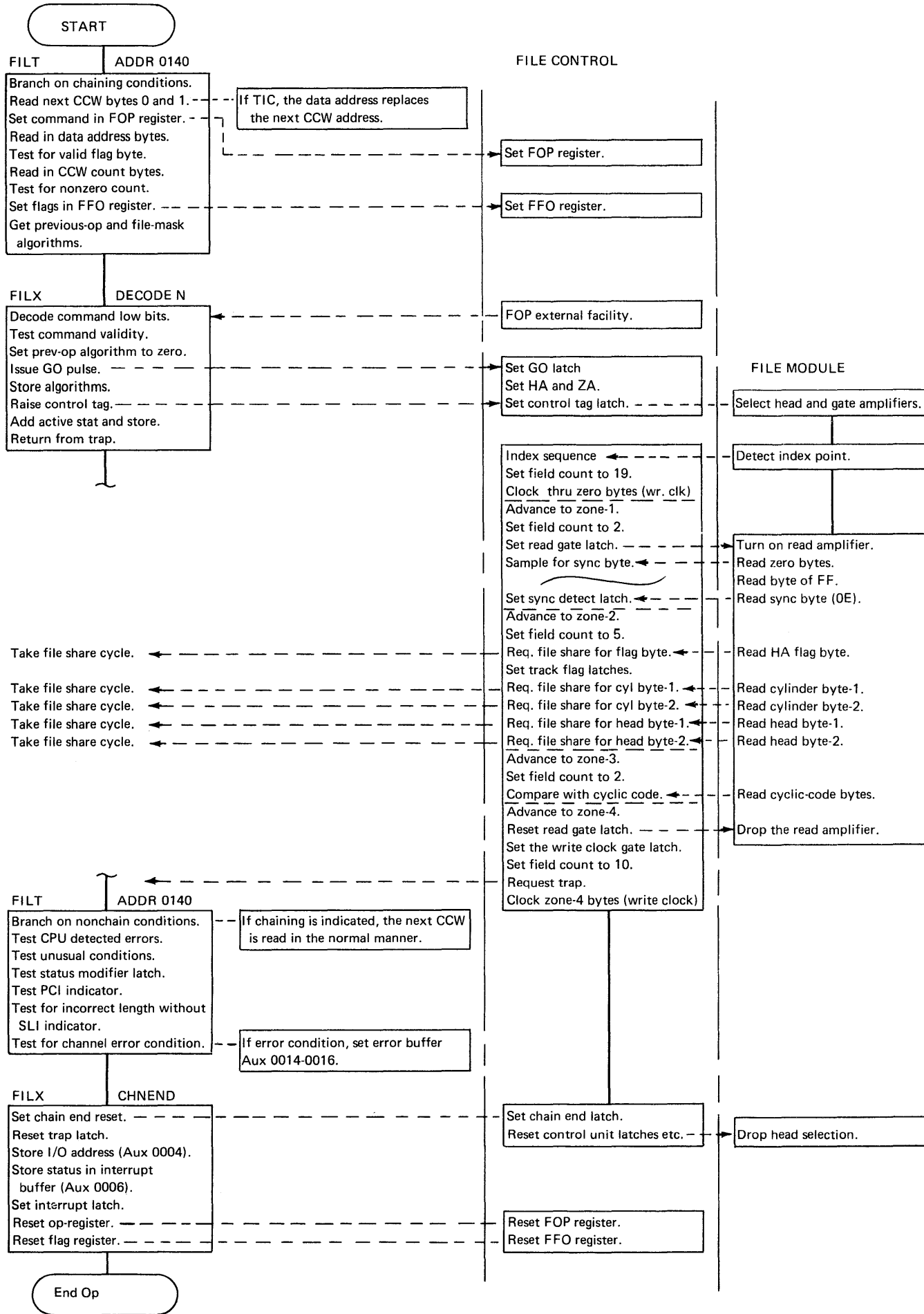
D

E

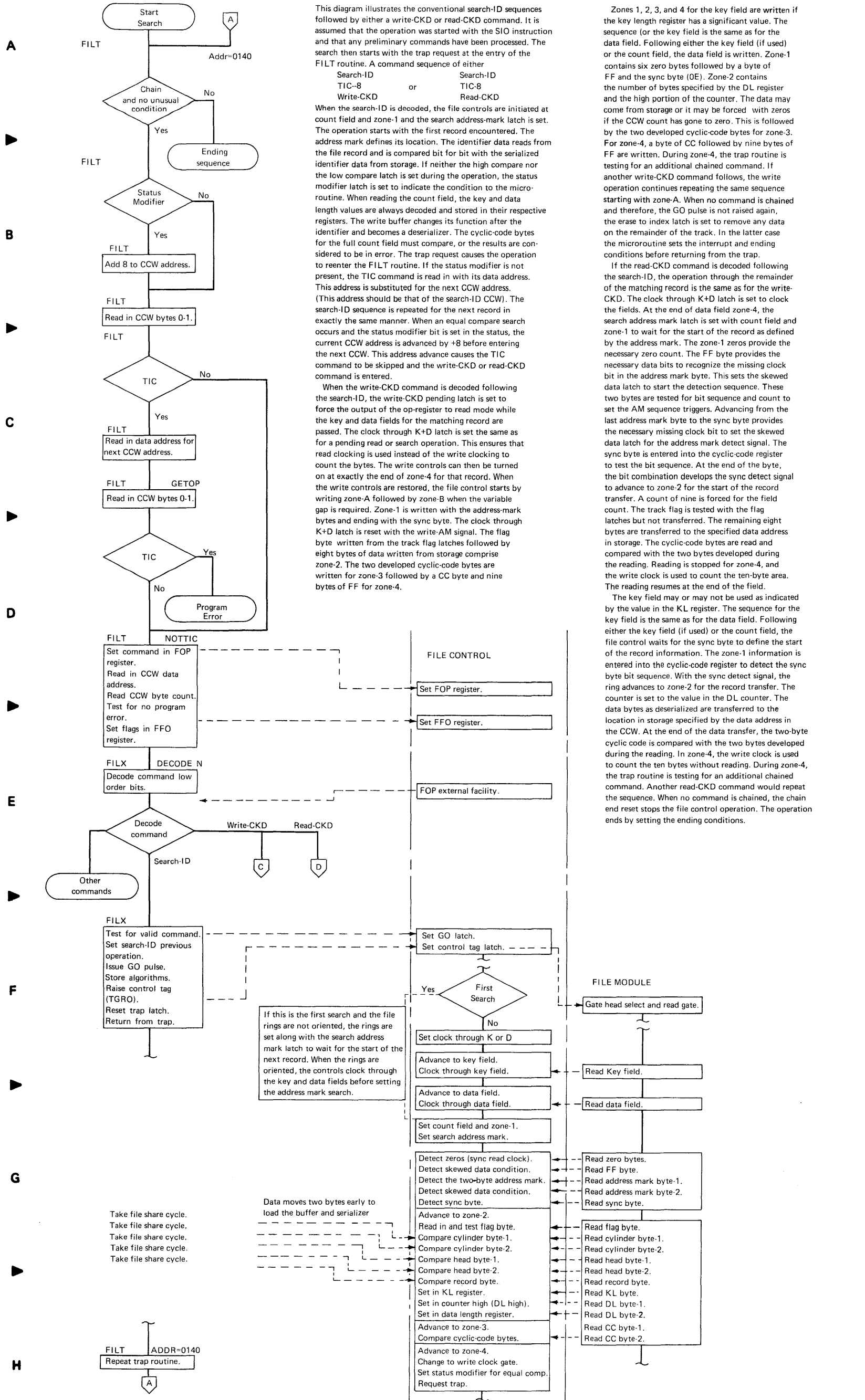
F

G

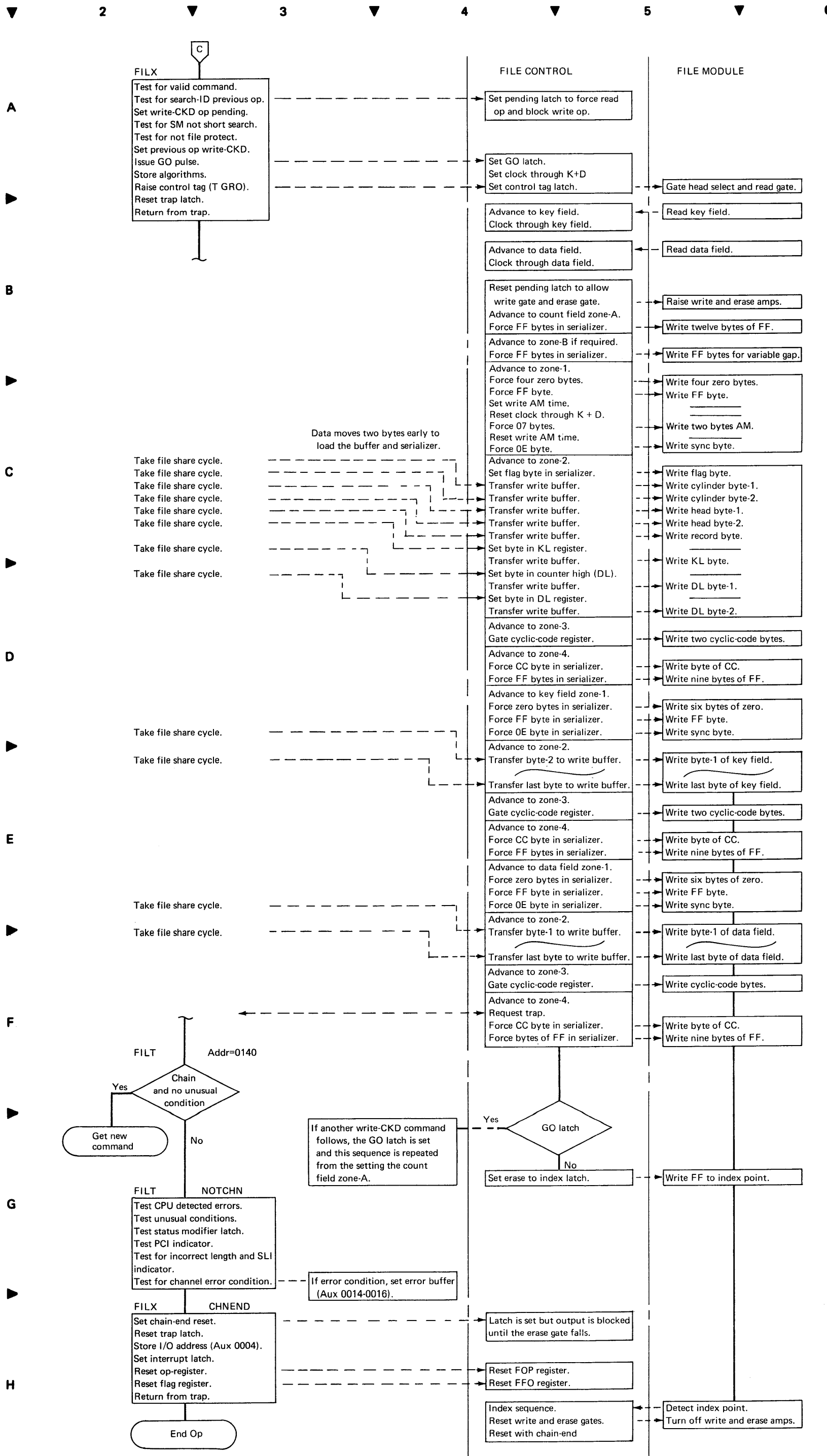
H



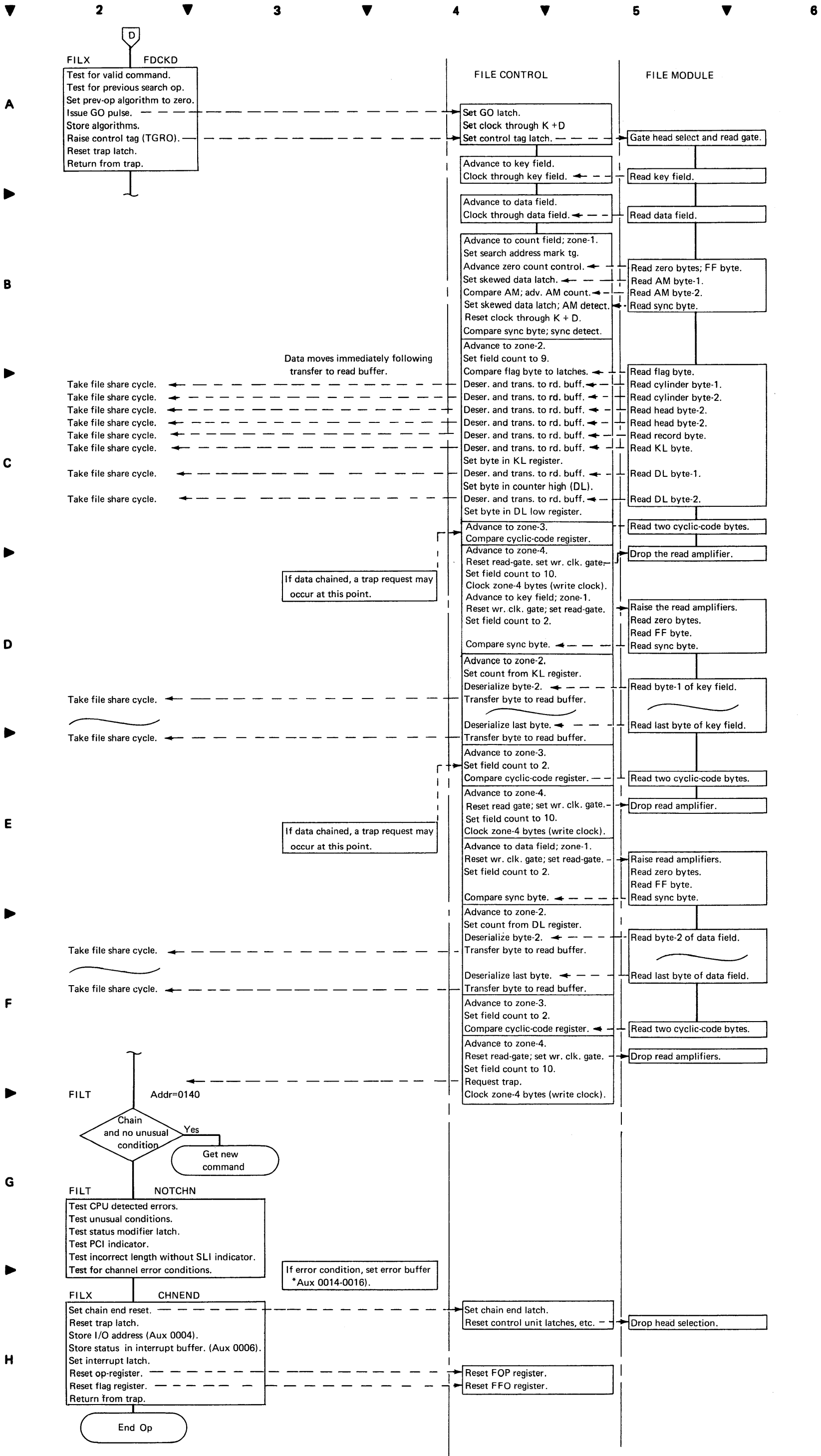
● Diagram 5-304. Read Home Address Operation, File



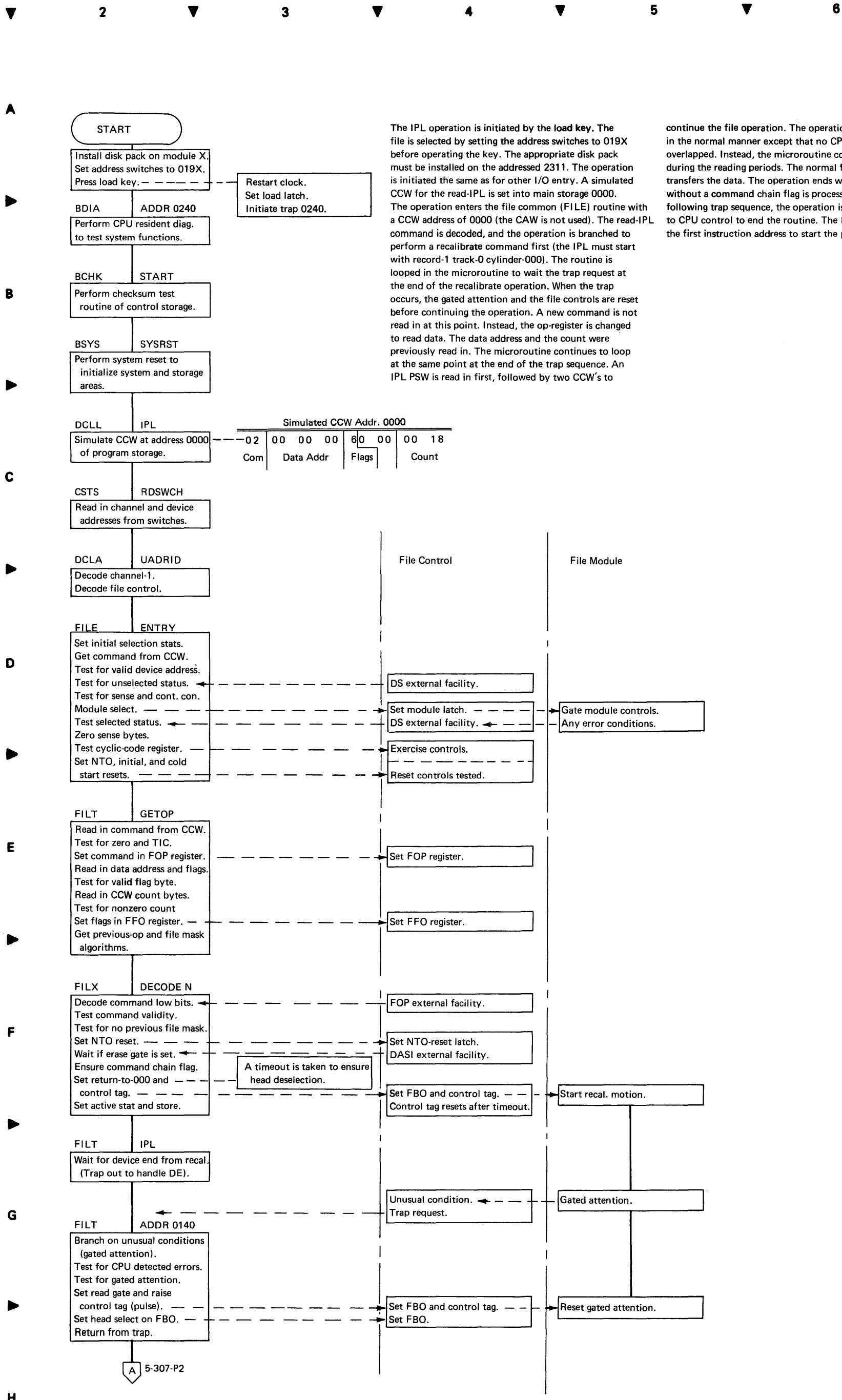
● Diagram 5-305. Search-ID with Write- or Read-CKD (Part 1 of 3)



● Diagram 5-305. Search-ID with Write- or Read-CKD (Part 2 of 3)

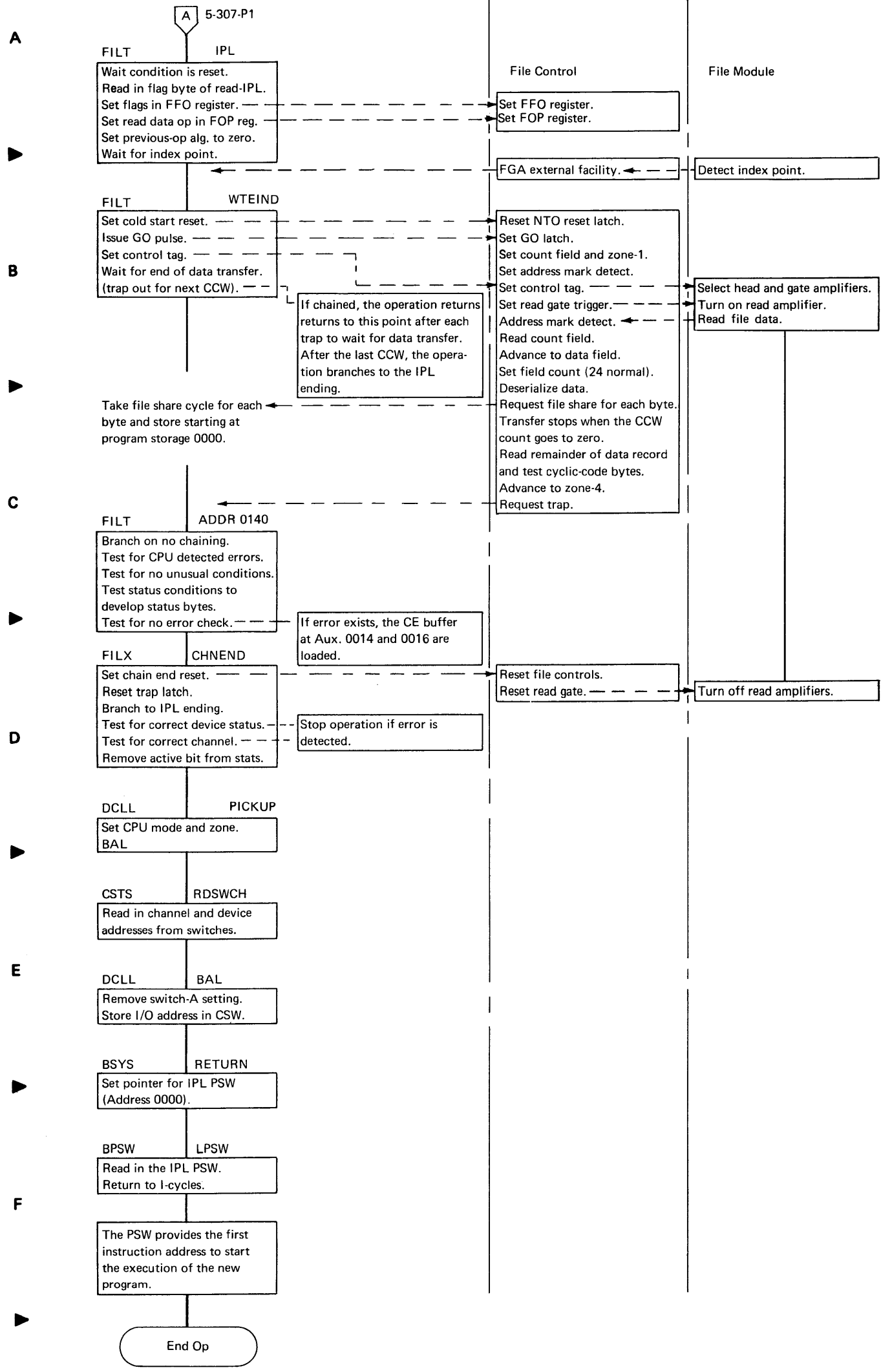


● Diagram 5-305. Search ID with Write-or Read CKD (Part 3 of 3)



● Diagram 5-307. Read IPL Operation, File (Part 1 of 2)

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6



● Diagram 5-307. Read IPL Operation, File (Part 2 of 2)

CHANNEL OPERATION (Start I/O, Read Command) On Selector Channel

Read out and decode instruction (9C). In routine DCLA, test to see that machine is in supervisor state. Determine that I/O operation to be performed and branch accordingly. Read CAW in two-byte increments. See that CCW is on 8-byte boundary. Identify channel involved and branch to proper routine. Test if file operation. Test if burst channel operation.

In routine DCLB, test active bit, set condition code in PSW and set to channel mode. Determine if specified I/O device is fully buffered. Test if inbound or outbound command. Check if data chain is indicated. Test for nonzero byte count. Branch to initial selection routine, DCLC.

Routine DCLC

Test for program control interrupt.

If PCI, set channel 1 interrupt latch

Set initial selection latch

Place Device Address on Bus-Out

Device Address (Bus-Out)

Set Address-Out signal (tag)

Address-Out

Set Select-Out

Select-Out and Hold-Out

Address-Out reset by the microprogram upon receipt of Op-In.

Operational-In (generated by I/O device)

Address-In (tag)

Device Address (bus-in)

Test address parity and match.

Command (bus-out)

C

Command-Out

Command-Out drops.

Address-In drops

Status (bus-in)

Status-In (tag)

Set Service-Out

Service-Out

Status-In drops

Service-Out drops.

Set burst latch and turn on active bit in 8E K addressable auxiliary storage. Select-Out is still up, holding the device on the interface.

Mode register set to CPU mode and program returns to 1 cycles. When the first byte of data is ready to be transmitted from the I/O device to the CPU, the device raises service-in causing a hardware trap to the data handling routine (DCLD).

Channel Data Request is developed and causes the address of the first instruction in the data loop to be generated.

Service-In, No Tag-Out

Data (bus-in)

E

Service-Out

Service-In is reset

Service-Out is reset

The data loop is repeated until all data has been transferred, at which time the ending sequence begins. Status-In causes a hardware trap to the status handling routine (DCLE)

DCLE and DCLC routines

Status (bus-in)

Status-In

F

With status-in up, the burst latch on, and data chain request off, channel 0 trap request is generated. This causes the address of the first microword of the ending sequence to be generated and gated to the storage address assembler. Thus the ending sequence is executed.

Test parity of the status byte; test for presence of chain command; test for PCI. Store status, set interrupt buffer latch.

Service-Out

(signals acceptance of status)

Operational-In drops

Return to original routine.

G

H

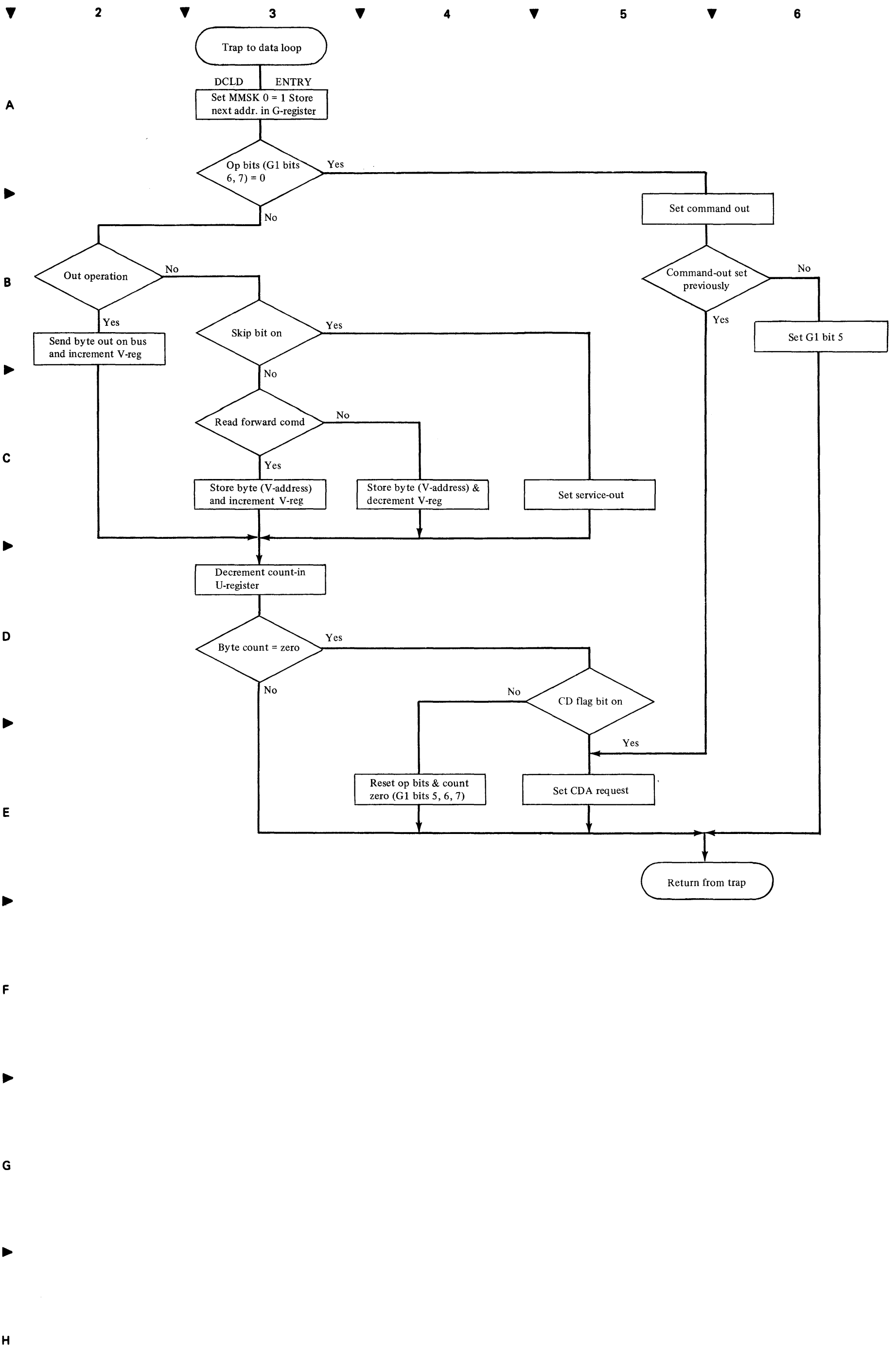


Diagram 5-403. Flowchart of Data Loop for Selector Channel (Routine DCLD)

CHANNEL OPERATION (Byte Mode)

CPU

CHANNEL and I/O DEVICE

A Read and decode instruction in microroutine CICY and branch to DCLA

DCLA
Machine must be in supervisor state. (Check program mask)

Determine I/O operation to be performed and branch to the proper routine.

▶ Determine that channel 0 is specified.
Construct UCW address, using the device and control unit address.
Test active bit.
Branch to DCLB.

B DCLB
Fetch and edit the CCW. Test for TIC command. (TIC should not occur as first command.) Test for valid flags (3 low-order flag bits must be zero). If flags present, branch to DCLR to handle. Test for data chain indication. Test Op bits and branch accordingly (outbound, in forward, in backward). Test for non-zero byte count. Construct UCW using information in CCW. Branch to DCLC.

▶ DCLC
Test for presence of PCI bit. If present, set channel 1 interrupt latch.
Perform initial selection placing I/O device on interface.

Set initial selection latch.

C Place device address on Bus-Out

Set Address-Out tag.

Set Select-Out.

Set Hold-Out

▶ Op-In generated by I/O device)

Drop Address-Out

(Device address is on Bus-In.)

D

Place Command on Bus-Out.

Test address on Bus-In for parity error and agreement with Address-Out.

▶ Set Command-Out

Drop Select-Out.

Drop Hold-Out.

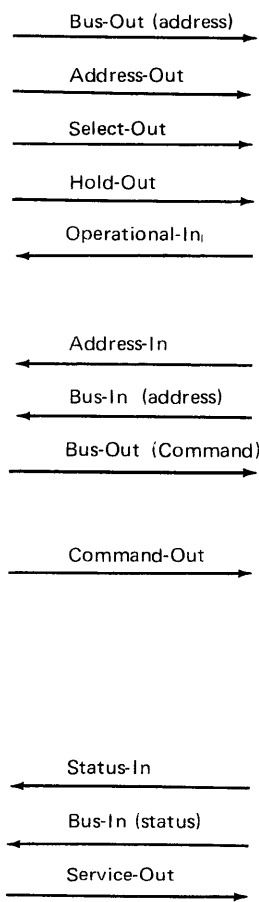
Drop Address-In and Command-Out.

E Set Status-In

Place status on Bus-In

Test for parity error; set Service-Out .

▶ Drop Status-In, Service-Out and Operational-In. Set condition code 0 and active bit. Return to I-Cycles.



F

▶

G

▶

H

Diagram 5-405. Operation Chart for Start I/O on Byte Channel

Diagram 5-407. Flowchart of Data Loop in Byte Channel Operation

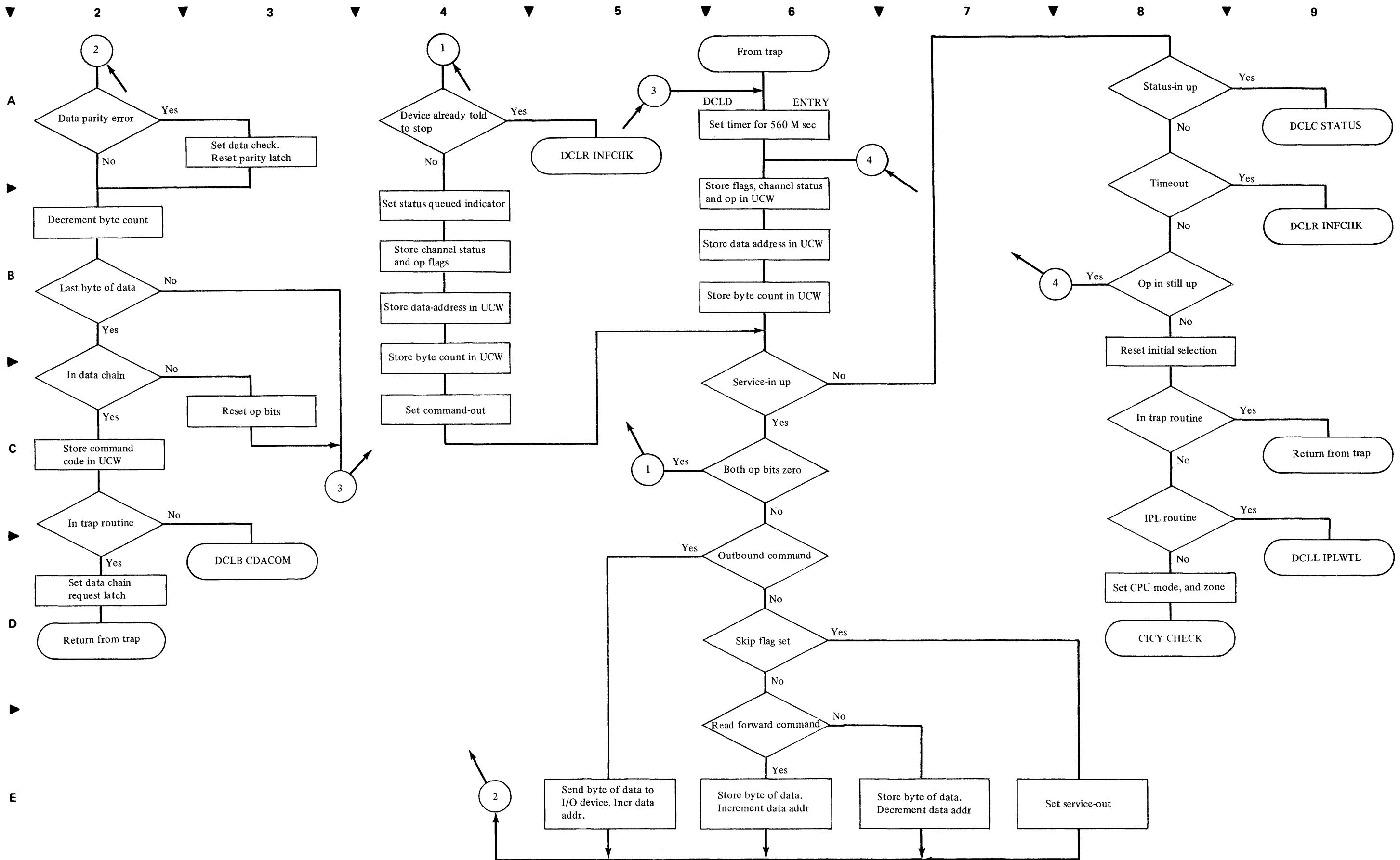


Figure 5-407 Flowchart of Data Loop in Byte Channel Operation.

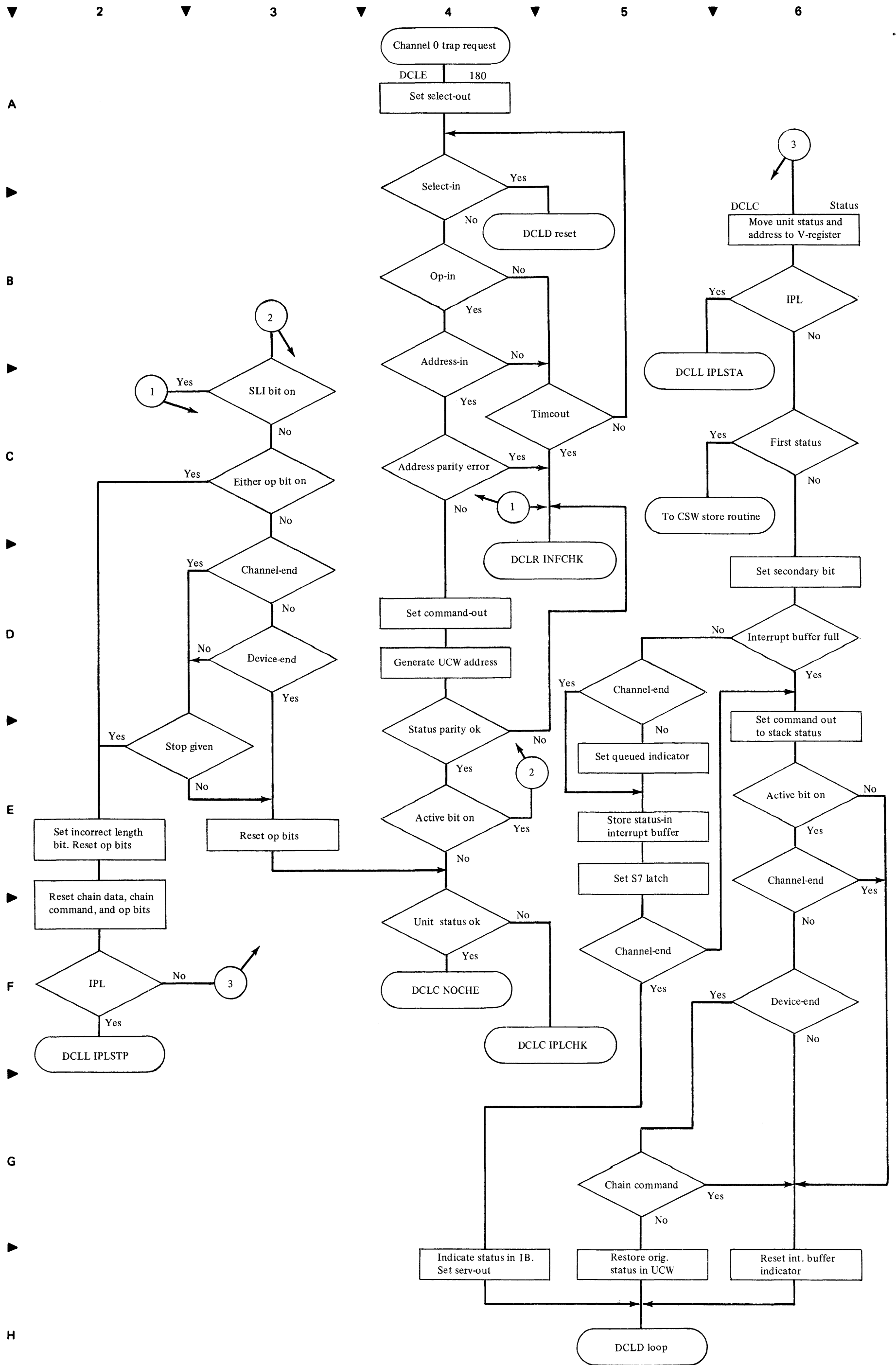
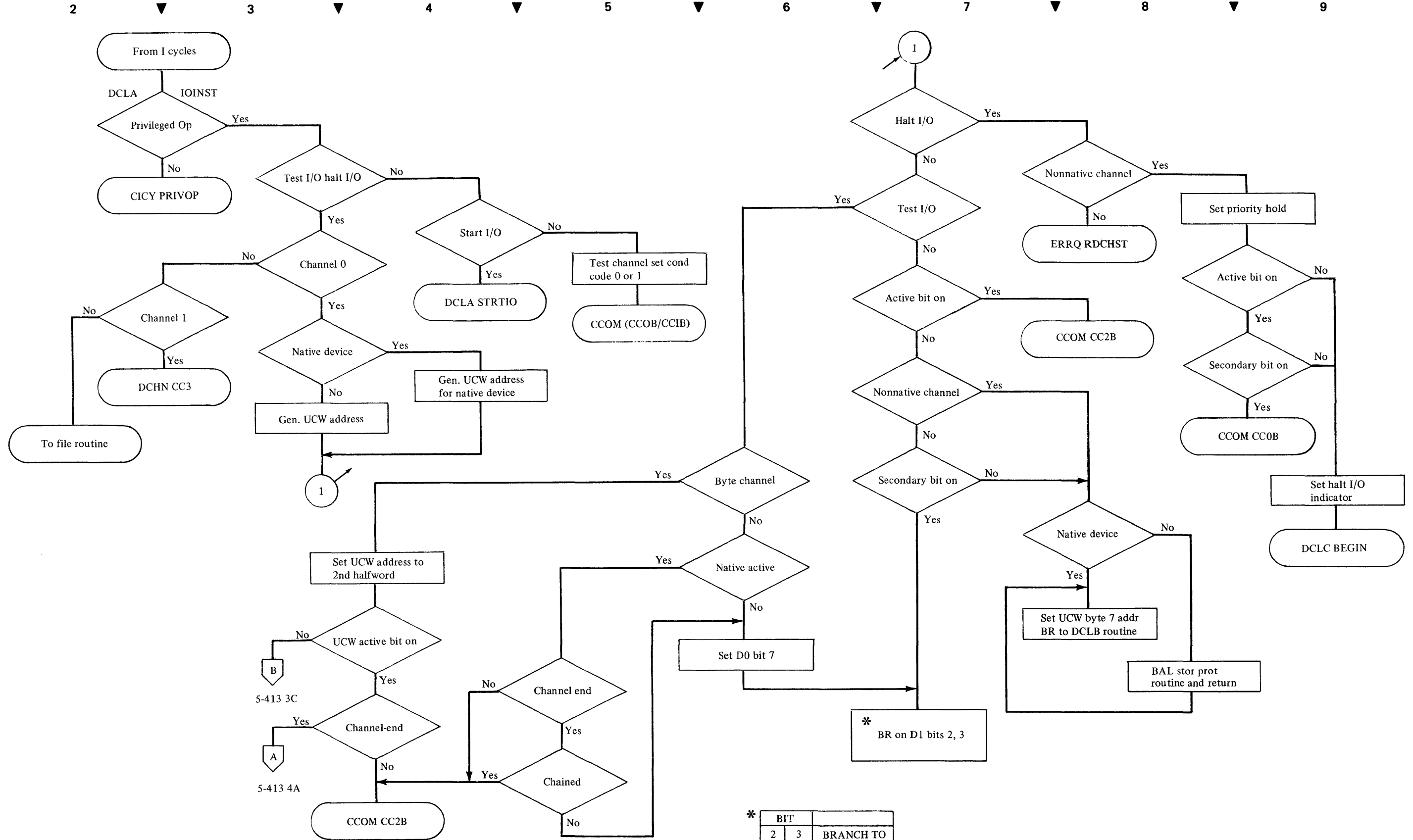


Diagram 5-409. Ending Operation on Byte Channel



* BR on D1 bits 2, 3

BIT 2	BIT 3	BRANCH TO
0	0	DPTT
0	1	ERRQ
1	0	ERRQ
1	1	DYPE

5-411 Test I/O Routine, Byte Mode

A
B
C
D
E
F
G
H

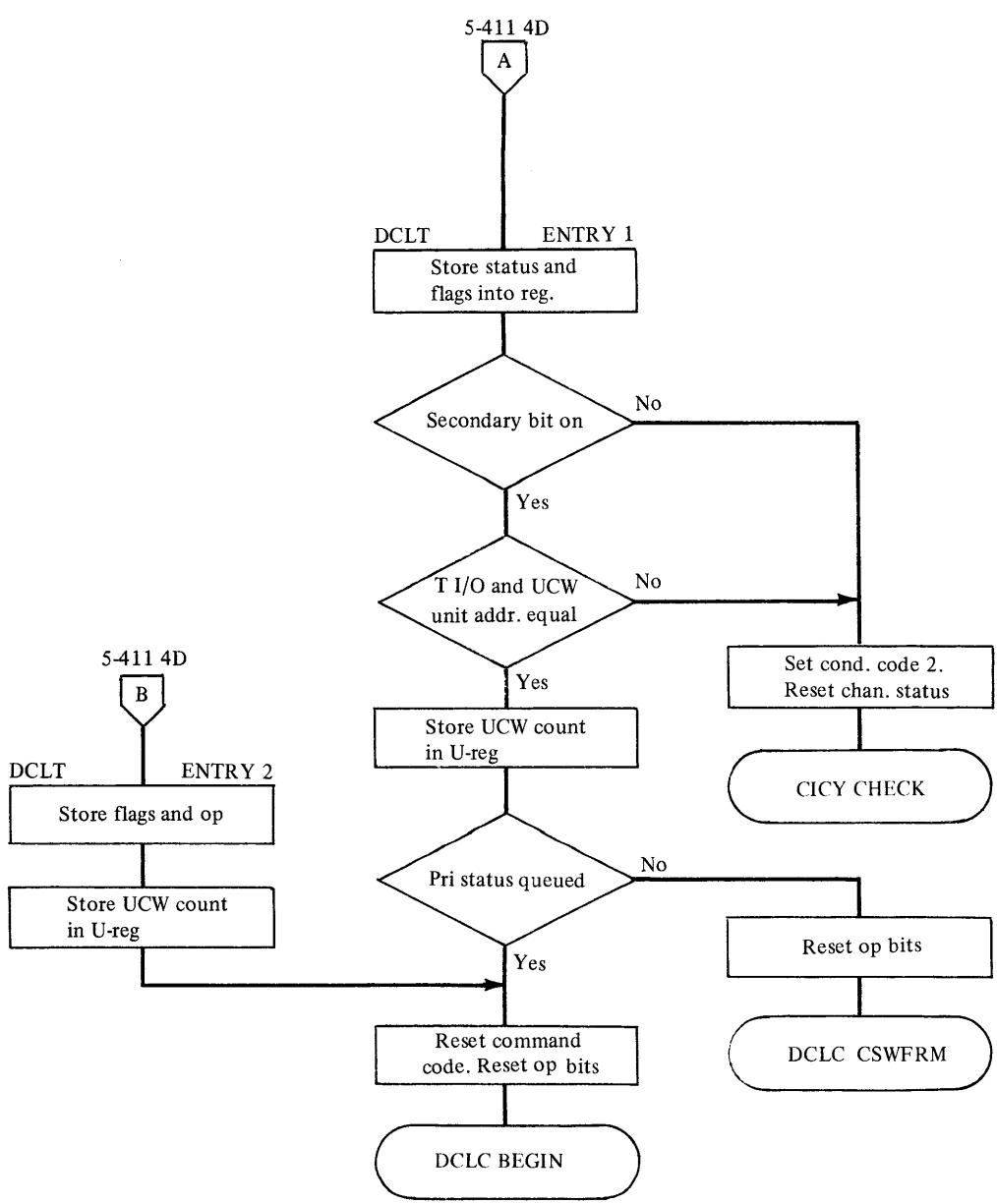
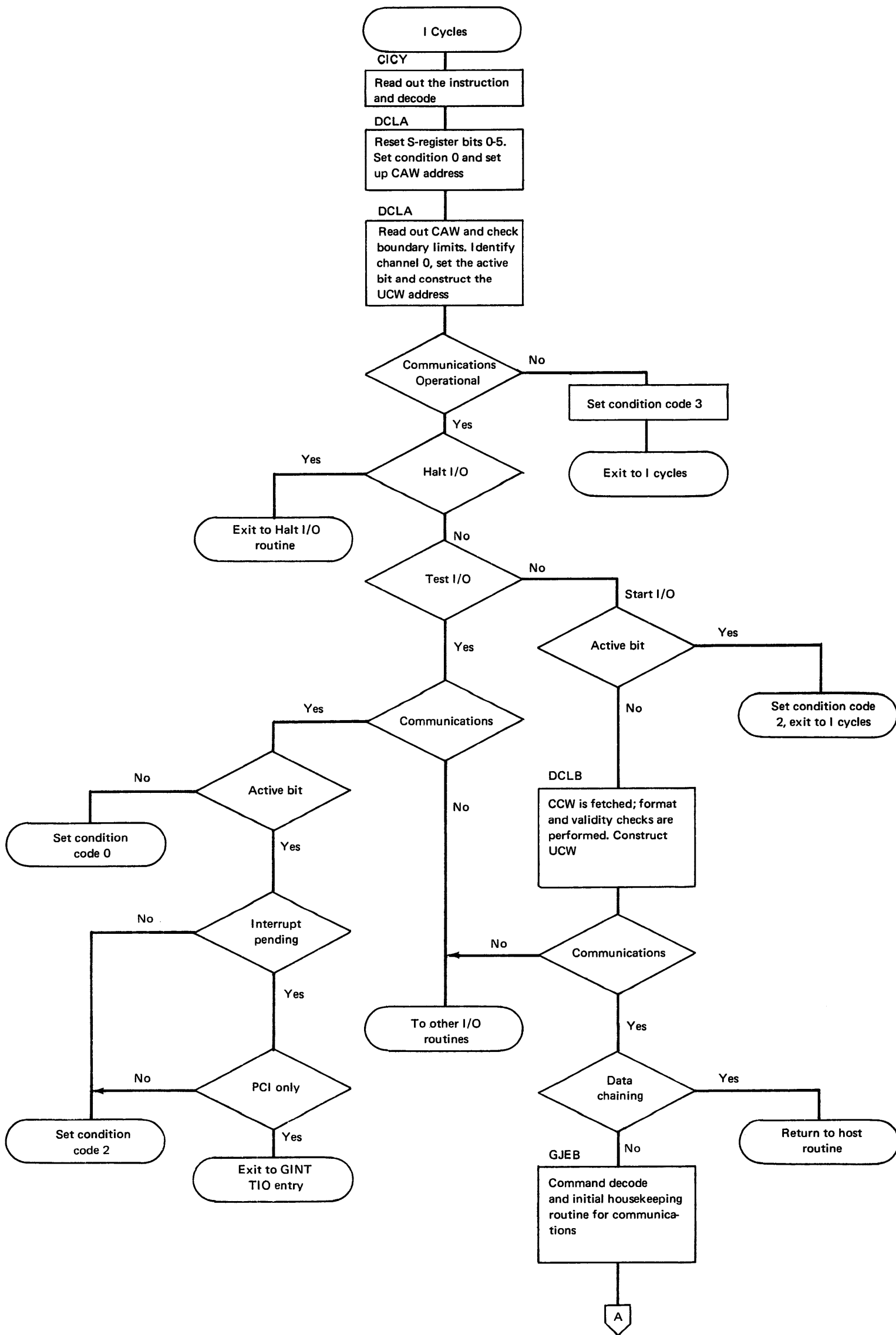


Diagram 5-413. Test I/O Routine, Byte Channel



Diag. 5-501 3A

● Diagram 5-500. Communications Command Decode

Diag 5-500 5G

A

GJEB

Set communications priority, mode, and zone. Translate the command by table lookup method.
Note: If GSTAT bit 1 equals 1 (start/stop chain request), further Start I/O commands are prevented until the chaining request is serviced.

Objectives:

1. This routine is entered following a CCW fetch due to either a command chain or a Start I/O.
2. The command is decoded by table lookup method.
3. Immediate commands are executed in the same trap, while the Start I/O commands branch to command initiate routines for start/stop or synchronous operation.

Sense I/O No-Op or SADxx command

Yes

No

GJEC

Stop the scanner, address the line adapter, determine the type of terminal control being used, and exit to the command initiate routines for start/stop or synchronous operations

Sense command

Yes

No

GAN3
Store the sense byte in storage at the location specified by CCW

GJEB
GEND
Set sense remember bit and set channel-end and device-end, providing command chaining is not specified

Exit to I cycles

Start/stop or synchronous

Start/stop

Synchronous

GJEF

GJED

I/O No-Op and SADxx commands are treated as immediate commands, but no operation is performed. If command chaining is not specified, the commands are terminated immediately with channel-end and device-end status being set in the CSW

Exit to I cycles

A

B

C

D

E

F

G

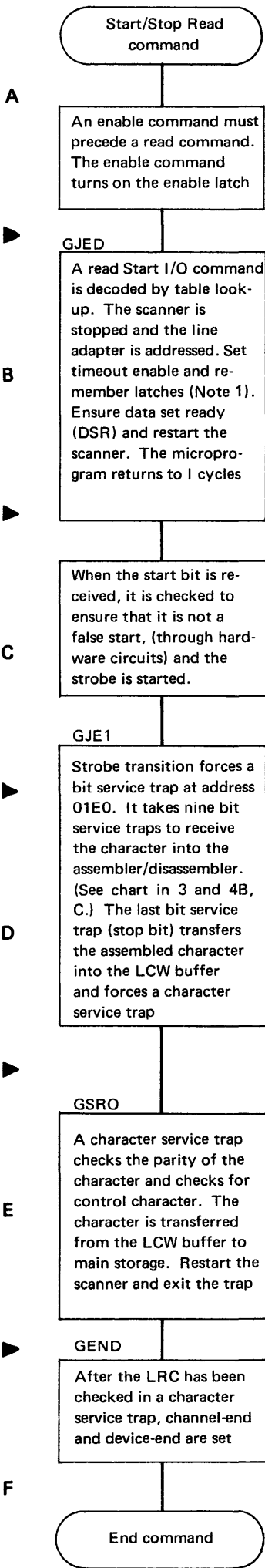
H

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6

Objectives:

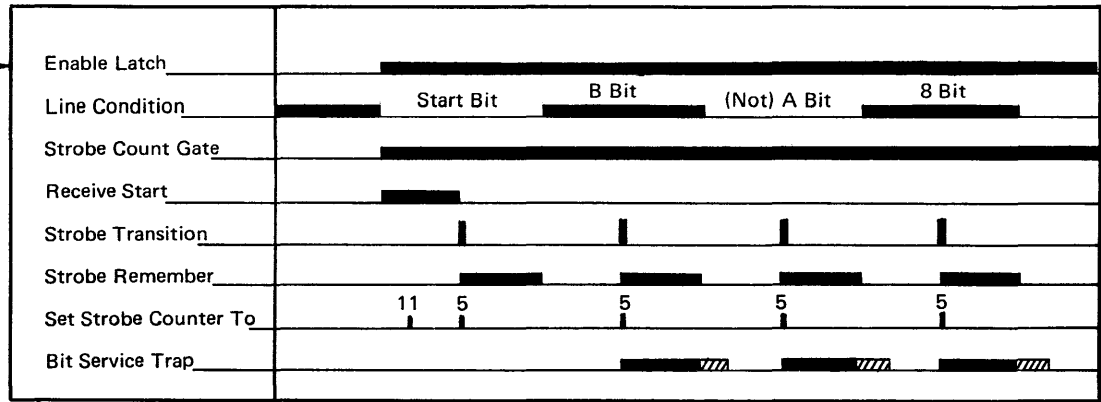
1. Receive the following characters. V, (B), LRC.
2. Transfer the character to main storage.
3. Set channel-end and device-end.

Note: Program should chain to a write command to transmit the answerback.



Bit Service Trap	G0	G1	Bit Position
1	EX	0000 0000	B of V
2	3X	0000 0001	A of V
3	4X	0000 0010	8 of V
4	5X	0000 0101	4 of V
5	6X	0000 1010	2 of V
6	7X	0001 0101	1 of V
7	8X	0010 1010	C of V
8	9X	0000 0000	Stop
	EX	0000 0000	Start
9	EX	0000 0000	B of (B)
10	3X	0000 0001	A of (B)
11	4X	0000 0011	8 of (B)
12	5X	0000 0111	4 of (B)
13	6X	0000 1111	2 of (B)
14	7X	0001 1110	1 of (B)
15	8X	0011 1101	C of (B)
16	9X	0000 0000	Stop
	EX	0000 0000	Start
17	EX	0000 0000	B of LRC
18	3X	0000 0000	A of LRC
19	4X	0000 0001	8 of LRC
20	5X	0000 0010	4 of LRC
21	6X	0000 0101	2 of LRC
22	7X	0000 1011	1 of LRC
23	8X	0001 0111	C of LRC
24	9X	0000 0000	Stop
	CX	0000 0000	Stop

Note: Additional bit service traps are taken to decrement the count in G0 and to monitor the line status.



Note 1:

Timeout enable and remember latches are not turned on for Start/Stop inhibit commands. Inhibit commands are performed the same as read commands with this exception: Inhibit commands are issued normally to a keyboard device where the speed of operation is dependent upon operator capability.

● Diagram 5-502. Start/Stop Read Command

Objectives:

1. Set controls for transmit operation.
2. Transmit the following characters:
V, B, and LRC.
3. Set channel-end and device-end.

Note: Program should be chained to a read command to receive answerback.

Conditions:

1. Start/stop operation
2. IBM Type I terminal control
3. Data set ready and line adapter enabled.

GJED

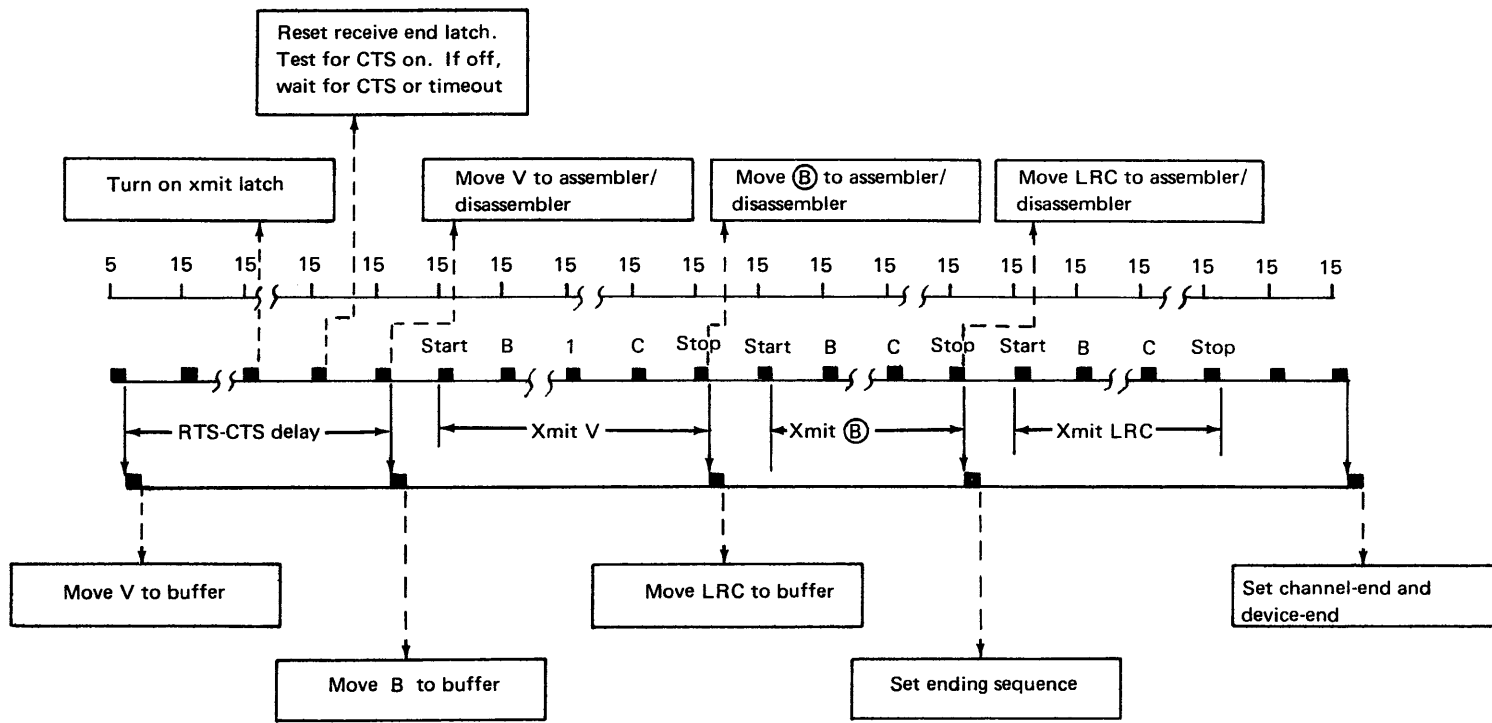
This routine sets write state and receive end latch for RTS-CTS delay. Start the strobe. Set timeout enable and remember latches. Set timeout command. Restart the scanner and exit routine

GJE1 (Bit Service Trap)

When the strobe count reaches count 15 (strobe transition), a bit service trap is forced starting at address 01E0. The first bit service trap forces a character service request. Approximately 9 bit service traps are required for RTS-CTS delay. The transmit latch is turned on after RTS delay has been completed. Bit service traps transmit the character serially by bit. The stop bit service trap moves the character from the LCW buffer to the assembler/disassembler if the character service trap has occurred. If not, a PAD character is transmitted. The stop bit service trap also forces a character service request

GSRO (Character Service Trap)

The character service trap routine moves the character from main storage to the LCW buffer. The character service trap also sets up the ending sequence prior to transmission of the LRC character. Channel-end and device-end are set in the character service trap following the LRC character



Note 1:

The operation of the bit service trap routine (GJE1) is dependent upon the bit count in the LCW.

Bit count 0 (Start)

Shift out start bit.
Set the bit count to first data bit.

Bit count 1 (First data)

Test for PAD character. If not a PAD character, test for transfer check or echo check, set the appropriate flags, set bit count to stop bit (count F), restart scanner and exit trap.

If PAD character is detected, bypass error checks, increment the bit count, shift out the start bit, restart the scanner and exit trap.

Bit count 2-8 (Normal data)

Test the bit for errors. If errors are detected, set appropriate flags, force bit count to F, restart the scanner and exit trap.

If no errors are detected, increment the bit count, restart the scanner and exit trap.

Bit Count 9 (Stop Bit)

Move character from LCW buffer to the assembler/disassembler. Force a character service trap request.

Ending Sequence

Two additional bit service traps (xmit end 1- and 2) are taken following the transmission of the LRC Stop.

The second bit service trap forces a character service trap request for channel-end and device-end.

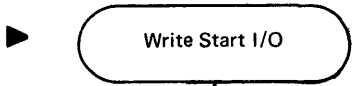
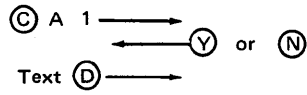
● Diagram 5-503. Start/Stop Write Operation

A start/stop addressing operation is performed by a sequence of chained commands as follows.

- Ⓢ = control character
- A = address character
- 1 = component select character
- Ⓨ = positive acknowledgment
- Ⓝ = negative acknowledgment
- Ⓣ = end of address; text following

A

Write Start I/O
Read
Write



B

GJED
This routine sets write state in the LCW and turns on the receive end latch for RTS-CTS delay. Start the strobe. Set timeout enable and timeout remember latches, restart the scanner and exit routine.

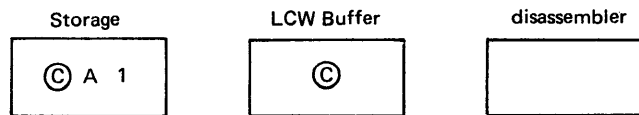
Start the strobe counter. When the strobe count reaches 15, (strobe transition) a bit service trap is forced at address 01E0. Start a 3.5 second timeout.

GJE1

The first bit service trap generates a character service trap

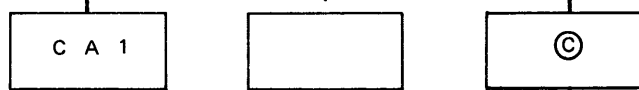
C

GSRO
The character service trap fetches a character from storage (under control of the CCW byte count), determines that it is a control character, and places the Ⓢ character in the LCW buffer. Write state and IBM control mode are set in the LCW state field. Restart the scanner and exit trap



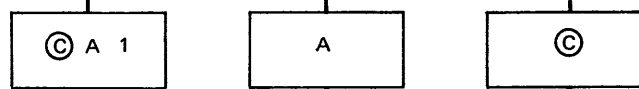
D

GJE1
Approximately 9 bit service traps (under control of the strobe counter) are taken for RTS-CTS delay. The transmit latch (MDM 4-529) is set during this delay. When CTS (clear to send) becomes active, a character service trap is generated. Reset timeout indicator. Move Ⓢ to the assembler/disassembler, restart the scanner and exit trap.



E

GSRO
Move the address character (A) to the LCW buffer, decrement the count, restart the scanner and exit the trap.



F



Diag 5-504 Part 2 2A

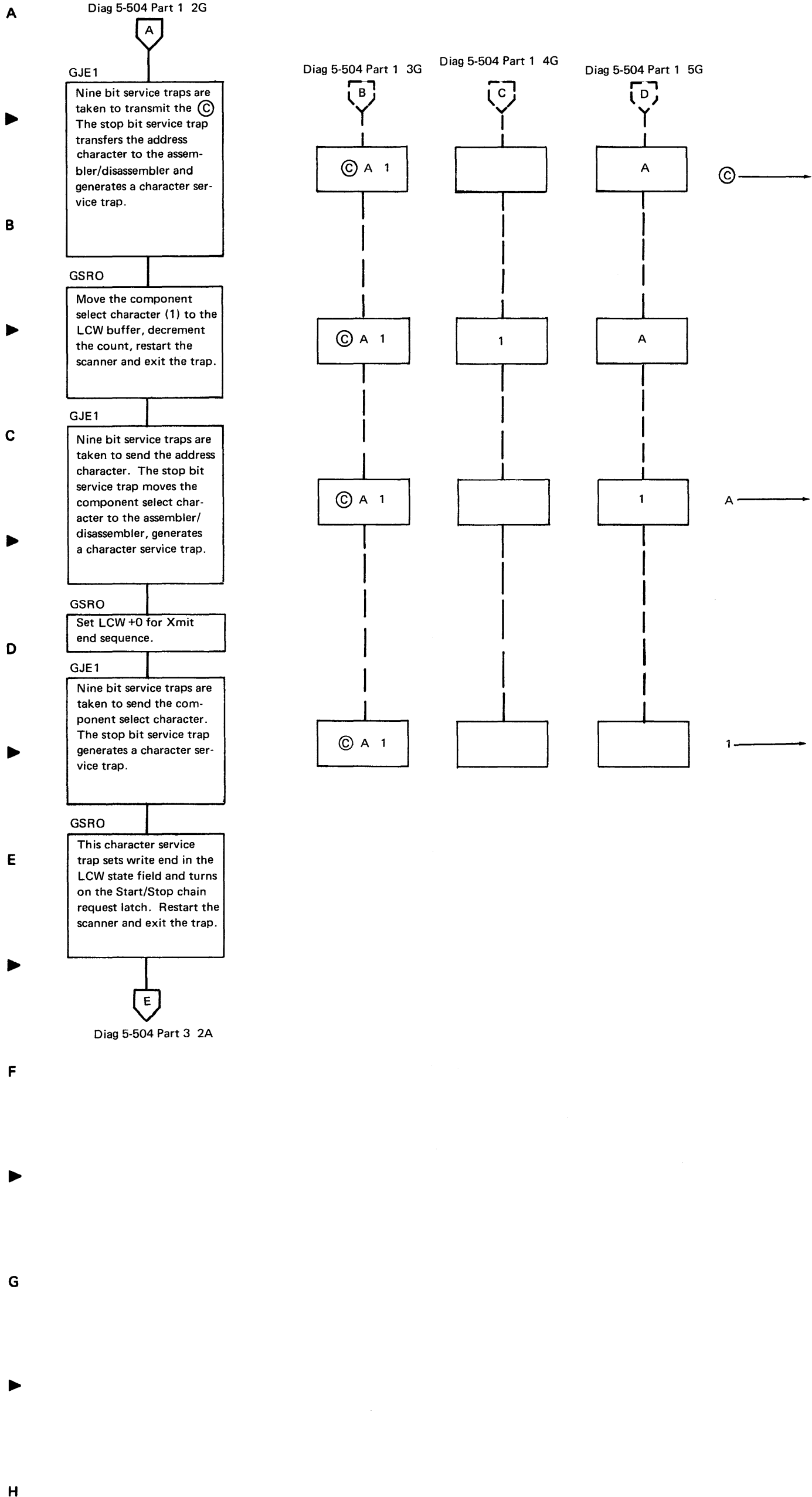
Diag 5-504 Part 2 3A

Diag 5-504 Part 2 4A

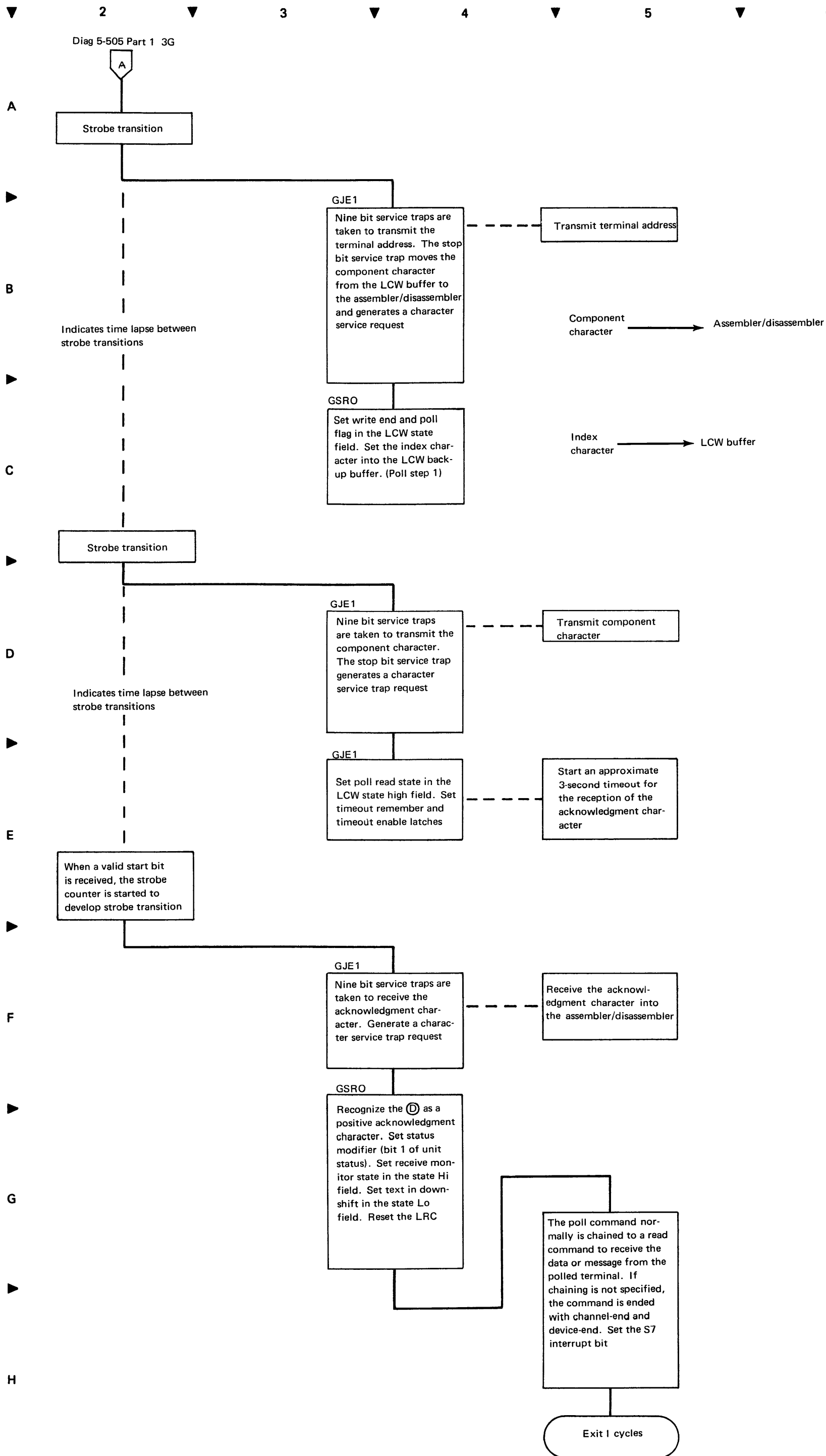
Diag 5-504 Part 2 5A

G

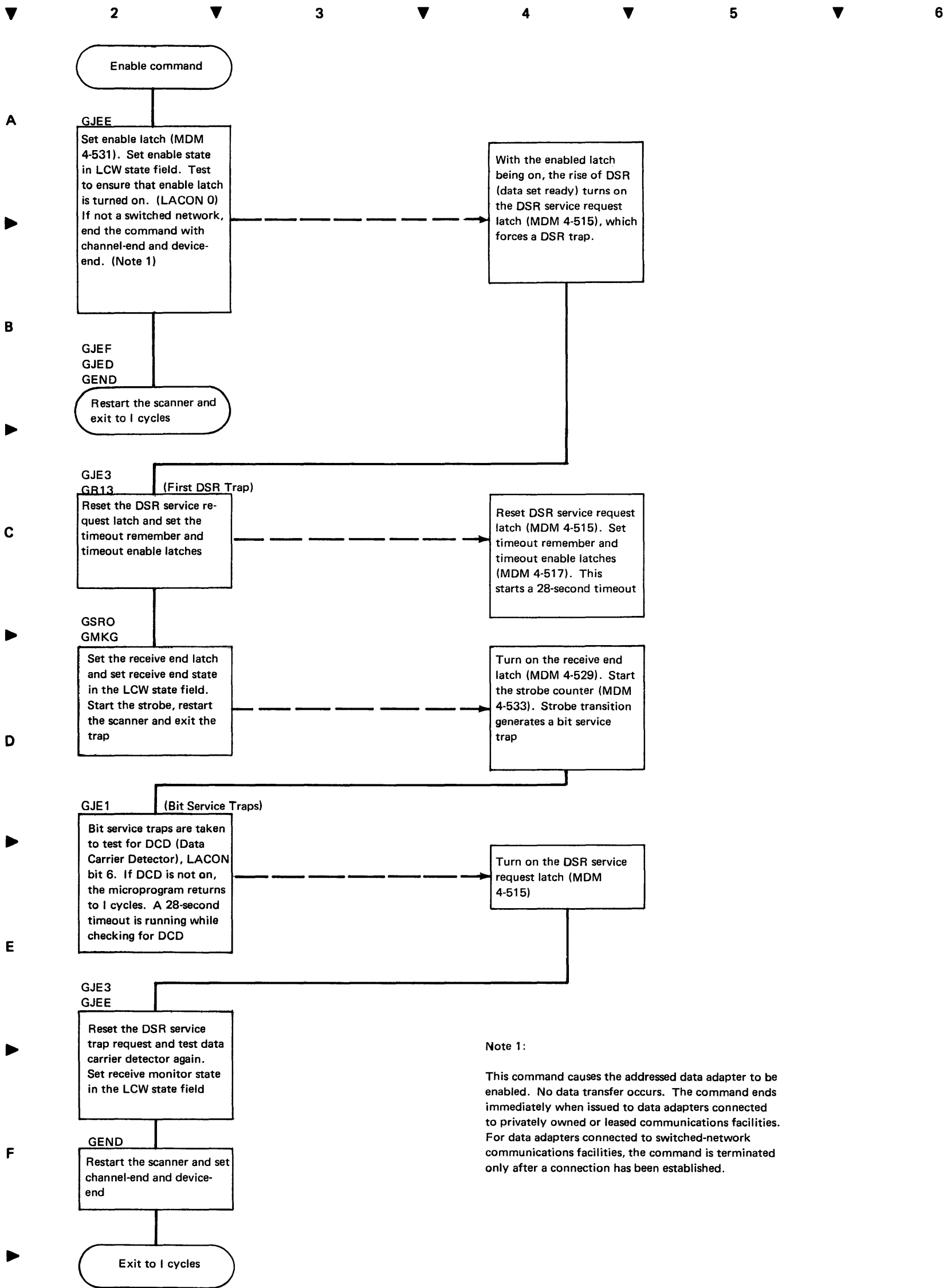
H



● Diagram 5-504. Start/Stop Addressing Operation (Part 2 of 3)



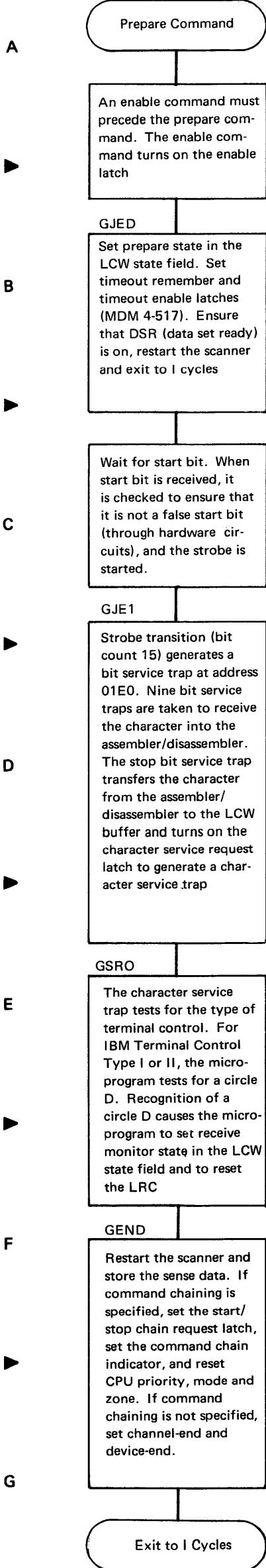
● Diagram 5-505. Start/Stop Poll Command (Part 2 of 2)



Note 1:

This command causes the addressed data adapter to be enabled. No data transfer occurs. The command ends immediately when issued to data adapters connected to privately owned or leased communications facilities. For data adapters connected to switched-network communications facilities, the command is terminated only after a connection has been established.

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6



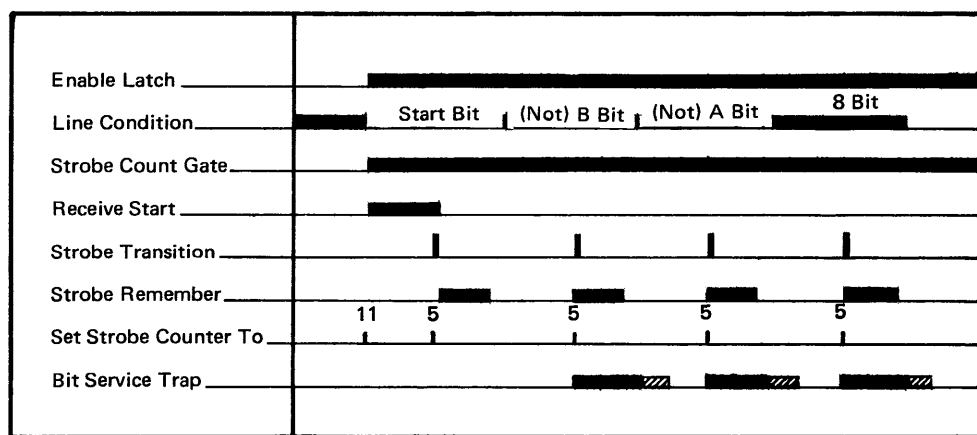
Objectives:

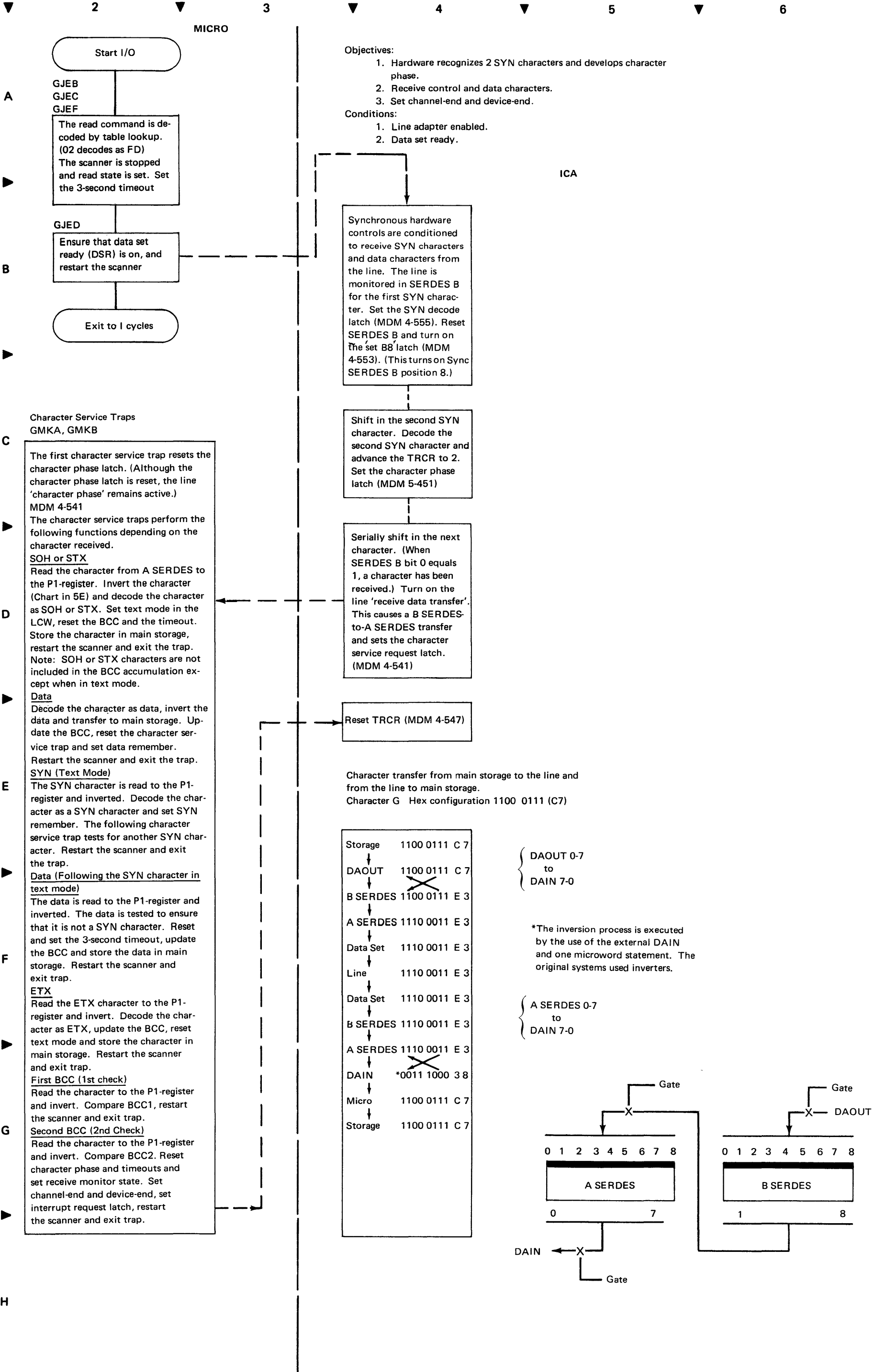
This read type command is used in contention type systems to permit the ICA to monitor the addressed line to signal the program that a character has been detected. An enable command must precede this read type command.

IBM Terminal Control Types I and II check for a circle D character.

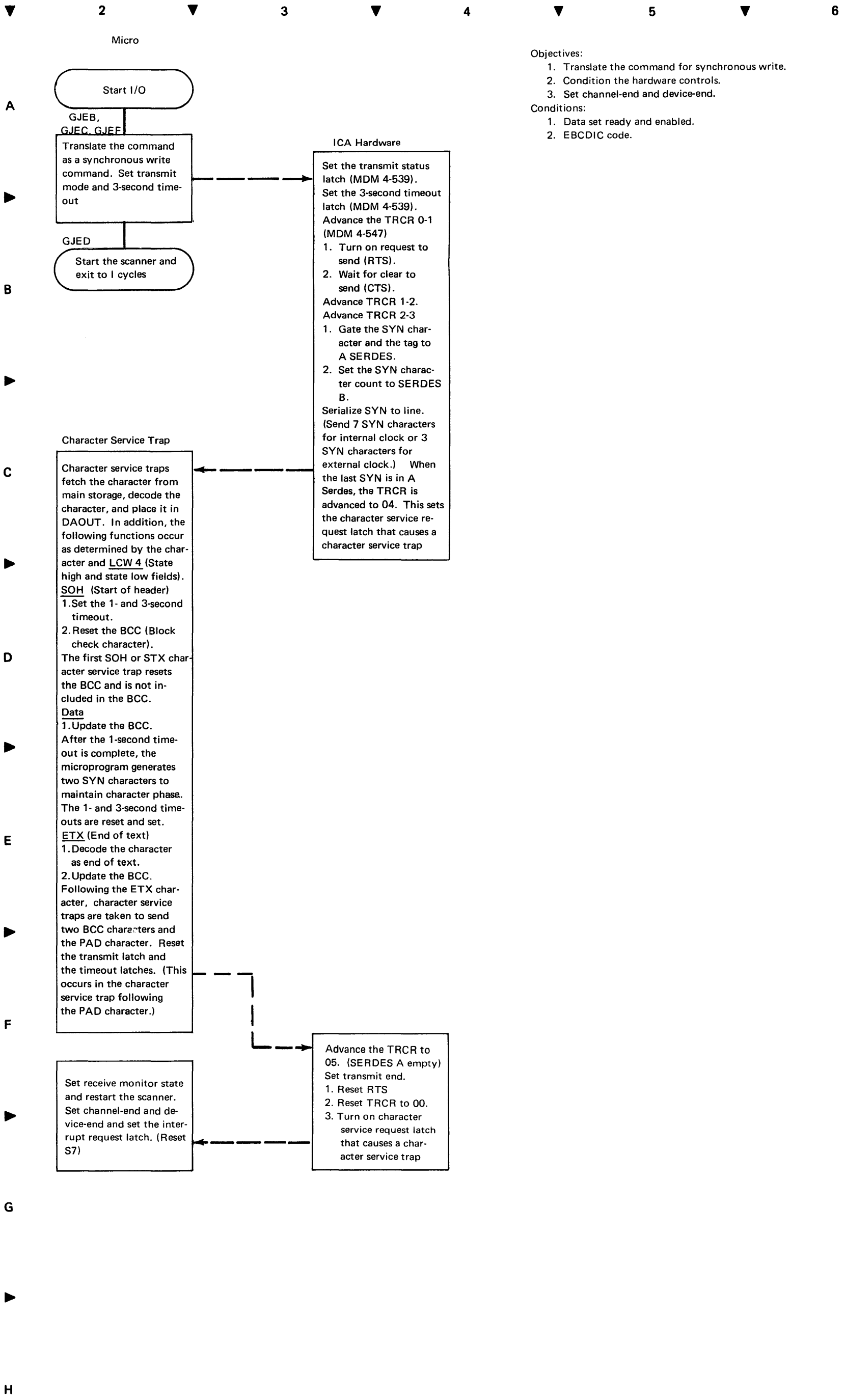
The command is terminated after one character has been received. No data is transferred to storage.

Channel-end and device-end are set only if command chaining is not specified.





● Diagram 5-508. Synchronous Receive Operation



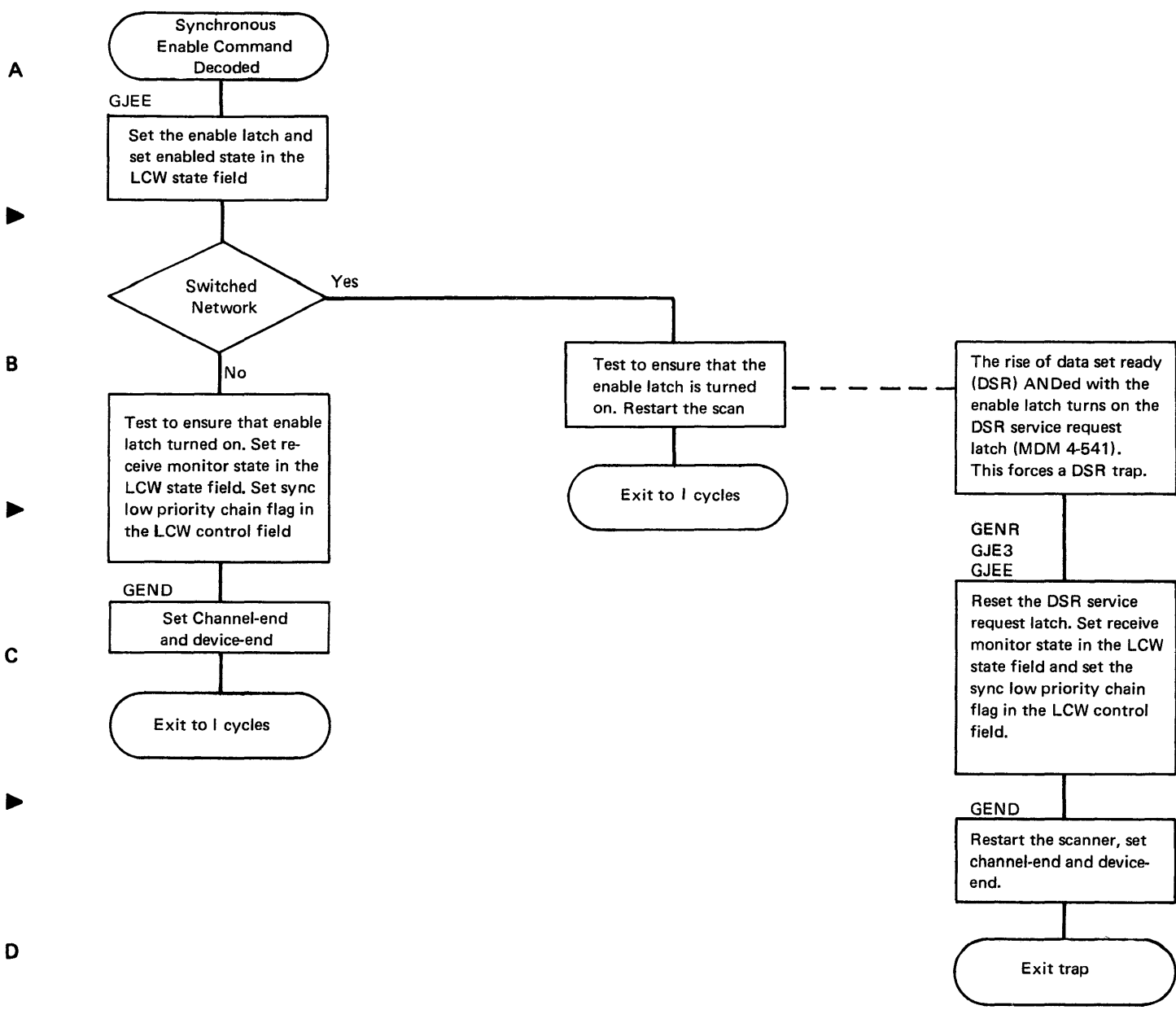
Objectives:

1. Translate the command for synchronous write.
2. Condition the hardware controls.
3. Set channel-end and device-end.

Conditions:

1. Data set ready and enabled.
2. EBCDIC code.

● Diagram 5-509. Synchronous Write Operation



The enable command causes the addressed data adapter to be enabled.
No data transfer occurs.
The command is terminated immediately if issued to a private or leased line.
If issued to a switched line, the command is not terminated until the rise of DSR is detected.

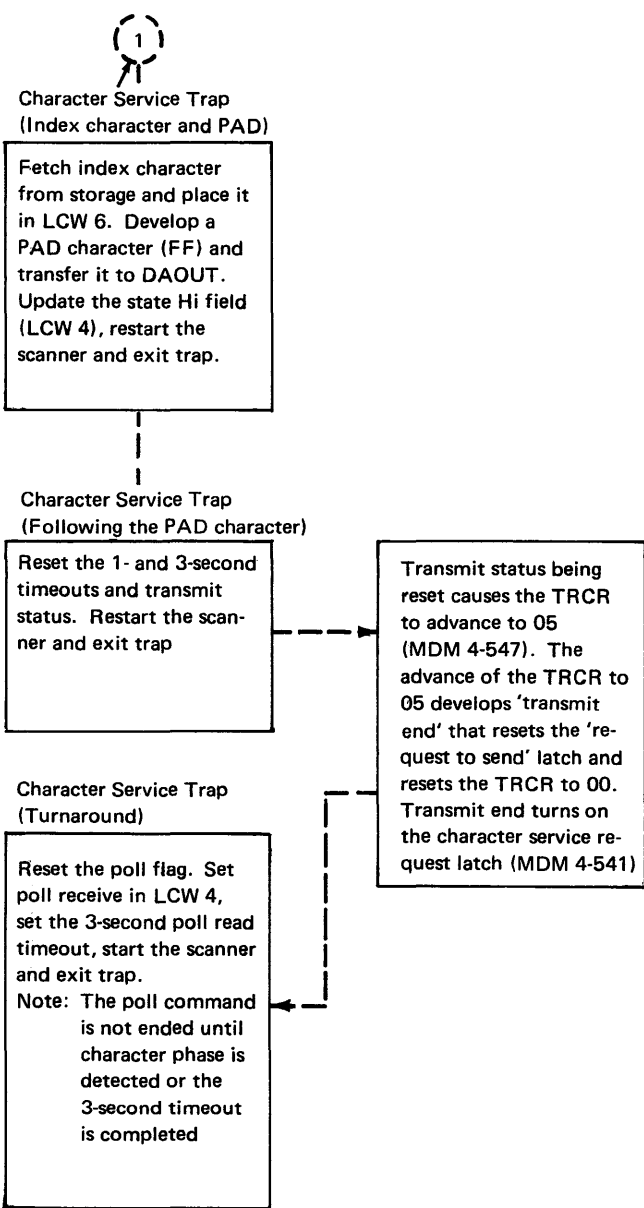
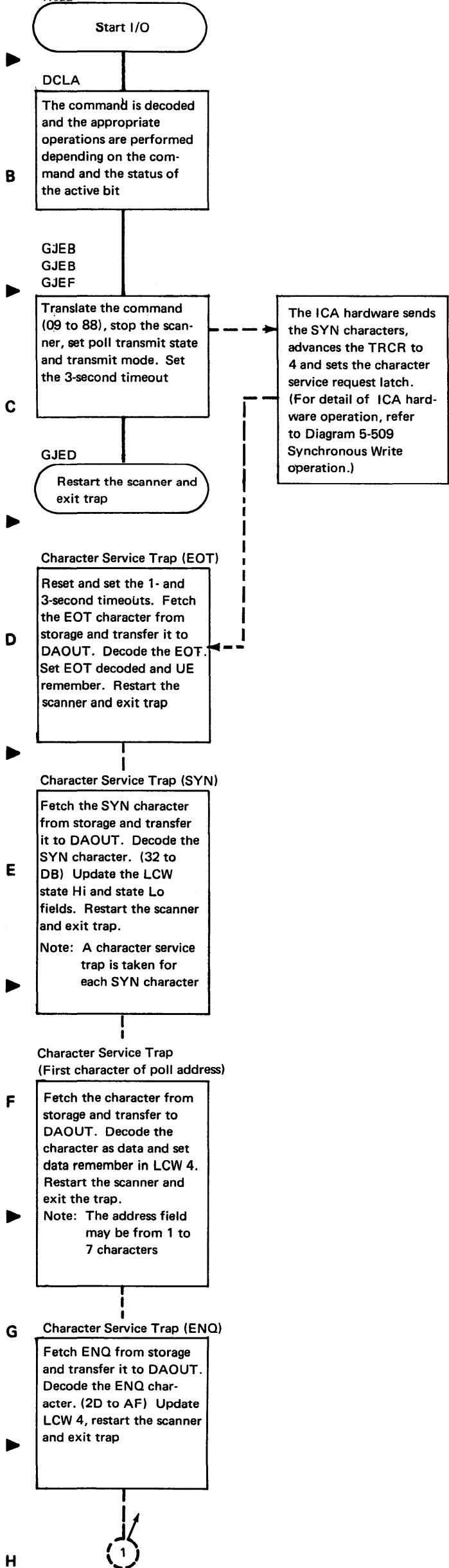
● Diagram 5-510. Synchronous Enable Command

Polling of synchronous terminals is done under a Start I/O that refers to the following channel

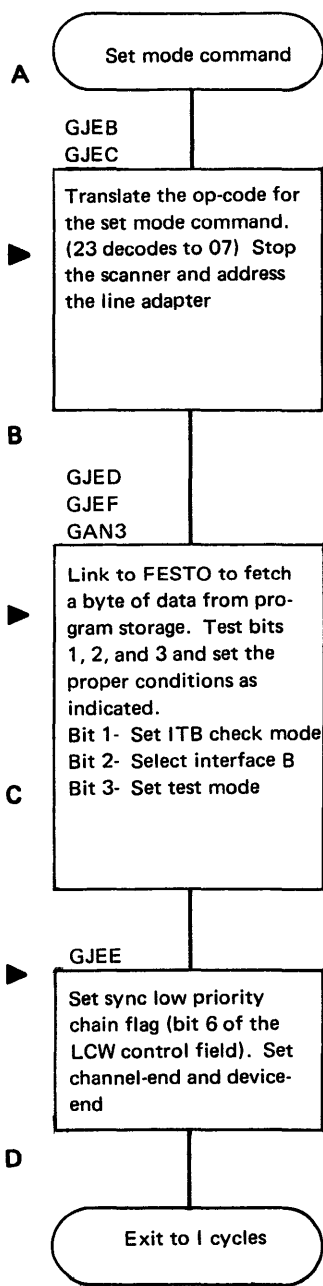
A command word sequence.

Poll
Tic
Read

Character Sequence
S S S E F S S S A X X X X X X E P
Y Y Y O F Y Y Y D N A
N N N T N N N D Q D



● Diagram 5-512. Synchronous Poll Write Command



This command is a control command that causes a single byte of data to be fetched from program storage.

Bits 1, 2, and 3 are used to set the following conditions.

- Bit 1 - Places the adapter in ITB mode.
- Bit 2 - Selects interface B. (Interface B can only set on the first adapter with dual communications interface feature.)
- Bit 3 - Places the adapter in test mode.

Bits 1 and 2 are reset by system reset. Bit 3 is reset by issuing a disable command.

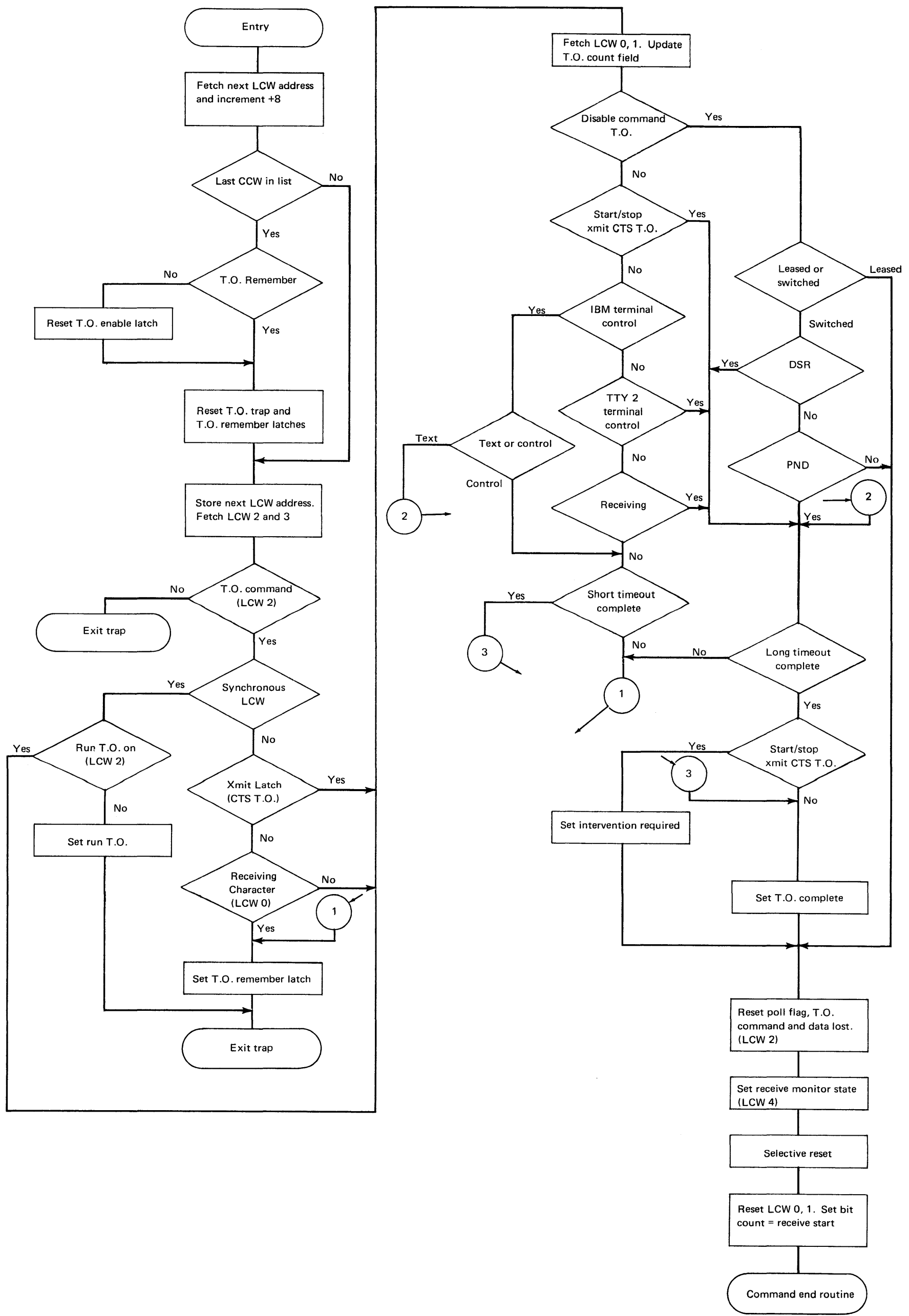
The existing mode setting can be changed by issuing another set mode command.

Program note: To change interface designation, a disable command must precede the set mode command.

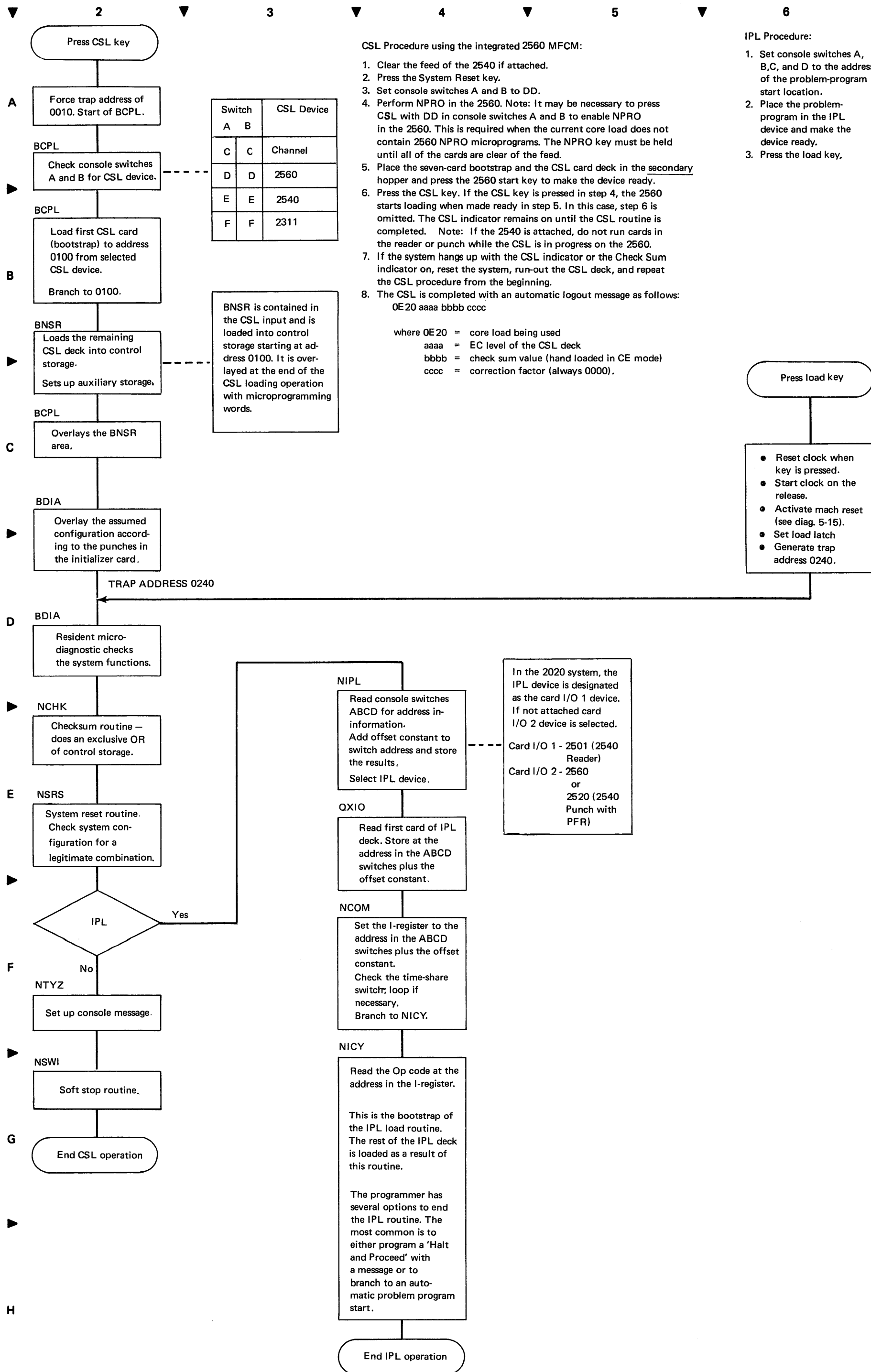
● Diagram 5-513. Synchronous Set Mode Command

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6

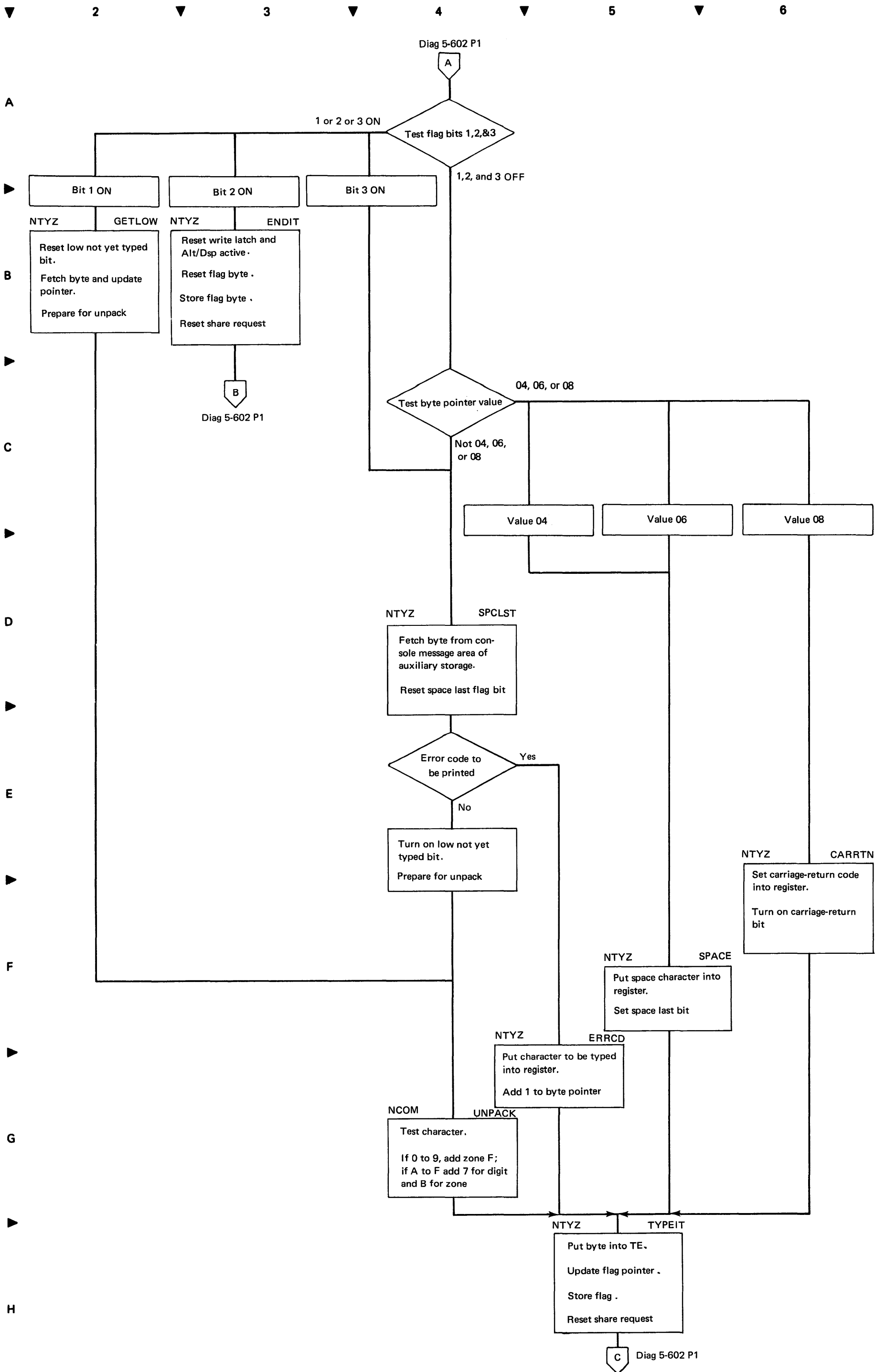
A
B
C
D
E
F
G
H



● Diagram 5-514. Timeout Update Trap Routine



● Diagram 5-600. CSL/IPL Operational Diagram



● Diagram 5-602. Error Message Procedure (Part 2 of 2)

SYSTEM/360 MODEL 20 ERROR SUMMARY

The following errors are recognized by the System/360 Model 20 system and cause a program stop in that system. In the System/360 Model 20 Mode feature, the microprogram analyzes the problem program and data for the same type of errors.

If an error is found, an error message is typed on the printer/keyboard and the microprogram waits in the soft stop loop for operator handling. The error message includes the error codes shown here to identify the type of error. See MDM 5-602 for additional information.

A

I. Programming Error Stop Conditions

01 Error Code — Invalid Operating Code

04 Error Code — Addressing Error

05 Error Code — Addressing Error

1. An instruction address or an operand address refers to the protected first 144 bytes of main storage.

1. An instruction address or an operand address is outside of available storage.
2. The R1 or R2 fields of an RR or an RX format binary instruction contain binary values 0 through 7, the R1 field in a branch and store instruction contains binary values 0 through 7, or the R2 field of an RR format branch instruction contains binary values 1 through 7.
3. An instruction byte is located at the last available storage position.

B

06 Error Code — Specification Error

1. An instruction address is not located on a half-word boundary of main storage.
2. A binary operand is not located on a specified boundary of main storage.
3. For decimal add, decimal subtract, zero and add, and decimal compare instructions, the length code L2 is greater than the length code L1.
4. For decimal multiply and decimal divide instructions, the length code L2 is greater than 7 or greater than or equal to the length code L1.
5. Bits 12 through 15 of an RX format instruction are not all zero.
6. A 2560 write card instruction is encountered in the program and there is no card in the punch or print station, or no print head has been selected.
7. The field length specified in an input/output instruction is zero or is greater than the maximum allowable number for the I/O device addressed.

07 Error Code — Data Error

1. A sign or digit code of an operand in the decimal instructions zero and add, add, subtract, compare, multiply, or divide is incorrect or the operand fields in these operations overlap incorrectly.
2. The multiplicand field (first operand) in a decimal multiply instruction has insufficient high-order zeros.
3. An invalid digit code is contained within the second operand field of an edit operation.

C

08 Error Code — Binary Overflow Check

0B Error Code — Decimal Divide Check

1. The resultant quotient in a divide decimal instruction exceeds the specified data field instruction (including division by zero) or the dividend has no leading zero.

II. Process Error Stop Condition

(No Error Code) — Parity Error

Each system handles parity as an internal processing error. No error message or error code is assigned.

III. I/O Error Conditions (CPU)

D

01 Error Code — Invalid Operation Code

04 Error Code — Addressing Error

05 Error Code — Addressing Error

06 Error Code — Specification Error

NOTE: An input/output instruction containing an I/O device address that specifies a device not attached to the system is treated as a no-operation.

1. An instruction address or the address of an input/output data field refers to the protected first 144 bytes of main storage.

1. An instruction address, the address of an input/output data field, or a branch address is outside available storage.
2. An instruction part is located in the last two main-storage positions.

1. An instruction address is not located on a half-word boundary of main storage.
2. A 2560 write card instruction is encountered in the program, and there is no card in the punch or print station, or no print head has been selected.
3. The field length specified in an input/output instruction is zero or is greater than the maximum allowable number for the I/O device addressed.

E

IV. I/O Error Conditions (I/O)

Error conditions that may occur in I/O devices are included in the IBM Systems Reference Library publication for the respective device.

F

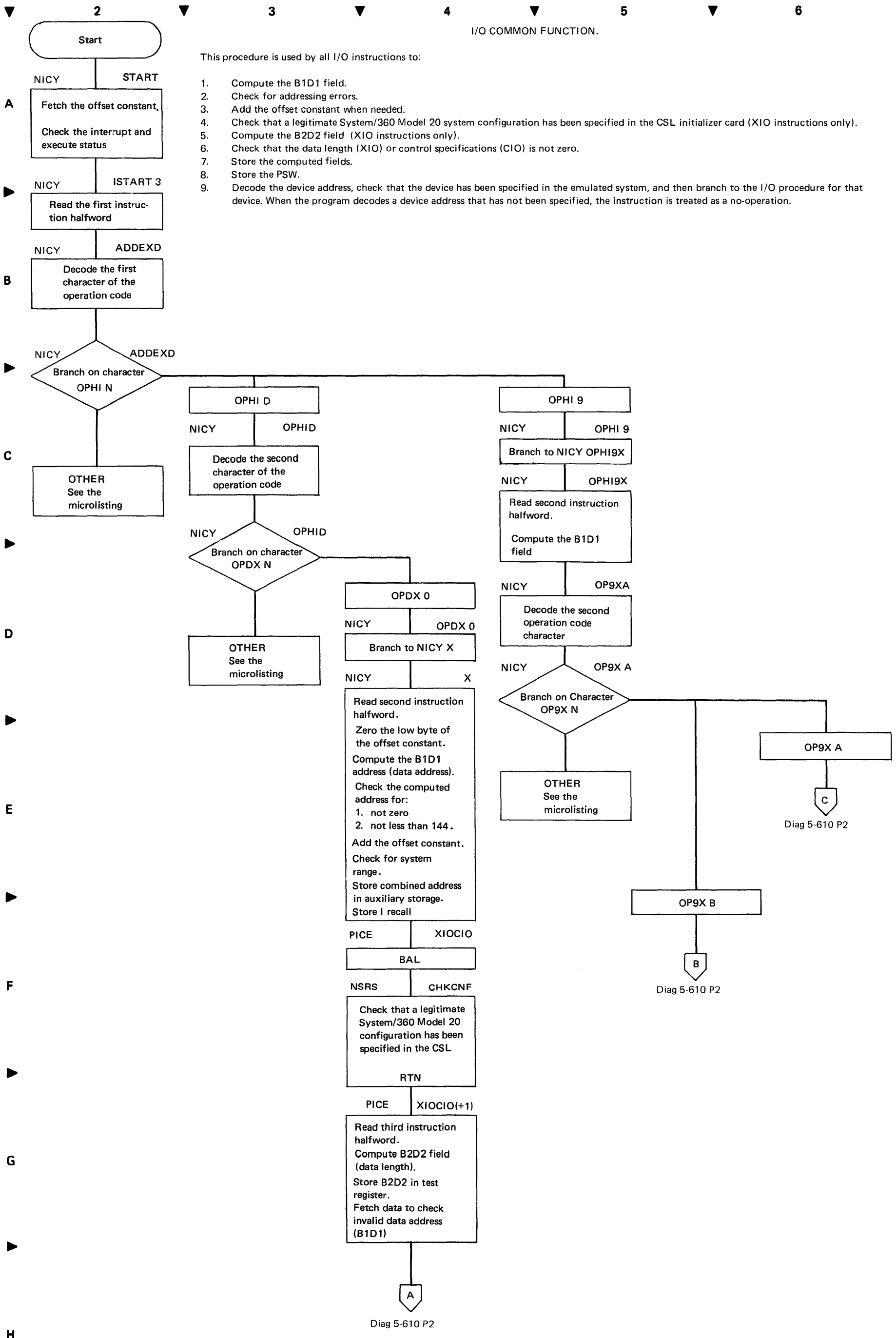
G

H

I/O COMMON FUNCTION.

This procedure is used by all I/O instructions to:

1. Compute the B1D1 field.
2. Check for addressing errors.
3. Add the offset constant when needed.
4. Check that a legitimate System/360 Model 20 system configuration has been specified in the CSL initializer card (XIO instructions only).
5. Compute the B2D2 field (XIO instructions only).
6. Check that the data length (XIO) or control specifications (CIO) is not zero.
7. Store the computed fields.
8. Store the PSW.
9. Decode the device address, check that the device has been specified in the emulated system, and then branch to the I/O procedure for that device. When the program decodes a device address that has not been specified, the instruction is treated as a no-operation.



● Diagram 5-610. I/O Common Routine (Part 1 of 2)

2

3

4

5

6

Diag 5-610 P1

A

B

C

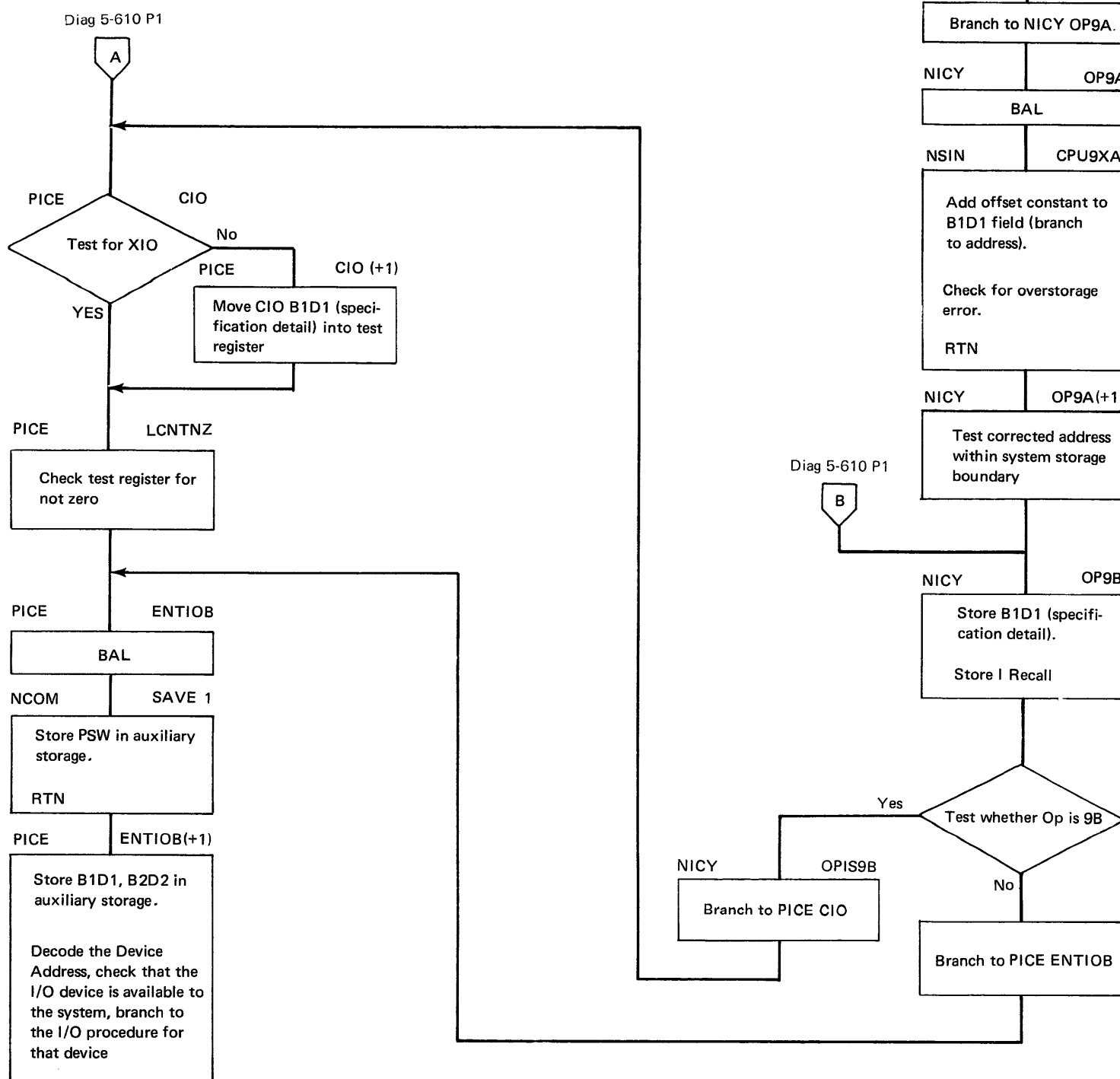
D

E

F

G

H



Device Address	I/O Procedure	MDM Diagram
0	No Op	
1 (2501)	QXIO RD2540	5-612 Read a Card (XIO) 5-618 Test Reader Busy (TIOB)
2 (2520) (2560)	QAAD RP2520 PCIO MF2560	
3 (1442)	QPXI SRTXIO	5-614 Punch a Card (XIO)
4 (2203) (1403)	PRTB START PRTB START	5-616 Print a Line (XIO) 5-620 Delayed Skip to 1 (CIO)
5	No Op	
6	No Op	
7 (IIOC)	RTAA IOCHNL	5-640 Channel Operation
8 (2311)	RFIL FILE20	5-631 Write Count and Data (Write Format) 5-632 Read Data Operation
9	No Op	
A	No Op	
B	No Op	
C	No Op	
D	No Op	
E (2152)	NTOP START	
F	No Op	

● Diagram 5-610. I/O Common Routine (Part 2 of 2)

READ A CARD

Instruction: D0 1 2 B1D1 B2D2

D0: XIO instruction (data transfer).

1: Device address (2501).

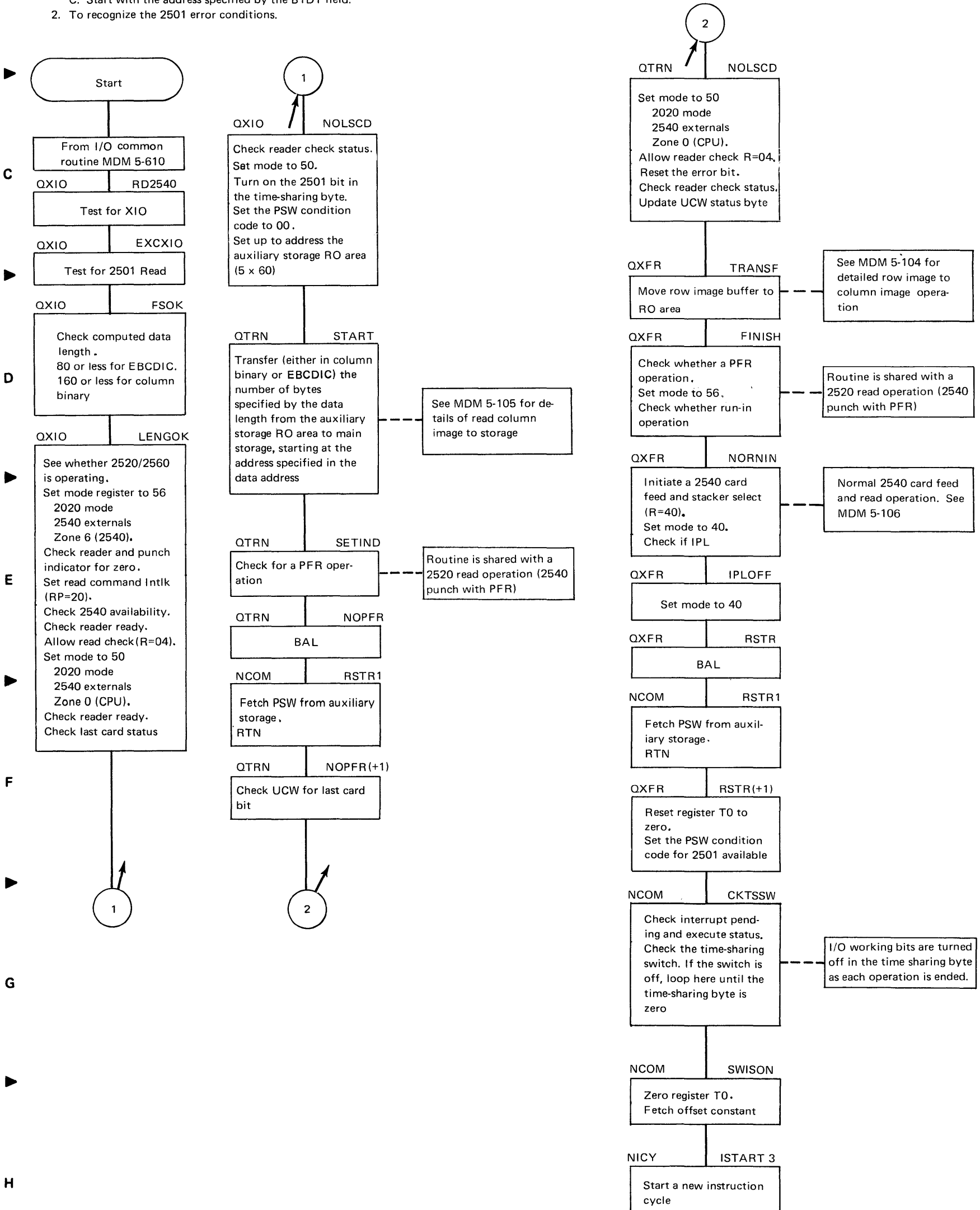
- A**
- 2: Function specification (read a card).
 - B1D1: Data address.
 - B2D2: Data length.

Conditions:

- 1. No other I/O device is working.
- 2. No errors on read-in.
- 3. Not the last card.

Objectives:

- 1. To emulate the 2501 serial read operation on the 2540:
 - A. Read a card (read and feed with an automatic selection of stacker R1 on the 2540).
 - B. Transfer to the program storage the number of bytes (card columns) specified by the B2D2 field.
 - C. Start with the address specified by the B1D1 field.
- 2. To recognize the 2501 error conditions.



● Diagram 5-612. 2501/2540 Read a Card (XIO)

PUNCH A CARD

Instruction: D0 3 6 B1D1 B2D2

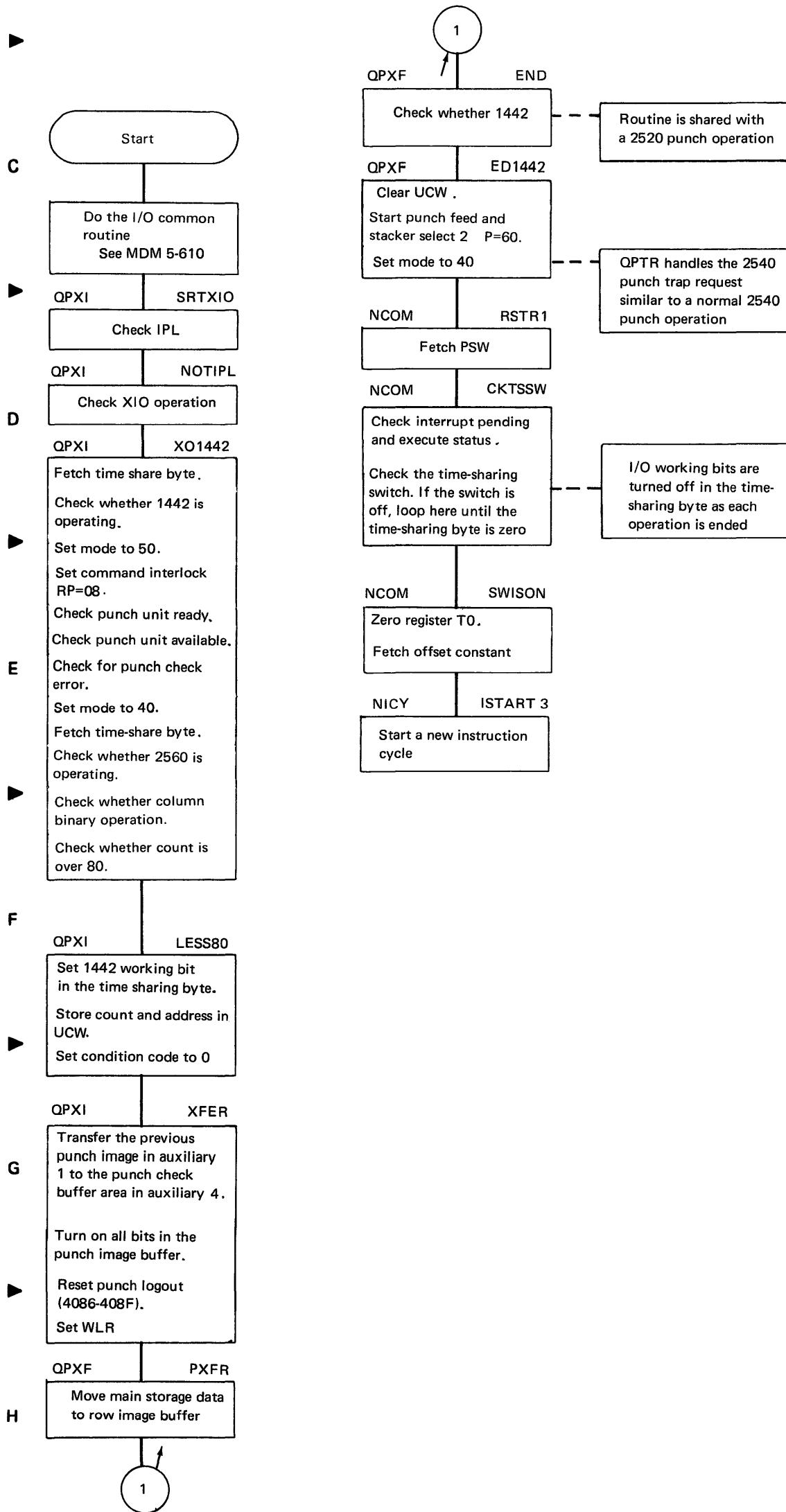
D0 : XIO instruction (data transfer)
3 : Device address (1442)
6 : Function specification (punch and feed)
B1D1: Data address
B2D2: Data length

Conditions:

1. Not IPL.
2. No other I/O device is operating.
3. Not column binary.
4. No I/O errors.

Objectives:

1. Emulate a 1442 serial punch and feed operation on the 2540.
2. Stacker select P2 for non-error cards, and P1 for error cards.



● Diagram 5-614. 1442/2540 Punch a Card (XIO)

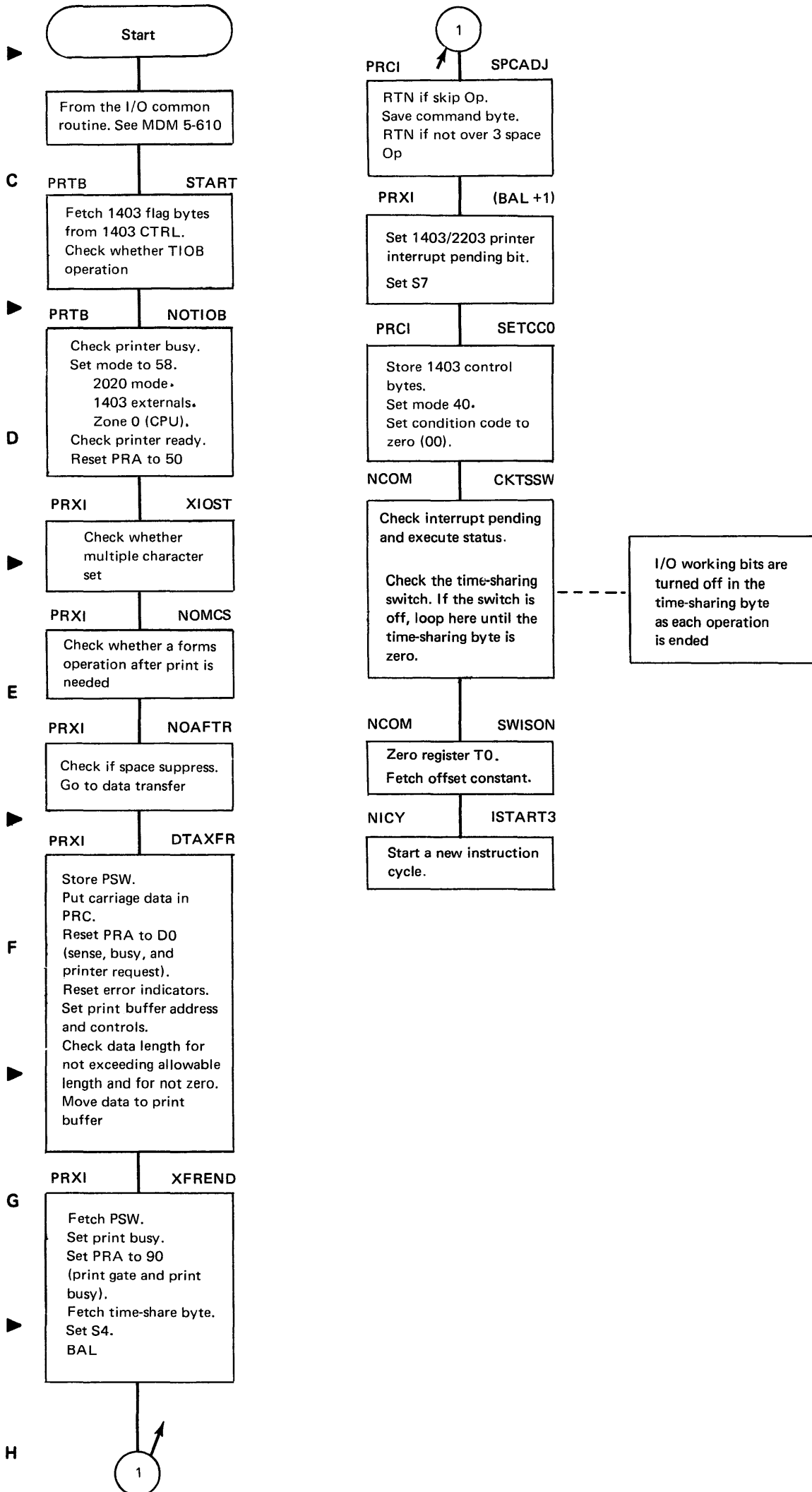
Instruction: D0 4 0 B1D1 B2D2

- D0 : XIO instruction (data transfer) .
- 4 : Device address (either 1403 or 2203) .
- 0 : Function specification (print and space) .
- B1D1: Data address .
- B2D2: Data length .

Conditions:

1. No other I/O device is operating.
2. No I/O errors have occurred.
3. Single space.
4. No carriage operation (skipping).

B



● Diagram 5-616. 1403/1403 Print a Line (XIO)

TEST I/O AND BRANCH

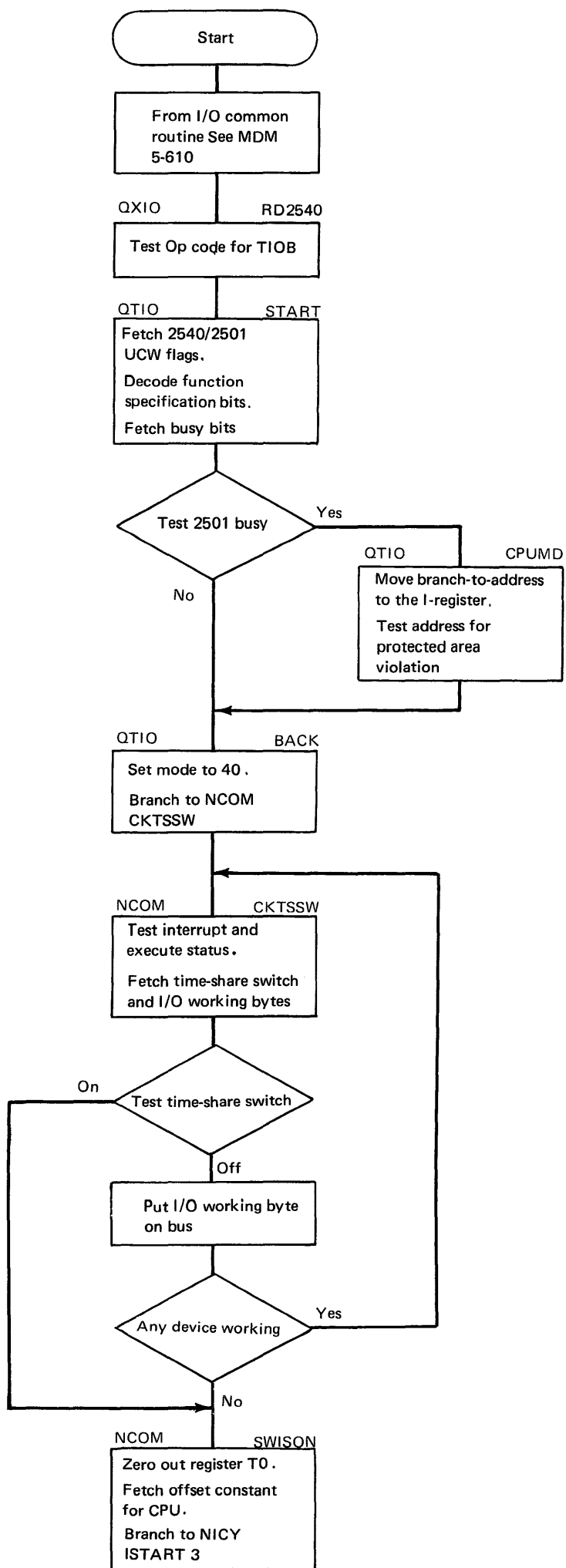
Instruction: (020E) 9A 1 0 020E

(020E): Instruction address.
9A : Operation code (TIOB).
1 : Device address (2501).
0 : Function specification (test reader busy).
020E : Branch to address.

Objectives:

1. Decode Op code (9A) as a TIOB instruction
2. Fetch busy bits from auxiliary storage.
3. If 2501 busy bit is ON:
 - a. Move branch address to I-register.
 - b. Test branch to address for non-protected area.
 - c. Test-time sharing switch.
 - d. Branch to NICY ISTART 3.
4. If 2501 busy bit is OFF:
 - a. Test time-sharing switch.
 - b. Branch to NICY ISTART 3.

(I-reg contains the address of the next sequential instruction)



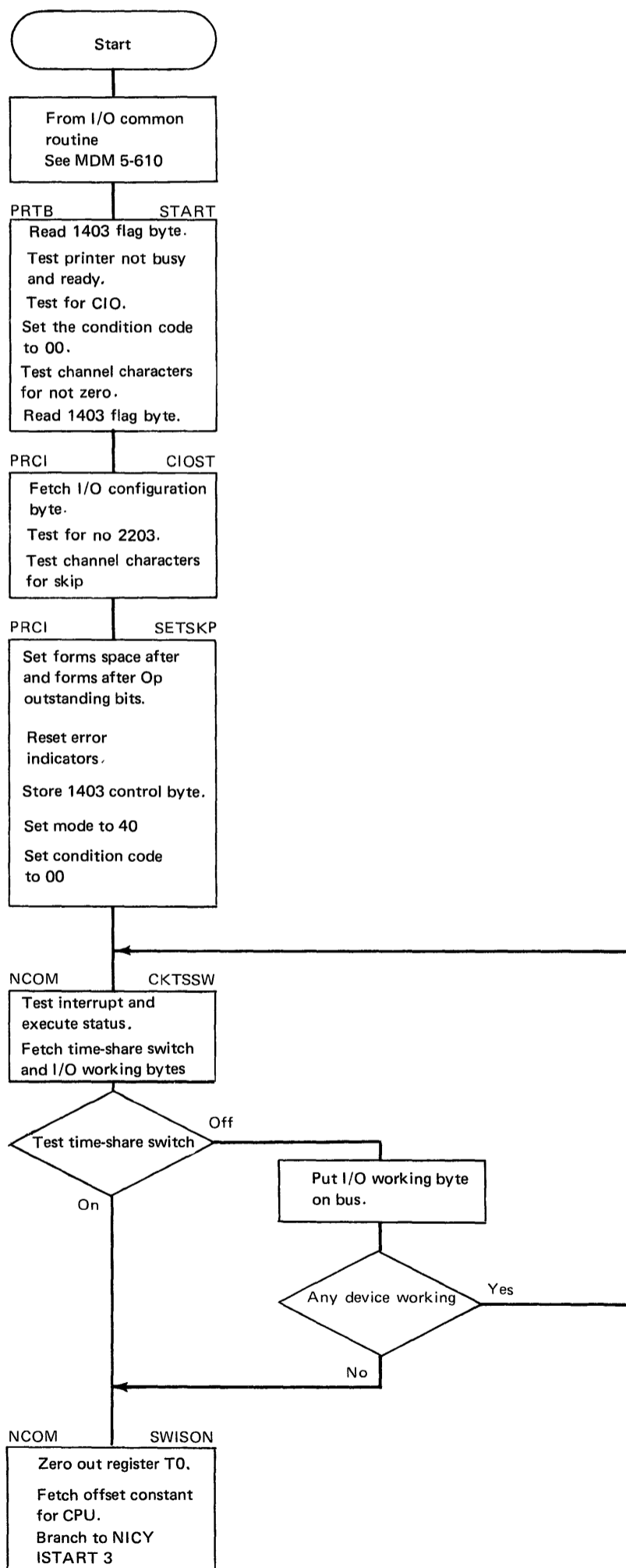
● Diagram 5-618. 2501/2540 Test Reader Busy (TIOB)

Instruction: 9B 4 7 0001

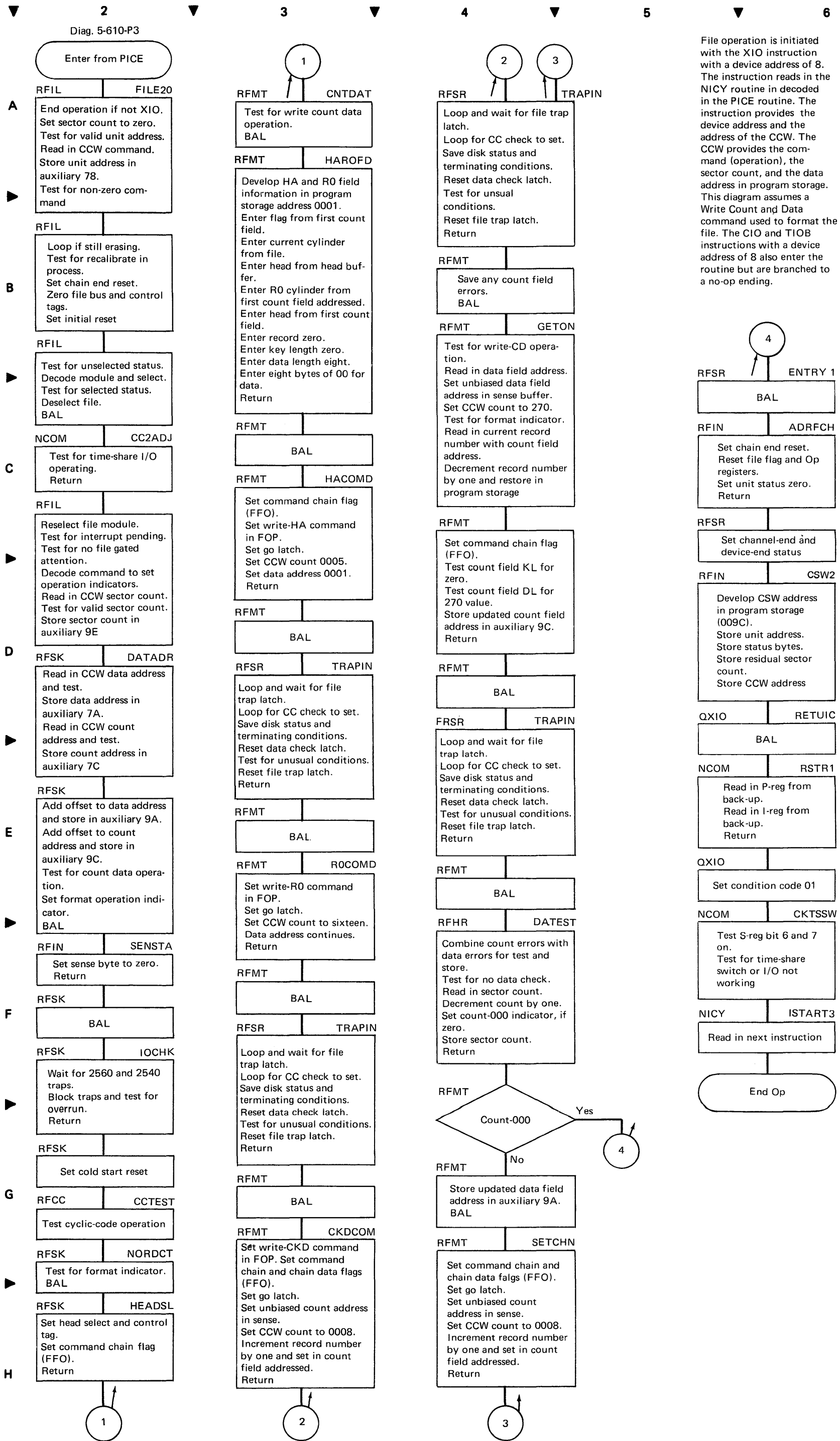
- A
- 9B : Operation code (CIO).
 - 4 : Device address (printer 2203 or 1403).
 - 7 : Function specification (delayed skip).
 - 0001 : Detailed functional specification (carriage tape channel 1).

Objectives:

- B
1. Read 1403 flag byte from 1403 UCW.
 2. Test for printer ready and not busy.
 3. Test for CIO operation.
 4. Zero out condition code.
 5. Test function specified.
 6. Test I/O configuration.
 7. Store condition in 1403 UCW flag byte.
 8. Test time-share switch.
 9. Branch to NICY ISTART 3.
 10. Skip will be stored until after the next print operation.

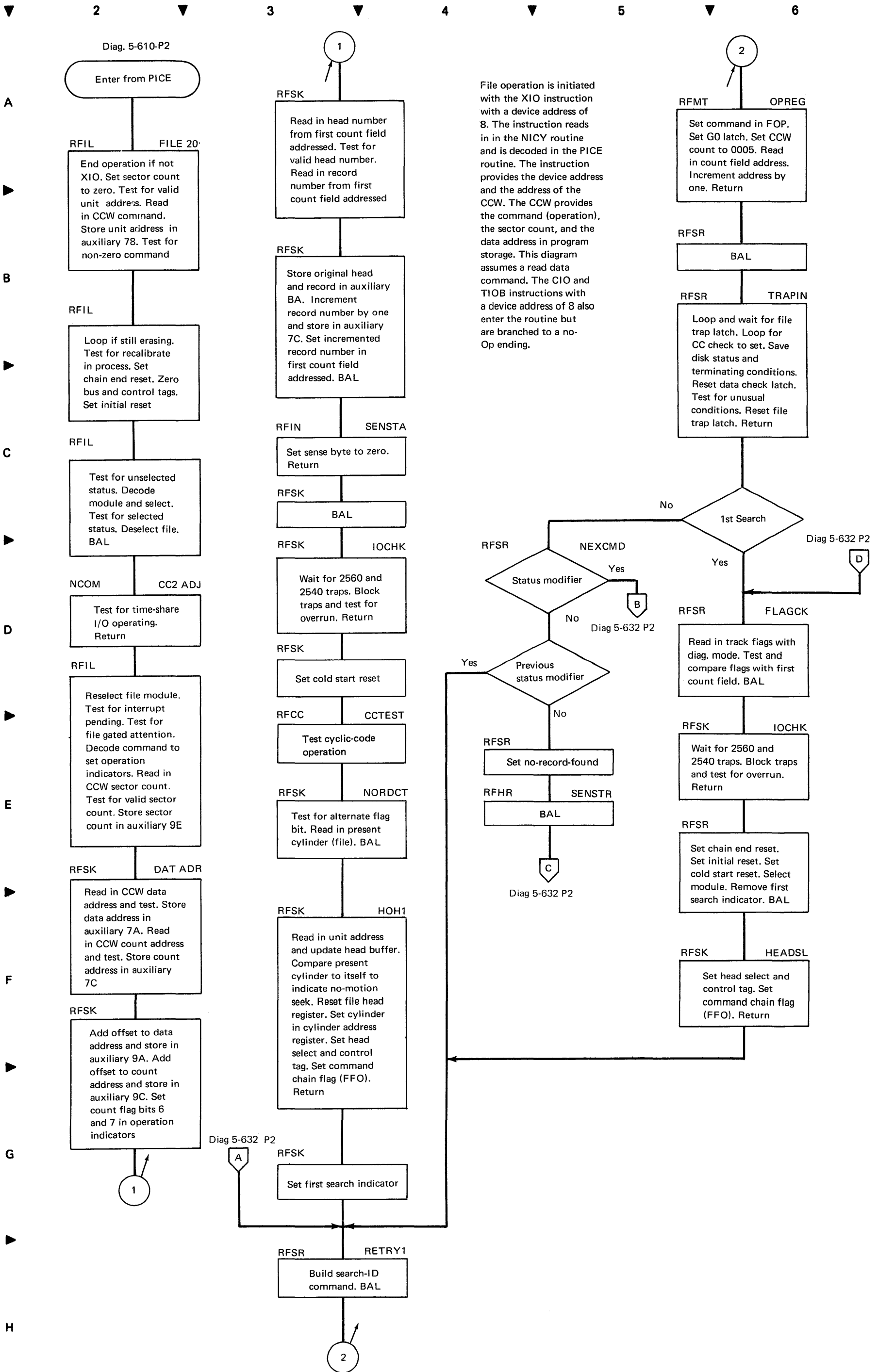


● Diagram 5-620. 1403/1403 Delayed Skip to 1 (CIO)

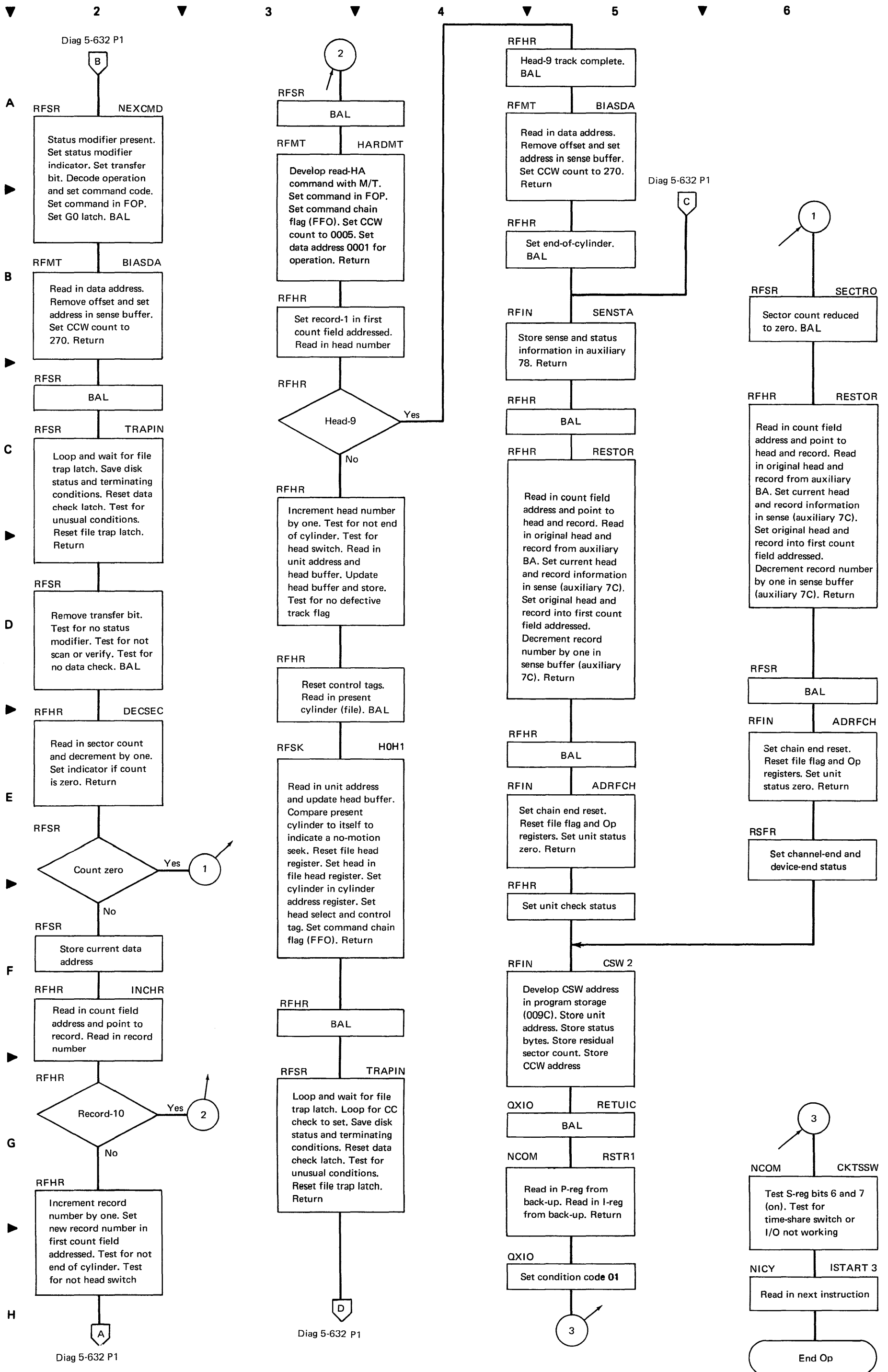


File operation is initiated with the XIO instruction with a device address of 8. The instruction reads in the NICY routine in decoded in the PICE routine. The instruction provides the device address and the address of the CCW. The CCW provides the command (operation), the sector count, and the data address in program storage. This diagram assumes a Write Count and Data command used to format the file. The CIO and TIOB instructions with a device address of 8 also enter the routine but are branched to a no-op ending.

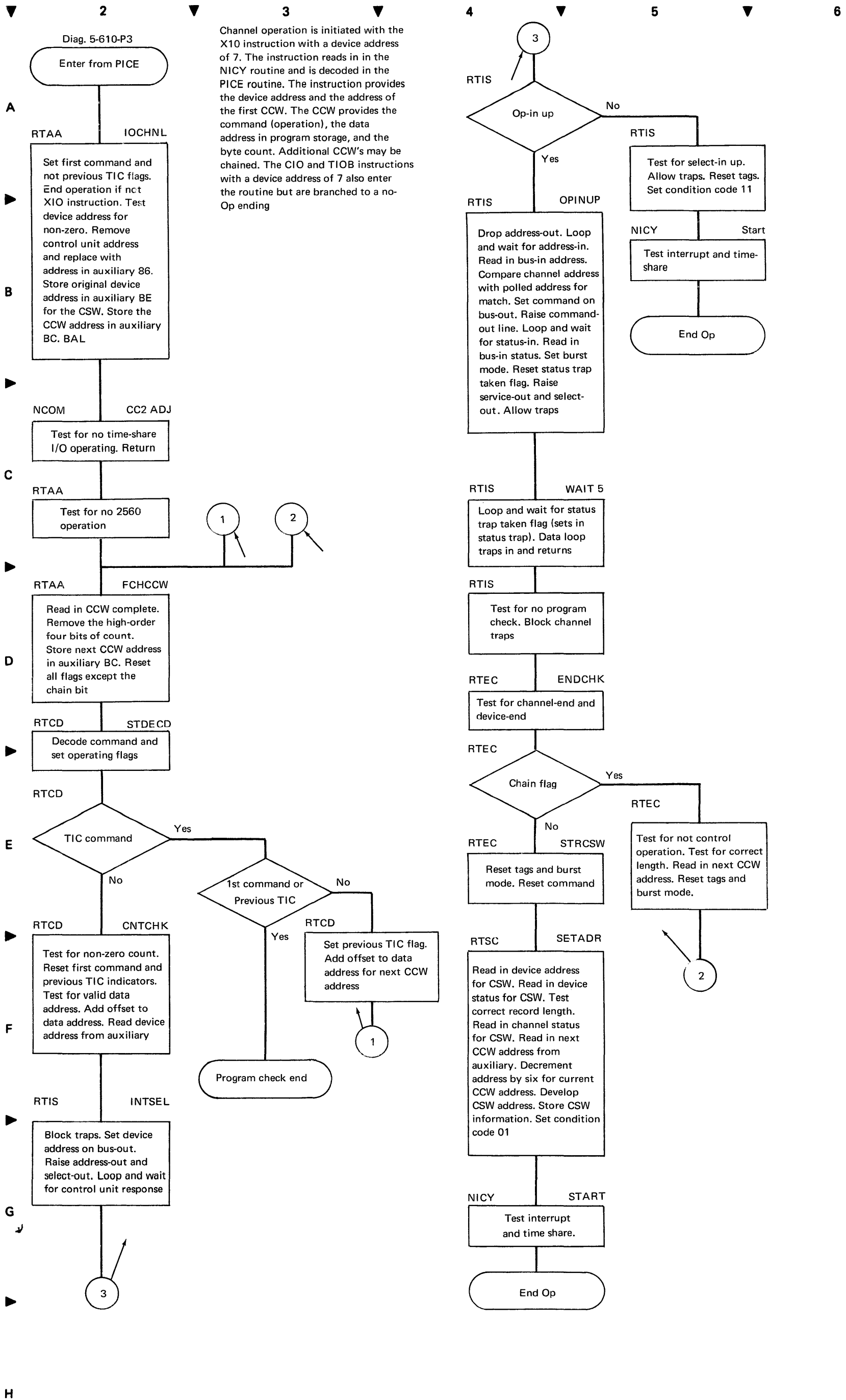
● Diagram 5-631. File, Write Count Data Operation



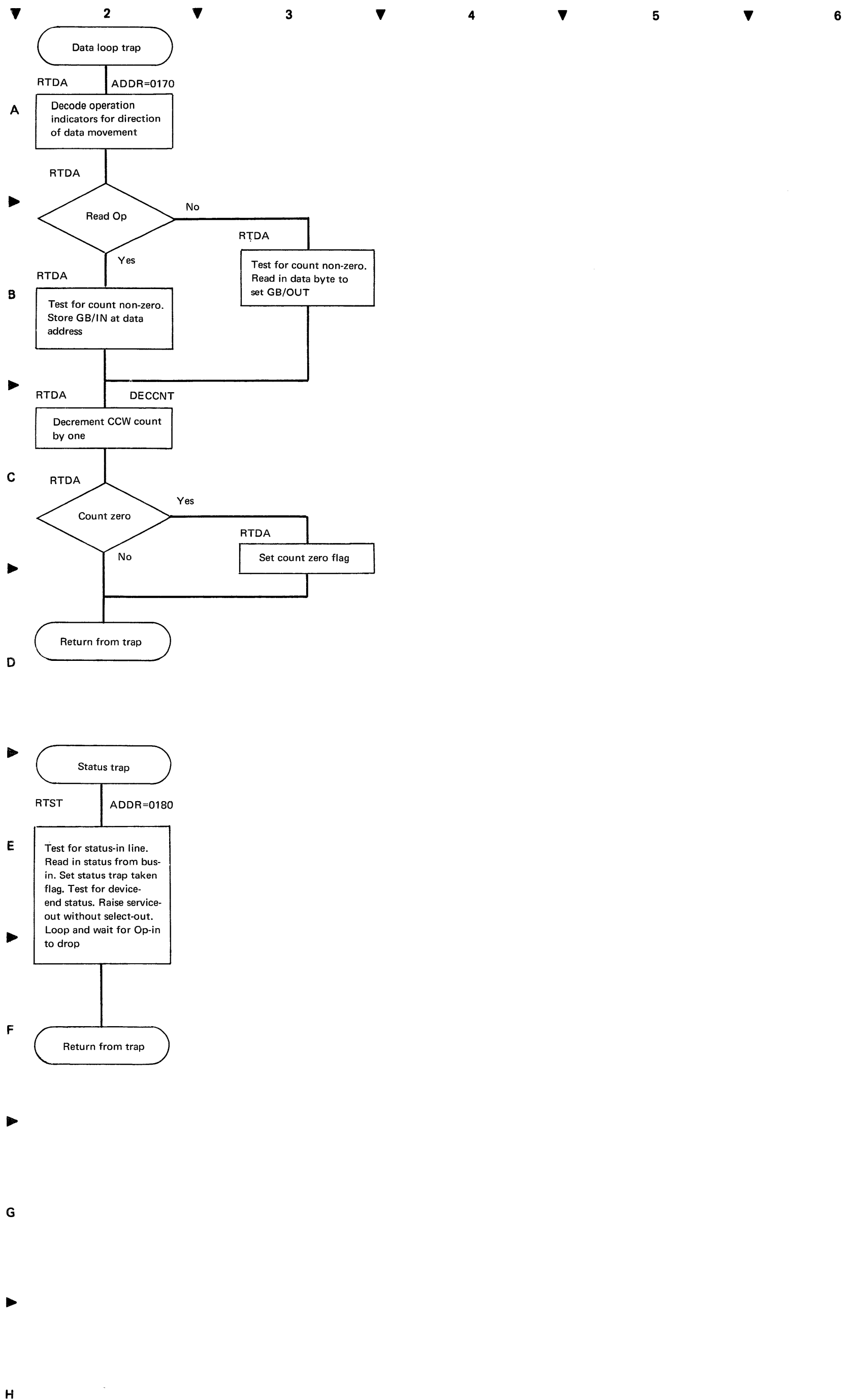
● Diagram 5-632. File, Read Data Operation (Part 1 of 2)



● Diagram 5-632. File, Read Data Operation (Part 2 of 2)



● Diagram 5-640. Channel Operation (Part 1 of 2)



● Diagram 5-640. Channel Operation (Part 2 of 2)

Instruction: D0 22 B1D1 B2D2

- A**
- D0: XIO instruction (data transfer)
 - 2: Device address (2560)
 - 2: Function specification (read a primary card)
 - B1D1: Data Address
 - B2D2: Data Length Count.

Conditions:

1. No other I/O device is working.
2. No errors, and primary feed is ready.
3. Not last card.

Objectives:

1. Read a card from the primary feed of the 2560.
2. Transfer the number of bytes specified by the B2D2 field.
3. Transfer these bytes into storage, starting at the address specified by the B1D1 field.

B

C

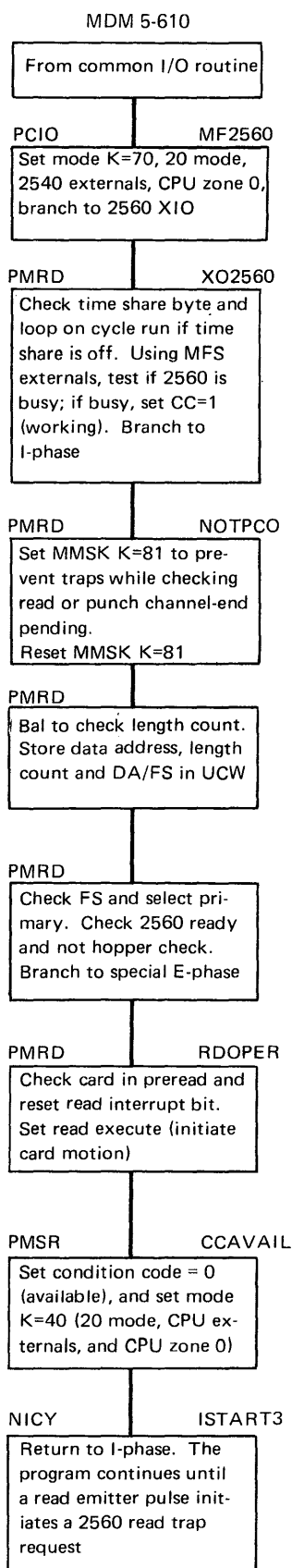
D

E

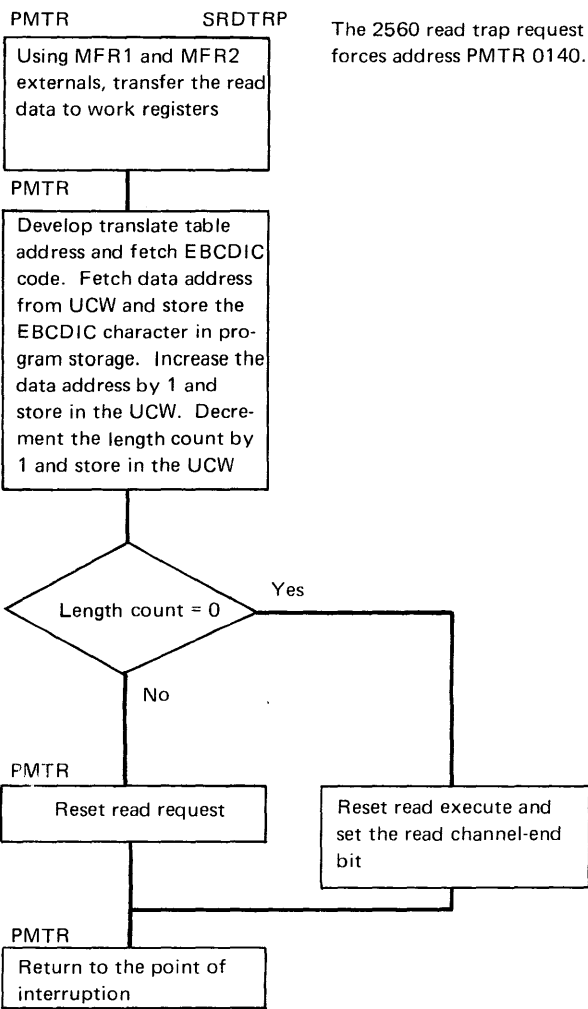
F

G

H



Trap Routine



Instruction: D0 27 B1D1 B2D2

- A**
- D0: XIO instruction (data transfer)
 - 2: Device address (2560)
 - 7: Function specification (punch and feed a secondary card)
 - B1D1: Data Address
 - B2D2: Data Length Count

Conditions:

1. No other I/O device is working.
2. No errors, and secondary feed is ready.
3. No previous instructions.
4. Not last card.

Objectives:

1. Punch a card from the 2560 secondary feed.
2. Transfer the number of bytes specified by the B2D2 field.
3. Transfer these bytes from storage to the punch, starting at the address specified by the B1D1 field.

B

▶

C

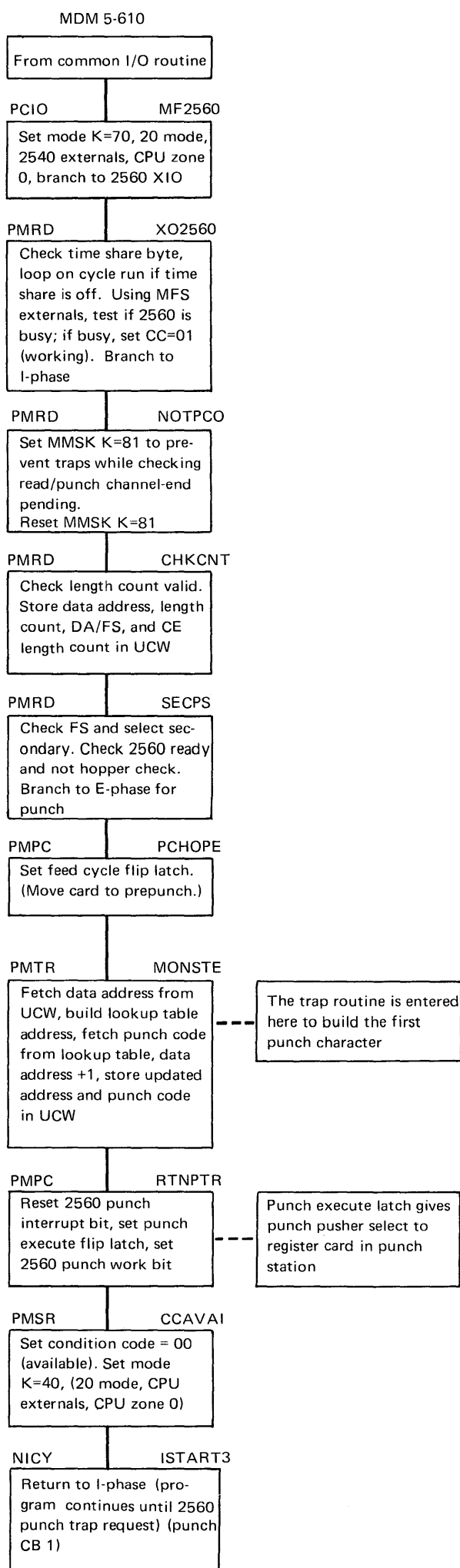
D

E

F

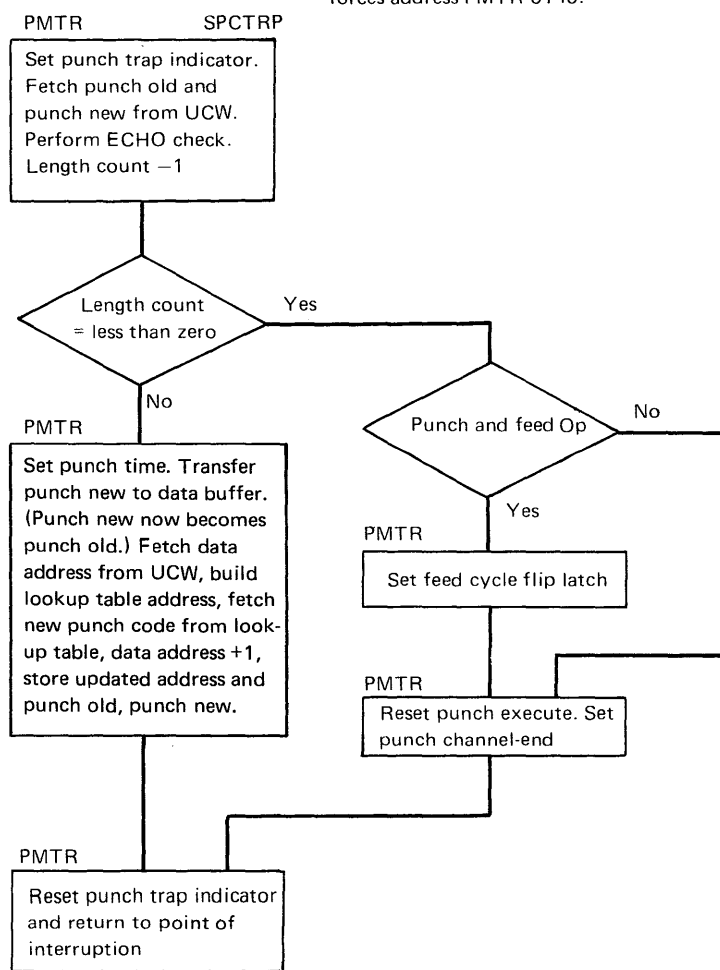
G

H



Trap Routine

The 2560 punch trap request forces address PMTR 0140.



●Diagram 5-653. 2560 Punch Operation Chart

Instruction: D0 20 B1D1 B2D2

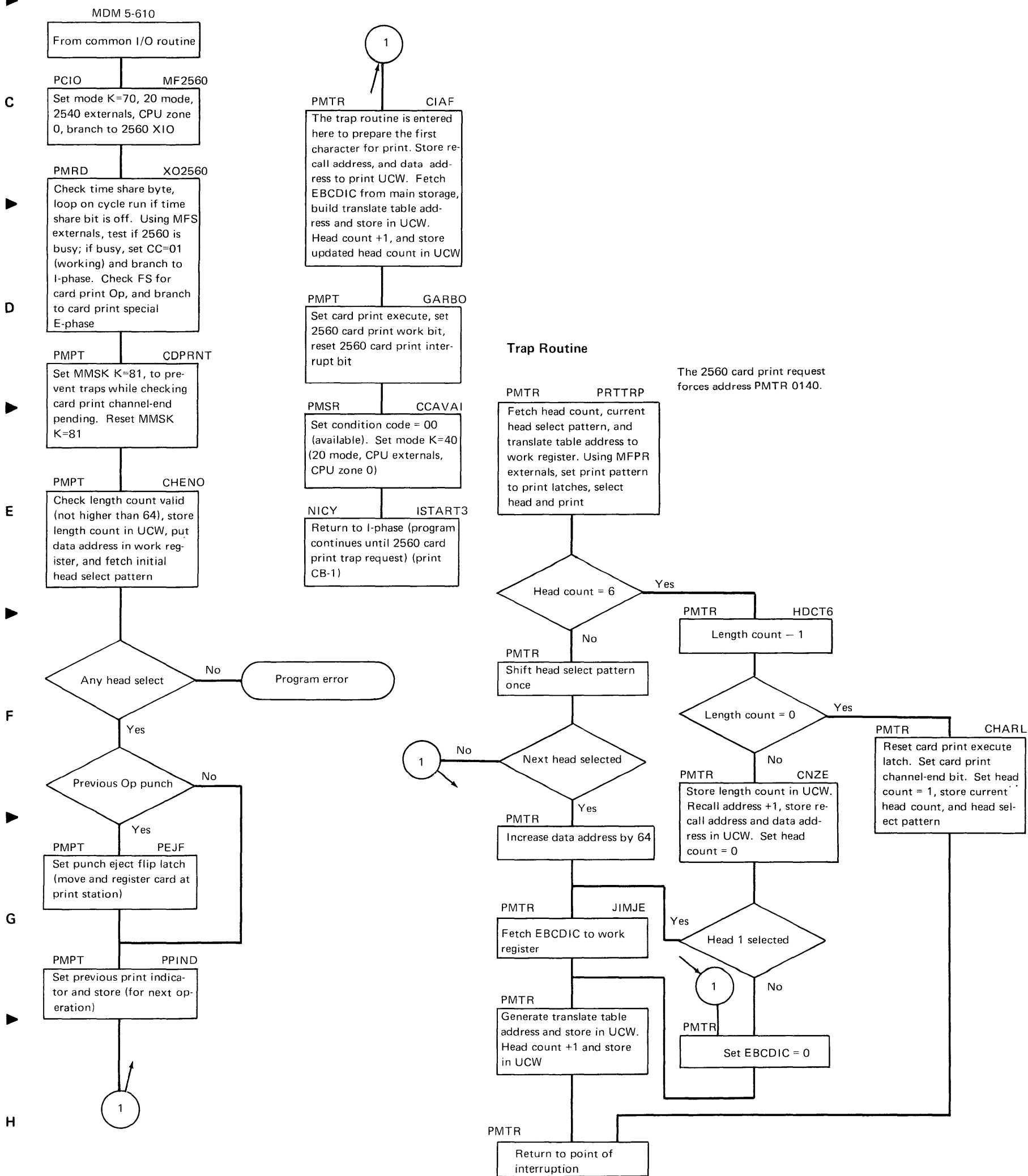
D0: XIO instruction (data transfer)
2: Device Address (2560)
0: Function Specification (write a card)
B1D1: Data Address
B2D2: Data Length Count

Conditions:

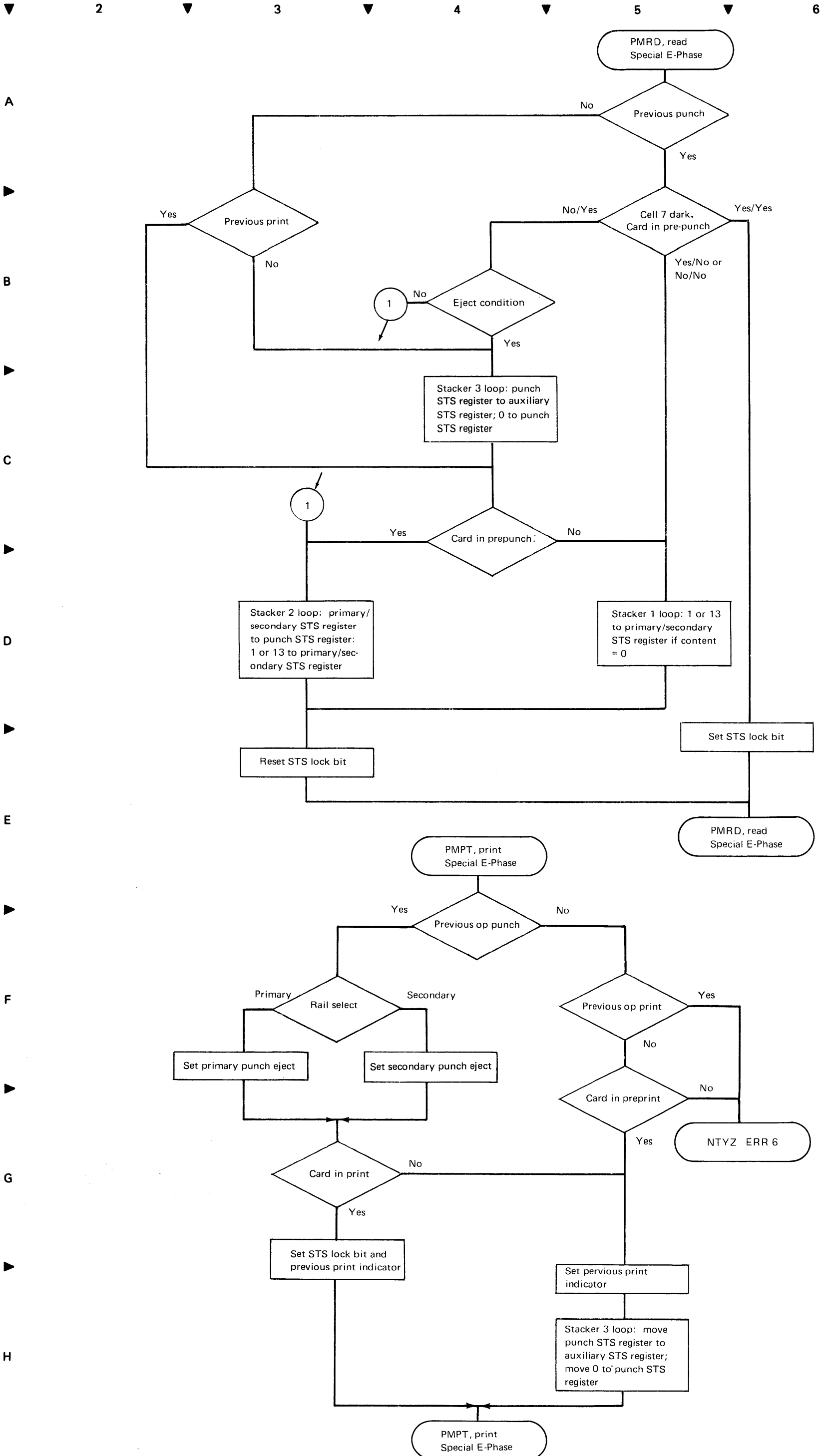
1. No other I/O device is working.
2. No errors, and this instruction follows a punch and stop operation in the program. (card is sitting in punch station).
3. A CIO instruction preceded the write a card XIO (to select a head).
4. Not last card.

Objectives:

1. Write a card from the 2560 card print station.
2. Transfer and print the number of characters specified by the B2D2 field.
3. Transfer these characters to the print magnet unit, starting at the address specified by the B1D1 field.



● Diagram 5-655. 2560 Print Operation Chart



● Diagram 5-657. 2560 Read, and Print Stacker Select Operations, In Special E-Phase

2

3

4

5

6

A

B

C

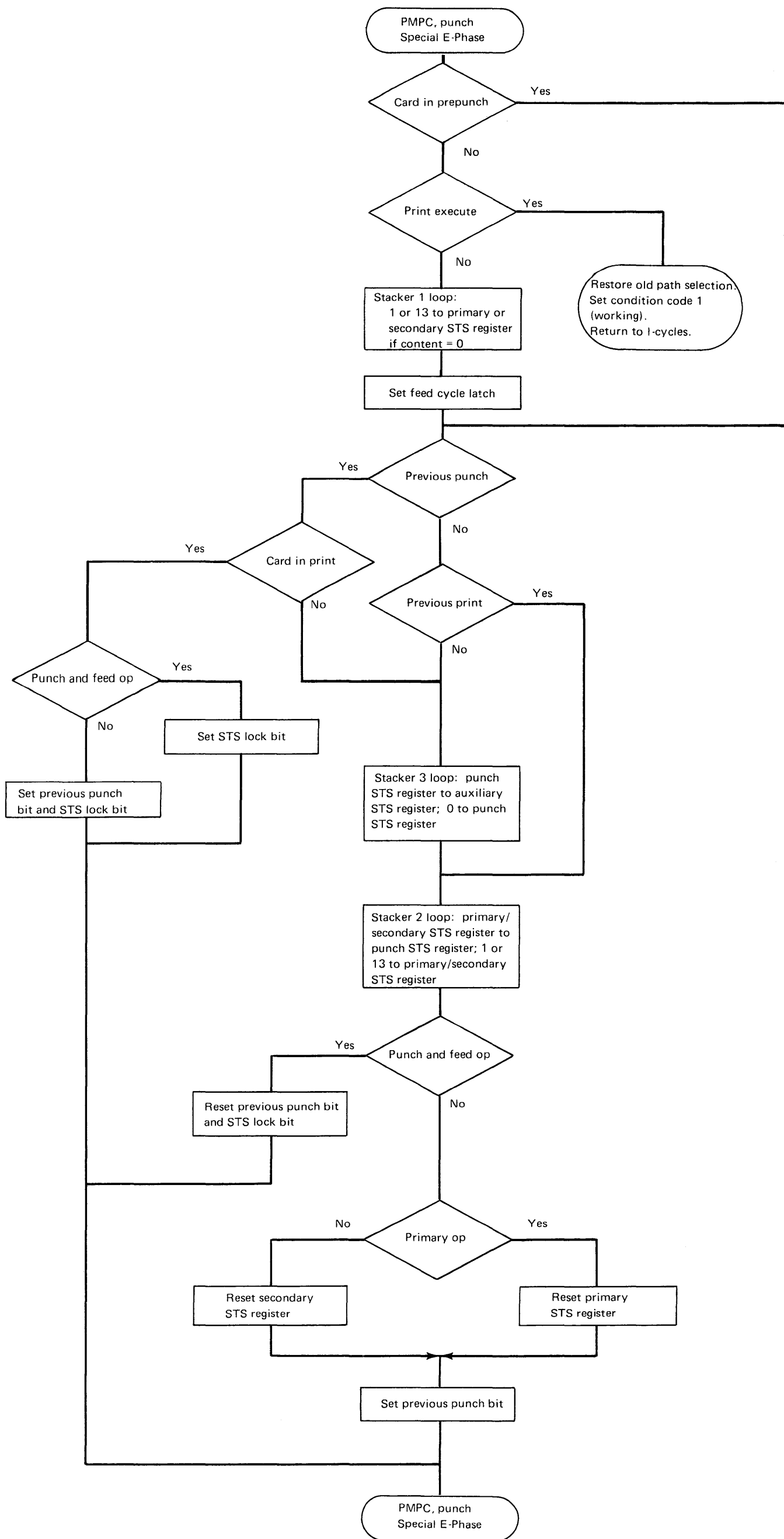
D

E

F

G

H



● Diagram 5-659. 2560 Punch Stacker Select Operation, in Special E-Phase

A

B

C

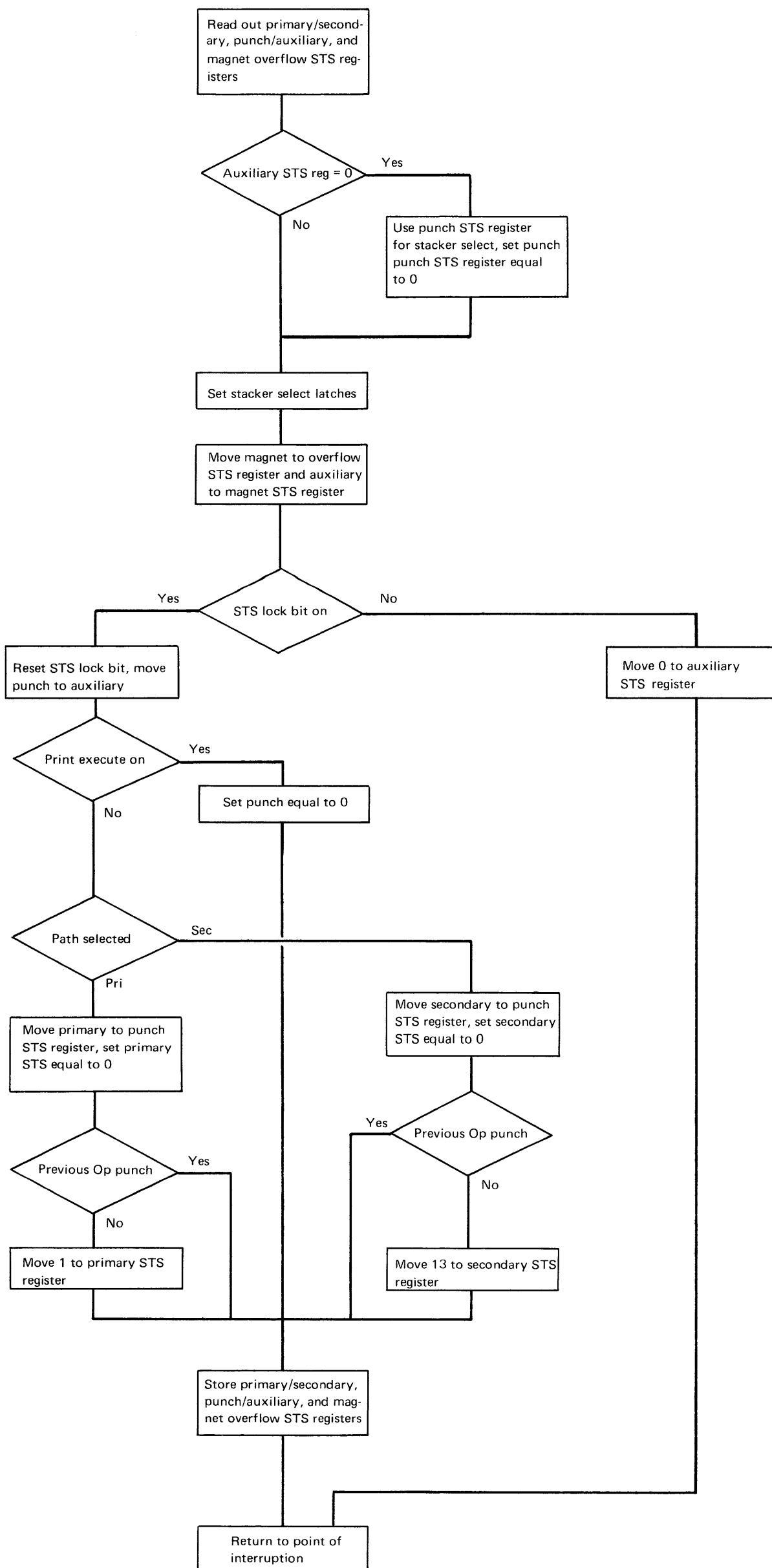
D

E

F

G

H



●Diagram 5-661. 2560 STS Trap Routine Chart

2

3

4

5

6

A

B

C

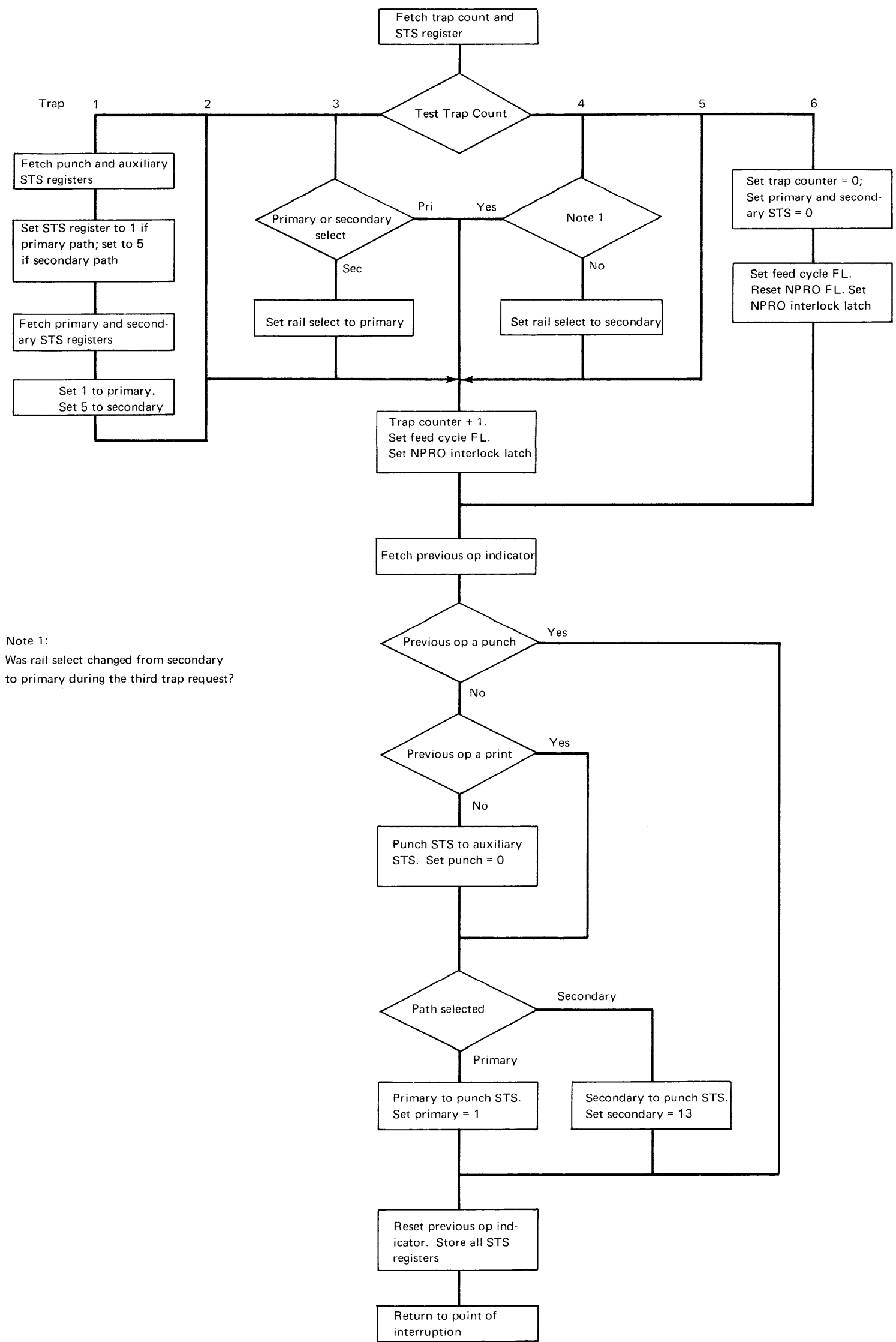
D

E

F

G

H



Note 1:
Was rail select changed from secondary to primary during the third trap request?

Instruction: Start I/O (9C)

Command: Read and feed, Select Stacker

A

Conditions:

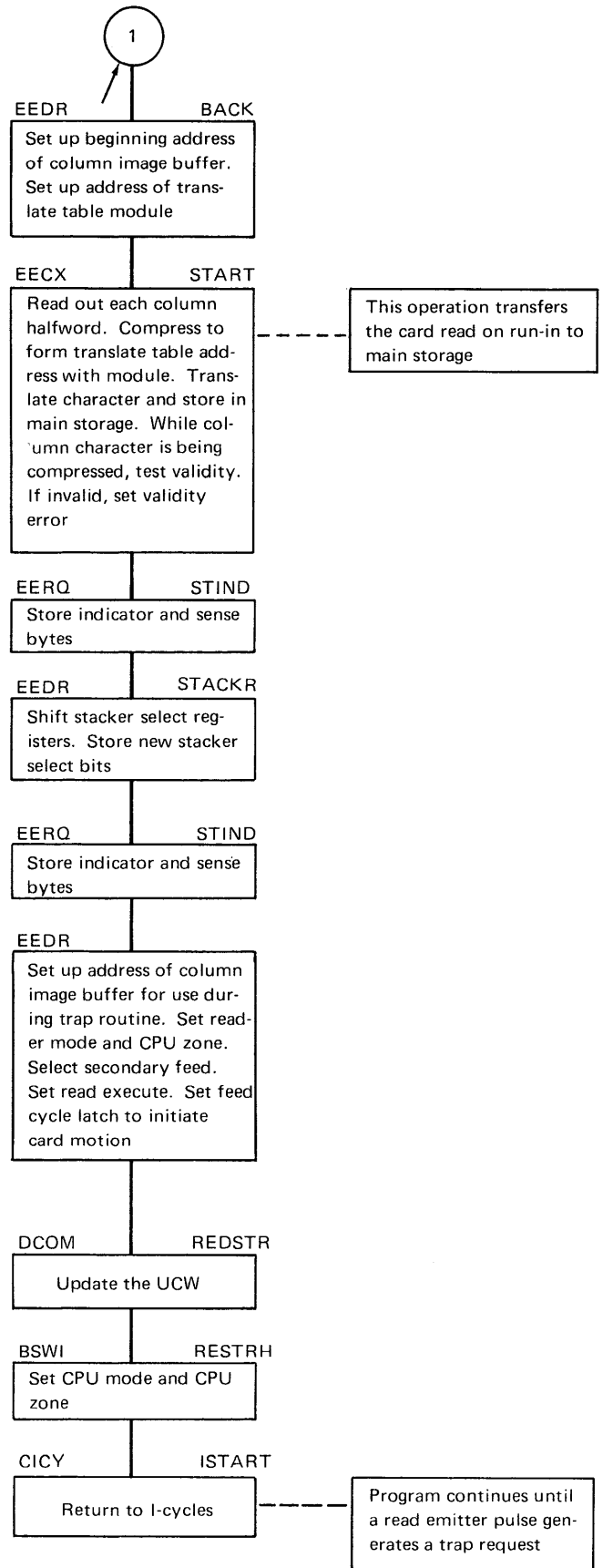
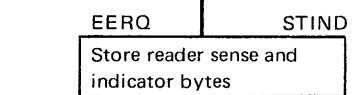
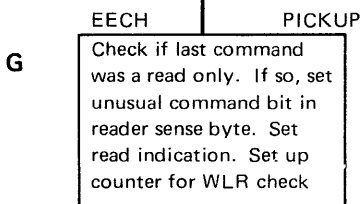
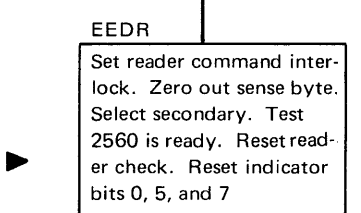
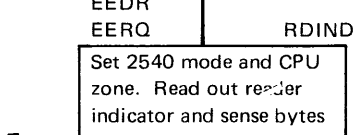
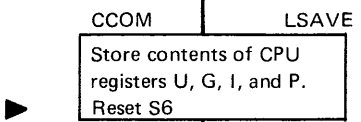
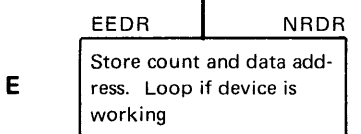
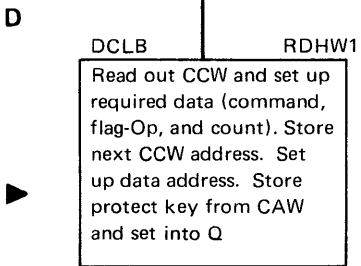
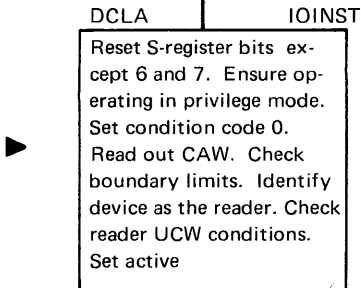
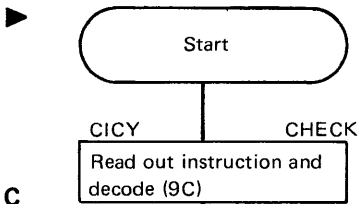
1. First command after run-in.
2. Status bytes and flag byte clear.
3. Card read on run-in is in the column image buffer.

B

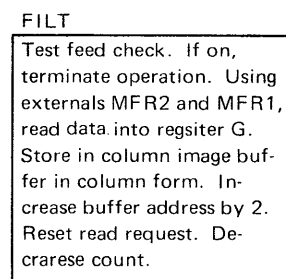
Objectives:

1. Emulate the 2540 read, feed, and stacker select command using the 2560.
2. Set up reader UCW.
3. Set up for read and feed command.
4. Translate the card read on run-in and store in main storage.
5. Check validity of each character.
6. Set up 2560 for secondary feed and stacker select.
7. Start card feed and set read execute.
8. Store the card being read (in binary) in the column image buffer. This requires 80 read trap requests.
9. Set reader check if one occurs.
10. Set reader device-end.

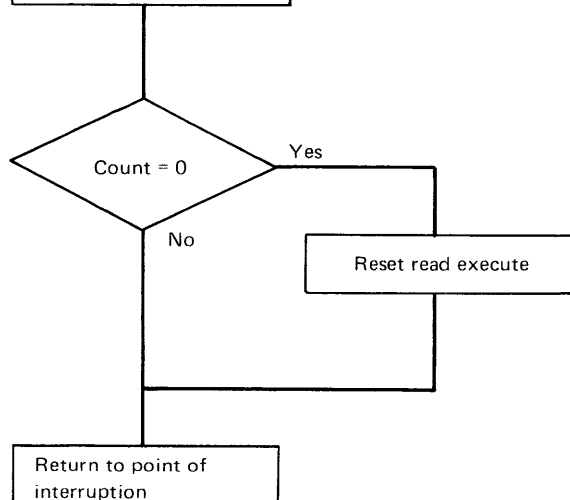
C



Read Trap Routine



The 2560 read trap request forces address FILT 0140.



● Diagram 5-671. Read, Feed, and Stacker Select in 2560 Emulating the 2540

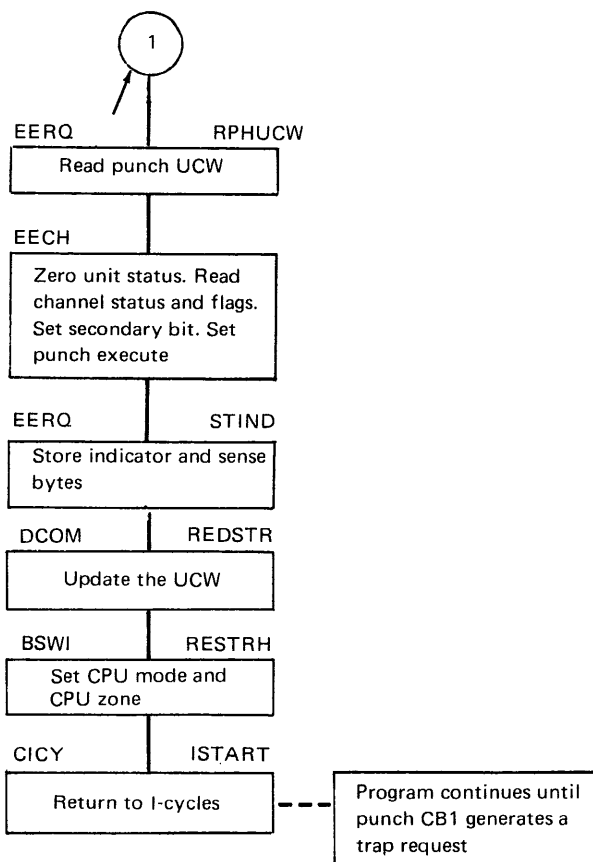
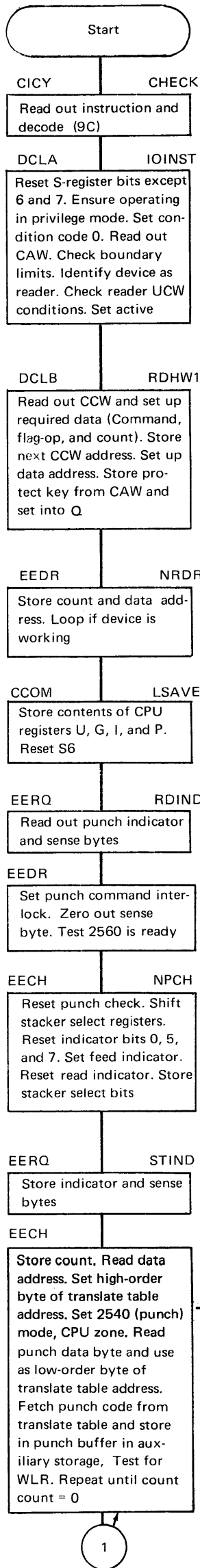
Instruction: Start I/O (9C)

Command: PFR Write, Feed, and Stacker Select

- Conditions:
1. Command follows a PFR read command.
 2. Status bytes and flag byte clear.
 3. Cards are run-in and 2560 is ready.

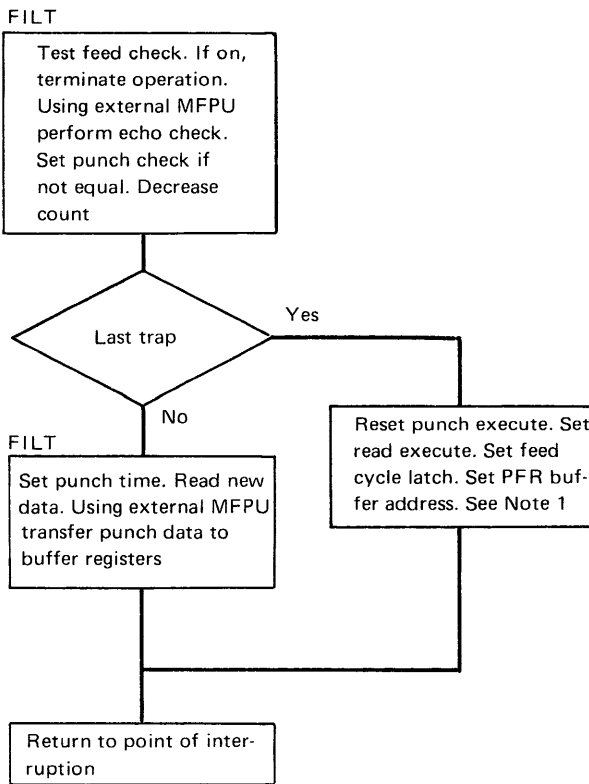
- Objectives:
1. Emulate the 2540 PFR write, feed, and stacker select command using the 2560.
 2. Transfer and translate to punch code, the punch data from main storage to the punch buffer in auxiliary storage.
 3. Transfer the punch code to the 2560 for punching.
 4. Set punch check if one occurs. This will be presented with device-end of the next punch command.
 5. Initiate a read cycle when punching is completed.
 6. Transfer the data being read to the PFR buffer.
 7. Set PFR read check if one occurs.
 8. Set punch device-end.

B



Punch Trap Routine

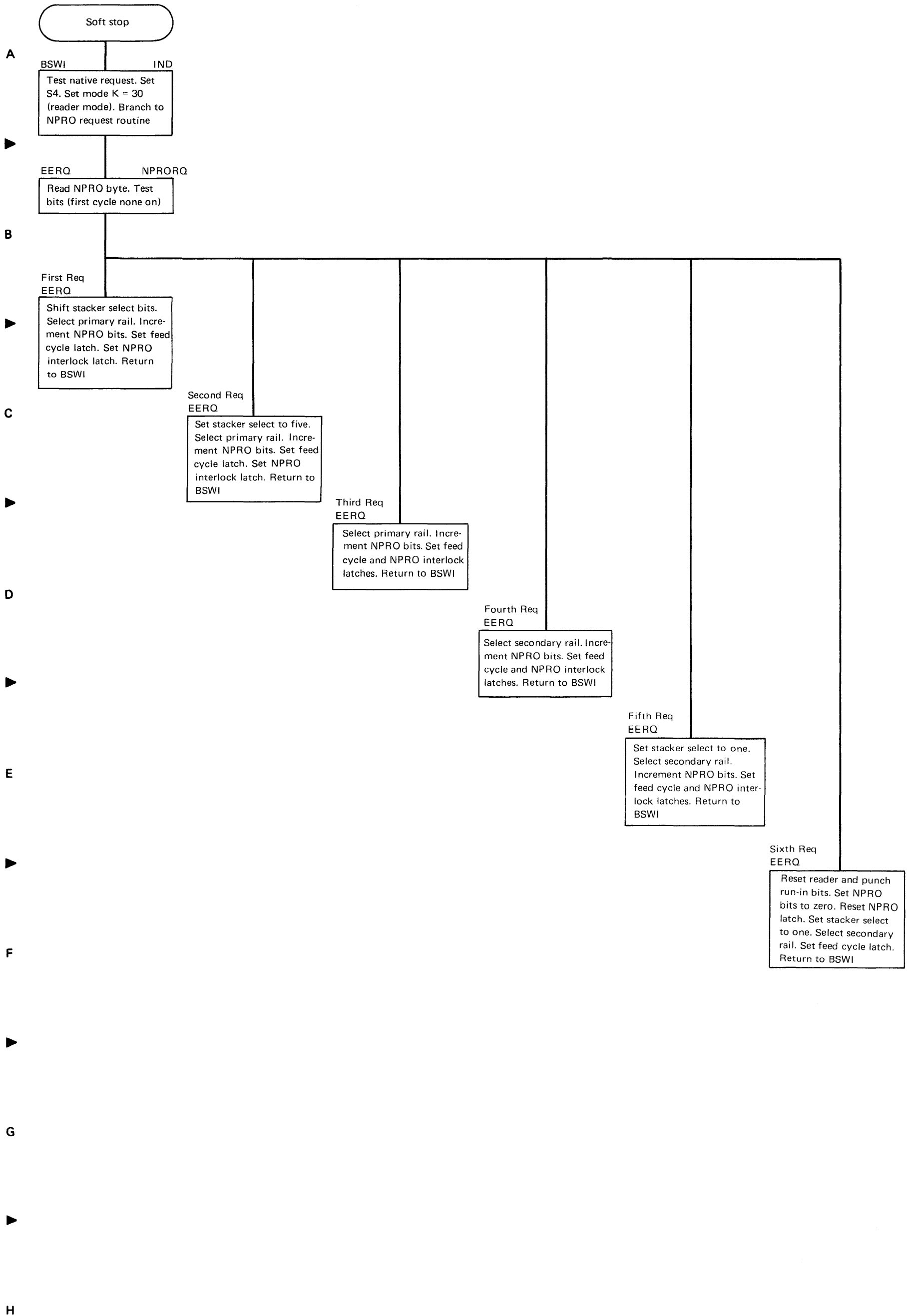
The 2560 punch trap request forces address FILT 0140.



Note 1: The read execute, feed cycle latch, and PFR buffer address are set to cause PFR reading of the card passing the read station. Eighty read traps occur during the resulting feed cycle. This completes the operation.

●Diagram 5-673. Write, Feed, and Stacker Select in 2560 Emulating the 2540

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6



● Diagram 5-675. NPRO 2560 Emulating 2540

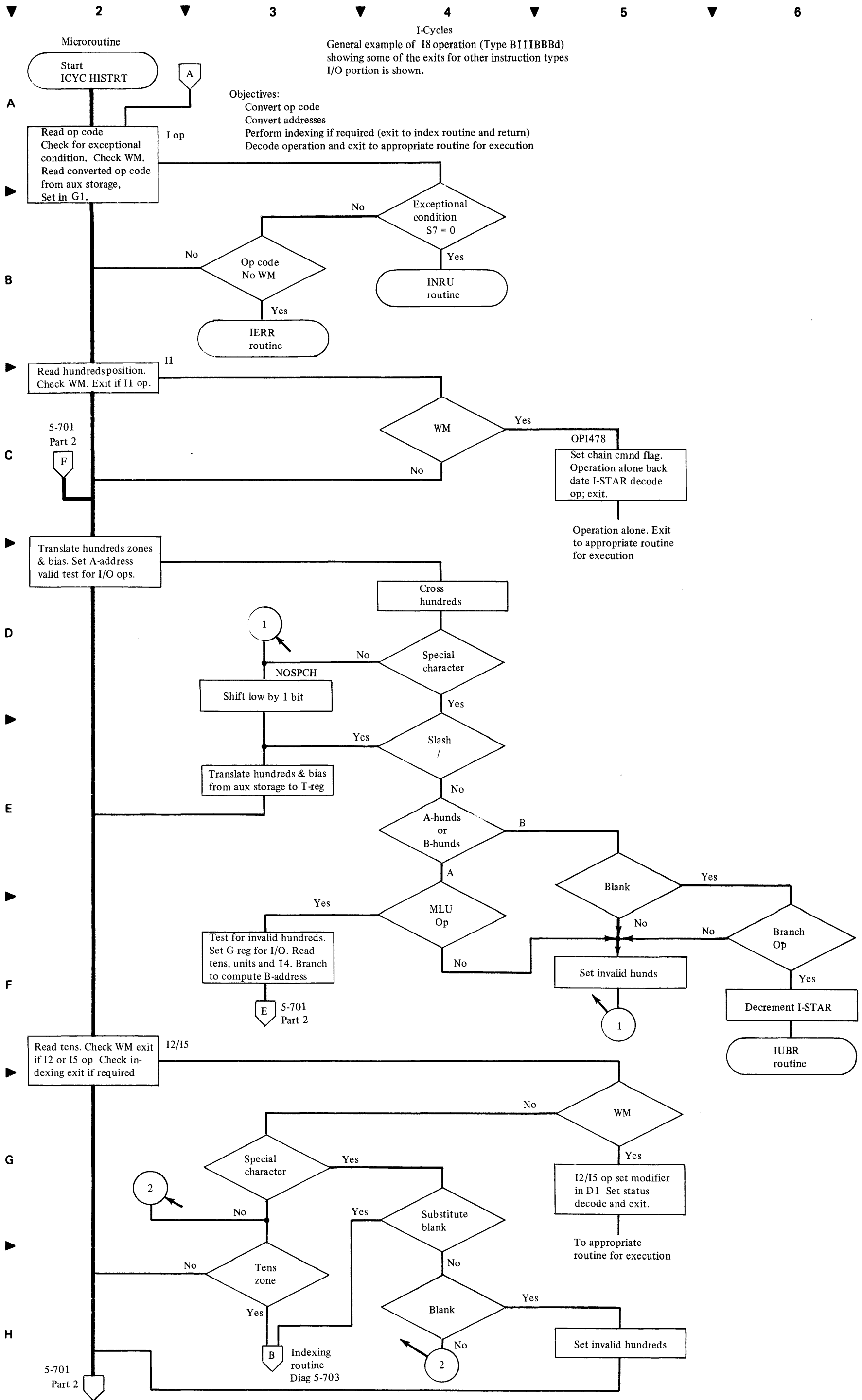


Diagram 5-701. 1400 Compatibility, I-Cycles (Part 1 of 2)

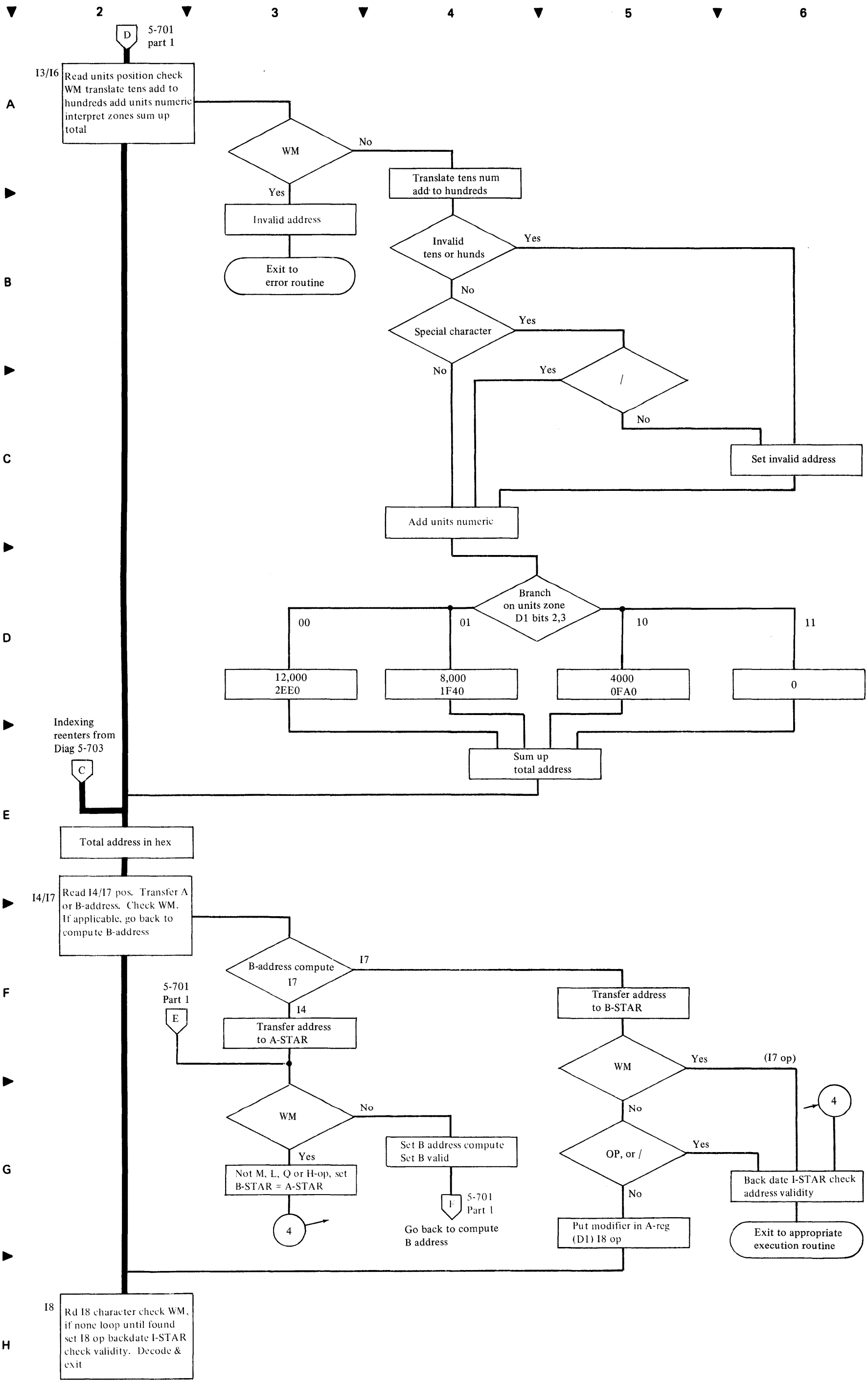
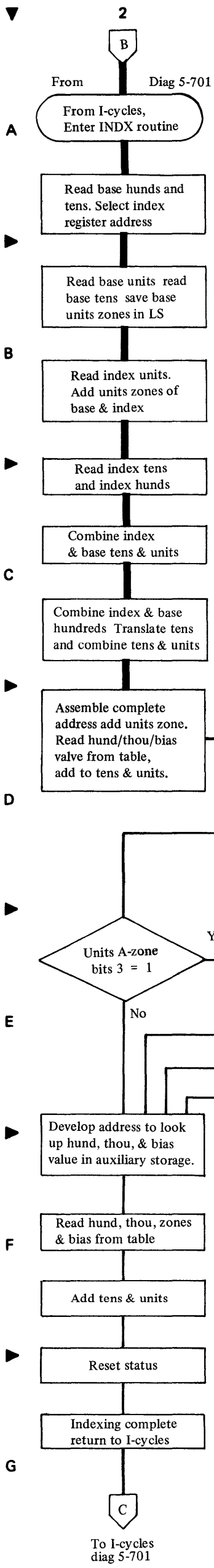


Diagram 5-701. 1400 Compatibility, I-Cycles (Part 2 of 2)

Indexing Routine

Objectives:

- Select an index register
- Generate an address consisting of the total of base address, index register and the bias.
- Return to I-cycles, read remainder of instruction. Either A- or B-address or both may be indexed.



Example values

Base hundreds = 500
 Base tens = 20
 Zones BA = 2030
 Address

Base units = 5
 Base tens = 20
 Units zones = A = 10

Index units = 4
 Zones = A = 10

Index tens = 20
 Index hundreds = 100

Total tens = 20
 & units = 4
 20
 49

Index hund = 100
 Base hundreds = 500
 600

Tens = $40_{10} = 28_{16}$
 U = $9_{10} = 9_{16}$
 Total = $49_{10} = 31_{16}$

Indexing example.
 Develop address from base address 5BV and index value A24

Summary:

5 B V
 Units numeric =
 Units zones A = 10 =
 Tens numeric
 Tens zones = AB = index reg 2030
 Hundreds num =
 Hunds zones none.

Index register addresses

Tens position BCD zones	EBCDIC bits 2, 3	Aux storage address
None	11	None
A	10	2010
B	01	2020
BA	00	2030

Hundreds zones values

1400 BA	BCD	EBCDIC	Decimal value
BA	11	00	3000
B	10	01	200
A	01	10	1000
None	00	11	

Units zones values

1400 BA	BCD	EBCDIC	Decimal value
BA	11	00	12,000
B	10	01	8,000
A	01	10	4,000
None	00	11	

8033₁₀
 or 1F6₁₆

Example (cont)

(Accumulate amounts in boxes)

Unit A-zone 0FA0

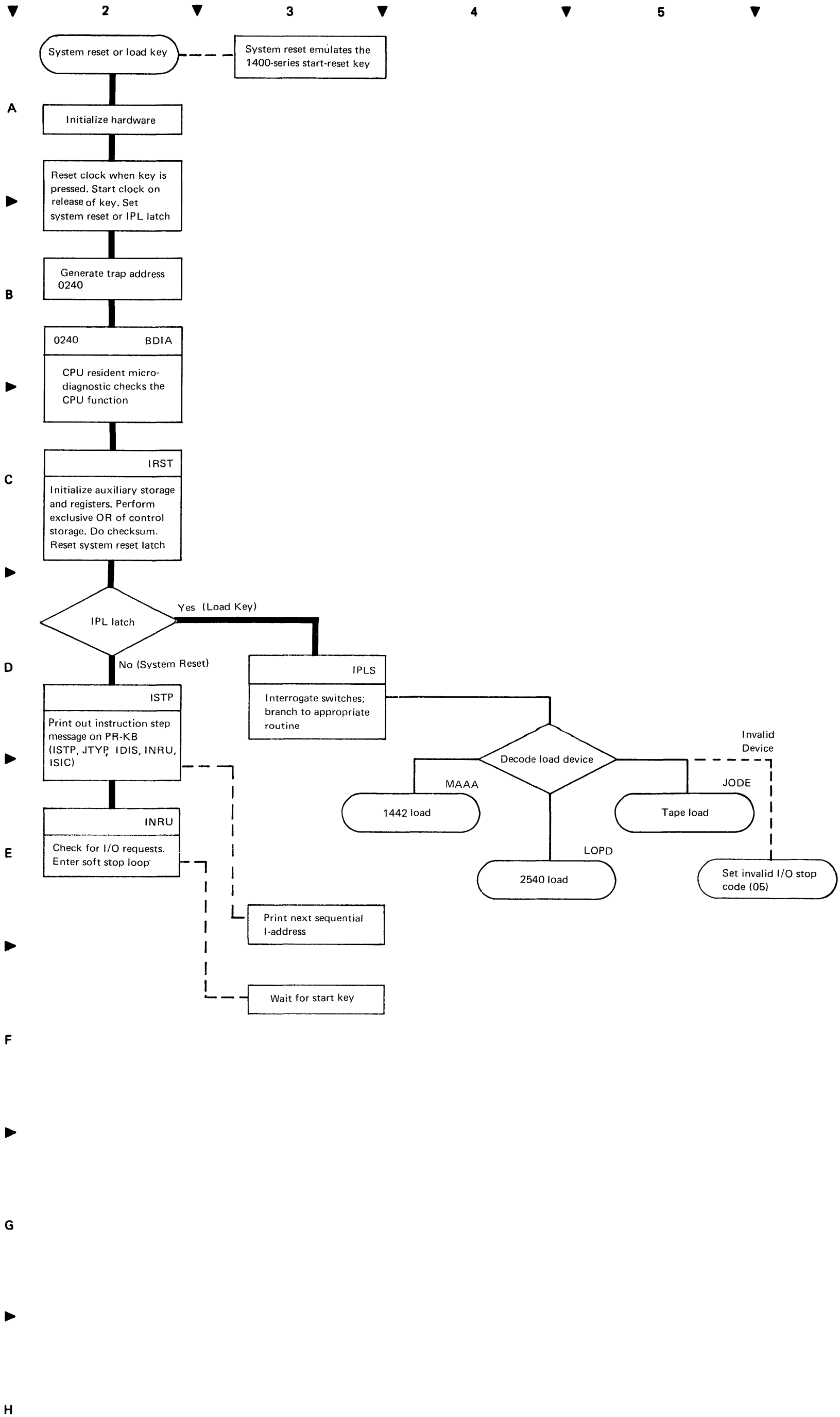
Table location 2078

From table (inc bias) 0F90

Units & tens 31

Total = 1F61
 (Decimal 8,033)

Diagram 5-703. 1400 Compatibility, Indexing



● Diagram 5-709. 1400 Compatibility-System Reset/IPL

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6

A

B

C

D

E

F

G

H

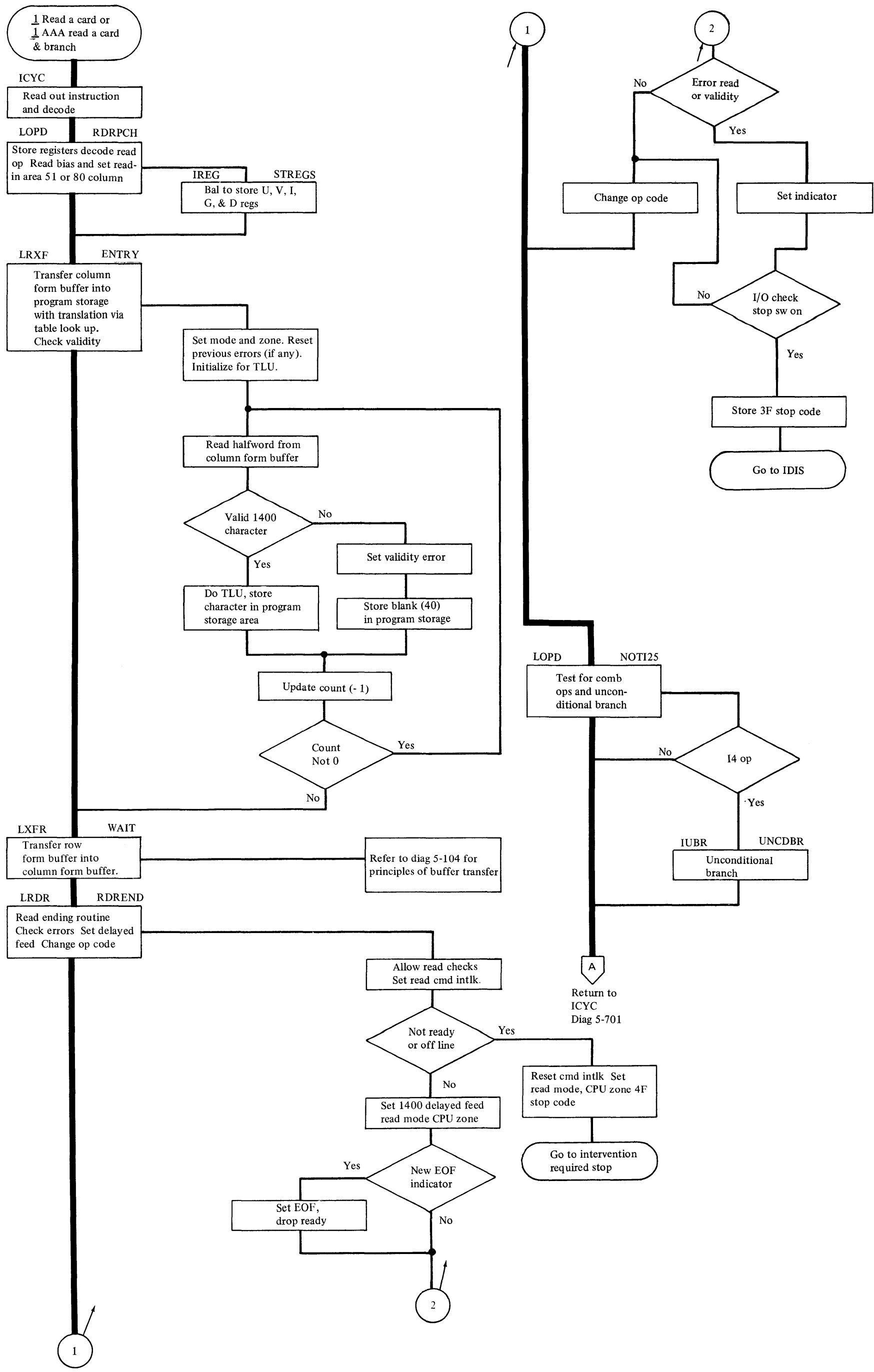


Diagram 5-713. 1400 Compatibility, 1402 Read

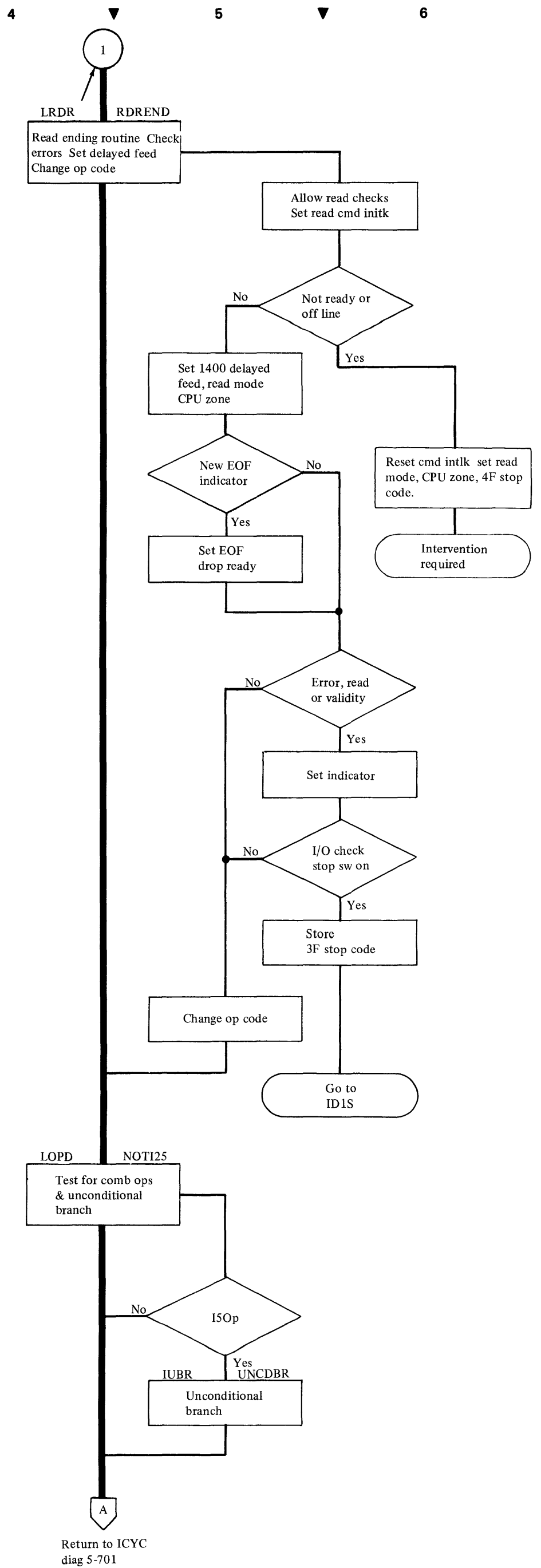
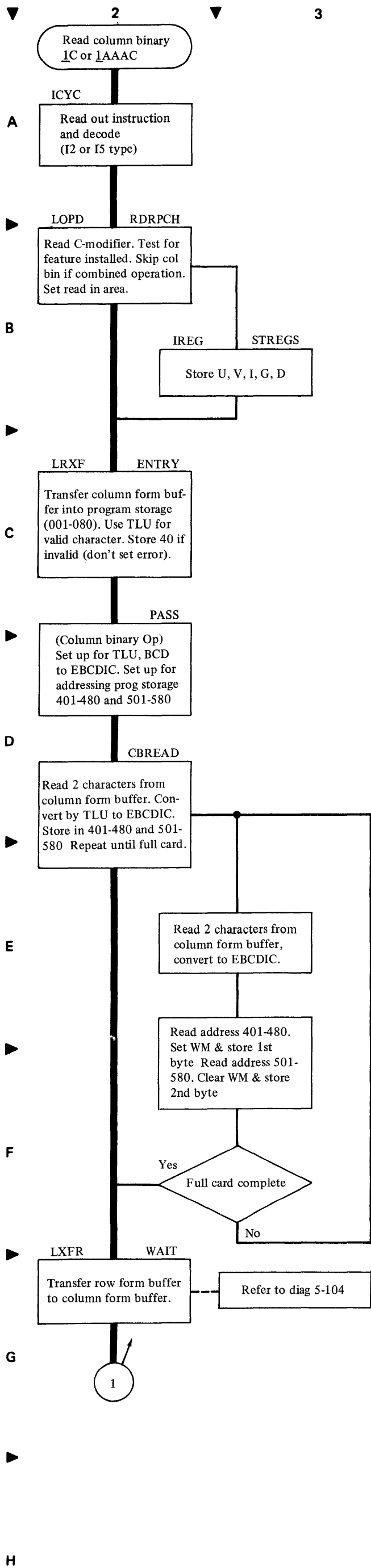


Diagram 5-715. 1400 Compatibility, 1402 Read Column Binary

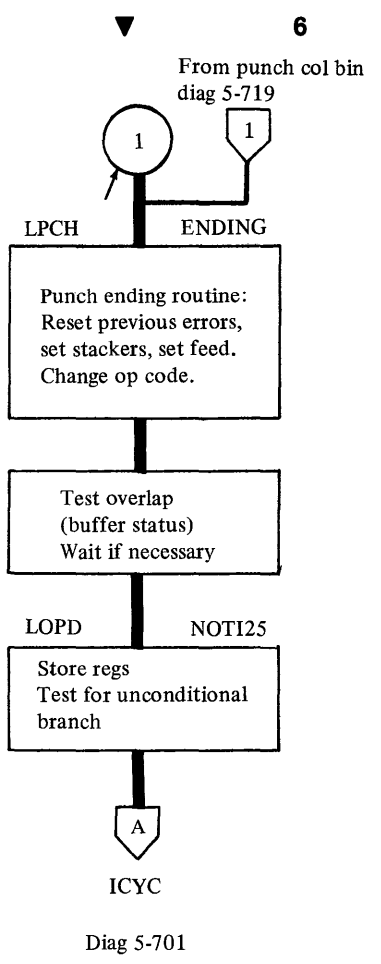
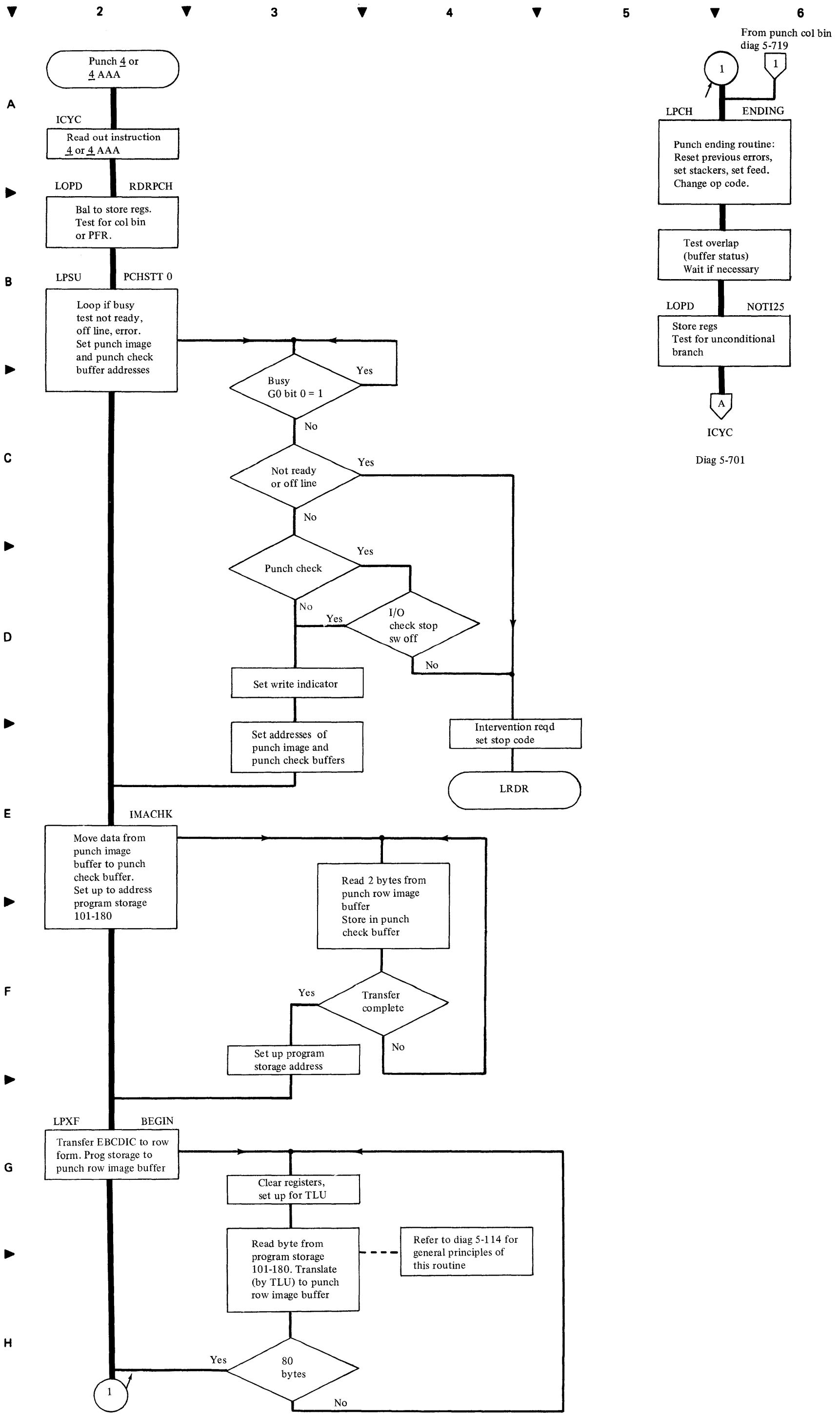


Diagram 5-717 1400 Compatibility, 1402 Punch

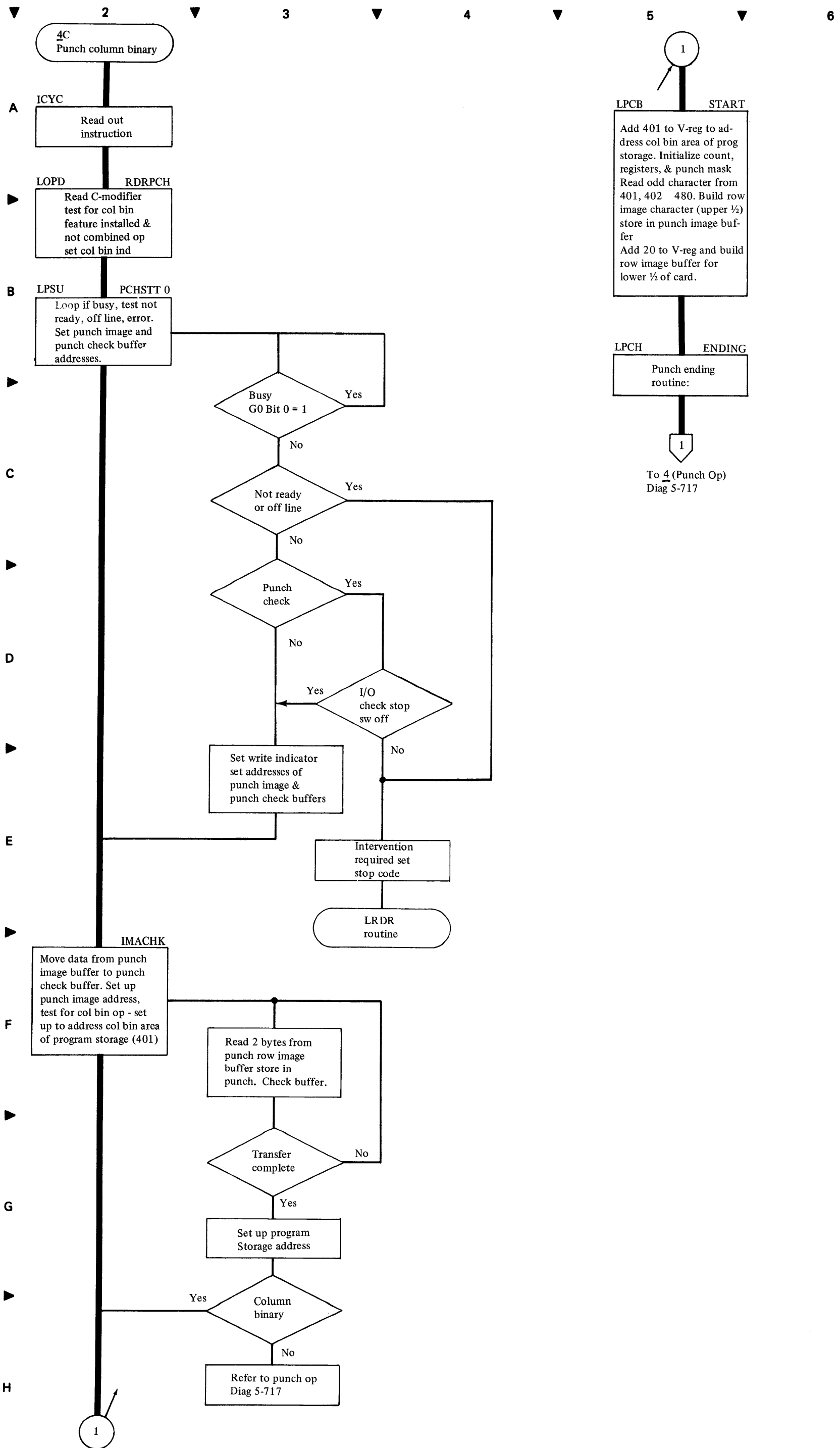
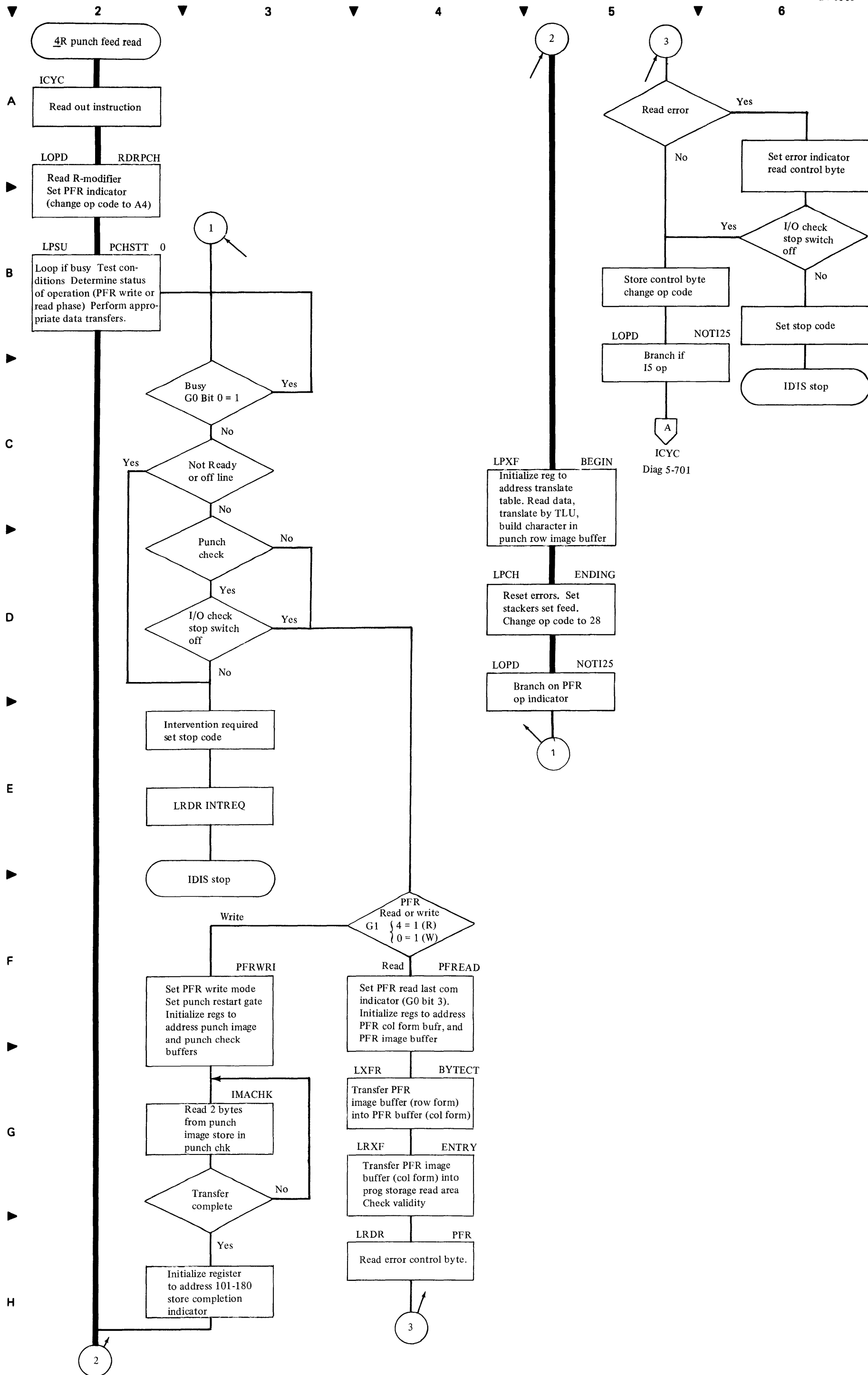
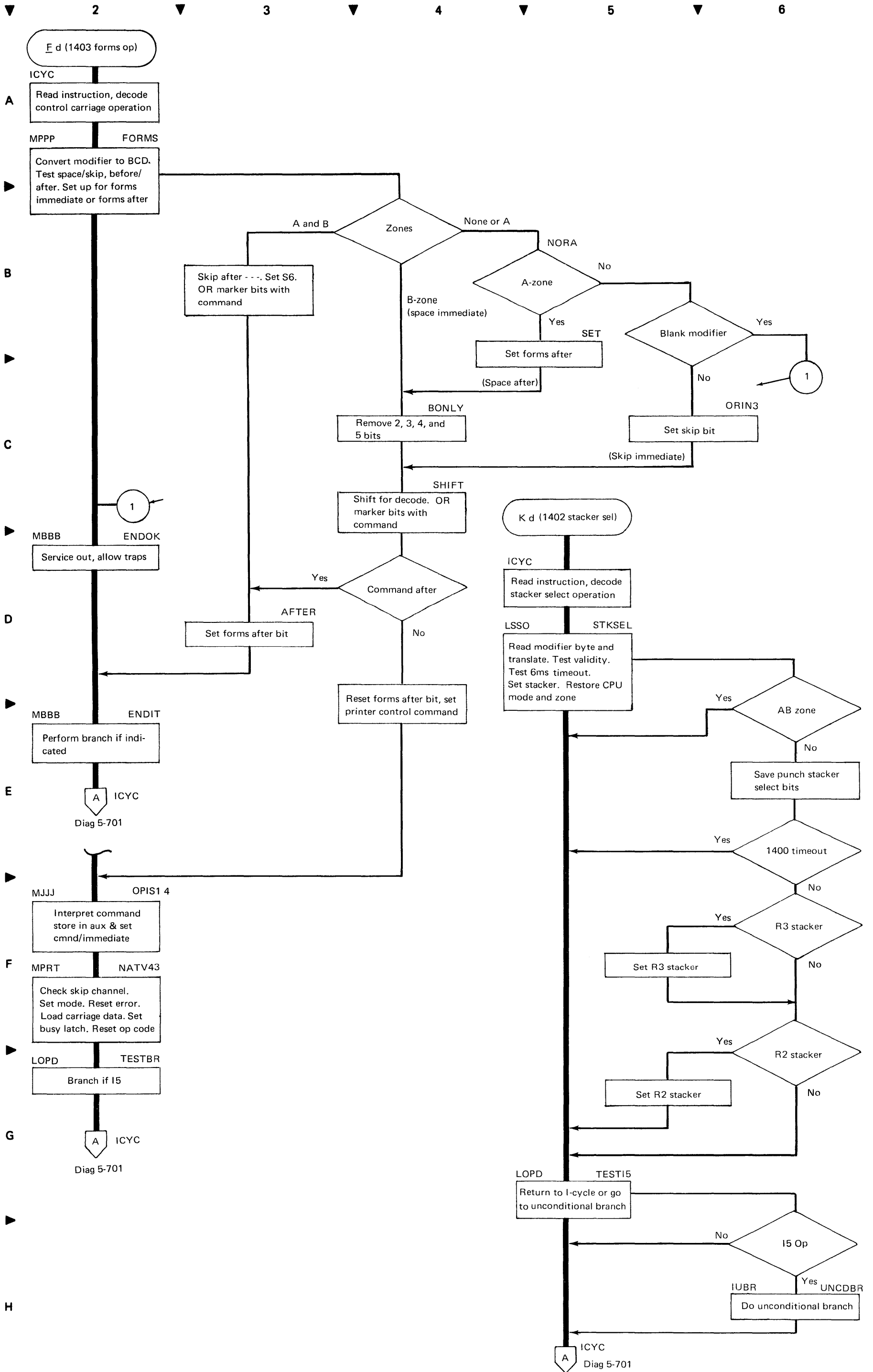


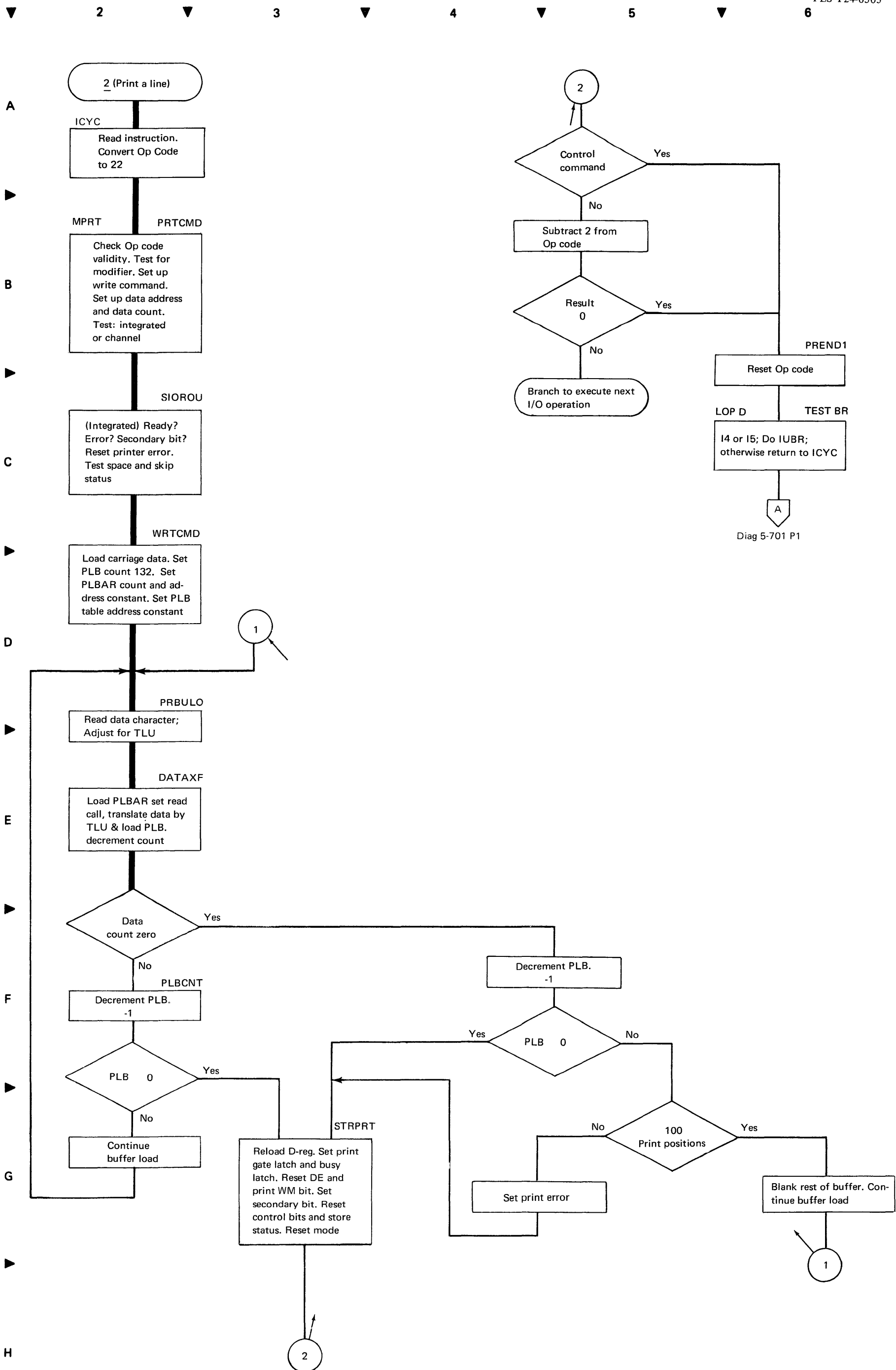
Diagram 5-719 1400 Compatibility, 1402 Punch Column Binary



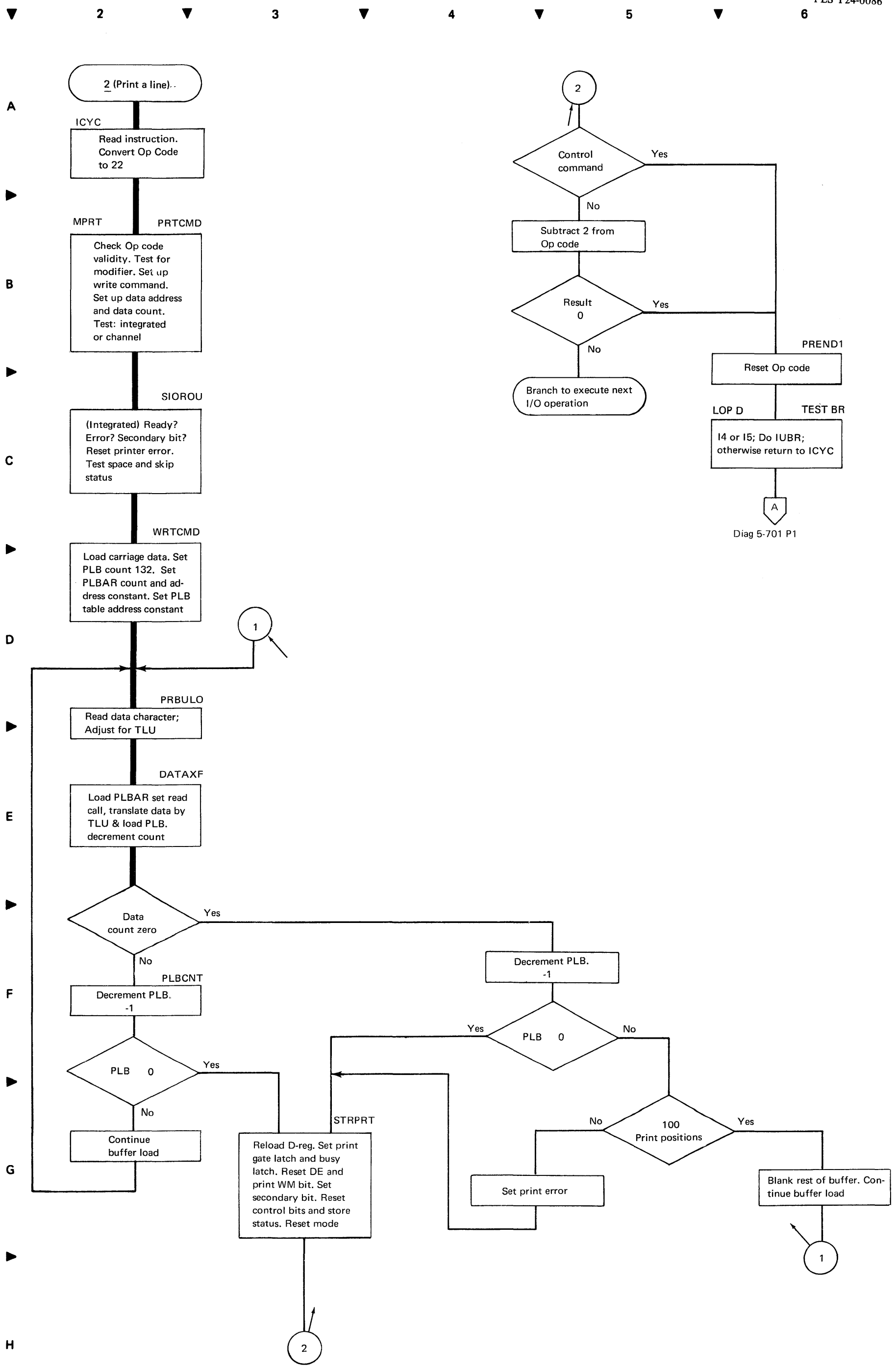
● Diagram 5-721 1400 Compatibility, 1402 Punch Feed Read



● Diagram 5-722. 1400 Compatibility-1403 Forms Op and 1442 Stacker Select Op



Diag 5-701 P1



Diag 5-701 P1

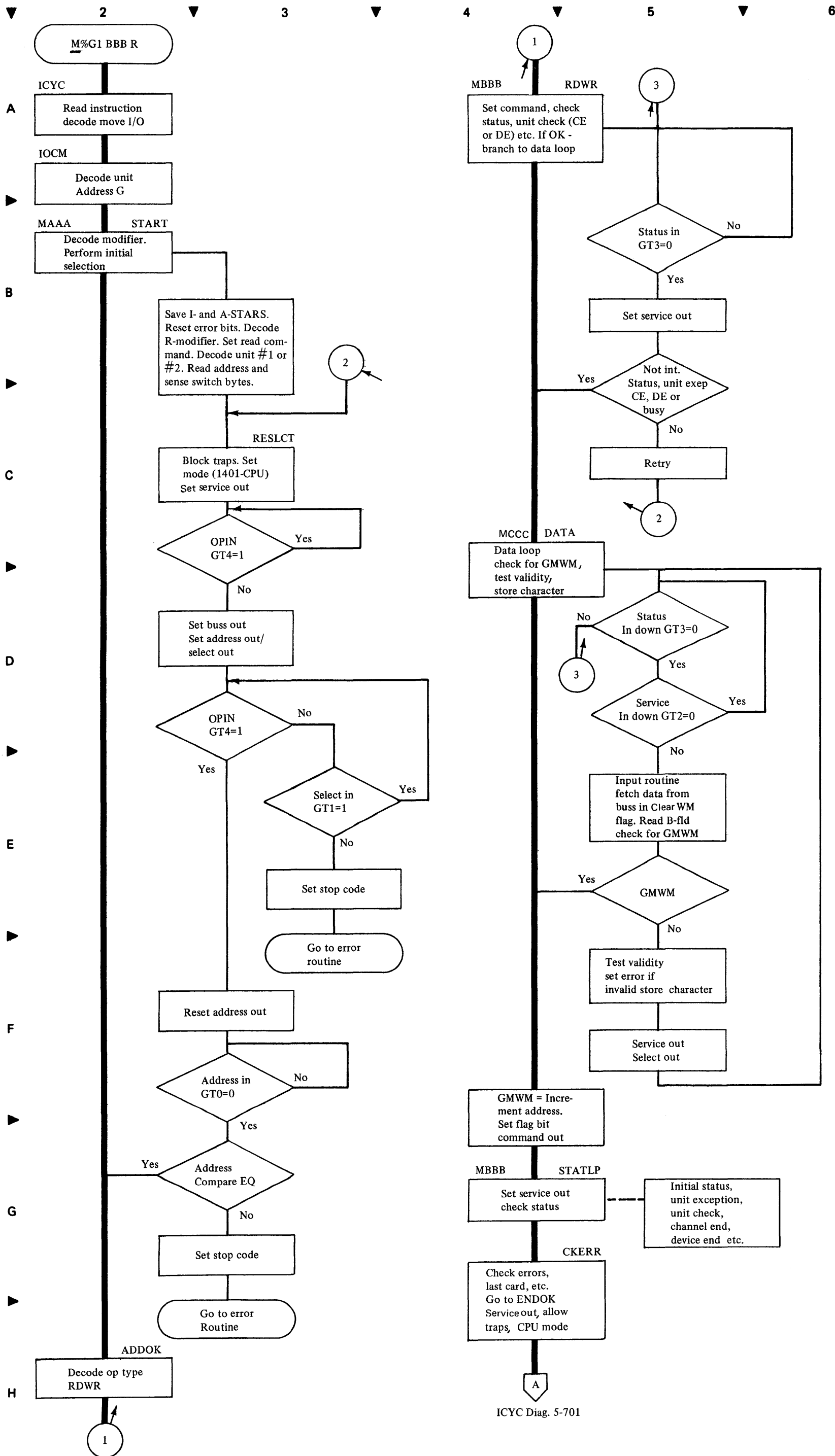
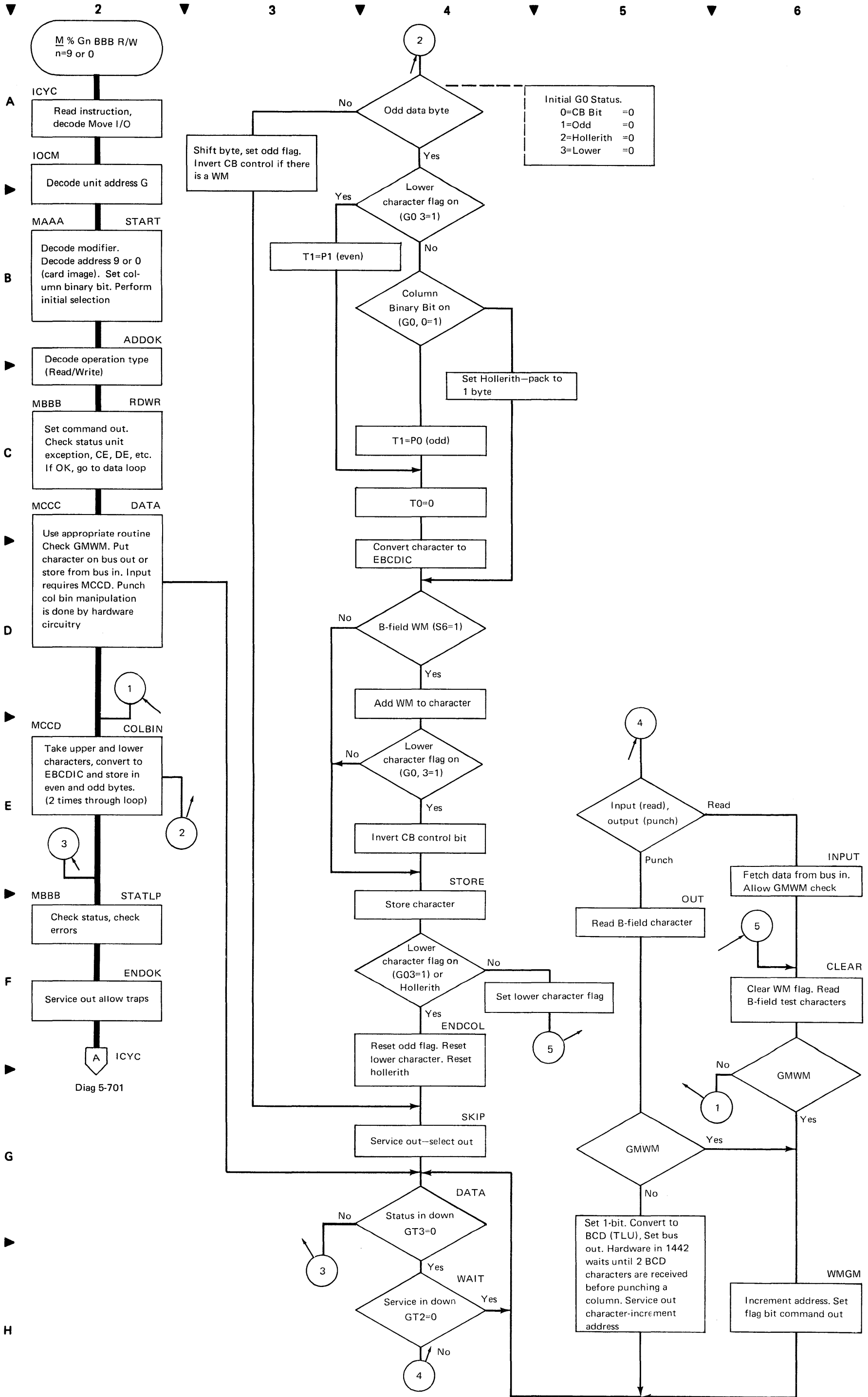
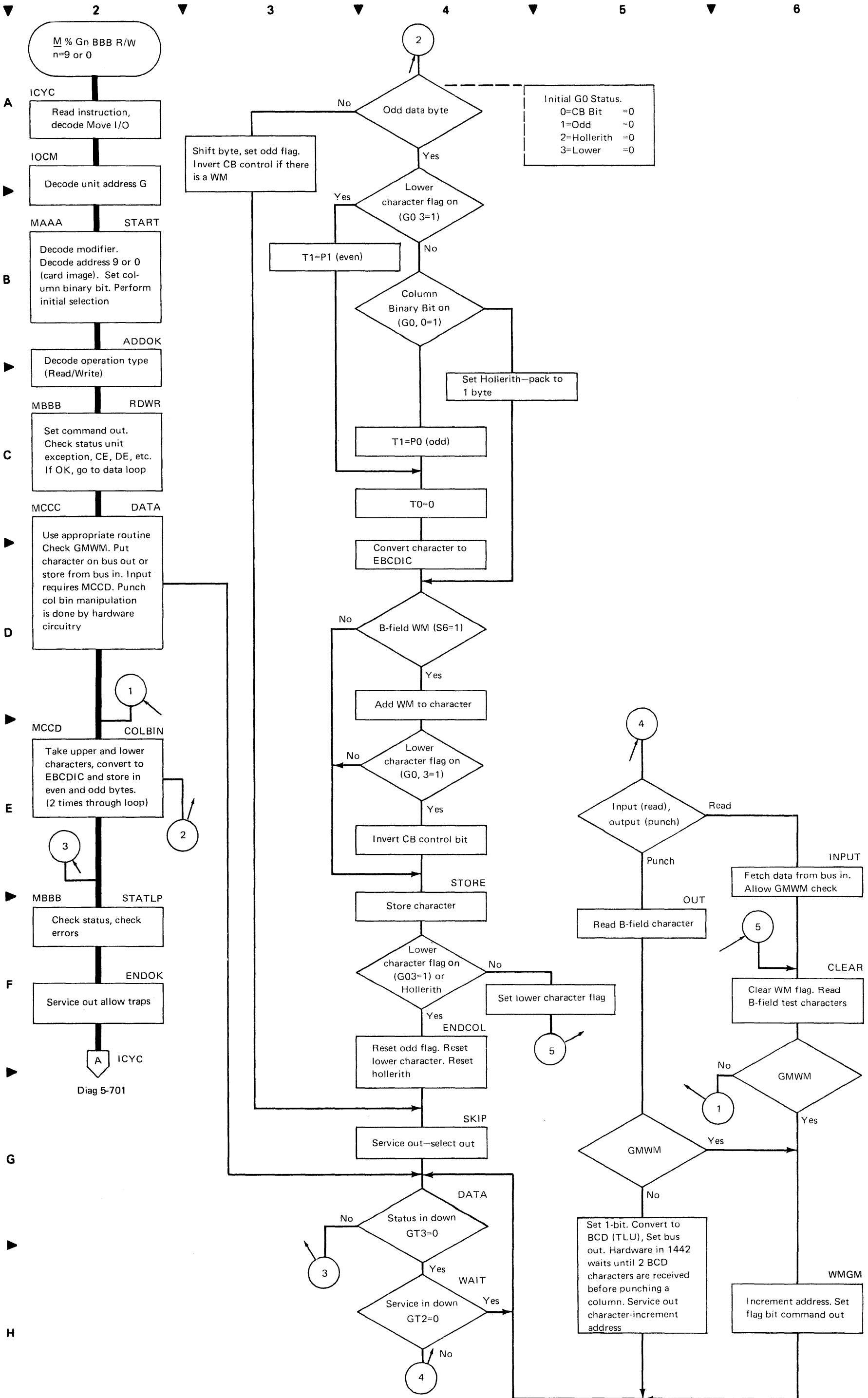


Diagram 5-725. 1400 Compatibility, 1442 Read



● Diagram 5-727. 1400 Compatibility-1442 Read/Punch Card Image



● Diagram 5-727. 1400 Compatibility-1442 Read/Punch Card Image

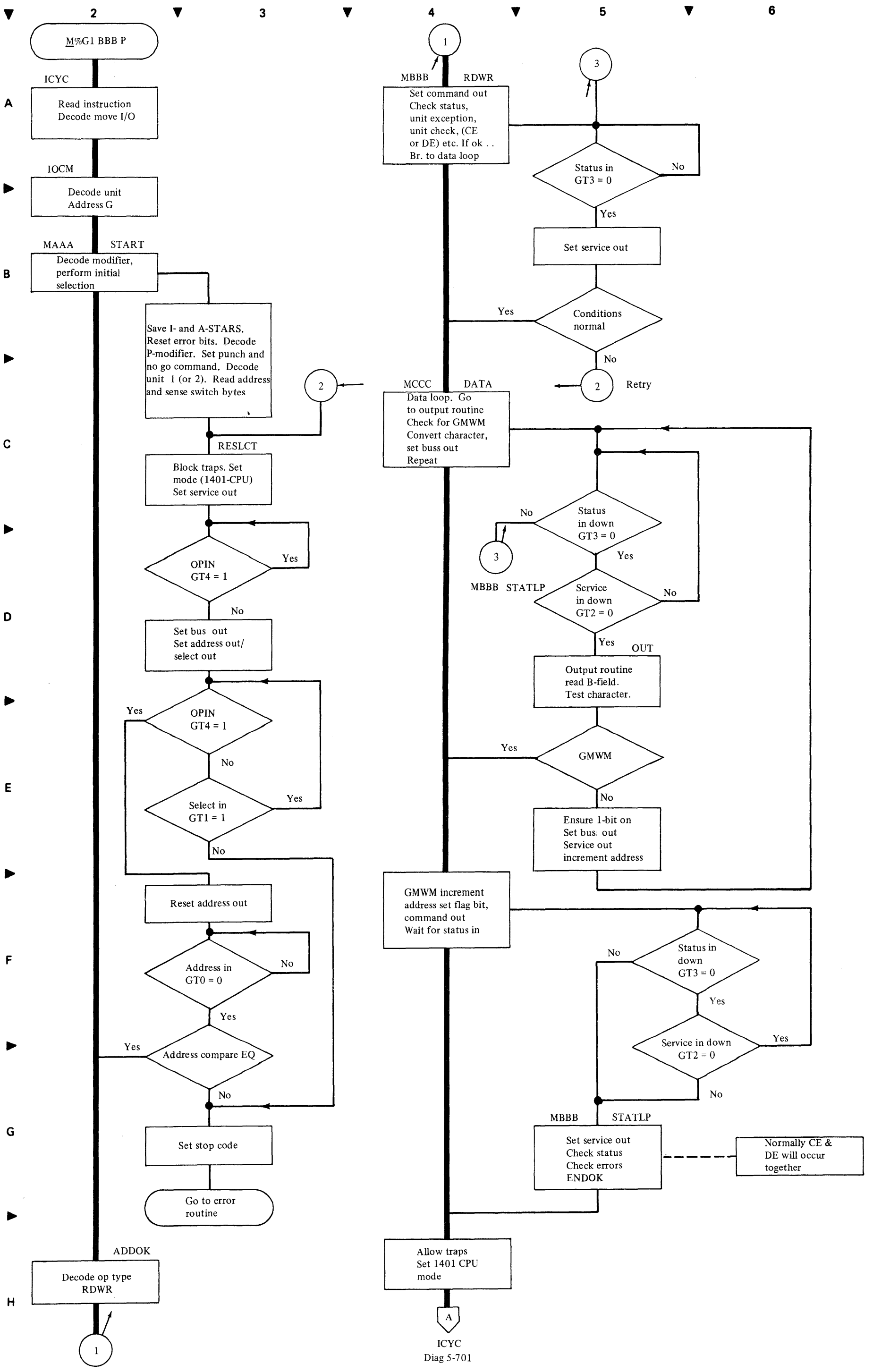
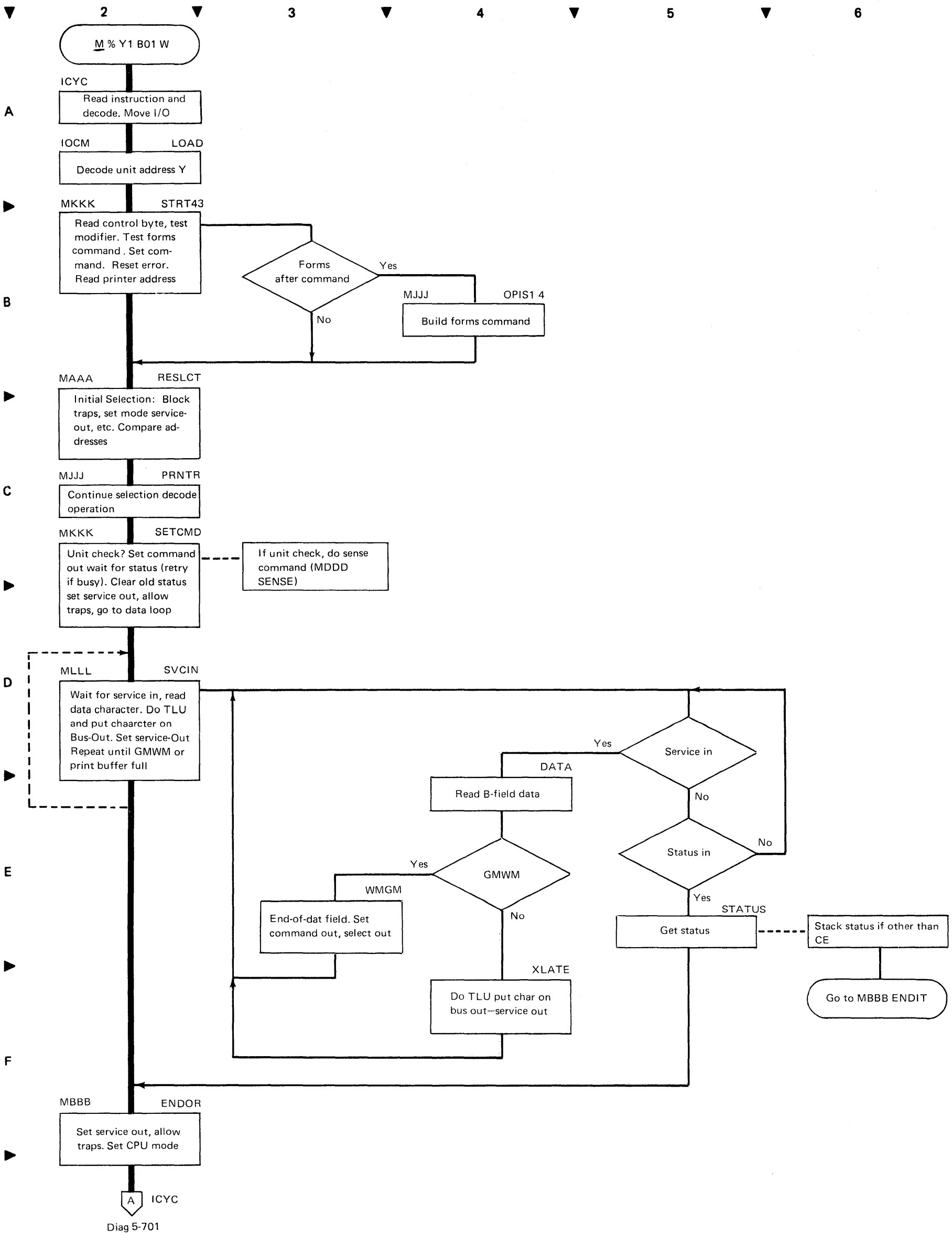


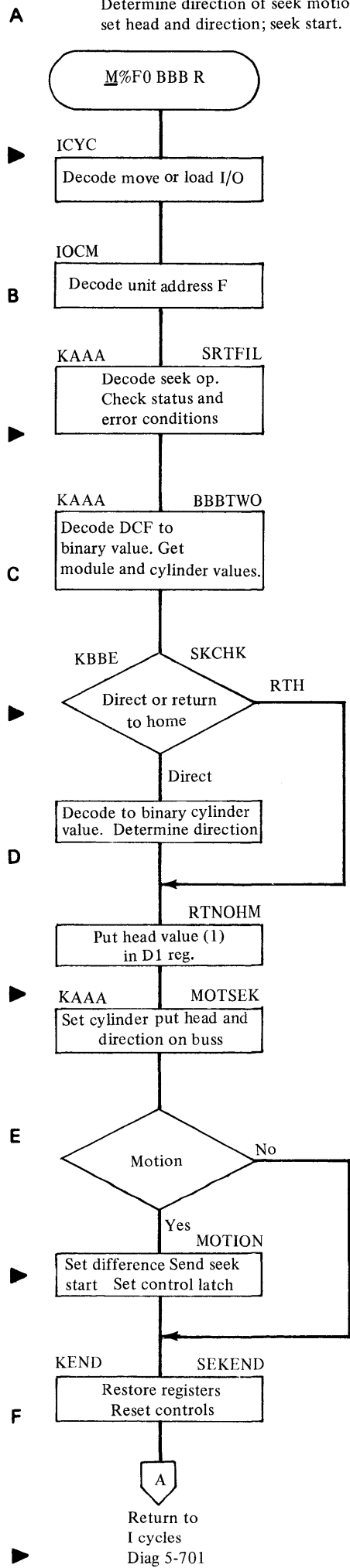
Diagram 5-729. 1400 Compatibility, 1442 Punch



● Diagram 5-733. 1400 Compatibility-1443 Print

Seek
Return to home & direct

Objectives:
Decode the disk control field for module and cylinder values
Determine direction of seek motion (if direct seek)
set head and direction; seek start.

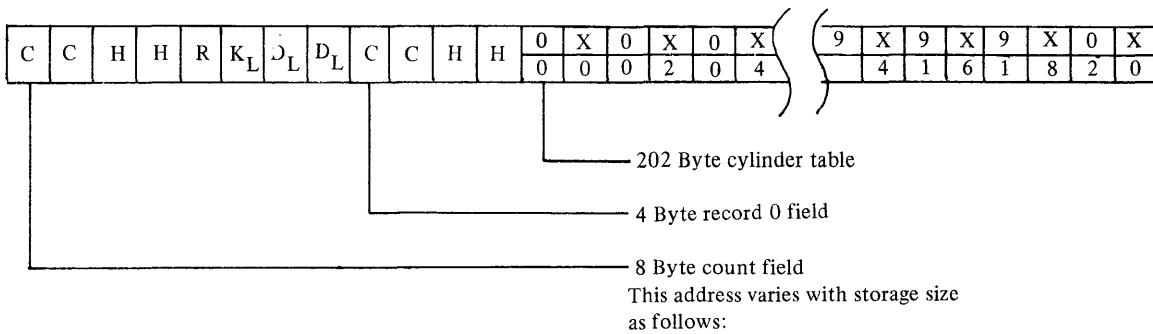


Miscellaneous disk file information
Auxiliary storage module 0

K0		K1		K2		K3		K4		K5		K6		K7	
88		8A		8C		8E	Work Area	98	Work Area	9A	Work Area	9C		9E	
89		8B		8D			Count Field Address		File Data Address	9B	Zone to zone transfer Present selected module	9D		9F	

K8		K9		KA		KB		KC		KD		KE		KF	
A8		AA		AC		AE	Previous file operation	B8		BA		BC	Work Area Present DCF mod value	BE	Work Area Word count 2982 100 move
		AB		AD			0 = RBC Inlk 1 = Recal seq 2 = X 3 = \ 4 = W 5 = Y 6 = V 7 = N	B9		BB		BD	Present cylinder value	BF	2982 90 Load

Program storage positions reserved for file tables

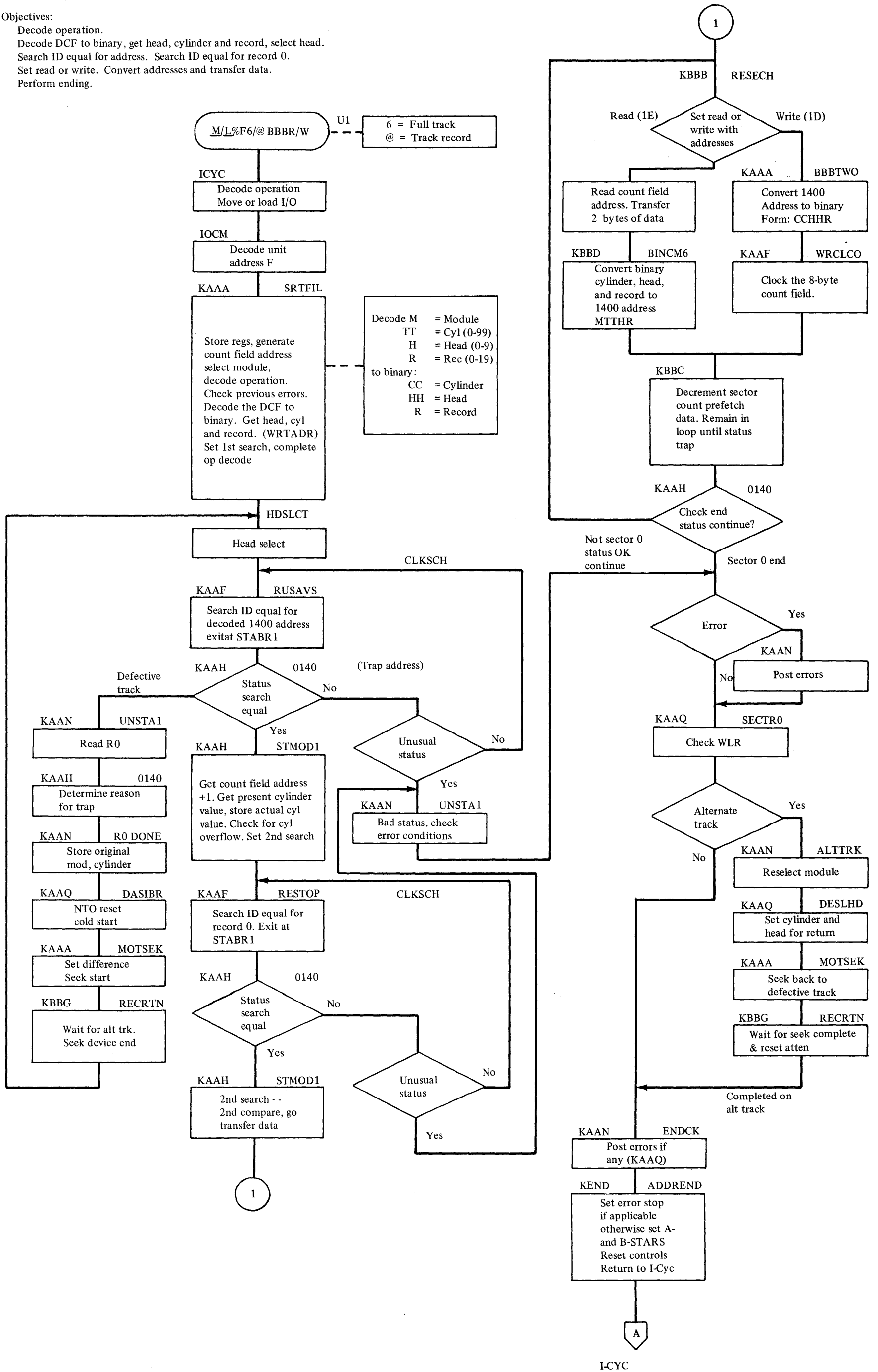


25	16,384	24,576	32,768	49,152
1400	0000	2000	4000	8000
16K	1000	3000	5000	9000
8K	1F00	3F00	5F00	9F00
4K	2F00	4F00	6F00	AF00
2K	3700	5700	7700	B700
1.4K	3900	5900	7900	B900

Objectives:

- Decode operation.
- Decode DCF to binary, get head, cylinder and record, select head.
- Search ID equal for address. Search ID equal for record 0.
- Set read or write. Convert addresses and transfer data.
- Perform ending.

A
B
C
D
E
F
G
H

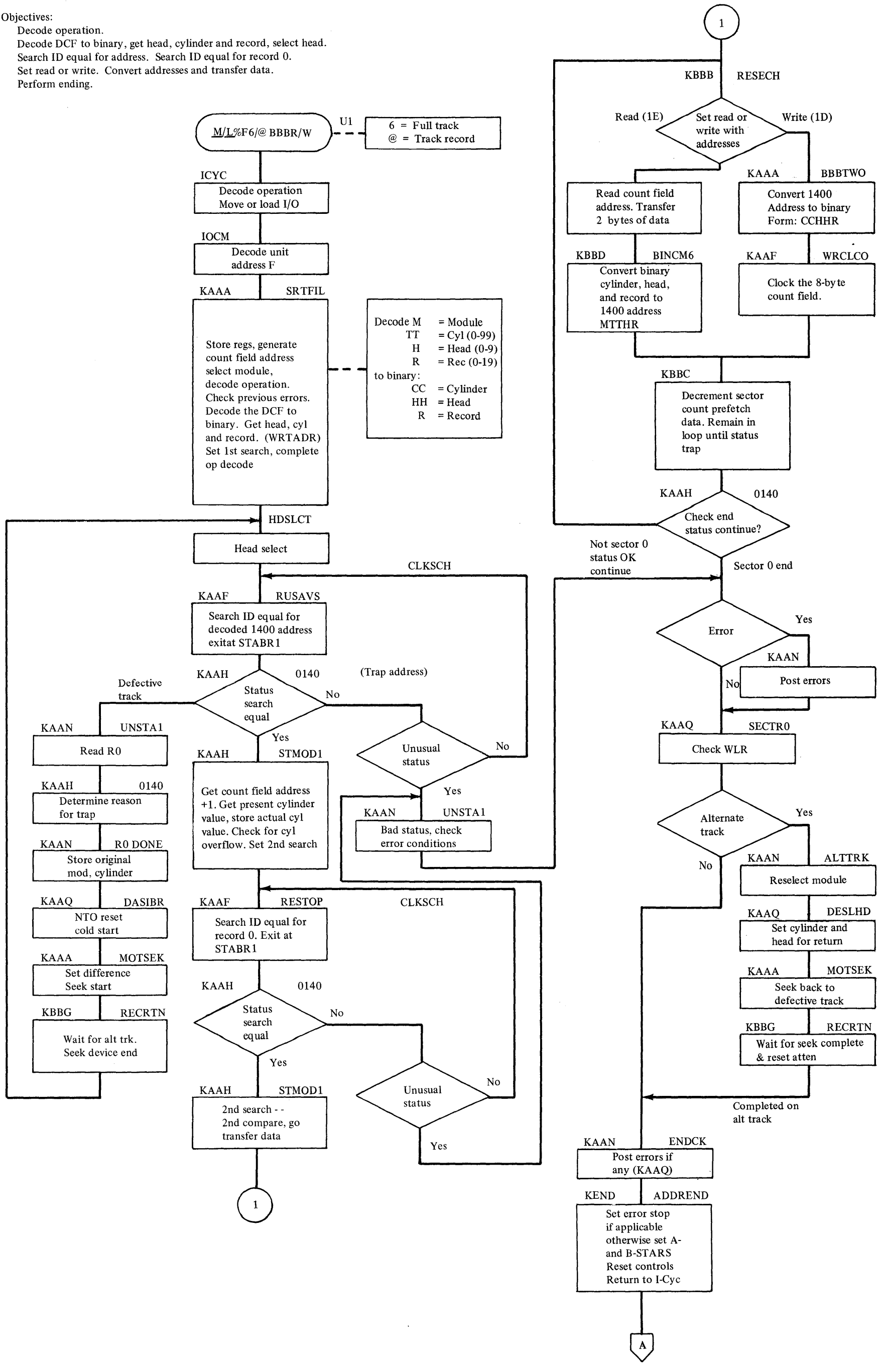


Diag 5-701

Objectives:

- Decode operation.
- Decode DCF to binary, get head, cylinder and record, select head.
- Search ID equal for address. Search ID equal for record 0.
- Set read or write. Convert addresses and transfer data.
- Perform ending.

A
B
C
D
E
F
G
H



Diag 5-701

Diagram 5-737. 1400 Compatibility, R/W Disk with Addresses

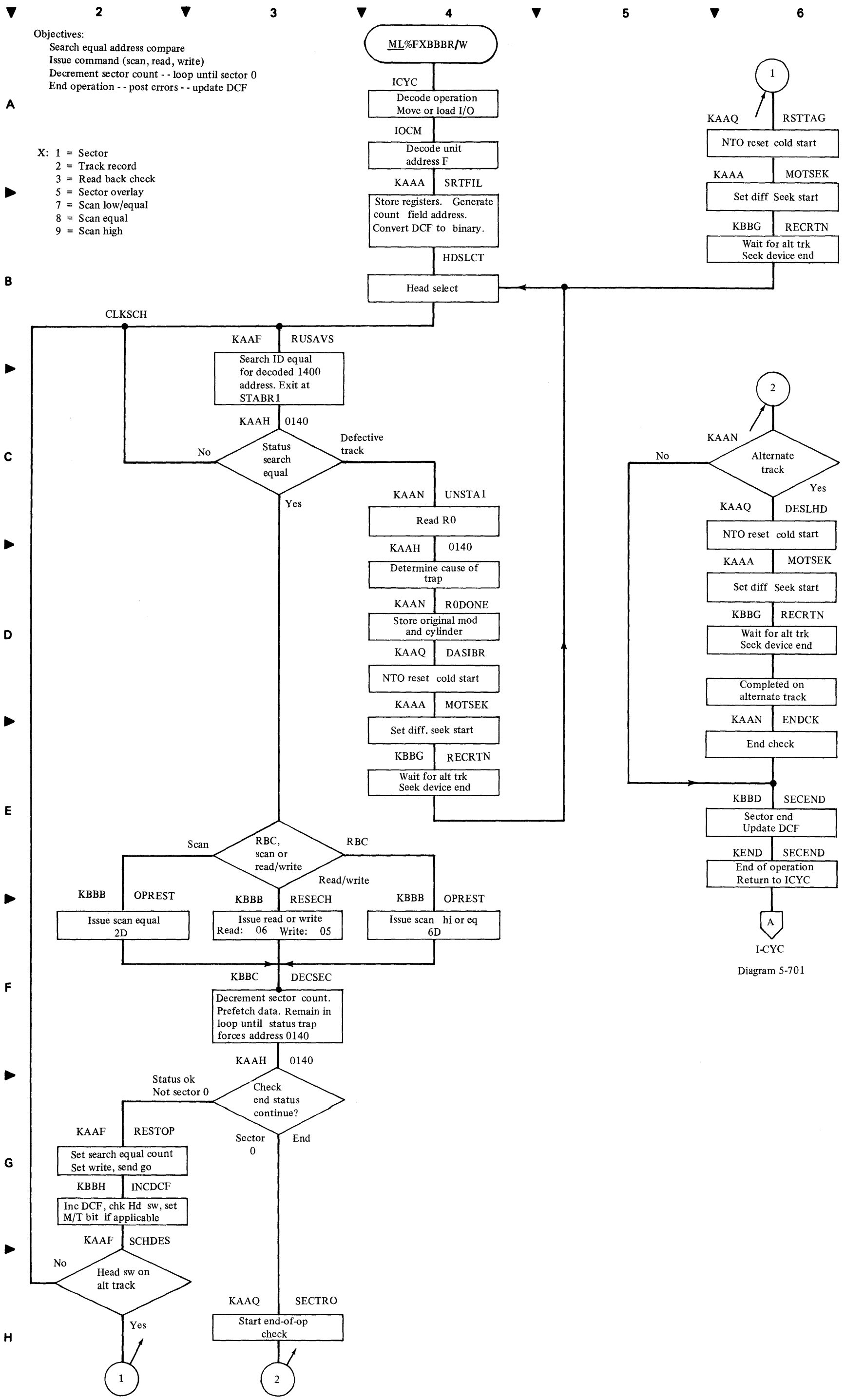
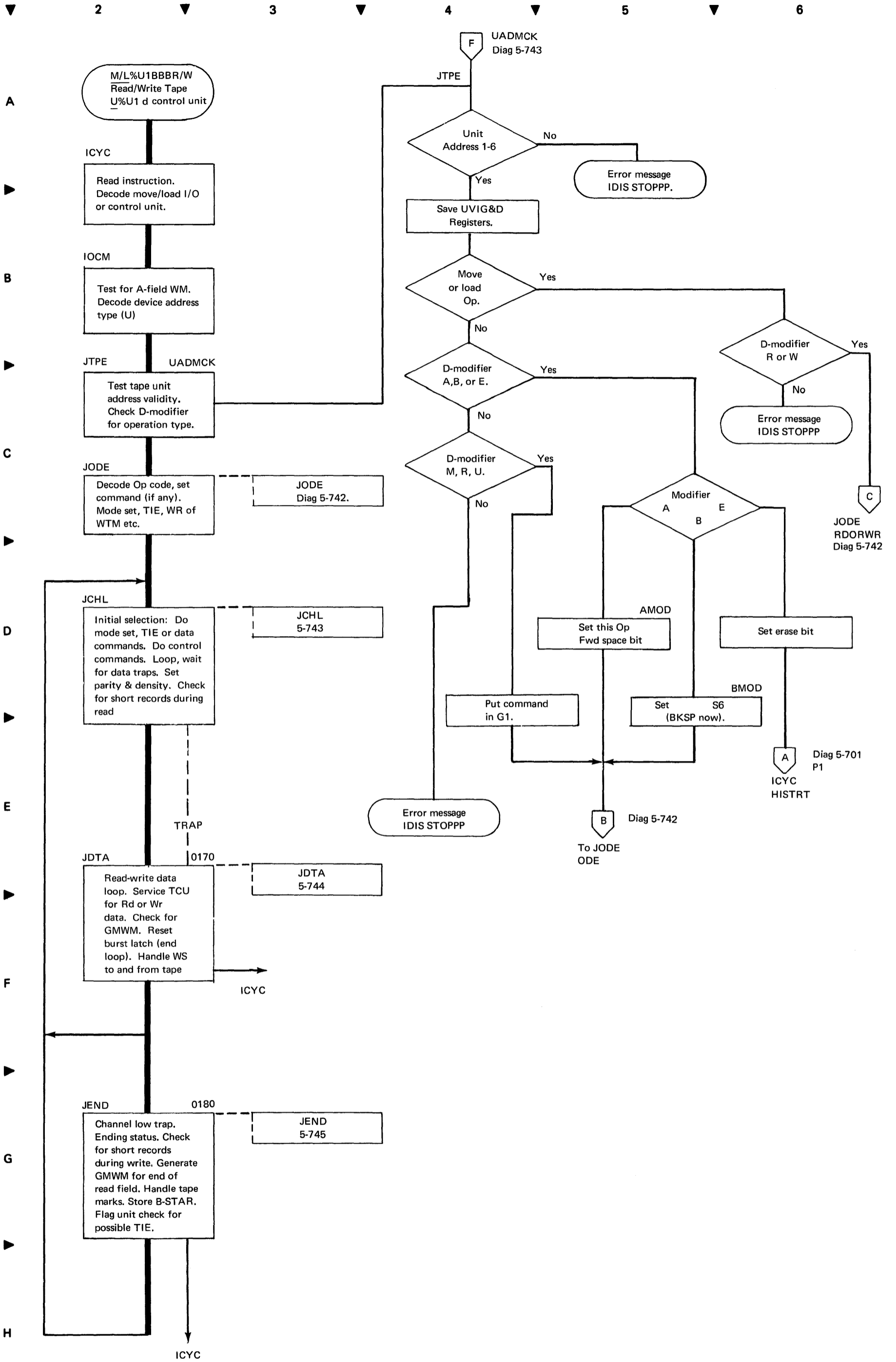
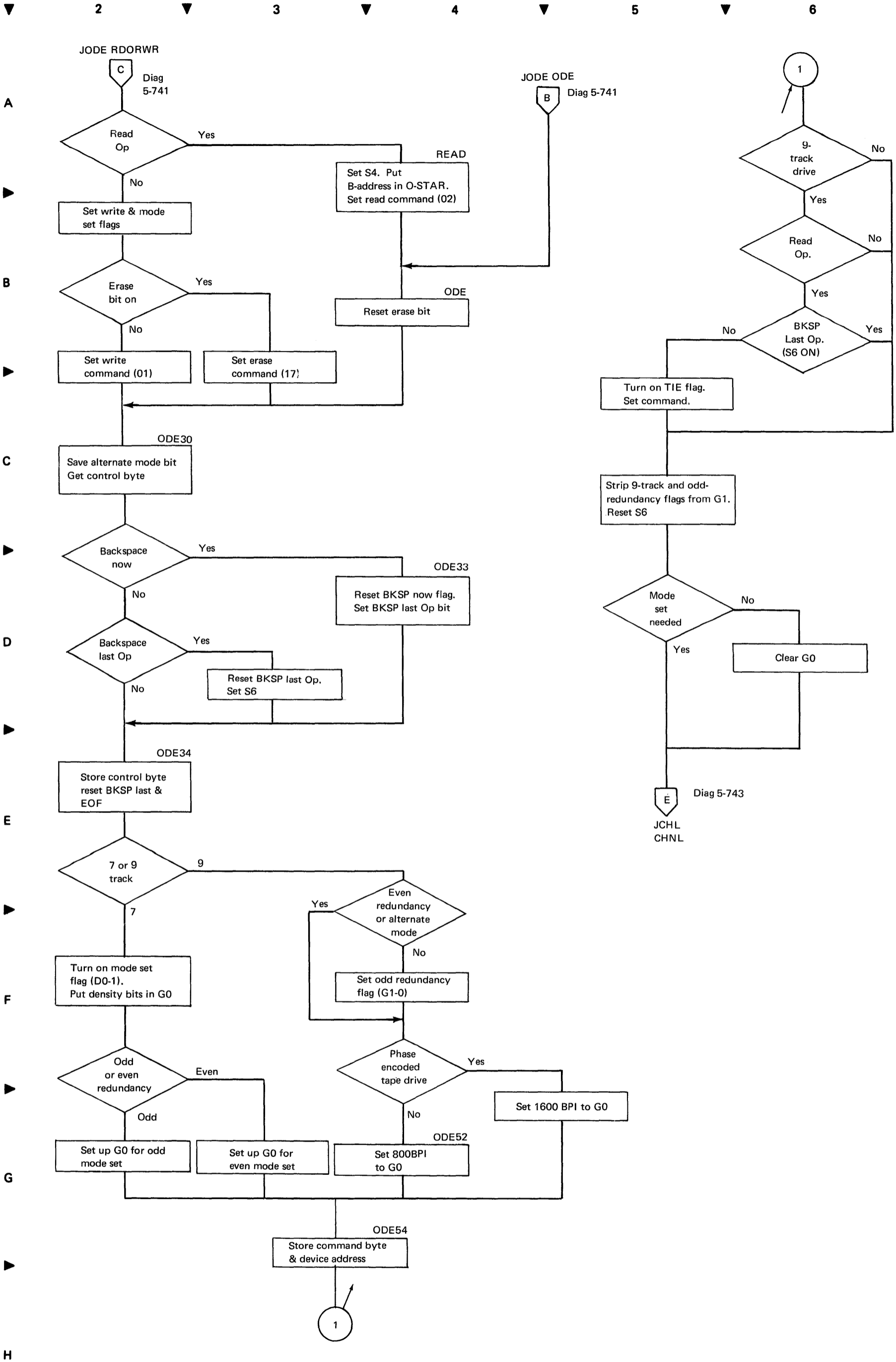


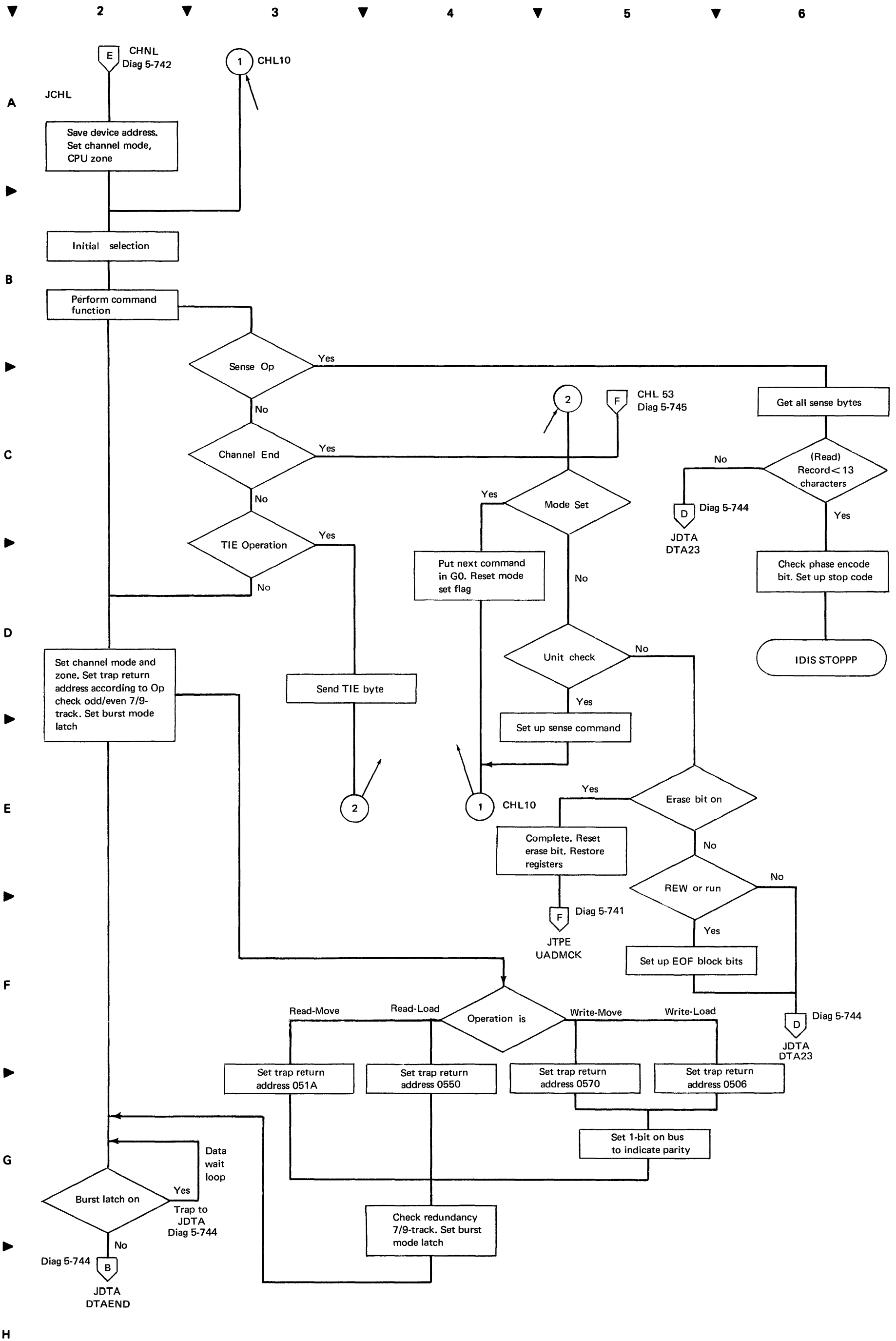
Diagram 5-739. 1400 Compatibility R/W Disk Sector Mode



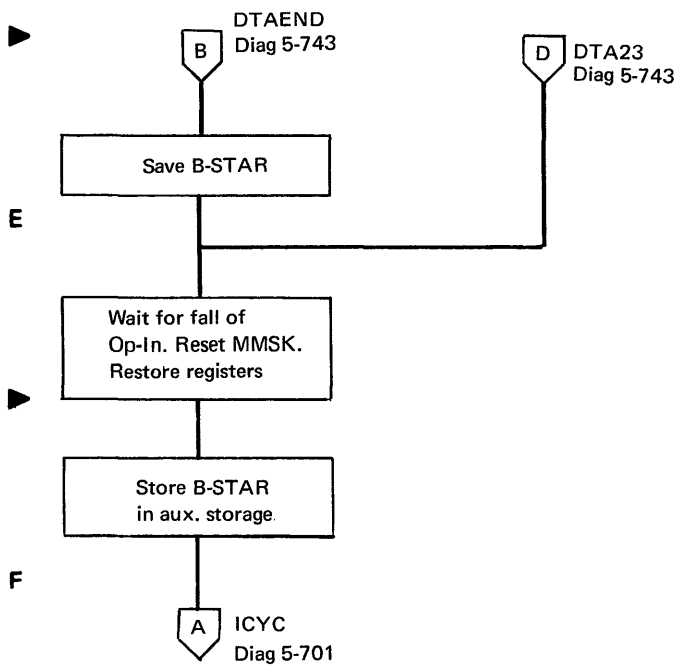
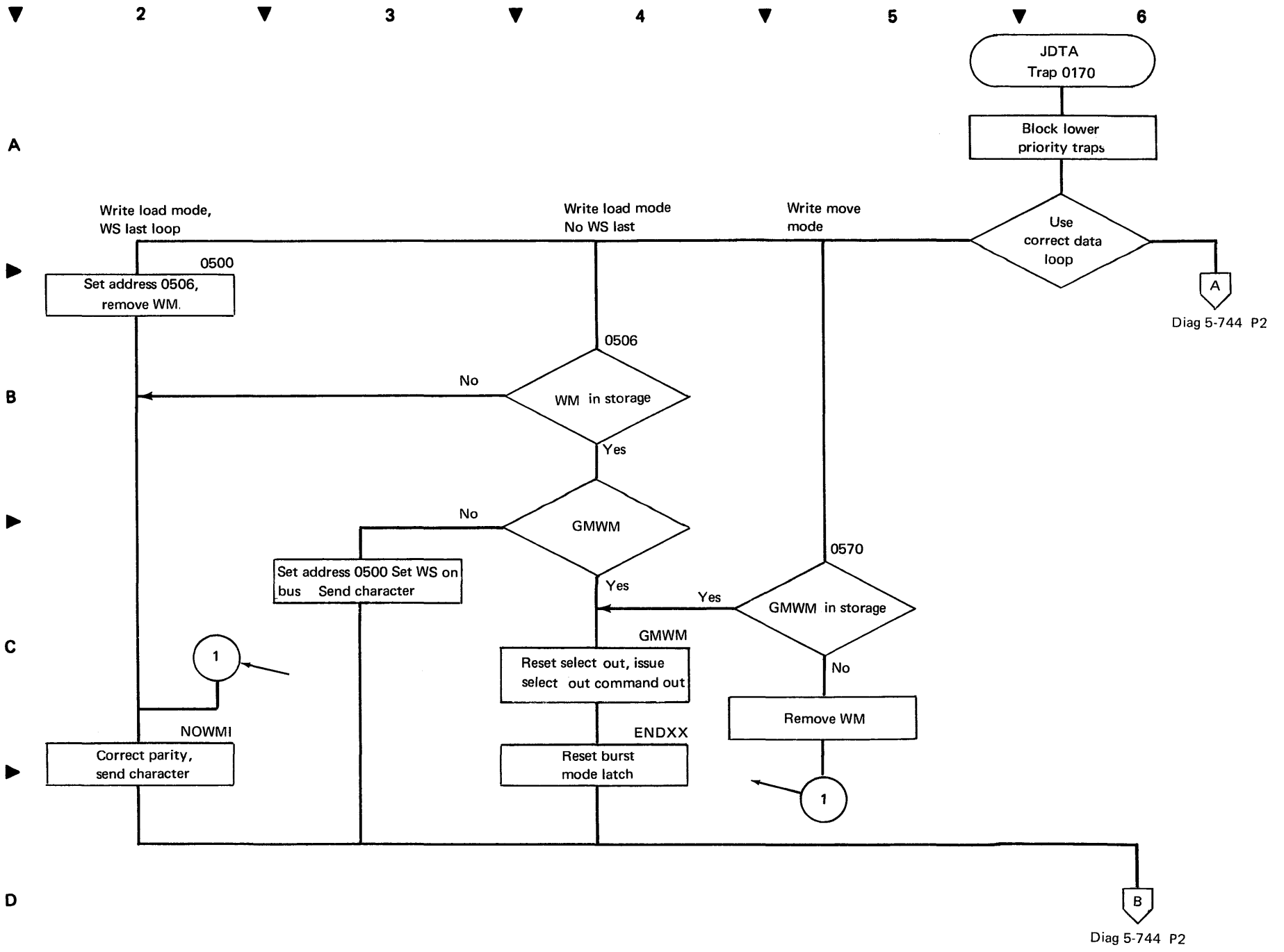
● Diagram 5-741. 1400 Compatibility - Tape Operations; General



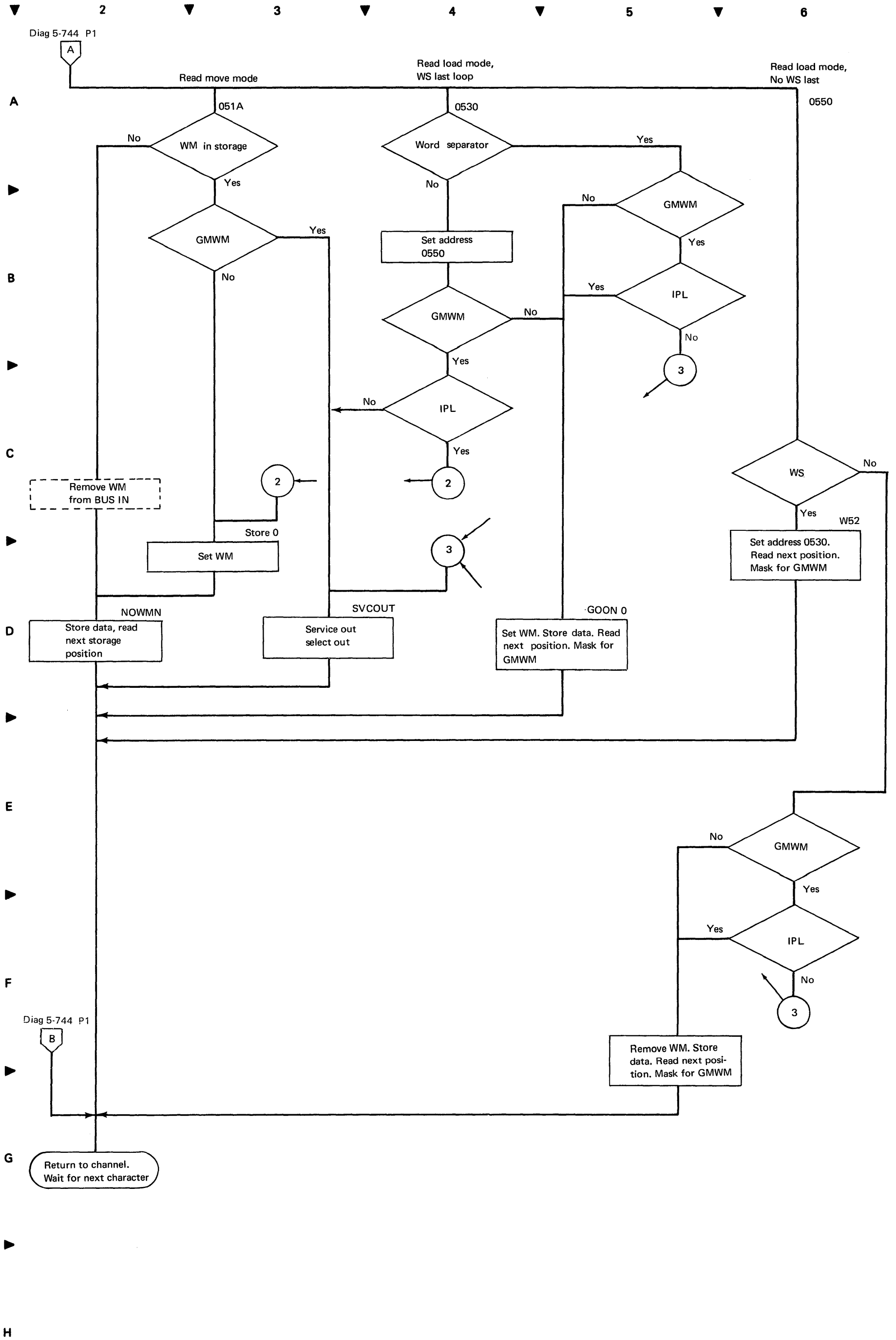
● Diagram 5-742. 1400 Compatibility - Tape Operations; Op Code Decode



● Diagram 5-743. 1400 Compatibility - Tape Operations; Channel



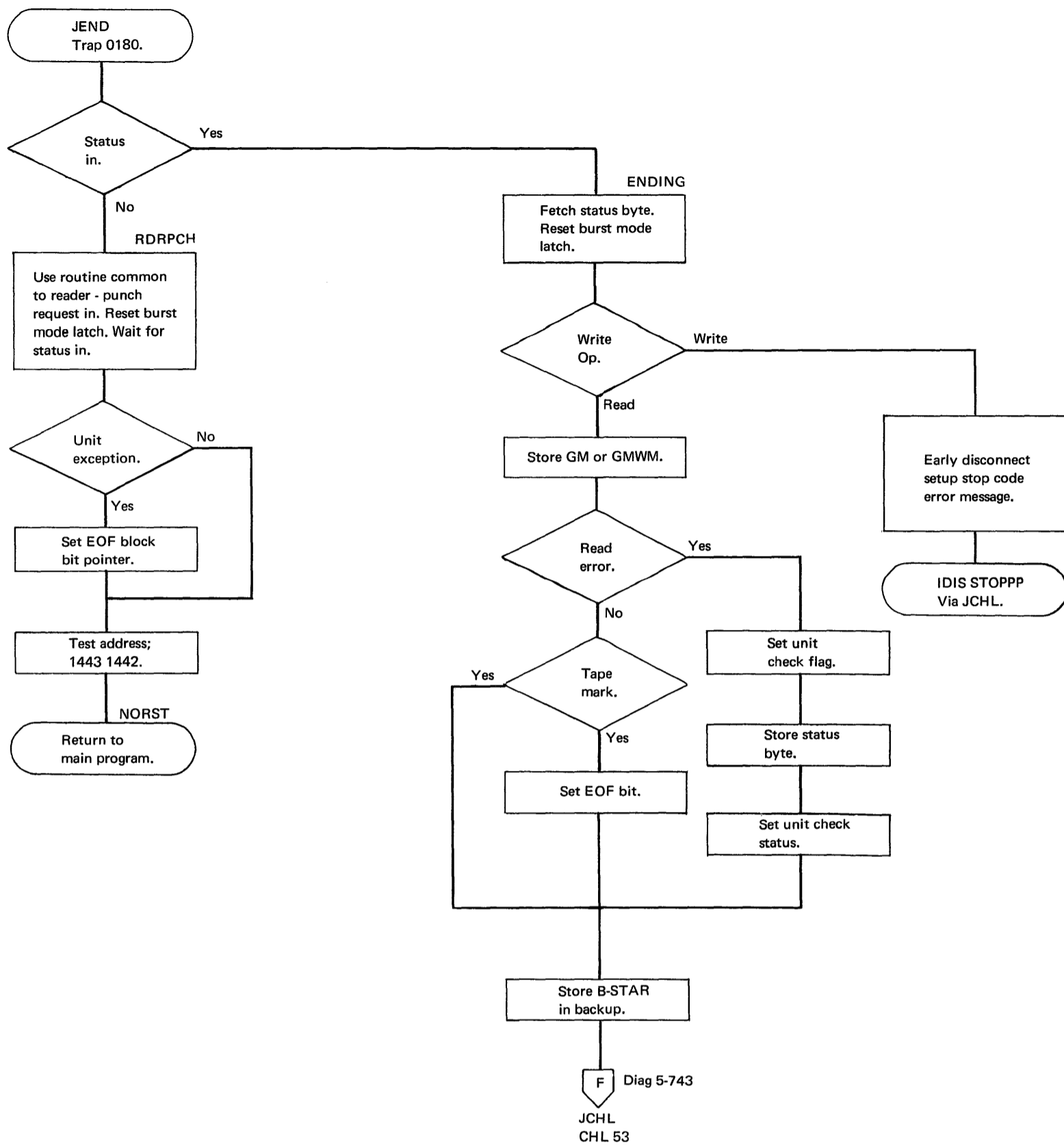
● Diagram 5-744. 1400 Compatibility - Tape Operations; Data Loops (Part 1 of 2)



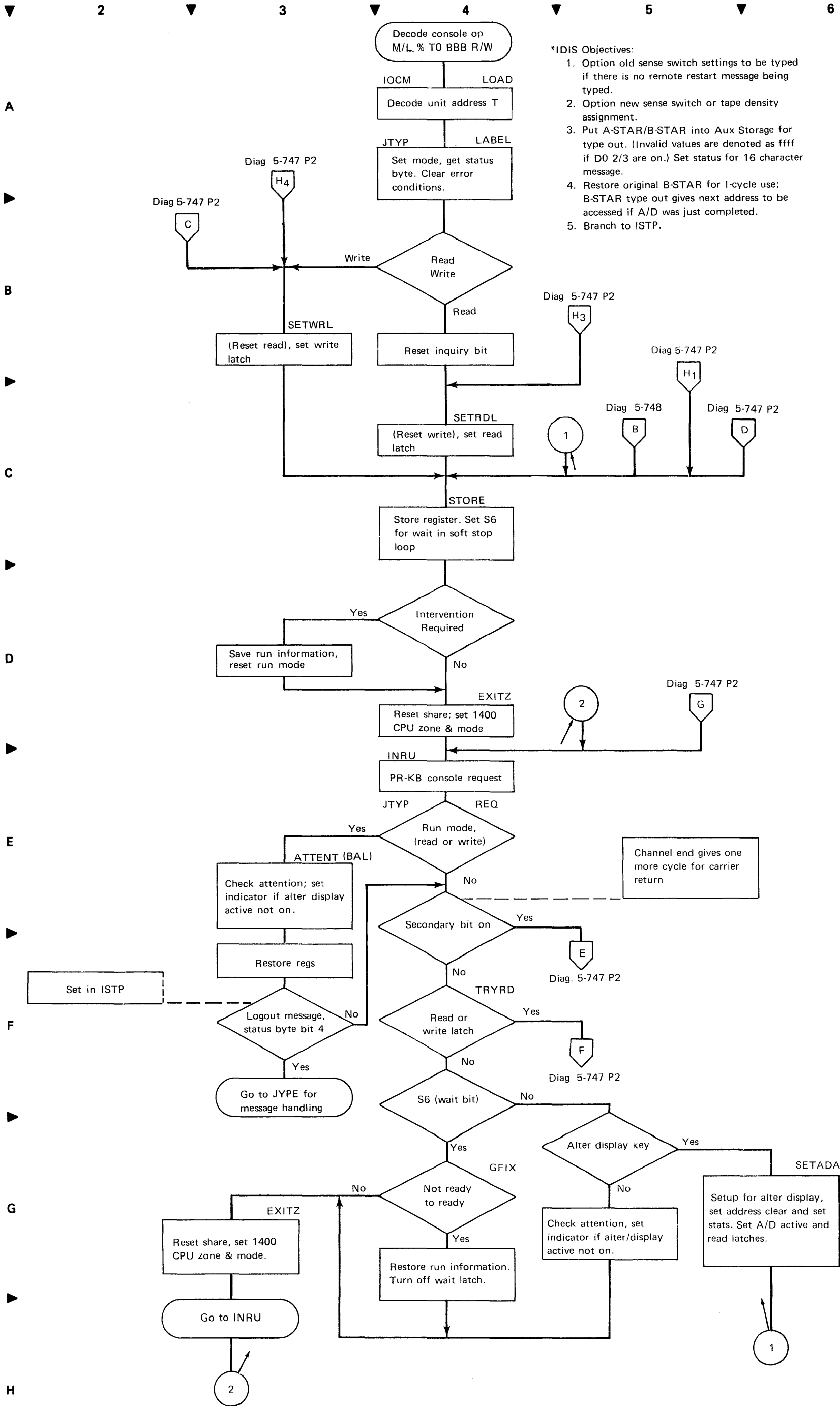
● Diagram 5-744. 1400 Compatibility - Tape Operations; Data Loops (Part 2 of 2)

▼ 2 ▼ 3 ▼ 4 ▼ 5 ▼ 6

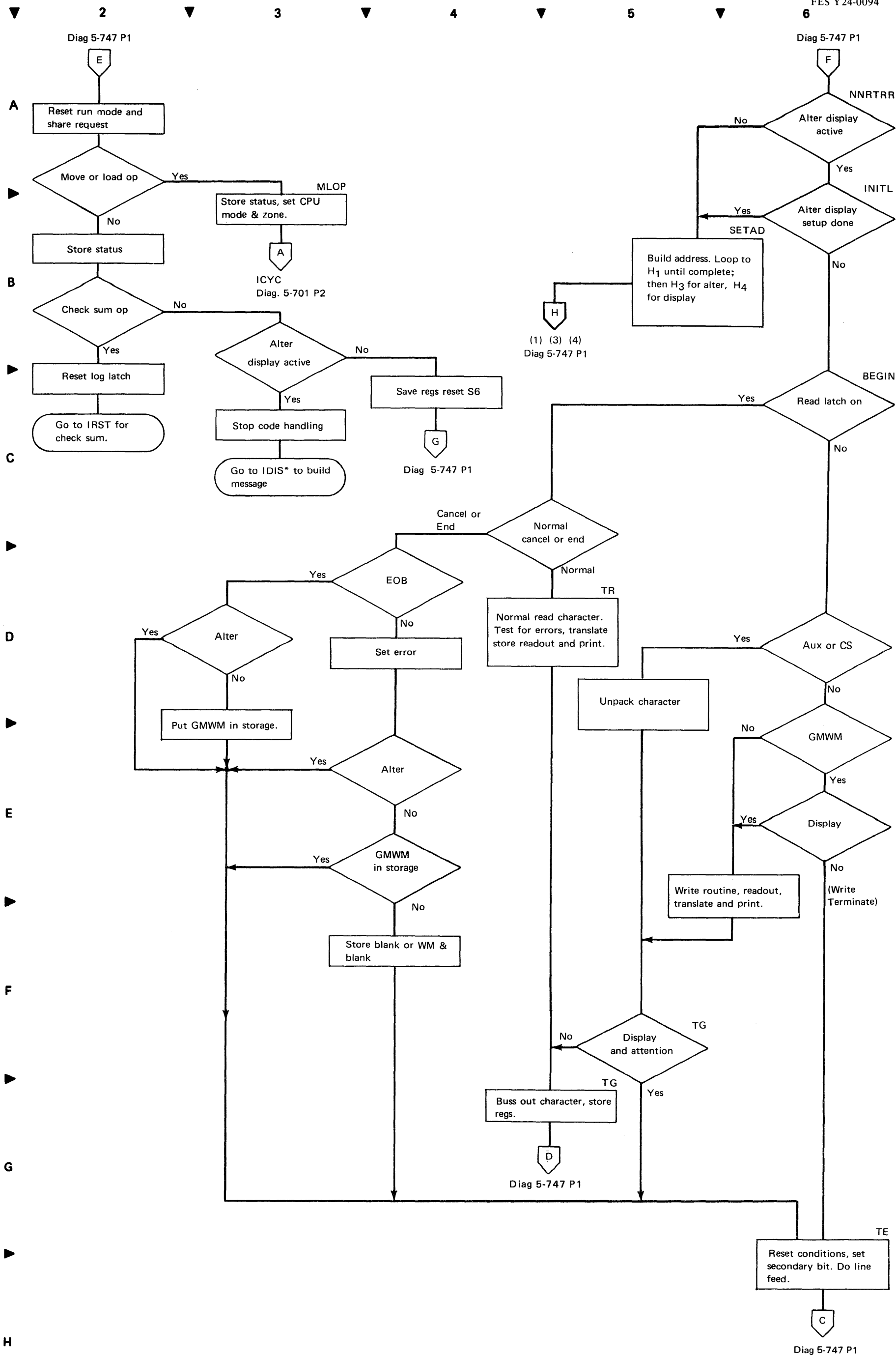
A
▶
B
▶
C
▶
D
▶
E
▶
F
▶
G
▶
H



● Diagram 5-745. 1400 Compatibility - Tape Operations; Ending



● Diagram 5-747. 1400 Compatibility-PR-KB Share Request Handling Routine (Part 1 of 2)



● Diagram 5-747. 1400 Compatibility-PR-KB Share Request Handling Routine (Part 2 of 2)

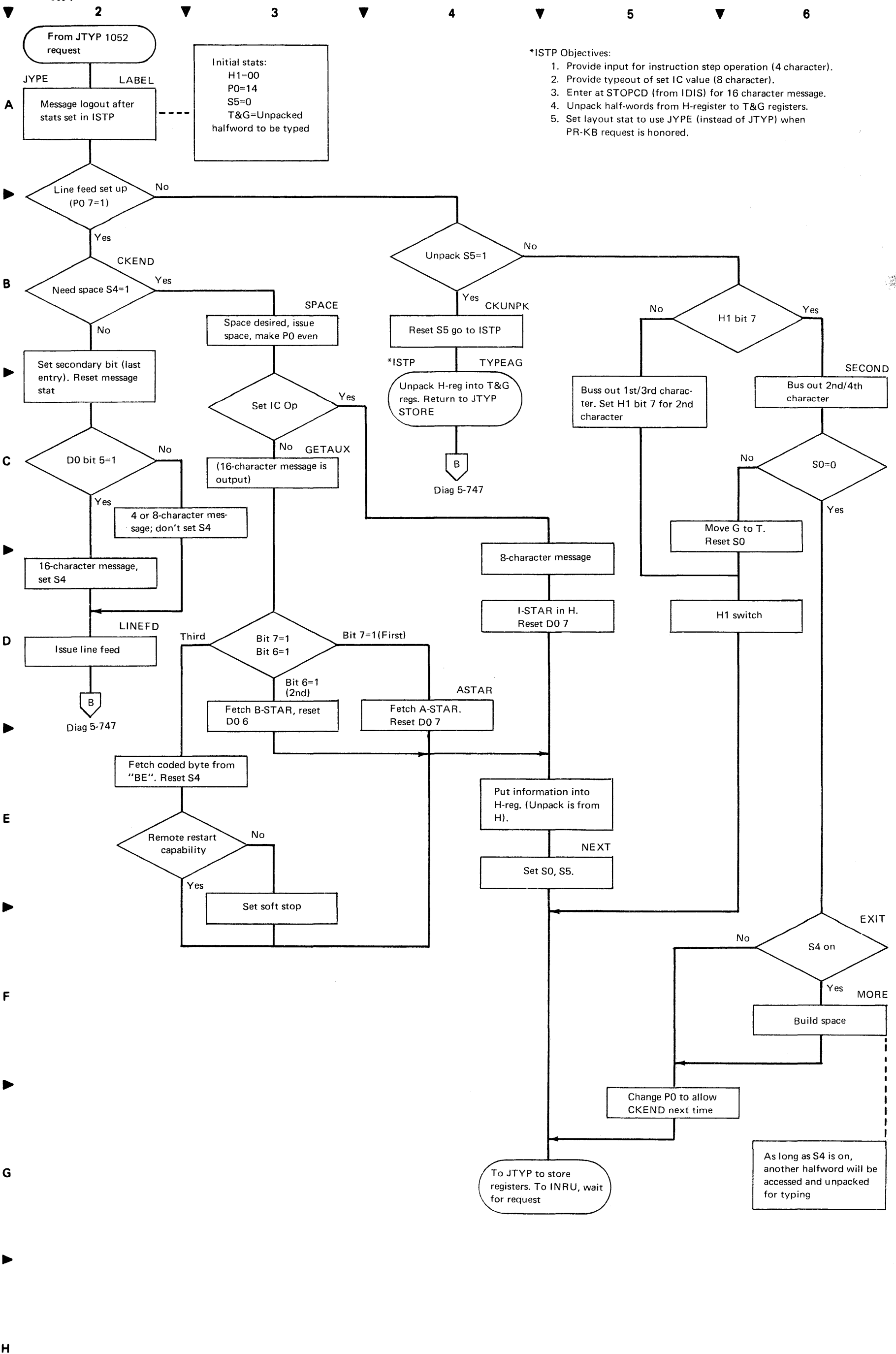


Diagram 5-748. 1400 Compatibility-PR-KB Display Messages

The IBM logo consists of the letters "IBM" in a bold, sans-serif font, with a small registered trademark symbol (®) to the right of the "M". A diagonal line extends from the top right of the "M" upwards and to the right.

FE Supplement

System: System/360 Model 25

Re: Form No. Y24-3529-0

This Supplement No. Y24-0506

Date: June 12, 1969

Previous Supplement No. Y24-0086
Y24-0094
Y24-0503

**LOGIC DIAGRAMS AND OPERATIONAL DIAGRAMS FOR THE SYSTEM/360 MODEL 25,
INTEGRATED COMMUNICATIONS ATTACHMENT FEATURE**

This supplement adds new diagrams to the Field Engineering Maintenance Diagram Manual, 2025 Processing Unit, Form Y24-3529-0. Diagrams to be inserted and/or removed are listed below.

iii, iv
v
vii, viii (added due
ix, x to change
xi, xii in layout)
1-1 (9 parts), 1-3
3-11, 3-12 (added)
4-500 through 591 (added)
5-500 through 514 (added)

A change to the text or a small change to an illustration is indicated by a vertical line to the left of the change; a changed or added illustration is denoted by the symbol ● to the left of the caption.

Summary of Amendments.

This supplement provides logic diagrams, operational diagrams, and revised diagnostic strategy diagrams for the Integrated Communications Attachment. Front matter pages (pages numbered with roman numerals) are included because of re-layout. Parts 4 and 9 of diagram 1-1 are included because of the addition of technical information. The remaining parts of diagram 1-1 are included because of re-layout and do not reflect any technical changes.

File this cover letter at the back of the manual to provide a record of the changes.

IBM Corporation, Product Publications, Endicott, N. Y. 13760

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IBM / **FE Supplement**

System: System/360 Model 25

Re: Form No. Y24-3529-0

This Supplement No. Y24-0503

Date: March 25, 1969

Previous Supplement No. Y24-0086
Y24-0094

LOGIC DIAGRAMS AND OPERATIONAL DIAGRAMS FOR SYSTEM/360 MODEL 25,
INTEGRATED 2560 ATTACHMENT

This supplement adds new diagrams to the Field Engineering Maintenance Diagram Manual, 2025 Processing Unit, Form Y24-3529-0.

List of diagrams to be inserted and/or removed.

iii, iv
4-213, 4-301
4-651 through 4-695 (added)
5-203
5-651 through 5-675 (added)
5-709
5-721, 5-722
5-723
5-725, 5-727
5-735
5-747 (Part 1)

A change to the text is indicated by a vertical line to the left of the change; added illustrations are denoted by the symbol ● to the left of the caption.

Summary of Amendments.

Logic diagrams for System/360 Model 25 Integrated 2560 Attachment are added.

Operational diagrams for System/360 Model 25 Integrated 2560 Attachment are added.

Operational diagrams for System/360 Model 25 1400 Compatibility Feature are included in this supplement to correct the numerical sequence in supplement number Y24-0094.

File this cover letter at the back of the manual to provide a record of changes.

IBM / **FE Supplement**

System System/360 Model 25

Re: Form No. Y24-3529-0

This Supplement No. Y24-0094

Date: February 28, 1969

Previous Supplement No. Y24-0086

This supplement provides replacement pages for the 2025 Processing Unit, Field Engineering Maintenance Diagram Manual, Form Y24-3529-0.

List of pages to be inserted and/or removed.

ii
iii, iv
4-200 through 4-213
5-301 through 5-307 (added)
5-709 (added)
5-722 (added)
5-727 (added)
5-733 (added)
5-747 (added)
5-748 (added)

A change to the text or a small change to an illustration is indicated by a vertical line to the left of the change; a changed or added diagram is denoted by the symbol ● next to the caption or folio.

Summary of Amendments.

Logic diagrams for the Integrated 1403 Attachment have been updated to reflect 1403 Model N1 capability.

Operational diagrams for the Integrated 2311 Attachment are added.

Additional operational diagrams for the 1400 Compatibility feature are added.

File this cover letter at the back of the manual to provide a record of changes.

IBM**FE Supplement**

System System/360 Model 25

Re: Form No. Y24-3529-0

This Supplement No. Y24-0086

Date: January 20, 1969

Previous Supplement No. None

OPERATIONAL DIAGRAMS FOR SYSTEM/360 MODEL 20 MODE FEATURE AND
1400 COMPATIBILITY TAPE OPERATIONS.

This supplement replaces diagrams in the Field Engineering Maintenance Diagram Manual, 2025 Processing Unit, Form Y24-3529-0.

List of diagrams to be inserted and/or removed.

iii, iv
1-1 through 1-300 (Category 1 replaced entirely)
5-600 through 5-640 (added)
5-721, 5-723,
5-725, blank
5-741 through 5-745 (added)

A changed or added diagram is indicated by the symbol ● near the caption.

Summary of Amendments.

Category 1 is replaced entirely and includes the diagnostic techniques for the System/360 Model 20 Mode feature.

Operational diagrams for System/360 Model 20 Mode feature are added to Category 5.

Operational diagrams for 1400 Compatibility Tape Operations and 1403 Printer are also added to Category 5.

File this cover letter at the back of the manual to provide a record of changes.

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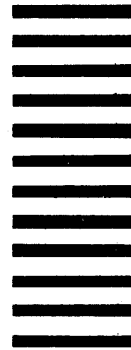
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